TEXAS INSTRUMENTS

ABT Logic
Advanced BiCMOS Technology

A High-Performance Line of 5-V Products

Data Book

1998

Logic Products

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INTRODUCTION

The Advanced BiCMOS Technology (ABT) logic family has earned its place as the preferred high-performance 5-V logic family. It combines high-drive capability, lower power consumption, low noise, and propagation delays fast enough to be transparent with respect to overall system performance. Optimized for live-insertion applications with an I_{off} specification of 0.1 mA, ABT logic delivers the most complete solution for high-performance 5-V designs. In addition, the ABT logic family offers the broadest line of advanced-bus products in the industry. With over 100 released devices ranging from the simple and popular octal buffer/transceiver to the multifunction 36-bit universal bus transceivers (UBT™), all offered in a variety of surface-mount and fine-pitch package options, the performance premium of ABT is enhanced by product selection.

ABT features include:

- 2.3-ns typical, 3.9-ns maximum propagation delays ('245B)
- Low noise < 0.8 V
- High 64-mA drive for heavily loaded signal lines
- I_{off} specification of 0.1 mA to allow for live insertion
- Power-up 3-state to ensure valid output levels during power up
- Bus hold (selected functions) (ABTHxxx, ABTH16xxx)
- Series-damping-resistor options (selected functions) (ABT2xxx, ABT162xxx)
- Package options ranging from PDIP, SOIC, SSOP, and TSSOP to TVSOP
- JTAG devices available (see the *1997 Boundary-Scan Logic IEEE Std 1149.1 (JTAG) Data Book*, literature number SCTD002A)

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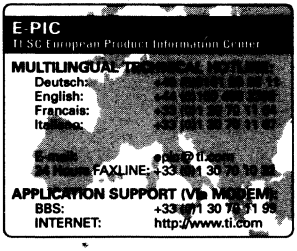

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PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

Contents

INTRODUCTION

These symbols, terms, and definitions are in accordance with those currently agreed upon by the JEDEC Council of the Electronic Industries Association (EIA) for use in the USA and by the International Electrotechnical Commission (IEC) for international use.

operating conditions and characteristics (in sequence by letter symbols)

C_i **Input capacitance**
The internal capacitance at an input of the device

C_{io} **Input/output capacitance**
Input-to-output internal capacitance; transcapacitance

C_o **Output capacitance**
The internal capacitance at an output of the device

C_{pd} **Power dissipation capacitance**
Used to determine the no-load dynamic power dissipation per logic function (see individual circuit pages):
$P_D = C_{pd} V_{CC}^2 f + I_{CC} V_{CC}$

f_{max} **Maximum clock frequency**
The highest rate at which the clock input of a bistable circuit can be driven through its required sequence while maintaining stable transitions of logic level at the output with input conditions established that should cause changes of output logic level in accordance with the specification

I_{CC} **Supply current**
The current into* the V_{CC} supply terminal of an integrated circuit

ΔI_{CC} **Supply current change**
The increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}

I_{CEX} **Output high leakage current**
The maximum leakage current into the collector of the pulldown output transistor when the output is high and the output forcing condition $V_O = 5.5$ V

$I_{I(hold)}$ **Input hold current**
Input current that holds the input at the previous state when the driving device goes to a high-impedance state

I_{IH} **High-level input current**
The current into* an input when a high-level voltage is applied to that input

I_{IL} **Low-level input current**
The current into* an input when a low-level voltage is applied to that input

I_{off} **Input/output power-off leakage current**
The maximum leakage current into/out of the input/output transistors when forcing the input/output to 4.5 V and $V_{CC} = 0$ V

I_{OH} **High-level output current**
The current into* an output with input conditions applied that, according to the product specification, establishes a high level at the output

*Current out of a terminal is given as a negative value.

I_{OL} **Low-level output current**

The current into* an output with input conditions applied that, according to the product specification, establishes a low level at the output

I_{OZ}, $I_{OZPU/PD}$ **Off-state (high-impedance-state) output current (of a 3-state output)**

The current flowing into* an output having 3-state capability with input conditions established that, according to the product specification, establishes the high-impedance state at the output

t_a **Access time**

The time interval between the application of a specified input pulse and the availability of valid signals at an output

t_c **Clock cycle time**

Clock cycle time is $1/f_{max}$.

t_{dis} **Disable time (of a 3-state or open-collector output)**

The propagation time between the specified reference points on the input and output voltage waveforms with the output changing from either of the defined active levels (high or low) to a high-impedance (off) state

NOTE: For 3-state outputs, $t_{dis} = t_{PHZ}$ or t_{PLZ}. Open-collector outputs change only if they are low at the time of disabling, so $t_{dis} = t_{PLH}$.

t_{en} **Enable time (of a 3-state or open-collector output)**

The propagation time between the specified reference points on the input and output voltage waveforms with the output changing from a high-impedance (off) state to either of the defined active levels (high or low)

NOTE: In the case of memories, this is the access time from an enable input (e.g., $\overline{OE}$). For 3-state outputs, $t_{en} = t_{PZH}$ or t_{PZL}. Open-collector outputs change only if they are responding to data that would cause the output to go low, so $t_{en} = t_{PHL}$.

t_h **Hold time**

The time interval during which a signal is retained at a specified input terminal after an active transition occurs at another specified input terminal

NOTES: 1. The hold time is the actual time interval between two signal events and is determined by the system in which the digital circuit operates. A minimum value is specified that is the shortest interval for which correct operation of the digital circuit is to be expected.

2. The hold time may have a negative value in which case the minimum limit defines the longest interval (between the release of the signal and the active transition) for which correct operation of the digital circuit is to be expected.

t_{pd} **Propagation delay time**

The time between the specified reference points on the input and output voltage waveforms with the output changing from one defined level (high or low) to the other defined level ($t_{pd} = t_{PHL}$ or t_{PLH})

t_{PHL} **Propagation delay time, high-to-low level output**

The time between the specified reference points on the input and output voltage waveforms with the output changing from the defined high level to the defined low level

t_{PHZ} **Disable time (of a 3-state output) from high level**

The time interval between the specified reference points on the input and the output voltage waveforms with the 3-state output changing from the defined high level to the high-impedance (off) state

*Current out of a terminal is given as a negative value.

t_{PLH} **Propagation delay time, low-to-high level output**

The time between the specified reference points on the input and output voltage waveforms with the output changing from the defined low level to the defined high level

t_{PLZ} **Disable time (of a 3-state output) from low level**

The time interval between the specified reference points on the input and the output voltage waveforms with the 3-state output changing from the defined low level to the high-impedance (off) state

t_{PZH} **Enable time (of a 3-state output) to high level**

The time interval between the specified reference points on the input and output voltage waveforms with the 3-state output changing from the high-impedance (off) state to the defined high level

t_{PZL} **Enable time (of a 3-state output) to low level**

The time interval between the specified reference points on the input and output voltage waveforms with the 3-state output changing from the high-impedance (off) state to the defined low level

$t_{sk(o)}$ **Output skew**

The difference between any two propagation delay times when a single switching input or multiple inputs switching simultaneously cause multiple outputs to switch, as observed across all switching output. This parameter is used to describe the fanout capability of a clock driver and is of concern when making decisions on clock buffering and distribution networks.

t_{su} **Setup time**

The time interval between the application of a signal at a specified input terminal and a subsequent active transition at another specified input terminal

NOTES: 1. The setup time is the actual time interval between two signal events and is determined by the system in which the digital circuit operates. A minimum value is specified that is the shortest interval for which correct operation of the digital circuit is to be expected.

2. The setup time may have a negative value, in which case the minimum limit defines the longest interval (between the active transition and the application of the other signal) for which correct operation of the digital circuit is to be expected.

t_w **Pulse duration (width)**

The time interval between specified reference points on the leading and trailing edges of the pulse waveform

V_{IH} **High-level input voltage**

An input voltage within the more positive (less negative) of the two ranges of values used to represent the binary variables

NOTE: A minimum is specified that is the least-positive value of high-level input voltage for which operation of the logic element within specification limits is to be expected.

V_{IL} **Low-level input voltage**

An input voltage within the less positive (more negative) of the two ranges of values used to represent the binary variables

NOTE: A maximum is specified that is the most-positive value of low-level input voltage for which operation of the logic element within specification limits is to be expected.

V_{OH} **High-level output voltage**

The voltage at an output terminal with input conditions applied that, according to product specification, establishes a high level at the output

V_{OL} **Low-level output voltage**

The voltage at an output terminal with input conditions applied that, according to product specification, establishes a low level at the output

V_{IT+} **Positive-going input threshold level**

The voltage level at a transition-operated input that causes operation of the logic element according to specification as the input voltage rises from a level below the negative-going threshold voltage, V_{IT-}

V_{IT-} **Negative-going input threshold level**

The voltage level at a transition-operated input that causes operation of the logic element according to specification as the input voltage falls from a level above the positive-going threshold voltage, V_{IT+}

The following symbols are used in function tables on TI data sheets:

H	=	high level (steady state)
L	=	low level (steady state)
↑	=	transition from low to high level
↓	=	transition from high to low level
→	=	value/level or resulting value/level is routed to indicated destination
↶	=	value/level is re-entered
X	=	irrelevant (any input, including transitions)
Z	=	off (high-impedance) state of a 3-state output
a . . . h	=	the level of steady-state inputs A through H, respectively
Q_0	=	level of Q before the indicated steady-state input conditions were established
$\overline{Q}_0$	=	complement of Q_0 or level of $\overline{Q}$ before the indicated steady-state input conditions were established
Q_n	=	level of Q before the most recent active transition indicated by ↓ or ↑
⎍	=	one high-level pulse
⎎	=	one low-level pulse
Toggle	=	each output changes to the complement of its previous level on each active transition indicated by ↓ or ↑

If, in the input columns, a row contains only the symbols H, L, and/or X, this means the indicated output is valid whenever the input configuration is achieved and regardless of the sequence in which it is achieved. The output persists so long as the input configuration is maintained.

If, in the input columns, a row contains H, L, and/or X together with ↑ and/or ↓, this means the output is valid whenever the input configuration is achieved but the transition(s) must occur following the achievement of the steady-state levels. If the output is shown as a level (H, L, Q_0, or $\overline{Q}_0$), it persists so long as the steady-state input levels and the levels that terminate indicated transitions are maintained. Unless otherwise indicated, input transitions in the opposite direction to those shown have no effect at the output. (If the output is shown as a pulse, ⎍ or ⎎, the pulse follows the indicated input transition and persists for an interval dependent on the circuit.)

EXPLANATION OF FUNCTION TABLES

Among the most complex function tables are those of the shift registers. These embody most of the symbols used in any of the function tables, plus more. Below is the function table of a 4-bit bidirectional universal shift register.

FUNCTION TABLE

INPUTS										OUTPUTS			
CLEAR	MODE		CLOCK	SERIAL		PARALLEL				Q_A	Q_B	Q_C	Q_D
	S1	S0		LEFT	RIGHT	A	B	C	D				
L	X	X	X	X	X	X	X	X	X	L	L	L	L
H	X	X	L	X	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
H	H	H	↑	X	X	a	b	c	d	a	b	c	d
H	L	H	↑	X	H	H	H	H	H	H	Q_{An}	Q_{Bn}	Q_{Cn}
H	L	H	↑	X	L	L	L	L	L	L	Q_{An}	Q_{Bn}	Q_{Cn}
H	H	L	↑	H	X	X	X	X	X	Q_{Bn}	Q_{Cn}	Q_{Dn}	H
H	H	L	↑	L	X	X	X	X	X	Q_{Bn}	Q_{Cn}	Q_{Dn}	L
H	L	L	X	X	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}

The first line of the table represents a synchronous clearing of the register and says that if clear is low, all four outputs will be reset low regardless of the other inputs. In the following lines, clear is inactive (high) and so has no effect.

The second line shows that so long as the clock input remains low (while clear is high), no other input has any effect and the outputs maintain the levels they assumed before the steady-state combination of clear high and clock low was established. Since on other lines of the table only the rising transition of the clock is shown to be active, the second line implicitly shows that no further change in the outputs occurs while the clock remains high or on the high-to-low transition of the clock.

The third line of the table represents synchronous parallel loading of the register and says that if S1 and S0 are both high then, without regard to the serial input, the data entered at A is at output Q_A, data entered at B is at Q_B, and so forth, following a low-to-high clock transition.

The fourth and fifth lines represent the loading of high- and low-level data, respectively, from the shift-right serial input and the shifting of previously entered data one bit; data previously at Q_A is now at Q_B, the previous levels of Q_B and Q_C are now at Q_C and Q_D, respectively, and the data previously at Q_D is no longer in the register. This entry of serial data and shift takes place on the low-to-high transition of the clock when S1 is low and S0 is high and the levels at inputs A through D have no effect.

The sixth and seventh lines represent the loading of high- and low-level data, respectively, from the shift-left serial input and the shifting of previously entered data one bit; data previously at Q_B is now at Q_A, the previous levels of Q_C and Q_D are now at Q_B and Q_C, respectively, and the data previously at Q_A is no longer in the register. This entry of serial data and shift takes place on the low-to-high transition of the clock when S1 is high and S0 is low and the levels at inputs A through D have no effect.

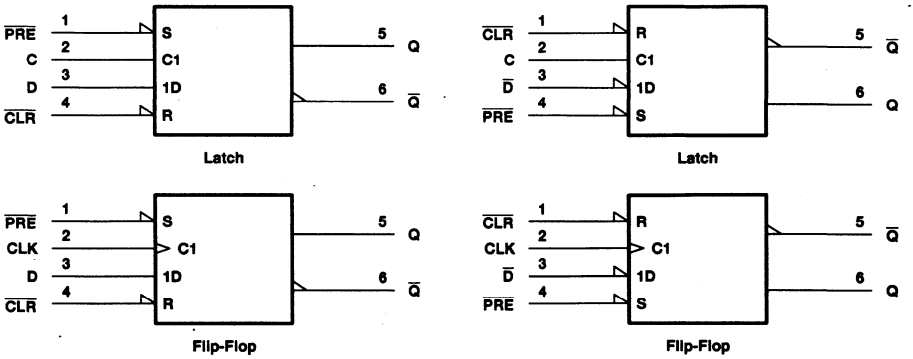
The last line shows that as long as both inputs are low, no other input has any effect and, as in the second line, the outputs maintain the levels they assumed before the steady-state combination of clear high and both mode inputs low was established.

The function table functional tests do not reflect all possible combinations or sequential modes.

It is normal TI practice to name the outputs and other inputs of a D-type flip-flop or latch and to draw its logic symbol based on the assumption of true data (D) inputs. Outputs that produce data in phase with the data inputs are called Q and those producing complementary data are called $\overline{Q}$. An input that causes a Q output to go high or a $\overline{Q}$ output to go low is called preset (PRE). An input that causes a $\overline{Q}$ output to go high or a Q output to go low is called clear (CLR). Bars are used over these pin names ($\overline{PRE}$ and $\overline{CLR}$) if they are active low.

The devices on several data sheets are second-source designs, and the pin-name conventions used by the original manufacturers have been retained. That makes it necessary to designate the inputs and outputs of the inverting circuits $\overline{D}$ and Q.

In some applications, it may be advantageous to redesignate the data input from D to $\overline{D}$ or vice versa. In that case, all the other inputs and outputs should be renamed as shown below. Also shown are corresponding changes in the graphical symbols. Arbitrary pin numbers are shown.



The figures show that when Q and $\overline{Q}$ exchange names, the preset and clear pins also exchange names. The polarity indicators (⊏) on $\overline{PRE}$ and $\overline{CLR}$ remain, as these inputs are still active low, but the presence or absence of the polarity indicator changes at D (or $\overline{D}$), Q, and $\overline{Q}$. Pin 5 (Q or $\overline{Q}$) is still in phase with the data input (D or $\overline{D}$); their active levels change together.

DEVICE NAMES AND PACKAGE DESIGNATORS

Example:

1 Standard Prefix

Example: SNJ – Conforms to MIL-PRF-38535 (QML)

2 Temperature Range

Examples: 54 – Military
74 – Commercial

3 Family

Examples: Blank – Transistor-Transistor Logic
ABT – Advanced BiCMOS Technology
ABTE – Advanced BiCMOS Technology/ Enhanced Transceiver Logic
AC/ACT – Advanced CMOS Logic
AHC/AHCT – Advanced High-Speed CMOS Logic
ALS – Advanced Low-Power Schottky Logic
AS – Advanced Schottky Logic
ALVC – Advanced Low-Voltage CMOS Technology
BCT – BiCMOS Bus-Interface Technology
CBT – Crossbar Technology
F – F Logic
FB – Backplane Transceiver Logic/Futurebus+
GTL – Gunning Transceiver Logic
HC/HCT – High-Speed CMOS Logic
LS – Low-Power Schottky Logic
LV – Low-Voltage HCMOS Technology
LVC – Low-Voltage CMOS Technology
LVT – Low-Voltage BiCMOS Technology
S – Schottky Logic
SSTL – Stub Series Terminated Logic

4 Special Features

Examples: Blank = No Special Features
D – Level-Shifting Diode (CBTD)
H – Bus Hold (ALVCH)
R – Damping Resistor on Inputs/Outputs (LVCR)
S – Schottky Clamping Diode (CBTS)

5 Bit Width

Examples: Blank = Gates, MSI, and Octals
1G – Single Gate
8 – Octal IEEE 1149.1 (JTAG)
16 – Widebus™ (16, 18, and 20 bit)
18 – Widebus IEEE 1149.1 (JTAG)
32 – Widebus+™ (32 and 36 bit)

6 Options

Examples: Blank = No Options
2 – Series-Damping Resistor on Outputs
4 – Level Shifter
25 – 25-Ω Line Driver

7 Function

Examples: 244 – Noninverting Octal Buffer/Driver
374 – Octal D-Type Flip-Flop
573 – D-Type Transparent Latch
640 – Inverting Octal Transceiver

8 Device Revision

Examples: Blank = No Revision
Letter Designator A–Z

9 Packages

Examples: D, DW – Small-Outline Integrated Circuit (SOIC)
DB, DL – Shrink Small-Outline Package (SSOP)
DBB, DGV – Thin Very Small-Outline Package (TVSOP)
DBV – Small-Outline Transistor Package (SOT)
DGG, PW – Thin Shrink Small-Outline Package (TSSOP)
FK – Leadless Ceramic Chip Carrier (LCCC)
FN – Plastic Leaded Chip Carrier (PLCC)
GB – Ceramic Pin Grid Array (CPGA)
HFP, HS, HT, HV – Ceramic Quad Flat Package (CQFP)
J, JT – Ceramic Dual-In-Line Package (CDIP)
N, NP, NT – Plastic Dual-In-Line Package (PDIP)
PAG, PAH, PCA, PCB, PM, PN, PZ – Plastic Thin Quad Flat Package (TQFP)
PH, PQ, RC – Plastic Quad Flat Package (QFP)
W, WA, WD – Ceramic Flat Package (CFP)

10 Tape and Reel

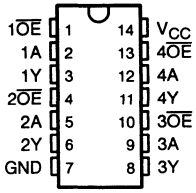
Examples: LE – Left Embossed (required for DB and PW packages)
R – Standard (required for DGG, DBB, DGV, and DBV; optional for D, DL, and DW packages)

Contents

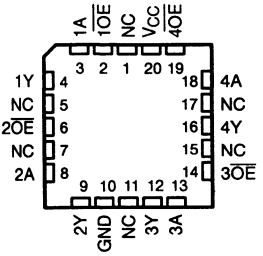
Contents (continued)

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (N) and Ceramic (J) DIPs**

SN54ABT125 . . . J OR W PACKAGE
SN74ABT125 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT125 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABT125 quadruple bus buffer gates feature independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable ($\overline{OE}$) input is high.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT125 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT125 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

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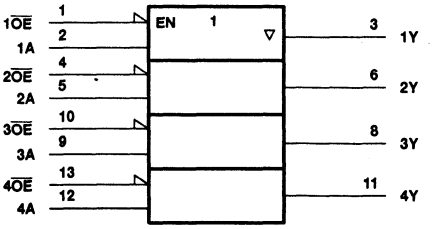
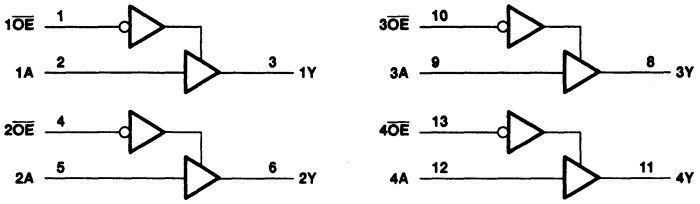
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT125	96 mA
SN74ABT125	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	127°C/W
DB package	158°C/W
N package	78°C/W
PW package	170°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stressratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT125		SN74ABT125		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		µs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT125		SN74ABT125		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V,	V_O = 2.7 V, $\overline{OE}$ ≥ 2 V			10		10		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V,	V_O = 0.5 V, $\overline{OE}$ ≥ 2 V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–200¶	–50	–200¶	–50	–200¶	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_o		V_O = 2.5 V or 0.5 V			7						pF

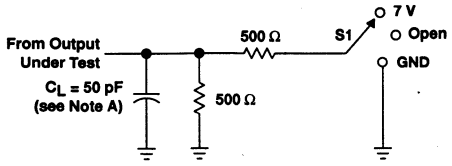
* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This limit may vary among suppliers.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT125		SN74ABT125		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}†	A	Y	1	3.2	4.6	1	6	1	4.9	ns
t_{PHL}†			1	2.5	4.6	1	6.2	1	4.9	
t_{PZH}†	$\overline{OE}$	Y	1	3.6	5	1	6	1	5.9	ns
t_{PZL}†			1	2.5	6.2	1	7.5	1	6.8	
t_{PHZ}	$\overline{OE}$	Y	1	3.8	5.4	1	6.3	1	6.2	ns
t_{PLZ}†			1	3.3	5.3	1	6.5	1	6.2	

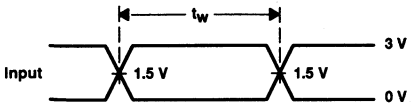
† This limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

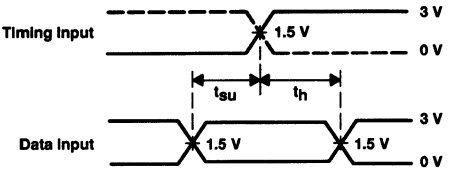


LOAD CIRCUIT

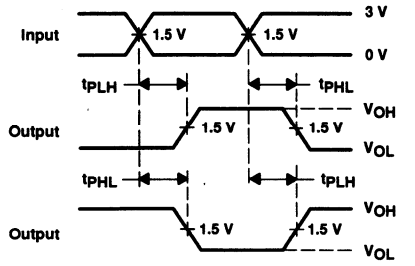
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



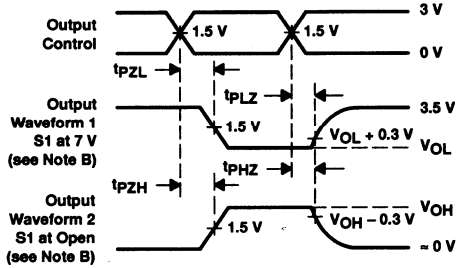
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



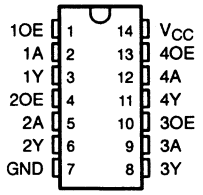
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

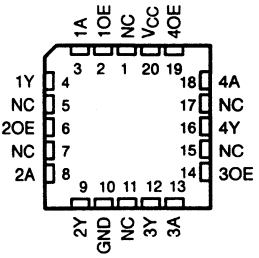
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (D) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs**

SN54ABT126 . . . J PACKAGE
SN74ABT126 . . . D, DB, OR N PACKAGE
(TOP VIEW)



SN54ABT126 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABT126 bus buffer gates feature independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (OE) input is low.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

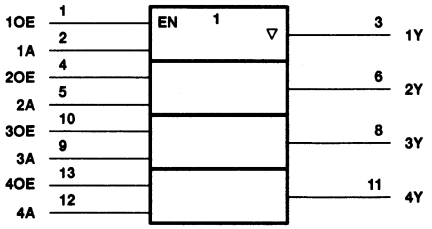
The SN54ABT126 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT126 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
OE	A	Y
H	H	H
H	L	L
L	X	Z

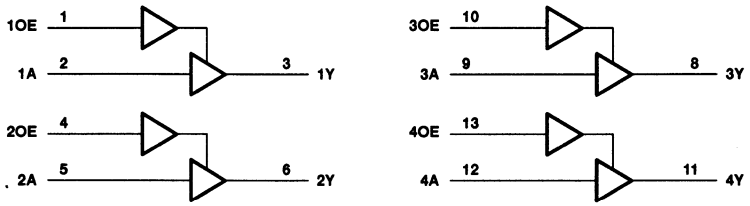
EPIC-IIB is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, and N packages.

logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, and N packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT126 ..... 96 mA
SN74ABT126 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package ..... 127°C/W
DB package ..... 158°C/W
N package ..... 78°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stressratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT126		SN74ABT126		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		µs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT126		SN74ABT126		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
		I_{OH} = –32 mA	2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
		I_{OL} = 64 mA			0.55*				0.55	
V_{hys}				100						mV
I_I	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZPU}‡	V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, OE = X§				±50		±50		±50	µA
I_{OZPD}‡	V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, OE = X§				±50		±50		±50	µA
I_{OZH}	V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, OE ≤ 0.8 V				10		10		10	µA
I_{OZL}	V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, OE ≤ 0.8 V				–10		–10		–10	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–200	–50	–200	–50	–200	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
		Outputs low		24	30		30		30	mA
		Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}#	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
		Outputs disabled			50		50		50	µA
C_i	V_I = 2.5 V or 0.5 V			3						pF
C_o	V_O = 2.5 V or 0.5 V			7						pF

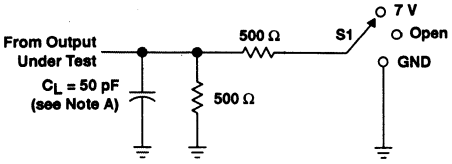
* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ For V_{CC} between 2.1 V and 4 V, OE should be less than or equal to 0.5 V to ensure a low state.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT126		SN74ABT126		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2.9	4.9	1	7.3	1	6.3	ns
t_{PHL}			1	2.5	5.1	1	5.9	1	5.7	
t_{PZH}	OE	Y	1	4.4	5.8	1	5.3	1	6.5	ns
t_{PZL}			1	4.4	5.9	1	6.4	1	6.5	
t_{PHZ}	OE	Y	1	3	5.7	1	6.9	1	6.8	ns
t_{PLZ}			1	3	5.8	1	7.2	1	6.7	

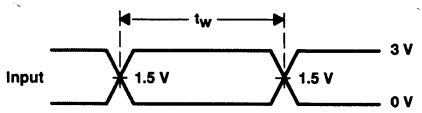
NOTE 4: Limits may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

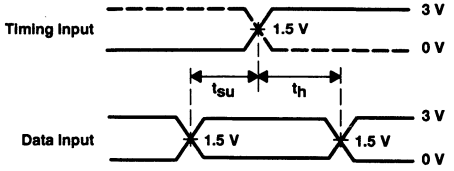


LOAD CIRCUIT

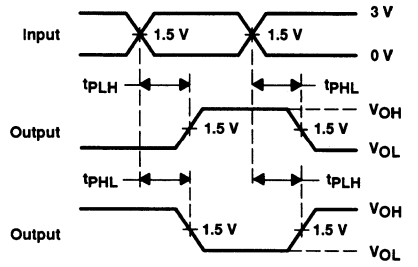
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



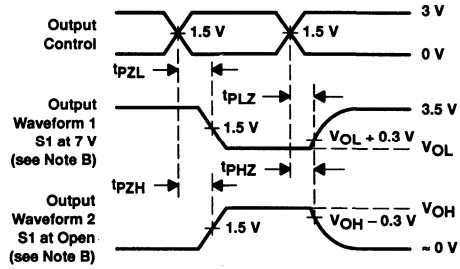
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



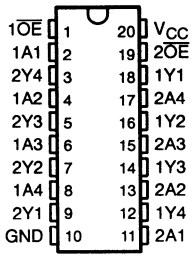
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

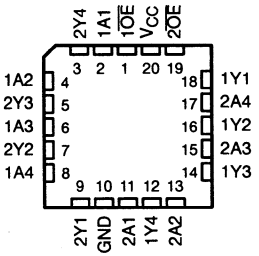
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC-IIB*™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT240 . . . J OR W PACKAGE
SN74ABT240A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT240 . . . FK PACKAGE
(TOP VIEW)



description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the SN54ABT241, SN74ABT241A, SN54ABT244, and SN74ABT244A, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable ($\overline{OE}$) inputs, and complementary OE and $\overline{OE}$ inputs.

The SN54ABT240 and SN74ABT240A are organized as two 4-bit buffers/line drivers with separate $\overline{OE}$ inputs. When $\overline{OE}$ is low, the devices pass inverted data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT240 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT240A is characterized for operation from –40°C to 85°C.

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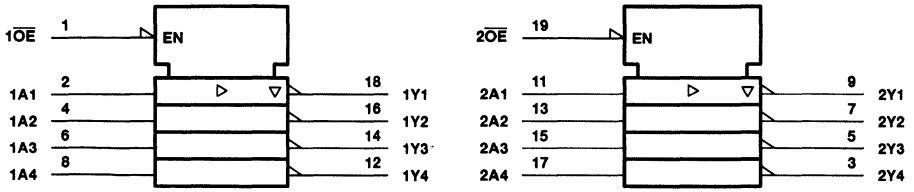
FUNCTION TABLE
(each buffer)

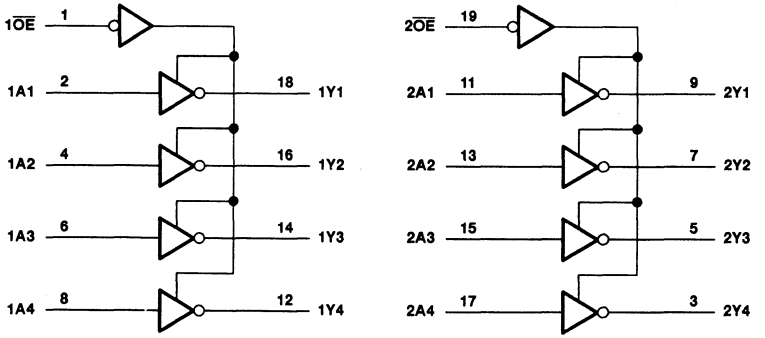
INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	L
L	L	H
H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT240 ..... 96 mA
SN74ABT240A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT240		SN74ABT240A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT240		SN74ABT240A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			4						pF
C_o		V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

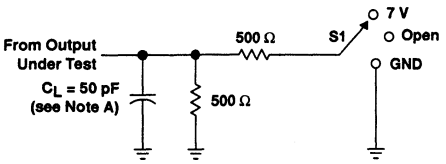
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT240					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.9	4.3	0.8	5.5	ns
t_{PHL}			1.6	3.1	4.5	1	5.5	
t_{PZH}	$\overline{OE}$	Y	1.1	3.1	5.8	0.8	7.5	ns
t_{PZL}			1.1	2.7	6.2	0.8	7.7	
t_{PHZ}	$\overline{OE}$	Y	1.8	4.6	5.9	1.7	7	ns
t_{PLZ}			1.6	4	5.9	1.3	7.2	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

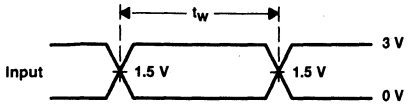
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT240A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.9	4.1	1	4.8	ns
t_{PHL}			1.6	3.1	4.6	1.6	4.8	
t_{PZH}	$\overline{OE}$	Y	1.1	3.1	4.7	1.1	5.2	ns
t_{PZL}			1.1	2.7	5.8	1.1	6.2	
t_{PHZ}	$\overline{OE}$	Y	1.8	4.6	5.7	1.8	6.4	ns
t_{PLZ}			1.6	4	5.4	1.6	5.8	

PARAMETER MEASUREMENT INFORMATION

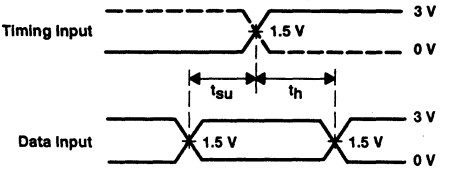


LOAD CIRCUIT

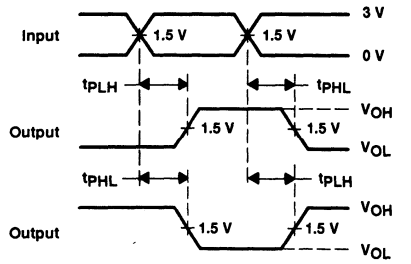
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



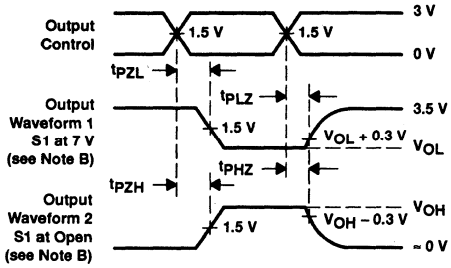
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



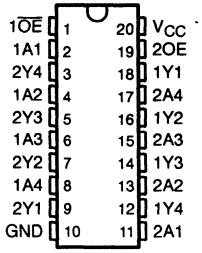
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

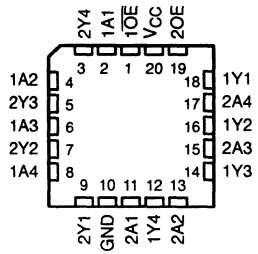
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT241 . . . J OR W PACKAGE
SN74ABT241A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT241 . . . FK PACKAGE
(TOP VIEW)



description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the SN54ABT240, SN74ABT240A, and 'ABT244A, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable ($\overline{OE}$) inputs, and complementary OE and $\overline{OE}$ inputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT241 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT241A is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

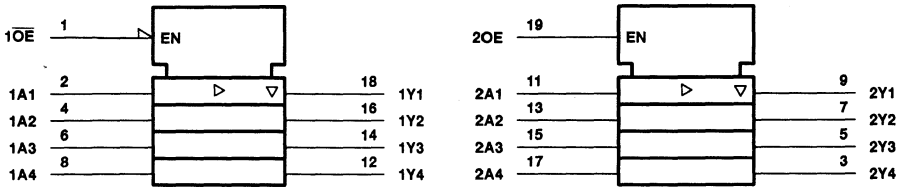
TEXAS INSTRUMENTS

FUNCTION TABLES

INPUTS		OUTPUT
$1\overline{OE}$	1A	1Y
L	H	H
L	L	L
H	X	Z

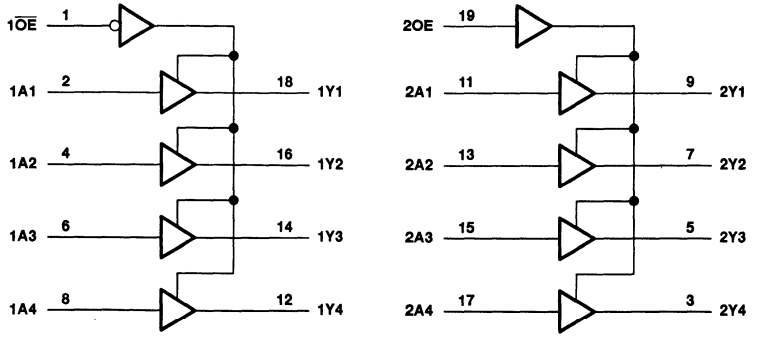
INPUTS		OUTPUT
2OE	2A	2Y
H	H	H
H	L	L
L	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT241 ..... 96 mA
SN74ABT241A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT241		SN74ABT241A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT241		SN74ABT241A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			4						pF
C_o		V_O = 2.5 V or 0.5 V			5.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

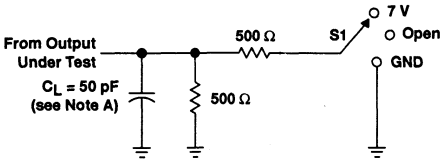
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT241					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.6	4.1	0.8	5.3	ns
t_{PHL}			1	2.9	4.2	0.8	5	
t_{PZH}	$\overline{OE}$ or OE	Y	1.1	4.8	6.3	1	7	ns
t_{PZL}			1.3	4.3	5.8	1	7	
t_{PHZ}	$\overline{OE}$ or OE	Y	1.1	4.6	6.1	0.8	7.9	ns
t_{PLZ}			1	3.9	5.4	0.8	6.2	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

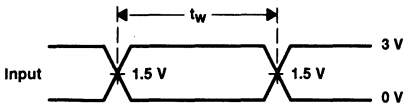
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT241A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.6	4.1	1	4.6	ns
t_{PHL}			1	2.9	4.4	1	4.6	
t_{PZH}	$\overline{OE}$ or OE	Y	1.1	4.8	6.3	1.1	6.8	ns
t_{PZL}			1.3	4.3	5.8	1.3	6.8	
t_{PHZ}	$\overline{OE}$ or OE	Y	1.6	4.6	6.1	1.6	7.1	ns
t_{PLZ}			1	3.9	5.4	1	5.9	

PARAMETER MEASUREMENT INFORMATION

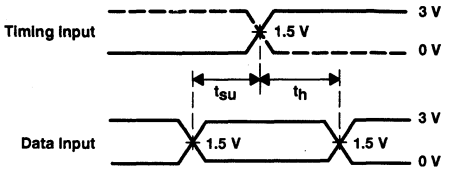


LOAD CIRCUIT

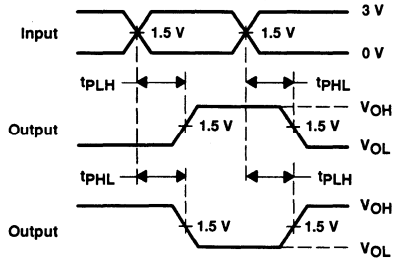
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



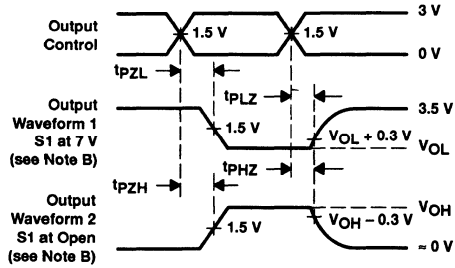
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



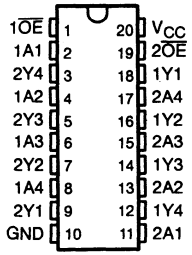
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

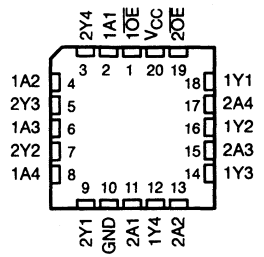
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC-IIB*™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT244 . . . J OR W PACKAGE
SN74ABT244A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT244 . . . FK PACKAGE
(TOP VIEW)



description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the SN54ABT240, SN74ABT240A, SN54ABT241, and SN74ABT241A, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable ($\overline{OE}$) inputs, and complementary OE and $\overline{OE}$ inputs.

The SN54ABT244 and SN74ABT244A are organized as two 4-bit buffers/line drivers with separate $\overline{OE}$ inputs. When $\overline{OE}$ is low, the devices pass noninverted data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT244 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT244A is characterized for operation from –40°C to 85°C.

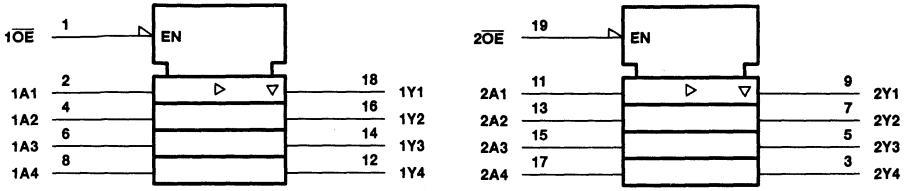
EPIC-IIB is a trademark of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

FUNCTION TABLE
(each buffer)

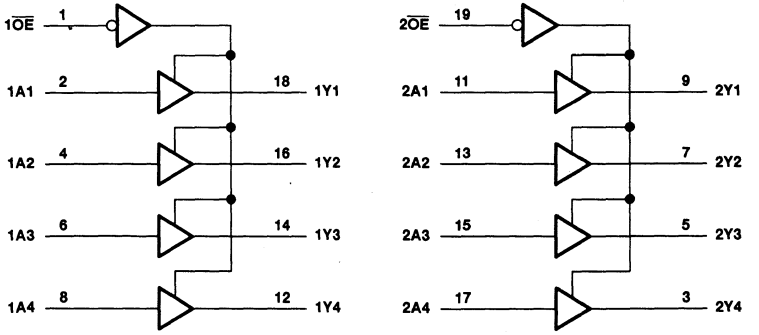
INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT244 ..... 96 mA
SN74ABT244A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT244		SN74ABT244A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT244		SN74ABT244A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V	Outputs high			50		50		50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

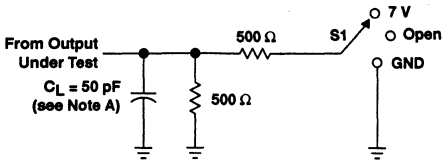
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT244					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.6	4.1	1	5.3	ns
t_{PHL}			1	2.9	4.2	1	5	
t_{PZH}	$\overline{OE}$	Y	1.1	3.1	4.6	0.8	5.7	ns
t_{PZL}			2.1	4.1	5.6	1.2	7.9	
t_{PHZ}	$\overline{OE}$	Y	2.1	4.1	5.6	1.2	7.6	ns
t_{PLZ}			1.5	3.7	5.6	1	7.9	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

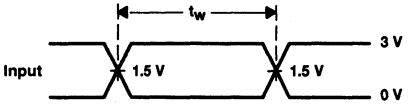
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT244A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.6	4.1	1	4.6	ns
t_{PHL}			1	2.9	4.3	1	4.6	
t_{PZH}	$\overline{OE}$	Y	1.1	3.1	4.6	1.1	5.1	ns
t_{PZL}			2.1	4.1	5.6	2.1	6.1	
t_{PHZ}	$\overline{OE}$	Y	1.8	4.1	5.6	1.8	6.6	ns
t_{PLZ}			1.4	3.7	5.2	1.4	5.7	

PARAMETER MEASUREMENT INFORMATION

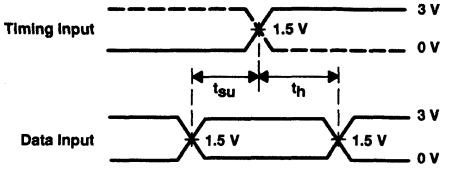


LOAD CIRCUIT

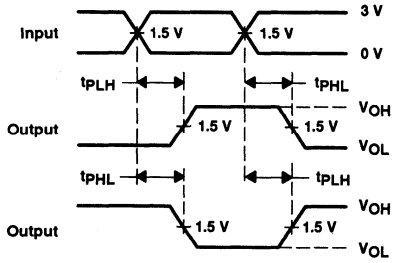
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



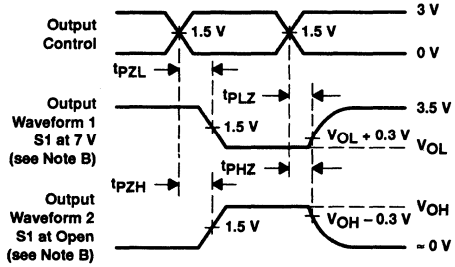
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



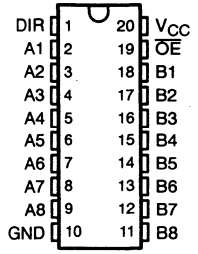
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

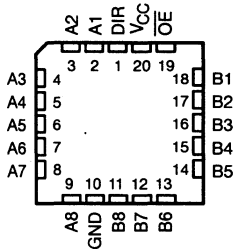
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Thin Very Small-Outline (DGV) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (N) and Ceramic (J) DIPs**

SN54ABT245A . . . J OR W PACKAGE
SN74ABT245B . . . DB, DGV, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT245B . . . FK PACKAGE
(TOP VIEW)



description

These octal bus transceivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so the buses are effectively isolated.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

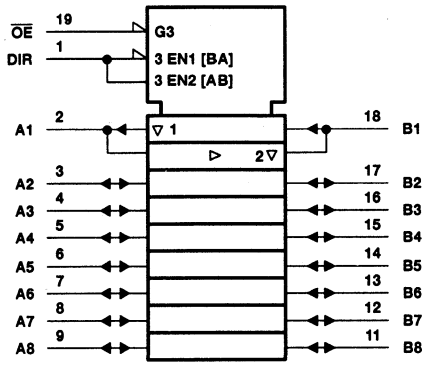
The SN54ABT245A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT245B is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

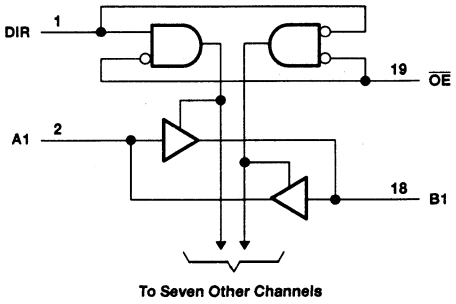
EPIC-IIB is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT245A ..... 96 mA
SN74ABT245B ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DGV package ..... 146°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT245A		SN74ABT245B		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate			200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT245A		SN74ABT245B		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±100		±20	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–140	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		5	250		250		250	µA
			Outputs low		22	30		30		30	mA
			Outputs disabled		1	250		250		250	µA
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			50		50		50	µA
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			8						pF

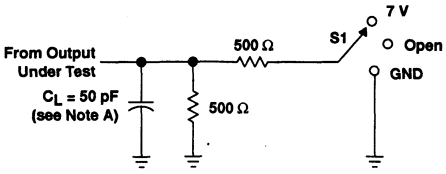
* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT245A		SN74ABT245B		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	2	3.2	0.8	3.8	1	3.6	ns
t_{PHL}			1	2.6	3.5	1	4.2	1	3.9	
t_{PZH}	$\overline{OE}$	A or B	2	3.5	4.5	1.2	6.2	2	5.6	ns
t_{PZL}			1.9	4	5.3	1.3	6.8	1.9	6.2	
t_{PHZ}	$\overline{OE}$	A or B	2.2	4.4	5.4	2.2	6.1	2.2	5.9	ns
t_{PLZ}			1.5	3	4	1.0	4.9	1.5	4.5	
$t_{sk(o)}$†					0.5				0.5	ns

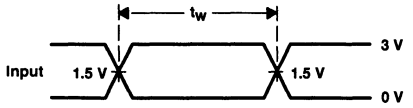
† Skew between any two outputs of the same package switching in the same direction. This parameter is warranted but not production tested.

PARAMETER MEASUREMENT INFORMATION

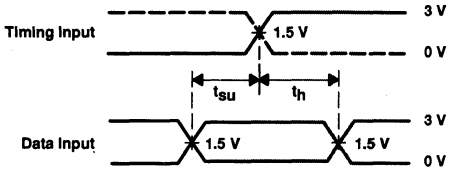


LOAD CIRCUIT

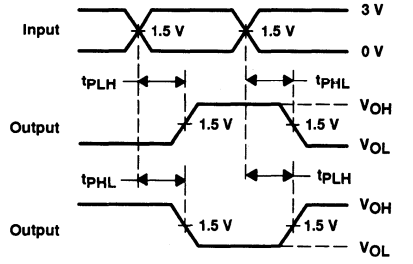
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



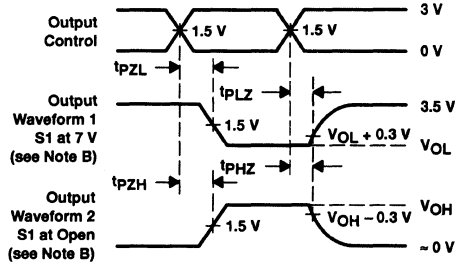
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



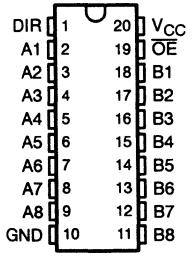
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

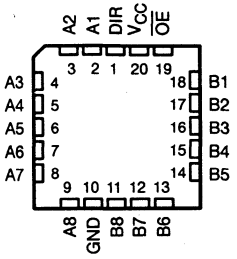
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Thin Very Small-Outline (DGV) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABTH245 . . . J OR W PACKAGE
SN74ABTH245 . . . DB, DGV, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABTH245 . . . FK PACKAGE
(TOP VIEW)



description

These octal bus transceivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so the buses are effectively isolated.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

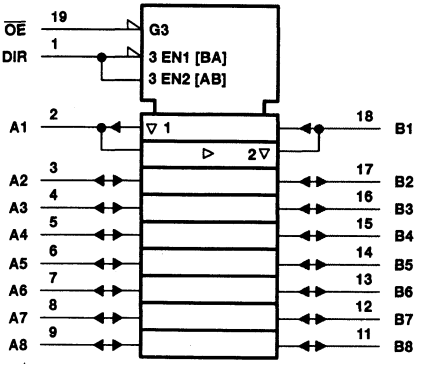
The SN54ABTH245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH245 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

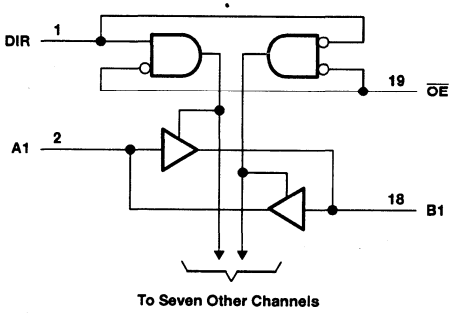
EPIC-IIB is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH245 ..... 96 mA
SN74ABTH245 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DGV package ..... 146°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABTH245		SN74ABTH245		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate			200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABTH245		SN74ABTH245		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V,	V_I = V_{CC} or GND			±20		±100		±20	
$I_{I(hold)}$		V_{CC} = 4.5 V	V_I = 0.8 V	100			100		100		µA
			V_I = 2 V	–100			–100		–100		
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–140	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		5	250		250		250	µA
			Outputs low		22	30		30		30	mA
			Outputs disabled		1	250		250		250	µA
ΔI_{CC}¶	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			50		50		50	µA
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			8						pF

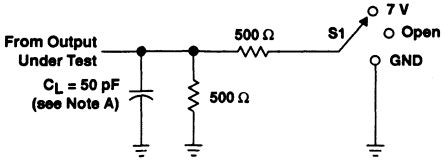
* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABTH245		SN74ABTH245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	2	3.2	0.8	3.8	1	3.6	ns
t_{PHL}			1	2.6	3.5	1	4.2	1	3.9	
t_{PZH}	$\overline{OE}$	A or B	2	3.5	4.5	1.2	6.2	2	5.6	ns
t_{PZL}			1.9	4	5.3	1.3	6.8	1.9	6.2	
t_{PHZ}	$\overline{OE}$	A or B	2.2	4.4	5.4	2.2	6.1	2.2	5.9	ns
t_{PLZ}			1.5	3	4	1	4.9	1.5	4.5	
$t_{sk(o)}$†					0.5				0.5	ns

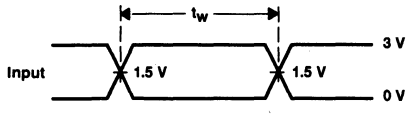
† Skew between any two outputs of the same package switching in the same direction. This parameter is warranted but not production tested.

PARAMETER MEASUREMENT INFORMATION

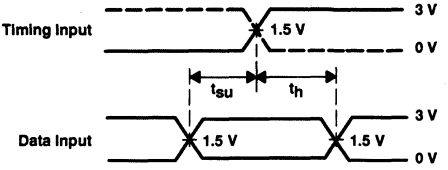


LOAD CIRCUIT

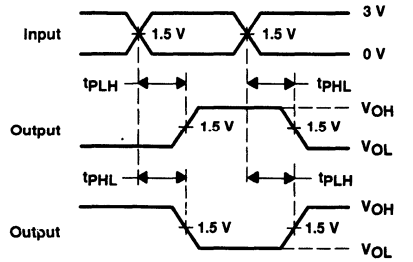
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



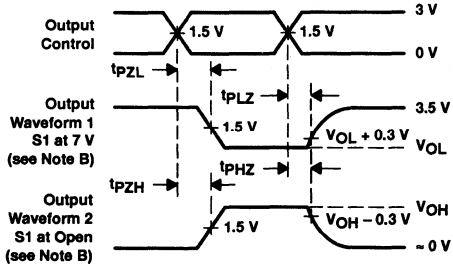
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



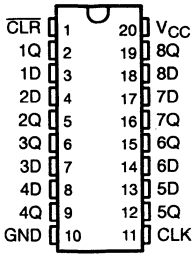
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

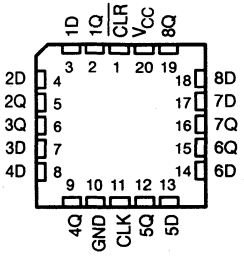
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT273 . . . J OR W PACKAGE
SN74ABT273 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT273 . . . FK PACKAGE
(TOP VIEW)



description

The 'ABT273 are 8-bit positive-edge-triggered D-type flip-flops with a direct clear ($\overline{CLR}$) input. They are particularly suitable for implementing buffer and storage registers, shift registers, and pattern generators.

Information at the data (D) inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock (CLK) input is at either the high or low level, the D input signal has no effect at the output.

The SN54ABT273 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT273 is characterized for operation from –40°C to 85°C.

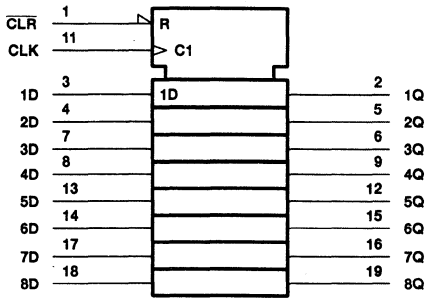
FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
$\overline{CLR}$	CLK	D	Q
L	X	X	L
H	↑	H	H
H	↑	L	L
H	H or L	X	Q_0

EPIC-IIB is a trademark of Texas Instruments Incorporated.

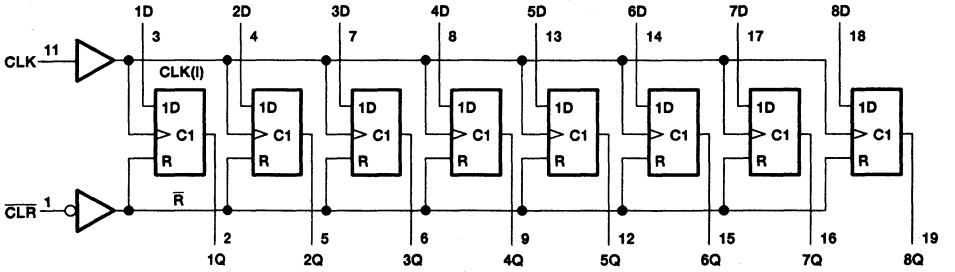
TEXAS INSTRUMENTS

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT273 ..... 96 mA
SN74ABT273 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT273		SN74ABT273		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT273		SN74ABT273		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA		3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA		2			2				
		I_{OH} = –32 mA		2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA				0.55		0.55			V
		I_{OL} = 64 mA				0.55*				0.55	
V_{hys}					100						mV
I_I	V_{CC} = 5.5 V,	$V_I = V_{CC}$ or GND				±1		±1		±1	µA
I_{off}	V_{CC} = 0,	V_I or $V_O \le 4.5$ V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–100	–200§	–50	–200§	–50	–200§	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, $V_I = V_{CC}$ or GND		Outputs high		1	400§		400§		400§	µA
			Outputs low		24	30		30		30	mA
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V				7						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This data sheet limit may vary among suppliers.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C		SN54ABT273		SN74ABT273		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	150	0	150	0	150	MHz
t_w	Pulse duration	CLK high or low	3.3		3.3		3.3		ns
		$\overline{CLR}$ low	3.3		3.3		3.3		
t_{su}	Setup time before CLK↑	Data high	2		2		2		ns
		Data low	2.5		2.5		2.5		
		$\overline{CLR}$ high	2		2		2		
t_h	Hold time after CLK↑	Data high or low	1.2†		1.4†		1.2†		ns

† This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C		SN54ABT273		UNIT
			MIN	MAX	MIN	MAX	
f_{max}			150		150		MHz
t_{PLH}	CLK	Q	2.5	6	2.5	7	ns
t_{PHL}			3.3	6.8	3.3	7.5	
t_{PHL}	$\overline{CLR}$	Q	2.5	7.5†	2.5	8.2	ns

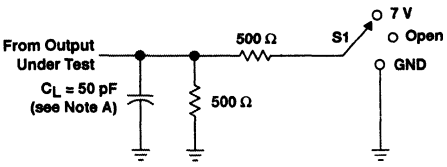
† This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C		SN74ABT273		UNIT
			MIN	MAX	MIN	MAX	
f_{max}			150		150		MHz
t_{PLH}	CLK	Q	2.5	6	2.5	6.5	ns
t_{PHL}			3.3	6.8	3.3	7.3	
t_{PHL}	$\overline{CLR}$	Q	2.5	6.7†	2.5	7.4†	ns

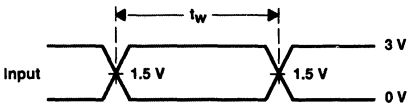
† This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

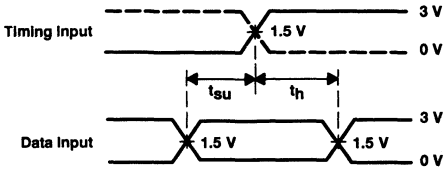


LOAD CIRCUIT

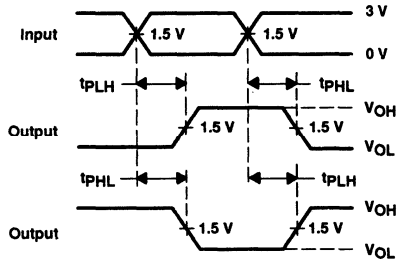
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



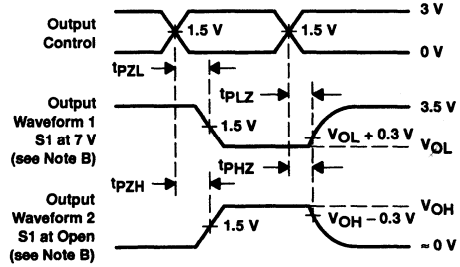
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



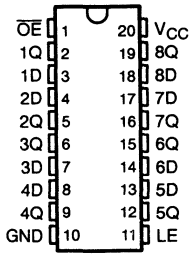
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

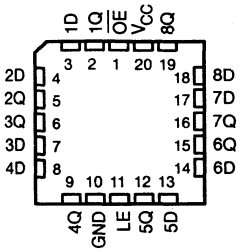
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (N) and Ceramic (J) DIPs**

SN54ABT373 . . . J OR W PACKAGE
SN74ABT373 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT373 . . . FK PACKAGE
(TOP VIEW)



description

The eight latches of the 'ABT373 are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT373 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT373 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each latch)

INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

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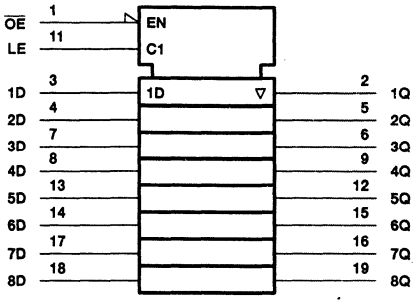
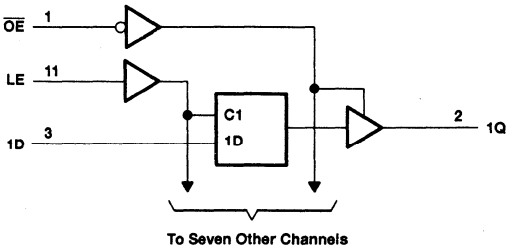
TEXAS INSTRUMENTS

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT373 ..... 96 mA
SN74ABT373 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT373		SN74ABT373		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT373		SN74ABT373		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA		3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA		2			2				
		I_{OH} = –32 mA		2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA				0.55		0.55			V
		I_{OL} = 64 mA				0.55*				0.55	
V_{hys}					100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V				10‡		10‡		10‡	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V				–10‡		–10‡		–10‡	µA
I_{off}	V_{CC} = 0,	V_I or $V_O \le$ 4.5 V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND		Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V				3						pF
C_o	V_O = 2.5 V or 0.5 V				6						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This data sheet limit may vary among suppliers.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54ABT373		UNIT
			V_{CC} = 5 V, T_A = 25°C	MIN MAX	
			MIN MAX		
t_w	Pulse duration, LE high		3.3	3.3	ns
t_{su}	Setup time, data before LE↓	High	2.2	2.5	ns
		Low	2.2	2.5	
t_h	Hold time, data after LE↓	High or low	2.2	2.5	ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN74ABT373		UNIT
			V_{CC} = 5 V, T_A = 25°C	MIN MAX	
			MIN MAX		
t_w	Pulse duration, LE high		3.3	3.3	ns
t_{su}	Setup time, data before LE↓	High	1.9	1.9	ns
		Low	1.5	1.5	
t_h	Hold time, data after LE↓	High or low	1	1	ns

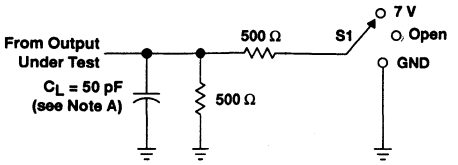
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT373					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	Q	1.9	3.9	5.4	1.3	6.8	ns
t_{PHL}			2.2	4.2	5.7	2	7	
t_{PLH}	LE	Q	2.2	4.6	6.1	1.8	7.7	ns
t_{PHL}			3.2	5.2	6.7	2.5	7.7	
t_{PZH}	$\overline{OE}$	Q	1.2	3.2	5.5	1	6.2	ns
t_{PZL}			2	4.7	6.2	1.5	7.2	
t_{PHZ}	$\overline{OE}$	Q	2.5	4.9	6.4	2.4	8	ns
t_{PLZ}			2	4.5	6	2	7	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

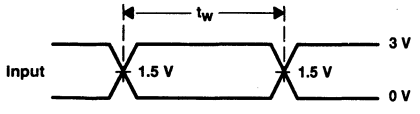
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT373					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	Q	1.9	3.9	5.4	1.9	5.9	ns
t_{PHL}			2.2	4.2	5.7	2.2	6.2	
t_{PLH}	LE	Q	2.2	4.6	6.1	2.2	6.6	ns
t_{PHL}			3.2	5.2	6.7	3.2	7.2	
t_{PZH}	$\overline{OE}$	Q	1.2	3.2	4.7	1.2	5.2	ns
t_{PZL}			2.7	4.7	6.2	2.7	6.7	
t_{PHZ}	$\overline{OE}$	Q	2.5	4.9	6.4	2.5	6.9	ns
t_{PLZ}			2	4.5	6	2	6.5	

PARAMETER MEASUREMENT INFORMATION

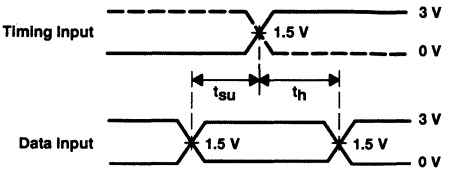


LOAD CIRCUIT

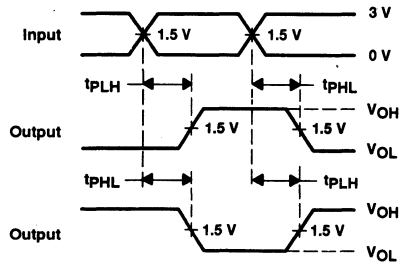
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



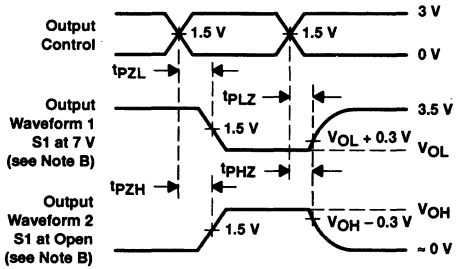
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



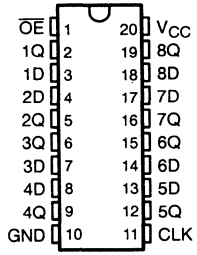
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

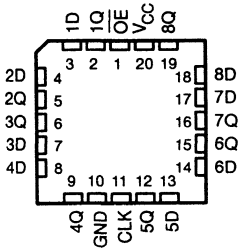
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT374 . . . J OR W PACKAGE
SN74ABT374A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT374 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the SN54ABT374 and SN74ABT374A are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components. $\overline{OE}$ does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT374 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT374A is characterized for operation from –40°C to 85°C.

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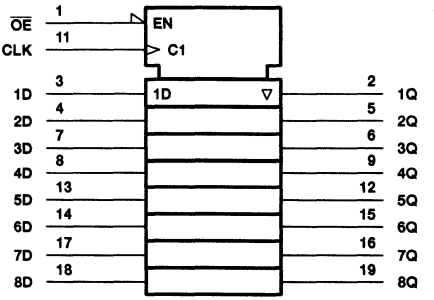
TEXAS INSTRUMENTS

FUNCTION TABLE
(each flip-flop)

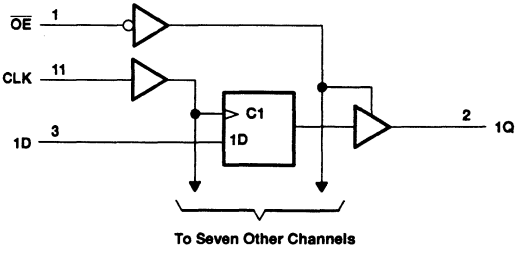
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT374 ..... 96 mA
SN74ABT374A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT374		SN74ABT374A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT374		SN74ABT374A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA		3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA		2			2				
		I_{OH} = –32 mA		2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA				0.55		0.55			V
		I_{OL} = 64 mA				0.55*				0.55	
V_{hys}					100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V				10‡		10‡		10‡	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V				–10‡		–10‡		–10‡	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND		Outputs high			250		250		250	µA
			Outputs low			30		30		30	mA
			Outputs disabled			250		250		250	µA
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V				3.5						pF
C_o	V_O = 2.5 V or 0.5 V				6.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This data sheet limit may vary among suppliers.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54ABT374				UNIT
			V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
			MIN	MAX			
f_{clock}	Clock frequency		0	150	0	150	MHz
t_w	Pulse duration	CLK high or low	3.3		3.3		ns
t_{su}	Setup time before CLK↑	Data high	2		2.5		ns
		Data low	2		2.5		
t_h	Hold time after CLK↑	Data high or low	2		2.5		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN74ABT374A				UNIT
			V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
			MIN	MAX			
f_{clock}	Clock frequency		0	150	0	150	MHz
t_w	Pulse duration	CLK high or low	3.3		3.3		ns
t_{su}	Setup time before CLK↑	Data high	1		1		ns
		Data low	1.9		1.9		
t_h	Hold time after CLK↑	Data high or low	2.1†		2.1†		ns

† This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

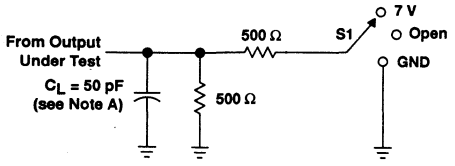
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT374					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150	200		150		MHz
t_{PLH}	CLK	Q	2.2	4.2	5.7	1.8	6.6	ns
t_{PHL}			3.1	5.1	6.6	2.6	7.6	
t_{PZH}	$\overline{OE}$	Q	1.2	3.2	4.7	0.8	5.7	ns
t_{PZL}			2.3	4.7	6.2	1.5	7.2	
t_{PHZ}	$\overline{OE}$	Q	2.3	4.5	6.1	1.3	7.2	ns
t_{PLZ}			1.9	4.5	6	1	7	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT374A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150	200		150		MHz
t_{PLH}	CLK	Q	2.2	4.2	5.7	2.2	6.2	ns
t_{PHL}			3.1	5.1	6.6	3.1	7.1	
t_{PZH}	$\overline{OE}$	Q	1.2	3.2	4.7	1.2	5.2	ns
t_{PZL}			2.7	4.7	6.2	2.7	6.7	
t_{PHZ}	$\overline{OE}$	Q	2.5	4.5	6	2.5	6.7†	ns
t_{PLZ}			2	4.5	6	2	6.5	

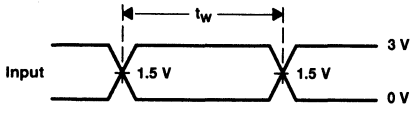
† This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

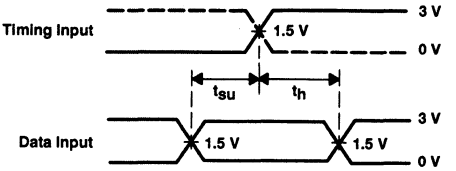


LOAD CIRCUIT

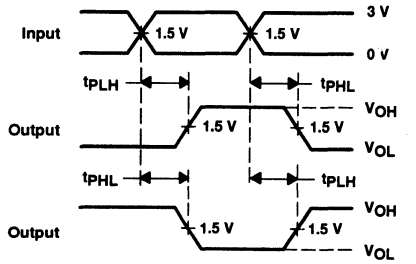
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



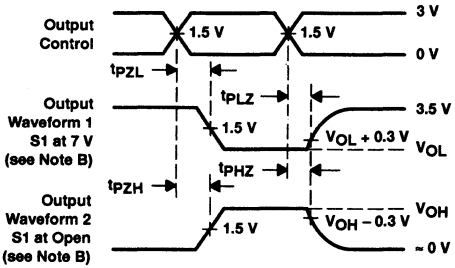
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



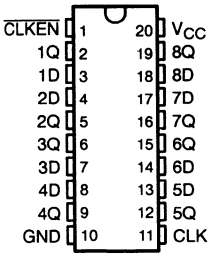
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

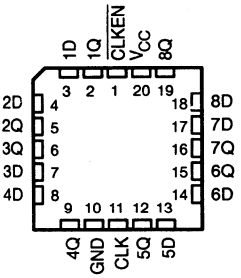
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT377 . . . J OR W PACKAGE
SN74ABT377A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT377 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit positive-edge-triggered D-type flip-flops with a clock (CLK) input are particularly suitable for implementing buffer and storage registers, shifts registers, and pattern generators.

Data (D) input information that meets the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if the common clock-enable ($\overline{CLKEN}$) input is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the buffered clock (CLK) input is at either the high or low level, the D-input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at $\overline{CLKEN}$.

The SN54ABT377 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT377A is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
$\overline{CLKEN}$	CLK	D	Q
H	X	X	Q_0
L	↑	H	H
L	↑	L	L
X	H or L	X	Q_0

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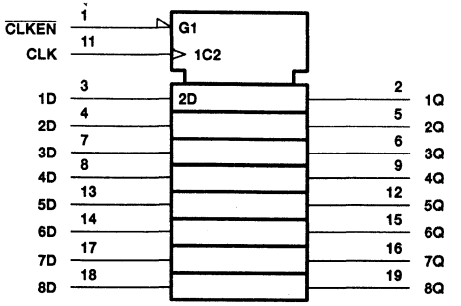
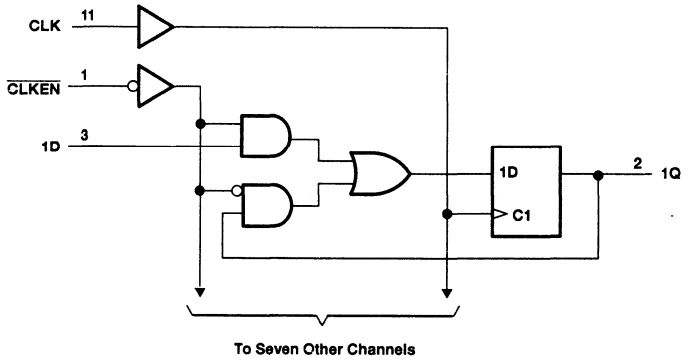
TEXAS INSTRUMENTS

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT377 ..... 96 mA
SN74ABT377A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT377		SN74ABT377A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT377		SN74ABT377A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA		3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA		2			2				
		I_{OH} = –32 mA		2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA				0.55		0.55			V
		I_{OL} = 64 mA				0.55*				0.55	
V_{hys}					100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND				±1		±1		±1	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND		Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
ΔI_{CC}§	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V				3.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54ABT377				UNIT
			V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
			MIN	MAX			
f_{clock}	Clock frequency		0	150	0	150	MHz
t_w	Pulse duration	CLK high or low	3.3		3.3		ns
t_{su}	Setup time before CLK↑	Data high or low	2		2.5		ns
		$\overline{CLKEN}$ high or low	3		3		
t_h	Hold time after CLK↑	Data high or low	1.8¶		1.8¶		ns
		$\overline{CLKEN}$ high or low	1.8¶		1.8¶		

¶ This data sheet limit may vary among suppliers.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN74ABT377A				UNIT
			V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
			MIN	MAX			
f_{clock}	Clock frequency		0	150	0	150	MHz
t_w	Pulse duration	CLK high or low	3.3		3.3		ns
t_{su}	Setup time before CLK↑	Data high or low	2		2.5		ns
		$\overline{CLKEN}$ high or low	3		3		
t_h	Hold time after CLK↑	Data high or low	1.8†		1.8†		ns
		$\overline{CLKEN}$ high or low	1.2†		1.2†		

† This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

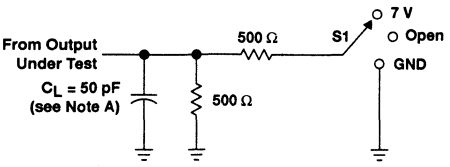
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT377					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150			150		MHz
t_{PLH}	CLK	Q	2.2	4.5	6	2.2	7	ns
t_{PHL}			3.1	5.3	6.8	2	7.6	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT377A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150			150		MHz
t_{PLH}	CLK	Q	2.2	4.5	6	2.2	6.5	ns
t_{PHL}			2.6†	5.3	6.8	2.6†	7.3	

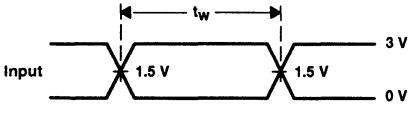
† This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

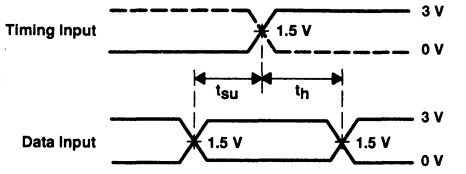


LOAD CIRCUIT

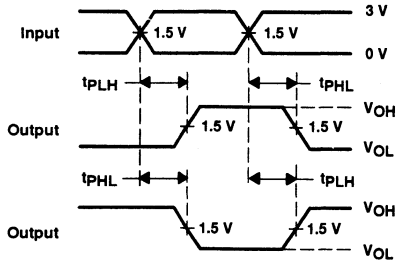
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



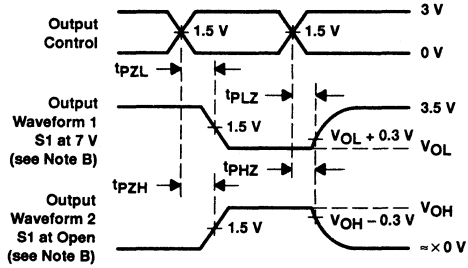
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



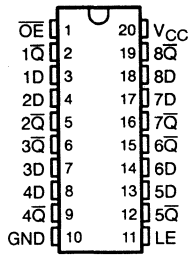
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

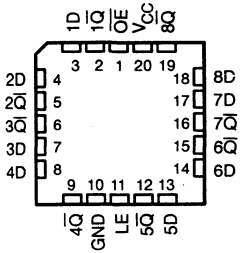
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT533 . . . J OR W PACKAGE
SN74ABT533A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT533 . . . FK PACKAGE
(TOP VIEW)



description

These octal transparent D-type latches with 3-state outputs are designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

When the latch-enable (LE) input is high, the $\overline{Q}$ outputs follow the complements of the data (D) inputs. When LE is taken low, the $\overline{Q}$ outputs are latched at the inverse of the levels at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latches. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

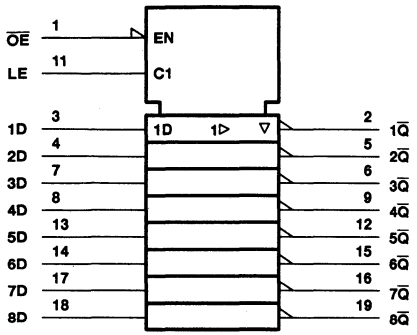
The SN54ABT533 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT533A is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE
(each latch)

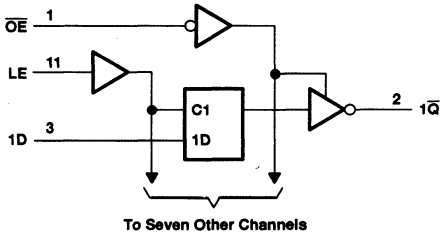
INPUTS			OUTPUT
$\overline{OE}$	LE	D	$\overline{Q}$
L	H	H	L
L	H	L	H
L	L	X	$\overline{Q}_0$
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT533 ..... 96 mA
SN74ABT533A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT533		SN74ABT533A		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT533		SN74ABT533A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA		3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA		2			2				
		I_{OH} = –32 mA		2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA				0.55		0.55			V
		I_{OL} = 64 mA				0.55*				0.55	
V_{hys}					100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V				10		10		10	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V				–10		–10		–10	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V				±150				±150	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–140	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND		Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}§	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND		Outputs high			1.5		1.5		1.5	mA
			Outputs low			1.5		1.5		1.5	
			Outputs disabled			1.5		1.5		1.5	
C_i	V_I = 2.5 V or 0.5 V				3.5						pF
C_o	V_O = 2.5 V or 0.5 V				6.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54ABT533			UNIT
			V_{CC} = 5 V, T_A = 25°C	MIN	MAX	
			MIN	MAX		
t_w	Pulse duration, LE high		3.3		3.3	ns
t_{su}	Setup time, data before LE↓	High or low	2.1		2.1	ns
t_h	Hold time, data after LE↓	High or low	1.5		1.5	ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN74ABT533A			UNIT
			V_{CC} = 5 V, T_A = 25°C	MIN	MAX	
			MIN	MAX		
t_w	Pulse duration, LE high		3.3		3.3	ns
t_{su}	Setup time, data before LE↓	High or low	2.1		2.1	ns
t_h	Hold time, data after LE↓	High or low	2.1		2.1	ns

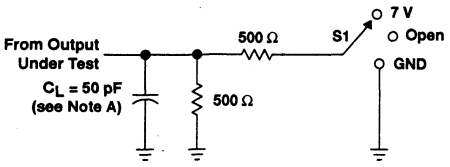
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT533					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	$\overline{Q}$	1.9	4.2	5.4	1.9	6.7	ns
t_{PHL}			3.1	4.9	6.3	3.1	6.9	
t_{PLH}	LE	$\overline{Q}$	2.7	4.9	6.2	2.7	7.6	ns
t_{PHL}			3.5	5.4	6.8	3.5	7.5	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	1.6	3.7	4.8	1.6	5.8	ns
t_{PZL}			2.4	4.2	6.2	2.4	6.9	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	2.8	5.1	6.2	2.8	7.2	ns
t_{PLZ}			2	4.1	6	2	6.9	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

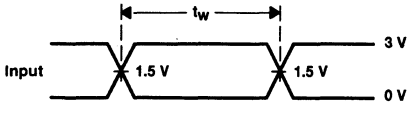
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT533A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	$\overline{Q}$	1.7	4.2	5.4	1.7	6.4	ns
t_{PHL}			2.6	4.9	6.3	2.6	6.6	
t_{PLH}	LE	$\overline{Q}$	2.7	4.9	6.2	2.7	7.3	ns
t_{PHL}			3.5	5.4	6.8	3.5	7.3	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	1.6	3.7	4.8	1.6	5.7	ns
t_{PZL}			2.4	4.2	6.2	2.4	6.7	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	1.6	5.1	6.2	1.6	6.9	ns
t_{PLZ}			2	4.1	6	2	6.5	

PARAMETER MEASUREMENT INFORMATION

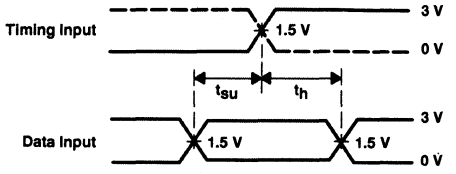


LOAD CIRCUIT

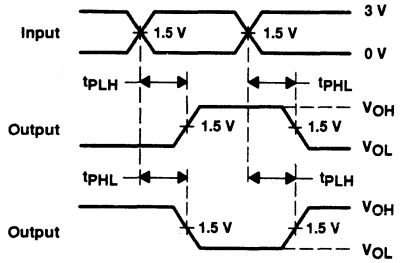
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



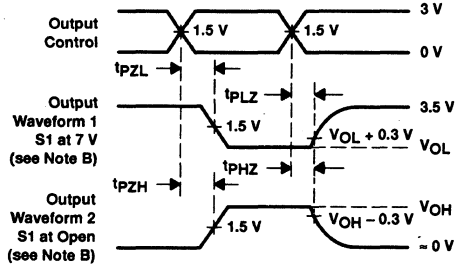
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



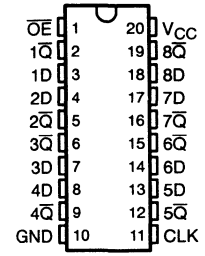
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

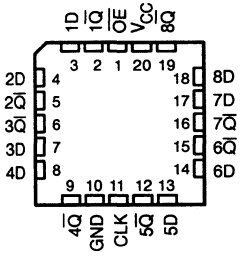
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT534 . . . J OR W PACKAGE
SN74ABT534A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT534 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit flip-flops with 3-state outputs are designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK), the $\overline{Q}$ outputs are set to the complement of the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the flip-flop. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

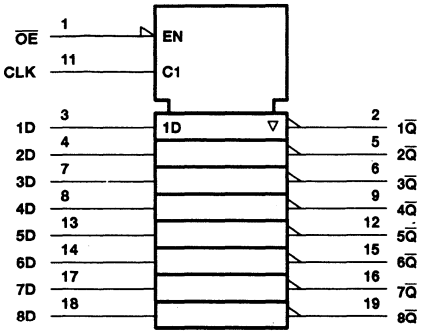
The SN54ABT534 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT534A is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE
(each flip-flop)

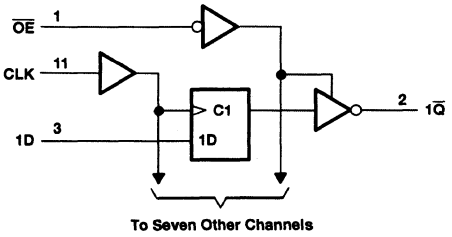
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	$\overline{Q}$
L	↑	H	L
L	↑	L	H
L	H or L	X	$\overline{Q}_0$
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT534 ..... 96 mA
SN74ABT534A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT534		SN74ABT534A		UNIT
				MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT534		SN74ABT534A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA		3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA		2			2				
		I_{OH} = –32 mA		2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA				0.55		0.55			V
		I_{OL} = 64 mA				0.55*				0.55	
V_{hys}					100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V				10‡		10‡		10‡	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V				–10‡		–10‡		–10‡	µA
I_{off}	V_{CC} = 0,	V_I or $V_O \le$ 4.5 V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–100	–180‡	–50	–180‡	–50	–180‡	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND		Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V				3.5						pF
C_o	V_O = 2.5 V or 0.5 V				6.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This data sheet limit may vary among suppliers.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54ABT534			UNIT
			V_{CC} = 5 V, T_A = 25°C	MIN	MAX	
			MIN MAX			
f_{clock}	Clock frequency		125		125	MHz
t_w	Pulse duration	CLK high or low	3.5	3.5		ns
t_{su}	Setup time, data before CLK↑	High or low	1.6	1.6		ns
t_h	Hold time, data after CLK↑	High or low	1.6	1.6		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN74ABT534A			UNIT
			V_{CC} = 5 V, T_A = 25°C	MIN	MAX	
			MIN MAX			
f_{clock}	Clock frequency		125		125	MHz
t_w	Pulse duration	CLK high or low	3.5	3.5		ns
t_{su}	Setup time, data before CLK↑	High or low	1.6	1.6		ns
t_h	Hold time, data after CLK↑	High or low	2†	2†		ns

† This data sheet limit may vary among suppliers.

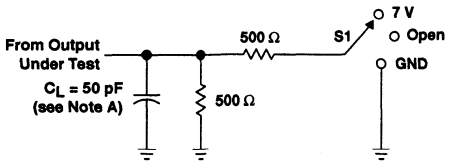
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT534					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125	175		125		MHz
t_{PLH}	CLK	$\overline{Q}$	2.6	4.5	6.1	2.6	7	ns
t_{PHL}			3.4	5.5	6.7	3.4	7.9	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	1	3.4	5.2	1	5.8	ns
t_{PZL}			2.6	4	5.8	2.6	7	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	2.4	4.7	6.6	2.4	7.6	ns
t_{PLZ}			2.3	3.8	5.8	2.3	6.8	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

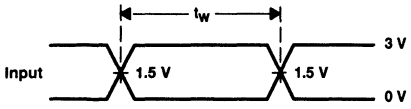
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT534A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125	175		125		MHz
t_{PLH}	CLK	$\overline{Q}$	2.6	4.5	5.9	2.6	6.7	ns
t_{PHL}			3.4	5.5	6.7	3.4	7.6	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	1	3.4	4.2	1	5	ns
t_{PZL}			2.6	4	5.8	2.6	6.8	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	2.4	4.7	6.6	2.4	7.3	ns
t_{PLZ}			2.3	3.8	5.8	2.3	6.5	

PARAMETER MEASUREMENT INFORMATION

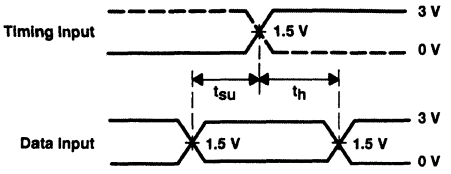


LOAD CIRCUIT

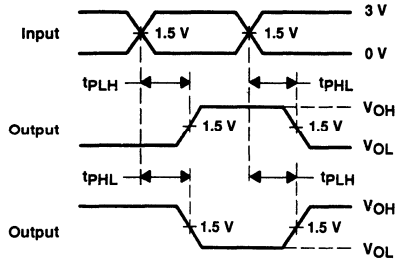
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



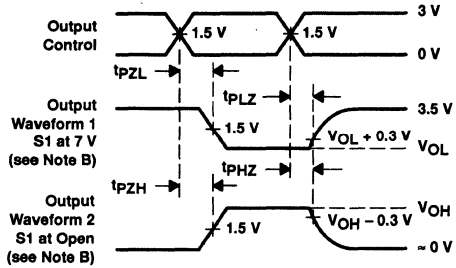
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



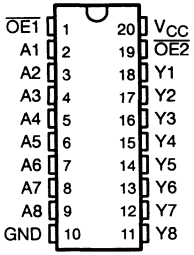
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

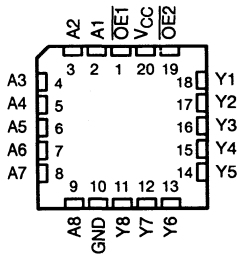
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT540 . . . J OR W PACKAGE
SN74ABT540 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT540 . . . FK PACKAGE
(TOP VIEW)



description

The 'ABT540 octal buffers and line drivers are ideal for driving bus lines or buffer memory address registers. The devices feature inputs and outputs on opposite sides of the package that facilitate printed circuit board layout.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all corresponding outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT540 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT540 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	H
L	L	H	L
H	X	X	Z
X	H	X	Z

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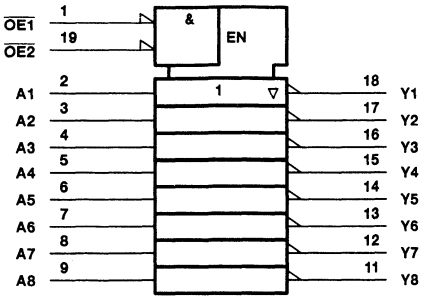
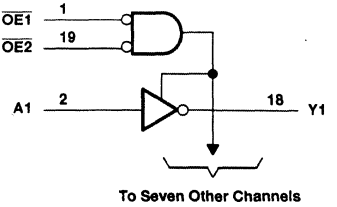
TEXAS INSTRUMENTS

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT540 ..... 96 mA
SN74ABT540 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT540		SN74ABT540		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

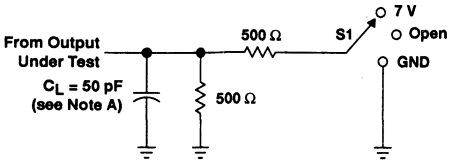
PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT540		SN74ABT540		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = −18 mA			−1.2		−1.2		−1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = −3 mA	2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = −3 mA	3			3		3		
	V_{CC} = 4.5 V	I_{OH} = −24 mA	2			2				
		I_{OH} = −32 mA	2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
		I_{OL} = 64 mA			0.55*				0.55	
V_{hys}				100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V			−50		−50		−50	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡	V_{CC} = 5.5 V,	V_O = 2.5 V	−50	−100	−180	−50	−180	−50	−180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
		Outputs low		24	30		30		30	mA
		Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}§ Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
		Outputs disabled			0.05		0.05		0.05	
ΔI_{CC}§ Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	V_I = 2.5 V or 0.5 V			3						pF
C_o	V_O = 2.5 V or 0.5 V			8						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

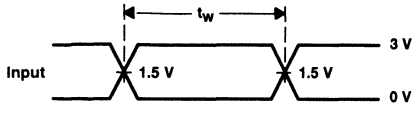
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT540		SN74ABT540		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2.9	4.1	1		1	4.8	ns
t_{PHL}			1	3.1	4.3	1		1	4.8	
t_{PZH}	$\overline{OE}$	Y	1.1	3.4	4.9	1.1		1.1	5.9	ns
t_{PZL}			1.1	3	5.8	1.1		1.1	6.4	
t_{PHZ}	$\overline{OE}$	Y	1.5	5.3	6.8	1.5		1.5	7.3	ns
t_{PLZ}			1.2	4.4	5.7	1.2		1.2	6.2	

PARAMETER MEASUREMENT INFORMATION

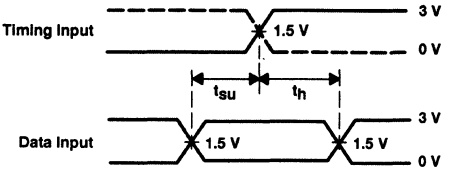


LOAD CIRCUIT

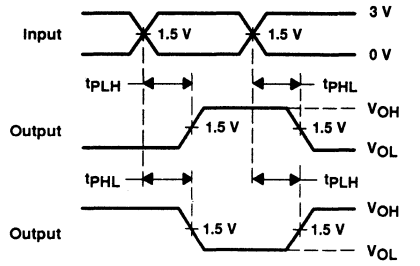
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



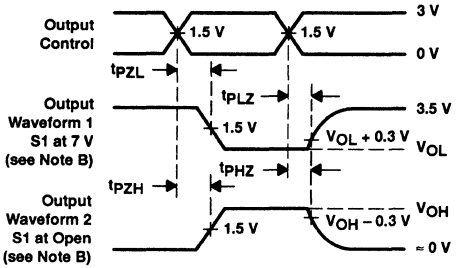
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



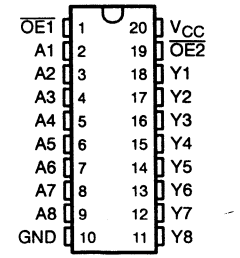
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

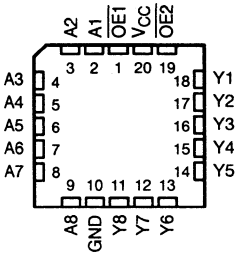
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (N) and Ceramic (J) 300-mil DIPs**

SN54ABT541 . . . J OR W PACKAGE
SN74ABT541B . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT541 . . . FK PACKAGE
(TOP VIEW)



description

The SN54ABT541 and SN74ABT541B octal buffers and line drivers are ideal for driving bus lines or buffering memory address registers. The devices feature inputs and outputs on opposite sides of the package to facilitate printed circuit board layout.

The 3-state control gate is a two-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all eight outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

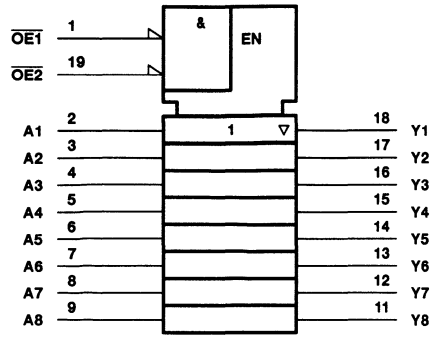
The SN54ABT541 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT541B is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

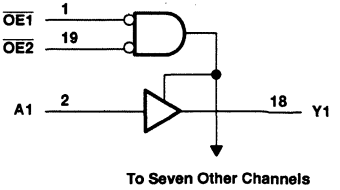
EPIC-IIB is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT541 ..... 96 mA
SN74ABT541B ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT541		SN74ABT541B		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT541		SN74ABT541B		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
		I_{OH} = –32 mA	2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
		I_{OL} = 64 mA			0.55*				0.55	
V_{hys}				100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZPU}‡	V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡	V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–140	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		5	250		250		250	µA
		Outputs low		22	30		30		30	mA
		Outputs disabled		1	250		250		250	µA
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
		Outputs disabled			50		50		50	µA
		Control inputs			1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V			3						pF
C_o	V_O = 2.5 V or 0.5 V			6						pF

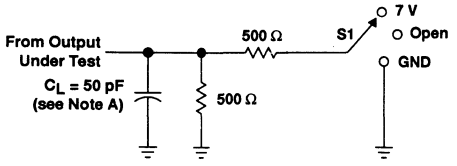
* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT541		SN74ABT541B		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2	3.2	1	3.8	1	3.6	ns
t_{PHL}			1	2.6	3.5	1	4.2	1	3.9	
t_{PZH}	$\overline{OE}$	Y	2	3.5	4.5	2	6	2	4	ns
t_{PZL}			1.9	4	5.1	1.9	6.5	1.9	5.9	
t_{PHZ}	$\overline{OE}$	Y	2.2	4.4	5.4	2.2	6	2.2	5.8	ns
t_{PLZ}			1.5	3	4	1.5	4.8	1.5	4.4	
$t_{sk(o)}$#					0.5				0.5	ns

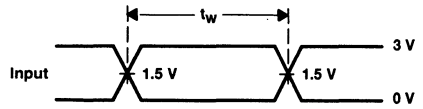
Skew between any two outputs of the same package switching in the same direction. This parameter is warranted, but not production tested.

PARAMETER MEASUREMENT INFORMATION

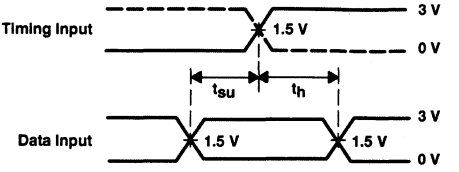


LOAD CIRCUIT

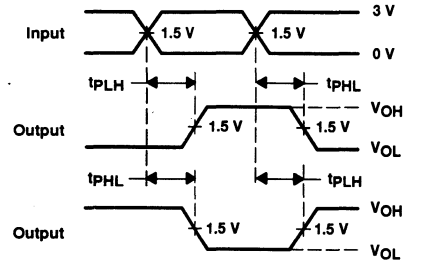
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



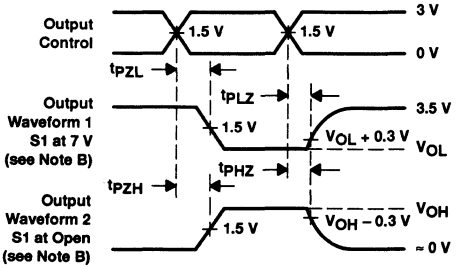
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



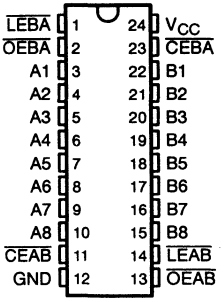
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

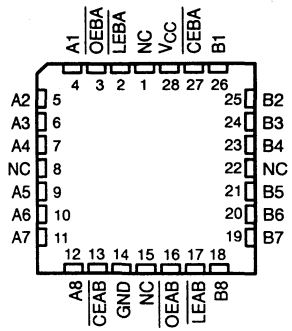
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT543A . . . JT OR W PACKAGE
SN74ABT543A . . . DB, DW, NT, OR PW PACKAGE
(TOP VIEW)



SN54ABT543A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABT543A octal transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable ($\overline{LEAB}$ or $\overline{LEBA}$) and output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable ($\overline{CEAB}$) input must be low to enter data from A or to output data from B. If $\overline{CEAB}$ is low and $\overline{LEAB}$ is low, the A-to-B latches are transparent; a subsequent low-to-high transition of $\overline{LEAB}$ puts the A latches in the storage mode. With $\overline{CEAB}$ and $\overline{OEAB}$ both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires using the $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$ inputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT543A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT543A is characterized for operation from –40°C to 85°C.

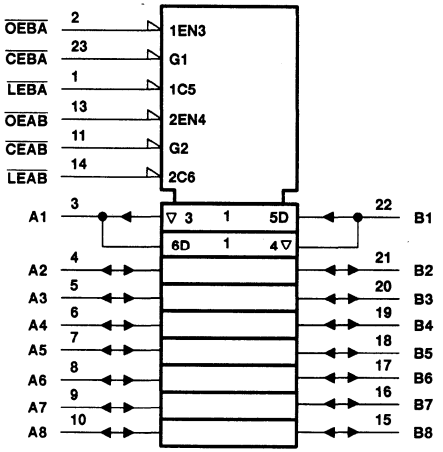
EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE†

INPUTS				OUTPUT
$\overline{CEAB}$	$\overline{LEAB}$	$\overline{OEAB}$	A	B
H	X	X	X	Z
X	X	H	X	Z
L	H	L	X	B_0‡
L	L	L	L	L
L	L	L	H	H

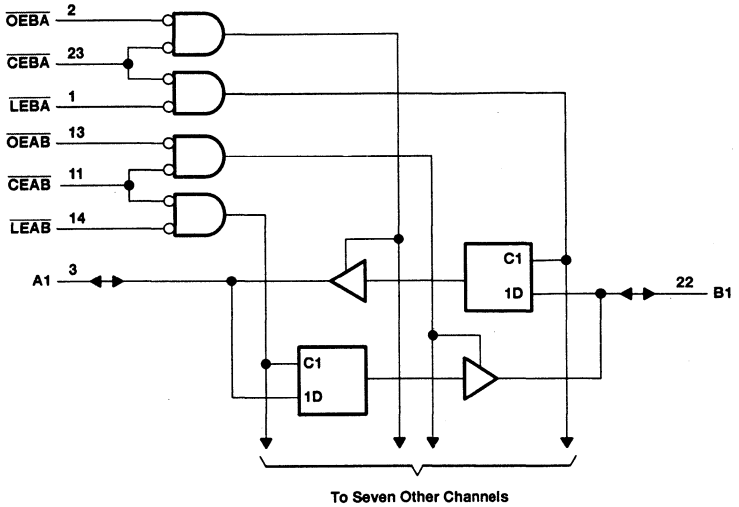
† A-to-B data flow is shown; B-to-A flow control is the same except that it uses $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$.
‡ Output level before the indicated steady-state input conditions were established

logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT543A ..... 96 mA
SN74ABT543A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
NT package ..... 67°C/W
PW package ..... 120°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT543A		SN74ABT543A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT543A		SN74ABT543A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			10§		10§		10§	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–10§		–10§		–10§	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50*	–100	–180*	–50	–200	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250*		350		250	µA
			Outputs low		24	30*		34		30	mA
			Outputs disabled		0.5	250*		350		250	µA
ΔI_{CC}#		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			7						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ This data sheet limit may vary among suppliers.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN54ABT543A		UNIT
				V_{CC} = 5 V, T_A = 25°C	MIN MAX	
				MIN MAX		
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low			3.5	3.5	ns
t_{su}	Setup time	Data before $\overline{LEAB}$ or $\overline{LEBA}\uparrow$	High	2.5	2.5	ns
			Low	3	3	
		Data before $\overline{CEAB}$ or $\overline{CEBA}\uparrow$	High	2.5	2.5	
			Low	3	3	
t_h	Hold time	Data after $\overline{LEAB}$ or $\overline{LEBA}\uparrow$		1	1	ns
		Data after $\overline{CEAB}$ or $\overline{CEBA}\uparrow$		1	1	

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN74ABT543A		UNIT
				V_{CC} = 5 V, T_A = 25°C	MIN MAX	
				MIN MAX		
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low			3.5	3.5	ns
t_{su}	Setup time	Data before $\overline{LEAB}$ or $\overline{LEBA}\uparrow$	High	3.5	3.5	ns
			Low	3	3	
		Data before $\overline{CEAB}$ or $\overline{CEBA}\uparrow$	High	3.5	3.5	
			Low	3	3	
t_h	Hold time	Data after $\overline{LEAB}$ or $\overline{LEBA}\uparrow$		0.5	0.5	ns
		Data after $\overline{CEAB}$ or $\overline{CEBA}\uparrow$		0.5	0.5	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT543A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1.6†	4.4	4.4	1.6†	5.5	ns
t_{PHL}			1.6	4.4	5.1	1.6	6.2	
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	1.6†	4.1	5.1	1.6†	6.6	ns
t_{PHL}			1.6	4.6	5.4	1.6	6.4	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	1.4	3.9	4.1	1.4	5.1	ns
t_{PZL}			2	5	4.9	2	5.8	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	2.5†	5.9	5.8	2.5†	6.9	ns
t_{PLZ}			2.5†	5.5	6.1	2.5†	7.6	
t_{PZH}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	1.4	3.9	4.7	1.4	5.6	ns
t_{PZL}			2	5	5.7	2	6.2	
t_{PHZ}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	3.2†	5.9	6.5	3.2†	7.3	ns
t_{PLZ}			2.5†	5.5	6.7	2.5†	7.8	

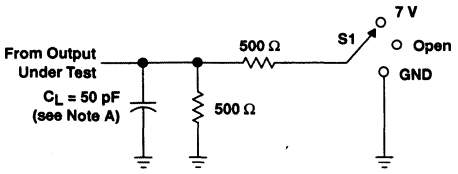
† This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT543A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1.8†	4.4	5.9	1.8†	6.9	ns
t_{PHL}			1.9	4.4	5.9	1.9	6.9	
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	1.5†	4.1	5.6	1.5†	6.6	ns
t_{PHL}			2.1	4.6	6.1	2.1	7.1	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	1.4	3.9	5.4	1.4	6.4	ns
t_{PZL}			2.5	5	6.5	2.5	7.5	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	2.5†	5.9	7.4	2.5†	8.4	ns
t_{PLZ}			2.5†	5.5	7	2.5†	8	
t_{PZH}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	1.4	3.9	5.4	1.4	6.4	ns
t_{PZL}			2.5	5	6.5	2.5	7.5	
t_{PHZ}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	2.9†	5.9	7.4	2.9†	8.4	ns
t_{PLZ}			2.4†	5.5	7	2.4†	8	

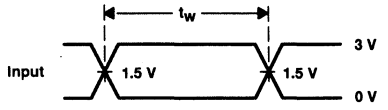
† This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

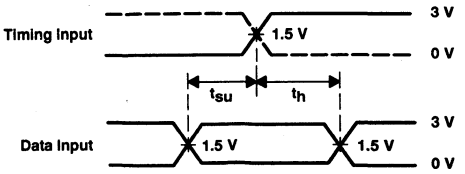


LOAD CIRCUIT

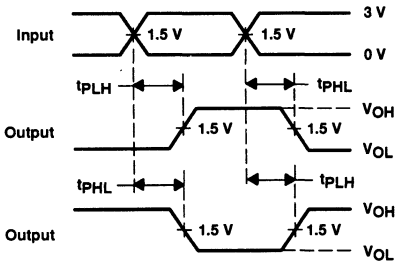
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



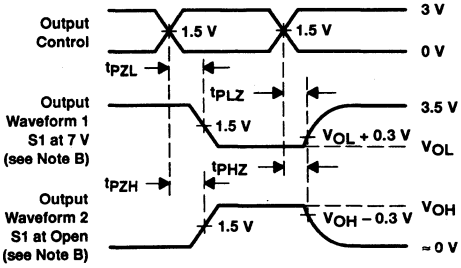
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



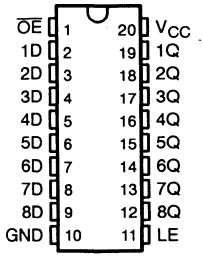
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

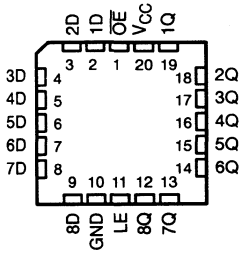
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Packages**

SN54ABT573 . . . J OR W PACKAGE
SN74ABT573A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT573 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the SN54ABT573 and SN74ABT573A are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT573 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT573A is characterized for operation from –40°C to 85°C.

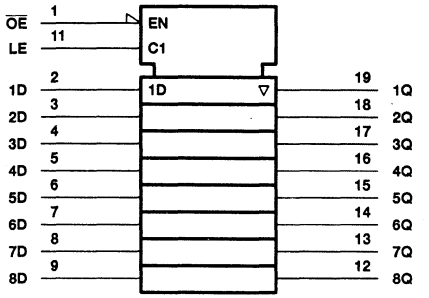
EPIC-IIB is a trademark of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

FUNCTION TABLE
(each latch)

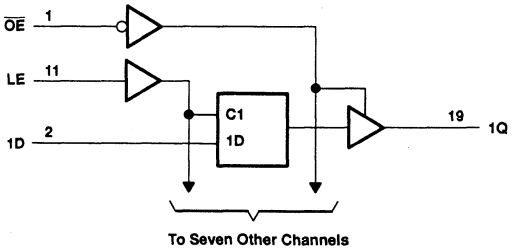
INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT573 ..... 96 mA
SN74ABT573A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT573		SN74ABT573A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT573		SN74ABT573A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = −18 mA				−1.2		−1.2		−1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = −3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = −3 mA		3			3		3		
	V_{CC} = 4.5 V	I_{OH} = −24 mA		2			2				
		I_{OH} = −32 mA		2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA				0.55		0.55			V
		I_{OL} = 64 mA				0.55*				0.55	
V_{hys}					100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V				10‡		10‡		10‡	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V				−10‡		−10‡		−10‡	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V		−50	−100	−180	−50	−180	−50	−180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND		Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V				3.5						pF
C_o	V_O = 2.5 V or 0.5 V				6.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This data sheet limit may vary among suppliers.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54ABT573			UNIT
			V_{CC} = 5 V, T_A = 25°C		MIN	MAX
			MIN	MAX		
t_w	Pulse duration, LE high		3.3		3.3		ns
t_{su}	Setup time, data before LE↓	High	1.9		2.5		ns
		Low	1.5		2.5		
t_h	Hold time, data after LE↓		1		2.5		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN74ABT573A				UNIT
			V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
			MIN	MAX			
t_w	Pulse duration, LE high		3.3		3.3		ns
t_{su}	Setup time, data before LE↓	High	1.9		1.9		ns
		Low	1.5		1.5		
t_h	Hold time, data after LE↓		1.8†		1.8†		ns

† This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

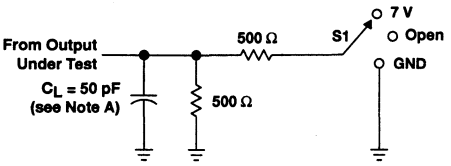
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT573					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	Q	1.9	3.2	5.4	1.4	6.4	ns
t_{PHL}			2.2	4.2	5.7	1.6	6.7	
t_{PLH}	LE	Q	2.2	4	6.1	2	7.1	ns
t_{PHL}			3.2	5.2	6.7	2.8	7.5	
t_{PZH}	$\overline{OE}$	Q	1.2	3.2	4.7	0.8	6.2	ns
t_{PZL}			2.7	4.7	6.2	2	7.2	
t_{PHZ}	$\overline{OE}$	Q	2.5	4.9	6.4	2.2	7.7	ns
t_{PLZ}			2	4.2	6	1.4	7	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT573A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	Q	1.9	3.2	5.4	1.9	5.9	ns
t_{PHL}			2.2	4.2	5.7	2.2	6.2	
t_{PLH}	LE	Q	2.2	4	6.1	2.2	6.6	ns
t_{PHL}			3.2	5.2	6.7	3.2	7.2	
t_{PZH}	$\overline{OE}$	Q	1.2	3.2	4.7	1.2	5.2	ns
t_{PZL}			2.5†	4.7	6.2	2.5†	6.7	
t_{PHZ}	$\overline{OE}$	Q	2.5	4.9	6.4	2.5	7.1†	ns
t_{PLZ}			2	4.2	6	2	6.5	

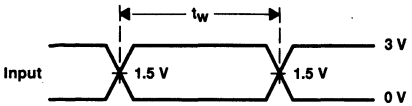
† This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

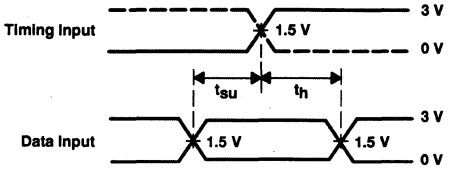


LOAD CIRCUIT

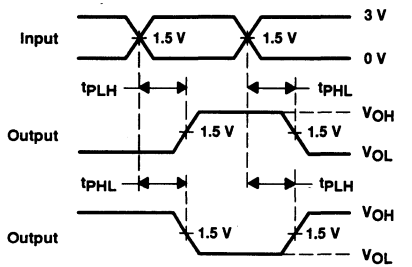
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



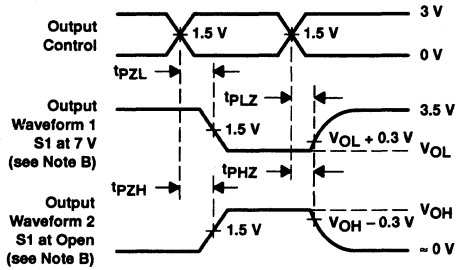
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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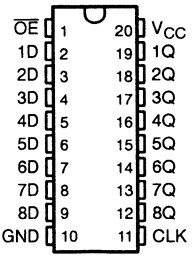
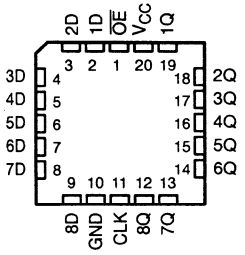
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT574 . . . J OR W PACKAGE
SN74ABT574A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT574 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the SN54ABT574 and SN74ABT574A are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT574 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT574A is characterized for operation from –40°C to 85°C.

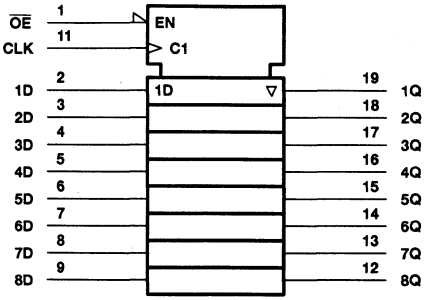
EPIC-IIB is a trademark of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

FUNCTION TABLE
(each flip-flop)

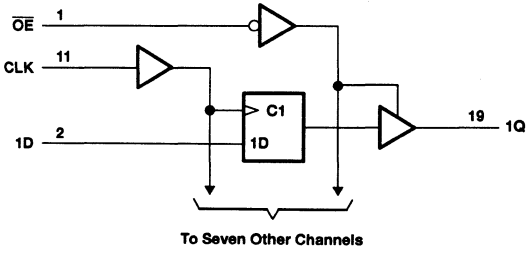
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT574 ..... 96 mA
SN74ABT574A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT574		SN74ABT574A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT574		SN74ABT574A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA		3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA		2			2				
		I_{OH} = –32 mA		2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA				0.55		0.55			V
		I_{OL} = 64 mA				0.55*				0.55	
V_{hys}					100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V				10‡		10‡		10‡	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V				–10‡		–10‡		–10‡	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V				±100		±500		±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND		Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V				3.5						pF
C_o	V_O = 2.5 V or 0.5 V				6.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This data sheet limit may vary among suppliers.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54ABT574			UNIT
			V_{CC} = 5 V, T_A = 25°C		MIN	MAX
			MIN	MAX		
f_{clock}	Clock frequency			150		150	MHz
t_w	Pulse duration, CLK high or low		3.3		3.3		ns
t_{su}	Setup time, data before CLK↑	High	1.5		1.5		ns
		Low	2		2		
t_h	Hold time, data after CLK↑	High or low	2		2		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN74ABT574A				UNIT
			V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
			MIN	MAX			
f_{clock}	Clock frequency			150		150	MHz
t_w	Pulse duration, CLK high or low		3.3		3.3		ns
t_{su}	Setup time, data before CLK↑	High	1		1		ns
		Low	1.5		1.5		
t_h	Hold time, data after CLK↑	High or low	1.8†		1.8†		ns

† This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

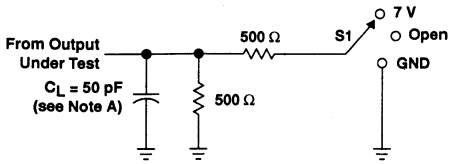
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT574					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150	200		150		MHz
t_{PLH}	CLK	Q	2.2	3.9	6.2	2.2	7	ns
t_{PHL}			3	4.8	7	3	7.4	
t_{PZH}	$\overline{OE}$	Q	1	3.3	5	1	5.8	ns
t_{PZL}			2.5	4.7	5.9	2.5	7.2	
t_{PHZ}	$\overline{OE}$	Q	2.4	4.9	6.2	2.4	7.2	ns
t_{PLZ}			2	4	5.8	2	6.9	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT574A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150	200		150		MHz
t_{PLH}	CLK	Q	2.2	3.9	6.2	2.2	6.8	ns
t_{PHL}			3	4.8	6.6	3	7.1	
t_{PZH}	$\overline{OE}$	Q	1	3.3	4.3	1	5.1	ns
t_{PZL}			2.1†	4.7	5.9	2.1†	6.7	
t_{PHZ}	$\overline{OE}$	Q	2.4	4.9	6.2	2.4	7	ns
t_{PLZ}			2	4	5.8	2	6.5	

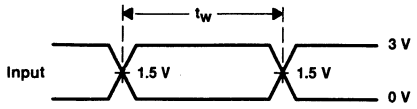
† This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

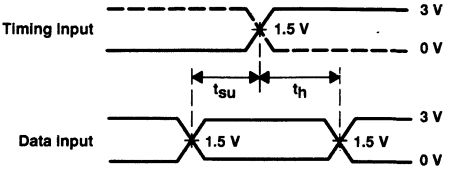


LOAD CIRCUIT

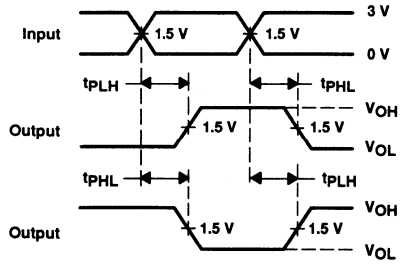
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



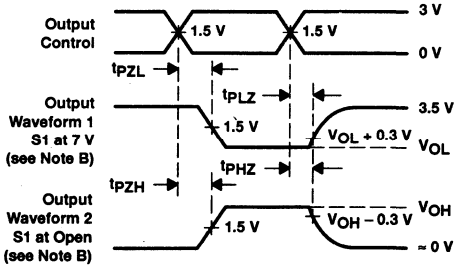
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



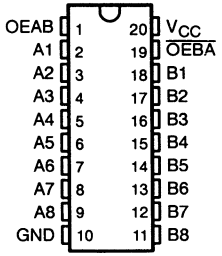
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

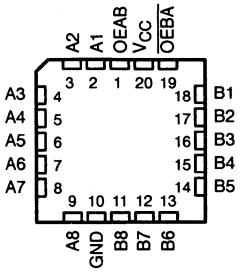
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC-IIB*™ BiCMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs**

SN54ABT620 . . . J PACKAGE
SN74ABT620 . . . DB, DW, OR N PACKAGE
(TOP VIEW)



SN54ABT620 . . . FK PACKAGE
(TOP VIEW)



description

These octal bus transceivers provide for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing. The 'ABT620 provide inverted data at the outputs.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and $\overline{\text{OEBA}}$) inputs.

The output-enable inputs can be used to disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability of storing data by simultaneously enabling OEAB and $\overline{\text{OEBA}}$. When both OEAB and $\overline{\text{OEBA}}$ are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 total) remain at their last states. In this way, each output reinforces its input in this configuration.

To ensure the high-impedance state during power up or power down, $\overline{\text{OEBA}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

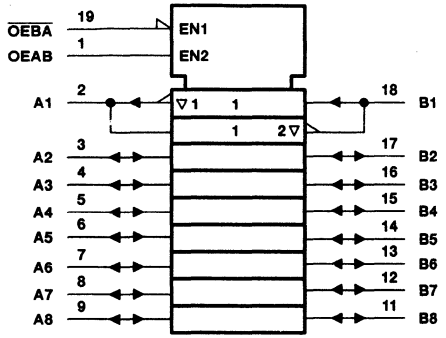
The SN54ABT620 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT620 is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE

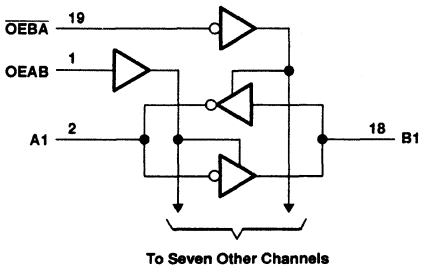
INPUTS		OPERATION
$\overline{OEBA}$	OEAB	
L	L	$\overline{B}$ data to A bus
L	H	$\overline{B}$ data to A bus, $\overline{A}$ data to B bus
H	L	Isolation
H	H	$\overline{A}$ data to B bus

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT620 ..... 96 mA
SN74ABT620 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT620		SN74ABT620		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

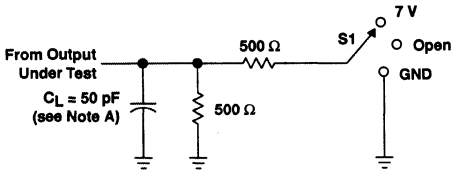
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT620		SN74ABT620		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		5	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}¶	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			7						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

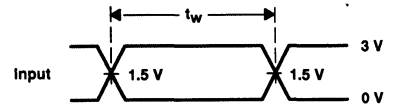
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C		SN54ABT620		SN74ABT620		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	4.1	1		1	4.8	ns
t_{PHL}			1	4.3	1		1	4.8	
t_{PZH}	$\overline{OEBA}$	A	1.3	4.6	1.3		1.3	5.5	ns
t_{PZL}			1	6.1	1		1	7.1	
t_{PHZ}	$\overline{OEBA}$	A	2	6.3	2		2	7	ns
t_{PLZ}			1.4	5.4	1.4		1.4	5.8	
t_{PZH}	OEAB	B	1.6	6.2	1.6		1.6	6.8	ns
t_{PZL}			2	5.9	2		2	6.4	
t_{PHZ}	OEAB	B	1.2	5.6	1.2		1.2	6.5	ns
t_{PLZ}			1.1	4.7	1.1		1.1	5.6	

PARAMETER MEASUREMENT INFORMATION

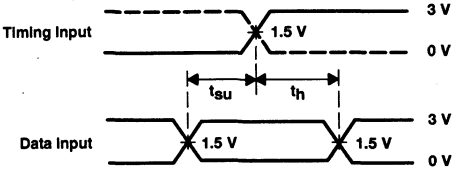


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

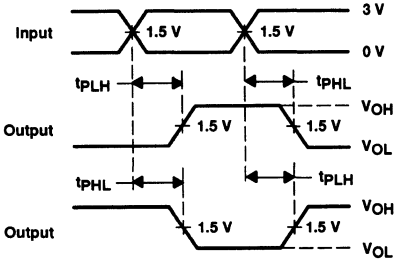
LOAD CIRCUIT



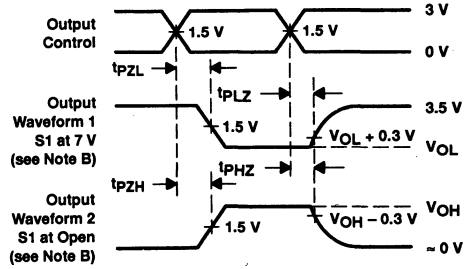
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



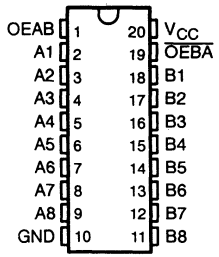
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

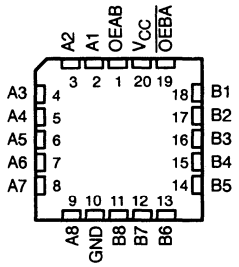
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (N) and Ceramic (JT) DIPs**

SN54ABT623A . . . JT OR W PACKAGE
SN74ABT623 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT623A . . . FK PACKAGE
(TOP VIEW)



description

The SN54ABT623A and SN74ABT623 bus transceivers are designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing. The SN54ABT623A and SN74ABT623 provide true data at their outputs.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and $\overline{\text{OEBA}}$) inputs.

The output-enable inputs can be used to disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability of storing data by simultaneously enabling OEAB and $\overline{\text{OEBA}}$. Each output reinforces its input in this configuration. When both OEAB and $\overline{\text{OEBA}}$ are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 total) remain at their last states.

To ensure the high-impedance state during power up or power down, $\overline{\text{OEBA}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

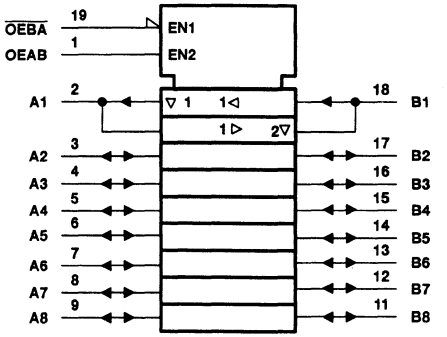
The SN54ABT623A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT623 is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE

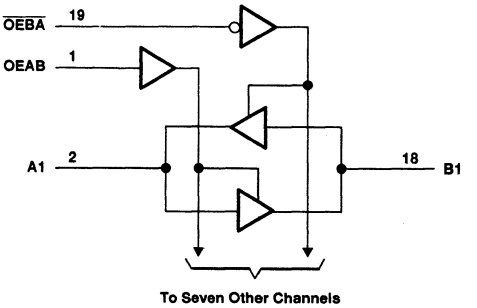
INPUTS		OPERATION
$\overline{OEBA}$	OEAB	
L	L	B data to A bus
L	H	B data to A bus, A data to B bus
H	L	Isolation
H	H	A data to B bus

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT623A ..... 96 mA
SN74ABT623 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT623A		SN74ABT623		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

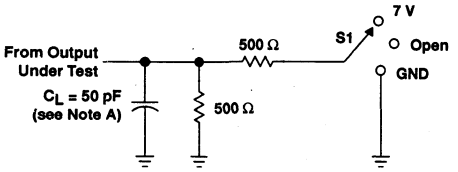
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT623A		SN74ABT623		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50**		10		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50**		–10		–50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		5	250		250		250	µA
			Outputs low		22	30		30		30	mA
			Outputs disabled		1	250		250		250	µA
ΔI_{CC}¶	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			7						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
** These limits apply only to the SN74ABT623.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

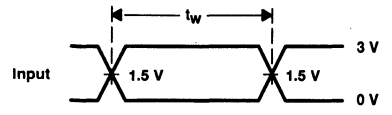
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT623A		SN74ABT623		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	2.6	4.1	1	4	1	4.6	ns
t_{PHL}			1	2.6	4.2	0.8	4.1	1	4.6	
t_{PZH}	$\overline{OEBA}$	A	1.7	3.4	6.5	1.2	5.4	1.7	7.5	ns
t_{PZL}			1.7	3.8	6.5	1.5	6.8	1.7	7.5	
t_{PHZ}	$\overline{OEBA}$	A	1.7	4.2	6.5	1.7	7.1	1.7	7.5	ns
t_{PLZ}			1.7	4.7	6.5	1.5	7.1	1.7	7.5	
t_{PZH}	OEAB	B	1.7	4.8	6.5	1.2	6.8	1.7	7.5	ns
t_{PZL}			1.7	4	6.5	1.7	6.5	1.7	7.5	
t_{PHZ}	OEAB	B	1.7	3.9	6.5	1.5	6.8	1.7	7.5	ns
t_{PLZ}			1.7	3.2	6.5	1.3	5.8	1.7	7.5	

PARAMETER MEASUREMENT INFORMATION

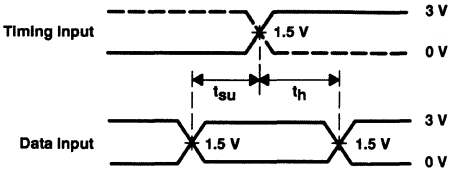


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

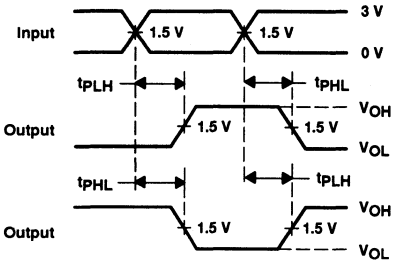
LOAD CIRCUIT



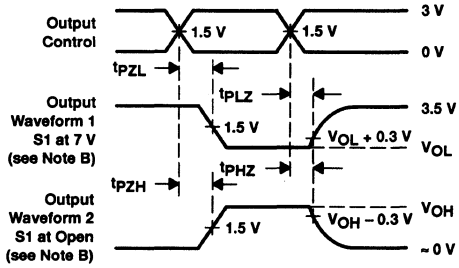
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



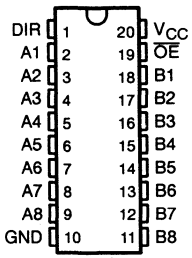
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

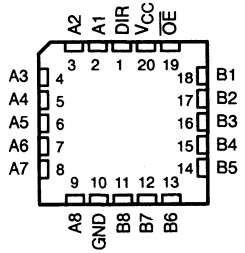
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs**

SN54ABT640 . . . J PACKAGE
SN74ABT640 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT640 . . . FK PACKAGE
(TOP VIEW)



description

The 'ABT640 bus transceivers are designed for asynchronous communication between data buses. These devices transmit inverted data from the A bus to the B bus or from the B bus to the A bus, depending on the level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so that the buses are effectively isolated.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

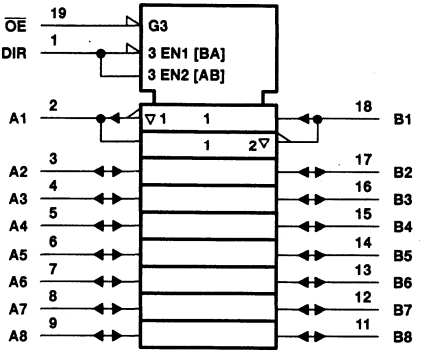
The SN54ABT640 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT640 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	$\overline{B}$ data to A bus
L	H	$\overline{A}$ data to B bus
H	X	Isolation

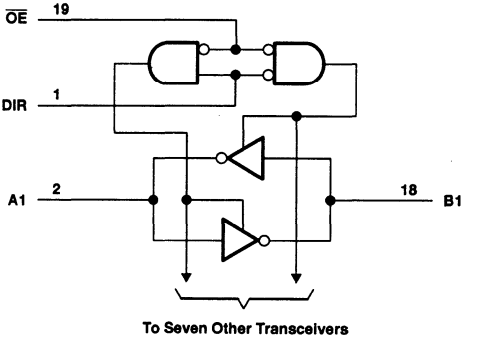
EPIC-IIB is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT640 ..... 96 mA
SN74ABT640 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT640		SN74ABT640		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

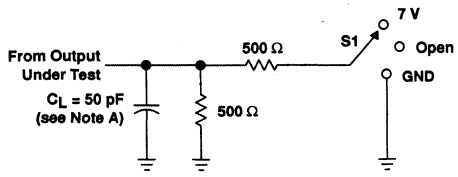
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT640		SN74ABT640		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		5	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}¶	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			7						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

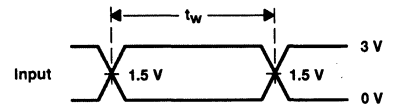
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT640		SN74ABT640		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	2.7	4.2	1	5	1	4.9	ns
t_{PHL}			1.5	2.7	4.3	1.5	5	1.5	4.9	
t_{PZH}	$\overline{OE}$	A or B	1.5	3.7	4.9	1.5	5.9	1.5	5.8	ns
t_{PZL}			1.3	5	5.9	1.3	7.4	1.3	7.3	
t_{PHZ}	$\overline{OE}$	A or B	2.5	4.1	6.5	2.5	6.9	2.5	6.8	ns
t_{PLZ}			2	3.3	5.3	2	5.6	2	5.5	

PARAMETER MEASUREMENT INFORMATION

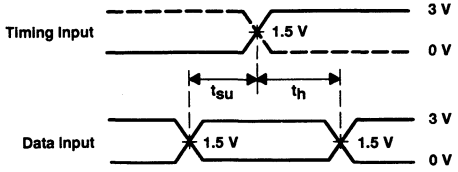


LOAD CIRCUIT

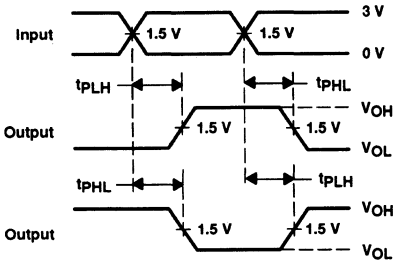
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



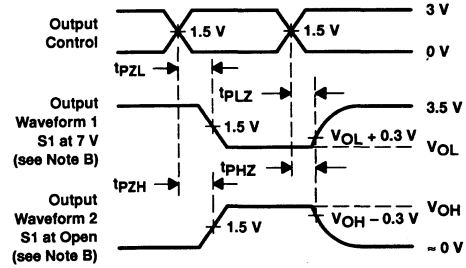
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



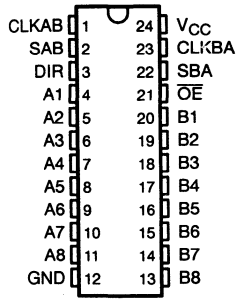
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

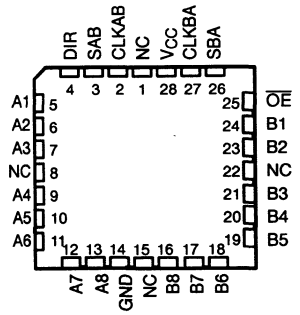
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT646A . . . JT OR W PACKAGE
SN74ABT646A . . . DB, DW, NT, OR PW PACKAGE
(TOP VIEW)



SN54ABT646A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

These devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT646A.

Output-enable ($\overline{OE}$) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port can be stored in either register or in both.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The direction control (DIR) determines which bus receives data when $\overline{OE}$ is low. In the isolation mode ($\overline{OE}$ high), A data can be stored in one register and/or B data can be stored in the other register.

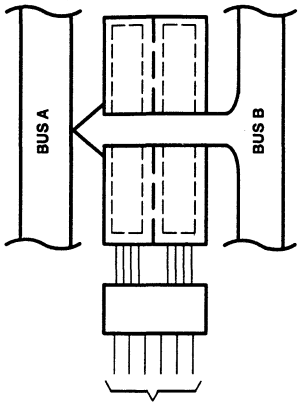
When an output function is disabled, the input function is still enabled and can be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT646A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT646A is characterized for operation from –40°C to 85°C.

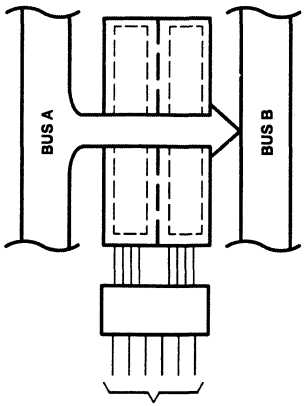
EPIC-IIB is a trademark of Texas Instruments Incorporated.

TEXAS INSTRUMENTS



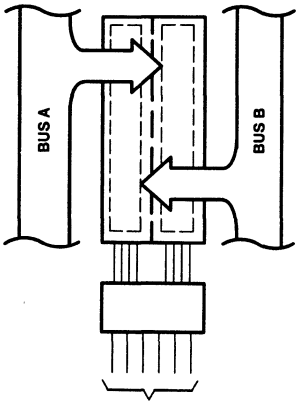
21	3	1	23	2	22
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
L	L	X	X	X	L

REAL-TIME TRANSFER BUS B TO BUS A



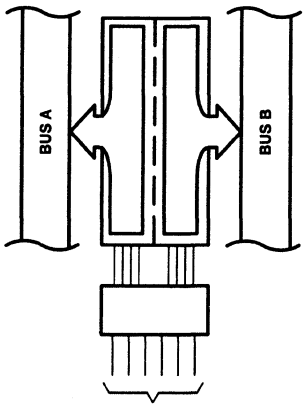
21	3	1	23	2	22
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
L	H	X	X	L	X

REAL-TIME TRANSFER BUS A TO BUS B



21	3	1	23	2	22
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
X	X	↑	X	X	X
X	X	X	↑	X	X
H	X	↑	↑	X	X

STORAGE FROM A, B, OR A AND B



21	3	1	23	2	22
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
L	L	X	L	X	H
L	H	L	X	H	X

TRANSFER STORED DATA TO A AND/OR B

Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

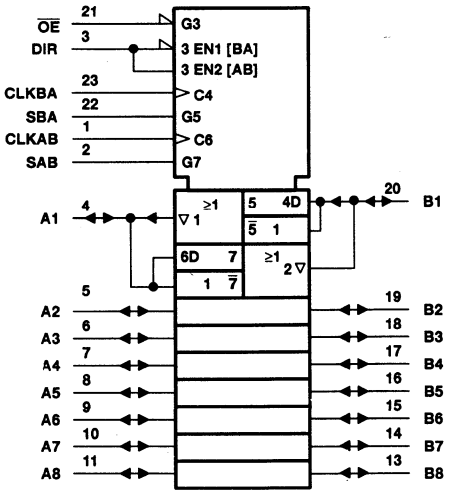
Figure 1. Bus-Management Functions

FUNCTION TABLE

INPUTS						DATA I/Os		OPERATION OR FUNCTION
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	
X	X	↑	X	X	X	Input	Unspecified†	Store A, B unspecified†
X	X	X	↑	X	X	Unspecified†	Input	Store B, A unspecified†
H	X	↑	↑	X	X	Input	Input	Store A and B data
H	X	H or L	H or L	X	X	Input disabled	Input disabled	Isolation, hold storage
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
L	H	X	X	L	X	Input	Output	Real-time A data to B bus
L	H	H or L	X	H	X	Input	Output	Stored A data to B bus

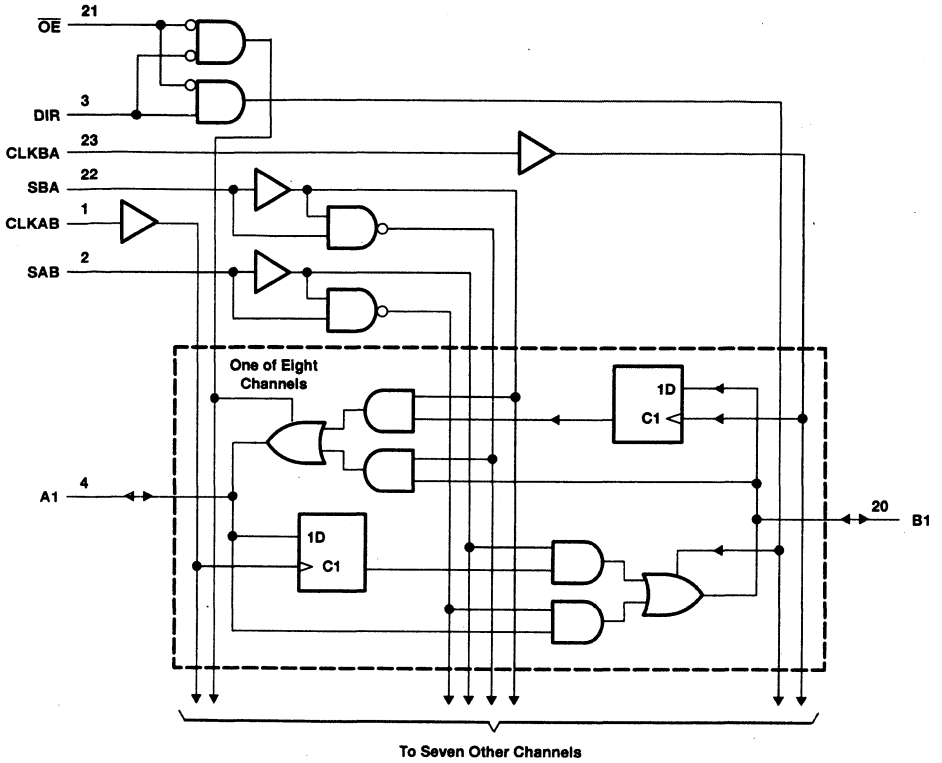
† The data-output functions may be enabled or disabled by various signals at $\overline{OE}$ and DIR. Data-input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

logic symbol‡



‡ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT646A ..... 96 mA
SN74ABT646A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
NT package ..... 67°C/W
PW package ..... 120°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT646A		SN74ABT646A		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT646A		SN74ABT646A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			10§		10§		10§	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–10§		–10§		–10§	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			250		250		250	µA
			Outputs low			30		30		30	mA
			Outputs disabled			250		250		250	µA
ΔI_{CC}#		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			7						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			12						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ This data sheet limit may vary among suppliers.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN54ABT646A				UNIT
		V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
		MIN	MAX			
f_{clock}	Clock frequency	0	125	0	125	MHz
t_w	Pulse duration, CLK high or low	4		4		ns
t_{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3.5		ns
t_h	Hold time, A or B after CLKAB↑ or CLKBA↑	1.5		1.5		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN74ABT646A				UNIT
		V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
		MIN	MAX			
f_{clock}	Clock frequency	0	125	0	125	MHz
t_w	Pulse duration, CLK high or low	4		4		ns
t_{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3		ns
t_h	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT646A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125			125		MHz
t_{PLH}	CLKBA or CLKAB	A or B	2.2	4	5.1	2.2	6.7	ns
t_{PHL}			1.7	4	5.1	1.2	6.7	
t_{PLH}	A or B	B or A	1.5	3	4.3	1.5	5	ns
t_{PHL}			1.5	3.3	4.6	1.5	5.6	
t_{PLH}	SAB or SBA†	B or A	1.5	4	5.7	1.5	7.8	ns
t_{PHL}			1.5	3.6	4.9	1.5	6.2	
t_{PZH}	$\overline{OE}$	A or B	1.5	4.3	5.3	1.5	7	ns
t_{PZL}			3	5.8	8	3	10.5	
t_{PHZ}	$\overline{OE}$	A or B	1.5	3.5	5.8	1	7.3	ns
t_{PLZ}			1.5	3	4	1.5	5.7	
t_{PZH}	DIR	A or B	1.5	4.5	5.7	1.5	7.3	ns
t_{PZL}			2.5	6.5	9	2.5	11	
t_{PHZ}	DIR	A or B	1.5	3.8	6.5	1	9	ns
t_{PLZ}			1.5	3.8	4.7	1.2	6.7	

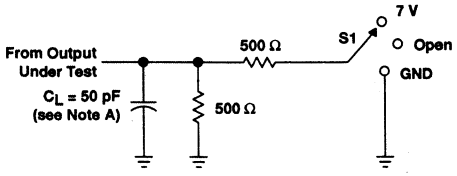
† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT646A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125			125		MHz
t_{PLH}	CLKBA or CLKAB	A or B	2.2	4	5.1	2.2	5.6	ns
t_{PHL}			1.7	4	5.1	1.7	5.6	
t_{PLH}	A or B	B or A	1.5	3	4.3	1.5	4.8	ns
t_{PHL}			1.5	3.3	4.6	1.5	5.4	
t_{PLH}	SAB or SBA†	B or A	1.5	4	5.1	1.5	6.5	ns
t_{PHL}			1.5	3.6	4.9	1.5	5.9	
t_{PZH}	$\overline{OE}$	A or B	1.5	4.3	5.3	1.5	6.3	ns
t_{PZL}			3	5.8	7.4	3	8.8	
t_{PHZ}	$\overline{OE}$	A or B	1.5	3.5	4.5	1.5	5	ns
t_{PLZ}			1.5	3	4	1.5	4.5	
t_{PZH}	DIR	A or B	1.5	4.5	5.7	1.5	6.7	ns
t_{PZL}			2.5	6.5	9	2.5	9.5	
t_{PHZ}	DIR	A or B	1.5	3.8	5	1.5	5.7	ns
t_{PLZ}			1.5	3.8	4.7	1.5	6	

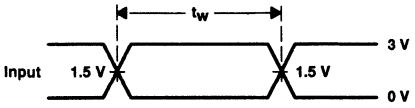
† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

PARAMETER MEASUREMENT INFORMATION

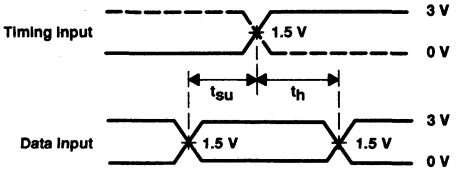


LOAD CIRCUIT

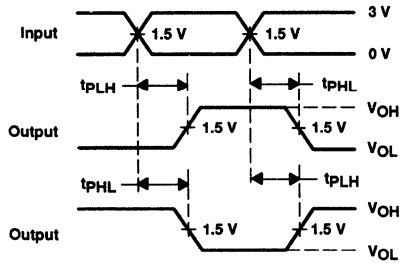
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



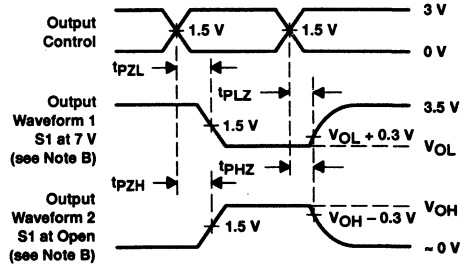
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



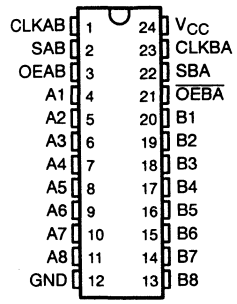
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

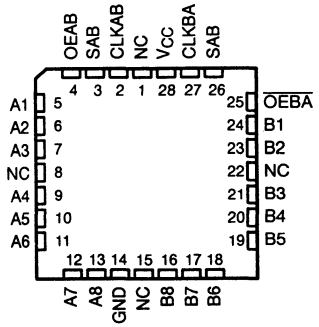
Figure 2. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Multiplexed Real-Time and Stored Data**
- **Inverting Data Paths**
- **Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT651 . . . JT PACKAGE
SN74ABT651 . . . DB, DW, OR NT PACKAGE
(TOP VIEW)



SN54ABT651 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

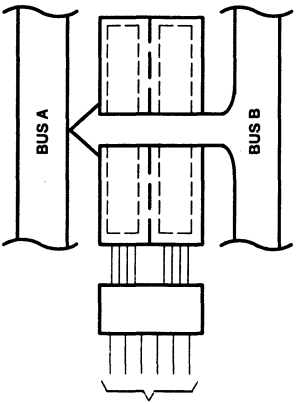
These devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Output-enable (OEAB and $\overline{OEBA}$) inputs are provided to control the transceiver functions. The select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT651.

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the select- or enable-control pins. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and $\overline{OEBA}$. In this configuration, each output reinforces its input. When all the other data sources to the two sets of bus lines are at high impedance, each set remains at its last state.

To ensure the high-impedance state during power up or power down, $\overline{OEBA}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver (B to A). OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver (A to B).

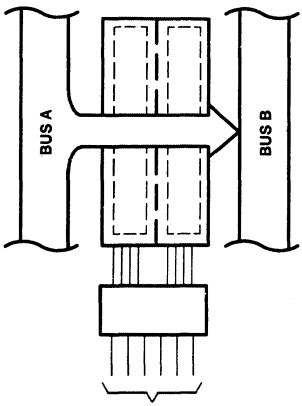
The SN54ABT651 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT651 is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.



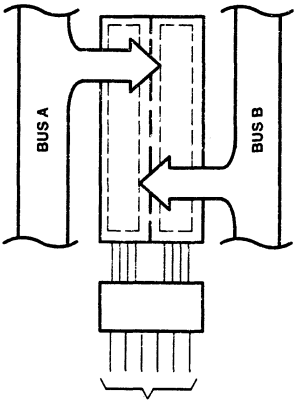
3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
L	L	X	X	X	L

REAL-TIME TRANSFER BUS B TO BUS A



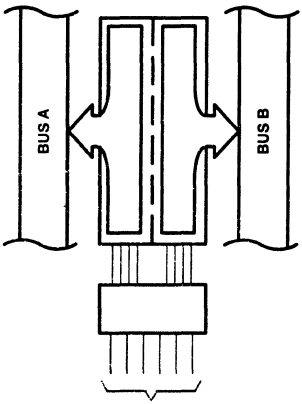
3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	H	X	X	L	X

REAL-TIME TRANSFER BUS A TO BUS B



3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
X	H	↑	X	X	X
L	X	X	↑	X	X
L	H	↑	↑	X	X

STORAGE FROM A, B, OR A AND B



3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	L	H or L	H or L	H	H

TRANSFER STORED DATA TO A AND/OR B

Pin numbers are for the DB, DW, JT, and NT packages.

Figure 1. Bus-Management Functions

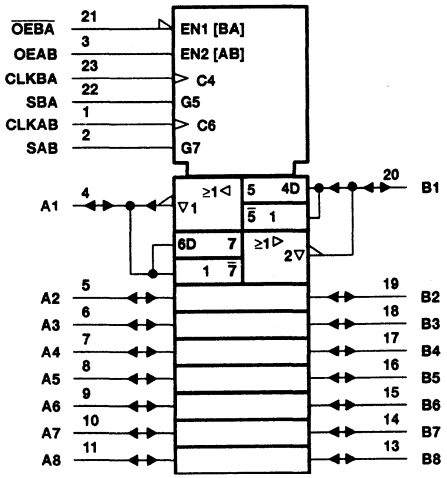
FUNCTION TABLE

INPUTS						DATA I/O		OPERATION OR FUNCTION
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	H or L	X	X	Input	Unspecified†	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	H or L	↑	X	X	Unspecified†	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time $\overline{B}$ data to A bus
L	L	X	H or L	X	H	Output	Input	Stored $\overline{B}$ data to A bus
H	H	X	X	L	X	Input	Output	Real-time $\overline{A}$ data to B bus
H	H	H or L	X	H	X	Input	Output	Stored $\overline{A}$ data to B bus
H	L	H or L	H or L	H	H	Output	Output	Stored $\overline{A}$ data to B bus and stored $\overline{B}$ data to A bus

† The data output functions may be enabled or disabled by a variety of level combinations at OEAB or $\overline{OEBA}$. Data input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

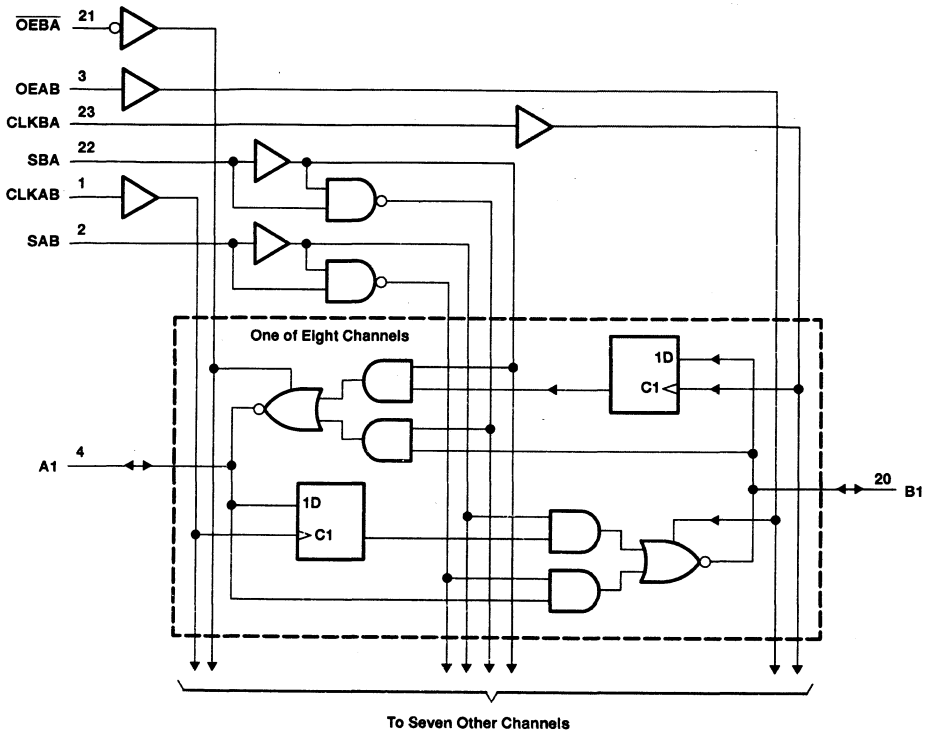
‡ When select control is low, clocks can occur simultaneously if allowances are made for propagation delays from A to B (B to A) plus setup and hold times. When select control is high, clocks must be staggered to load both registers.

logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, and NT packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT651 ..... 96 mA
SN74ABT651 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
NT package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT651		SN74ABT651		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT651		SN74ABT651		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			250		250		250	µA
			Outputs low			30		30		30	mA
			Outputs disabled			250		250		250	µA
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			6						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

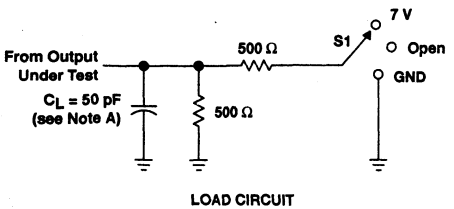
		V_{CC} = 5 V, T_A = 25°C		SN54ABT651		SN74ABT651		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	125	0	125	0	125	MHz
t_w	Pulse duration, CLK high or low	4		4		4		ns
t_{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3		3		ns
t_h	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		0		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT651		SN74ABT651		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			125			125		125		MHz
t_{PLH}	CLKBA or CLKAB	A or B	2.2	4	5.1	2.2	5.9	2.2	5.6	ns
t_{PHL}			1.7	4	5.1	1.7	5.9	1.7	5.6	
t_{PLH}	A or B	B or A	1.5	4	5.1	1.5	6.4	1.5	6.2	ns
t_{PHL}			1.5	3.3	4.6	1.5	5.8	1.5	5.4	
t_{PLH}	SAB or SBA†	A or B	1.5	4	5.1	1.5	6.8	1.5	6.5	ns
t_{PHL}			1.5	3.6	4.9	1.5	6.2	1.5	5.9	
t_{PZH}	$\overline{OEBA}$	A	1.3	3.6	4.6	1.3	5.9	1.3	5.8	ns
t_{PZL}			2.5	5.7	6.8	2.5	8.9	2.5	8.5	
t_{PHZ}	$\overline{OEBA}$	A	1.5	3.2	4.5	1.5	6.2	1.5	5	ns
t_{PLZ}			1.5	3	3.8	1.5	4.3	1.5	4.1	
t_{PZH}	OEAB	B	1.8	4.3	6.1	1.8	6.7	1.8	6.5	ns
t_{PZL}			2.9	5.5	6.5	2.9	7.6	2.9	7.4	
t_{PHZ}	OEAB	B	1.5	3.3	4.5	1.5	6.5	1.5	5.5	ns
t_{PLZ}			1.5	3.4	4.4	1.5	5.2	1.5	5.1	

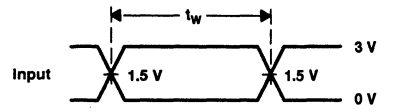
† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

PARAMETER MEASUREMENT INFORMATION

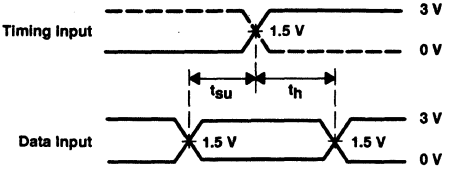


LOAD CIRCUIT

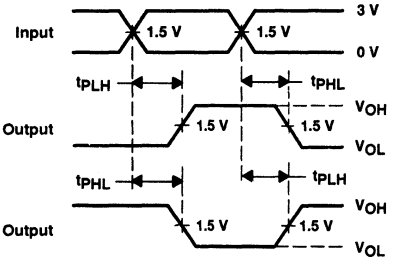
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



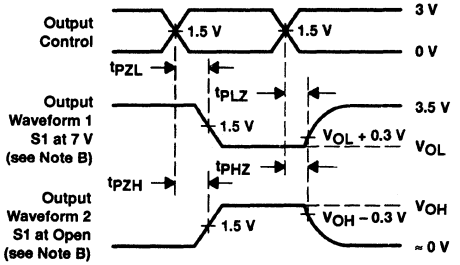
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



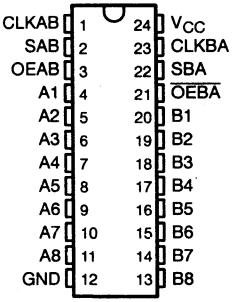
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

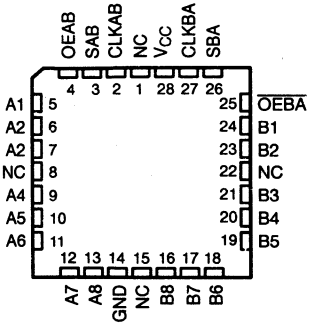
Figure 2. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT652A . . . JT OR W PACKAGE
SN74ABT652A . . . DB, DW, NT, OR PW PACKAGE
(TOP VIEW)



SN54ABT652A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

These devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers.

Output-enable (OEAB and $\overline{\text{OEBA}}$) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select either real-time or stored data for transfer. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input selects real-time data, and a high input selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT652A.

Data on the A- or B-data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the select- or enable-control inputs. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and $\overline{\text{OEBA}}$. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

To ensure the high-impedance state during power up or power down, $\overline{\text{OEBA}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver (B to A). OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver (A to B).

EPIC-IIB is a trademark of Texas Instruments Incorporated.

description (continued)

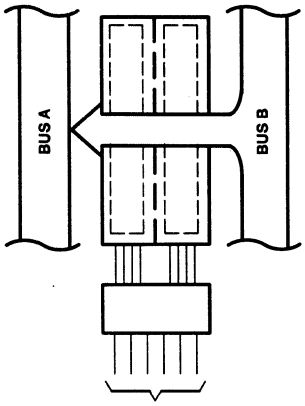
The SN54ABT652A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT652A is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS						DATA I/O†		OPERATION OR FUNCTION
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	H or L	X	X	Input	Unspecified‡	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	H or L	↑	X	X	Unspecified‡	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	H or L	X	H	X	Input	Output	Stored A data to B bus
H	L	H or L	H or L	H	H	Output	Output	Stored A data to B bus and stored B data to A bus

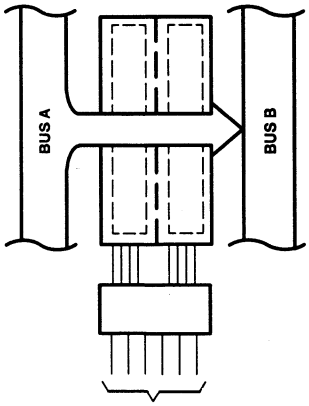
† The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or $\overline{OEBA}$. Data-input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

‡ Select control = L; clocks can occur simultaneously.
Select control = H; clocks must be staggered to load both registers.



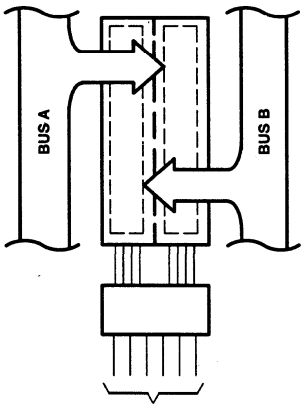
3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
L	L	X	X	X	L

REAL-TIME TRANSFER BUS B TO BUS A



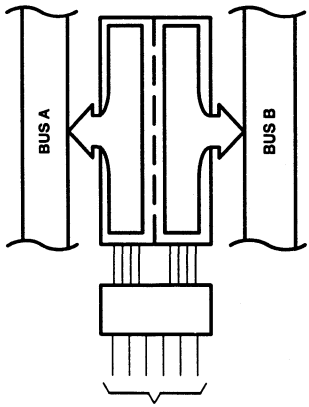
3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	H	X	X	L	X

REAL-TIME TRANSFER BUS A TO BUS B



3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
X	H	↑	X	X	X
L	X	X	↑	X	X
L	H	↑	↑	X	X

STORAGE FROM A, B, OR A AND B



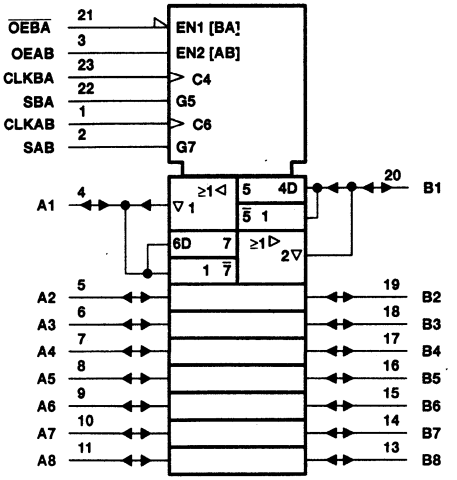
3	21	1	23	2	22
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	L	H or L	H or L	H	H

TRANSFER STORED DATA TO A AND/OR B

Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

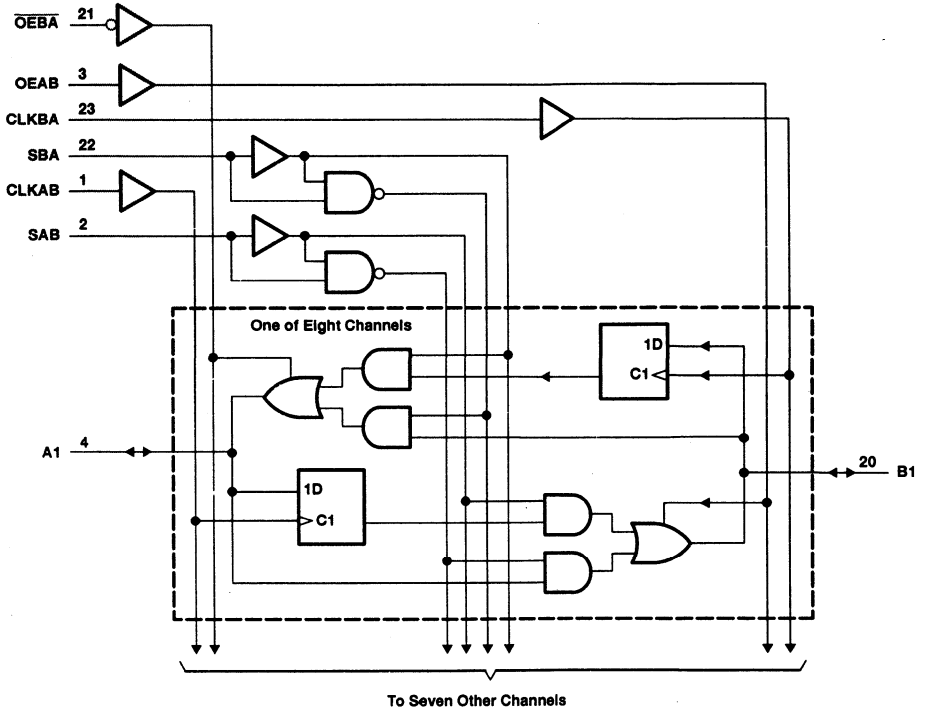
Figure 1. Bus-Management Functions

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT652A ..... 96 mA
SN74ABT652A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
NT package ..... 67°C/W
PW package ..... 120°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT652A		SN74ABT652A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT652A		SN74ABT652A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50**		10		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50**		–10		–50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			250		250		250	µA
			Outputs low			30		30		30	mA
			Outputs disabled			250		250		250	µA
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			7						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			12						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
** These limits apply only to the SN74ABT652A.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN54ABT652A				UNIT
		V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
		MIN	MAX			
f_{clock}	Clock frequency	0	125	0	125	MHz
t_w	Pulse duration, CLK high or low	4		4		ns
t_{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3.5		ns
t_h	Hold time, A or B after CLKAB↑ or CLKBA↑	1.5		1.5		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN74ABT652A				UNIT
		V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
		MIN	MAX			
f_{clock}	Clock frequency	0	125	0	125	MHz
t_w	Pulse duration, CLK high or low	4		4		ns
t_{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3		ns
t_h	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT652A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125	200		125		MHz
t_{PLH}	CLK	B or A	2.2	4	5.1	1.7	5.9	ns
t_{PHL}			1.7	4	5.1	1.7	5.9	
t_{PLH}	A or B	B or A	1.5	3	4.8	1	5	ns
t_{PHL}			1.5	3.3	4.6	1	5.6	
t_{PLH}	SAB or SBA†	B or A	1.5	4	5.5	1.5	6.8	ns
t_{PHL}			1.5	3.6	4.9	1.5	6.2	
t_{PZH}	$\overline{OEBA}$	A	2	3.6	5.4	2	6.8	ns
t_{PZL}			3	5.7	7.7	3	9.2	
t_{PHZ}	$\overline{OEBA}$	A	1.5	3.2	5.8	1	7.5	ns
t_{PLZ}			1.5	3	4.3	1	4.6	
t_{PZH}	OEAB	B	2	4.3	6.1	2	7.8	ns
t_{PZL}			3	5.5	7.4	3	8.9	
t_{PHZ}	OEAB	B	1.5	3.3	6	1	8	ns
t_{PLZ}			1.5	3.4	5	1.5	6.8	

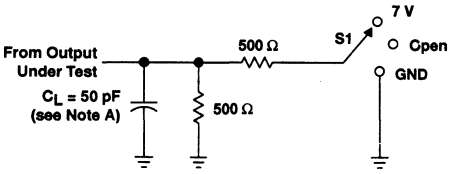
† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT652A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125	200		125		MHz
t_{PLH}	CLK	B or A	2.2	4	5.1	2.2	5.6	ns
t_{PHL}			1.7	4	5.1	1.7	5.6	
t_{PLH}	A or B	B or A	1.5	3	4.3	1.5	4.8	ns
t_{PHL}			1.5	3.3	4.6	1.5	5.4	
t_{PLH}	SAB or SBA†	B or A	1.5	4	5.1	1.5	6.5	ns
t_{PHL}			1.5	3.6	4.9	1.5	5.9	
t_{PZH}	$\overline{OEBA}$	A	2	3.6	4.6	2	5.8	ns
t_{PZL}			3	5.7	6.8	3	8.5	
t_{PHZ}	$\overline{OEBA}$	A	1.5	3.2	4.5	1.5	5	ns
t_{PLZ}			1.5	3	3.8	1.5	4.1	
t_{PZH}	OEAB	B	2	4.3	6.1	2	6.5	ns
t_{PZL}			3	5.5	6.5	3	7.4	
t_{PHZ}	OEAB	B	1.5	3.3	4.5	1.5	5.5	ns
t_{PLZ}			1.5	3.4	4.4	1.5	5.1	

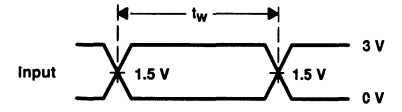
† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

PARAMETER MEASUREMENT INFORMATION

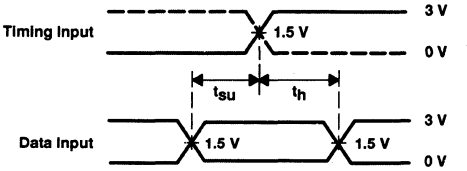


LOAD CIRCUIT

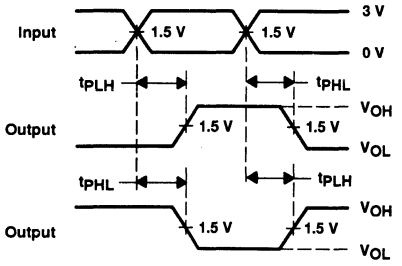
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



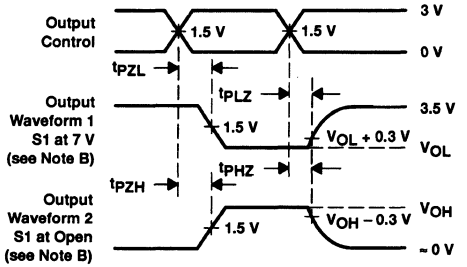
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



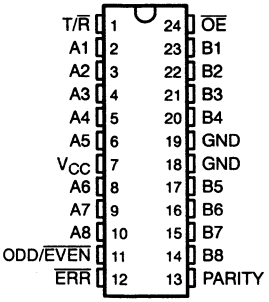
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

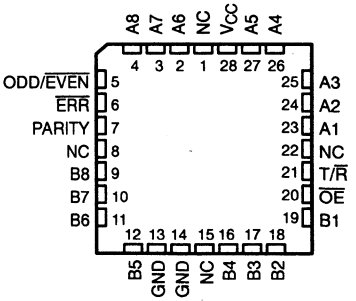
Figure 2. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT657A . . . JT PACKAGE
SN74ABT657A . . . DW OR NT PACKAGE
(TOP VIEW)



SN54ABT657A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABT657A transceivers have eight noninverting buffers with parity-generator/checker circuits and control signals. The transmit/receive (T/$\overline{R}$) input determines the direction of data flow. When T/$\overline{R}$ is high, data flows from the A port to the B port (transmit mode); when T/$\overline{R}$ is low, data flows from the B port to the A port (receive mode). When the output-enable ($\overline{OE}$) input is high, both the A and B ports are in the high-impedance state.

Odd or even parity is selected by a logic high or low level on the ODD/$\overline{EVEN}$ input. PARITY carries the parity-bit value; it is an output from the parity generator/checker in the transmit mode and an input to the parity generator/checker in the receive mode.

In the transmit mode, after the A bus is polled to determine the number of high bits, PARITY is set to the logic level that maintains the parity sense selected by the level at ODD/$\overline{EVEN}$. For example, if ODD/$\overline{EVEN}$ is low (even parity selected) and there are five high bits on the A bus, PARITY is set to the logic high level so that an even number of the nine total bits (eight A-bus bits plus parity bit) are high.

In the receive mode, after the B bus is polled to determine the number of high bits, the error ($\overline{ERR}$) output logic level indicates whether or not the data to be received exhibits the correct parity sense. For example, if ODD/$\overline{EVEN}$ is high (odd parity selected), PARITY is high, and there are three high bits on the B bus, $\overline{ERR}$ is low, indicating a parity error.

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TEXAS INSTRUMENTS

description (continued)

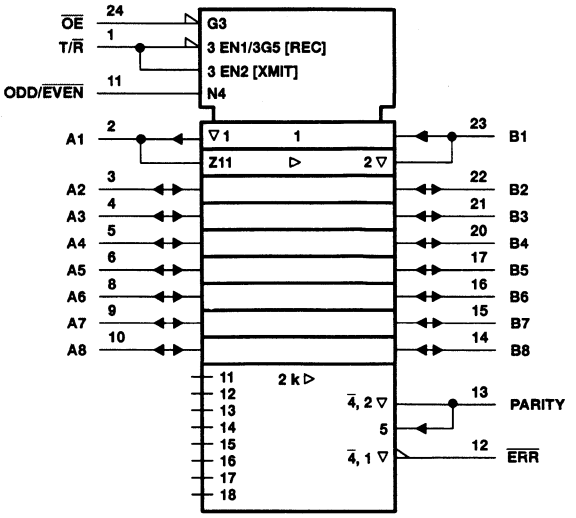
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT657A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT657A is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

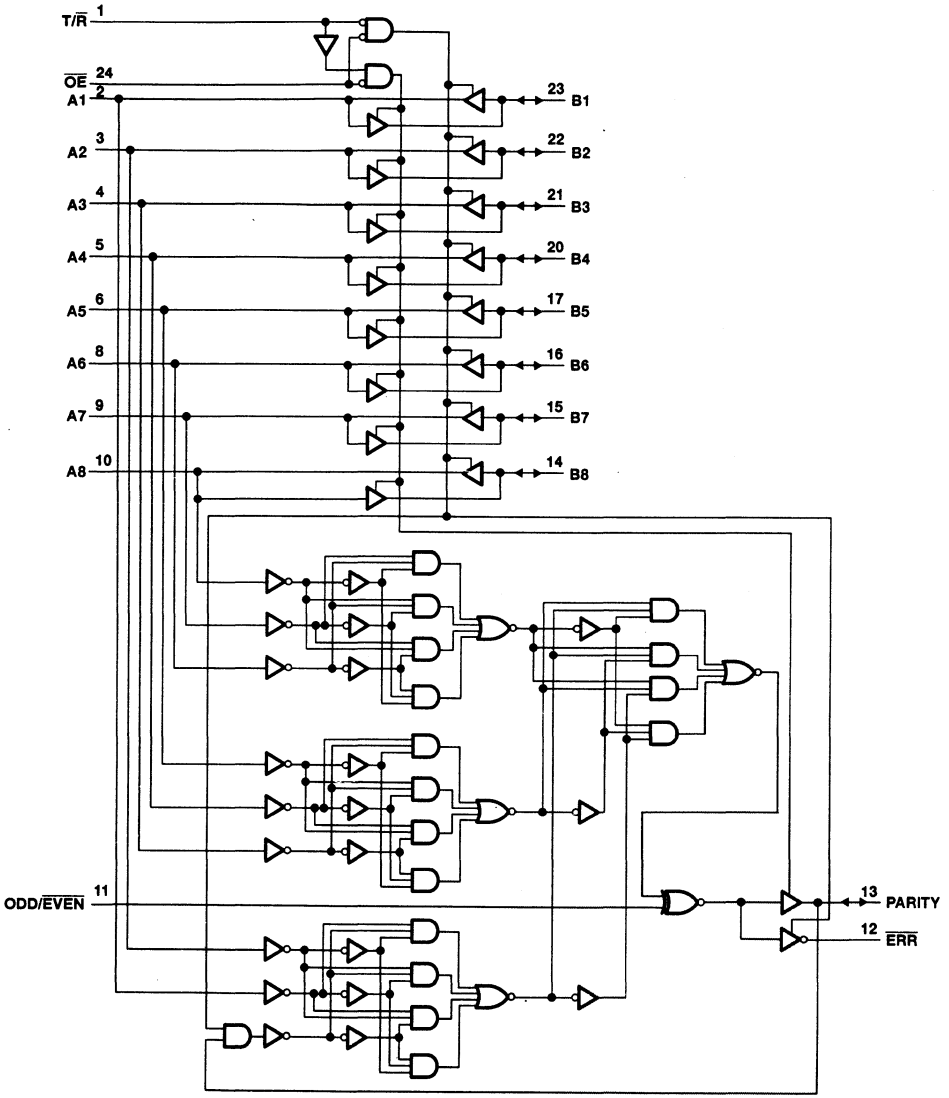
NUMBER OF A OR B INPUTS THAT ARE HIGH	INPUTS			I/O PARITY	OUTPUTS	
	$\overline{OE}$	T/$\overline{R}$	ODD/$\overline{EVEN}$		$\overline{ERR}$	OUTPUT MODE
0, 2, 4, 6, 8	L	H	H	H	Z	Transmit
	L	H	L	L	Z	Transmit
	L	L	H	H	H	Receive
	L	L	H	L	L	Receive
	L	L	L	H	L	Receive
	L	L	L	L	H	Receive
1, 3, 5, 7	L	H	H	L	Z	Transmit
	L	H	L	H	Z	Transmit
	L	L	H	H	L	Receive
	L	L	H	L	H	Receive
	L	L	L	H	H	Receive
	L	L	L	L	L	Receive
Don't care	H	X	X	Z	Z	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW, JT, and NT packages.

logic diagram (positive logic)



Pin numbers shown are for the DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT657A ..... 96 mA
SN74ABT657A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package ..... 81°C/W
NT package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT657A		SN74ABT657A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		µs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

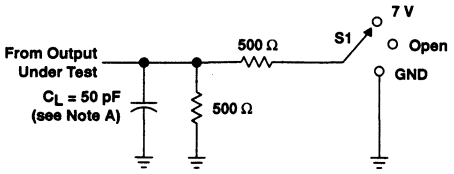
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT657A		SN74ABT657A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±20		±20	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–200	–50	–200	–50	–200	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			250		250		250	µA
			Outputs low			40		40		40	mA
			Outputs disabled			250		250		250	µA
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.25		0.25		0.25	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			10						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

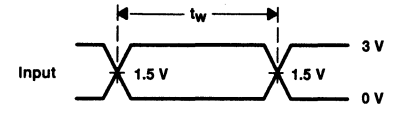
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT657A		SN74ABT657A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	3.2	4.2	1	5	1	4.6	ns
t_{PHL}			1	2.8	3.8	1	4.5	1	4.3	
t_{PLH}	A	PARITY	1.8	4.8	6.3	1.8	8.5	1.8	8.1	ns
t_{PHL}			2.3	4.9	6.4	2.3	8.1	2.3	7.7	
t_{PLH}	ODD/$\overline{EVEN}$	PARITY, $\overline{ERR}$	1.1	3.3	4.2	1.1	5.3	1.1	4.9	ns
t_{PHL}			1.3	3.4	4.5	1.3	5.1	1.3	4.9	
t_{PLH}	B	$\overline{ERR}$	1.6	4.7	6.5	1.6	8.4	1.6	7.9	ns
t_{PHL}			2.1	4.9	6.9	2.1	8	2.1	7.8	
t_{PLH}	PARITY	$\overline{ERR}$	2	4.8	6.3	2	8.1	2	7.7	ns
t_{PHL}			2.1	4.9	6.7	2.1	8	2.1	7.5	
t_{PZH}	$\overline{OE}$	A, B, PARITY	1.4	4	5.4	1.4	6.8	1.4	6.5	ns
t_{PZL}			1.7	4.1	5.8	1.7	6.7	1.7	6.5	
t_{PZH}	$\overline{OE}$	$\overline{ERR}$	1.8	4.1	5.4	1.8	6.9	1.8	6.6	ns
t_{PZL}			3.3	6.2	7.6	3.3	9.7	3.3	9.2	
t_{PHZ}	$\overline{OE}$	A, B, PARITY, or $\overline{ERR}$	2.4	4.2	5.6	2.4	6.3	2.4	6.2	ns
t_{PLZ}			1.8	4.2	6.2	1.8	8.9	1.8	7.8	

PARAMETER MEASUREMENT INFORMATION

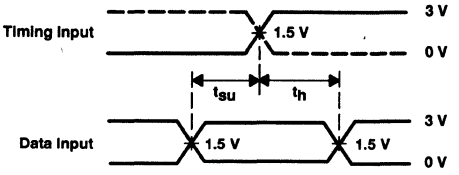


LOAD CIRCUIT

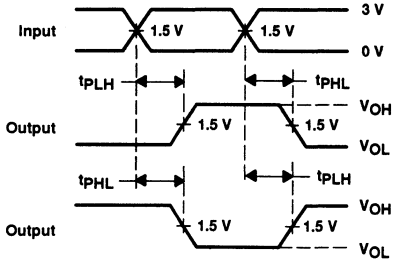
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



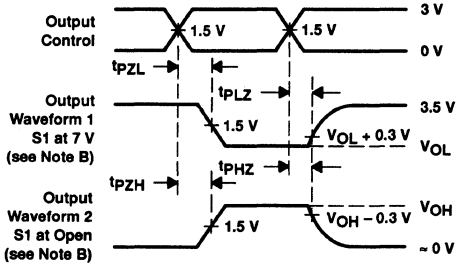
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



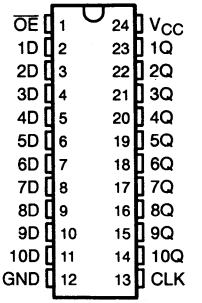
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

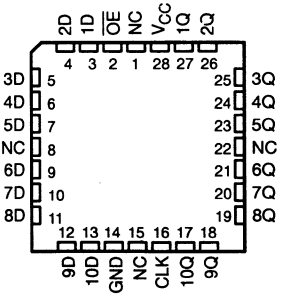
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT821 . . . JT OR W PACKAGE
SN74ABT821A . . . DB, DW, OR NT PACKAGE
(TOP VIEW)



SN54ABT821 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

These 10-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

The ten flip-flops are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the devices provide true data at the Q outputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the ten outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latch. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT821 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT821A is characterized for operation from –40°C to 85°C.

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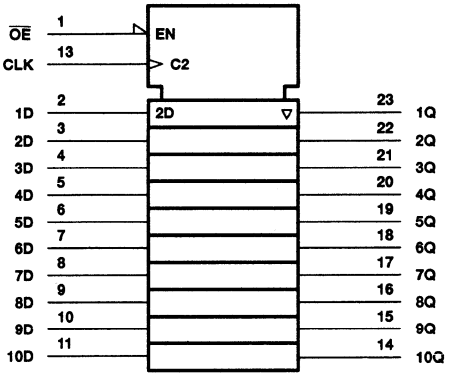
FUNCTION TABLE
(each flip-flop)

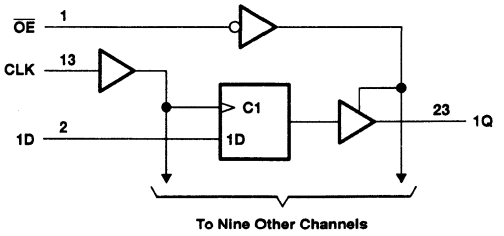
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT821 ..... 96 mA
SN74ABT821A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
NT package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT821		SN74ABT821A		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT821		SN74ABT821A		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
		I_{OH} = –32 mA	2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
		I_{OL} = 64 mA			0.55*				0.55	
V_{hys}				100						mV
I_I	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZPU}‡	V_{CC} = 0 to 2.1 V, V_O = 0.5 to 2.7 V, $\overline{OE}$ = X				±50*				±50	µA
I_{OZPD}‡	V_{CC} = 2.1 V to 0, V_O = 0.5 to 2.7 V, $\overline{OE}$ = X				±50*				±50	µA
I_{OZH}	V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}	V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
		Outputs low		24	38		38		38	mA
		Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V			3.5						pF
C_o	V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C		SN54ABT821		SN74ABT821A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	125	0	125	0	125	MHz
t_w	Pulse duration, CLK high or low	High	2.9		2.9		2.9		ns
		Low	3.8		3.8		3.8		
t_{su}	Setup time, data before CLK↑		2.1		2.1		2.1		ns
t_h	Hold time, data after CLK↑		1.3		1.3		1.3		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT821					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125			125		MHz
t_{PLH}	CLK	Q	1.6†	4.1	5.6	1.6†	6.9	ns
t_{PHL}			2.1†	4.6	6.2	2.1†	6.9	
t_{PZH}	$\overline{OE}$	Q	1	3	4.5	1	6	ns
t_{PZL}			2.2	4.1	5.6	2.2	6.5	
t_{PHZ}	$\overline{OE}$	Q	2.7	4.7	6.2	2.7	7	ns
t_{PLZ}			1.7†	4.6	6.1	1.7†	7	

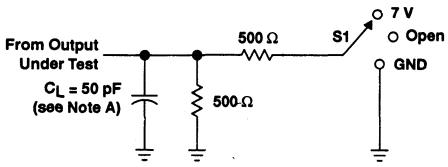
† This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT821A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125			125		MHz
t_{PLH}	CLK	Q	1.6†	4.1	5.6	1.6†	6.2	ns
t_{PHL}			2.3†	4.6	6.2	2.3†	6.7	
t_{PZH}	$\overline{OE}$	Q	1	3	4.5	1	5.8	ns
t_{PZL}			2.2	4.1	5.6	2.2	6.3	
t_{PHZ}	$\overline{OE}$	Q	2.7	4.7	6.2	2.7	6.7	ns
t_{PLZ}			1.7†	4.6	6.1	1.7†	6.5	

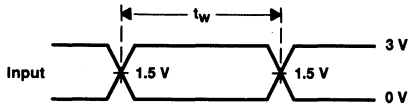
† This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

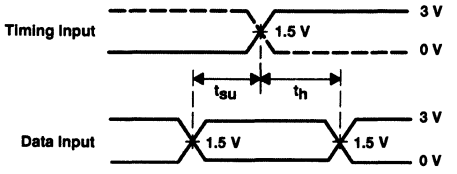


LOAD CIRCUIT

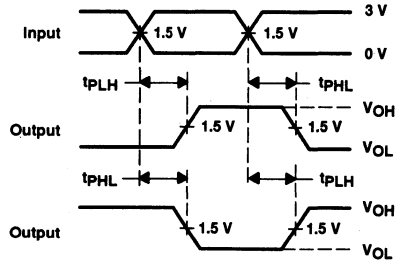
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



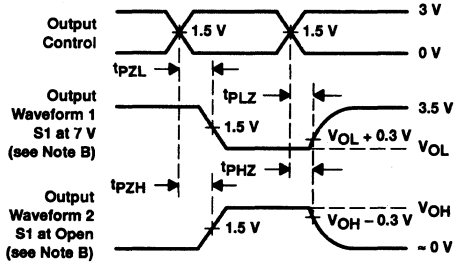
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



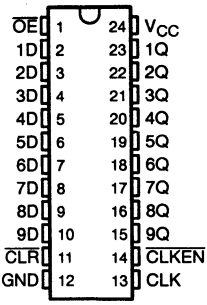
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

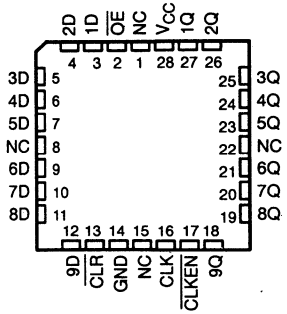
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Buffered Control Inputs to Reduce dc Loading Effects**
- **Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT823 . . . JT OR W PACKAGE
SN74ABT823 . . . DB, DW, OR NT PACKAGE
(TOP VIEW)



SN54ABT823 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

These 9-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

With the clock-enable ($\overline{CLKEN}$) input low, the nine D-type edge-triggered flip-flops enter data on the low-to-high transitions of the clock. Taking $\overline{CLKEN}$ high disables the clock buffer, thus latching the outputs. Taking the clear ($\overline{CLR}$) input low causes the nine Q outputs to go low, independently of the clock.

A buffered output-enable ($\overline{OE}$) input can be used to place the nine outputs in either a normal logic state (high or low logic level) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

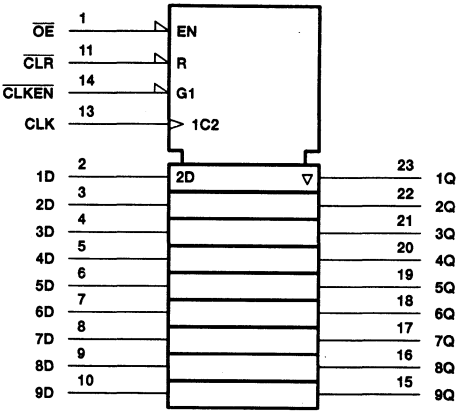
The SN54ABT823 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT823 is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE
(each flip-flop)

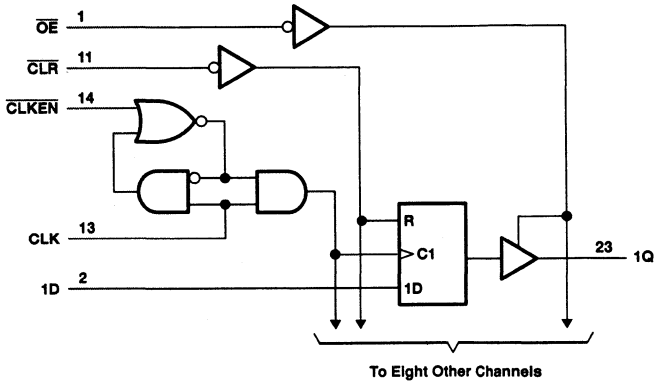
INPUTS					OUTPUT
$\overline{OE}$	$\overline{CLR}$	$\overline{CLKEN}$	CLK	D	Q
L	L	X	X	X	L
L	H	L	↑	H	H
L	H	L	↑	L	L
L	H	H	X	X	Q_0
H	X	X	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT823 ..... 96 mA
SN74ABT823 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
NT package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "recommended operating conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT823		SN74ABT823		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT823		SN74ABT823		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
		I_{OH} = –32 mA	2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
		I_{OL} = 64 mA			0.55*				0.55	
V_{hys}				100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	μA
I_{OZPU}‡	V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	μA
I_{OZPD}‡	V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	μA
I_{OZH}	V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10§		10§		10§	μA
I_{OZL}	V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10§		–10§		–10§	μA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	μA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	μA
I_O¶	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–140	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	μA
		Outputs low		24	38		38		38	mA
		Outputs disabled		0.5	250		250		250	μA
ΔI_{CC}#	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V			4						pF
C_o	V_O = 2.5 V or 0.5 V			7						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ This data sheet limit may vary among suppliers.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

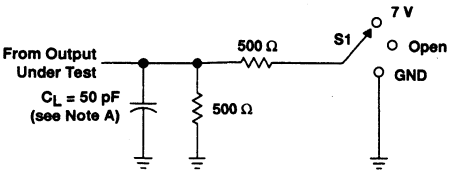
			V_{CC} = 5 V, T_A = 25°C		SN54ABT823		SN74ABT823		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	125	0	125	0	125	MHz
t_w	Pulse duration	$\overline{CLR}$ low	5.5		5.5		5.5		ns
		CLK high	2.9		2.9		2.9		
		CLK low	3.8		3.8		3.8		
t_{su}	Setup time before CLK↑	$\overline{CLR}$ inactive	2.5		2.5		2.5		ns
		Data	2.1		2.1		2.1		
		$\overline{CLKEN}$ high	2		2		2		
		$\overline{CLKEN}$ low	3.3		3.3		3.3		
t_h	Hold time after CLK↑	Data	1.3		1.3		1.3		ns
		$\overline{CLKEN}$ high	1		1		1		
		$\overline{CLKEN}$ low	2		2		2		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT823		SN74ABT823		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			125	200		125		125		MHz
t_{PLH}	CLK	Q	2.1	4.3	5.9	2.1	8.1	2.1	6.8	ns
t_{PHL}			2.2	4.4	6.1	2.2	7	2.2	6.7	
t_{PHL}	$\overline{CLR}$	Q	2	4.1	6.3	2	7.3	2	7.1	ns
t_{PZH}	$\overline{OE}$	Q	1	3	4.7†	1	6.3	1	6†	ns
t_{PZL}			2.2	4.1	5.6	2.2	6.6	2.2	6.5†	
t_{PHZ}	$\overline{OE}$	Q	2.7	4.8	6.5†	2.7	7.7	2.7	7.5†	ns
t_{PLZ}			1.9	5	6.4	1.9	7.4	1.9	6.9	

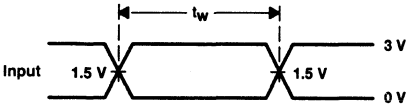
† This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

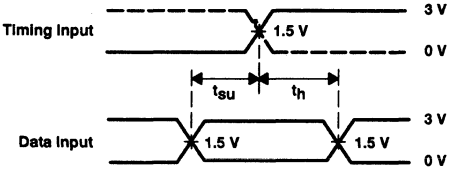


LOAD CIRCUIT

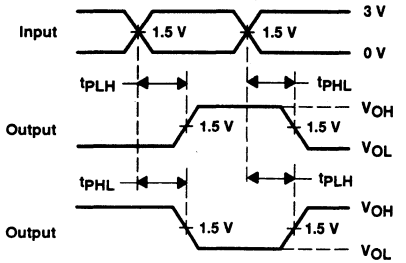
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



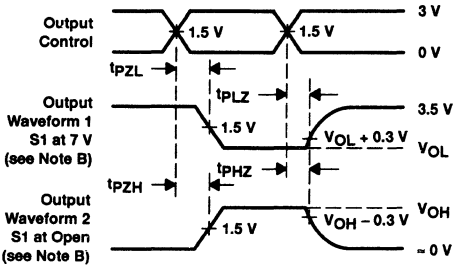
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



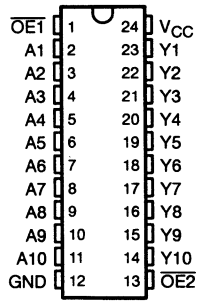
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

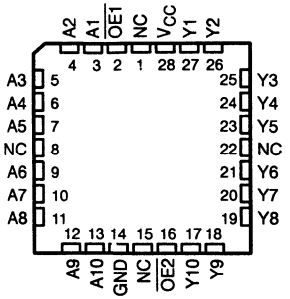
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT827 . . . JT PACKAGE
SN74ABT827 . . . DB, DW, NT, OR PW PACKAGE
(TOP VIEW)



SN54ABT827 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

These 10-bit buffers or bus drivers provide a high-performance bus interface for wide data paths or buses carrying parity.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all ten outputs are in the high-impedance state. The 'ABT827 provide true data at the outputs.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT827 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT827 is characterized for operation from –40°C to 85°C.

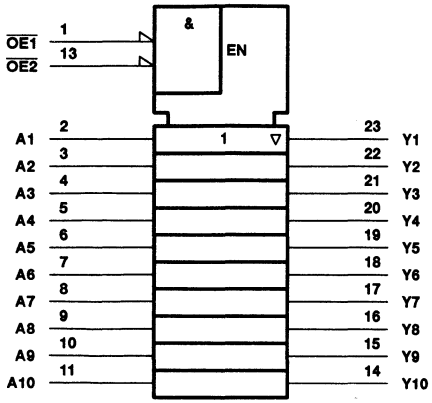
FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

EPIC-IIB is a trademark of Texas Instruments Incorporated.

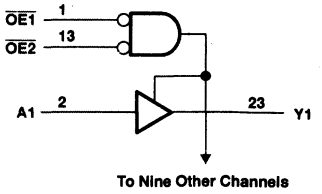
TEXAS INSTRUMENTS

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, and PW packages.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT827 ..... 96 mA
SN74ABT827 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
NT package ..... 67°C/W
PW package ..... 120°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT827		SN74ABT827		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT827		SN74ABT827		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = −18 mA			−1.2		−1.2		−1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = −3 mA	2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = −3 mA	3			3		3		
	V_{CC} = 4.5 V	I_{OH} = −24 mA	2			2				
		I_{OH} = −32 mA	2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
		I_{OL} = 64 mA			0.55*				0.55	
V_{hys}				100						mV
I_I	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZPU}‡	V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±10		±50	µA
I_{OZPD}‡	V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±10		±50	µA
I_{OZH}	V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10§		10		10§	µA
I_{OZL}	V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				−10§		−10		−10§	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶	V_{CC} = 5.5 V,	V_O = 2.5 V	−50	−140	−225§	−50	−225§	−50	−225§	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		80	250		250		250	µA
		Outputs low		35	40§		40§		40§	mA
		Outputs disabled		80	250		250		250	µA
ΔI_{CC}#	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
		Outputs disabled			50		50		50	µA
		Control inputs			1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V			4						pF
C_o	V_O = 2.5 V or 0.5 V			8						pF

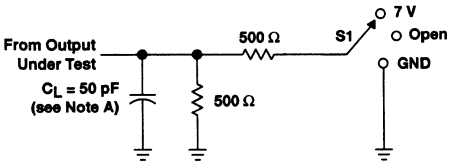
* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ This data sheet limit may vary among suppliers.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT827		SN74ABT827		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.1	2.6	4.4	1.1	4.9	1.1	4.8	ns
t_{PHL}			1.1	2.3	4.1	1.1	4.8	1.1	4.7	
t_{PZH}	$\overline{OE}$	Y	1§	3.2	5.1	1	6	1§	5.9	ns
t_{PZL}			1§	3.3	5.9	1	7.1	1§	6.9	
t_{PHZ}	$\overline{OE}$	Y	2	4.9	6.3	2	7	2	6.8	ns
t_{PLZ}			1.3§	4.2	6.6	1.3	7.9	1.3§	6.9	

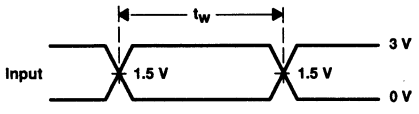
§ This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

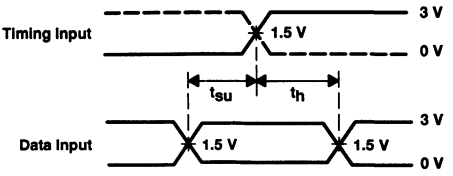


LOAD CIRCUIT

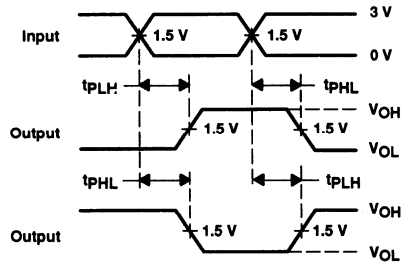
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



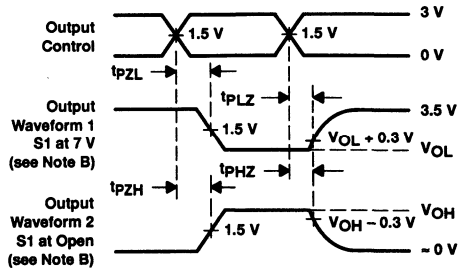
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

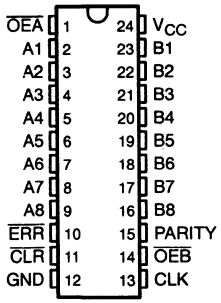
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

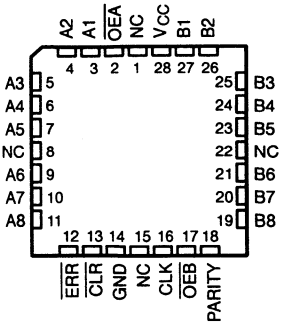
SCBS195C – FEBRUARY 1991 – REVISED JANUARY 1997

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Parity Error Flag With Parity Generator/Checker**
- **Register for Storage of the Parity Error Flag**
- **Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT833 . . . JT PACKAGE
SN74ABT833 . . . DW OR NT PACKAGE
(TOP VIEW)



SN54ABT833 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABT833 8-bit to 9-bit parity transceivers are designed for communication between data buses. When data is transmitted from the A bus to the B bus, a parity bit is generated. When data is transmitted from the B bus to the A bus with its corresponding parity bit, the open-collector parity-error ($\overline{ERR}$) output indicates whether or not an error in the B data has occurred. The output-enable ($\overline{OEA}$ and $\overline{OEB}$) inputs can be used to disable the device so that the buses are effectively isolated. The 'ABT833 provide true data at their outputs.

A 9-bit parity generator/checker generates a parity-odd (PARITY) output and monitors the parity of the I/O ports with the $\overline{ERR}$ flag. $\overline{ERR}$ is clocked into the register on the rising edge of the clock (CLK) input. The error flag register is cleared with a low pulse on the clear ($\overline{CLR}$) input. When both $\overline{OEA}$ and $\overline{OEB}$ are low, data is transferred from the A bus to the B bus and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

description (continued)

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

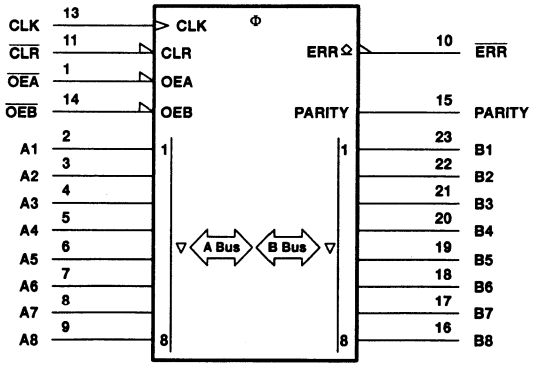
The SN54ABT833 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT833 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS						OUTPUT AND I/O				FUNCTION
$\overline{OEB}$	$\overline{OEA}$	$\overline{CLR}$	CLK	AI Σ OF H's	BI† Σ OF H's	A	B	PARITY	$\overline{ERR}$‡	
L	H	X	X	Odd	NA	NA	A	L	NA	A data to B bus and generate parity
				Even				H		
H	L	H	↑	NA	Odd	B	NA	NA	H	B data to A bus and check parity
					Even				L	
X	X	L	X	X	X	X	NA	NA	H	Check error-flag register
H	H	H	No↑	X	X	Z	Z	Z	NC	Isolation§
		L	No↑	X					H	
		H	↑	Odd					H	
		H	↑	Even					L	
L	L	X	X	Odd	NA	NA	A	H	NA	A data to B bus and generate inverted parity
				Even				L		

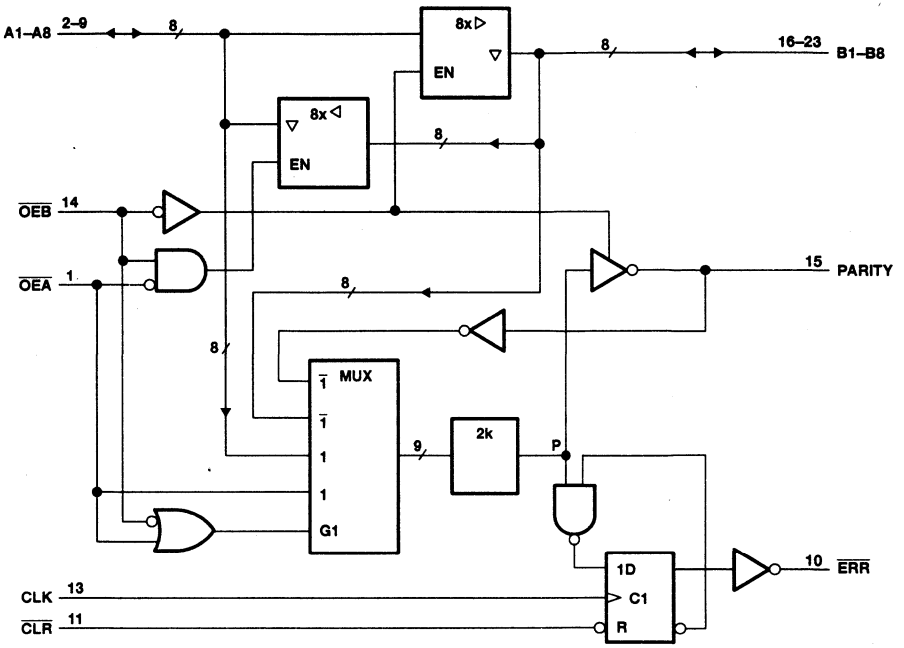
NA = not applicable, NC = no change, X = don't care
† Summation of high-level inputs includes PARITY along with Bi inputs.
‡ Output states shown assume $\overline{ERR}$ was previously high.
§ In this mode, $\overline{ERR}$ (when clocked) shows inverted parity of the A bus.

logic symbol¶



¶ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW, JT, and NT packages.

logic diagram (positive logic)



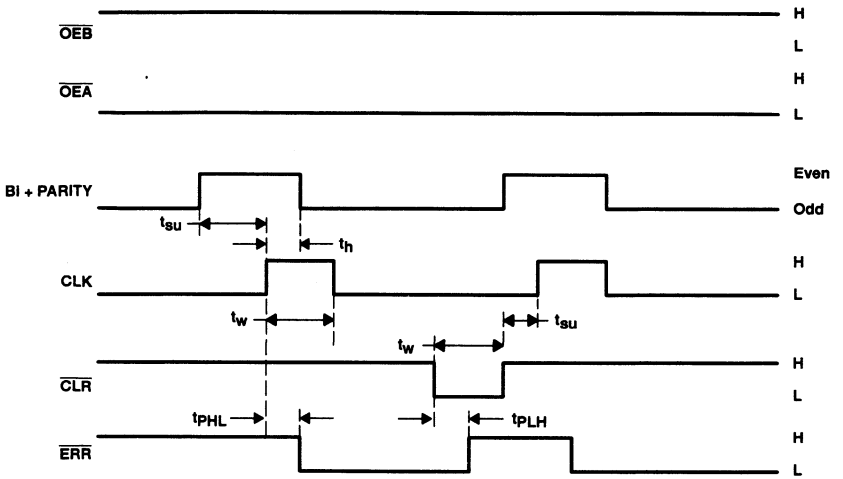
Pin numbers shown are for the DW, JT, and NT packages.

ERROR-FLAG FUNCTION TABLE

INPUTS		INTERNAL TO DEVICE	OUTPUT PRE-STATE	OUTPUT	FUNCTION
$\overline{CLR}$	CLK	POINT P	$\overline{ERR}_{n-1}$†	$\overline{ERR}$	
H	↑	H	H	H	Sample
H	↑	X	L	L	
H	↑	L	X	L	
L	X	X	X	H	Clear

† The state of $\overline{ERR}$ before any changes at $\overline{CLR}$, CLK, or point P

error-flag waveforms



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT833 ..... 96 mA
SN74ABT833 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package ..... 81°C/W
NT package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT833		SN74ABT833		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_{OH}	High-level output voltage	$\overline{ERR}$		5.5		5.5	V
I_{OH}	High-level output current	Except $\overline{ERR}$		–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT833		SN74ABT833		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	All outputs except $\overline{ERR}$	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 24 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_{OH}	$\overline{ERR}$	V_{CC} = 4.5 V,	V_{OH} = 5.5 V			20		20		20	µA
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{IL}	A or B ports	V_{CC} = 0,	V_I = GND			–50		–50		–50	µA
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–200¶	–50	–200¶	–50	–200¶	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	38¶		38¶		38¶	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			50		50		50	µA
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4.5						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			10.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ These limits may vary among suppliers.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

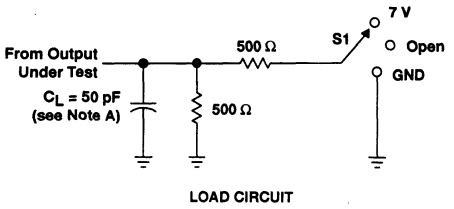
			V_{CC} = 5 V, T_A = 25°C		SN54ABT833		SN74ABT833		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	CLK high or low	3		3		3		ns
		$\overline{CLR}$ low	3		3		3		
t_{su}	Setup time before CLK↑	B or PARITY high	9.8		9.8		9.8		ns
		B or PARITY low	8.1		8.1		8.1		
		$\overline{CLR}$	2		2		2		
t_h	Hold time after CLK↑	B or PARITY	0		0		0		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT833		SN74ABT833		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.2	2.8	4.8	1.2	5.4	1.2	5.3	ns
t_{PHL}			1	3	4.8‡	1	5.4	1	5.3‡	
t_{PLH}	A	PARITY	2.1	5.5	9.5	2.1	11.3	2.1	11.2	ns
t_{PHL}			2.5	5.3	9.7	2.5	10.1	2.5	11	
t_{PZH}	$\overline{OE}$	PARITY	2.6	6.2	8.5	2.6	10.6	2.6	10.5	ns
t_{PZL}			2.6‡	5.8	8.6	2.6‡	10.1	2.6‡	10	
t_{PLH}	$\overline{CLR}$	$\overline{ERR}$	1	3.2	4.8‡	1	5.3	1	5.2	ns
t_{PHL}	CLK		1.2‡	2.8	5.7	1.2‡	6.3	1.2‡	6.2	
t_{PZH}	$\overline{OE}$	A, B, or PARITY	1	3.7	5.8‡	1	6.6	1	6.5‡	ns
t_{PZL}			1.3‡	3.8	5.8	1.3‡	6.6	1.3‡	6.5‡	
t_{PHZ}	$\overline{OE}$	A, B, or PARITY	1.9‡	4.4	7.3	1.9‡	8	1.9‡	7.9	ns
t_{PLZ}			2.2‡	4.4	7.7	2.2‡	8.2	2.2‡	8.1	

† All typical values are at V_{CC} = 5 V.
‡ These limits may vary among suppliers.

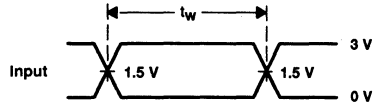
PARAMETER MEASUREMENT INFORMATION



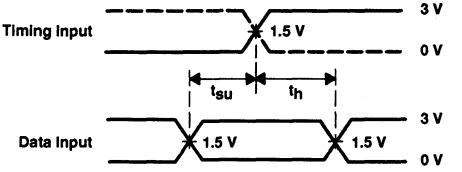
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

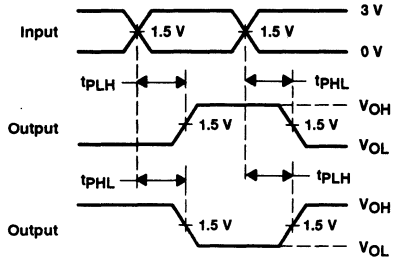
$\overline{ERR}$	S1
t_{PHL}	7 V
t_{PLH}	7 V



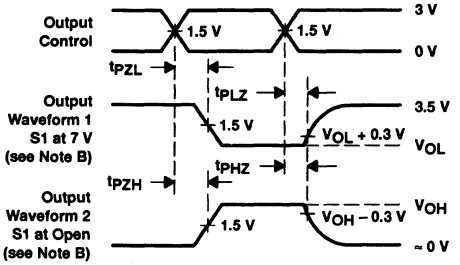
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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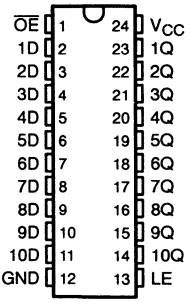
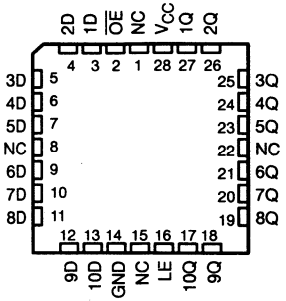
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT841 . . . JT OR W PACKAGE
SN74ABT841A . . . DB, DW, NT, OR PW PACKAGE
(TOP VIEW)



SN54ABT841 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The SN54ABT841 and SN74ABT841A 10-bit latches are designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The ten transparent D-type latches provide true data at their outputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the ten outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latch. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

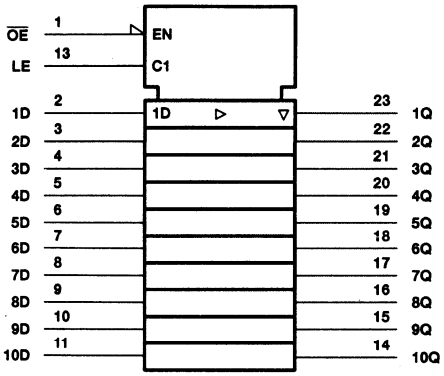
The SN54ABT841 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT841A is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE

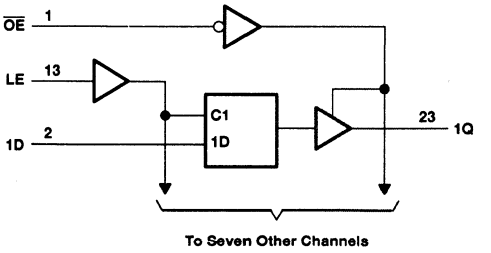
INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT841 ..... 96 mA
SN74ABT841A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
NT package ..... 67°C/W
PW package ..... 120°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT841		SN74ABT841A		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT841		SN74ABT841A		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
		I_{OH} = –32 mA	2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
		I_{OL} = 64 mA			0.55*				0.55	
V_{hys}				100						mV
I_I	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZPU}‡	V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡	V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}	V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}	V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–140	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1**	250**		280		250	µA
		Outputs low		24**	38¶**		45¶		38¶	mA
		Outputs disabled		0.5**	250**		280		250	µA
ΔI_{CC}#	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
		Outputs disabled			250**		280		250	µA
		Control inputs			1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V			4						pF
C_o	V_O = 2.5 V or 0.5 V			7						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
** These limits apply only to the SN74ABT841A.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This limit may vary among suppliers.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C		SN54ABT841		SN74ABT841A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high or low		3.3		3.3		3.3		ns
t_{su}	Setup time, data before LE↓	High	2.5		2.5		2.5		ns
		Low	1.5		1.5		1.5		
t_h	Hold time, data after LE↓	High	1.5		1.5		1.5		ns
		Low	1.5		2		1.5		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT841					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	Q	1†	4.1	5.5	1†	6.8	ns
t_{PHL}			1.5†	4	5.5	1.5†	6.8	
t_{PLH}	LE	Q	1.6†	4.1	6.6†	1.6†	7.4	ns
t_{PHL}			2†	4.6	6.2	2†	6.8	
t_{PZH}	$\overline{OE}$	Q	1	3	4.9†	1	5.8	ns
t_{PZL}			2.2	4.1	5.7†	2.2	6.5	
t_{PHZ}	$\overline{OE}$	Q	2†	4.7	6.2	2†	7.2	ns
t_{PLZ}			1.5†	4.6	6.1	1.5†	6.6	

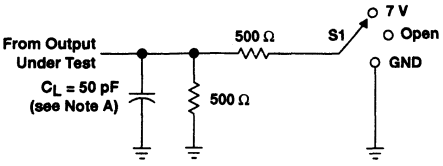
† This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT841A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	Q	1.4†	4.1	5.5	1.4†	6.2†	ns
t_{PHL}			1.5†	4	5.5	1.5†	6.2	
t_{PLH}	LE	Q	2.1†	4.1	5.9†	2.1†	6.5†	ns
t_{PHL}			2.4†	4.6	6.2	2.4†	6.7	
t_{PZH}	$\overline{OE}$	Q	1	3	4.7†	1	5.3†	ns
t_{PZL}			2.2	4.1	5.7†	2.2	6.3†	
t_{PHZ}	$\overline{OE}$	Q	2.6†	4.7	6.2	2.6†	7.1	ns
t_{PLZ}			1.9†	4.6	6.1	1.9†	6.5	

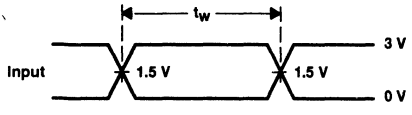
† This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

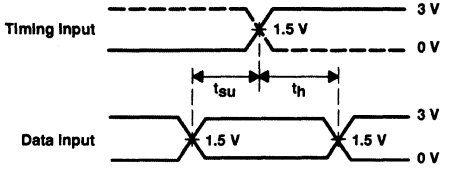


LOAD CIRCUIT

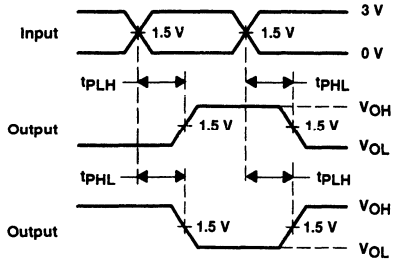
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



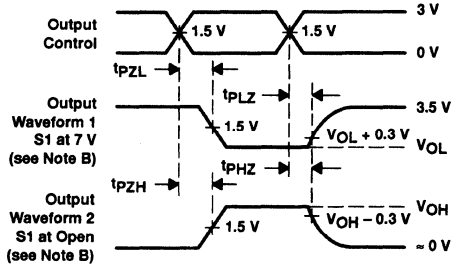
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



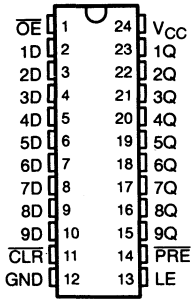
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

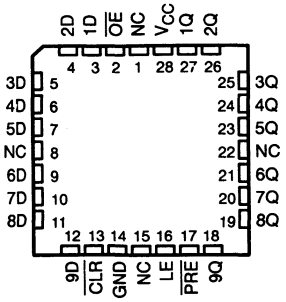
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT843 . . . JT OR W PACKAGE
SN74ABT843 . . . DB, DW, OR NT PACKAGE
(TOP VIEW)



SN54ABT843 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABT843 9-bit latches are designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The nine transparent D-type latches provide true data at the outputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the nine outputs in either a normal logic state (high or low logic levels) or a high-impedance state. The outputs are also in the high-impedance state during power-up and power-down conditions. The outputs remain in the high-impedance state while the device is powered down. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latch. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

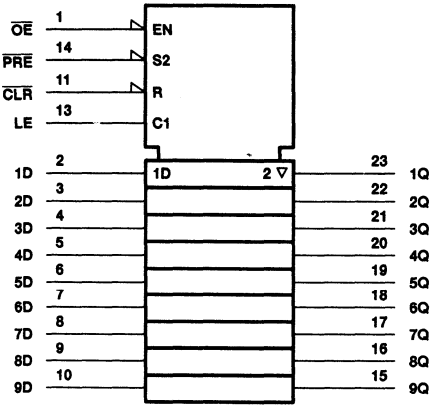
The SN54ABT843 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT843 is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE

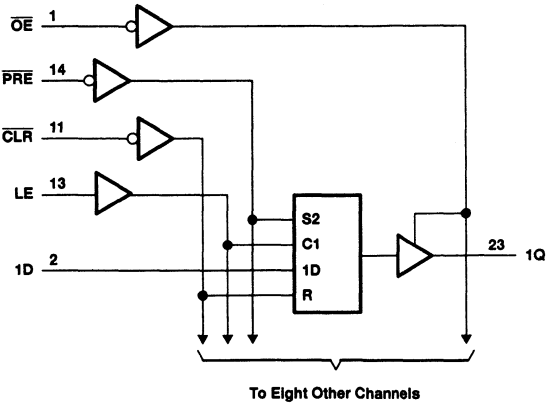
INPUTS					OUTPUT
$\overline{PRE}$	$\overline{CLR}$	$\overline{OE}$	LE	D	Q
L	X	L	X	X	H
H	L	L	X	X	L
H	H	L	H	L	L
H	H	L	H	H	H
H	H	L	L	X	Q_0
X	X	H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT843 ..... 96 mA
SN74ABT843 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
NT package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "recommended operating conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT843		SN74ABT843		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT843		SN74ABT843		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA		3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA					2				
		I_{OH} = –32 mA		2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA						0.55			V
		I_{OL} = 64 mA				0.55*				0.55	
V_{hys}					100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZH}‡	V_{CC} = 5.5 V,	V_O = 2.7 V				10		10		10	µA
I_{OZL}‡	V_{CC} = 5.5 V,	V_O = 0.5 V				–10		–10		–10	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–140	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = Open, V_I = V_{CC} or GND		Outputs high		1	250		250		250	µA
			Outputs low		24	34		34		34	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V				4						pF
C_o	V_O = 2.5 V or 0.5 V				7						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figures 1 and 2)

				V_{CC} = 5 V, T_A = 25°C		SN54ABT843		SN74ABT843		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{CLR}$ low		5.5		5.5		5.5		ns
		$\overline{PRE}$ low		4.5		4.5		4.5		
		LE low		3.3		3.3		3.4		
t_{su}	Setup time	Data before LE↓	Low	2.5		2.5		2.5		ns
			High	3		3		3		
		$\overline{PRE}$ inactive		1.6		1.6		1.6		
		$\overline{CLR}$ inactive		2		2		2		
t_h	Hold time, data after LE↓	High		1		1		1		ns
		Low		1.5†		2.3†		1.5†		

† This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT843		SN74ABT843		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	1.2†	3.8	5.2	1.2†	7.8	1.2†	6.7†	ns
t_{PHL}			1.5†	3.4	6.3	1.5†	7.3	1.5†	7.2	
t_{PLH}	LE	Q	1.7†	4.4	5.6	1.7†	8.3	1.7†	7.2†	ns
t_{PHL}			1.9†	4.1	6.3	1.3†	7.2	1.9†	6.9	
t_{PLH}	$\overline{PRE}$	Q	2.2	5	6.2	2.2	8.3	2.2	7.4	ns
t_{PHL}			2.1†	4.1	6.5	2.1†	7.5	2.1†	7.2	
t_{PLH}	$\overline{CLR}$	Q	2†	4.4	6.3	2†	7.6	2†	7.1	ns
t_{PHL}			1.9†	4.5	6.8	1.9†	8.1	1.9†	8	
t_{PZH}	$\overline{OE}$	Q	1	3.4	4.5†	1	6.4	1	5.7†	ns
t_{PZL}			2	4.3	5.7†	2	6.6	2	6.5	
t_{PHZ}	$\overline{OE}$	Q	2.4†	4.9	6.2	2.4†	7.3	2.4†	6.8	ns
t_{PLZ}			1.5†	4.2	6.3	1.5†	7	1.5†	5.9†	

† This data sheet limit may vary among suppliers.

recovery-time waveform

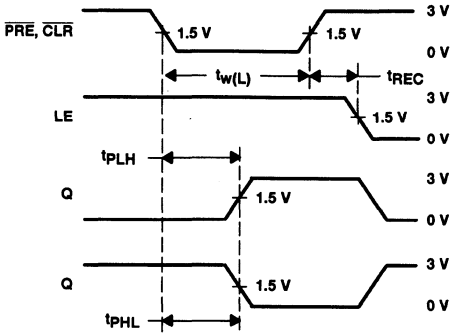
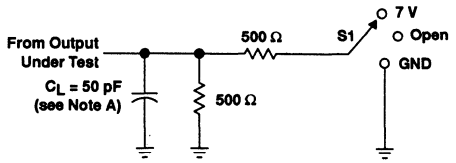


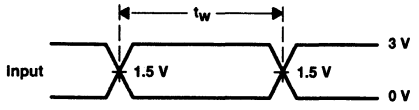
Figure 1. $\overline{\text{CLR}}$ and $\overline{\text{PRE}}$ Pulse Duration, $\overline{\text{CLR}}$ and $\overline{\text{PRE}}$ to Output Delay, and $\overline{\text{CLR}}$ and $\overline{\text{PRE}}$ to Latch-Enable Recovery Time

PARAMETER MEASUREMENT INFORMATION

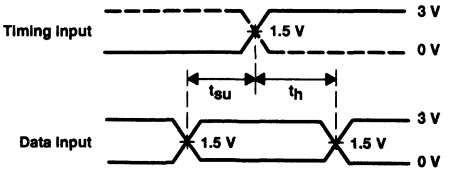


LOAD CIRCUIT

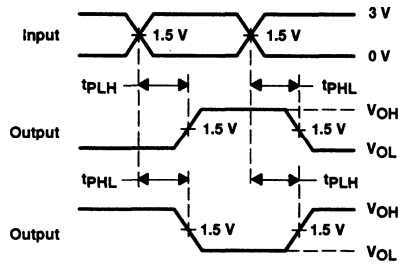
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



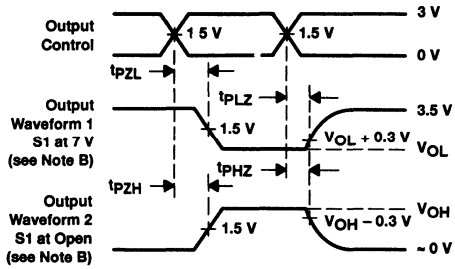
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

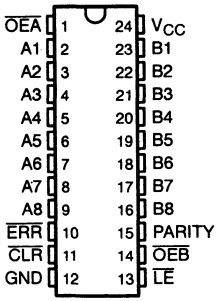
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

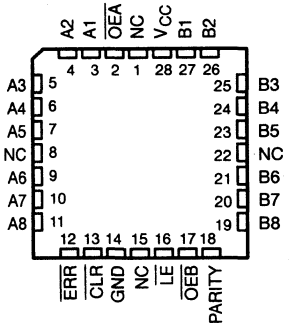
SCBS198E – FEBRUARY 1991 – REVISED MAY 1997

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **High-Impedance State During Power Up and Power Down**
- **Parity-Error Flag With Parity Generator/Checker**
- **Latch for Storage of Parity-Error Flag**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT853 . . . JT OR W PACKAGE
SN74ABT853 . . . DB, DW, NT, OR PW PACKAGE
(TOP VIEW)



SN54ABT853 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABT853 8-bit to 9-bit parity transceivers are designed for communication between data buses. When data is transmitted from the A bus to the B bus, a parity bit is generated. When data is transmitted from the B bus to the A bus with its corresponding parity bit, the open-collector parity-error ($\overline{ERR}$) output indicates whether or not an error in the B data has occurred. The output-enable ($\overline{OEA}$ and $\overline{OEB}$) inputs can be used to disable the device so that the buses are effectively isolated. The 'ABT853 transceivers provide true data at their outputs.

A 9-bit parity generator/checker generates a parity-odd (PARITY) output and monitors the parity of the I/O ports with the $\overline{ERR}$ flag. The parity-error output can be passed, sampled, stored, or cleared from the latch using the latch-enable ($\overline{LE}$) and clear ($\overline{CLR}$) control inputs. When both $\overline{OEA}$ and $\overline{OEB}$ are low, data is transferred from the A bus to the B bus and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

description (continued)

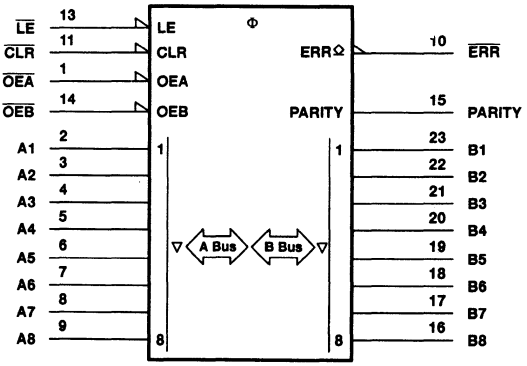
The SN54ABT853 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT853 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS						OUTPUTS AND I/Os				FUNCTION
$\overline{OEB}$	$\overline{OEA}$	$\overline{CLR}$	LE	AI Σ OF H	BI† Σ OF H	A	B	PARITY	$\overline{ERR}$‡	
L	H	X	X	Odd	NA	NA	A	L	NA	A data to B bus and generate parity
				Even				H		
H	L	X	L	NA	Odd	B	NA	NA	H	B data to A bus and check parity
					Even				L	
H	L	H	H	NA	X	X	NA	NA	NC	Store error flag
X	X	L	H	X	X	X	NA	NA	H	Clear error flag register
H	H	H	H	X	X	Z	Z	Z	NC	Isolation§ (parity check)
		L	H	X					H	
		X	L	L Odd					H	
		X	L	H Even					L	
L	L	X	X	Odd	NA	NA	A	H	NA	A data to B bus and generate inverted parity
				Even				L		

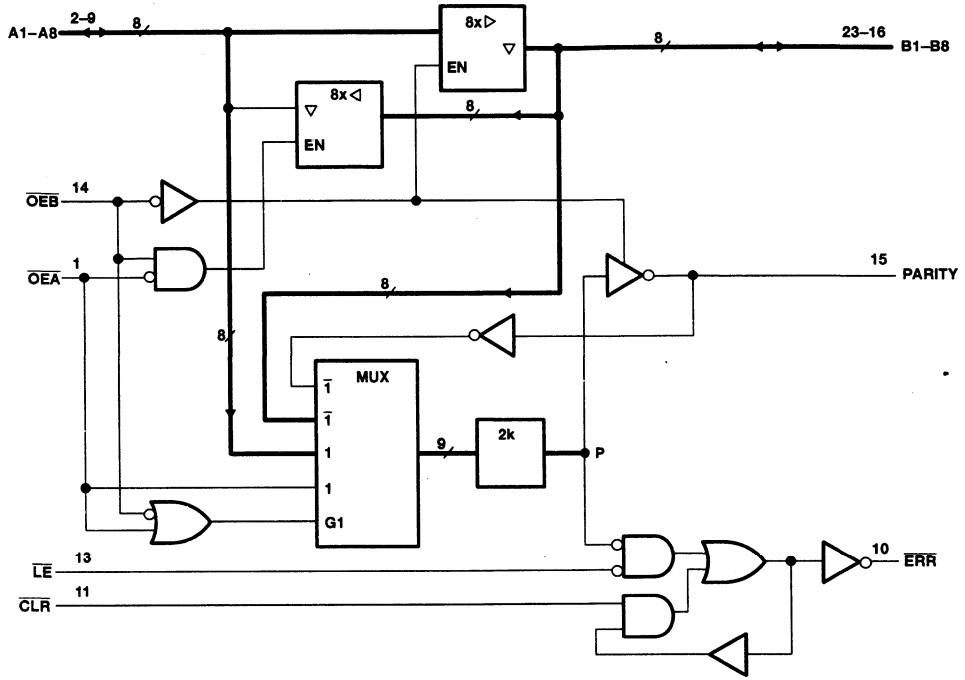
NA = not applicable, NC = no change, X = don't care
† Summation of high-level inputs includes PARITY along with Bi inputs.
‡ Output states shown assume $\overline{ERR}$ was previously high.
§ In this mode, $\overline{ERR}$ (when clocked) shows inverted parity of the A bus.

logic symbol¶



¶ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

logic diagram (positive logic)



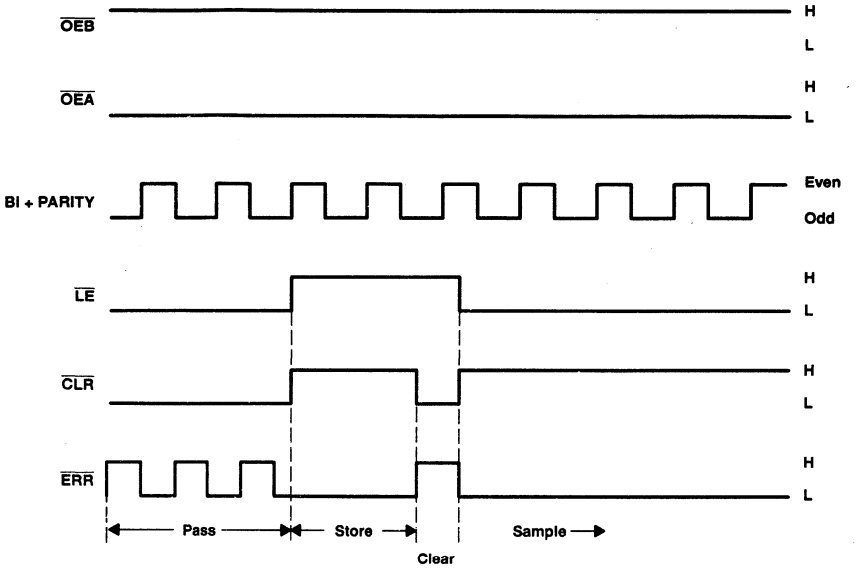
Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

ERROR-FLAG FUNCTION TABLE

INPUTS		INTERNAL TO DEVICE	OUTPUT PRESTATE	OUTPUT	FUNCTION
$\overline{CLR}$	LE	POINT P	$\overline{ERR}_{N-1}$†	$\overline{ERR}$	
L	L	L	X	L	Pass
		H		H	
H	L	L	X	L	Sample
		X	L	L	
		H	H	H	
L	H	X	X	H	Clear
H	H	X	L	L	Store
			H	H	

† The state of $\overline{ERR}$ before changes at $\overline{CLR}$, $\overline{LE}$, or point P

error-flag waveforms



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT853 ..... 96 mA
SN74ABT853 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
N package ..... 67°C/W
PW package ..... 120°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT853		SN74ABT853		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_{OH}	High-level output voltage	$\overline{ERR}$		5.5		5.5	V
I_{OH}	High-level output current	Except $\overline{ERR}$		–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT853		SN74ABT853		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	All outputs except $\overline{ERR}$	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 24 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_{OH}	$\overline{ERR}$	V_{CC} = 4.5 V,	V_{OH} = 5.5 V			50		50		50	µA
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}§		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–200#	–50	–200#	–50	–200#	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		450		250	µA
			Outputs low		24	38		38		38	mA
			Outputs disabled		0.5	250		450		250	µA
ΔI_{CC}‖	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			50		50		50	µA
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4.5						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			10.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This data sheet limit can vary among suppliers.
‖ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 3.3 V, ±0.3 V		SN54ABT853		SN74ABT853		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{LE}$ high or low	3.5		3.5		8.5		ns
		$\overline{CLR}$ low	4		4		4		
t_{su}	Setup time	B or PARITY before $\overline{LE}\downarrow$	9.4†		10.2		9.4†		ns
		$\overline{CLR}$ before $\overline{LE}\downarrow$	2		2		2		
t_h	Hold time	B or PARITY after $\overline{LE}\downarrow$	0		0		0		ns
		$\overline{CLR}$ after $\overline{LE}\downarrow$	3		3		3		

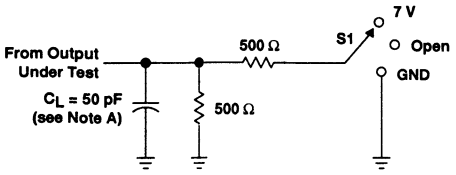
† This data sheet limit can vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT853		SN74ABT853		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.2		4.8	1.2	6.4	1.2	5.3	ns
t_{PHL}			1		4.8†	1	5.4	1	5.3†	
t_{PLH}	A	PARITY	2.1		9.5	2.1	13.3	2.1	11.2	ns
t_{PHL}			2.5		9.7	2.5	11	2.5	11	
t_{PLH}	$\overline{OE}$	PARITY	1.8		8.5	1.8	13.6	1.8	10.5	ns
t_{PHL}			2.3		8.6	2.3	11.7	2.3	10	
t_{PLH}	$\overline{CLR}$	$\overline{ERR}$	1		5.5	1	6.3	1	6.2	ns
t_{PLH}	$\overline{LE}$	ERR	1.8		5.1	1.8	6.1	1.8	6	ns
t_{PHL}			1†		5.8	1†	6.7	1	6.6	
t_{PLH}	B or PARITY	ERR	2		10.1	2	11.8	2	11.7	ns
t_{PHL}			2.2†		11.5	2.2†	12.9	2.2†	12.8	
t_{PZH}	$\overline{OE}$	A or B or PARITY	1		5.8†	1	8.8	1	6.7†	ns
t_{PZL}			1.5†		5.8	1.5†	9.8	1.5†	6.7	
t_{PHZ}	$\overline{OE}$	A or B or PARITY	1.8†		7.3	1.8†	9.5	1.8†	7.9	ns
t_{PLZ}			2.1†		7.2	2.1†	8.2	2.1†	8.1	

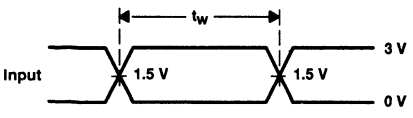
† This data sheet limit can vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

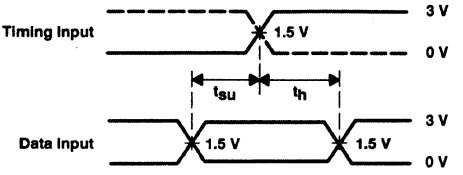


LOAD CIRCUIT

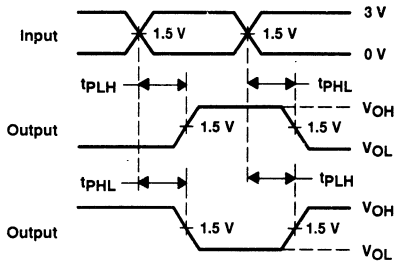
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



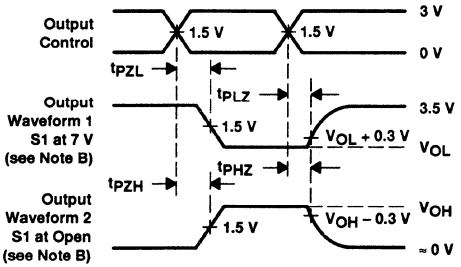
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
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LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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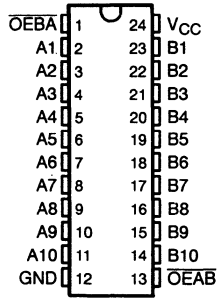
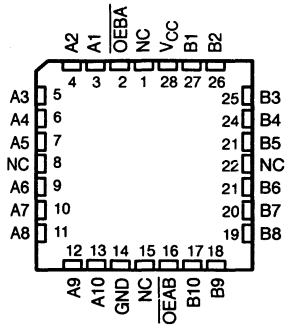
SN54ABT861 . . . JT PACKAGE
SN74ABT861 . . . DW OR NT PACKAGE
(TOP VIEW)



SN54ABT861 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABT861 are 10-bit transceivers designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing.

These devices allow noninverted data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable ($\overline{OEAB}$ and $\overline{OEBA}$) inputs.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

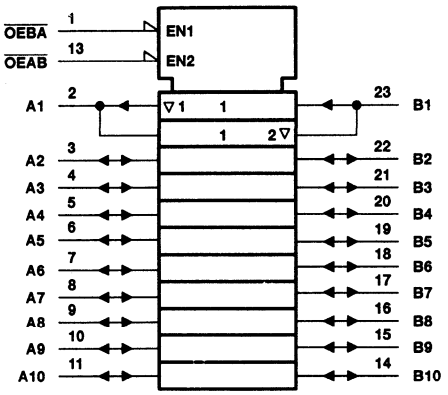
The SN54ABT861 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT861 is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE

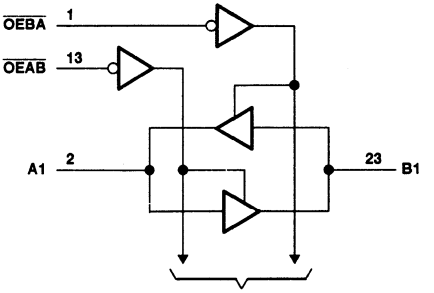
INPUTS		OPERATION
$\overline{OEAB}$	$\overline{OEBA}$	
L	H	A data to B bus
H	L	B data to A bus
H	H	Isolation
L	L	Latch A and B (A = B)

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW, JT, and NT packages.

logic diagram (positive logic)



Pin numbers shown are for the DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT861 ..... 96 mA
SN74ABT861 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package ..... 81°C/W
NT package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT861		SN74ABT861		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT861		SN74ABT861		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}§		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–225#	–50	–225#	–50	–225#	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	38		38		38	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}‖	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			1.5#		1.5#		1.5#	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4.5						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			10.5						pF

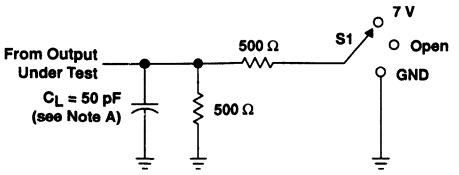
* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This limit may vary among suppliers.
‖ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT861		SN74ABT861		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	3.4	4.9	1	5.3	1	5.2	ns
t_{PHL}			1	3.2	4.4	1	5	1	4.9†	
t_{PZH}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	1	3.5	5	1	6	1	5.9	ns
t_{PZL}			1	4.6	6	1	7	1	6.9	
t_{PHZ}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	2.1	5.3	6.5	2.1	7.6	2.1	7.5	ns
t_{PLZ}			1.5	5.3	6.6	1.5	7.2	1.5	7.1	

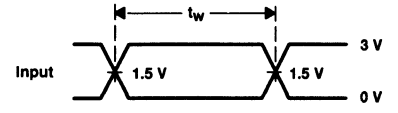
† This limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

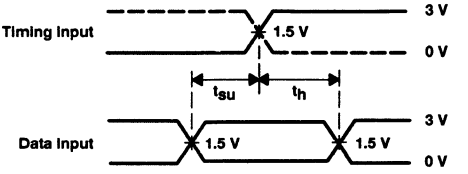


LOAD CIRCUIT

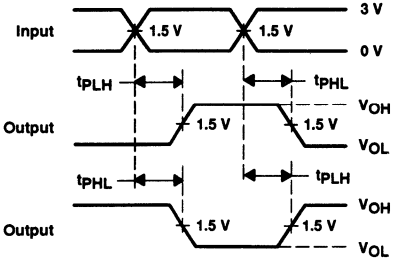
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



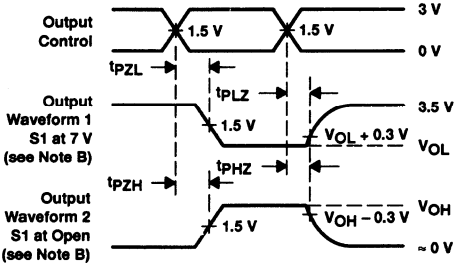
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



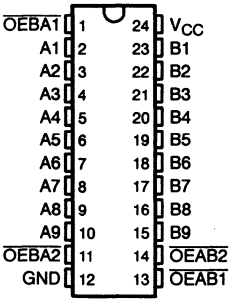
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

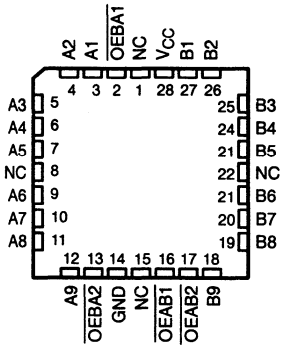
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT863 . . . JT PACKAGE
SN74ABT863 . . . DB, DW, OR NT PACKAGE
(TOP VIEW)



SN54ABT863 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABT863 are 9-bit transceivers designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing.

These devices allow noninverted data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable ($\overline{OEAB}$ and $\overline{OEBA}$) inputs.

The outputs are in the high-impedance state during power up and power down. The outputs remain in the high-impedance state while the device is powered down.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

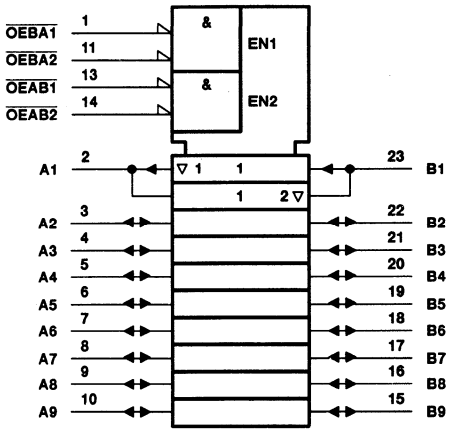
The SN54ABT863 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT863 is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE

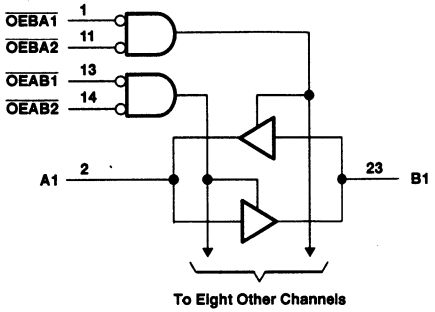
INPUTS				OPERATION
$\overline{OEAB1}$	$\overline{OEAB2}$	$\overline{OEBA1}$	$\overline{OEBA2}$	
L	L	L	L	Latch A and B
L	L	H	X	A to B
L	L	X	H	
H	X	L	L	B to A
X	H	L	L	
H	X	H	X	Isolation
H	X	X	H	
X	H	X	H	
X	H	H	X	

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, and NT packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT863 ..... 96 mA
SN74ABT863 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
NT package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT863		SN74ABT863		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		µs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

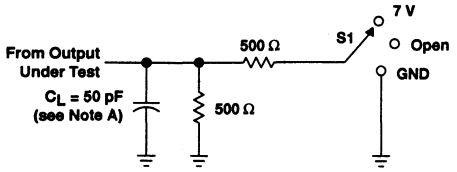
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT863		SN74ABT863		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V,	V_I = V_{CC} or GND			±20		±20		±20	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	30		38		38	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			7						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

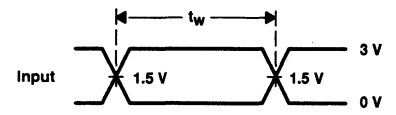
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT863		SN74ABT863		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	2.6	4.1	1	4.7	1	5.7	ns
t_{PHL}			1	2.3	3.3	1	3.9	1	3.9	
t_{PZH}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	1	3.2	4.3	1	5.4	1	5.5	ns
t_{PZL}			1	3.3	4.4	1	5.5	1	5.4	
t_{PHZ}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	2.5	4.8	6	2.5	6.8	2.5	6.7	ns
t_{PLZ}			1.5	4.4	5.9	1.5	7.8	1.5	6.9	

PARAMETER MEASUREMENT INFORMATION

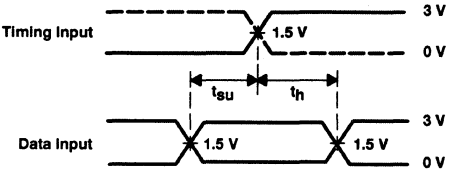


LOAD CIRCUIT

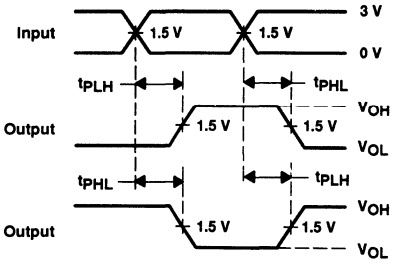
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



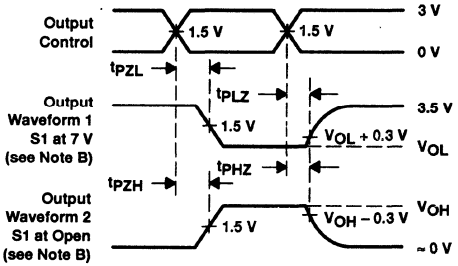
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



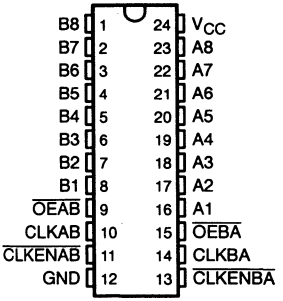
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

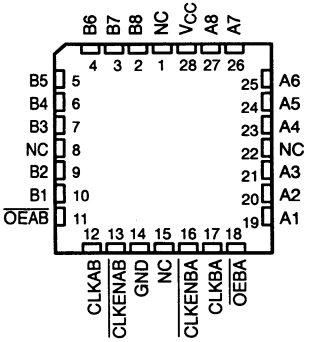
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Two 8-Bit Back-to-Back Registers Store Data Flowing In Both Directions**
- **Noninverting Outputs**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT2952A . . . JT OR W PACKAGE
SN74ABT2952A . . . DB, DW, OR NT PACKAGE
(TOP VIEW)



SN54ABT2952A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABT2952A transceivers consist of two 8-bit back-to-back registers that store data flowing in both directions between two bidirectional buses. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable ($\overline{\text{CLKENAB}}$ or $\overline{\text{CLKENBA}}$) input is low. Taking the output-enable ($\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$) input low accesses the data on either port.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT2952A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT2952A is characterized for operation from –40°C to 85°C.

EPIC is a trademark of Texas Instruments Incorporated.

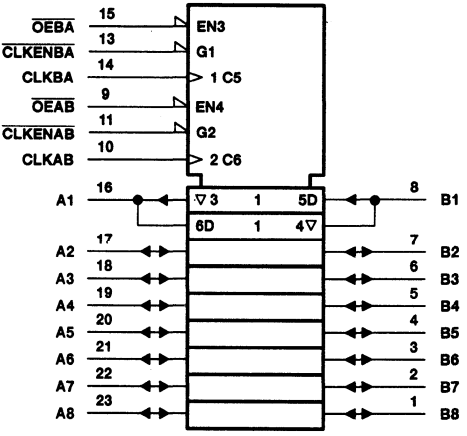
TEXAS INSTRUMENTS

FUNCTION TABLE†

INPUTS				OUTPUT
$\overline{\text{CLKENAB}}$	CLKAB	$\overline{\text{OEAB}}$	A	B
H	X	L	X	B_0‡
X	H or L	L	X	B_0‡
L	↑	L	L	L
L	↑	L	H	H
X	X	H	X	Z

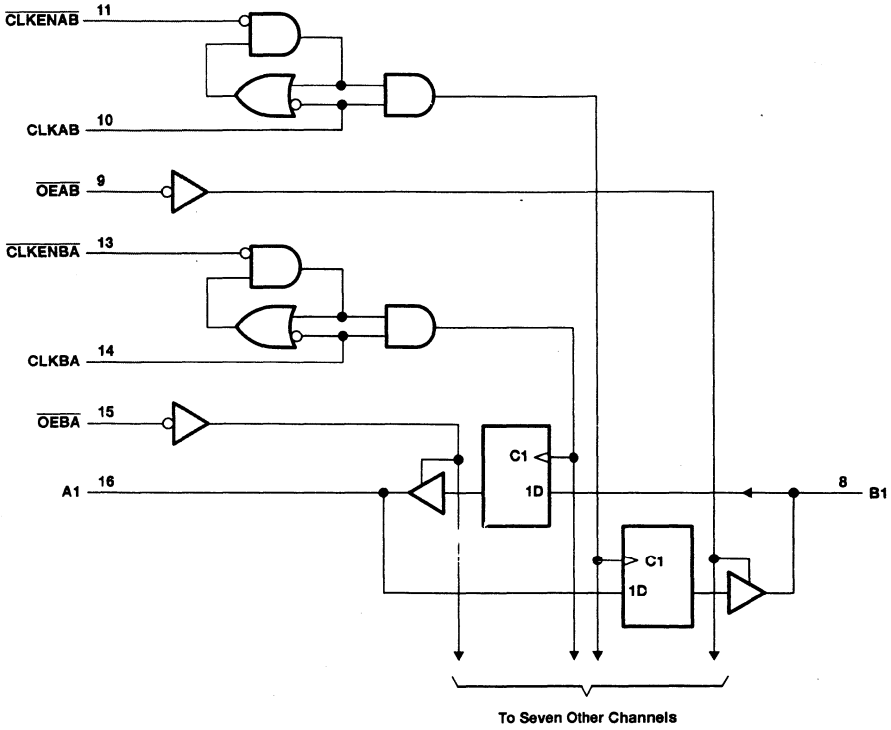
† A-to-B data flow is shown; B-to-A data flow is similar, but uses $\overline{\text{CLKENBA}}$, CLKBA, and $\overline{\text{OEBA}}$.
‡ Level of B before the indicated steady-state input conditions were established

logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT2952A ..... 96 mA
SN74ABT2952A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 104°C/W
DW package ..... 81°C/W
NT package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT2952A		SN74ABT2952A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT2952A		SN74ABT2952A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50**		10		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50**		–10		–50	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	35		35		35	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3.5						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
** These limits apply only to SN74ABT2952A.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

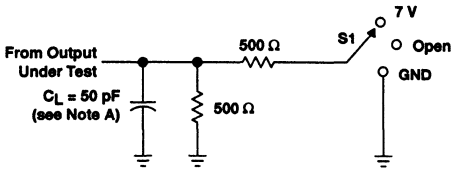
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				V_{CC} = 5 V, T_A = 25°C		SN54ABT2952A		SN74ABT2952A		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			0	150	0	150	0	150	MHz
t_w	Pulse duration, CLK high or low			3.3		3.3		3.3		ns
t_{su}	Setup time before CLK↑	A or B	High or low	2.5		3		2.5		ns
		$\overline{CLKEN}$		3		3		3		
t_h	Hold time after CLK↑	A or B		1.5		1.5		1.5		ns
		$\overline{CLKEN}$		2		2		2		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

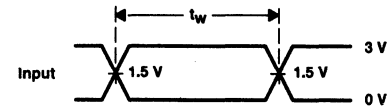
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT2952A		SN74ABT2952A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			150			150		150		MHz
t_{PLH}	CLKAB or CLKBA	B or A	2	3.3	5.2	2	6.3	2	5.9	ns
t_{PHL}			2.5	4	6.1	2.5	6.8	2.5	6.3	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	1.5	3.2	4.7	1.5	5.7	1.5	5.6	ns
t_{PZL}			2	3.7	5.7	2	6.7	2	6.6	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	1.5	3.5	5.1	1.5	6.5	1.5	6.4	ns
t_{PLZ}			1.5	3.4	5.9	1.5	6.7	1.5	6.2	

PARAMETER MEASUREMENT INFORMATION

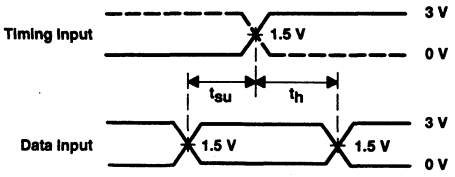


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

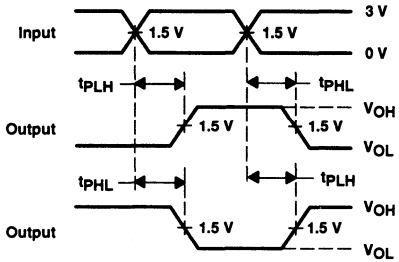
LOAD CIRCUIT



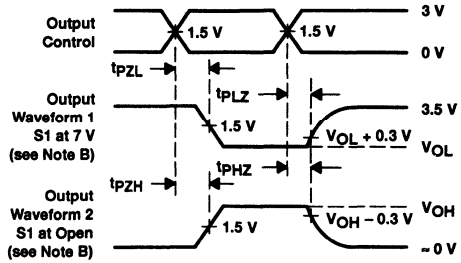
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



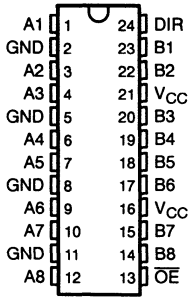
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

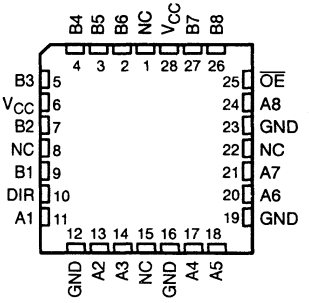
Figure 1. Load Circuit and Voltage Waveforms

- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Designed to Facilitate Incident-Wave Switching for Line Impedances of 25 Ω or Greater**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Package Options Include Plastic Small-Outline (DW) Package, Ceramic Chip Carriers (FK), and Standard Plastic (NT) and Ceramic (JT) DIPs**

SN54ABTH25245 . . . JT PACKAGE
SN74ABTH25245 . . . DW OR NT PACKAGE
(TOP VIEW)



SN54ABTH25245 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABTH25245 are 25-Ω octal bus transceivers designed for asynchronous communication between data buses. They improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented transceivers.

These devices allow noninverted data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can disable the device so that both buses are effectively isolated. When $\overline{OE}$ is low, the device is active.

These transceivers are capable of sinking 188 mA of I_{OL} current, which facilitates switching 25-Ω transmission lines on the incident wave. The distributed V_{CC} and GND pins minimize switching noise for more-reliable system operation.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

description (continued)

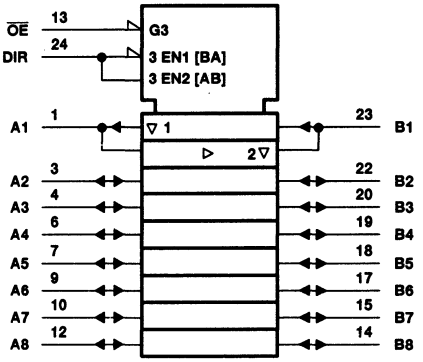
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTH25245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH25245 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

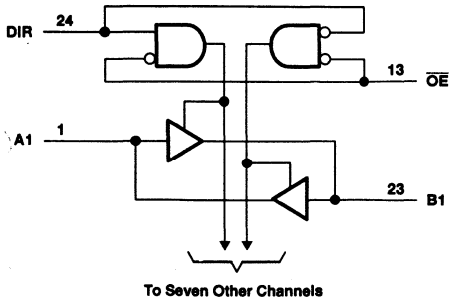
INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW, JT, and NT packages.

logic diagram (positive logic)



Pin numbers shown are for the DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V_O ..... –0.5 V to 5.5 V
Voltage range applied to any output in the high state, V_O ..... –0.5 V to V_{CC}
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Current into any output in the low state, I_O: SN74ABTH25245 (A port) ..... 376 mA
SN74ABTH25245 (B port) ..... 128 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package ..... 81°C/W
NT package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

				SN54ABTH25245		SN74ABTH25245		UNIT
				MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage			4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage			2		2		V
V_{IL}	Low-level input voltage				0.8		0.8	V
V_I	Input voltage			0	V_{CC}	0	V_{CC}	V
I_{IK}	Input clamp current				–18		–18	mA
I_{OH}	High-level output current		A port		–80		–80	mA
			B port		–32		–32	
I_{OL}	Low-level output current		A port		188		188	mA
			B port		64		64	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	Control inputs		4		4	ns/V
			A or B ports		10		10	
$\Delta t/\Delta V_{CC}$	Power-up ramp rate			200		200		μs/V
T_A	Operating free-air temperature			–55	125	–40	85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

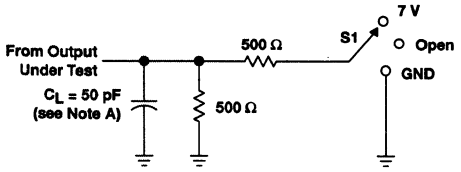
PARAMETER		TEST CONDITIONS		SN54ABTH25245			SN74ABTH25245			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2			–1.2	V
V_{OH}	A port	V_{CC} = 4.75 V,	I_{OH} = –3 mA	2.7			2.7			V
		V_{CC} = 4.5 V,	I_{OH} = –80 mA	2.4			2.4			
	B port	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5			
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3			
		V_{CC} = 4.5 V,	I_{OH} = –32 mA	2*			2			
V_{OL}	A port	V_{CC} = 4.5 V	I_{OL} = 94 mA			0.55			0.55	V
			I_{OL} = 188 mA			0.7			0.7	
	B port	V_{CC} = 4.5 V,	I_{OL} = 64 mA			0.55*			0.55	
V_{hys}					100			100		mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1			±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V,	V_I = V_{CC} or GND			±20			±20	
$I_{I(hold)}$	A or B ports	V_{CC} = 4.5 V	V_I = 0.8 V	100			100			µA
			V_I = 2 V	–100			–100			
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100			±100	µA
I_{CEX}		V_{CC} = 5.5 V,	V_O = 5.5 V			50			50	µA
I_O§	B port	V_{CC} = 5.5 V,	V_O = 2.5 V	–50		–210	–50		–210	mA
I_{CC}		V_{CC} = 5.5 V, Outputs open, V_I = V_{CC} or GND	Outputs high			500			500	µA
			Outputs low			20			20	mA
			Outputs disabled			500			500	µA
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1			1	mA
C_i	Control inputs	V_{CC} = 5 V,	V_I = V_{CC} or GND		4			4		pF
C_{io}	A or B ports	V_{CC} = 5 V,	V_O = V_{CC} or GND		11.5			11.5		pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

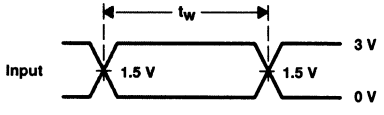
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABTH25245		SN74ABTH25245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	2.3	3.5	1		1	3.9	ns
t_{PHL}			1	2.4	3.5	1		1	4.3	
t_{PZH}	$\overline{OE}$	A or B	1.5	3.7	5.4	1.5		1.5	6.5	ns
t_{PZL}			1.4	4	5.8	1.4		1.4	6.8	
t_{PHZ}	$\overline{OE}$	A or B	2	4.3	6.1	2		2	7.2	ns
t_{PLZ}			2	3.9	5.8	2		2	6.4	

PARAMETER MEASUREMENT INFORMATION

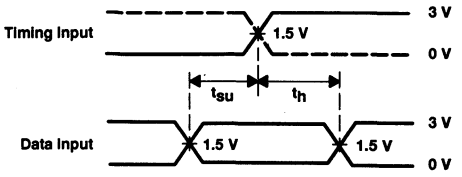


LOAD CIRCUIT

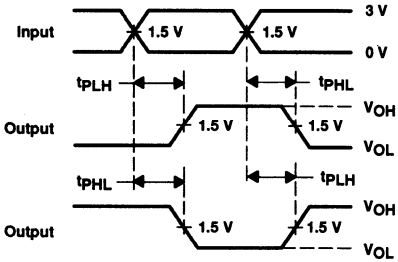
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



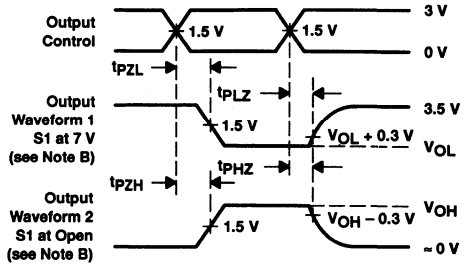
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

Contents

Contents (continued)

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- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
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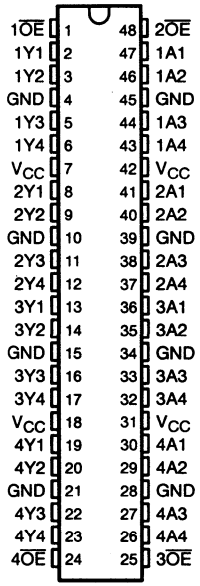
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16240 . . . WD PACKAGE
SN74ABT16240A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The SN54ABT16240 and SN74ABT16240A are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide inverting outputs and symmetrical active-low output-enable ($\overline{OE}$) inputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16240 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16240A is characterized for operation from –40°C to 85°C.

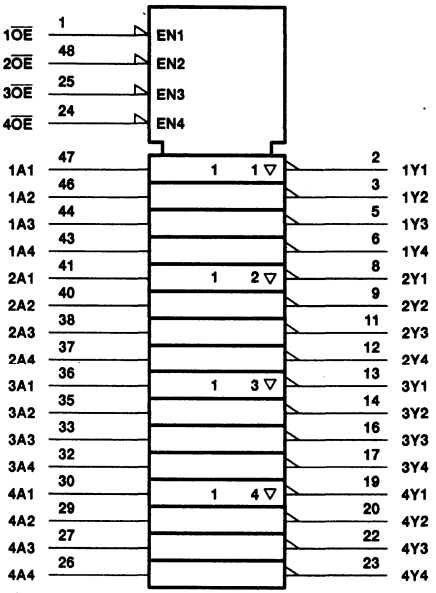
Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

FUNCTION TABLE
(each 4-bit buffer)

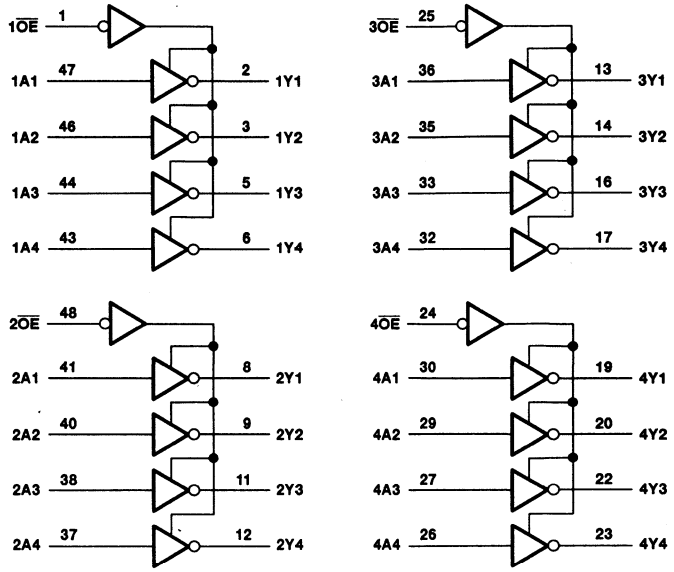
INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	L
L	L	H
H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16240 ..... 96 mA
SN74ABT16240A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DGV package ..... 93°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16240		SN74ABT16240A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16240		SN74ABT16240A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3*		2		3	mA
			Outputs low			34*		32		34	
			Outputs disabled			3*		2		3	
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1		1.5		1	mA
			Outputs disabled			0.05		1		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

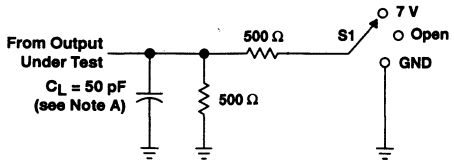
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16240					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	0.8	2.7	3.8	0.8	4.8	ns
t_{PHL}			1.1	3.1	4.3	1.1	4.9	
t_{PZH}	$\overline{OE}$	Y	1.3	3.3	4.3	1.3	5.4	ns
t_{PZL}			1.4	3.4	6.2	1.4	7.2	
t_{PHZ}	$\overline{OE}$	Y	1.6	3.6	6.2	1.6	7.2	ns
t_{PLZ}			1.4	3	5.1	1.4	5.7	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

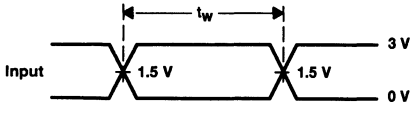
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16240A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.7	3.8	1	4.7	ns
t_{PHL}			1.1	3.1	4.3	1.1	4.8	
t_{PZH}	$\overline{OE}$	Y	1.3	3.3	4.3	1.3	5.3	ns
t_{PZL}			1.4	3.4	6.2	1.4	7.1	
t_{PHZ}	$\overline{OE}$	Y	1.6	3.6	4.8	1.6	6.1	ns
t_{PLZ}			1.4	3	5.1	1.4	5.6	

PARAMETER MEASUREMENT INFORMATION

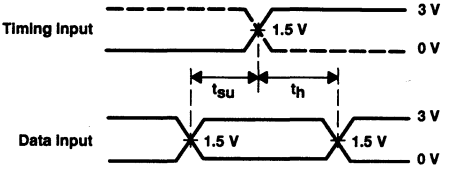


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

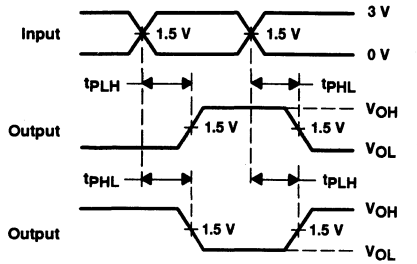
LOAD CIRCUIT



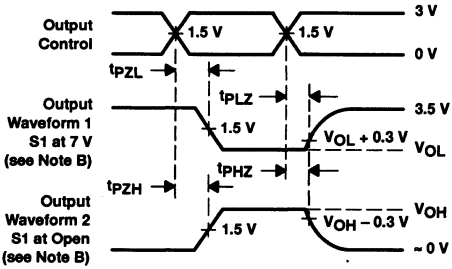
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
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Figure 1. Load Circuit and Voltage Waveforms

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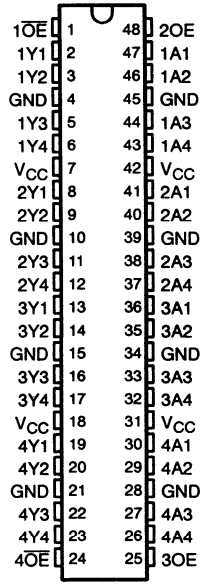
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16241 . . . WD PACKAGE
SN74ABT16241A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The SN54ABT16241 and SN74ABT16241A are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide true outputs and complementary output-enable (OE and $\overline{OE}$) inputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT16241 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16241A is characterized for operation from –40°C to 85°C.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

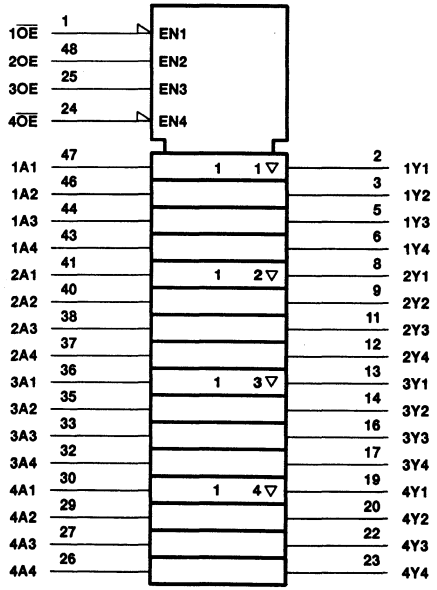
TEXAS INSTRUMENTS

FUNCTION TABLES

INPUTS		OUTPUTS
$1\overline{OE}$, $4\overline{OE}$	1A, 4A	1Y, 4Y
L	H	H
L	L	L
H	X	Z

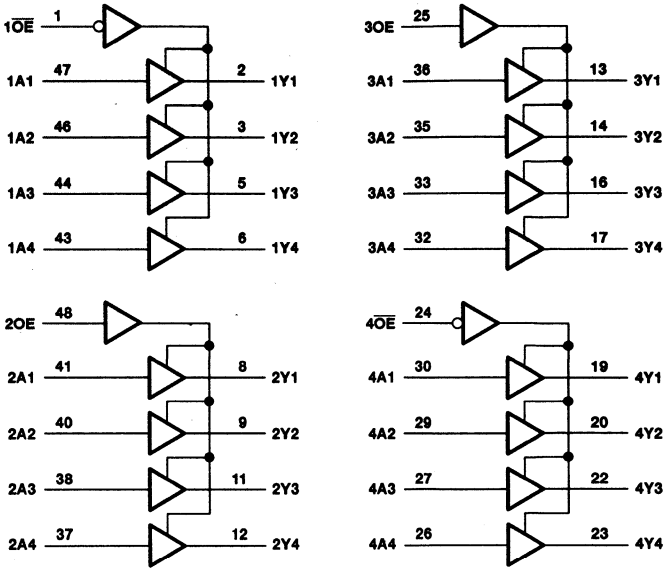
INPUTS		OUTPUTS
2OE, 3OE	2A, 3A	2Y, 3Y
H	H	H
H	L	L
L	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16241 ..... 96 mA
SN74ABT16241A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DGV package ..... 93°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16241		SN74ABT16241A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16241		SN74ABT16241A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3*		2		3	mA
			Outputs low			34*		32		34	
			Outputs disabled			3*		2		3	
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1		1.5		1	mA
			Outputs disabled			0.05		1		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

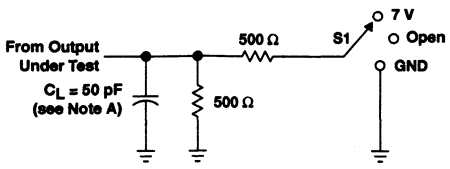
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16241					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	0.9	2.7	3.4	0.9	3.8	ns
t_{PHL}			0.9	2.7	3.9	0.9	4.6	
t_{PZH}	OE or $\overline{OE}$	Y	1.2	3.3	4.2	1.2	5.1	ns
t_{PZL}			1.3	3.4	5.9	1.3	7	
t_{PHZ}	OE or $\overline{OE}$	Y	1.5	4.1	5.5	1.5	7	ns
t_{PLZ}			1.7	3.6	5.1	1.7	5.7	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

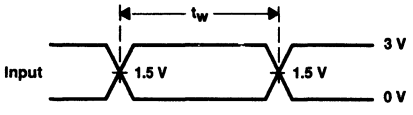
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16241A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.7	3.4	1	3.7	ns
t_{PHL}			1	2.7	3.9	1	4.5	
t_{PZH}	OE or $\overline{OE}$	Y	1.2	3.3	4.2	1.2	5	ns
t_{PZL}			1.3	3.4	5.9	1.3	6.9	
t_{PHZ}	OE or $\overline{OE}$	Y	1.5	4.1	5.2	1.5	6.2	ns
t_{PLZ}			1.7	3.6	5.1	1.7	5.6	

PARAMETER MEASUREMENT INFORMATION

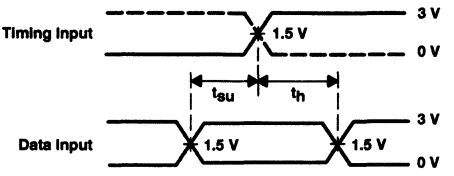


LOAD CIRCUIT

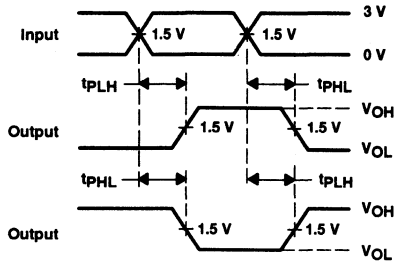
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



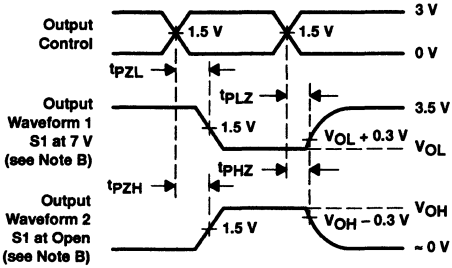
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



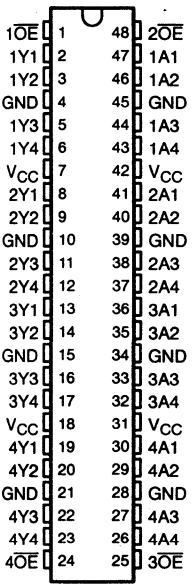
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC-IIB*™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16244 . . . WD PACKAGE
SN74ABT16244A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The SN54ABT16244 and SN74ABT16244A are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide true outputs and symmetrical $\overline{OE}$ (active-low output-enable) inputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16244 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16244A is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

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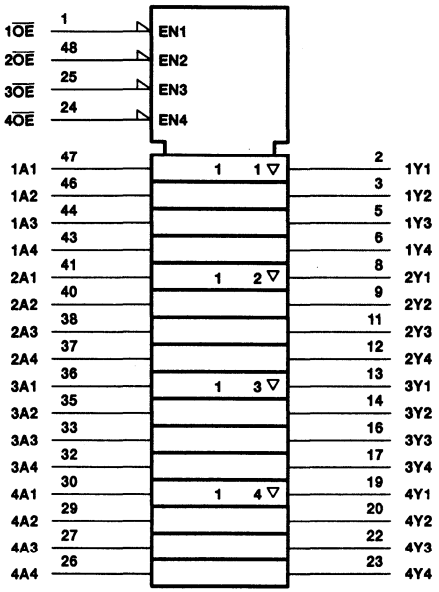
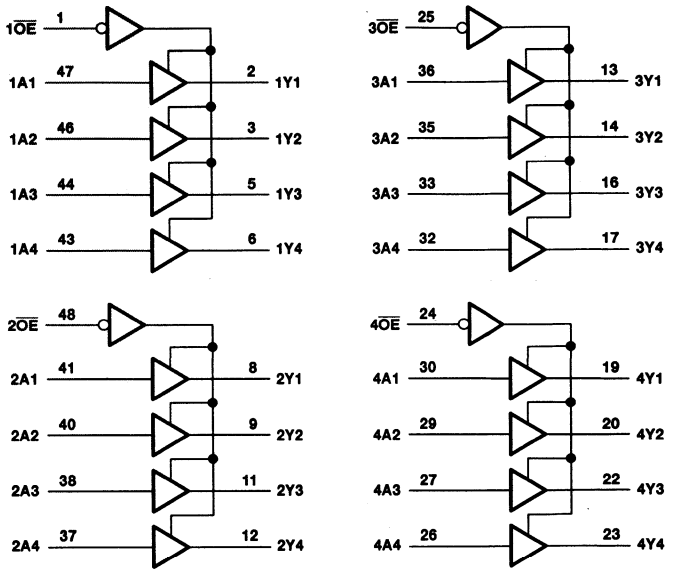
TEXAS INSTRUMENTS

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16244 ..... 96 mA
SN74ABT16244A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DGV package ..... 93°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16244		SN74ABT16244A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C†			SN54ABT16244		SN74ABT16244A		UNIT
				MIN	TYP‡	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			10§		10		10§	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–10§		–10		–10§	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3		2		3	mA
			Outputs low			32		32		32	
			Outputs disabled			3		2		3	
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			0.05		1.5		0.05	mA
			Outputs disabled			0.05		1		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				0.05		1.5		0.05	
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_o		V_O = 2.5 V or 0.5 V			8						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† Characteristics for T_A = 25°C apply to the SN74ABT16244A only.
‡ All typical values are at V_{CC} = 5 V.
§ This data sheet limit may vary among suppliers.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

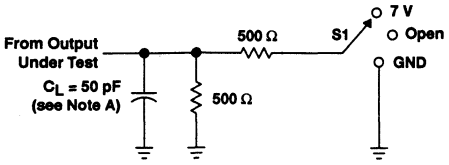
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16244					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	0.7	2.3	3.2	0.7	3.6	ns
t_{PHL}			0.5	2.6	3.7	0.5	4.2	
t_{PZH}	$\overline{OE}$	Y	0.7	3	4	0.7	4.9	ns
t_{PZL}			0.9	3.2	5.5	0.9	6.5	
t_{PHZ}	$\overline{OE}$	Y	1.7	3.6	5	1.7	6	ns
t_{PLZ}			1.5	2.9	4.7	1.5	5.7	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

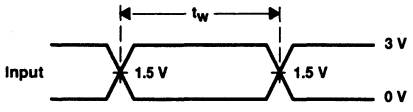
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16244A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.3	3.2	1	3.5	ns
t_{PHL}			1	2.6	3.7	1	4.1	
t_{PZH}	$\overline{OE}$	Y	1	3	3.8	1	4.8	ns
t_{PZL}			1	3.2	4	1	4.8	
t_{PHZ}	$\overline{OE}$	Y	1	3.6	4.4	1	4.8	ns
t_{PLZ}			1	2.9	3.7	1	4.1	

PARAMETER MEASUREMENT INFORMATION

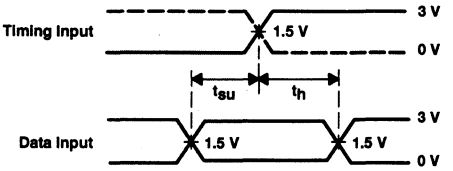


LOAD CIRCUIT

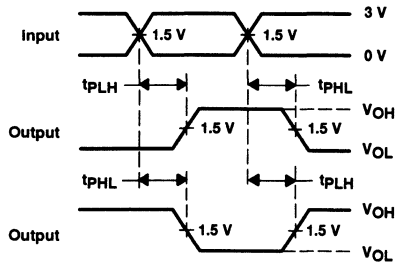
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



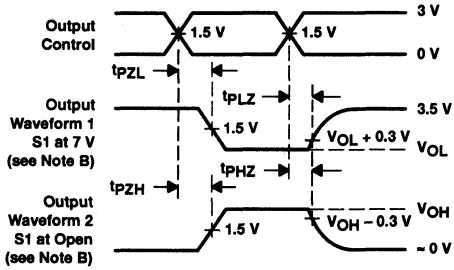
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
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Figure 1. Load Circuit and Voltage Waveforms

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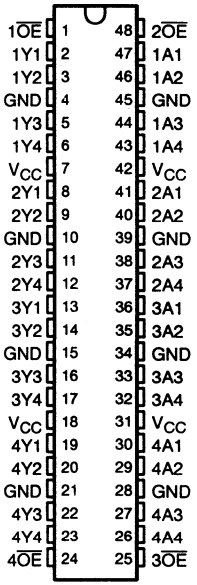
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Spacings**

SN54ABTH16244 . . . WD PACKAGE
SN74ABTH16244 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The 'ABTH16244 are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide true outputs and symmetrical active-low output-enable ($\overline{OE}$) inputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ABTH16244 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH16244 is characterized for operation from –40°C to 85°C.

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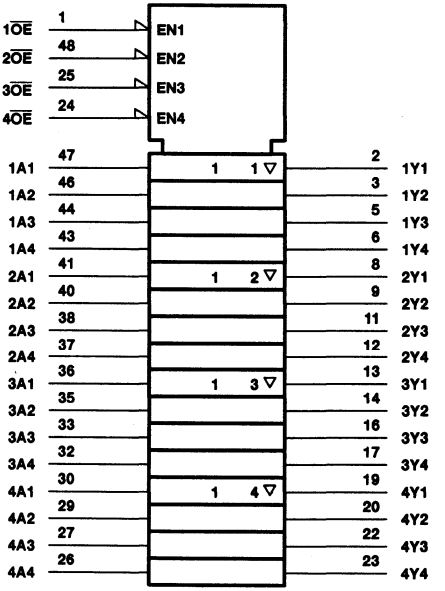
TEXAS INSTRUMENTS

FUNCTION TABLE
(each buffer)

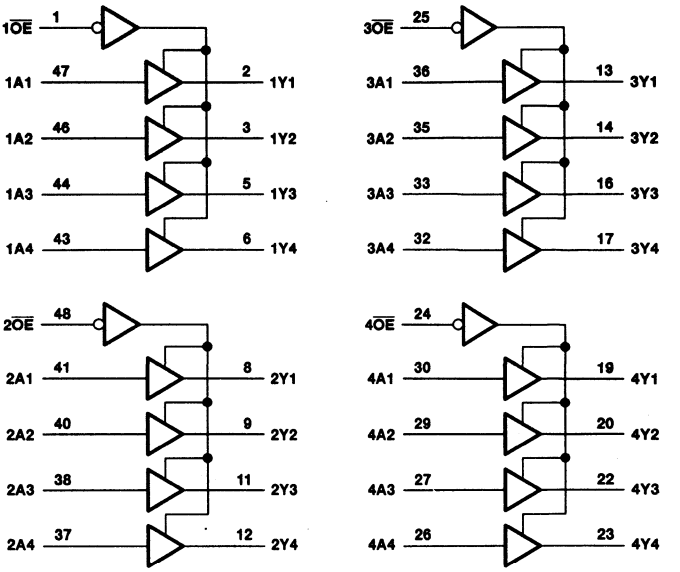
INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH16244 ..... 96 mA
SN74ABTH16244 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DGV package ..... 93°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABTH16244		SN74ABTH16244		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused control inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABTH16244		SN74ABTH16244		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
		I_{OH} = –32 mA	2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
		I_{OL} = 64 mA			0.55*				0.55	
V_{hys}				100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
$I_{I(hold)}$	V_{CC} = 4.5 V	V_I = 0.8 V	100			100		100		µA
		V_I = 2 V	–40			–40		–40		
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}	V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3		2		3	mA
		Outputs low			32		32		32	
		Outputs disabled			3		2		3	
ΔI_{CC}§	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V			3						pF
C_o	V_O = 2.5 V or 0.5 V			8						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

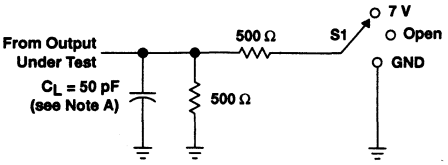
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABTH16244					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	0.7	2.3	3.2	0.7	3.6	ns
t_{PHL}			0.5	2.6	3.7	0.5	4.2	
t_{PZH}	$\overline{OE}$	Y	0.7	3	4	0.7	4.9	ns
t_{PZL}			0.9	3.2	5.5	0.9	6.5	
t_{PHZ}	$\overline{OE}$	Y	1.7	3.6	5	1.7	6	ns
t_{PLZ}			1.5	2.9	4.7	1.5	5.7	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

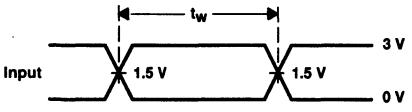
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABTH16244					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.3	3.2	1	3.5	ns
t_{PHL}			1	2.6	3.7	1	4.1	
t_{PZH}	$\overline{OE}$	Y	1	3	3.8	1	4.8	ns
t_{PZL}			1	3.2	4	1	4.8	
t_{PHZ}	$\overline{OE}$	Y	1	3.6	4.4	1	4.8	ns
t_{PLZ}			1	2.9	3.7	1	4.1	

PARAMETER MEASUREMENT INFORMATION

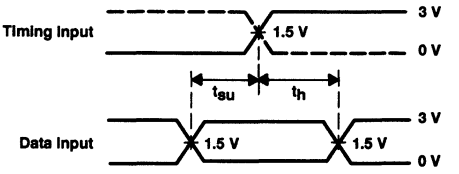


LOAD CIRCUIT

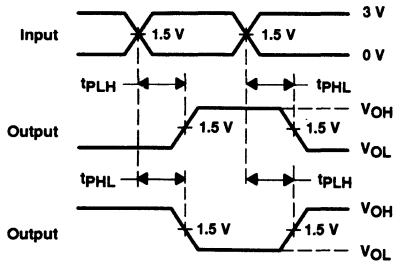
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



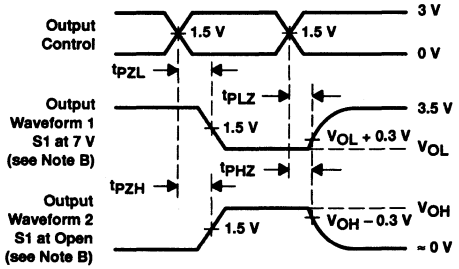
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



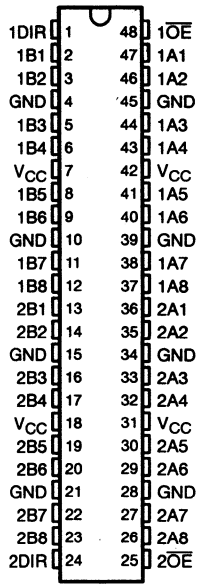
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Thin Very Small-Outline (DGV), 300-mil Shrink Small-Outline (DL), and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic (WD) Flat Package Using 25-mil Center-to-Center Spacings**

SN54ABT16245 . . . WD PACKAGE
SN74ABT16245A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The SN54ABT16245 and SN74ABT16245A are 16-bit noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so that the buses are effectively isolated.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16245A is characterized for operation from –40°C to 85°C.

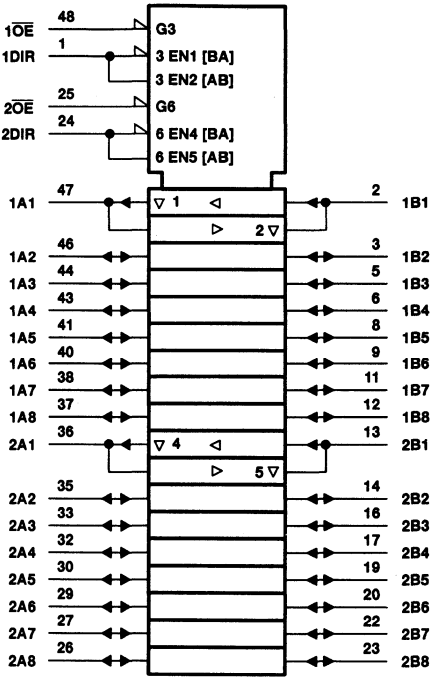
Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

FUNCTION TABLE
(each 8-bit section)

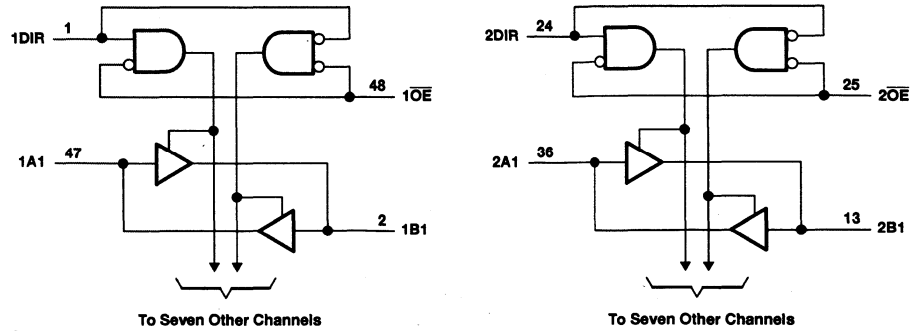
INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16245 ..... 96 mA
SN74ABT16245A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DGV package ..... 93°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16245		SN74ABT16245A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16245		SN74ABT16245A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±100		±20	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10¶		10		10¶	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10¶		–10		–10¶	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O#		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			32		32		32	
			Outputs disabled			2		2		2	
ΔI_{CC}‖	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			2		1.5		2	mA
			Outputs disabled			0.05		1		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_o	A or B ports	V_O = 2.5 V or 0.5 V			6						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ This limit may vary among suppliers.
# Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
‖ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

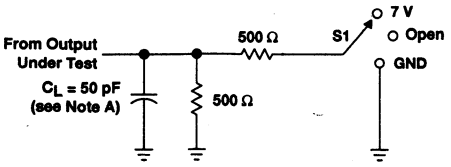
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16245					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	0.5	2.2	3.4	0.5	4	ns
t_{PHL}			0.5	2.3	3.8	0.5	4.6	
t_{PZH}	$\overline{OE}$	B or A	0.8	3.6	5.2	0.8	5.5	ns
t_{PZL}			0.9	3.7	6.1	0.9	7.3	
t_{PHZ}	$\overline{OE}$	B or A	1.3	4.4	5.8	1.3	6.3	ns
t_{PLZ}			1.4	3.3	4.7	1.4	5.3	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

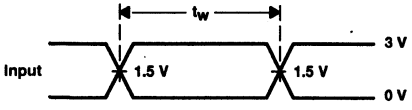
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16245A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1	2.2	3.4	1	3.9	ns
t_{PHL}			1	2.3	3.7	1	4.2	
t_{PZH}	$\overline{OE}$	B or A	1	3.6	5.2	1	6.3	ns
t_{PZL}			1	3.7	5.4	1	6.4	
t_{PHZ}	$\overline{OE}$	B or A	2	4.4	5.8	2	6.3	ns
t_{PLZ}			1.5	3.3	4.7	1.5	5.2	

PARAMETER MEASUREMENT INFORMATION

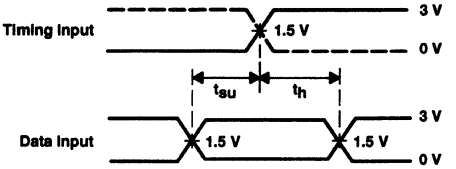


LOAD CIRCUIT

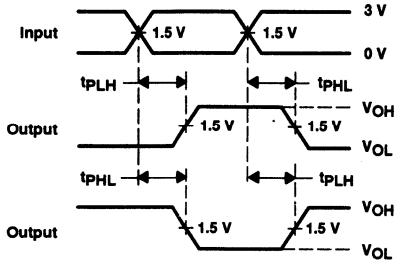
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



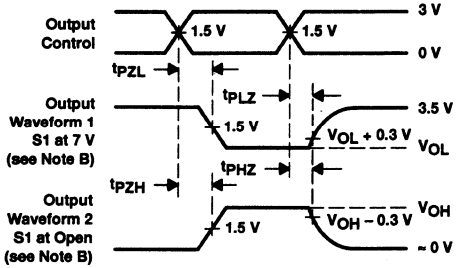
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



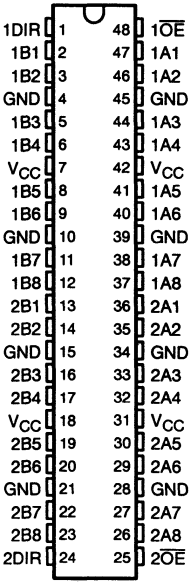
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABTH16245 . . . WD PACKAGE
SN74ABTH16245 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The 'ABTH16245 are 16-bit noninverting 3-state transceivers that provide synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the devices so that the buses are effectively isolated.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

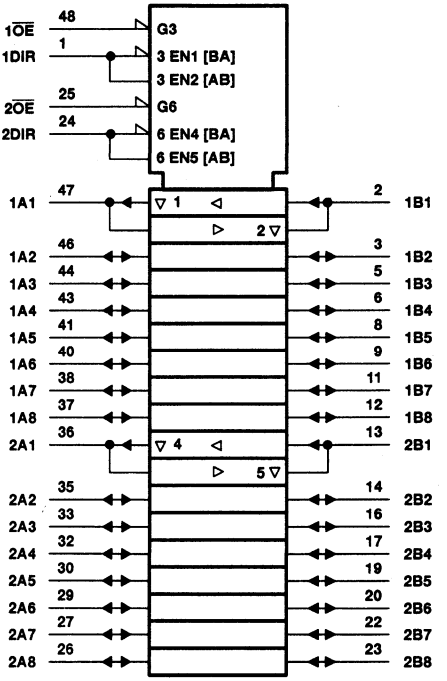
Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ABTH16245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH16245 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 8-bit section)

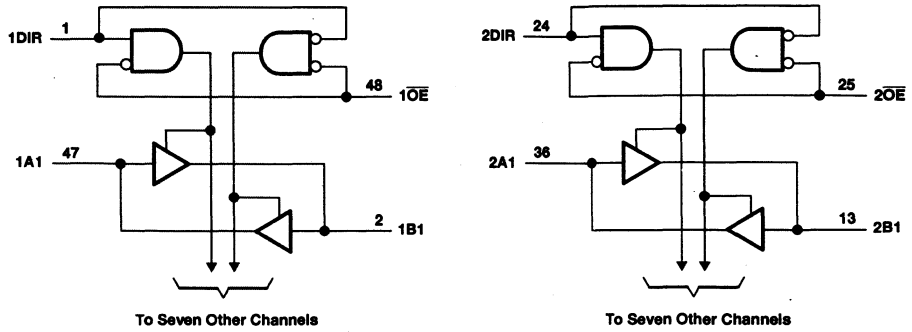
INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH16245 ..... 96 mA
SN74ABTH16245 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DGV package ..... 93°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABTH16245		SN74ABTH16245		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C MIN	TYP†	MAX	SN54ABTH16245 MIN	MAX	SN74ABTH16245 MIN	MAX	UNIT
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
$I_{I(hold)}$		V_{CC} = 4.5 V	V_I = 0.8 V	100			100		100		µA
			V_I = 2 V	–100			–100		–100		
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			32		32		32	
			Outputs disabled			2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			6						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

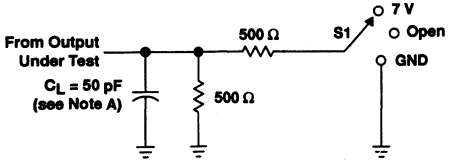
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABTH16245					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	0.5	2.2	3.4	1	4.1	ns
t_{PHL}			0.5	2.3	3.8	1	4.4	
t_{PZH}	$\overline{OE}$	B or A	0.8	3.6	5.2	1	6.4	ns
t_{PZL}			0.9	3.7	6.1	1	6.5	
t_{PHZ}	$\overline{OE}$	B or A	1.3	4.4	5.8	2	6.4	ns
t_{PLZ}			1.4	3.3	4.7	1.5	5.6	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

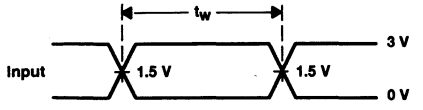
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABTH16245					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1	2.2	3.4	1	3.9	ns
t_{PHL}			1	2.3	3.7	1	4.2	
t_{PZH}	$\overline{OE}$	B or A	1	3.6	5.2	1	6.3	ns
t_{PZL}			1	3.7	5.4	1	6.4	
t_{PHZ}	$\overline{OE}$	B or A	2	4.4	5.8	2	6.3	ns
t_{PLZ}			1.5	3.3	4.7	1.5	5.2	

PARAMETER MEASUREMENT INFORMATION

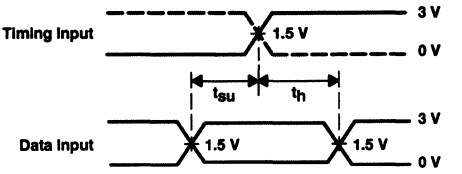


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

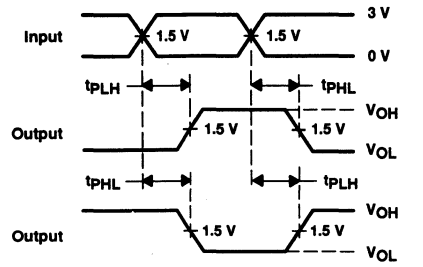
LOAD CIRCUIT



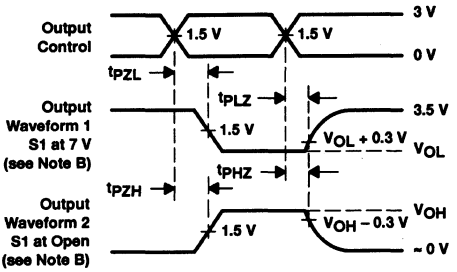
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



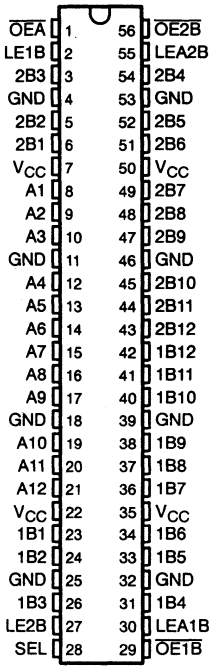
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16260 . . . WD PACKAGE
SN74ABTH16260 . . . DL PACKAGE
(TOP VIEW)



description

The SN54ABT16260 and SN74ABTH16260 are 12-bit to 24-bit multiplexed D-type latches used in applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single data path. Typical applications include multiplexing and/or demultiplexing of address and data information in microprocessor or bus-interface applications. This device is also useful in memory-interleaving applications.

Three 12-bit I/O ports (A1–A12, 1B1–1B12, and 2B1–2B12) are available for address and/or data transfer. The output-enable ($\overline{OE1B}$, $\overline{OE2B}$, and $\overline{OEA}$) inputs control the bus-transceiver functions. The $\overline{OE1B}$ and $\overline{OE2B}$ control signals also allow bank control in the A-to-B direction.

Address and/or data information can be stored using the internal storage latches. The latch-enable (LE1B, LE2B, LEA1B, and LEA2B) inputs are used to control data storage. When the latch-enable input is high, the latch is transparent. When the latch-enable input goes low, the data present at the inputs is latched and remains latched until the latch-enable input is returned high.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

description (continued)

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ABT16260 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH16260 is characterized for operation from –40°C to 85°C.

Function Tables

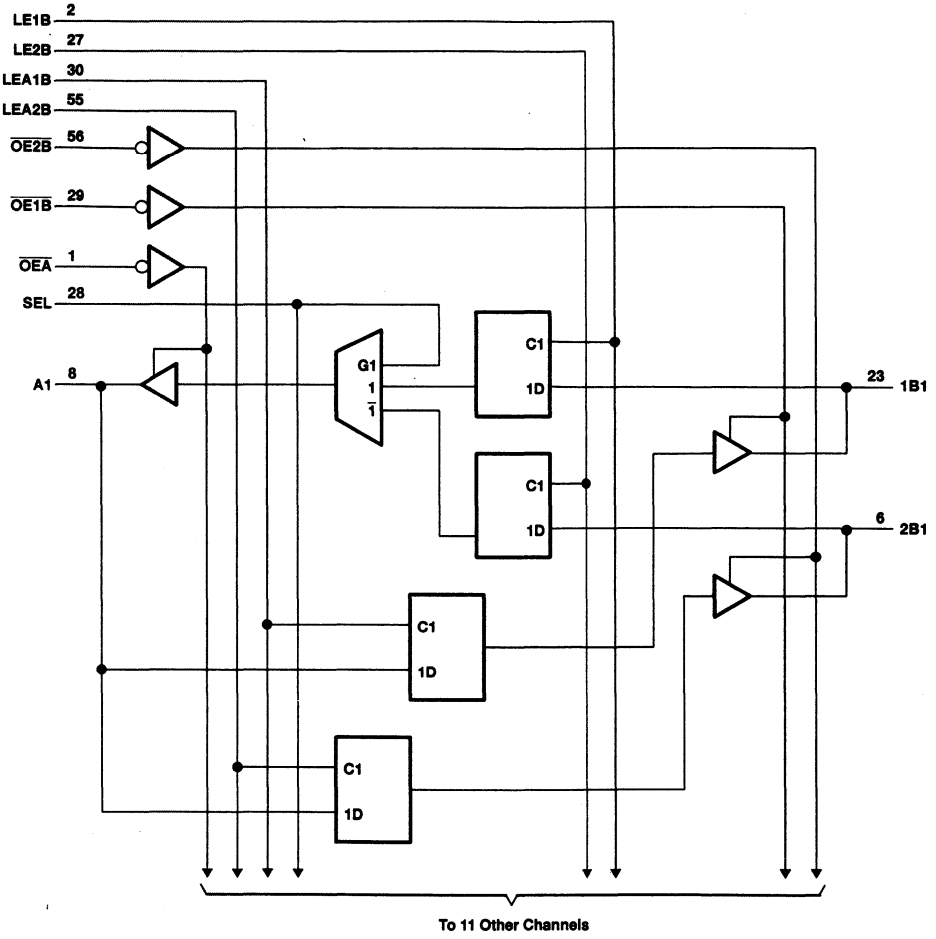
B TO A ($\overline{OEB}$ = H)

INPUTS						OUTPUT
1B	2B	SEL	LE1B	LE2B	$\overline{OEA}$	A
H	X	H	H	X	L	H
L	X	H	H	X	L	L
X	X	H	L	X	L	A_0
X	H	L	X	H	L	H
X	L	L	X	H	L	L
X	X	L	X	L	L	A_0
X	X	X	X	X	H	Z

A TO B ($\overline{OEA}$ = H)

INPUTS					OUTPUTS	
A	LEA1B	LEA2B	$\overline{OE1B}$	$\overline{OE2B}$	1B	2B
H	H	H	L	L	H	H
L	H	H	L	L	L	L
H	H	L	L	L	H	$2B_0$
L	H	L	L	L	L	$2B_0$
H	L	H	L	L	$1B_0$	H
L	L	H	L	L	$1B_0$	L
X	L	L	L	L	$1B_0$	$2B_0$
X	X	X	H	H	Z	Z
X	X	X	L	H	Active	Z
X	X	X	H	L	Z	Active
X	X	X	L	L	Active	Active

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16260 ..... 96 mA
SN74ABTH16260 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16260		SN74ABTH16260		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused control inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16260		SN74ABTH16260		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA		0.36			0.5			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±100		±20	
$I_{I(hold)}$	A or B ports	V_{CC} = 4.5 V	V_I = 0.8 V				100		100		µA
			V_I = 2 V				–100		–100		
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–225	–50	–225	–50	–225	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			1.5		1.5		1.5	mA
			Outputs low			63		63		63	
			Outputs disabled			1		1		1	
ΔI_{CC}#		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_{io}		V_O = 2.5 V or 0.5 V			11.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V_{CC} = 5 V, T_A = 25°C†		SN54ABT16260		SN74ABTH16260		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE1B, LE2B, LEA1B, or LEA2B high	3.3		3.3		3.3		ns
t_{su}	Setup time, data before LE1B, LE2B, LEA1B, or LEA2B↓	1.5		2		1.5		ns
t_h	Hold time, data after LE1B, LE2B, LEA1B, or LEA2B↓	1		1.5		1		ns

† These values apply only to the SN74ABTH16260.

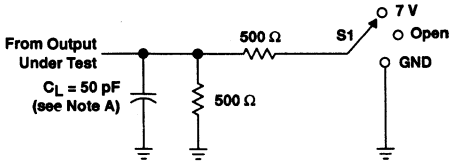
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16260					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1	3.1	5.3	1	5.9	ns
t_{PHL}			1	3.4	5.4	1	6.3	
t_{PLH}	LE	A or B	1.1	3.2	5.4	1.1	6.6	ns
t_{PHL}			1.1	3.3	5.3	1.1	5.9	
t_{PLH}	SEL (B1)	A	1.3	3.2	5.1	1.3	5.4	ns
	SEL (B2)		1.1	3.4	5.4	1.1	6.3	
t_{PHL}	SEL (B1)		1.5	3.1	4.6	1.5	5	
	SEL (B2)		1.6	3.6	5.3	1.6	6.2	
t_{PZH}	$\overline{OE}$	A or B	1	3.3	5.6	1	6.4	ns
t_{PZL}			1.6	3.8	5.9	1.6	6.5	
t_{PHZ}	$\overline{OE}$	A or B	2.2	4.1	5.9	2.2	7.5	ns
t_{PLZ}			1.3	3.2	5	1.3	5.4	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

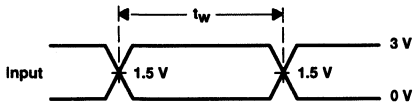
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABTH16260					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1	3.1	4.8	1	5.6	ns
t_{PHL}			1	3.4	5	1	5.9	
t_{PLH}	LE	A or B	1.1	3.2	4.9	1.1	5.8	ns
t_{PHL}			1.1	3.3	4.9	1.1	5.3	
t_{PLH}	SEL (B1)	A	1.3	3.2	4.6	1.3	5.3	ns
	SEL (B2)		1.1	3.4	4.9	1.1	6	
t_{PHL}	SEL (B1)		1.5	3.1	4.4	1.5	4.4	
	SEL (B2)		1.6	3.6	5.1	1.6	5.9	
t_{PZH}	$\overline{OE}$	A or B	1	3.3	4.7	1	5.7	ns
t_{PZL}			1.6	3.8	5.1	1.6	5.8	
t_{PHZ}	$\overline{OE}$	A or B	2.2	4.1	5.4	2.2	6.4	ns
t_{PLZ}			1.3	3.2	4.4	1.3	4.8	

PARAMETER MEASUREMENT INFORMATION

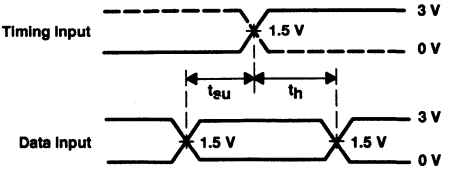


LOAD CIRCUIT

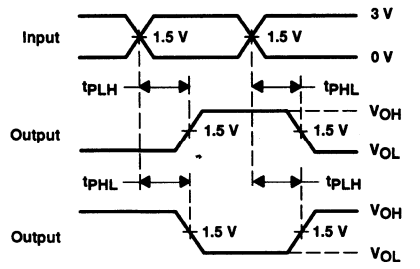
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



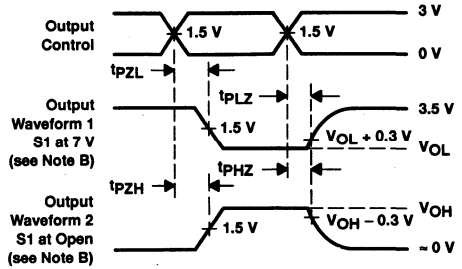
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



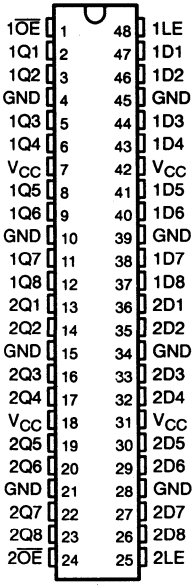
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16373A . . . WD PACKAGE
SN74ABT16373A . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16373A are 16-bit transparent D-type latches with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16373A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16373A is characterized for operation from –40°C to 85°C.

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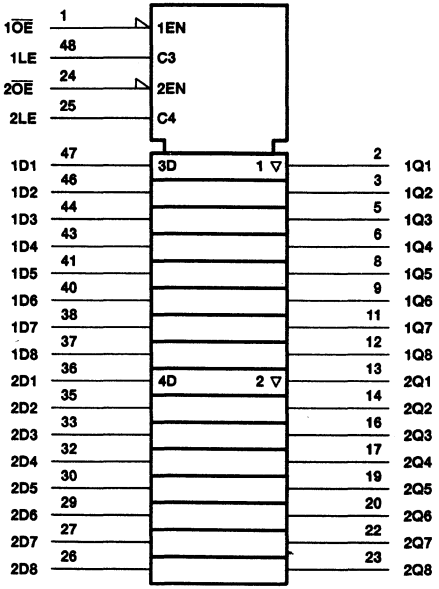
FUNCTION TABLE
(each 8-bit section)

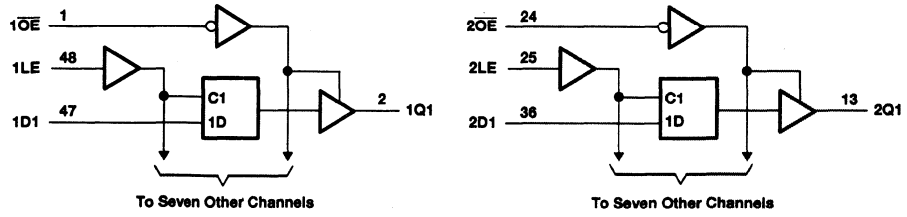
INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16373A ..... 96 mA
SN74ABT16373A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16373A		SN74ABT16373A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16373A		SN74ABT16373A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0, V_I or V_O ≤ 4.5 V				±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	Outputs high	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND				2		2		2	mA
	Outputs low					85		85		85	
	Outputs disabled					2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			9.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V_{CC} = 5 V, T_A = 25°C#		SN54ABT16373A		SN74ABT16373A		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	3.3		3.3		3.3		ns
t_{su}	Setup time, data before LE↓	1.5		2.4		1.5		ns
t_h	Hold time, data after LE↓	1		2.2		1		ns

These values apply only to the SN74ABT16373A.

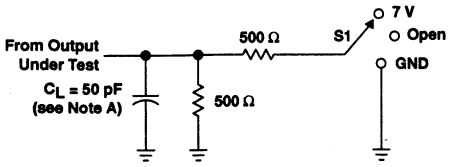
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16373A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	Q	1.4	3.7	5.3	1.4	6.5	ns
t_{PHL}			2	4	5.4	2	6.5	
t_{PLH}	LE	Q	1.7	4.1	5.7	1.7	7	ns
t_{PHL}			2.3	4.3	5.6	2.3	6.3	
t_{PZH}	$\overline{OE}$	Q	1.1	3.4	5	1.1	6.4	ns
t_{PZL}			1.5	3.5	4.9	1.5	5.8	
t_{PHZ}	$\overline{OE}$	Q	2.4	5.1	7.1	2.4	8.3	ns
t_{PLZ}			1.6	4.4	6.3	1.6	8	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

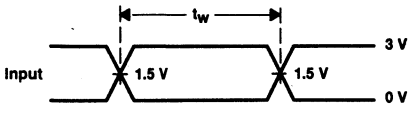
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16373A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	Q	1.4	3.7	5.3	1.4	6.3	ns
t_{PHL}			2	4	5.4	2	6.2	
t_{PLH}	LE	Q	1.7	4.1	5.7	1.7	6.7	ns
t_{PHL}			2.3	4.3	5.6	2.3	6.1	
t_{PZH}	$\overline{OE}$	Q	1.1	3.4	5	1.1	6.1	ns
t_{PZL}			1.5	3.5	4.9	1.5	5.6	
t_{PHZ}	$\overline{OE}$	Q	2.4	5.1	7.1	2.4	8.1	ns
t_{PLZ}			1.6	4.4	5.8	1.6	6.5	

PARAMETER MEASUREMENT INFORMATION

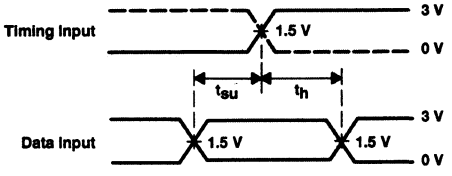


LOAD CIRCUIT

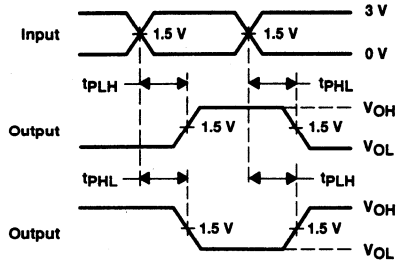
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



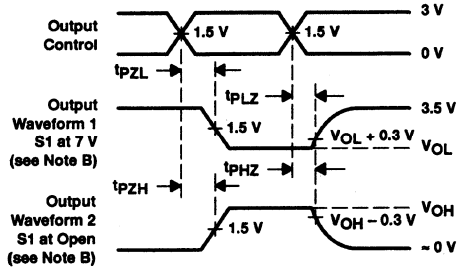
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
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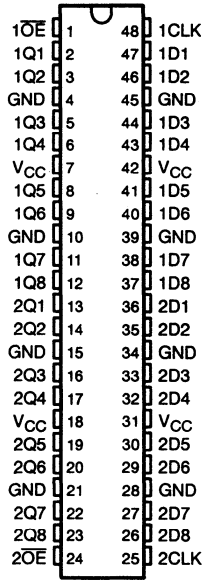
SN54ABT16374A . . . WD PACKAGE
SN74ABT16374A . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16374A are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components

$\overline{OE}$ does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16374A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16374A is characterized for operation from –40°C to 85°C.

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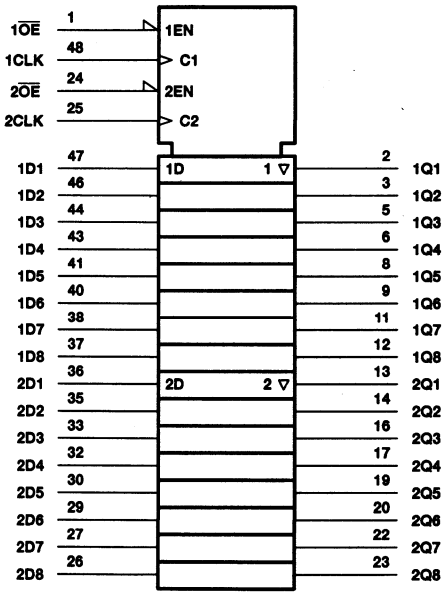
FUNCTION TABLE
(each flip-flop)

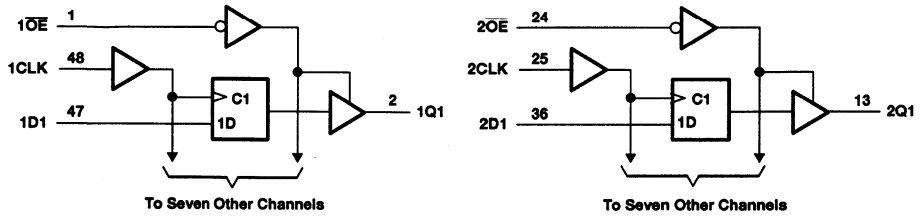
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16374A ..... 96 mA
SN74ABT16374A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16374A		SN74ABT16374A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16374A		SN74ABT16374A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	Outputs high	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND				2		2		2	mA
	Outputs low					72		72		72	
	Outputs disabled					2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			9.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V_{CC} = 5 V, T_A = 25°C#		SN54ABT16374A		SN74ABT16374A		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	150	0	150	0	150	MHz
t_w	Pulse duration, CLK high or low	3.3		3.3		3.3		ns
t_{su}	Setup time, data before CLK↑	1.1		1.3		1.1		ns
t_h	Hold time, data after CLK↑	1.3		1.5		1.3		ns

These values apply only to the SN74ABT16374A.

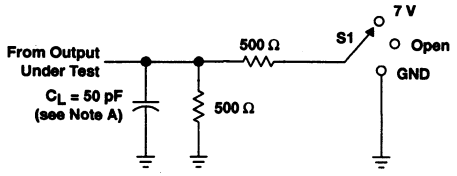
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16374A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150			150		MHz
t_{PLH}	CLK	Q	1.8	4.3	5.7	1.5	6.9	ns
t_{PHL}			2.7	4.7	6.1	2.2	6.9	
t_{PZH}	$\overline{OE}$	Q	1.2	3.4	4.8	0.8	6.1	ns
t_{PZL}			1.6	3.5	4.9	1.2	5.5	
t_{PHZ}	$\overline{OE}$	Q	2.2	5.5	8.6	1.8	9.6	ns
t_{PLZ}			2.2	4.3	6.2	1.8	7.2	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

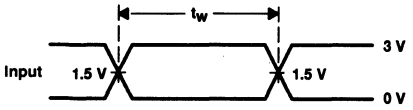
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16374A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150			150		MHz
t_{PLH}	CLK	Q	1.8	4.3	5.4	1.8	6.2	ns
t_{PHL}			2.7	4.7	5.6	2.7	5.9	
t_{PZH}	$\overline{OE}$	Q	1.2	3.4	4.8	1.2	5.6	ns
t_{PZL}			1.6	3.5	4.7	1.6	5.3	
t_{PHZ}	$\overline{OE}$	Q	2.2	5.5	7.1	2.2	8.2	ns
t_{PLZ}			2.2	4.3	5.8	2.2	6.6	

PARAMETER MEASUREMENT INFORMATION

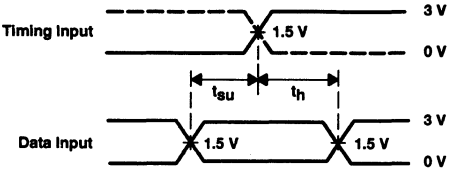


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

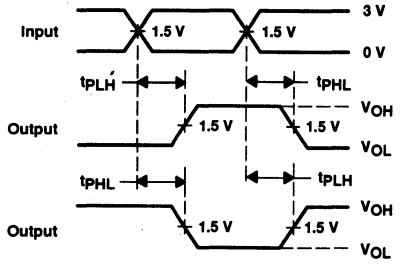
LOAD CIRCUIT



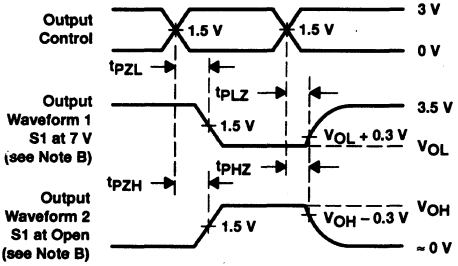
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



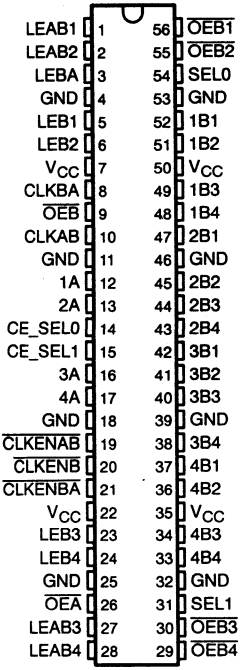
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABTH16460 . . . WD PACKAGE
SN74ABTH16460 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABTH16460 are 4-bit to 1-bit multiplexed registered transceivers used in applications where four separate data paths must be multiplexed onto or demultiplexed from a single data path. Typical applications include multiplexing and/or demultiplexing of address and data information in microprocessor or bus-interface applications. These devices also are useful in memory-interleaving applications.

Five 4-bit I/O ports (1A–4A, 1B1–4, 2B1–4, 3B1–4, and 4B1–4) are available for address and/or data transfer. The output-enable ($\overline{OEB}$, $\overline{OEB1}$–$\overline{OEB4}$, and $\overline{OEA}$) inputs control the bus-transceiver functions. These control signals also allow 4-bit or 16-bit control, depending on the $\overline{OEB}$ level.

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description (continued)

Address and/or data information can be stored using the internal storage latches/flip-flops. The latch-enable (LEB1–LEB4, LEBA, and LEAB1–LEAB4) and clock/clock-enable (CLK/$\overline{\text{CLKEN}}$) inputs are used to control data storage. When either one of the latch-enable inputs is high, the latch is transparent (clock is a don't care as long as the latch enable is high). When the latch-enable input goes low (providing that the clock does not transit from low to high), the data present at the inputs is latched and remains latched until the latch-enable input is returned high. When the clock enable is low and the corresponding latch enable is low, data can be clocked on the low-to-high transition of the clock. When either the clock enable or the corresponding latch enable is high, the clock is a don't care.

Four select pins (SEL0, SEL1, CE_SEL0, and CE_SEL1) are provided to multiplex data (A port), or to select one of four clock enables (B port). This allows the user the flexibility of controlling one bit at a time.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTH16460 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH16460 is characterized for operation from –40°C to 85°C.

Function Tables

A-TO-B OUTPUT ENABLE†

INPUTS		OUTPUT
$\overline{\text{OEB}}$	$\overline{\text{OEBn}}$	Bn
H	H	Z
H	L	Z
L	H	Z
L	L	Active

† n = 1, 2, 3, 4

A-TO-B STORAGE
(assuming $\overline{\text{OEB}}$ = L, $\overline{\text{OEBn}}$ = L)‡

INPUTS								OUTPUTS			
$\overline{\text{CLKENAB}}$	CE_SEL1	CE_SEL0	CLKAB	LEAB1	LEAB2	LEAB3	LEAB4	B1	B2	B3	B4
X	X	X	H or L	H	L	L	L	A	A_0	A_0	A_0
X	X	X	H or L	H	H	H	L	A	A	A	A_0
L	X	X	L	L	L	L	L	A_0	A_0	A_0	A_0
L	L	L	↑	L	L	L	L	A	A_0	A_0	A_0
L	L	H	↑	L	L	L	L	A_0	A	A_0	A_0
L	H	L	↑	L	L	L	L	A_0	A_0	A	A_0
L	H	H	↑	L	L	L	L	A_0	A_0	A_0	A
H	X	X	↑	L	L	L	L	A_0	A_0	A_0	A_0

‡ This table does not cover all the latch-enable cases since they have similar results.

Function Tables (Continued)

B-TO-A STORAGE
(before point P)

INPUTS								P
$\overline{CLKENB}$	CLKBA	LEB1	LEB2	LEB3	LEB4	SEL1	SEL0	
X	X	H	L	L	L	L	L	B1
X	X	L	H	L	L	L	H	B2
X	X	L	L	H	L	H	L	B3
X	X	L	L	L	H	H	H	B4
L	↑	L	L	L	L	L	L	B1
						L	H	B2
						H	L	B3
						H	H	B4
L	L	L	L	L	L	L	L	$B1_0$†
						L	H	$B2_0$†
						H	L	$B3_0$†
						H	H	$B4_0$†

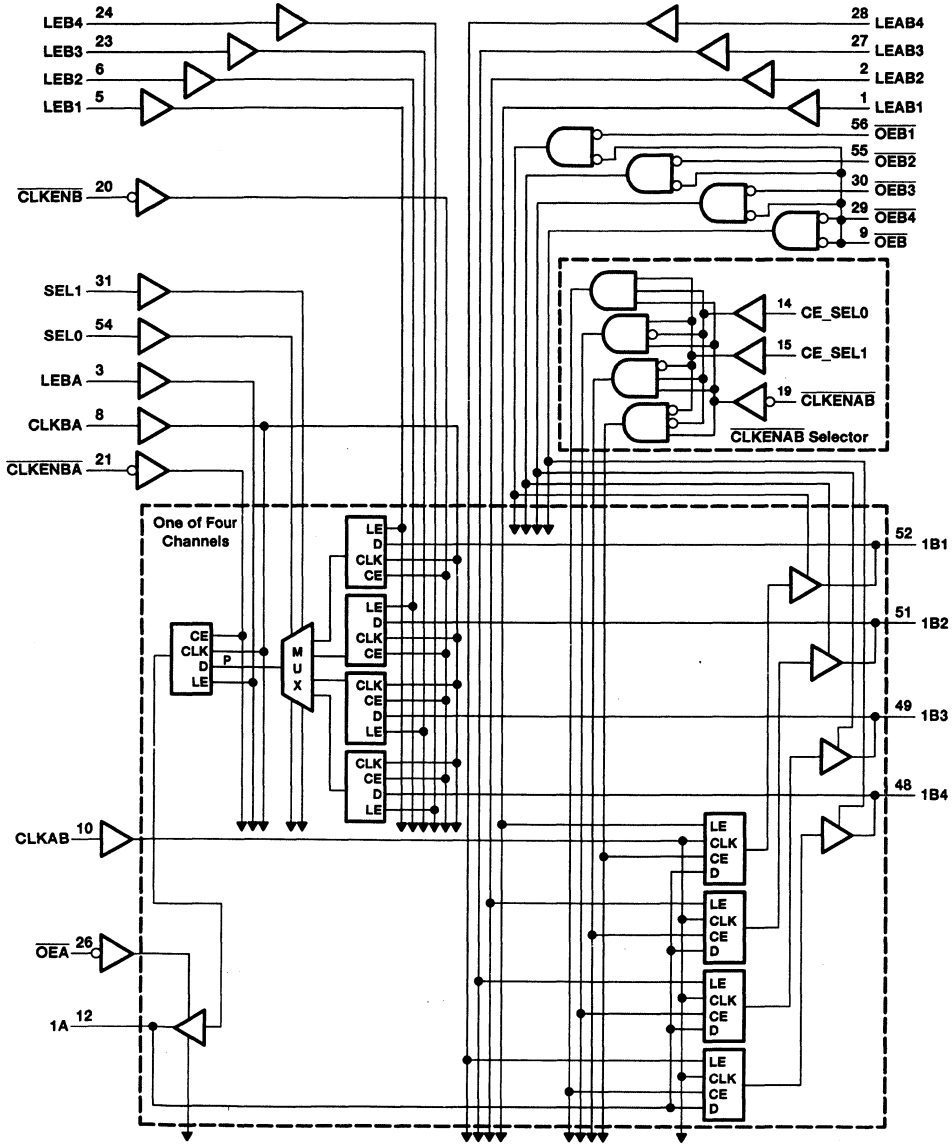
† Output level before the indicated steady-state input conditions were established

B-TO-A STORAGE
(after point P)

INPUTS					OUTPUT
$\overline{CLKENBA}$	CLKBA	LEBA	$\overline{OEA}$	B	A
X	X	X	H	X	Z
X	X	H	L	L	L
X	X	H	L	H	H
H	X	L	L	X	A_0†
L	↑	L	L	L	L
L	↑	L	L	H	H
L	L	L	L	X	A_0†

† Output level before the indicated steady-state input conditions were established

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH16460 ..... 96 mA
SN74ABTH16460 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABTH16460		SN74ABTH16460		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABTH16460		SN74ABTH16460		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA		0.36			0.5			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±20		±20	
$I_{I(hold)}$	A or B ports	V_{CC} = 4.5 V	V_I = 0.8 V	75		500	75	500	75	500	µA
			V_I = 2 V	–75		–500	–75	–500	–75	–500	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–200	–50	–200	–50	–200	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			1.5		1.5		1.5	mA
			A outputs low			10		10		10	
			B outputs low			32		32		32	
			Outputs disabled			1.5		1.5		1.5	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			8						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			3.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

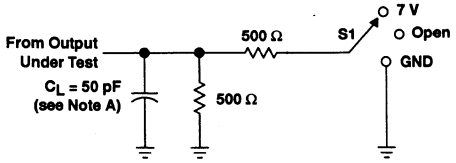
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				SN54ABTH16460		SN74ABTH16460		UNIT
				MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			0	160	0	160	MHz
t_w	Pulse duration	CLKAB high or low		3.8		3.8		ns
		CLKBA high or low		4.5		4.5		
		LEAB1, 2, 3, or 4 high		2.2		2.2		
		LEBA high		2.1		2.1		
		LEB1, 2, 3, or 4 high		2.4		2.4		
t_{su}	Setup time	Before CLKAB↑	A bus	2.5		2.5		ns
			CE_SEL0/1	3.2		3.2		
			$\overline{\text{CLKENAB}}$	3.2		3.2		
		Before LEAB1, 2, 3, or 4↓	A bus	3.6		3.6		
		Before CLKBA↑	B bus	3.8		3.8		
			$\overline{\text{CLKENB}}$	2.3		2.3		
			$\overline{\text{CLKENBA}}$	2.5		2.5		
			LEB1, 2, 3, or 4	4.3		4.3		
			SEL0/1	4.5		4.5		
		Before LEB1, 2, 3, or 4↓	B bus	3.2		3.2		
		Before LEBA↓	B bus	4		4		
			LEB1, 2, 3, or 4	4.4		4.4		
			SEL0/1	4.3		4.3		
t_h	Hold time	After CLKAB↑	A bus	0.5		0.5		ns
			CE_SEL0/1	1.1		1.1		
			$\overline{\text{CLKENAB}}$	0.5		0.5		
		After LEAB1, 2, 3, or 4↓	A bus	1.2		1.2		
		After CLKBA↑	B bus	1.3		1.3		
			$\overline{\text{CLKENB}}$	1		1		
			$\overline{\text{CLKENBA}}$	1		1		
			SEL0/1	0		0		
		After LEB1, 2, 3, or 4↓	B bus	1.5		1.5		
		After LEBA↓	B bus	0.4		0.4		
			SEL0/1	0.1		0.1		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

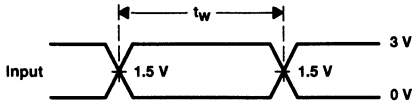
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABTH16460		SN74ABTH16460		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			160			160		160		MHz
t_{PLH}	B	A	2.5	3.6	5.9	2.5	7.1	2.5	6.5	ns
t_{PHL}			2	3.5	5.8	2	6.8	2	6.5	
t_{PZH}	$\overline{OEA}$	A	1.5	2.8	4.8	1.5	5.9	1.5	5.6	ns
t_{PZL}			1.5	2.6	4.6	1.5	5.5	1.5	5.2	
t_{PHZ}	$\overline{OEA}$	A	2.5	3.8	5.3	2.5	6	2.5	5.9	ns
t_{PLZ}			1.5	4.6	6.1	1.5	7	1.5	6.5	
t_{PLH}	A	B	2	3.2	5.2	2	6.2	2	5.7	ns
t_{PHL}			1.5	3.1	5.2	1.5	6.1	1.5	5.7	
t_{PZH}	$\overline{OEB}$	B	1.5	3.3	5.7	1.5	6.7	1.5	6.4	ns
t_{PZL}			1.5	3.2	5.5	1.5	6.6	1.5	6.3	
t_{PHZ}	$\overline{OEB}$	B	3	4.7	6.3	3	7.1	3	7	ns
t_{PLZ}			2	4	5.5	2	6.6	2	6.1	
t_{PZH}	$\overline{OEB1}$, $\overline{2}$, $\overline{3}$, $\overline{4}$	B	1.5	3	5.2	1.5	6	1.5	5.8	ns
t_{PZL}			1.5	2.9	4.9	1.5	5.9	1.5	5.6	
t_{PHZ}	$\overline{OEB1}$, $\overline{2}$, $\overline{3}$, $\overline{4}$	B	2.5	4	5.7	2.5	6.2	2.5	6.1	ns
t_{PLZ}			1.5	3.5	4.8	1.5	5.8	1.5	5.3	
t_{PLH}	CLKBA	A	1.5	4.2	6.7	1.5	8.1	1.5	7.4	ns
t_{PHL}			1.5	4.4	6.9	1.5	8.4	1.5	7.7	
t_{PLH}	CLKAB	B	2	3.4	5.6	2	6.8	2	6.2	ns
t_{PHL}			2	3.4	5.3	2	6.3	2	5.9	
t_{PLH}	LEBA	A	2	3	5	2	6.1	2	5.6	ns
t_{PHL}			2	3.1	4.8	2	5.8	2	5.3	
t_{PLH}	LEAB1, 2, 3, 4	B	2	3.2	5.2	2	6.3	2	5.8	ns
t_{PHL}			2	3.3	5	2	6.1	2	5.6	
t_{PLH}	LEBA1, 2, 3, 4	A	2.5	4	6.5	2.5	7.8	2.5	7.2	ns
t_{PHL}			2.5	4	6.1	2.5	7.5	2.5	6.8	
t_{PLH}	SEL	A	2	4.1	6.7	2	8.1	2	7.5	ns
t_{PHL}			2	3.8	6.2	2	7.3	2	6.9	

PARAMETER MEASUREMENT INFORMATION

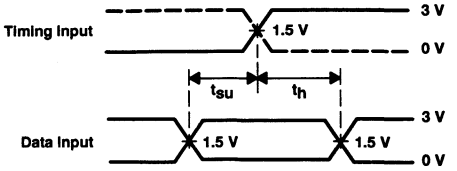


LOAD CIRCUIT

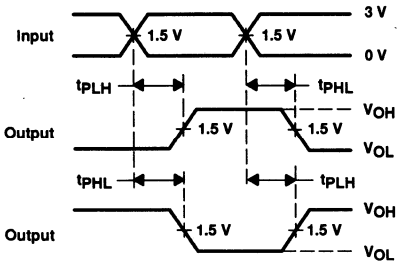
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



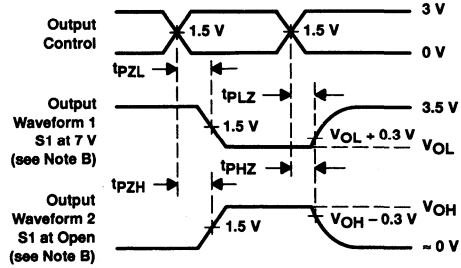
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



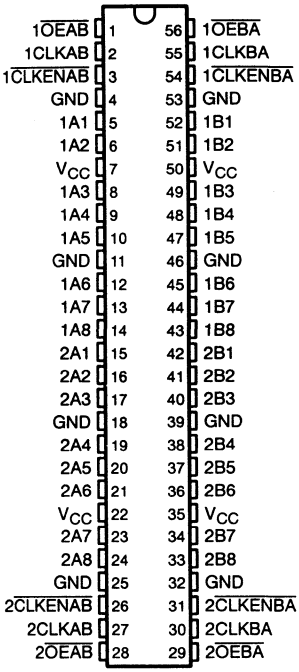
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16470 . . . WD PACKAGE
SN74ABT16470 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16470 are 16-bit registered transceivers that contain two sets of D-type flip-flops for temporary storage of data flowing in either direction. The 'ABT16470 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate clock (CLKAB or CLKBA) and output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs are provided for each register to permit independent control in either direction of data flow.

To avoid false clocking of the flip-flops, clock enable ($\overline{CLKEN}$) should not be switched from high to low while CLK is high.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16470 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16470 is characterized for operation from –40°C to 85°C.

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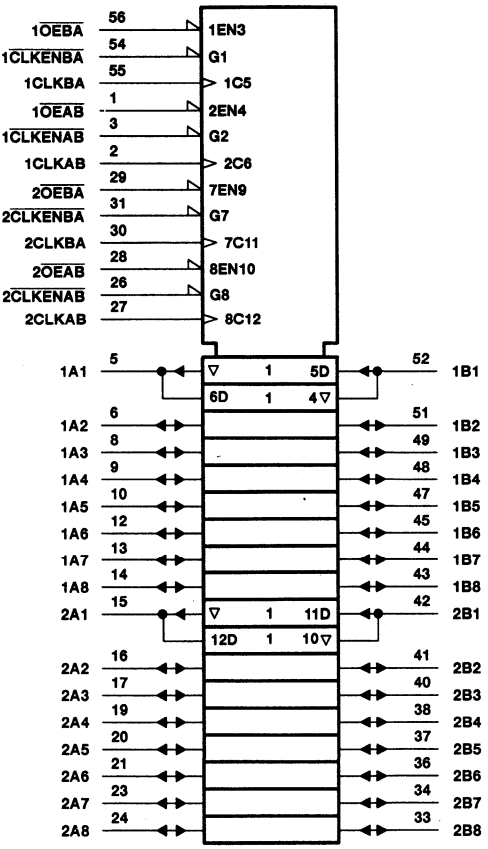
FUNCTION TABLE†

INPUTS				OUTPUT
$\overline{\text{CLKENAB}}$	CLKAB	$\overline{\text{OEAB}}$	A	B
H	X	X	X	Z
X	X	H	X	Z
L	L	L	X	B_0‡
L	↑	L	L	L
L	↑	L	H	H

† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{\text{CLKENBA}}$, CLKBA, and $\overline{\text{OEBA}}$.

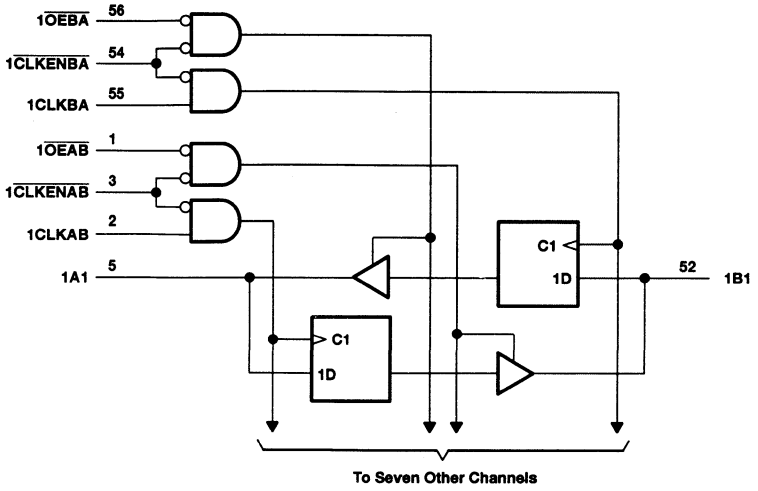
‡ Output level before the indicated steady-state input conditions were established

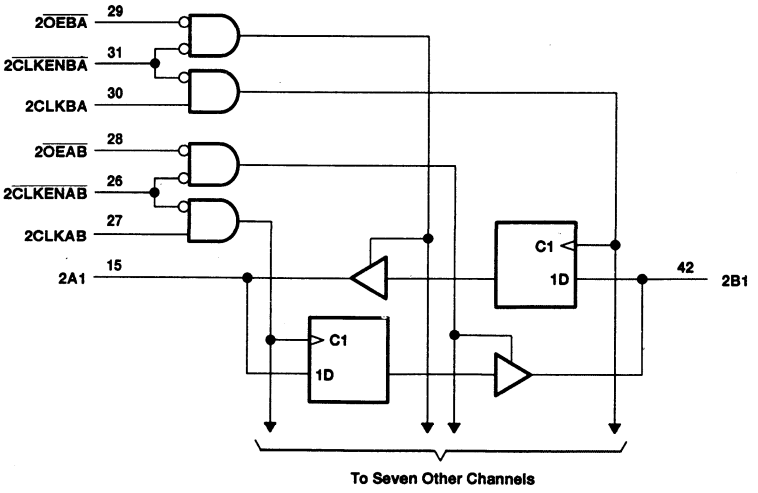
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16470 ..... 96 mA
SN74ABT16470 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16470		SN74ABT16470		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16470		SN74ABT16470		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–200	–50	–200	–50	–200	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			35		35		35	
			Outputs disabled			2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				0.5		0.5		0.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			8.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

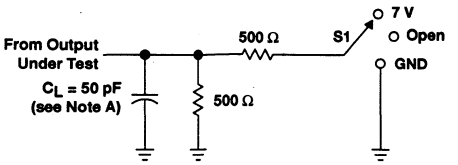
		V_{CC} = 5 V, T_A = 25°C		SN54ABT16470		SN74ABT16470		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	150	0	150	0	150	MHz
t_w#	Pulse duration, CLKAB or CLKBA high or low	3.3		3.3		3.3		ns
t_{su}	Setup time, data before CLKAB↑ or CLKBA↑	4		4		4		ns
t_h	Hold time, data after CLKAB↑ or CLKBA↑	1		1		1		ns

This parameter is characterized, but not production tested.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

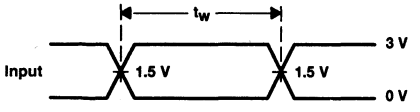
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16470		SN74ABT16470		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			150			150		150		MHz
t_{PLH}	CLK	A or B	1.4	3.1	4.8	1.4	5.1	1.4	4.9	ns
t_{PHL}			1.3	3.2	4.6	1.3	5.1	1.3	4.9	
t_{PZH}	$\overline{OE}$	A or B	1	3.1	4.3	1	5	1	4.9	ns
t_{PZL}			1.2	3.6	5.8	1.2	6.9	1.2	6.8	
t_{PHZ}	$\overline{OE}$	A or B	1.9	3.7	4.9	1.9	6	1.9	5.5	ns
t_{PLZ}			1.6	3.3	4.8	1.6	5.4	1.6	5.3	
t_{PZH}	$\overline{CLKEN}$	A or B	1	3.4	4.6	1	5.8	1	5.7	ns
t_{PZL}			1.2	3.9	6	1.2	7.3	1.2	7.2	
t_{PHZ}	$\overline{CLKEN}$	A or B	1.7	3.9	5.2	1.7	6.2	1.7	5.8	ns
t_{PLZ}			1.5	3.6	5.3	1.5	5.5	1.5	5.4	

PARAMETER MEASUREMENT INFORMATION

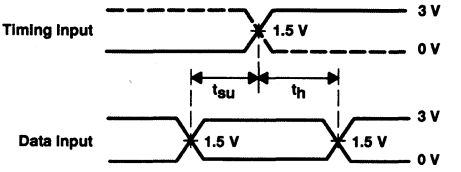


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

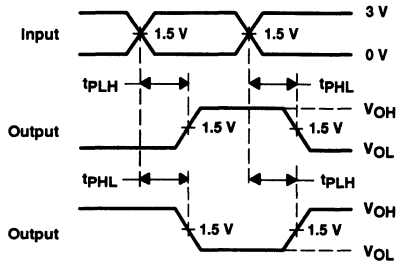
LOAD CIRCUIT



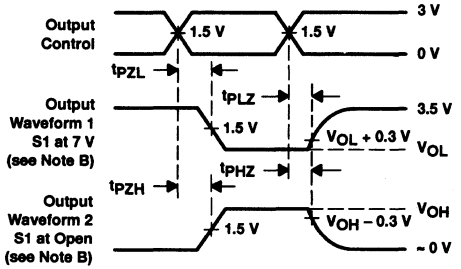
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



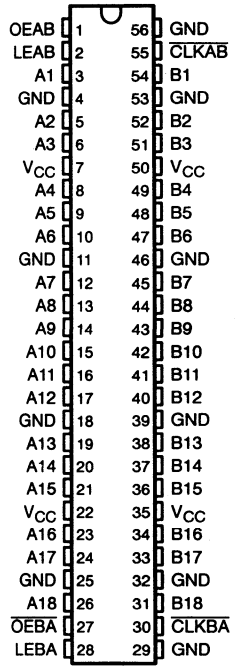
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- ***UBT*™ (Universal Bus Transceiver) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16500B . . . WD PACKAGE
SN74ABT16500B . . . DGG OR DL PACKAGE
(TOP VIEW)



description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes.

Data flow in each direction is controlled by output-enable (OEAB and $\overline{\text{OEBA}}$), latch-enable (LEAB and LEBA), and clock ($\overline{\text{CLKAB}}$ and $\overline{\text{CLKBA}}$) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if $\overline{\text{CLKAB}}$ is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the high-to-low transition of $\overline{\text{CLKAB}}$. OEAB is active-high. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B but uses $\overline{\text{OEBA}}$, LEBA, and $\overline{\text{CLKBA}}$. The output enables are complementary (OEAB is active high and $\overline{\text{OEBA}}$ is active low).

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TEXAS INSTRUMENTS

description (continued)

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

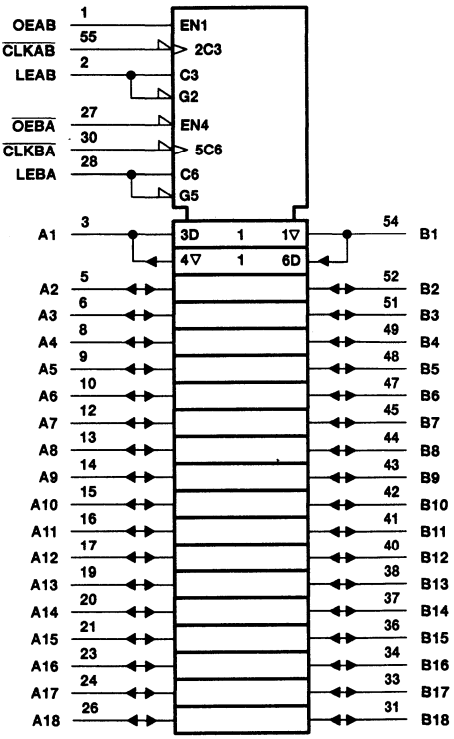
The SN54ABT16500B is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16500B is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

INPUTS				OUTPUT
OEAB	LEAB	$\overline{CLKAB}$	A	B
L	X	X	X	Z
H	H	X	L	L
H	H	X	H	H
H	L	↓	L	L
H	L	↓	H	H
H	L	H	X	B_0‡
H	L	L	X	B_0§

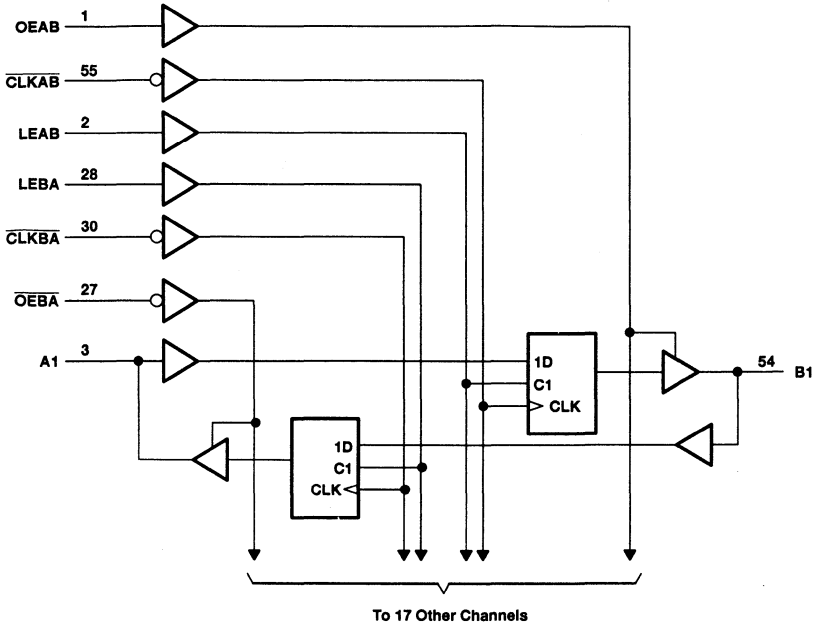
† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{OEBA}$, LEBA, and $\overline{CLKBA}$.
‡ Output level before the indicated steady-state input conditions were established
§ Output level before the indicated steady-state input conditions were established, provided that $\overline{CLKAB}$ was low before LEAB went low

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16500B ..... 96 mA
SN74ABT16500B ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16500B		SN74ABT16500B		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		µs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16500B		SN74ABT16500B		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±20		±20	
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{OZPU}§		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ or OE = X				±50		±50		±50	µA
I_{OZPD}§		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ or OE = X				±50		±50		±50	µA
I_{OZH}¶		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE} \ge$ 2 V, OE ≤ 0.8 V#				10		10		10	µA
I_{OZL}¶		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE} \ge$ 2 V, OE ≤ 0.8 V#				–10		–10		–10	µA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3		3		3	mA
			Outputs low			36		36		36	
			Outputs disabled			3		3		3	
ΔI_{CC}‖		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	µA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This parameter is characterized, but not production tested.
¶ The parameters I_{OZH} and I_{OZL} include the input leakage current.
# For V_{CC} between 2.1 V and 4 V, OE should be less than or equal to 0.5 V to ensure a low state.
‖ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

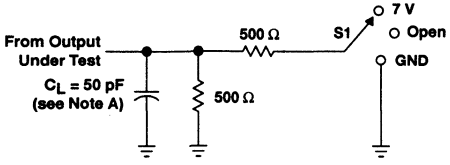
				SN54ABT16500B		SN74ABT16500B		UNIT
				MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			0	150	0	150	MHz
t_w†	Pulse duration	LEAB or LEBA high		2.5		2.5		ns
		$\overline{CLKAB}$ or $\overline{CLKBA}$ high or low		3		3		
t_{su}	Setup time	A before $\overline{CLKAB}$↓		3		3		ns
		B before $\overline{CLKBA}$↓		3		3		
		A before LEAB↓ or B before LEBA↓	$\overline{CLK}$ high	1		1		
			$\overline{CLK}$ low	2.5		2.5		
t_h	Hold time	A after $\overline{CLKAB}$↓ or B after $\overline{CLKBA}$↓		0		0		ns
		A after LEAB↓ or B after LEBA↓		2		2		

† This parameter is characterized, but not production tested.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

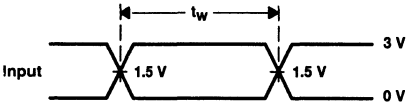
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16500B		SN74ABT16500B		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			150	200		150		150		MHz
t_{PLH}	A or B	B or A	1	2.5	3.6	1	4.2	1	4	ns
t_{PHL}			1	3.2	4.5	1	5.1	1	4.9	
t_{PLH}	LEAB or LEBA	B or A	1	3.2	4.5	1	5.6	1	5	ns
t_{PHL}			1	3.4	4.5	1	5.4	1	5	
t_{PLH}	$\overline{CLKAB}$ or $\overline{CLKBA}$	B or A	1	3.5	4.7	1	5.4	1	5.3	ns
t_{PHL}			1	3.5	4.7	1	5.4	1	5.3	
t_{PZH}	OEAB or $\overline{OEBA}$	B or A	1	3.4	4.6	1	5.3	1	5.1	ns
t_{PZL}			1.5	3.8	4.7	1.5	5.6	1.5	5.4	
t_{PHZ}	OEAB or $\overline{OEBA}$	B or A	1.5	4.5	5.7	1.5	6.9	1.5	6.5	ns
t_{PLZ}			1.4	3.4	4.7	1.4	5.8	1.4	5.4	

PARAMETER MEASUREMENT INFORMATION

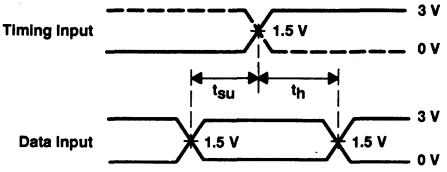


LOAD CIRCUIT

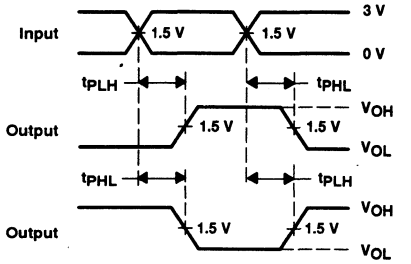
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



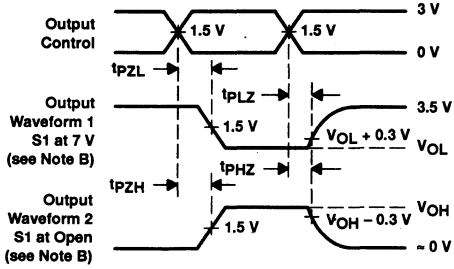
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



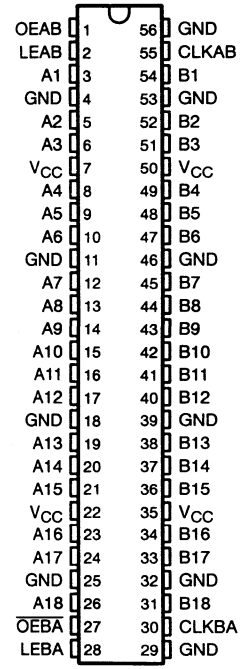
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- ***UBT*™ (Universal Bus Transceiver) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16501 . . . WD PACKAGE
SN74ABT16501 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

These 18-bit universal bus transceivers consist of storage elements that can operate either as D-type latches or D-type flip-flops to allow data flow in transparent or clocked modes.

Data flow in each direction is controlled by output-enable (OEAB and $\overline{\text{OEBA}}$), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B but uses $\overline{\text{OEBA}}$, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and $\overline{\text{OEBA}}$ is active low).

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor and $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sourcing/current-sinking capability of the driver.

description (continued)

The SN54ABT16501 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16501 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

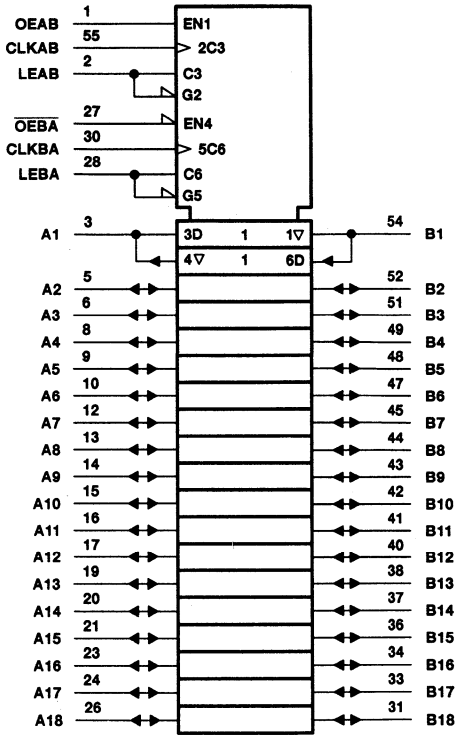
INPUTS				OUTPUT
OEAB	LEAB	CLKAB	A	B
L	X	X	X	Z
H	H	X	L	L
H	H	X	H	H
H	L	↑	L	L
H	L	↑	H	H
H	L	H	X	B_0‡
H	L	L	X	B_0§

† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{OEBA}$, LEBA, and CLKBA.

‡ Output level before the indicated steady-state input conditions were established, provided that CLKAB was high before LEAB went low

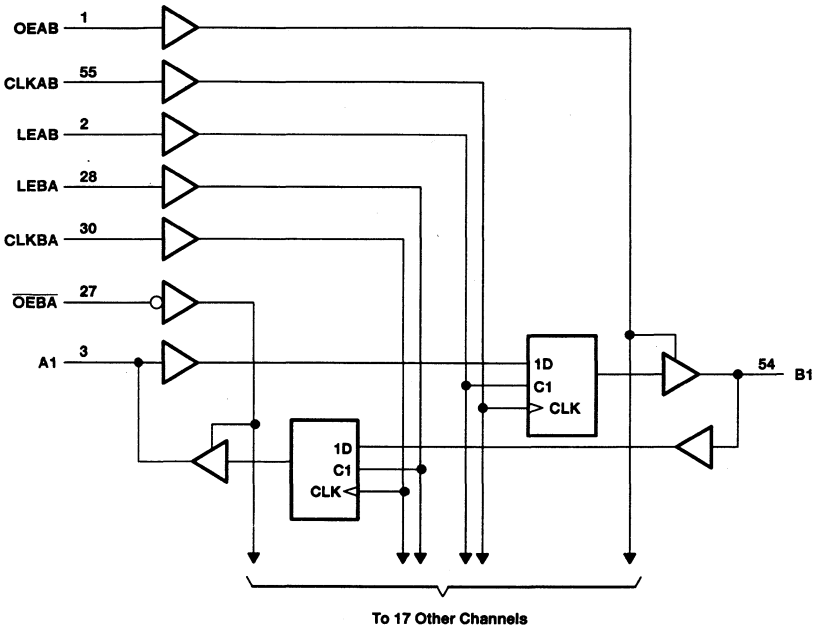
§ Output level before the indicated steady-state input conditions were established

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16501 ..... 96 mA
SN74ABT16501 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16501		SN74ABT16501		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16501		SN74ABT16501		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3		5		3	mA
			Outputs low			76		76		76	
			Outputs disabled			3.3		5.3		3.3	
ΔI_{CC}¶	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				5		6		5	mA
	A or B ports					1.5		1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			8						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

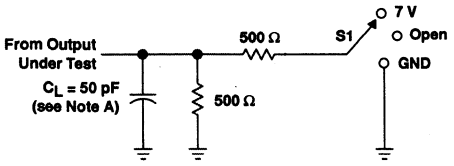
				SN54ABT16501		SN74ABT16501		UNIT
				MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency, CLKAB or CLKBA			0	105	0	105	MHz
t_w†	Pulse duration	LEAB or LEBA high		3.3		3.3		ns
		CLKAB or CLKBA high or low		4.7		4.7		
t_{su}	Setup time	A before CLKAB↑ or B before CLKBA↑		4		3.5		ns
		A before LEAB↓ or B before LEBA↓	CLK high	4		4		
			CLK low	1.5		1.5		
t_h	Hold time	A after CLKAB↑ or B after CLKBA↑		1		1		ns
		A after LEAB↓ or B after LEBA↓		2.5		2.5		

† This parameter is specified by design, but not production tested.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

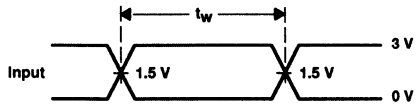
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16501		SN74ABT16501		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}	CLKAB or CLKBA		105	160		105		105		MHz
t_{PLH}	A or B	B or A	1	2.6	3.4	1	3.9	1	3.7	ns
t_{PHL}			1	2.6	3.4	1	4.1	1	4	
t_{PLH}	LEAB or LEBA	B or A	1.3	3.3	4.3	1.3	5.4	1.3	5.1	ns
t_{PHL}			1.4	3.1	4.1	1.4	4.6	1.4	4.4	
t_{PLH}	CLKAB or CLKBA	B or A	1.5	3.5	4.5	1.5	5.3	1.5	5	ns
t_{PHL}			1.3	3.1	4.1	1.3	4.6	1.3	4.4	
t_{PZH}	OEAB or $\overline{OEBA}$	B or A	1	3	4	1	4.8	1	4.7	ns
t_{PZL}			2.6	4.9	5.9	2.6	6.6	2.6	6.5	
t_{PHZ}	OEAB or $\overline{OEBA}$	B or A	1.6	3.9	4.9	1.6	5.9	1.6	5.8	ns
t_{PLZ}			1.1	3.4	4.4	1.1	5.1	1.1	4.9	

PARAMETER MEASUREMENT INFORMATION

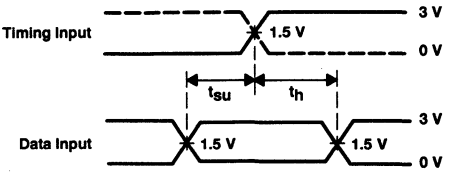


LOAD CIRCUIT

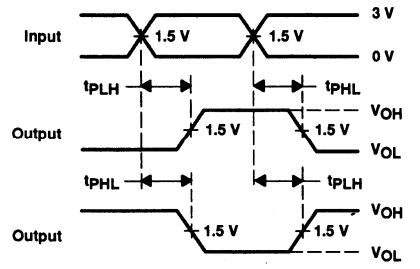
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



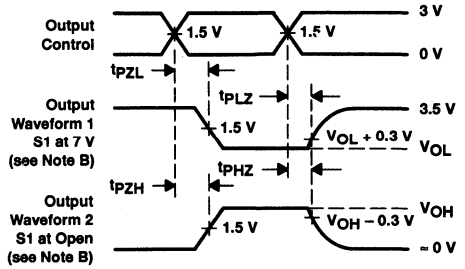
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



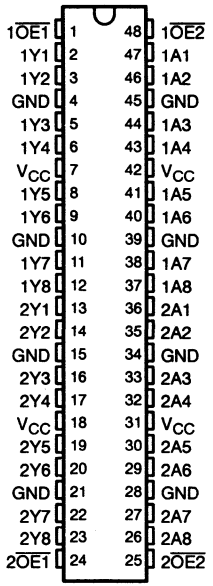
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16540 . . . WD PACKAGE
SN74ABT16540A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The SN54ABT16540 and SN74ABT16540A are inverting 16-bit buffers/drivers composed of two 8-bit sections with separate output-enable gates. These buffers and bus drivers provide a high-performance bus interface for wide data paths.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all corresponding outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16540 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16540A is characterized for operation from –40°C to 85°C.

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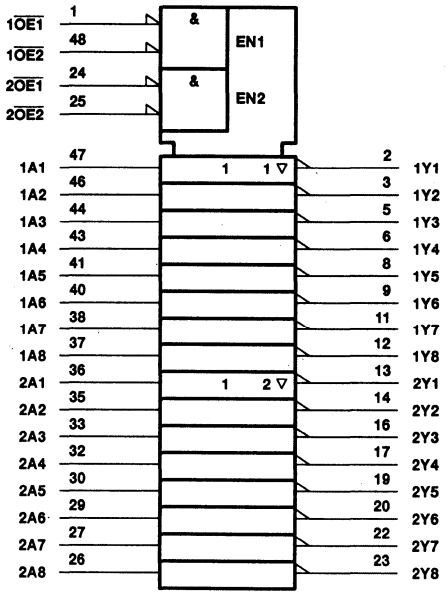
TEXAS INSTRUMENTS

FUNCTION TABLE
(each 8-bit section)

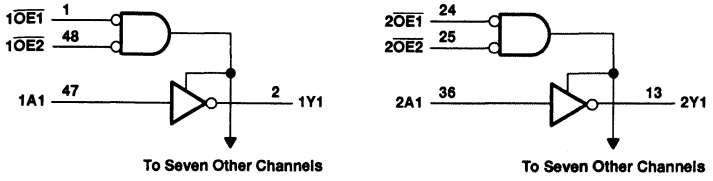
INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	H
L	L	H	L
H	X	X	Z
X	H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16540 ..... 96 mA
SN74ABT16540A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DGV package ..... 93°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16540		SN74ABT16540A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

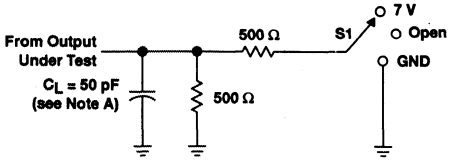
PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT16540		SN74ABT16540A		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
		I_{OH} = –32 mA	2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
		I_{OL} = 64 mA			0.55*				0.55	
V_{hys}				100						mV
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			10		50		10	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–50		–10	µA
I_{off}	V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3		2		3	mA
		Outputs low			34		32		34	
		Outputs disabled			3		2		3	
ΔI_{CC}§ Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1		1		1	mA
		Outputs disabled			0.05		0.05		0.05	
ΔI_{CC}§ Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	V_I = 2.5 V or 0.5 V			3.5						pF
C_o	V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

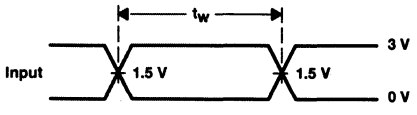
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16540		SN74ABT16540A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2.3	3.3	1	4.2	1	4.1	ns
t_{PHL}			1.1	2.5	4.1	1.1	4.4	1.1	4.3	
t_{PZH}	$\overline{OE}$	Y	1.1	3.1	4.2	1.1	5.2	1.1	5.1	ns
t_{PZL}			1.6	3.7	4.8	1.6	6	1.6	5.9	
t_{PHZ}	$\overline{OE}$	Y	1.6	4	5	1.6	5.4	1.6	5.7	ns
t_{PLZ}			1.4	3.2	4.4	1.4	4.7	1.4	4.7	

PARAMETER MEASUREMENT INFORMATION

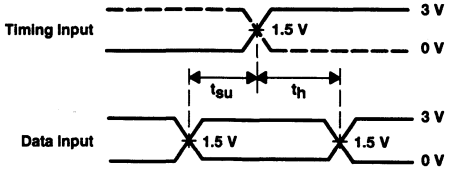


LOAD CIRCUIT

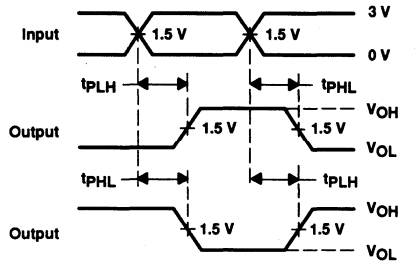
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



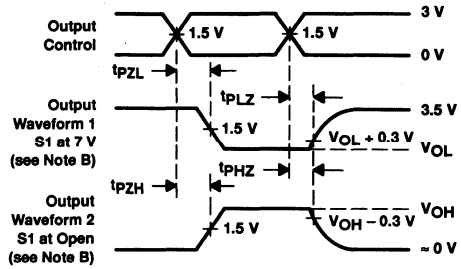
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
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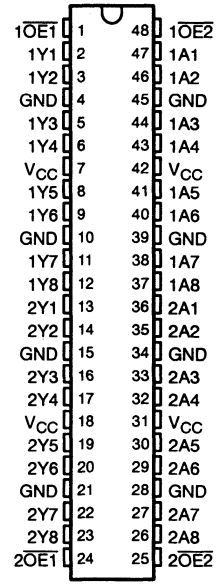
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Spacings**

SN54ABT16541 . . . WD PACKAGE
SN74ABT16541A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The SN54ABT16541 and SN74ABT16541A are noninverting 16-bit buffers composed of two 8-bit sections with separate output-enable signals. For either 8-bit buffer section, the two output-enable (1$\overline{OE1}$ and 1$\overline{OE2}$ or 2$\overline{OE1}$ and 2$\overline{OE2}$) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 8-bit buffer section are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16541 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16541A is characterized for operation from –40°C to 85°C.

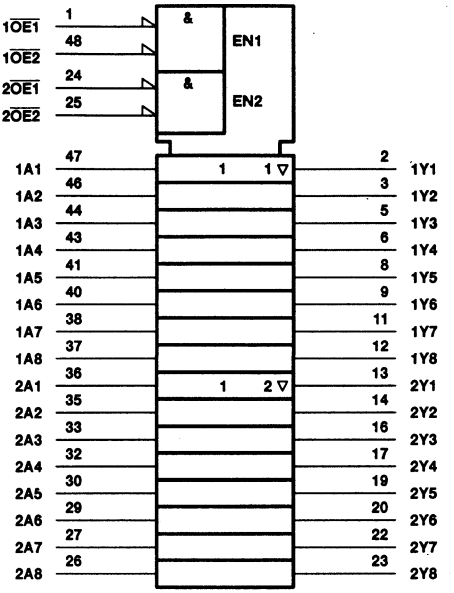
FUNCTION TABLE
(each 8-bit section)

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

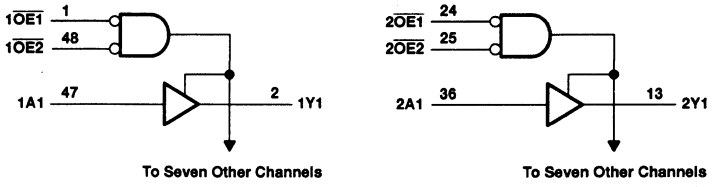
TEXAS INSTRUMENTS

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16541 ..... 96 mA
SN74ABT16541A ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DGV package ..... 93°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16541		SN74ABT16541A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

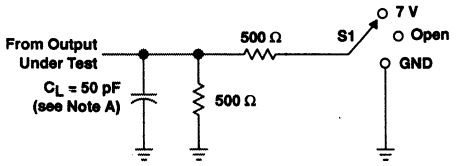
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16541		SN74ABT16541A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			10		50		10	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–50		–10	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3		2		3	mA
			Outputs low			34		32		34	
			Outputs disabled			3		2		3	
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1		1.5		1	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			3.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

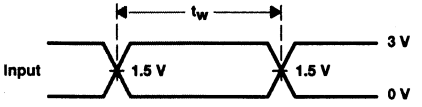
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16541		SN74ABT16541A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2.1	3	1	3.5	1	3.4	ns
t_{PHL}			1	2.5	3.6	1	4.3	1	4.2	
t_{PZH}	$\overline{OE}$	Y	1.3	3.2	4.3	1.3	5.3	1.3	5.2	ns
t_{PZL}			1.6	3.8	4.7	1.6	6.2	1.6	6	
t_{PHZ}	$\overline{OE}$	Y	1.3	4.1	4.8	1.3	5.4	1.3	5.4	ns
t_{PLZ}			1	3.3	4	1	4.3	1	4.3	

PARAMETER MEASUREMENT INFORMATION

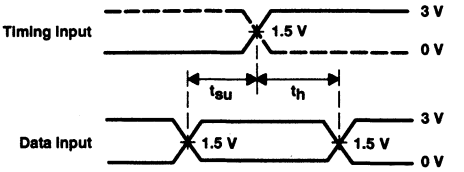


LOAD CIRCUIT

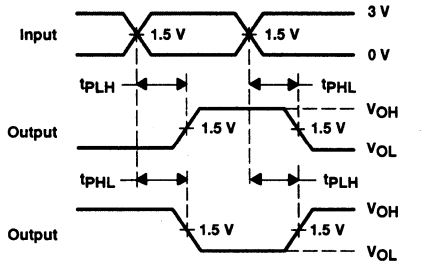
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



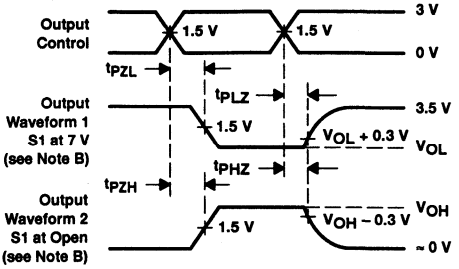
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



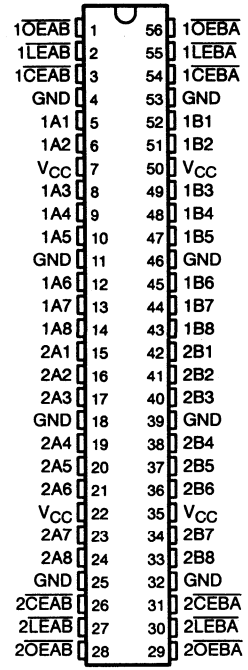
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16543 . . . WD PACKAGE
SN74ABT16543 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16543 16-bit registered transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. The 'ABT16543 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable ($\overline{LEAB}$ or $\overline{LEBA}$) and output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable ($\overline{CEAB}$) input must be low to enter data from A or to output data from B. If $\overline{CEAB}$ is low and $\overline{LEAB}$ is low, the A-to-B latches are transparent; a subsequent low-to-high transition of $\overline{LEAB}$ puts the A latches in the storage mode. With $\overline{CEAB}$ and $\overline{OEAB}$ both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$ inputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16543 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16543 is characterized for operation from –40°C to 85°C.

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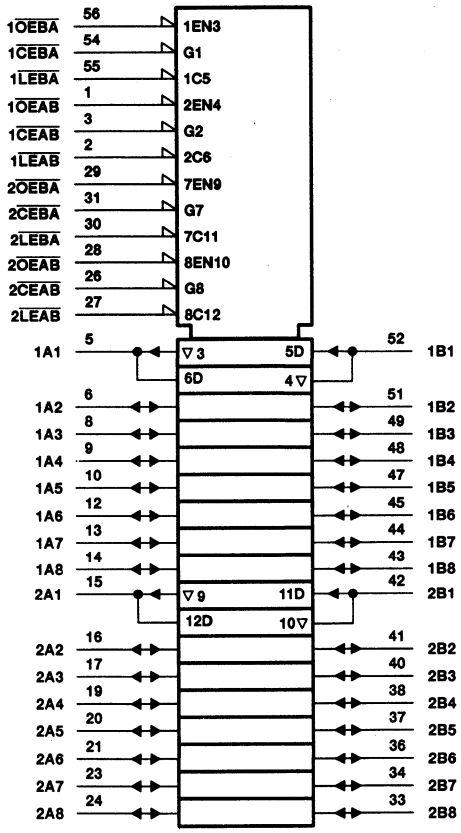
TEXAS INSTRUMENTS

FUNCTION TABLE† (each 8-bit section)

INPUTS				OUTPUT
$\overline{CEAB}$	$\overline{LEAB}$	$\overline{OEAB}$	A	B
H	X	X	X	Z
X	X	H	X	Z
L	H	L	X	B_0‡
L	L	L	L	L
L	L	L	H	H

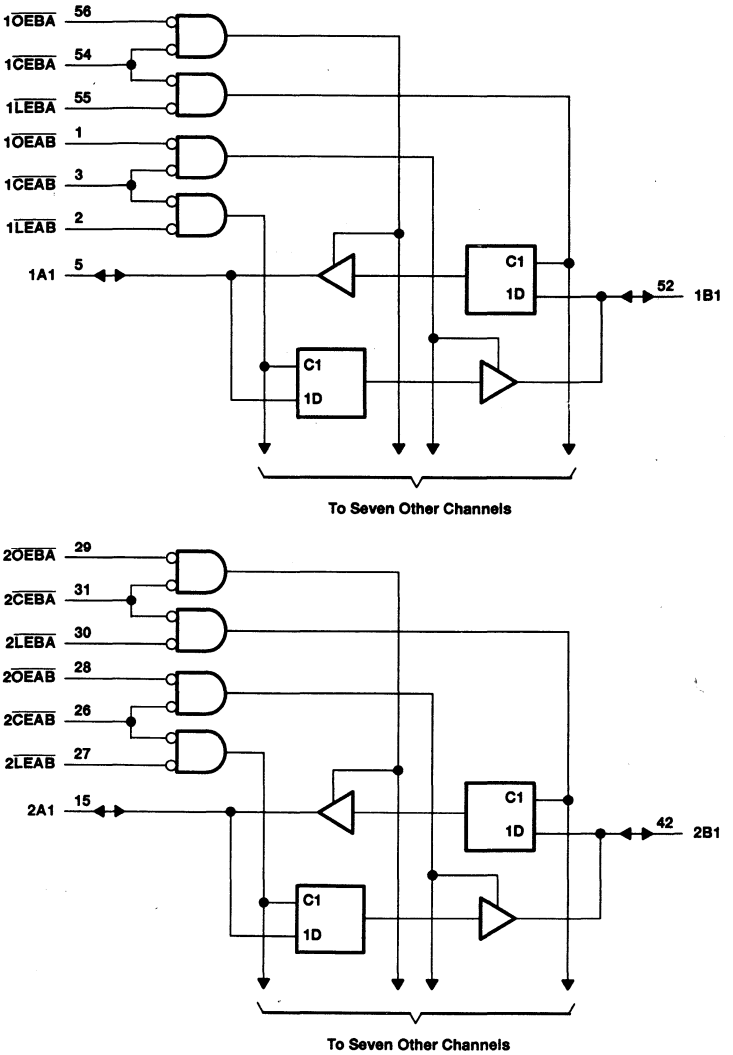
† A-to-B data flow is shown; B-to-A flow control is the same except that it uses $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$.
‡ Output level before the indicated steady-state input conditions were established

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16543 ..... 96 mA
SN74ABT16543 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16543		SN74ABT16543		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16543		SN74ABT16543		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50**		10		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50**		–10		–50	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–200	–50	–200	–50	–200	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			35		35		35	
			Outputs disabled			2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				0.5		0.5		0.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			8.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
** These limits apply only to the SN74ABT16543.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C		SN54ABT16543		SN74ABT16543		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low		4		4		4		ns
t_{su}	Setup time, data before $\overline{LEAB}$↑ or $\overline{LEBA}$↑	High	1.5		1.5		1.5		ns
		Low	3.5		3.5		3.5		
t_h	Hold time, data after $\overline{LEAB}$↑ or $\overline{LEBA}$↑	High	1.5		1.5		1.5		ns
		Low	2		2		2		

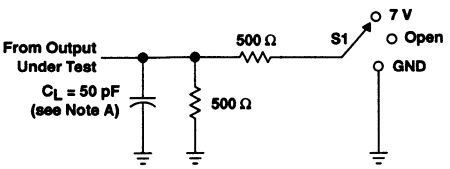
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16543					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	0.8	2.5	3.3	0.8	3.9	ns
t_{PHL}			0.9	2.7	4.4	0.9	5.2	
t_{PLH}	$\overline{LE}$	A or B	1	3.1	4.3	1	5.3	ns
t_{PHL}			1.2	3.3	4.8	1.2	5.7	
t_{PZH}	$\overline{OE}$	A or B	0.8	3.4	4.3	0.8	5.3	ns
t_{PZL}			1.1	3.8	7	1.1	7.9	
t_{PHZ}	$\overline{OE}$	A or B	1.9	4	6.3	1.9	7.2	ns
t_{PLZ}			1.6	3.3	4.6	1.6	5	
t_{PZH}	$\overline{CE}$	A or B	0.9	3.8	4.9	0.9	6.3	ns
t_{PZL}			1.2	4.2	6.8	1.2	7.9	
t_{PHZ}	$\overline{CE}$	A or B	2	4.5	6.4	2	7.3	ns
t_{PLZ}			1.7	3.9	5.1	1.7	5.6	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

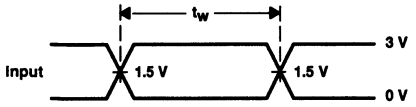
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16543					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1	2.5	3.3	1	3.8	ns
t_{PHL}			1	2.7	4.4	1	5.1	
t_{PLH}	$\overline{LE}$	A or B	1	3.1	4.3	1	5.2	ns
t_{PHL}			1.2	3.3	4.8	1.2	5.6	
t_{PZH}	$\overline{OE}$	A or B	1	3.4	4.3	1	5.2	ns
t_{PZL}			1.1	3.8	5.9	1.1	7	
t_{PHZ}	$\overline{OE}$	A or B	1.9	4	5	1.9	5.7	ns
t_{PLZ}			1.6	3.3	4.2	1.6	4.6	
t_{PZH}	$\overline{CE}$	A or B	1	3.8	4.9	1	6.2	ns
t_{PZL}			1.2	4.2	6.5	1.2	7.8	
t_{PHZ}	$\overline{CE}$	A or B	2	4.5	5.6	2	6.6	ns
t_{PLZ}			1.7	3.9	5.1	1.7	5.4	

PARAMETER MEASUREMENT INFORMATION

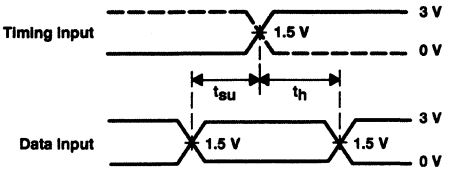


LOAD CIRCUIT

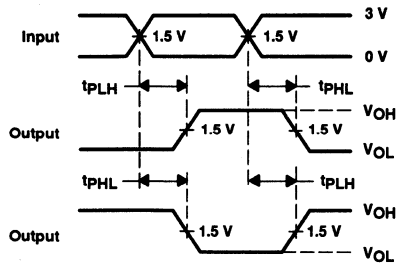
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



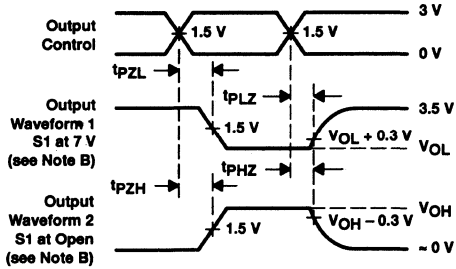
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



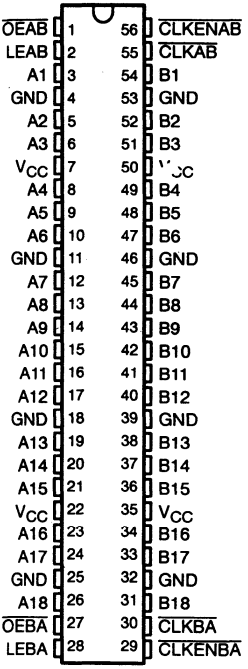
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- ***UBT*™ (Universal Bus Transceiver) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, Clocked, or Clock-Enabled Mode**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16600 . . . WD PACKAGE
SN74ABT16600 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, clocked, and clock-enabled modes.

Data flow in each direction is controlled by output-enable ($\overline{OEAB}$ and $\overline{OEBA}$), latch-enable (LEAB and LEBA), and clock ($\overline{CLKAB}$ and $\overline{CLKBA}$) inputs. The clock can be controlled by the clock-enable ($\overline{CLKENAB}$ and $\overline{CLKENBA}$) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if $\overline{CLKAB}$ is held at a high or low logic level. If LEAB is low, the A-bus data is stored in the latch/flip-flop on the high-to-low transition of $\overline{CLKAB}$. Output enable $\overline{OEAB}$ is active low. When $\overline{OEAB}$ is low, the outputs are active. When $\overline{OEAB}$ is high, the outputs are in the high-impedance state.

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description (continued)

Data flow for B to A is similar to that of A to B, but uses $\overline{OEBA}$, LEBA, $\overline{CLKBA}$, and $\overline{CLKENBA}$.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16600 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16600 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

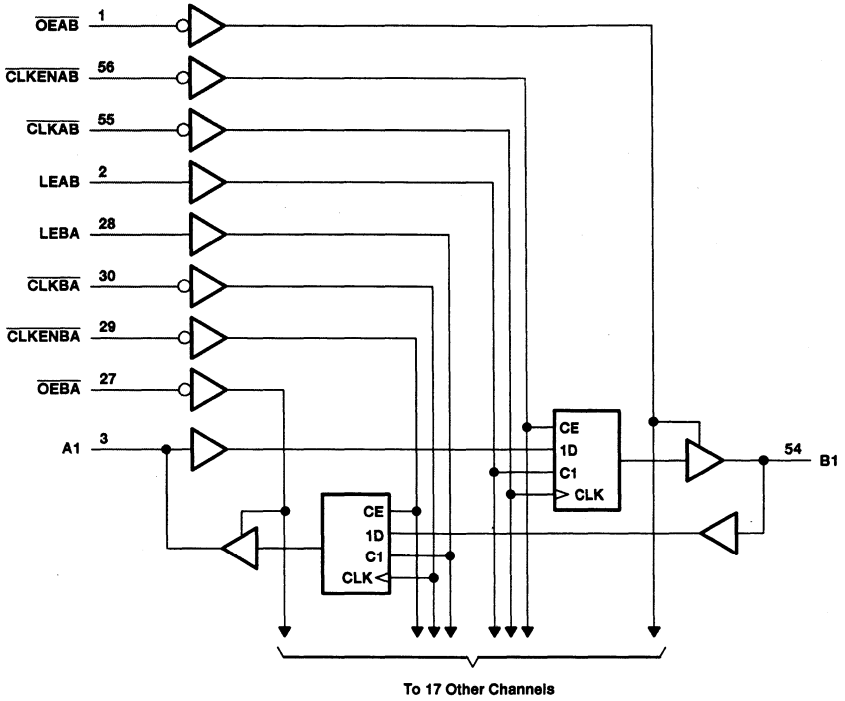
INPUTS					OUTPUT
$\overline{CLKENAB}$	$\overline{OEAB}$	LEAB	$\overline{CLKAB}$	A	B
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	B_0‡
H	L	L	X	X	B_0‡
L	L	L	↓	L	L
L	L	L	↓	H	H
L	L	L	H	X	B_0‡
L	L	L	L	X	B_0§

† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{OEBA}$, LEBA, $\overline{CLKBA}$, and $\overline{CLKENBA}$.

‡ Output level before the indicated steady-state input conditions were established

§ Output level before the indicated steady-state input conditions were established, provided that $\overline{CLKAB}$ was low before LEAB went low

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16600 ..... 96 mA
SN74ABT16600 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16600		SN74ABT16600		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16600		SN74ABT16600		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±20		±20		±20	
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{OZH}§		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}§		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3		3		3	mA
			Outputs low			36		36		36	
			Outputs disabled			3		3		3	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	µA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

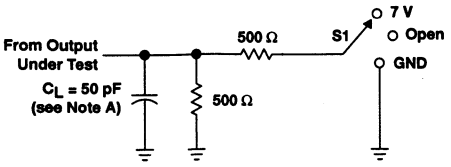
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54ABT16600		SN74ABT16600		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	150	0	150	MHz
t_w	Pulse duration	LEAB or LEBA high	2.5		2.5		ns
		$\overline{CLKAB}$ or $\overline{CLKBA}$ high or low	3		3		
t_{su}	Setup time	A before $\overline{CLKAB}$↓ or B before $\overline{CLKBA}$↓	3		3		ns
		A before LEAB↓ or B before LEBA↓	2.5		2.5		
		$\overline{CLKEN}$ before CLK↓	3		2.5		
t_h	Hold time	A after $\overline{CLKAB}$↓ or B after $\overline{CLKBA}$↓	0		0		ns
		A after LEAB↓ or B after LEBA↓	2		2		
		$\overline{CLKEN}$ after CLK↓	1		1		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

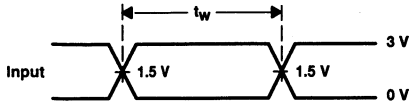
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16600		SN74ABT16600		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			150			150		150		MHz
t_{PLH}	A or B	B or A	1.5	2.5	3.6	1.5	4.2	1.5	4	ns
t_{PHL}			1.5	3.2	4.5	1.5	5.1	1.5	4.9	
t_{PLH}	LEAB or LEBA	B or A	2	3.2	4.5	2	5.6	2	5	ns
t_{PHL}			2	3.4	4.5	2	5.4	2	5	
t_{PLH}	$\overline{CLKAB}$ or $\overline{CLKBA}$	B or A	2	3.5	4.7	2	5.4	2	5.3	ns
t_{PHL}			2	3.5	4.3	2	5.2	2	5	
t_{PZH}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	1.5	3.4	4.6	1.5	5.3	1.5	5.1	ns
t_{PZL}			2	3.8	4.7	2	5.6	2	5.4	
t_{PHZ}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	2	4.5	5.4	2	6.6	2	6.2	ns
t_{PLZ}			1.5	3.4	4.7	1.5	5.8	1.5	5.4	

PARAMETER MEASUREMENT INFORMATION

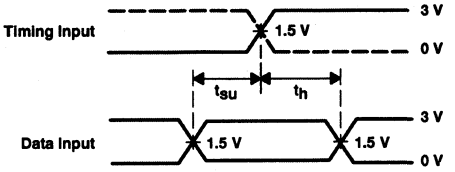


LOAD CIRCUIT

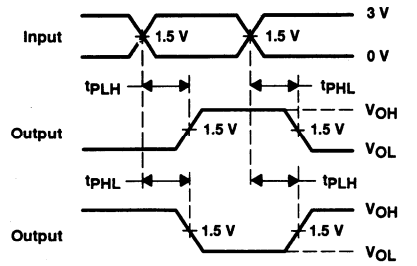
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



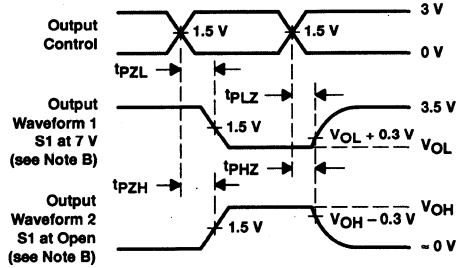
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



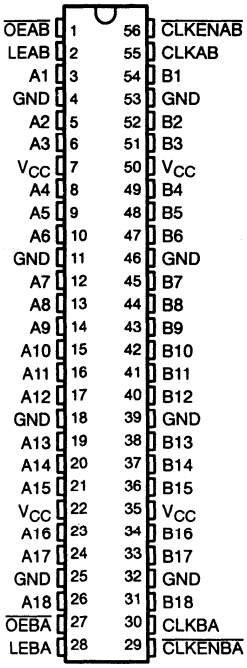
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- ***UBT*™ (Universal Bus Transceiver) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, Clocked, or Clock-Enabled Mode**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16601 . . . WD PACKAGE
SN74ABT16601 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, clocked, and clock-enabled modes.

Data flow in each direction is controlled by output-enable ($\overline{OEAB}$ and $\overline{OEBA}$), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable ($\overline{CLKENAB}$ and $\overline{CLKENBA}$) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. Output enable $\overline{OEAB}$ is active low. When $\overline{OEAB}$ is low, the outputs are active. When $\overline{OEAB}$ is high, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B, but uses $\overline{OEBA}$, LEBA, CLKBA, and $\overline{CLKENBA}$.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16601 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16601 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

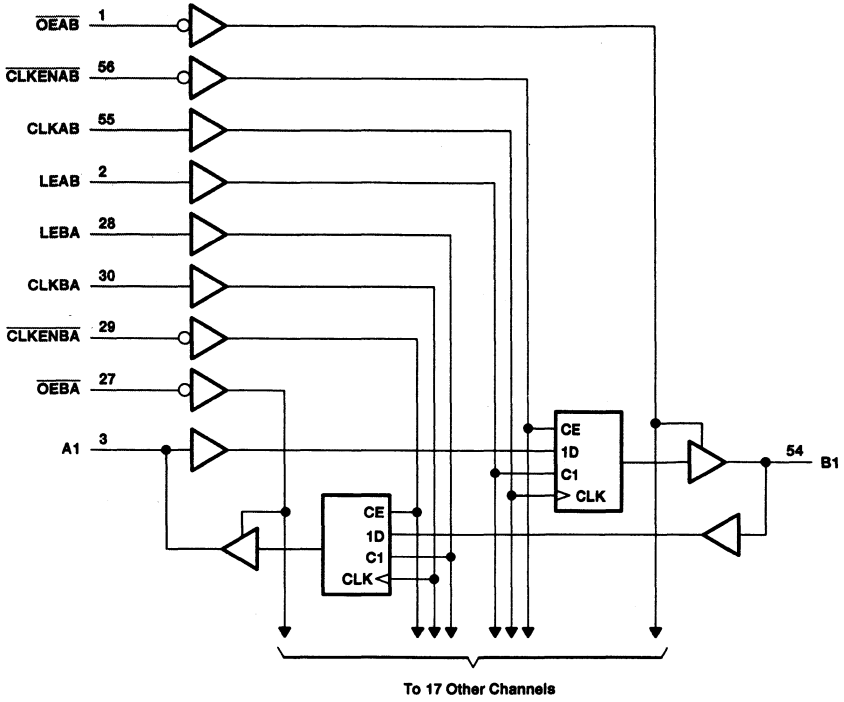
INPUTS					OUTPUT
$\overline{CLKENAB}$	$\overline{OEAB}$	LEAB	CLKAB	A	B
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	B_0‡
H	L	L	X	X	B_0‡
L	L	L	↑	L	L
L	L	L	↑	H	H
L	L	L	L	X	B_0‡
L	L	L	H	X	B_0§

† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{OEBA}$, LEBA, CLKBA, and $\overline{CLKENBA}$.

‡ Output level before the indicated steady-state input conditions were established

§ Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16601	96 mA
SN74ABT16601	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16601		SN74ABT16601		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16601		SN74ABT16601		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±20**		±100		±20	
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{OZH}§		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}§		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1.9	3		2		3	mA
			Outputs low		28	36		35		36	
			Outputs disabled		1.6	3		2		3	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50				50	µA
								1.5			mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
** This limit applies only to the SN74ABT16601.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN54ABT16601		SN74ABT16601		UNIT
				MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			0	150	0	150	MHz
t_w	Pulse duration	LEAB or LEBA high		2.5		2.5		ns
		CLKAB or CLKBA high or low		3		3		
t_{su}	Setup time	A before CLKAB↑ or B before CLKBA↑		4.6		4		ns
		A before LEAB↓ or B before LEBA↓	CLK high	2.5		2.5		
			CLK low	1.3		1		
		$\overline{CLKEN}$ before CLK↑		2.9		2.5		
t_h	Hold time	A after CLKAB↑ or B after CLKBA↑		0.4		0		ns
		A after LEAB↓ or B after LEBA↓		2.8		2		
		$\overline{CLKEN}$ after CLK↑		0		0		

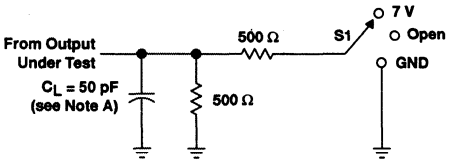
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16601					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150	200		150		MHz
t_{PLH}	A or B	B or A	1.5	2.5	4.1	1	4.6	ns
t_{PHL}			1.5	3.4	4.7	1	5.1	
t_{PLH}	LEAB or LEBA	B or A	2	3.4	4.7	1	5.6	ns
t_{PHL}			2	3.7	5	1	5.5	
t_{PLH}	CLKAB or CLKBA	B or A	1.5	3.2	4.5	1	5.2	ns
t_{PHL}			1.5	3.2	4.4	1	5	
t_{PZH}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	2	4	5	1	5.7	ns
t_{PZL}			2	4.2	5.6	1	6	
t_{PHZ}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	2	4.5	5.8	1	6.8	ns
t_{PLZ}			1.5	3.4	5.3	1	6.3	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

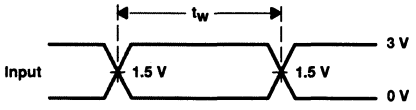
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16601					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150	200		150		MHz
t_{PLH}	A or B	B or A	1.5	2.5	3.6	1.5	4	ns
t_{PHL}			1.5	3.4	4.7	1.5	4.9	
t_{PLH}	LEAB or LEBA	B or A	2	3.4	4.7	2	5	ns
t_{PHL}			2	3.7	5	2	5.2	
t_{PLH}	CLKAB or CLKBA	B or A	1.5	3.2	4.5	1.5	4.7	ns
t_{PHL}			1.5	3.2	4.4	1.5	4.6	
t_{PZH}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	2	4	5	2	5.5	ns
t_{PZL}			2	4.2	5.6	2	5.8	
t_{PHZ}	$\overline{OEAB}$ or $\overline{OEBA}$	B or A	2	4.5	5.4	2	6.2	ns
t_{PLZ}			1.5	3.4	4.7	1.5	5.4	

PARAMETER MEASUREMENT INFORMATION

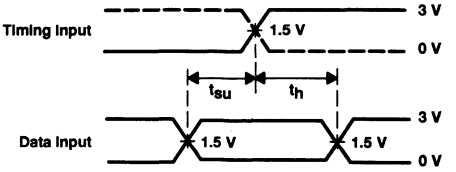


LOAD CIRCUIT

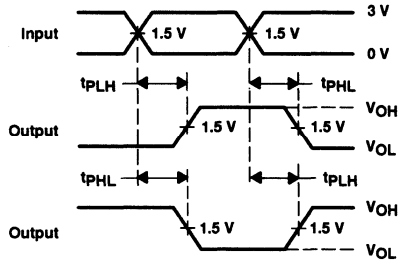
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



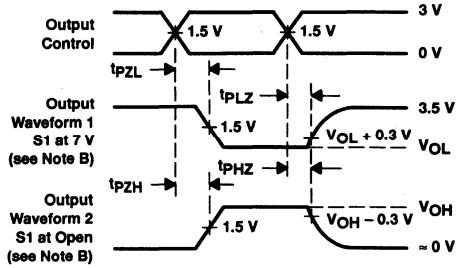
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



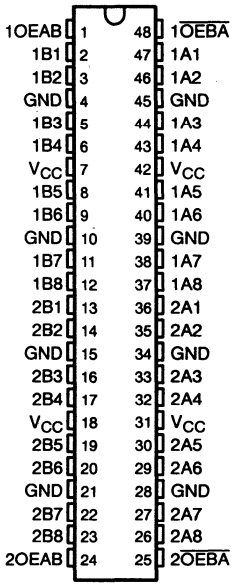
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16623 . . . WD PACKAGE
SN74ABT16623 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16623 are 16-bit transceivers designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing. The 'ABT16623 provide true data at the outputs.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and $\overline{OEBA}$) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability of storing data by simultaneously enabling OEAB and $\overline{OEBA}$. Each output reinforces its input in this configuration. When both OEAB and $\overline{OEBA}$ are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (32 total) remain at their last states.

description (continued)

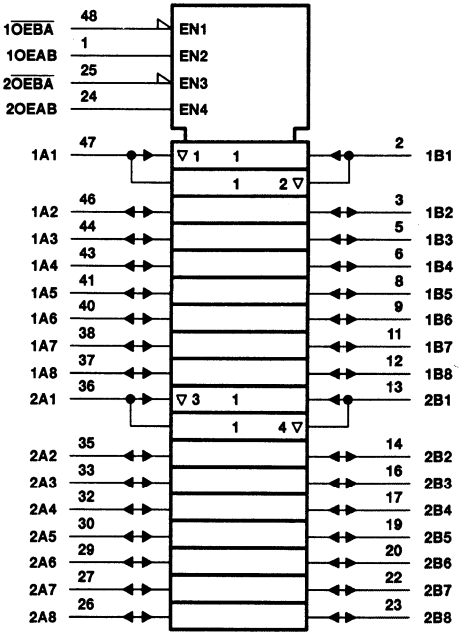
To ensure the high-impedance state during power up or power down, $\overline{OEBA}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT16623 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16623 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 8-bit section)

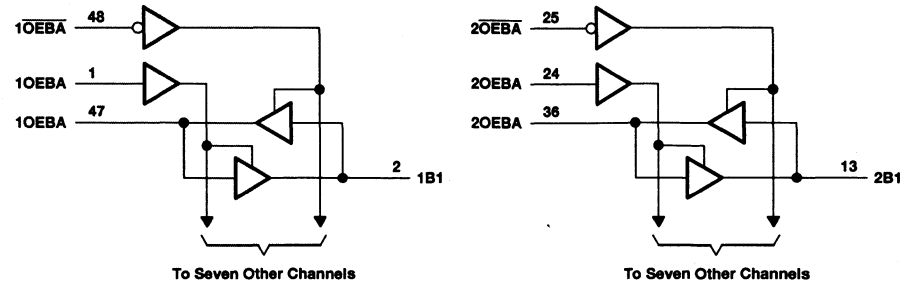
INPUTS		OPERATION
$\overline{OEBA}$	OEAB	
L	L	B data to A bus
L	H	B data to A bus, A data to B bus
H	L	Isolation
H	H	A data to B bus

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16623 ..... 96 mA
SN74ABT16623 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16623		SN74ABT16623		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

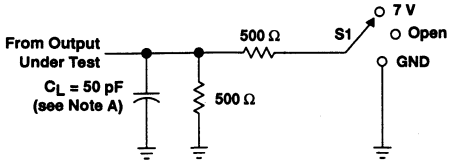
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16623		SN74ABT16623		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			35		35		35	
			Outputs disabled			2		2		2	
ΔI_{CC}¶	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1		1.5		1	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			8						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

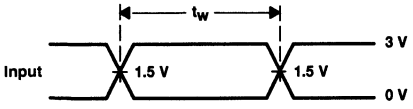
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16623		SN74ABT16623		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	2	3.2	1	6.7	1	3.6	ns
t_{PHL}			1	2.2	3.4	1	4.4	1	4.3	
t_{PZH}	$\overline{OEBA}$ or OEAB	A or B	1.1	3	4	1.1	5	1.1	4.9	ns
t_{PZL}			1.4	3.3	4.9	1	6.2	1.4	6	
t_{PHZ}	$\overline{OEBA}$ or OEAB	A or B	1	3.5	4.9	1	6.2	1	6	ns
t_{PLZ}			1.4	2.8	4.7	1.4	5.6	1.4	5.4	

PARAMETER MEASUREMENT INFORMATION

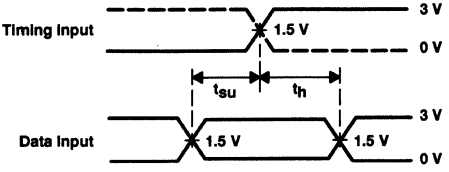


LOAD CIRCUIT

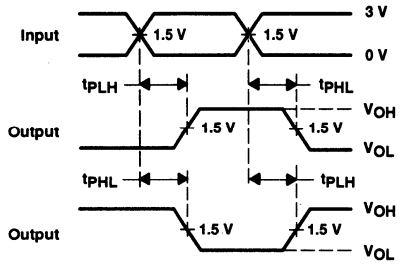
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



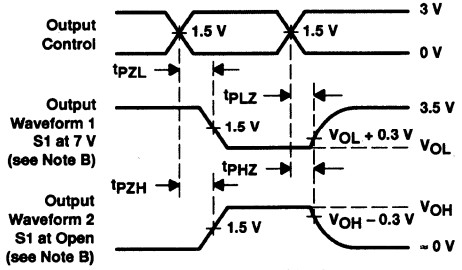
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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- **Flow-Through Architecture Optimizes PCB Layout**
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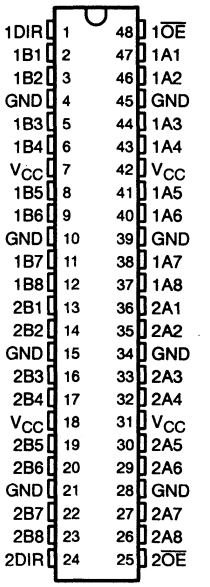
SN54ABT16640 . . . WD PACKAGE
SN74ABT16640 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16640 are inverting 16-bit transceivers designed for asynchronous communication between data buses.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (1DIR and 2DIR) inputs. The output-enable (1$\overline{OE}$ and 2$\overline{OE}$) inputs can be used to disable the device so that the buses are effectively isolated.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16640 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16640 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 8-bit section)

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	$\overline{B}$ data to A bus
L	H	$\overline{A}$ data to B bus
H	X	Isolation

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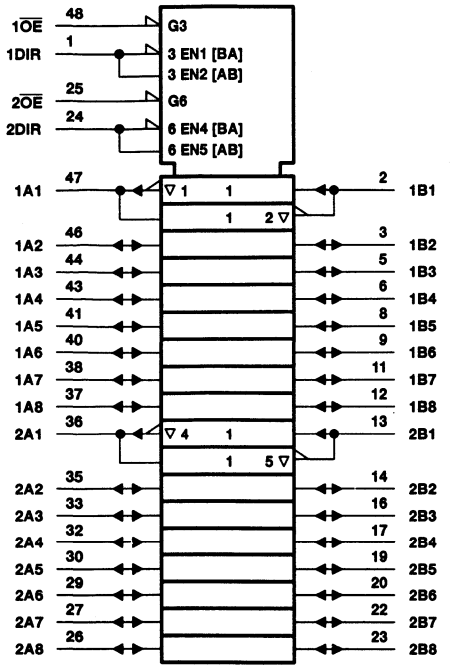
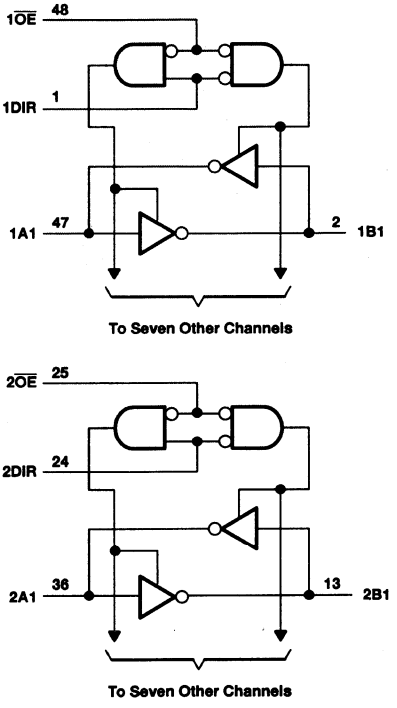
TEXAS INSTRUMENTS

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16640 ..... 96 mA
SN74ABT16640 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16640		SN74ABT16640		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16640		SN74ABT16640		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–40	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			32		32		32	
			Outputs disabled			2		2		2	
ΔI_{CC}¶	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1		1.5		1	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			8						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

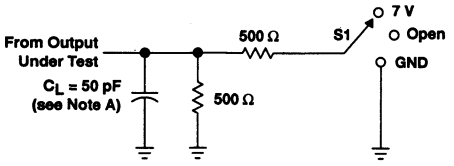
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16640					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	0.5	2.5	4.1	0.5	5.2	ns
t_{PHL}			0.5	2.8	4	0.5	4.5	
t_{PZH}	$\overline{OE}$	A or B	0.5	3.5	5.2	0.5	6.2	ns
t_{PZL}			0.5	3.9	6	0.5	7.4	
t_{PHZ}	$\overline{OE}$	A or B	0.5	3.8	6.8	0.5	7.9	ns
t_{PLZ}			0.5	3	4.5	0.5	5	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

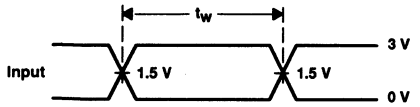
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16640					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1	2.5	3.4	1	4.3	ns
t_{PHL}			1.1	2.8	3.6	1.1	3.9	
t_{PZH}	$\overline{OE}$	A or B	1.2	3.5	4.5	1.2	5.5	ns
t_{PZL}			1.5	3.9	5	1.5	6.3	
t_{PHZ}	$\overline{OE}$	A or B	1.8	3.8	4.8	1.8	6.3	ns
t_{PLZ}			1.5	3	3.9	1.5	4.2	

PARAMETER MEASUREMENT INFORMATION

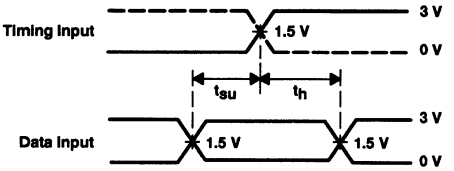


LOAD CIRCUIT

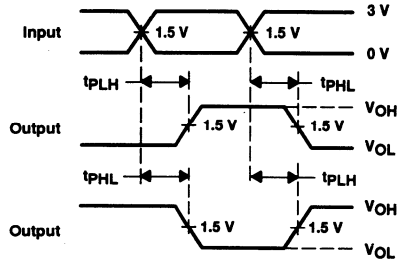
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



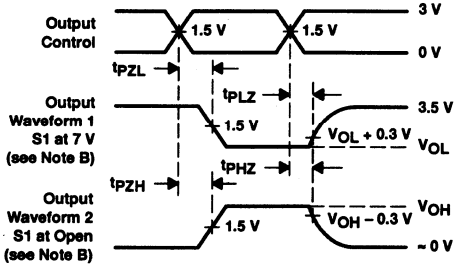
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



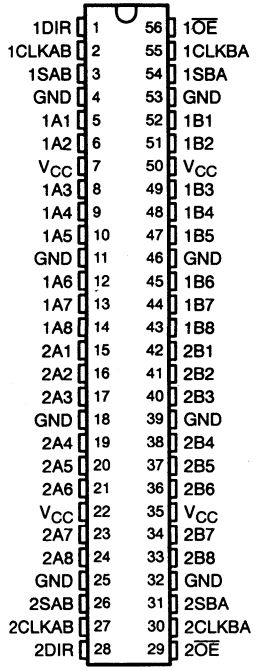
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16646 . . . WD PACKAGE
SN74ABT16646 . . . DL PACKAGE
(TOP VIEW)



description

The 'ABT16646 consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT16646.

Output-enable ($\overline{OE}$) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. The direction control (DIR) determines which bus receives data when $\overline{OE}$ is low. In the isolation mode ($\overline{OE}$ high), A data can be stored in one register and/or B data can be stored in the other register.

When an output function is disabled, the input function is still enabled and can be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

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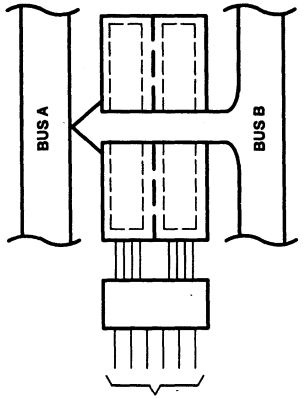
description (continued)

The SN54ABT16646 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16646 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

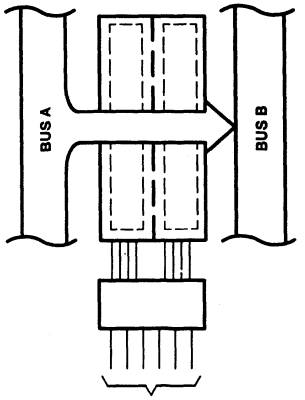
INPUTS						DATA I/O†		OPERATION OR FUNCTION
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	
X	X	↑	X	X	X	Input	Unspecified	Store A, B unspecified†
X	X	X	↑	X	X	Unspecified	Input	Store B, A unspecified†
H	X	↑	↑	X	X	Input	Input	Store A and B data
H	X	H or L	H or L	X	X	Input disabled	Input disabled	Isolation, hold storage
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
L	H	X	X	L	X	Input	Output	Real-time A data to B Bus
L	H	H or L	X	H	X	Input	Output	Stored A data to bus

† The data-output functions may be enabled or disabled by various signals at $\overline{OE}$ or DIR. Data-input functions are always enabled, i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



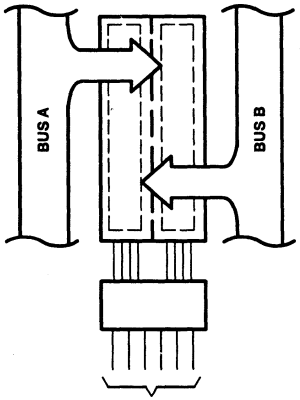
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
L	L	X	X	X	L

REAL-TIME TRANSFER BUS B TO BUS A



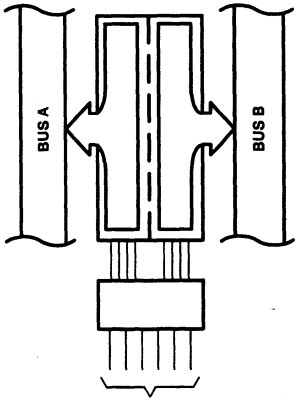
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
L	H	X	X	L	X

REAL-TIME TRANSFER BUS A TO BUS B



$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
X	X	↑	X	X	X
X	X	X	↑	X	X
H	X	↑	↑	X	X

STORAGE FROM A, B, OR A AND B

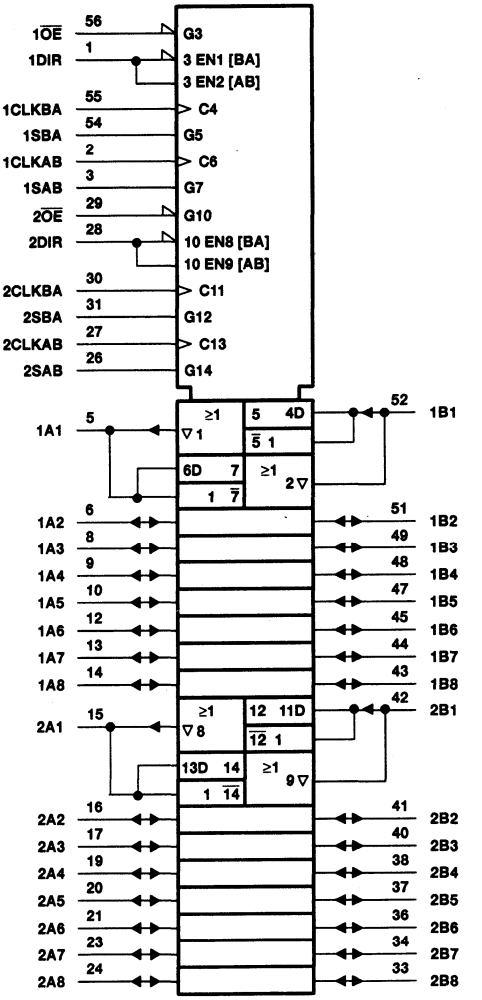


$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA
L	L	X	H or L	X	H
L	H	H or L	X	H	X

TRANSFER STORED DATA TO A AND/OR B

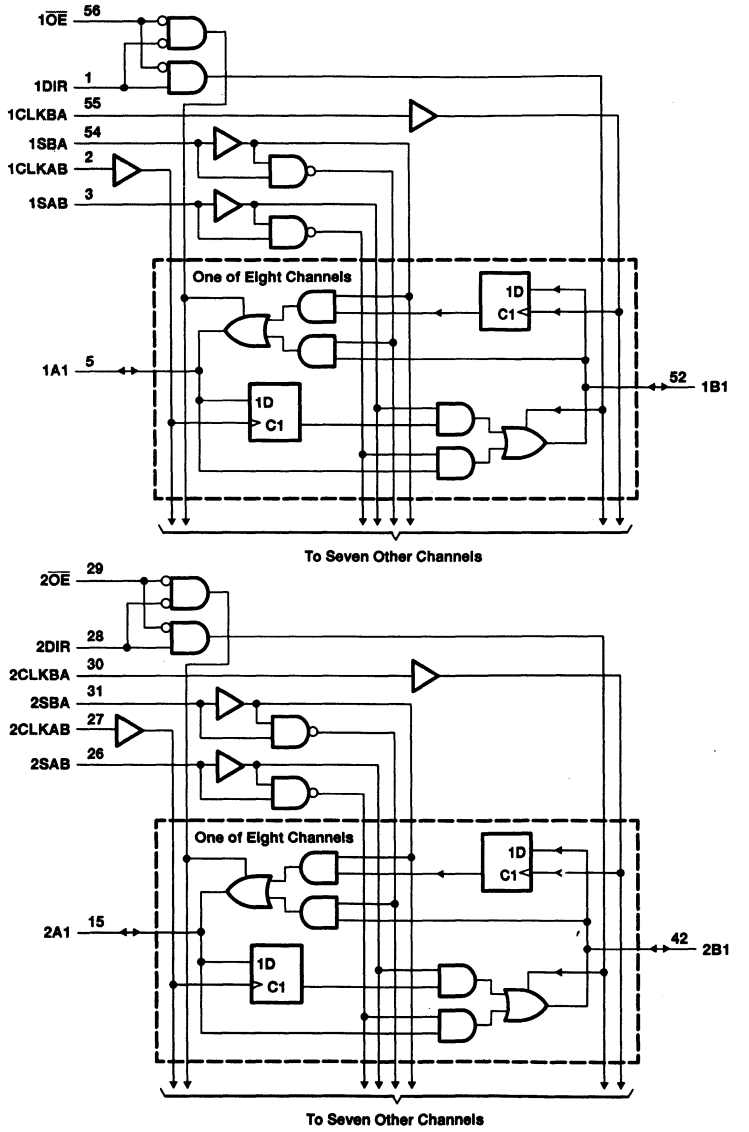
Figure 1. Bus-Management Functions

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16646 ..... 96 mA
SN74ABT16646 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16646		SN74ABT16646		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16646		SN74ABT16646		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports					±20		±20		±20	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			32		32		32	
			Outputs disabled			2		2		2	
ΔI_{CC}¶	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			50		50		50	µA
			Outputs disabled			50		50		50	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			8						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN54ABT16646				UNIT
		V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
		MIN	MAX			
f_{clock}	Clock frequency	0	125	0	125	MHz
t_w	Pulse duration, CLK high or low	4.3		4.3		ns
t_{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3.5		4		ns
t_h	Hold time, A or B after CLKAB↑ or CLKBA↑	0.5		0.5		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN74ABT16646				UNIT
		V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
		MIN	MAX			
f_{clock}	Clock frequency	0	125	0	125	MHz
t_w	Pulse duration, CLK high or low	4.3		4.3		ns
t_{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3		ns
t_h	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16646					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125			125		MHz
t_{PLH}	CLKBA or CLKAB	A or B	1.5	3.1	4	1	5	ns
t_{PHL}			1.5	3.2	4.1	1	5	
t_{PLH}	A or B	B or A	1	2.3	3.2	0.6	4	ns
t_{PHL}			1	3	4.1	0.6	4.9	
t_{PLH}	SAB or SBA†	B or A	1	2.9	4.3	0.6	5.3	ns
t_{PHL}			1	3.1	4.3	0.6	5.3	
t_{PZH}	$\overline{OE}$	A or B	1	3.4	4.6	0.6	5.9	ns
t_{PZL}			1.5	3.5	5.3	1	6	
t_{PHZ}	$\overline{OE}$	A or B	1.5	3.9	5.6	1	6.4	ns
t_{PLZ}			1.5	3.1	4.4	1	4.7	
t_{PZH}	DIR	A or B	1	3.2	4.5	0.6	5.8	ns
t_{PZL}			1.5	3.4	5.1	1	6.7	
t_{PHZ}	DIR	A or B	2	4.2	5.9	1.2	7.1	ns
t_{PLZ}			1.5	3.6	5.1	1	6.2	

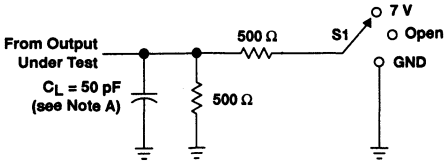
† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16646					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125			125		MHz
t_{PLH}	CLKBA or CLKAB	A or B	1.5	3.1	4	1.5	4.9	ns
t_{PHL}			1.5	3.2	4.1	1.5	4.7	
t_{PLH}	A or B	B or A	1	2.3	3.2	1	3.9	ns
t_{PHL}			1	3	4.1	1	4.6	
t_{PLH}	SAB or SBA†	B or A	1	2.9	4.3	1	5	ns
t_{PHL}			1	3.1	4.3	1	5	
t_{PZH}	$\overline{OE}$	A or B	1	3.4	4.6	1	5.5	ns
t_{PZL}			1.5	3.5	4.9	1.5	5.7	
t_{PHZ}	$\overline{OE}$	A or B	1.5	3.9	4.9	1.5	5.4	ns
t_{PLZ}			1.5	3.1	4.1	1.5	4.5	
t_{PZH}	DIR	A or B	1	3.2	4.5	1	5.4	ns
t_{PZL}			1.5	3.4	4.8	1.5	5.6	
t_{PHZ}	DIR	A or B	2	4.2	5.7	2	6.7	ns
t_{PLZ}			1.5	3.6	5.1	1.5	5.9	

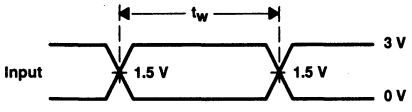
† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

PARAMETER MEASUREMENT INFORMATION

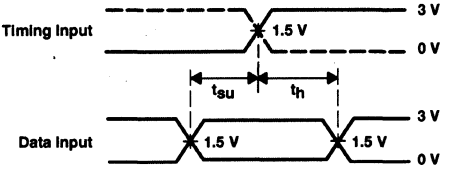


LOAD CIRCUIT

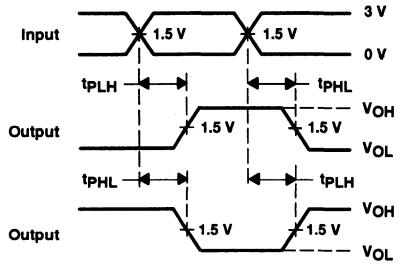
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



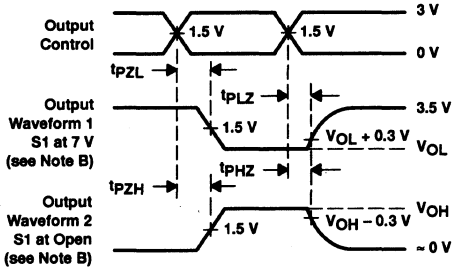
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



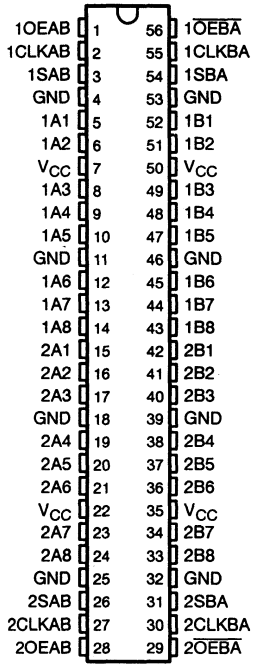
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16652 . . . WD PACKAGE
SN74ABT16652 . . . DL PACKAGE
(TOP VIEW)



description

The 'ABT16652 are 16-bit bus transceivers that consist of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. These devices can be used as two 8-bit transceivers or one 16-bit transceiver.

Output-enable (OEAB and $\overline{OEBA}$) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input selects real-time data, and a high input selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT16652.

Data on the A- or B-data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the select- or enable-control inputs. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and $\overline{OEBA}$. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

description (continued)

To ensure the high-impedance state during power up or power down, $\overline{OEBA}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver (B to A). OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver (A to B).

The SN54ABT16652 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16652 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS						DATA I/O†		OPERATION OR FUNCTION
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	H or L	X	X	Input	Unspecified‡	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	H or L	↑	X	X	Unspecified‡	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	H or L	X	H	X	Input	Output	Stored A data to B bus
H	L	H or L	H or L	H	H	Output	Output	Stored A data to B bus and stored B data to A bus

† The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or $\overline{OEBA}$. Data-input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

‡ Select control = L; clocks can occur simultaneously.
Select control = H; clocks must be staggered to load both registers.

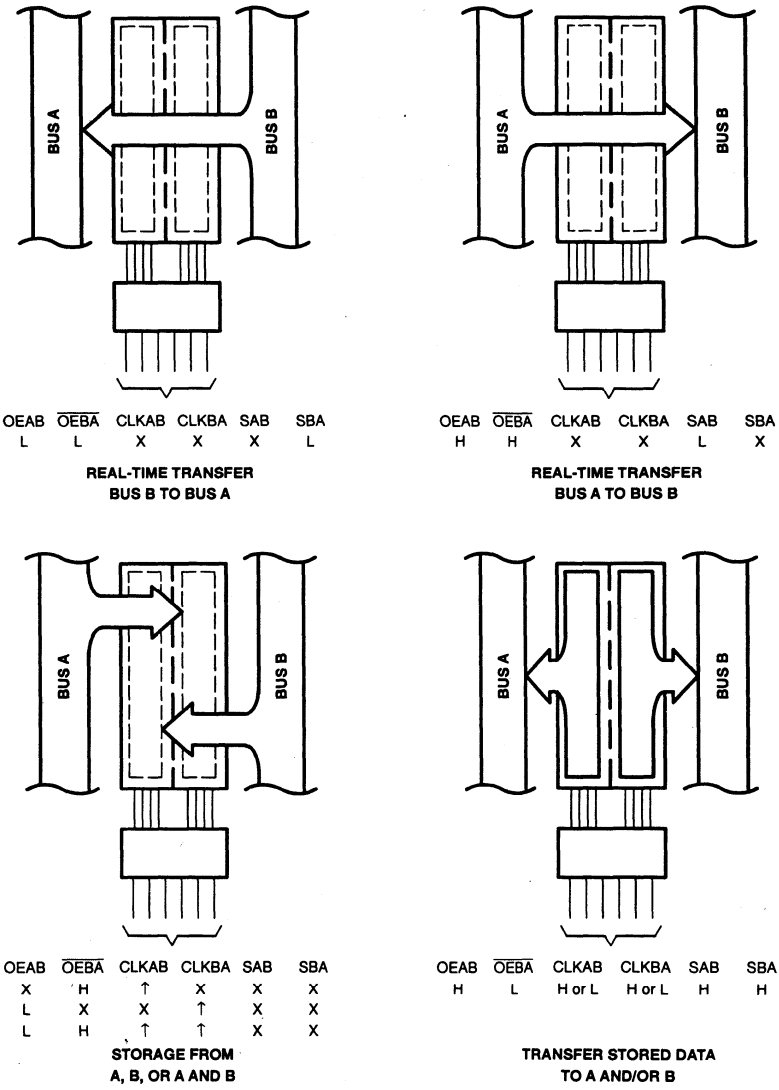
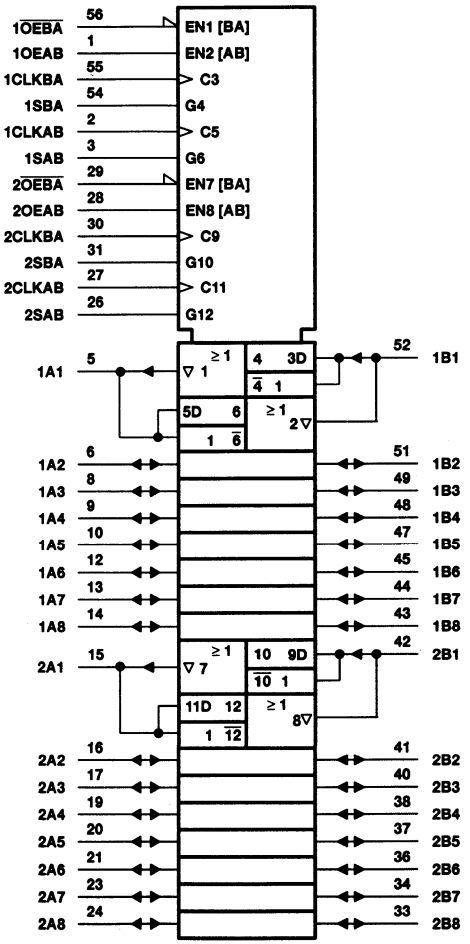


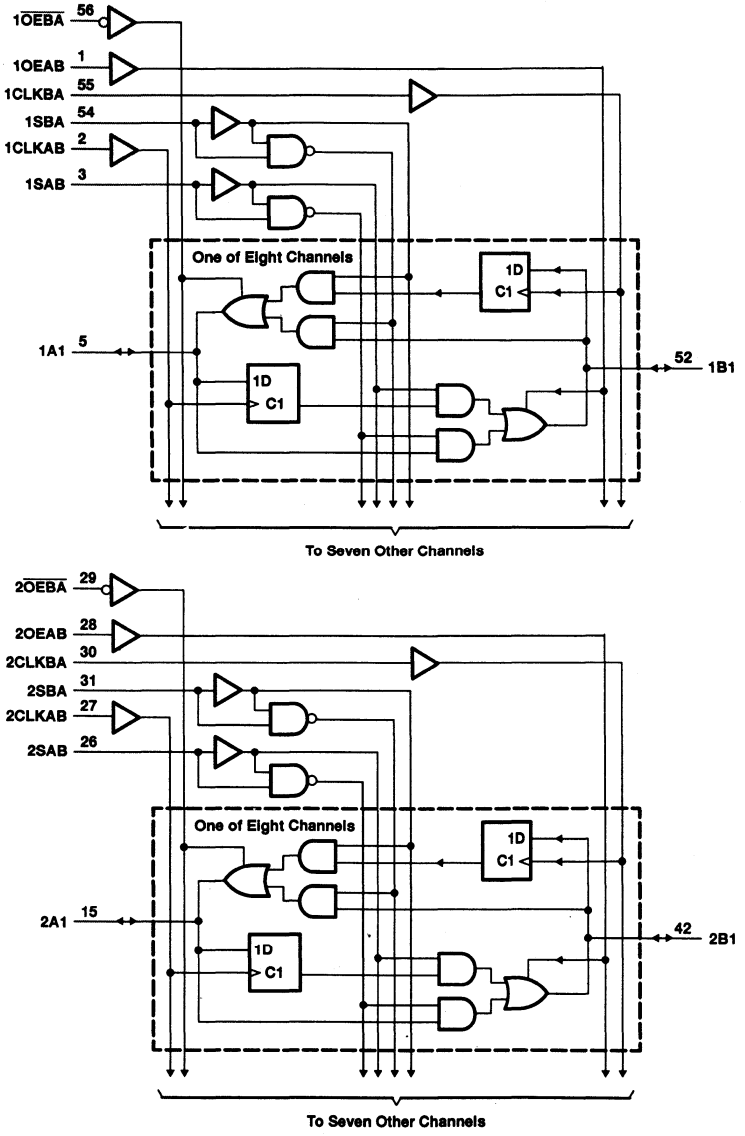
Figure 1. Bus-Management Functions

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16652 ..... 96 mA
SN74ABT16652 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16652		SN74ABT16652		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16652		SN74ABT16652		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports					±20		±20		±20	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			32		32		32	
			Outputs disabled			2		2		2	
ΔI_{CC}¶	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			50		50		50	µA
			Outputs disabled			50		50		50	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			8						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN54ABT16652				UNIT
		V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
		MIN	MAX			
f_{clock}	Clock frequency	0	125	0	125	MHz
t_w	Pulse duration, CLK high or low	4.3		4.3		ns
t_{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3.5		4		ns
t_h	Hold time, A or B after CLKAB↑ or CLKBA↑	0.5		0.5		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN74ABT16652				UNIT
		V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
		MIN	MAX			
f_{clock}	Clock frequency	0	125	0	125	MHz
t_w	Pulse duration, CLK high or low	4.3		4.3		ns
t_{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3		ns
t_h	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16652					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125			125		MHz
t_{PLH}	CLK	B or A	1.5	3.1	4	1	5	ns
t_{PHL}			1.5	3.2	4.1	1	5	
t_{PLH}	A or B	B or A	1	2.3	3.2	0.6	4	ns
t_{PHL}			1	3	4.1	0.6	4.9	
t_{PLH}	SAB or SBA†	B or A	1	2.9	4.3	0.6	5.3	ns
t_{PHL}			1	3.1	4.6	0.6	5.3	
t_{PZH}	$\overline{OEBA}$	A	1	2.8	4.1	0.6	5.2	ns
t_{PZL}			1.5	3.1	4.4	1	5.4	
t_{PHZ}	$\overline{OEBA}$	A	1.5	3.4	4.7	0.8	5.3	ns
t_{PLZ}			1.5	2.7	4	1	5.3	
t_{PZH}	OEAB	B	1	2.6	3.6	0.8	4.7	ns
t_{PZL}			1.5	2.8	4.5	1	5	
t_{PHZ}	OEAB	B	2	4.2	5.9	1	6.4	ns
t_{PLZ}			1.5	3.4	4.9	1	5.9	

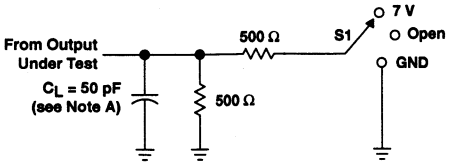
† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16652					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			125			125		MHz
t_{PLH}	CLK	B or A	1.5	3.1	4	1.5	4.9	ns
t_{PHL}			1.5	3.2	4.1	1.5	4.7	
t_{PLH}	A or B	B or A	1	2.3	3.2	1	3.9	ns
t_{PHL}			1	3	4.1	1	4.6	
t_{PLH}	SAB or SBA†	B or A	1	2.9	4.3	1	5	ns
t_{PHL}			1	3.1	4.3	1	5	
t_{PZH}	$\overline{OEBA}$	A	1	2.8	4.1	1	5	ns
t_{PZL}			1.5	3.1	4.4	1.5	5.3	
t_{PHZ}	$\overline{OEBA}$	A	1.5	3.4	4.4	1.5	4.9	ns
t_{PLZ}			1.5	2.7	3.6	1.5	4	
t_{PZH}	OEAB	B	1	2.6	3.6	1	4.2	ns
t_{PZL}			1.5	2.8	3.9	1.5	4.6	
t_{PHZ}	OEAB	B	2	4.2	5.5	2	5.9	ns
t_{PLZ}			1.5	3.4	4.5	1.5	5.2	

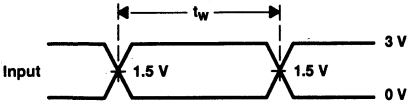
† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
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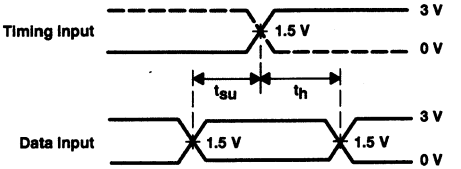

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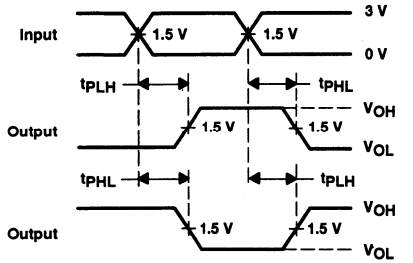
SETUP AND HOLD TIMES



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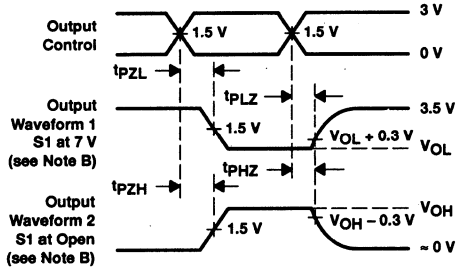
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
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LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
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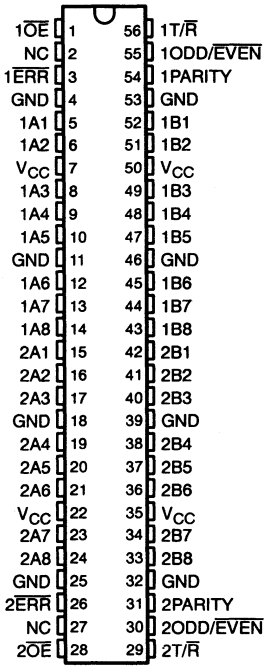
SN74ABT16657 . . . DGG OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABT16657 contain two noninverting octal transceiver sections with separate parity generator/checker circuits and control signals. For either section, the transmit/receive (1T/$\overline{R}$ or 2T/$\overline{R}$) input determines the direction of data flow. When 1T/$\overline{R}$ (or 2T/$\overline{R}$) is high, data flows from the 1A (or 2A) port to the 1B (or 2B) port (transmit mode); when 1T/$\overline{R}$ (or 2T/$\overline{R}$) is low, data flows from the 1B (or 2B) port to the 1A (or 2A) port (receive mode). When the output-enable (1$\overline{OE}$ or 2$\overline{OE}$) input is high, both the 1A (or 2A) and 1B (or 2B) ports are in the high-impedance state.

Odd or even parity is selected by a logic high or low level, respectively, on the 1ODD/$\overline{EVEN}$ (or 2ODD/$\overline{EVEN}$) input. 1PARITY (or 2PARITY) carries the parity bit value; it is an output from the parity generator/checker in the transmit mode and an input to the parity generator/checker in the receive mode.

In the transmit mode, after the 1A (or 2A) bus is polled to determine the number of high bits, 1PARITY (or 2PARITY) is set to the logic level that maintains the parity sense selected by the level at the 1ODD/$\overline{EVEN}$ (or 2ODD/$\overline{EVEN}$) input. For example, if 1ODD/$\overline{EVEN}$ is low (even parity selected) and there are five high bits on the 1A bus, then 1PARITY is set to the logic high level so that an even number of the nine total bits (eight 1A-bus bits plus parity bit) are high.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

description (continued)

In the receive mode, after the 1B (or 2B) bus is polled to determine the number of high bits, the 1$\overline{ERR}$ (or 2$\overline{ERR}$) output logic level indicates whether or not the data to be received exhibits the correct parity sense. For example, if 1ODD/$\overline{EVEN}$ is high (odd parity selected), 1PARITY is high, and there are three high bits on the 1B bus, then 1$\overline{ERR}$ is low, indicating a parity error.

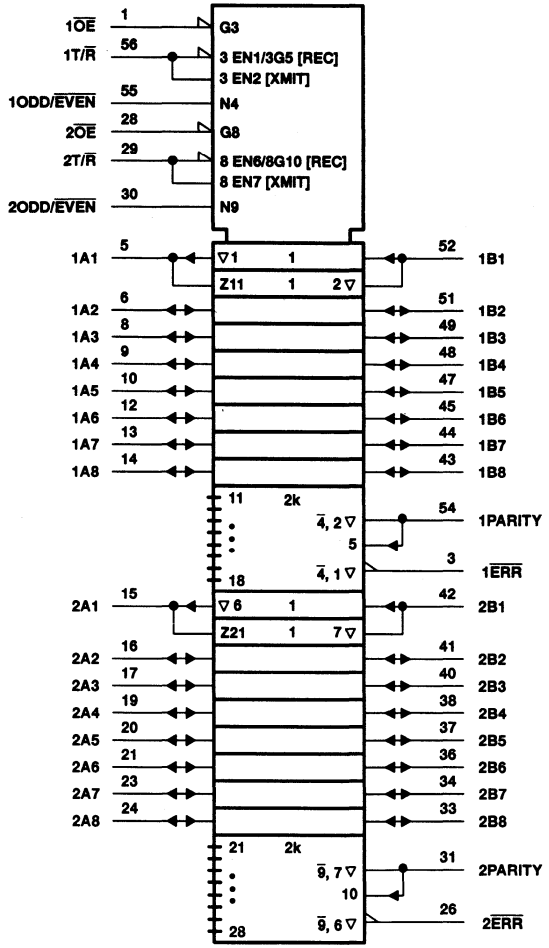
To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16657 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16657 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 8-bit section)

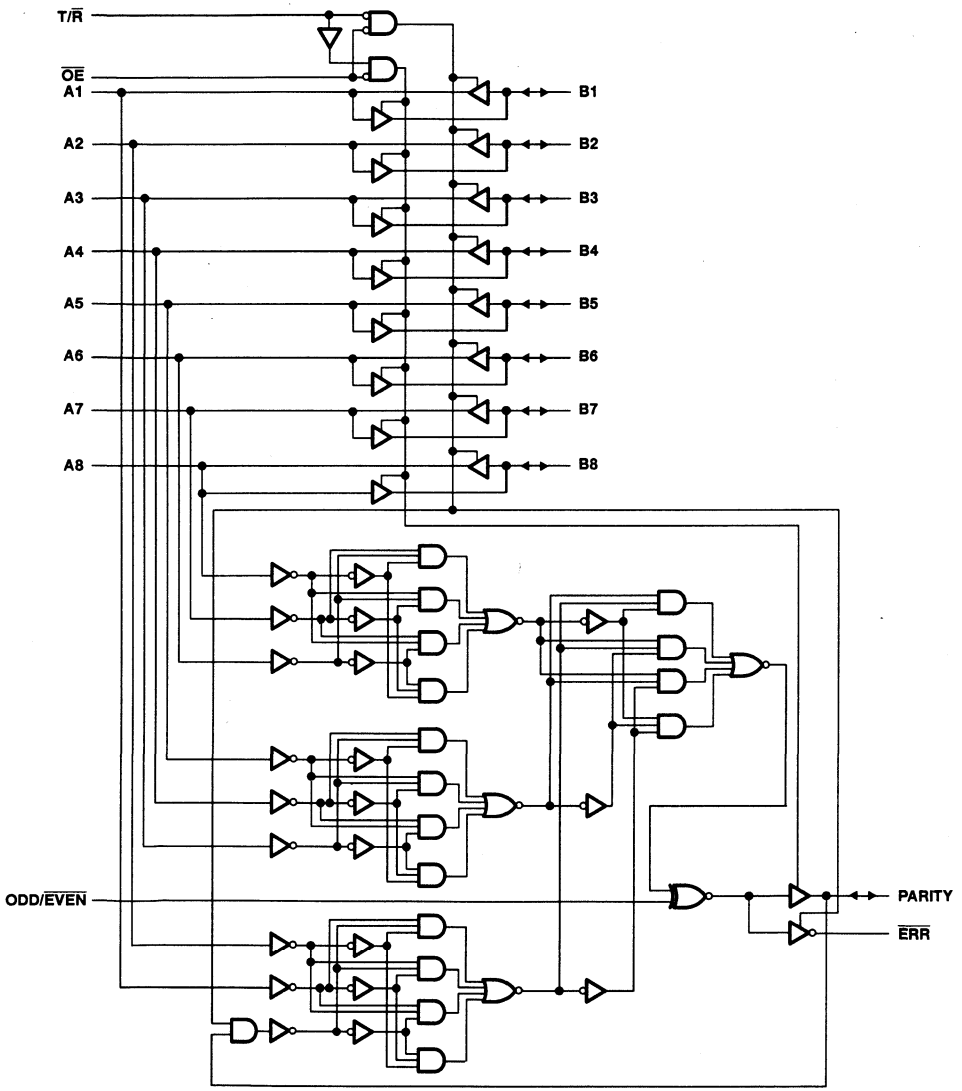
NUMBER OF A OR B INPUTS THAT ARE HIGH	INPUTS			INPUT/OUTPUT PARITY	OUTPUTS	
	$\overline{OE}$	T/$\overline{R}$	ODD/$\overline{EVEN}$		$\overline{ERR}$	OUTPUT MODE
0, 2, 4, 6, 8	L	H	H	H	Z	Transmit
	L	H	L	L	Z	Transmit
	L	L	H	H	H	Receive
	L	L	H	L	L	Receive
	L	L	L	H	L	Receive
	L	L	L	L	H	Receive
1, 3, 5, 7	L	H	H	L	Z	Transmit
	L	H	L	H	Z	Transmit
	L	L	H	H	L	Receive
	L	L	H	L	H	Receive
	L	L	L	H	H	Receive
	L	L	L	L	L	Receive
Don't care	H	X	X	Z	Z	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16657 ..... 96 mA
SN74ABT16657 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16657		SN74ABT16657		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

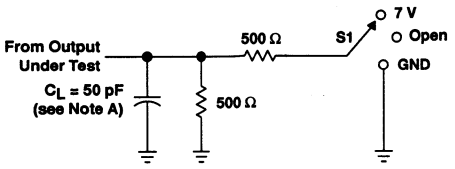
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16657		SN74ABT16657		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 24 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100		±450		±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			36		36		36	
			Outputs disabled			2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	µA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

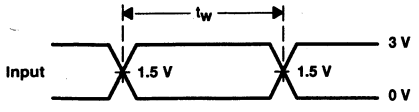
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16657		SN74ABT16657		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.5	2.5	3.3	1.5	4.2	1.5	4.1	ns
t_{PHL}			2	3.1	3.9	2	4.5	2	4.3	
t_{PLH}	A	PARITY	2	4.6	5.4	2	7	2	6.7	ns
t_{PHL}			2	4.3	5.1	2	6.5	2	6.1	
t_{PLH}	ODD/$\overline{EVEN}$	PARITY, $\overline{ERR}$	2	4.6	5.4	2	7	2	6.7	ns
t_{PHL}			2	4.3	5.1	2	6.5	2	6.1	
t_{PLH}	B	$\overline{ERR}$	2	4.6	5.4	2	7	2	6.7	ns
t_{PHL}			2	4.3	5.1	2	6.5	2	6.1	
t_{PLH}	PARITY	$\overline{ERR}$	2	4.6	5.4	2	7	2	6.7	ns
t_{PHL}			2	4.3	5.1	2	6.5	2	6.1	
t_{PZH}	$\overline{OE}$	A or B	2	3.9	4.9	2	5.8	2	5.6	ns
t_{PZL}			2.5	4.3	5.1	2.5	6.2	2.5	6	
t_{PHZ}	$\overline{OE}$	A or B	2	3.6	4.5	2	5.5	2	5.4	ns
t_{PLZ}			1.5	3	3.8	1.5	4.7	1.5	4.3	
t_{PZH}	$\overline{OE}$	PARITY, $\overline{ERR}$	2	4	4.9	2	5.8	2	5.6	ns
t_{PZL}			2.5	4.1	5.1	2.5	6.2	2.5	6	
t_{PHZ}	$\overline{OE}$	PARITY, $\overline{ERR}$	1	3.5	4.5	1	5.5	1	5.4	ns
t_{PLZ}			1.5	3	3.8	1.5	4.7	1.5	4.3	

PARAMETER MEASUREMENT INFORMATION

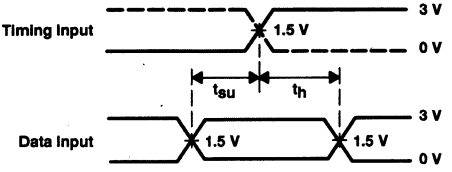


LOAD CIRCUIT

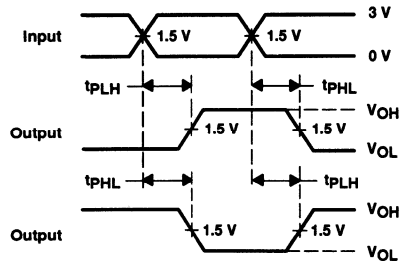
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



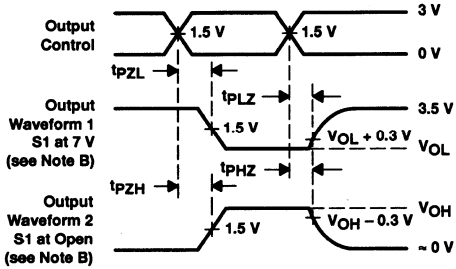
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



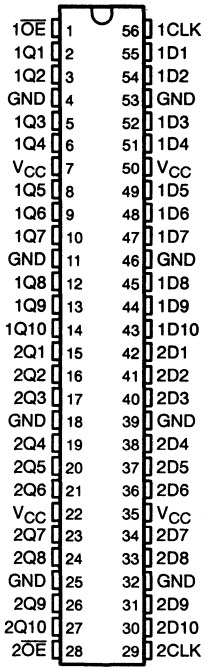
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Thin Shrink Small-Outline (DGG), 300-mil Shrink Small-Outline (DL) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16821 . . . WD PACKAGE
SN74ABT16821 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

These 20-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

The 'ABT16821 can be used as two 10-bit flip-flops or one 20-bit flip-flop. The 20 flip-flops are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the device provides true data at the Q outputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the ten outputs in either a normal logic state (high or low logic level) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

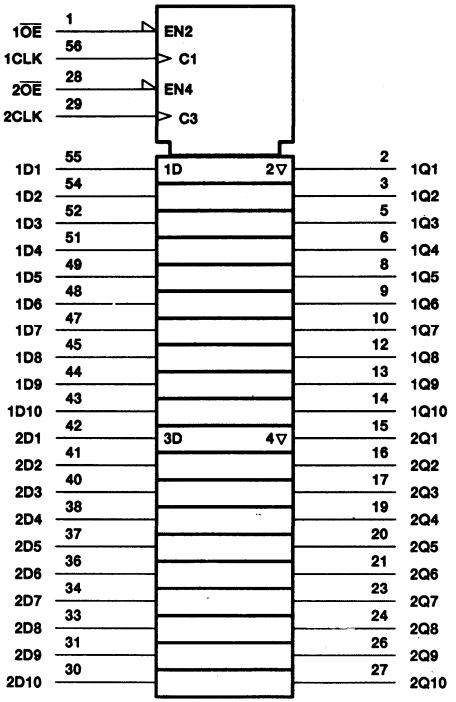
The SN54ABT16821 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16821 is characterized for operation from –40°C to 85°C.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

FUNCTION TABLE
(each flip-flop)

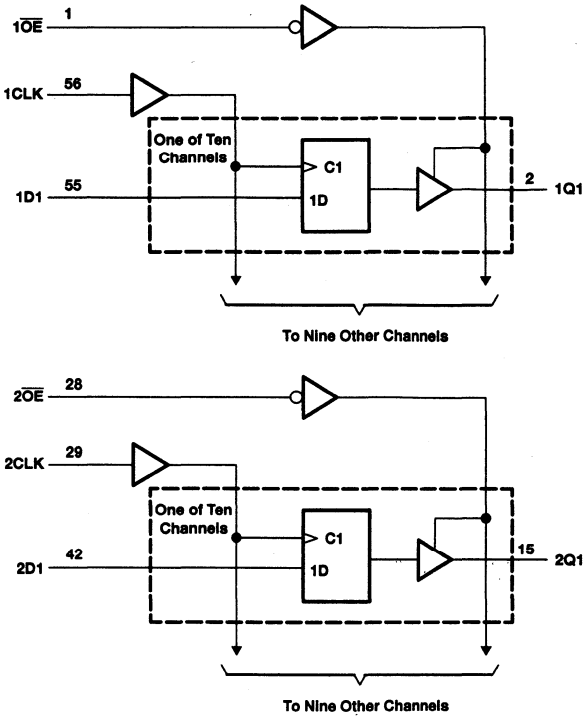
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16821 ..... 96 mA
SN74ABT16821 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16821		SN74ABT16821		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT16821		SN74ABT16821		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V, I_I = –18 mA					–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA		3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –24 mA		2			2				
		I_{OH} = –32 mA		2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA				0.55		0.55			V
		I_{OL} = 64 mA				0.55*				0.55	
V_{hys}					100						mV
I_I	V_{CC} = 5.5 V, V_I = V_{CC} or GND					±1		±1		±1	µA
I_{OZH}	V_{CC} = 5.5 V, V_O = 2.7 V					50		50		50	µA
I_{OZL}	V_{CC} = 5.5 V, V_O = 0.5 V					–50		–50		–50	µA
I_{off}	V_{CC} = 0,	V_I or $V_O \le$ 4.5 V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–100	–200	–50	–200	–50	–200	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND		Outputs high			500		500		500	µA
			Outputs low			89		89		89	mA
			Outputs disabled			500		500		500	µA
ΔI_{CC}§	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V				3.5						pF
C_o	V_O = 2.5 V or 0.5 V				7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

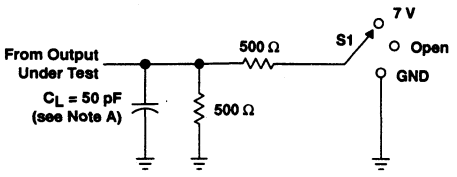
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V_{CC} = 5 V, T_A = 25°C		SN54ABT16821		SN74ABT16821		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	150	0	150	0	150	MHz
t_w	Pulse duration, CLK high or low	3.3		3.3		3.3		ns
t_{su}	Setup time, data before CLK↑	1.8		1.8		1.8		ns
t_h	Hold time, data after CLK↑	1.3		1.3		1.3		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

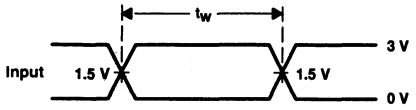
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16821		SN74ABT16821		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			150			150		150		MHz
t_{PLH}	CLK	Q	1.3	3.7	5.1	1.3	6.7	1.3	6.1	ns
t_{PHL}			1.6	3.9	5.1	1.6	5.8	1.6	5.4	
t_{PZH}	$\overline{OE}$	Q	1.1	3.2	4.7	1.1	5.8	1.1	5.7	ns
t_{PZL}			1.6	3.8	5	1.6	5.7	1.6	5.6	
t_{PHZ}	$\overline{OE}$	Q	2	4.5	5.7	2	6.6	2	6.5	ns
t_{PLZ}			1.8	4.1	5.8	1.8	8.4	1.8	7.1	

PARAMETER MEASUREMENT INFORMATION

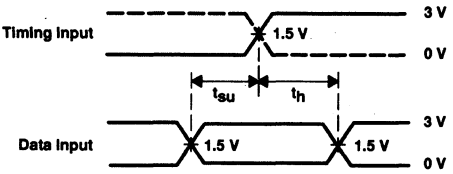


LOAD CIRCUIT

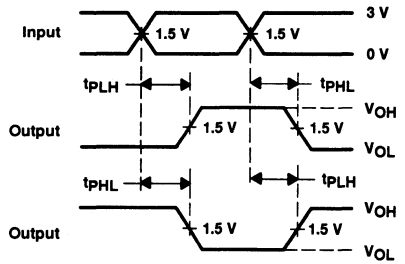
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



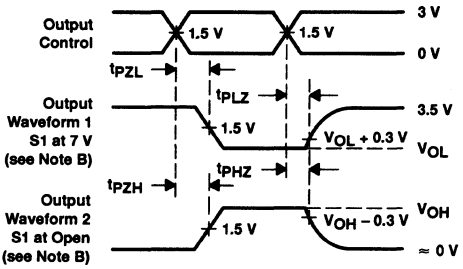
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



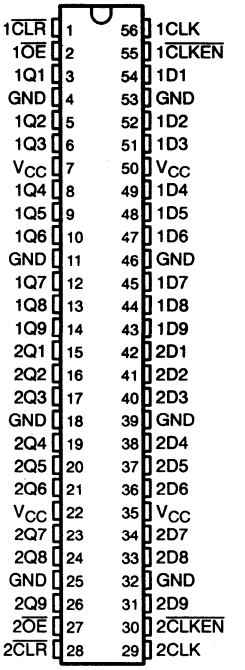
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **High-Impedance State During Power Up and Power Down**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16823 . . . WD PACKAGE
SN74ABT16823 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

These 18-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

The 'ABT16823 can be used as two 9-bit flip-flops or one 18-bit flip-flop. With the clock-enable ($\overline{CLKEN}$) input low, the D-type flip-flops enter data on the low-to-high transitions of the clock. Taking $\overline{CLKEN}$ high disables the clock buffer, latching the outputs. Taking the clear ($\overline{CLR}$) input low causes the Q outputs to go low independently of the clock.

A buffered output-enable ($\overline{OE}$) input can be used to place the nine outputs in either a normal logic state (high or low logic level) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

description (continued)

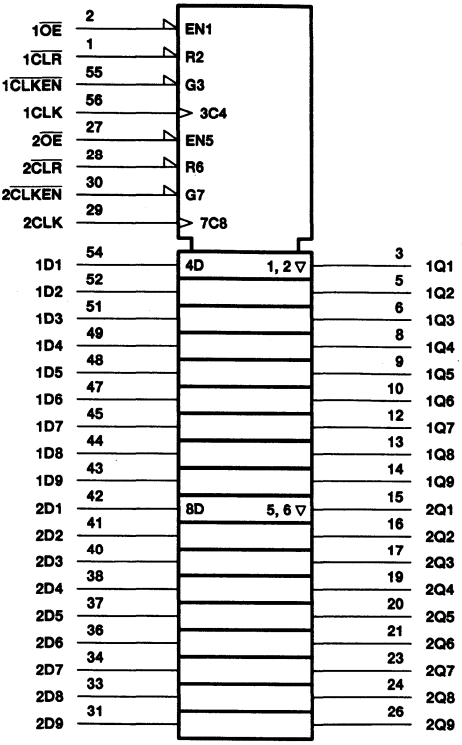
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The SN54ABT16823 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16823 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 9-bit flip-flop)

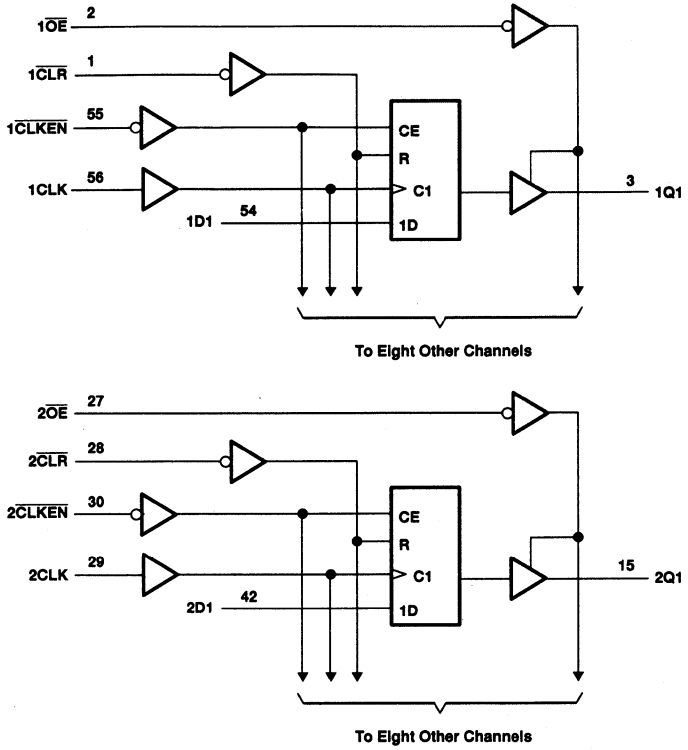
INPUTS					OUTPUT
$\overline{OE}$	$\overline{CLR}$	$\overline{CLKEN}$	CLK	D	Q
L	L	X	X	X	L
L	H	L	↑	H	H
L	H	L	↑	L	L
L	H	L	L	X	Q_0
L	H	H	X	X	Q_0
H	X	X	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16823 ..... 96 mA
SN74ABT16823 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16823		SN74ABT16823		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16823		SN74ABT16823		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZPU}		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10**		50		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10**		–50		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–200	–50	–200	–50	–200	mA
I_{CC}	Outputs high	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND				0.5		0.5		0.5	mA
	Outputs low					80		80		80	
	Outputs disabled					0.5		0.5		0.5	
ΔI_{CC}§		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
** These limits apply only to the SN74ABT16823.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C		SN54ABT16823		SN74ABT16823		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	150	0	150	0	150	MHz
t_w	Pulse duration	$\overline{CLR}$ low	3.3		3.3		3.3		ns
		CLK high or low	3.3		3.3		3.3		
t_{su}	Setup time before CLK↑	$\overline{CLR}$ inactive	1.6		2		1.6		ns
		Data	1.7		1.7		1.7		
		$\overline{CLKEN}$ low	2.8		2.8		2.8		
t_h	Hold time after CLK↑	Data	1.2		1.2		1.2		ns
		$\overline{CLKEN}$ low	0.6		0.6		0.6		

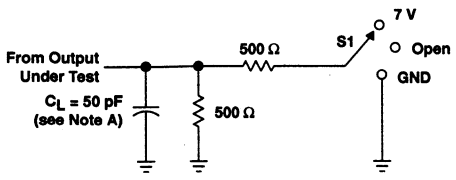
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16823					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150			150		MHz
t_{PLH}	CLK	Q	1.6	3.9	5.5	1.6	7.7	ns
t_{PHL}			2.1	3.9	5.4	2.1	6.4	
t_{PHL}	$\overline{CLR}$	Q	1.9	4.1	5.3	1.9	6.3	ns
t_{PZH}	$\overline{OE}$	Q	1	3.1	4.2	1	5.1	ns
t_{PZL}			1.5	3.5	4.6	1.5	5.7	
t_{PHZ}	$\overline{OE}$	Q	2.2	4.3	6	2.2	6.8	ns
t_{PLZ}			1.6	4.3	6.4	1.6	9.9	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

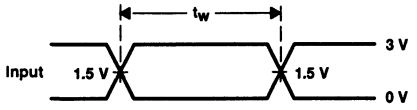
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16823					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150			150		MHz
t_{PLH}	CLK	Q	1.6	3.9	5.5	1.6	6.8	ns
t_{PHL}			2.1	3.9	5.4	2.1	6	
t_{PHL}	$\overline{CLR}$	Q	1.9	4.1	5.3	1.9	6.1	ns
t_{PZH}	$\overline{OE}$	Q	1	3.1	4.2	1	4.9	ns
t_{PZL}			1.5	3.5	4.6	1.5	5.5	
t_{PHZ}	$\overline{OE}$	Q	2.2	4.3	5.6	2.2	6.1	ns
t_{PLZ}			1.6	4.3	6.4	1.6	8.7	

PARAMETER MEASUREMENT INFORMATION

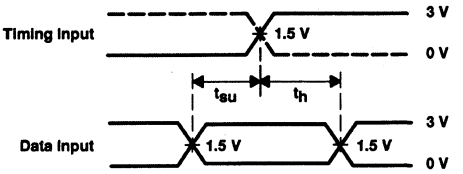


LOAD CIRCUIT

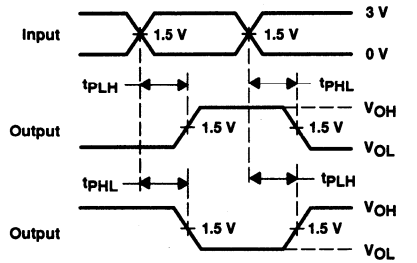
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



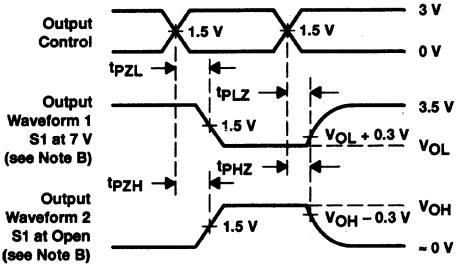
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
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- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
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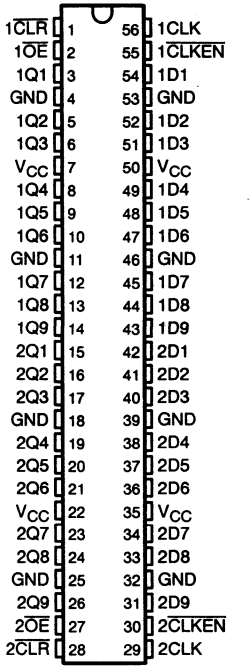
(TOP VIEW)



description

These 18-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

The 'ABTH16823 can be used as two 9-bit flip-flops or one 18-bit flip-flop. With the clock-enable ($\overline{CLKEN}$) input low, the D-type flip-flops enter data on the low-to-high transitions of the clock. Taking $\overline{CLKEN}$ high disables the clock buffer, latching the outputs. Taking the clear ($\overline{CLR}$) input low causes the Q outputs to go low independently of the clock.

A buffered output-enable ($\overline{OE}$) input can be used to place the nine outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

description (continued)

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

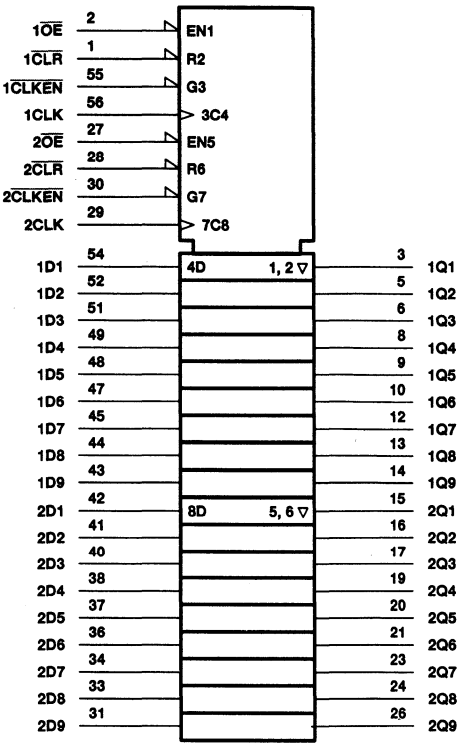
Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ABTH16823 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH16823 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 9-bit flip-flop)

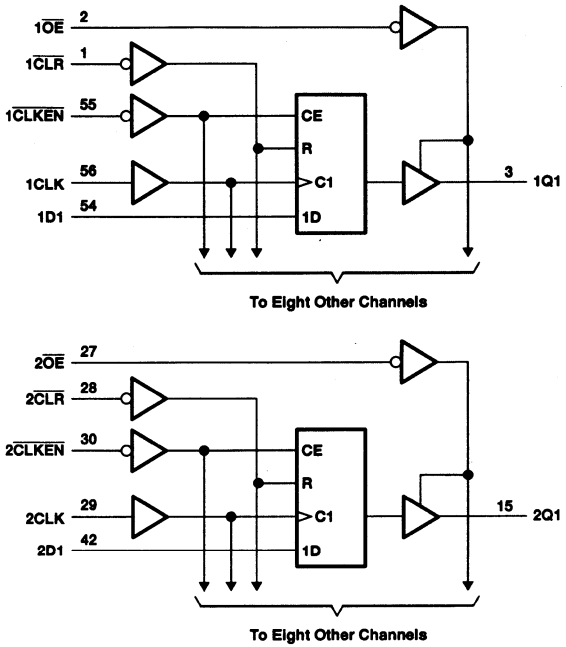
INPUTS					OUTPUT
$\overline{OE}$	$\overline{CLR}$	$\overline{CLKEN}$	CLK	D	Q
L	L	X	X	X	L
L	H	L	↑	H	H
L	H	L	↑	L	L
L	H	L	L	X	Q_0
L	H	H	X	X	Q_0
H	X	X	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH16823 ..... 96 mA
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Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
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Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
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Storage temperature range, T_{stg} ..... –65°C to 150°C

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NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABTH16823		SN74ABTH16823		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABTH16823		SN74ABTH16823		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
$I_{I(hold)}$		V_{CC} = –4.5 V	V_I = 0.8 V	100			100		100		µA
			V_I = 2 V	–100			–100		–100		
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10**		50		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10**		–50		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–200	–50	–200	–50	–200	mA
I_{CC}	Outputs high	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND				0.5		0.5		0.5	mA
	Outputs low					80		80		80	
	Outputs disabled					0.5		0.5		0.5	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i		V_I = 2.5 V or 0.5 V			4						pF
C_o		V_O = 2.5 V or 0.5 V			8.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
** These limits apply only to the SN74ABTH16823.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C		SN54ABTH16823		SN74ABTH16823		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	150	0	150	0	150	MHz
t_w	Pulse duration	$\overline{CLR}$ low	3.3		3.3		3.3		ns
		CLK high or low	3.3		3.3		3.3		
t_{su}	Setup time before CLK↑	$\overline{CLR}$ inactive	1.6		2		1.6		ns
		Data	1.7		1.7		1.7		
		$\overline{CLKEN}$ low	2.8		2.8		2.8		
t_h	Hold time after CLK↑	Data	1.2		1.2		1.2		ns
		$\overline{CLKEN}$ low	0.6		0.6		0.6		

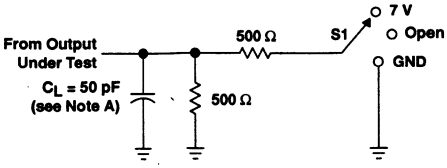
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABTH16823					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150			150		MHz
t_{PLH}	CLK	Q	1.6	3.9	5.5	1.6	7.7	ns
t_{PHL}			2.1	3.9	5.4	2.1	6.4	
t_{PHL}	$\overline{CLR}$	Q	1.9	4.1	6	1.9	6.9	ns
t_{PZH}	$\overline{OE}$	Q	1	3.1	4.2	1	5.1	ns
t_{PZL}			1.5	3.5	4.6	1.5	5.7	
t_{PHZ}	$\overline{OE}$	Q	2.2	4.3	6	2.2	6.8	ns
t_{PLZ}			1.6	4.3	6.4	1.6	9.9	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

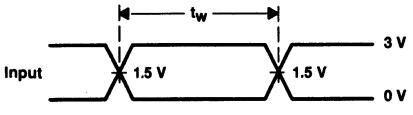
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABTH16823					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150			150		MHz
t_{PLH}	CLK	Q	1.6	3.9	5.5	1.6	6.8	ns
t_{PHL}			2.1	3.9	5.4	2.1	6	
t_{PHL}	$\overline{CLR}$	Q	1.9	4.1	6	1.9	6.7	ns
t_{PZH}	$\overline{OE}$	Q	1	3.1	4.2	1	4.9	ns
t_{PZL}			1.5	3.5	4.6	1.5	5.5	
t_{PHZ}	$\overline{OE}$	Q	2.2	4.3	5.6	2.2	6.1	ns
t_{PLZ}			1.6	4.3	6.4	1.6	8.7	

PARAMETER MEASUREMENT INFORMATION

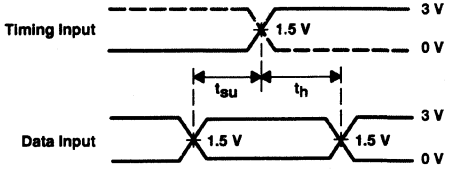


LOAD CIRCUIT

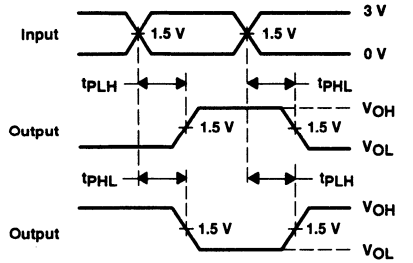
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



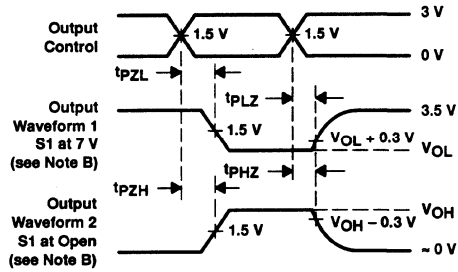
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



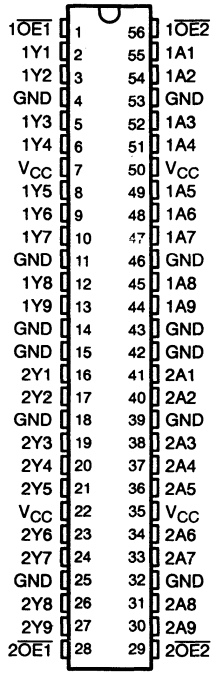
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16825 . . . WD PACKAGE
SN74ABT16825 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16825 are 18-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. These devices can be used as two 9-bit buffers or one 18-bit buffer. They provide true data.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all nine affected outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16825 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16825 is characterized for operation from –40°C to 85°C.

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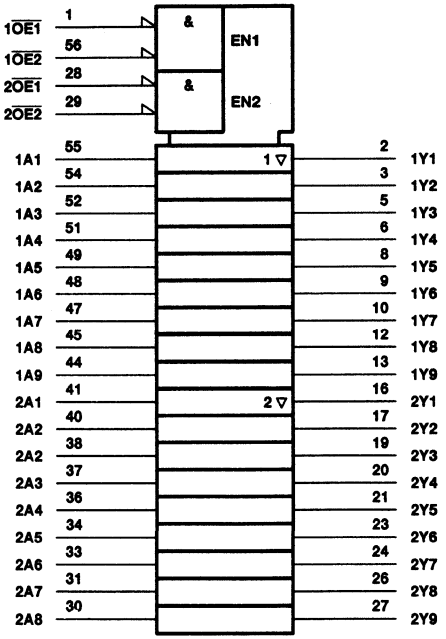
FUNCTION TABLE
(each 9-bit section)

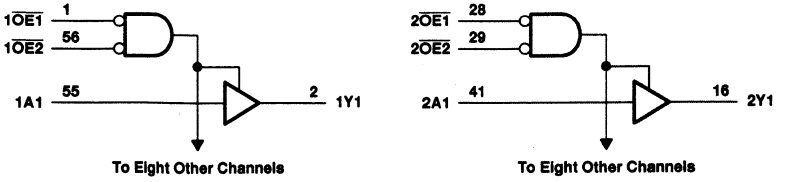
INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16825 ..... 96 mA
SN74ABT16825 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16825		SN74ABT16825		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Control pins		4		4	ns/V
		Data pins		10		10	
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		µs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

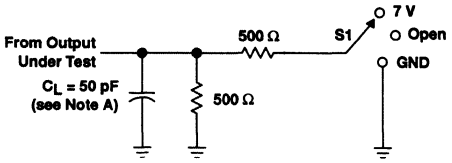
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16825		SN74ABT16825		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	Outputs high	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND				2		2		2	mA
	Outputs low					32		32		32	
	Outputs disabled					2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_o		V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

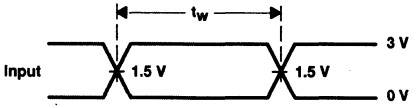
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16825		SN74ABT16825		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	1.9	3.6	1	4.1	1	3.9	ns
t_{PHL}			1	2.1	3.9	1	4.7	1	4.4	
t_{PZH}	$\overline{OE}$	Y	1	2.8	5.5	1	6.4	1	6.1	ns
t_{PZL}			1	2.8	5.4	1	6.3	1	6	
t_{PHZ}	$\overline{OE}$	Y	2.4	4.5	6.8	2.4	7.1	2.4	6.9	ns
t_{PLZ}			1.6	3.7	6.2	1.6	7.6	1.6	6.6	

PARAMETER MEASUREMENT INFORMATION

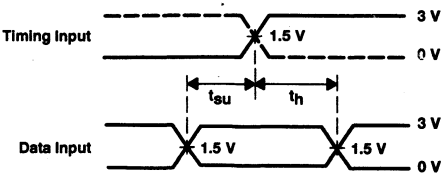


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

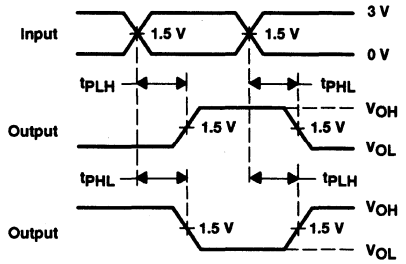
LOAD CIRCUIT



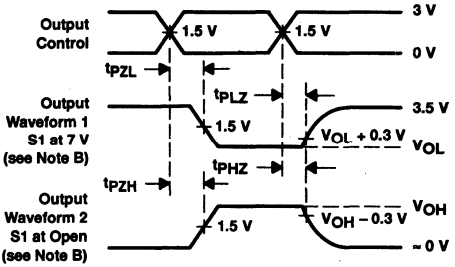
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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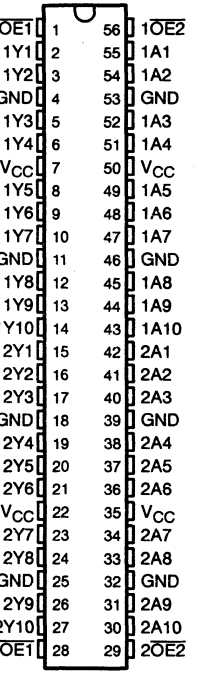
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16827 . . . WD PACKAGE
SN74ABT16827 . . . DL PACKAGE
(TOP VIEW)



description

The 'ABT16827 are noninverting 20-bit buffers composed of two 10-bit sections with separate output-enable signals. For either 10-bit buffer section, the two output-enable ($1\overline{OE1}$ and $1\overline{OE2}$ or $2\overline{OE1}$ and $2\overline{OE2}$) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 10-bit buffer section are in the high-impedance state.

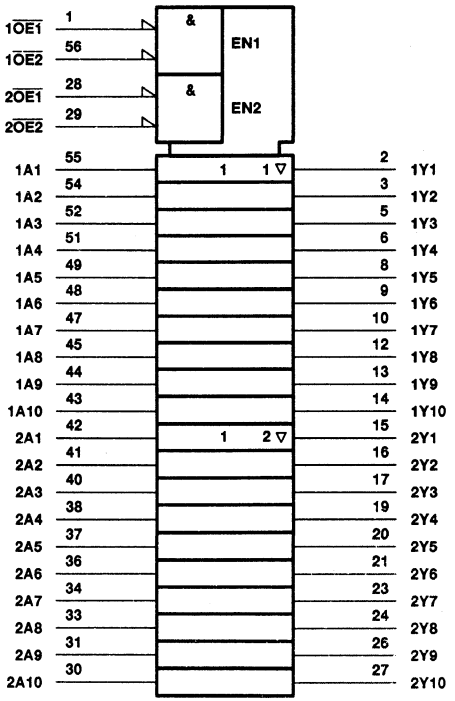
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16827 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16827 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 10-bit section)

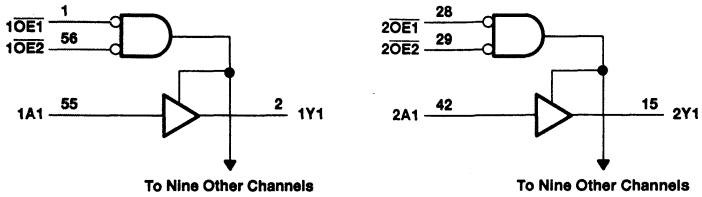
INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16827 ..... 96 mA
SN74ABT16827 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16827		SN74ABT16827		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Control pins		4		4	ns/V
		Data pins		10		10	
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		µs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

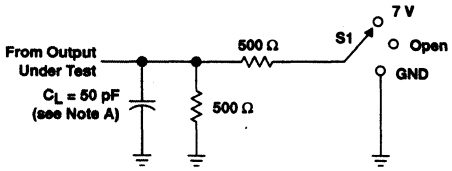
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16827		SN74ABT16827		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = −18 mA			−1.2		−1.2		−1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = −3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = −3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = −24 mA	2			2				
			I_{OH} = −32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				−10		−10		−10	µA
I_{off}		V_{CC} = 0.	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	−50	−100	−180	−50	−180	−50	−180	mA
I_{CC}	Outputs high	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND				2		2		2	mA
	Outputs low					32		32		32	
	Outputs disabled					2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_o		V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

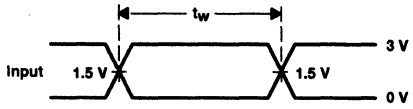
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16827		SN74ABT16827		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	1.9	3.1	1	3.6	1	3.4	ns
t_{PHL}			1	2.1	3.7	1	4.5	1	4.2	
t_{PZH}	$\overline{OE}$	Y	1	2.8	5	1	5.9	1	5.6	ns
t_{PZL}			1	2.8	4.9	1	5.8	1	5.5	
t_{PHZ}	$\overline{OE}$	Y	2.4	4.5	6.5	2.4	6.8	2.4	6.6	ns
t_{PLZ}			1.6	3.7	5.7	1.6	7.1	1.6	6.1	

PARAMETER MEASUREMENT INFORMATION

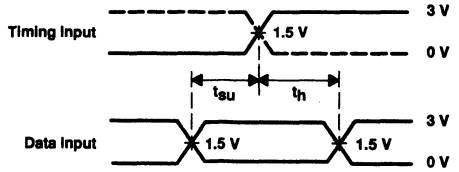


LOAD CIRCUIT

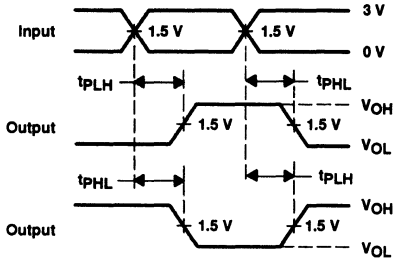
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



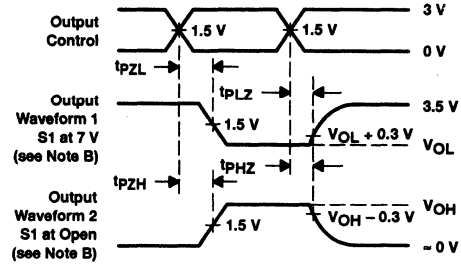
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

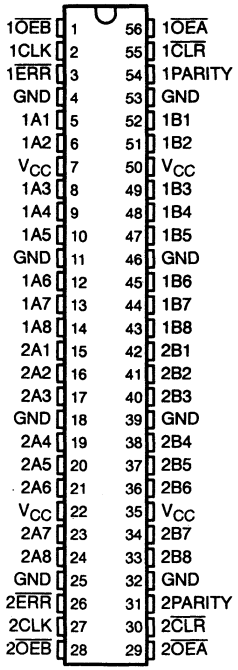
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

SCBS097D – FEBRUARY 1991 – REVISED JANUARY 1997

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Parity-Error Flag With Parity Generator/Checker**
- **Register for Storage of Parity-Error Flag**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16833 . . . WD PACKAGE
SN74ABT16833 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16833 consist of two noninverting 8-bit to 9-bit parity bus transceivers and are designed for communication between data buses. For each transceiver, when data is transmitted from the A bus to the B bus, an odd-parity bit is generated and output on the parity I/O pin (1PARITY or 2PARITY). When data is transmitted from the B bus to the A bus, 1PARITY (or 2PARITY) is configured as an input and combined with the B-input data to generate an active-low error flag if odd parity is not detected.

The error (1$\overline{ERR}$ or 2$\overline{ERR}$) output is configured as an open-collector output. The B-to-A parity-error flag is clocked into 1$\overline{ERR}$ (or 2$\overline{ERR}$) on the low-to-high transition of the clock (1CLK or 2CLK) input. 1$\overline{ERR}$ (or 2$\overline{ERR}$) is cleared (set high) by taking the clear (1$\overline{CLR}$ or 2$\overline{CLR}$) input low.

The output-enable ($\overline{OEA}$ and $\overline{OEB}$) inputs can be used to disable the device so that the buses are effectively isolated. When both $\overline{OEA}$ and $\overline{OEB}$ are low, data is transferred from the A bus to the B bus and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

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description (continued)

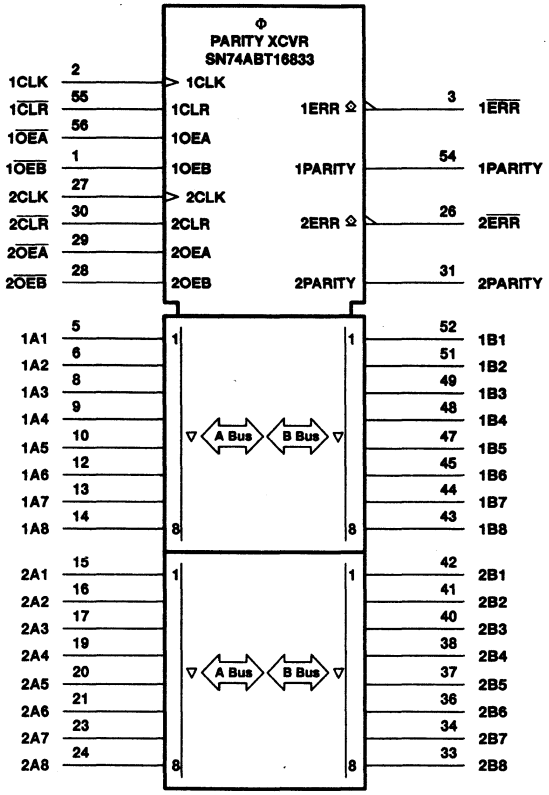
The SN54ABT16833 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16833 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS						OUTPUT AND I/O				FUNCTION
$\overline{OEB}$	$\overline{OEA}$	$\overline{CLR}$	CLK	AI Σ OF H	BI† Σ OF H	A	B	PARITY	$\overline{ERR}$‡	
L	H	X	X	Odd Even	NA	NA	A	L H	NA	A data to B bus and generate parity
H	L	H	↑	NA	Odd Even	B	NA	NA	H L	B data to A bus and check parity
X	X	L	X	X	X	X	NA	NA	H	Check error-flag register
H	H	H	No↑	X	X	Z	Z	Z	NC	Isolation§
		L	No↑	X					H	
		H	↑	Odd					H	
		H	↑	Even					L	
L	L	X	X	Odd Even	NA	NA	A	H L	NA	A data to B bus and generate inverted parity

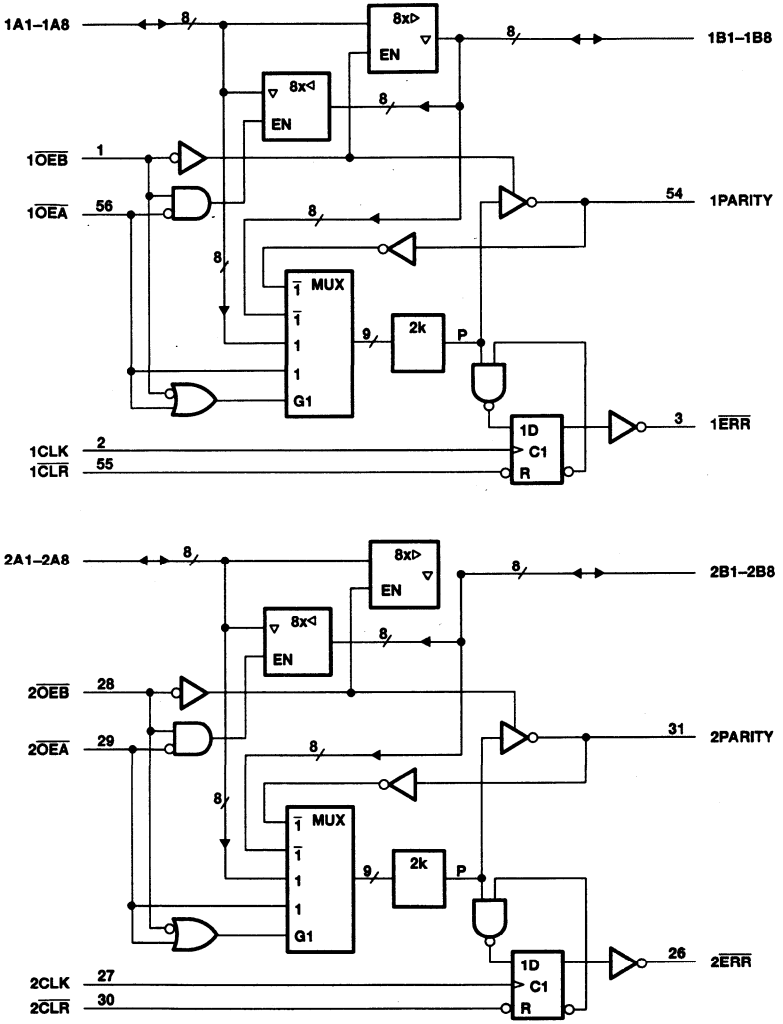
NA = not applicable, NC = no change, X = don't care
† Summation of high-level inputs includes PARITY along with Bi inputs.
‡ Output states shown assume $\overline{ERR}$ was previously high.
§ In this mode, $\overline{ERR}$ (when clocked) shows inverted parity of the A bus.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

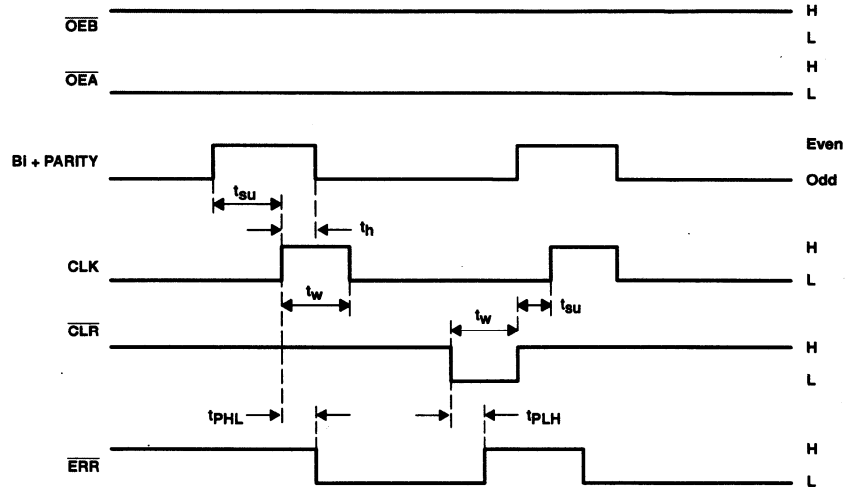


ERROR-FLAG FUNCTION TABLE

INPUTS		INTERNAL TO DEVICE	OUTPUT PRE-STATE	OUTPUT $\overline{ERR}$	FUNCTION
$\overline{CLR}$	CLK	POINT P	$\overline{ERR}_{n-1}$†		
H	↑	H	H	H	Sample
H	↑	X	L	L	
H	↑	L	X	L	
L	X	X	X	H	Clear

† State of $\overline{ERR}$ before changes at $\overline{CLR}$, CLK, or point P

error-flag waveforms



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16833 ..... 96 mA
SN74ABT16833 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16833		SN74ABT16833		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_{OH}	High-level output voltage	$\overline{ERR}$		5.5		5.5	V
I_{OH}	High-level output current	Except $\overline{ERR}$		–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16833		SN74ABT16833		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	All outputs except $\overline{ERR}$	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5	3		2.5				V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3	3.4		3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA				2				
			I_{OH} = –32 mA	2*	2.7				2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 24 mA		0.25	0.55		0.55			V
			I_{OL} = 64 mA		0.3	0.55*				0.55	
V_{hys}					100						mV
I_{OH}	$\overline{ERR}$	V_{CC} = 4.5 V,	V_{OH} = 5.5 V			20		20		20	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_I	Control inputs	V_{CC} = 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{IL}	A or B ports	V_{CC} = 0,	V_I = GND			–50		–50		–50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{OZH}§		V_{CC} =5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}§		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1.5	2		2		2	mA
			Outputs low		28	36		36		36	
			Outputs disabled		1	2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	µA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

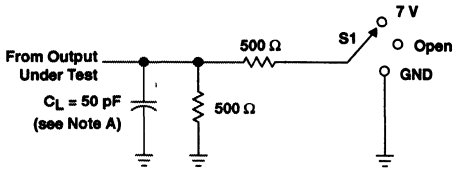
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C		SN54ABT16833		SN74ABT16833		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low		3		3		3		ns
t_{su}	Setup time before CLK↑	A port	4.5		4.5		4.5		ns
		$\overline{CLR}$	1		1		1		
		$\overline{OEA}$	5		5		5		
t_h	Hold time after CLK↑	A port or $\overline{OEA}$	0		0		0		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16833		SN74ABT16833		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.5	2.5	3.3	1.5	4.2	1.5	4.1	ns
t_{PHL}			2	3.1	3.9	2	4.5	2	4.3	
t_{PZH}	$\overline{OE}$	A or B	2	3.9	4.9	2	5.8	2	5.6	ns
t_{PZL}			2.5	4.3	5.1	2.5	6.2	2.5	6	
t_{PHZ}	$\overline{OE}$	A or B	2	3.6	4.5	2	5.5	2	5.4	ns
t_{PLZ}			1.5	3	3.8	1.5	4.7	1.5	4.3	
t_{PLH}	A or $\overline{OE}$	PARITY	2	4.6	5.4	2	7	2	6.7	ns
t_{PHL}			2	4.3	5.1	2	6.5	2	6.1	
t_{PZH}	$\overline{OE}$	PARITY	2	3.6	5	2	5.8	2	5.7	ns
t_{PZL}			2.5	4.4	5.8	2.5	6.7	2.5	6.5	
t_{PHZ}	$\overline{OE}$	PARITY	1.5	3.2	4	1.5	4.8	1.5	4.7	ns
t_{PLZ}			1.5	2.9	3.7	1.5	4.2	1.5	4.1	
t_{PLH}	CLK, $\overline{CLR}$	$\overline{ERR}$	2	3.4	4.2	2	4.8	2	4.6	ns
t_{PHL}	CLK		2	2.8	3.6	2	4.1	2	3.9	

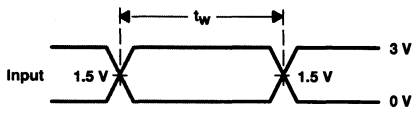
PARAMETER MEASUREMENT INFORMATION



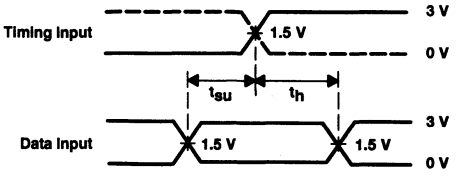
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

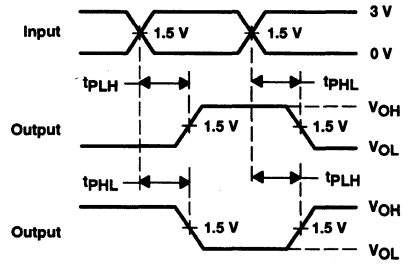
ERR	S1
t_{PHL} (see Note E)	7 V
t_{PLH} (see Note F)	7 V



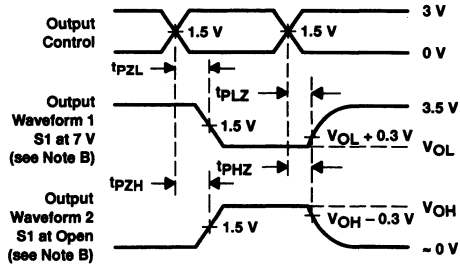
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



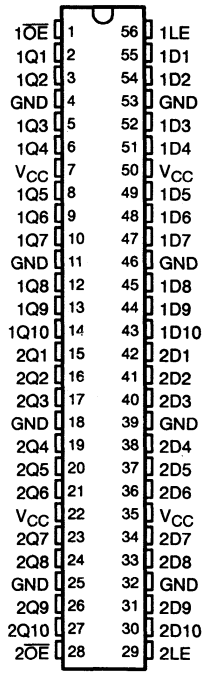
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PHL} is measured at 1.5 V.
F. t_{PLH} is measured at V_{OL} + 0.3 V.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16841 . . . WD PACKAGE
SN74ABT16841 . . . DL PACKAGE
(TOP VIEW)



description

These 20-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The 'ABT16841 can be used as two 10-bit latches or one 20-bit latch. The 20 transparent D-type latches provide true data at the outputs. While the latch-enable (1LE or 2LE) input is high, the Q outputs of the corresponding 10-bit latch follow the D inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable ($1\overline{OE}$ or $2\overline{OE}$) input can be used to place the outputs of the corresponding 10-bit latch in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

The output-enable input does not affect the internal operation of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

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TEXAS INSTRUMENTS

description (continued)

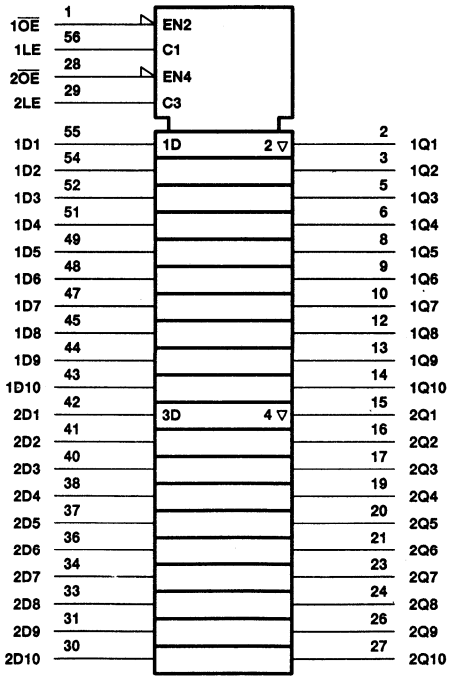
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16841 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16841 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 10-bit latch)

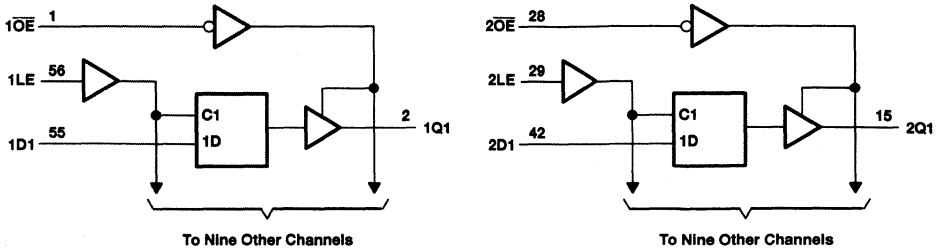
INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16841 ..... 96 mA
SN74ABT16841 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16841		SN74ABT16841		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16841		SN74ABT16841		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1				±1	µA
		V_{CC} = 5 V, V_I = V_{CC} or GND						±5			
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	Outputs high	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND				0.5		0.5			mA
	Outputs low					89		89		89	
	Outputs disabled					0.5		0.5		0.5	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN54ABT16841			UNIT
		V_{CC} = 5 V, T_A = 25°C		MIN MAX	
		MIN	MAX		
t_w	Pulse duration, LE high or low	4		4	ns
t_{su}	Setup time, data before LE↓	3		3	ns
t_h	Hold time, data after LE↓	2.6		2.6	ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN74ABT16841				UNIT
		V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
		MIN	MAX			
t_w	Pulse duration, LE high or low	4		4		ns
t_{su}	Setup time, data before LE↓	1		1		ns
t_h	Hold time, data after LE↓	2		2		ns

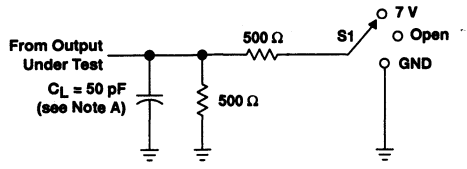
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16841					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	Q	1.1	3.2	4.3	1.1	5.7	ns
t_{PHL}			1.6	3.5	4.5	1.6	5.3	
t_{PLH}	LE	Q	1.1	3.2	4.4	1.1	5.6	ns
t_{PHL}			1.6	3.4	5	1.6	5.5	
t_{PZH}	$\overline{OE}$	Q	1.2	3.2	4.7	1.2	5.8	ns
t_{PZL}			1.7	3.6	5	1.7	5.7	
t_{PHZ}	$\overline{OE}$	Q	2.2	4.1	6.6	2.2	7.7	ns
t_{PLZ}			1.9	4.4	5.8	1.2	8.4	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

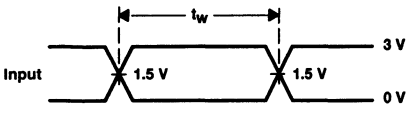
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16841					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	D	Q	1.1	3.2	4.3	1.1	5	ns
t_{PHL}			1.6	3.5	4.5	1.6	5.1	
t_{PLH}	LE	Q	1.1	3.2	4.4	1.1	5	ns
t_{PHL}			1.6	3.4	4.6	1.6	5	
t_{PZH}	$\overline{OE}$	Q	1.2	3.2	4.7	1.2	5.7	ns
t_{PZL}			1.7	3.6	5	1.7	5.6	
t_{PHZ}	$\overline{OE}$	Q	2.2	4.1	5.7	2.2	6.5	ns
t_{PLZ}			1.9	4.4	5.8	1.9	7.1	

PARAMETER MEASUREMENT INFORMATION

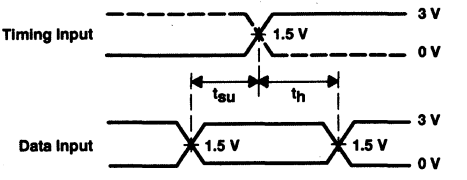


LOAD CIRCUIT

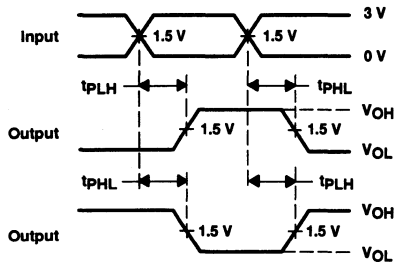
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



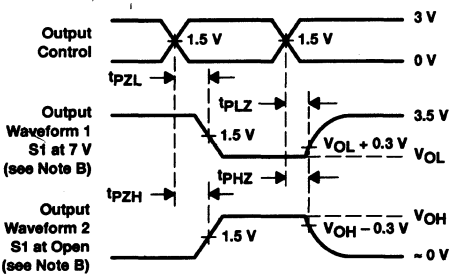
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



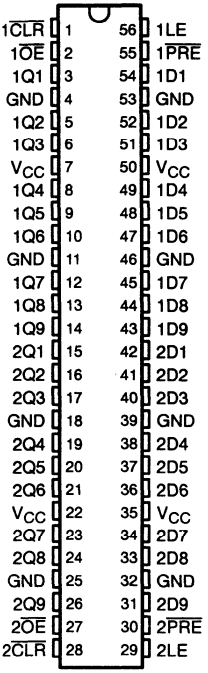
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Impedance State During Power Up and Power Down**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Thin Shrink Small-Outline (DGG), 300-mil Shrink Small-Outline (DL) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16843 . . . WD PACKAGE
SN74ABT16843 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16843 18-bit bus-interface D-type latches are designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The 'ABT16843 can be used as two 9-bit latches or one 18-bit latch. The 18 latches are transparent D-type latches. The device provides true data at its outputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the nine outputs in either a normal logic state (high or low logic levels) or a high-impedance state. The outputs are in the high-impedance state during power up and power down. The outputs remain in the high-impedance state while the device is powered down. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

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description (continued)

$\overline{OE}$ does not affect the internal operations of the latch. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

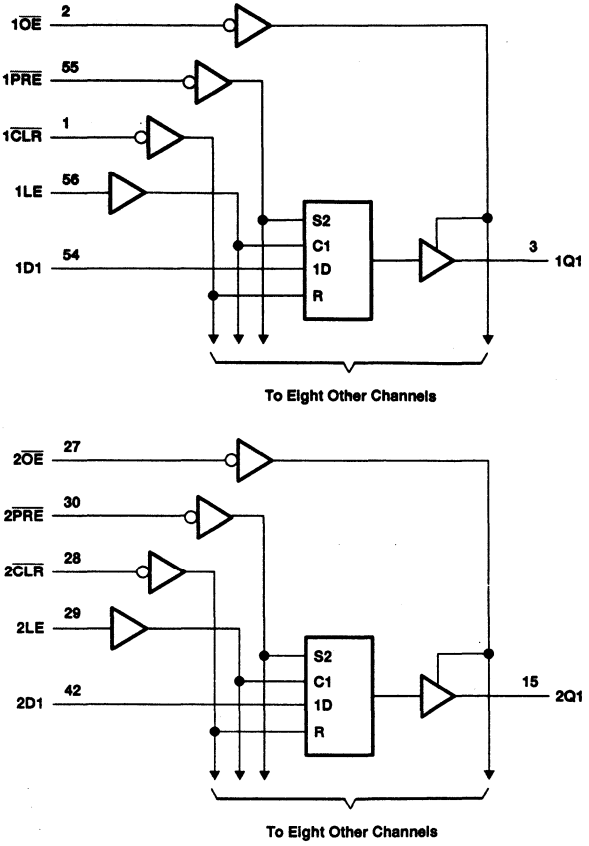
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16843 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16843 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 9-bit latch)

INPUTS					OUTPUT
$\overline{PRE}$	$\overline{CLR}$	$\overline{OE}$	LE	D	Q
L	X	L	X	X	H
H	L	L	X	X	L
H	H	L	H	L	L
H	H	L	H	H	H
H	H	L	L	X	Q_0
X	X	H	X	X	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16843 ..... 96 mA
SN74ABT16843 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16843		SN74ABT16843		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16843		SN74ABT16843		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	Outputs high	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND				0.5		0.5		0.5	mA
	Outputs low					85		85		85	
	Outputs disabled					0.5		0.5		0.5	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			8						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

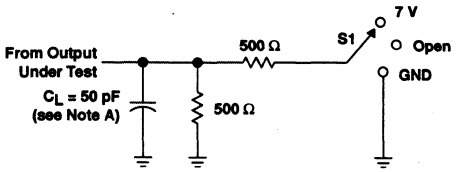
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C		SN54ABT16843		SN74ABT16843		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{CLR}$ low	3.3		3.3		3.3		ns
		$\overline{PRE}$ low	3.3		3.3		3.3		
		LE high	3.3		3.3		3.3		
t_{su}	Setup time, data before LE↓	High	0.9		0.9		0.9		ns
		Low	0.6		0.6		0.6		
t_h	Hold time, data after LE↓	High	1.7		1.7		1.7		ns
		Low	1.8		1.8		1.8		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

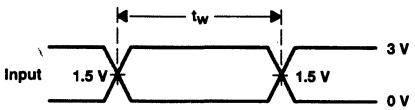
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16843		SN74ABT16843		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	1.6	3.1	4.2	1.6	5.1	1.6	4.8	ns
t_{PHL}			1.6	3.2	4.2	1.6	5	1.6	4.8	
t_{PLH}	LE	Q	2.3	4	5	2.3	6.3	2.3	5.9	ns
t_{PHL}			2.5	3.9	4.8	2.5	5.6	2.5	5.3	
t_{PLH}	$\overline{PRE}$	Q	2.1	4	5.1	2.1	6.3	2.1	6.1	ns
t_{PHL}			2.2	3.7	4.6	2.2	5.3	2.2	5	
t_{PLH}	$\overline{CLR}$	Q	1.9	3.7	4.8	1.9	5.7	1.9	5.4	ns
t_{PHL}			2.2	4.2	5.3	2.2	6.1	2.2	6	
t_{PZH}	$\overline{OE}$	Q	1.6	3.3	4.3	1.6	5.5	1.6	5.4	ns
t_{PZL}			2	3.2	4.6	2	5.9	2	5.8	
t_{PHZ}	$\overline{OE}$	Q	1.7	4	5.5	1.7	6.4	1.7	6.3	ns
t_{PLZ}			1.7	3.7	4.4	1.7	5.3	1.7	5.2	

PARAMETER MEASUREMENT INFORMATION

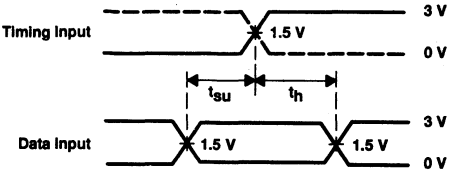


LOAD CIRCUIT

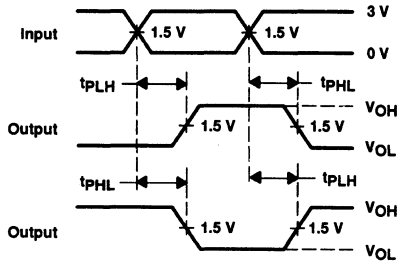
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



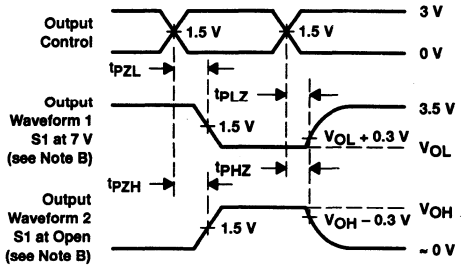
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

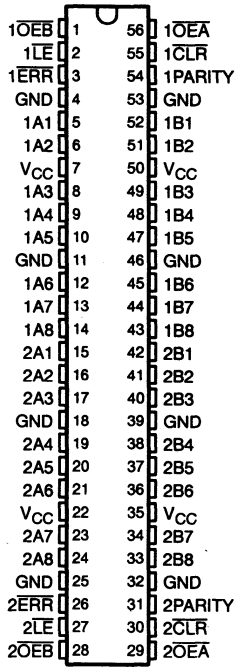
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

SCBS153B – OCTOBER 1992 – REVISED JANUARY 1997

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Parity-Error Flag With Parity Generator/Checker**
- **Latch for Storage of the Parity-Error Flag**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16853 . . . WD PACKAGE
SN74ABT16853 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16853 dual 8-bit to 9-bit parity transceivers are designed for communication between data buses. When data is transmitted from the A bus to the B bus, a parity bit is generated. When data is transmitted from the B bus to the A bus, with its corresponding parity bit, the open-collector parity-error ($\overline{ERR}$) output indicates whether or not an error in the B data has occurred. The output-enable ($\overline{OEA}$ and $\overline{OEB}$) inputs can be used to disable the device so that the buses are effectively isolated. The 'ABT16853 provide true data at the outputs.

A 9-bit parity generator/checker generates a parity-odd (PARITY) output and monitors the parity of the I/O ports with the $\overline{ERR}$ flag. The parity-error output can be passed, sampled, stored, or cleared from the latch using the latch-enable ($\overline{LE}$) and clear ($\overline{CLR}$) control inputs. When both $\overline{OEA}$ and $\overline{OEB}$ are low, data is transferred from the A bus to the B bus, and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

description (continued)

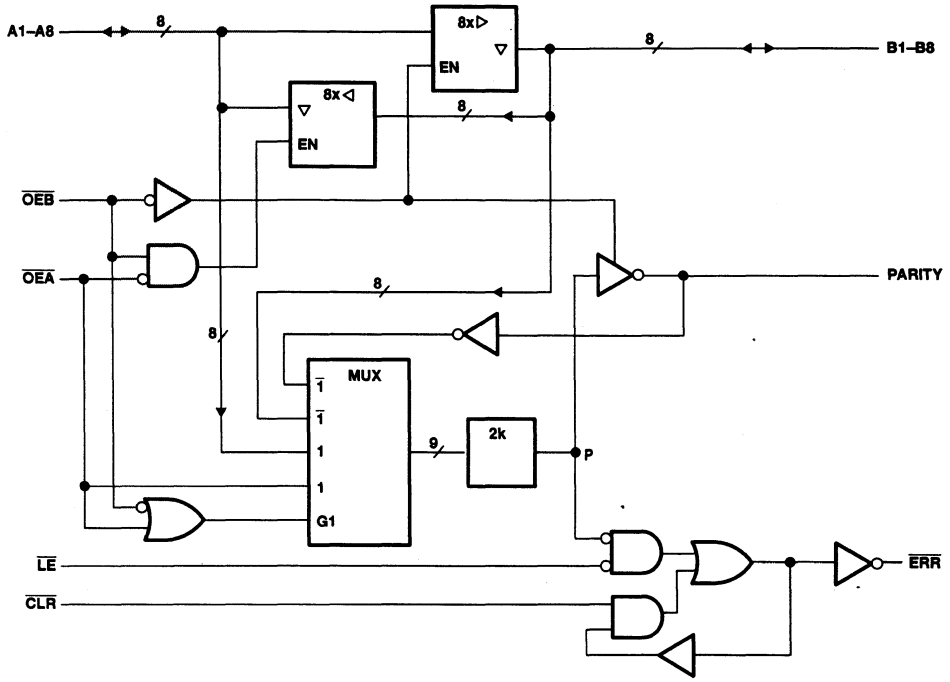
The SN54ABT16853 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16853 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS						OUTPUT AND I/O				FUNCTION
$\overline{OEB}$	$\overline{OEA}$	$\overline{CLR}$	LE	AI Σ OF H	BI† Σ OF H	A	B	PARITY	$\overline{ERR}$‡	
L	H	X	X	Odd Even	NA	NA	A	L H	NA	A data to B bus and generate parity
H	L	X	L	NA	Odd Even	B	NA	NA	H L	B data to A bus and check parity
H	L	H	H	NA	X	X	NA	NA	NC	Store error flag
X	X	L	H	X	X	X	NA	NA	H	Clear error-flag register
H	H	H L X X	H H L L	X X L Odd H Even	X	Z	Z	Z	NC H H L	Isolation§ (parity check)
L	L	X	X	Odd Even	NA	NA	A	H L	NA	A data to B bus and generate inverted parity

NA = not applicable, NC = no change, X = don't care
† Summation of high-level inputs includes PARITY along with Bi inputs.
‡ Output states shown assume $\overline{ERR}$ was previously high.
§ In this mode, $\overline{ERR}$ (when clocked) shows inverted parity of the A bus.

logic diagram (each transceiver) (positive logic)

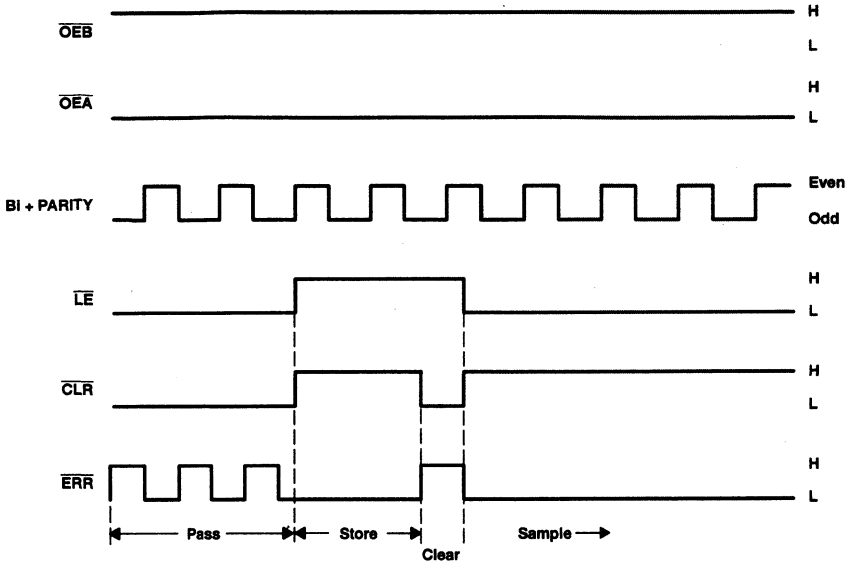


ERROR-FLAG FUNCTION TABLE

INPUTS		INTERNAL TO DEVICE	OUTPUT	OUTPUT	FUNCTION
$\overline{CLR}$	$\overline{LE}$	POINT P	$\overline{ERR}_{n-1}$†	$\overline{ERR}$	
L	L	L	X	L	Pass
		H		H	
H	L	L	X	L	Sample
		X	L	L	
		H	H	H	
L	H	X	X	H	Clear
H	H	X	L	L	Store
			H	H	

† State of $\overline{ERR}$ before changes at $\overline{CLR}$, $\overline{LE}$, or point P

error-flag waveforms



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16853 ..... 96 mA
SN74ABT16853 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16853		SN74ABT16853		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_{OH}	High-level output voltage	$\overline{ERR}$		5.5		5.5	V
I_{OH}	High-level output current	Except $\overline{ERR}$		–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16853		SN74ABT16853		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	All outputs except $\overline{ERR}$	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5	3		2.5				V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3	3.4		3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA				2				
			I_{OH} = –32 mA	2*	2.7				2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 24 mA		0.25	0.55		0.55			V
			I_{OL} = 64 mA		0.3	0.55*				0.55	
V_{hys}					100						mV
I_{OH}	$\overline{ERR}$	V_{CC} = 4.5 V,	V_{OH} = 5.5 V			20		20		20	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_I	Control inputs	V_{CC} = 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{IL}	A or B ports	V_{CC} = 0,	V_I = GND			–50		–50		–50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{OZH}§		V_{CC} =5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}§		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1.5	2		2		2	mA
			Outputs low		32	40		40		40	
			Outputs disabled		1	2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	µA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

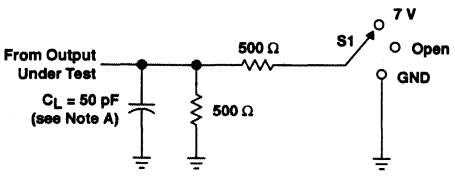
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C		SN54ABT16853		SN74ABT16853		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{LE}$ high or low	8.5		8.5		8.5		ns
		$\overline{CLR}$ low	4		4		4		
t_{su}	Setup time	A, B, and PARITY before $\overline{LE}\downarrow$	10		10		10		ns
		$\overline{CLR}$ before $\overline{LE}\downarrow$	0		0		0		
t_h	Hold time	A, B, and PARITY after $\overline{LE}\downarrow$	0		0		0		ns
		$\overline{CLR}$ after $\overline{LE}\downarrow$	0		0		0		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16853		SN74ABT16853		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.5	2.5	3.3	1.5	4.2	1.5	4.1	ns
t_{PHL}			2	3.1	3.9	2	4.5	2	4.3	
t_{PLH}	A or $\overline{OE}$	PARITY	2	4.6	5.9	2	7.3	2	7.1	ns
t_{PHL}			2	4.8	6.2	2	7.6	2	7.2	
t_{PLH}	$\overline{CLR}$	$\overline{ERR}$	2	3.7	5.1	2	5.9	2	5.7	ns
t_{PZH}	$\overline{OE}$	A or B	2	3.9	4.9	2	5.8	2	5.6	ns
t_{PZL}			2.5	4.3	5.1	2.5	6.2	2.5	6	
t_{PHZ}	$\overline{OE}$	A or B	2	3.6	4.5	2	5.5	2	5.4	ns
t_{PLZ}			1.5	3	3.8	1.5	4.7	1.5	4.3	
t_{PZH}	$\overline{OE}$	PARITY	2	3.6	5	2	5.8	2	5.7	ns
t_{PZL}			2.5	4.4	5.8	2.5	6.7	2.5	6.5	
t_{PHZ}	$\overline{OE}$	PARITY	1.5	3.2	4	1.5	4.8	1.5	4.7	ns
t_{PLZ}			1.5	2.9	3.7	1.5	4.2	1.5	4.1	
t_{PLH}	$\overline{LE}$	$\overline{ERR}$	2	3.5	4.2	2	5	2	4.8	ns
t_{PHL}			2	3.4	4.4	2	5.2	2	4.9	
t_{PLH}	A, B, or PARITY	$\overline{ERR}$	2	4.5	6.3	2	7.5	2	7.2	ns
t_{PHL}			2	4.8	6.3	2	7.7	2	7.4	

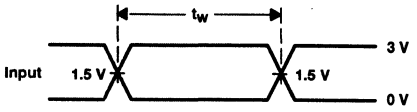
PARAMETER MEASUREMENT INFORMATION



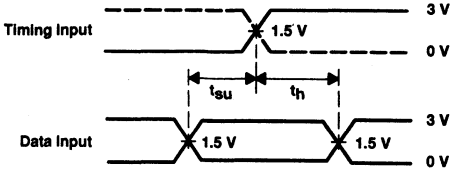
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

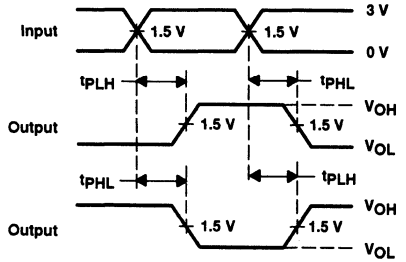
ERR	S1
t_{PHL} (see Note E)	7 V
t_{PLH} (see Note F)	7 V



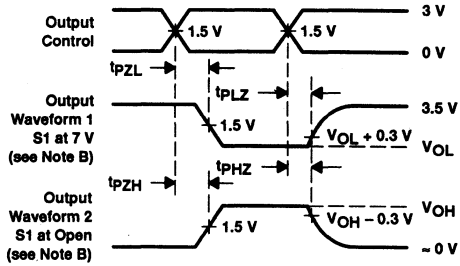
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PHL} is measured at 1.5 V.
F. t_{PLH} is measured at V_{OL} + 0.3 V.

Figure 1. Load Circuit and Voltage Waveforms

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- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
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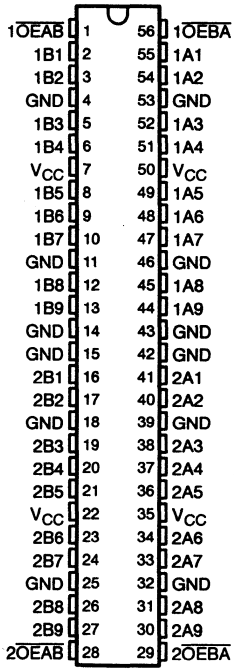
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16863 . . . WD PACKAGE
SN74ABT16863 . . . DL PACKAGE
(TOP VIEW)



description

The 'ABT16863 are 18-bit noninverting transceivers designed for asynchronous communication between data buses. The control-function implementation minimizes external timing requirements.

The 'ABT16863 can be used as two 9-bit transceivers or one 18-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16863 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16863 is characterized for operation from –40°C to 85°C.

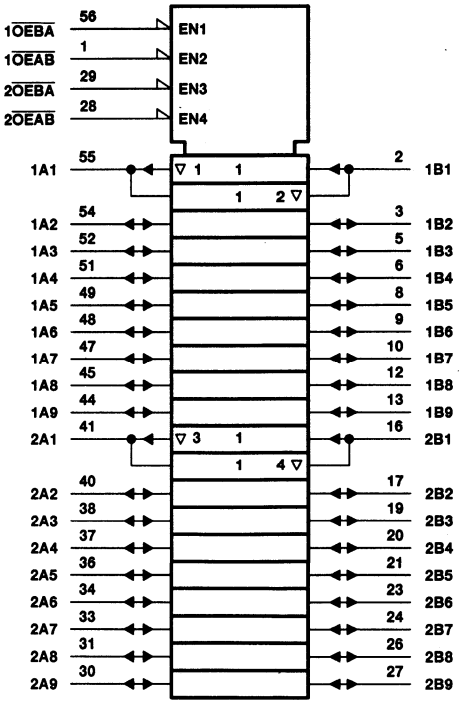
Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

FUNCTION TABLE
(each 9-bit section)

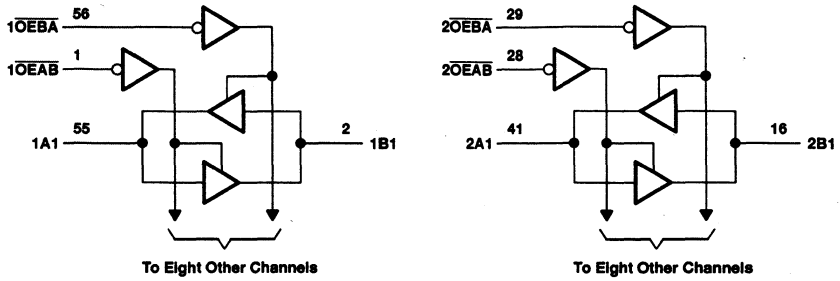
INPUTS		OPERATION
$\overline{OEAB}$	$\overline{OEBA}$	
H	L	B data to A bus
L	H	A data to B bus
H	H	Isolation

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16863 ..... 96 mA
SN74ABT16863 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16863		SN74ABT16863		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		µs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

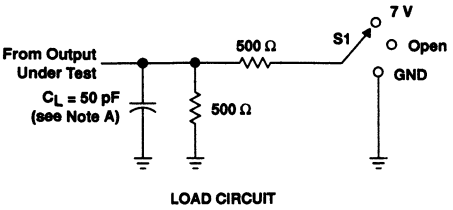
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16863		SN74ABT16863		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±20		±20	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			32		32		32	
			Outputs disabled			2		2		2	
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1		1.5		1	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3.5						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

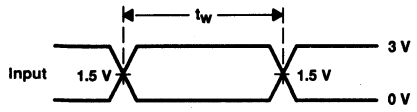
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16863		SN74ABT16863		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	2.2	3.2	1	3.7	1	3.5	ns
t_{PHL}			1	2.2	3.4	1	4.2	1	3.9	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	1	2.9	4.5	1	5.7	1	5.4	ns
t_{PZL}			1	2.6	4.1	1	5.2	1	4.8	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	1.6	4.1	5.4	1.6	6.3	1.6	6	ns
t_{PLZ}			1.5	3.3	4.5	1.5	5.3	1.5	5	

PARAMETER MEASUREMENT INFORMATION

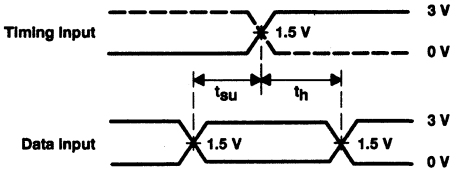


LOAD CIRCUIT

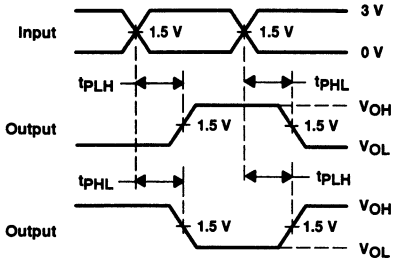
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



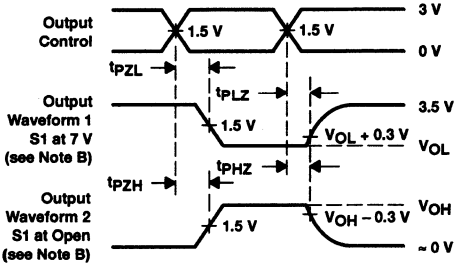
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



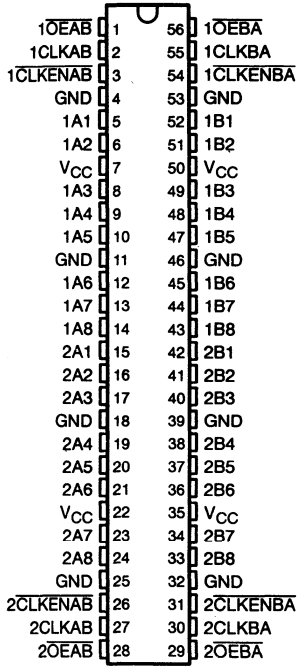
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16952 . . . WD PACKAGE
SN74ABT16952 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT16952 are 16-bit registered transceivers that contain two sets of D-type flip-flops for temporary storage of data flowing in either direction. The 'ABT16952 can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable ($\overline{\text{CLKENAB}}$ or $\overline{\text{CLKENBA}}$) input is low. Taking the output-enable ($\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$) input low accesses the data on either port.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16952 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16952 is characterized for operation from –40°C to 85°C.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

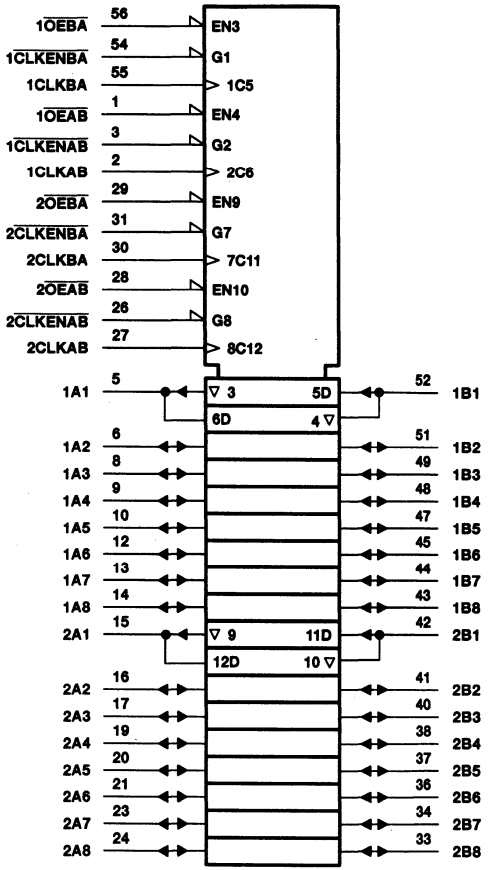
FUNCTION TABLE†

INPUTS				OUTPUT
$\overline{CLKENAB}$	CLKAB	$\overline{OEAB}$	A	B
H	X	L	X	B_0‡
X	L	L	X	B_0‡
L	↑	L	L	L
L	↑	L	H	H
X	X	H	X	Z

† A-to-B data flow is shown; B-to-A data flow is similar, but uses $\overline{CLKENBA}$, CLKBA, and $\overline{OEBA}$.

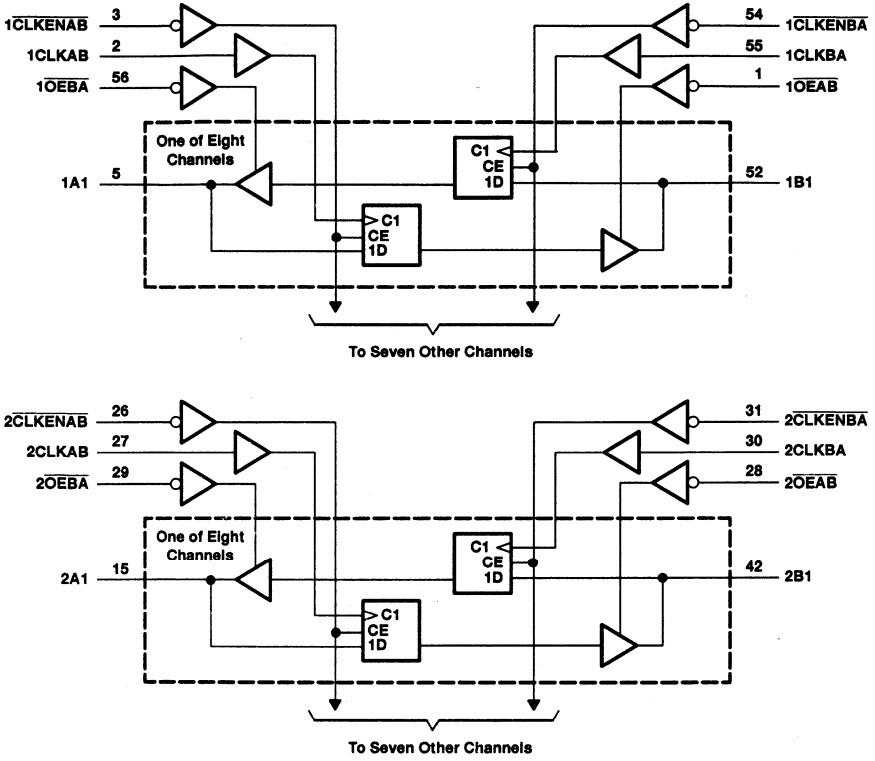
‡ Level of B before the indicated steady-state input conditions were established

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16952 ..... 96 mA
SN74ABT16952 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16952		SN74ABT16952		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16952		SN74ABT16952		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–200	–50	–200	–50	–200	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			35		35		35	
			Outputs disabled			2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				0.5		0.5		0.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			8.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

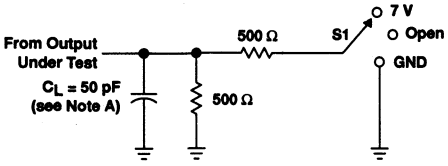
			V_{CC} = 5 V, T_A = 25°C		SN54ABT16952		SN74ABT16952		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	150	0	150	0	150	MHz
t_w†	Pulse duration, CLKAB or CLKBA high or low		3.3		3.3		3.3		ns
t_{su}	Setup time, before CLKAB↑ or CLKBA↑	A or B	3.5		3.5		3.5		ns
		$\overline{CLKENAB}$ or $\overline{CLKENBA}$	3				3		
t_h	Hold time, after CLKAB↑ or CLKBA↑	A or B	1		1		1		ns
		$\overline{CLKENAB}$ or $\overline{CLKENBA}$	1		1		1		

† This parameter is warranted, but not production tested.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

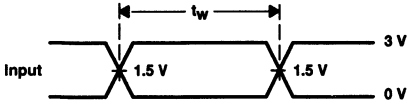
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16952		SN74ABT16952		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			150			150		150		MHz
t_{PLH}	CLK	A or B	1	2.6	3.9	1	4.4	1	4.3	ns
t_{PHL}			1	2.6	4.2	1	4.6	1	4.5	
t_{PZH}	$\overline{OE}$	A or B	1	2.5	3.8	1	4.7	1	4.6	ns
t_{PZL}			1	2.8	5.1	1	6.1	1	6	
t_{PHZ}	$\overline{OE}$	A or B	1.7	3.4	4.7	1.7	6.1	1.7	5.5	ns
t_{PLZ}			1.3	3	3.9	1.3	4.8	1.3	4.2	

PARAMETER MEASUREMENT INFORMATION

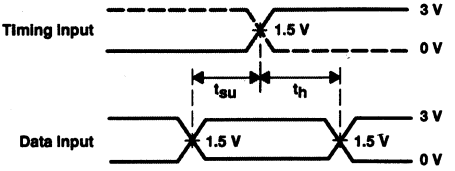


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

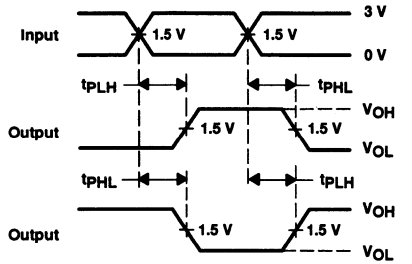
LOAD CIRCUIT



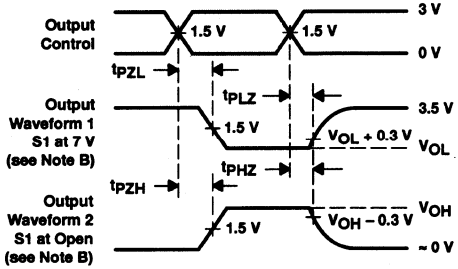
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

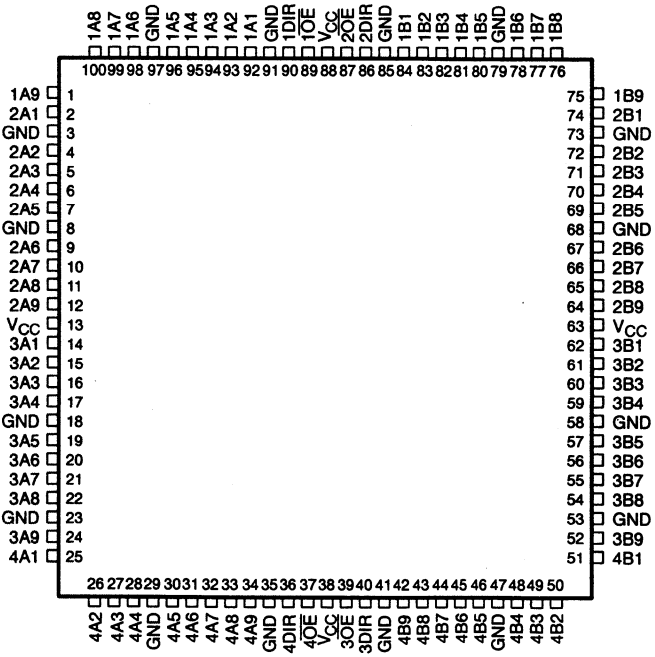
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

Contents

- Members of the Texas Instruments *Widebus+*™ Family
- State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C
- High-Impedance State During Power Up and Power Down
- Released as DSCC SMD 5962-9557701NXD
- PZ Package Qualified for Military Per MIL-PRF-38535 (QML)
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include 100-Pin Plastic Thin Quad Flat (PZ) Package With 14 × 14-mm Body Using 0.5-mm Lead Pitch and Space-Saving 100-Pin Ceramic Quad Flat (HS) Package†

'ABTH32245 . . . PZ PACKAGE
(TOP VIEW)



† The HS package is not production released.

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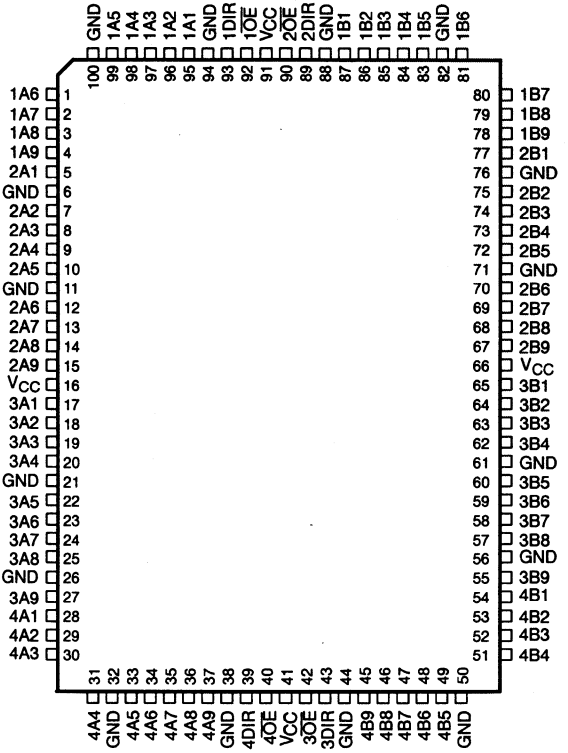
TEXAS INSTRUMENTS

SN54ABTH32245 . . . HS PACKAGE†
(TOP VIEW)



† For HS package availability, please contact the factory or your local TI Field Sales Office.

description

The 'ABTH32245 are 36-bit (quad 9-bit) noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as four 9-bit transceivers, two18-bit transceivers, or one 36-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) inputs. The output-enable ($\overline{OE}$) inputs can be used to disable the device so that the buses are effectively isolated.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or floating data inputs at a valid logic level.

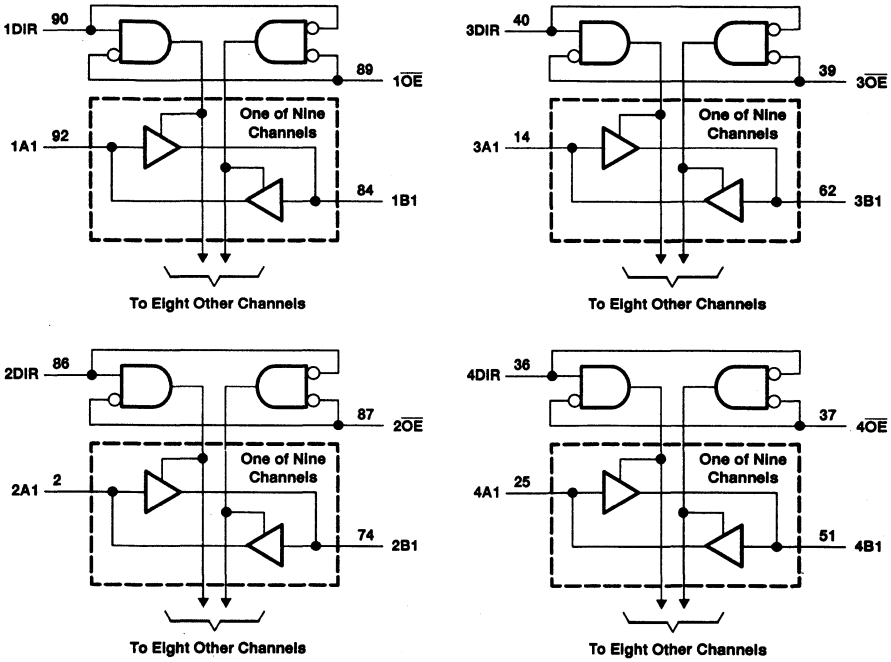
description (continued)

The SN54ABTH32245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH32245 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 9-bit section)

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic diagram (positive logic)



Pin numbers shown are for the PZ package.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH32245 ..... 96 mA
SN74ABTH32245 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): PZ package ..... 50°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABTH32245		SN74ABTH32245		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ABTH32245			SN74ABTH32245			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2			–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5			V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3			
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2						
			I_{OH} = –32 mA				2			
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55			0.55	V
			I_{OL} = 64 mA						0.55	
V_{hys}					100			100		mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND						±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V,	V_I = V_{CC} or GND						±20	
	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1				µA
	A or B ports					±20				
$I_{I(hold)}$	A or B ports	V_{CC} = 4.5 V	V_I = 0.8 V	100			100			µA
			V_I = 2 V	–100			–100			
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V						±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50			50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–100	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3			3	mA
			Outputs low			20			20	
			Outputs disabled			2			2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1			1	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3.5			3.5		pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9.5			9.5		pF

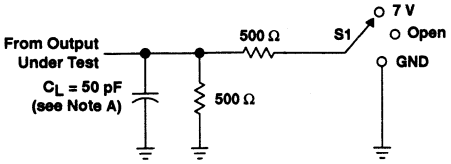
† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ This parameter is specified by characterization.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C#			SN54ABTH32245		SN74ABTH32245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.7	3.2	4.4	1	5.3	1.7	5	ns
t_{PHL}			1.7	3.3	4.6	1	5.3	1.7	5.2	
t_{PZH}	$\overline{OE}$	B or A	1.6	4.2	6.1	1	7.6	1.6	7.3	ns
t_{PZL}			2.7	5.2	7	1.5	8.2	2.7	8.1	
t_{PHZ}	$\overline{OE}$	B or A	1.3	3.9	6.1	0.8	6.7	1.3	6.5	ns
t_{PLZ}			2	4.4	6.6	1	7.2	2	6.9	

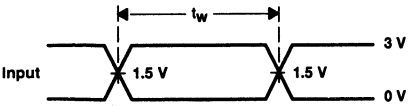
These limits apply only to the SN74ABTH32245

PARAMETER MEASUREMENT INFORMATION

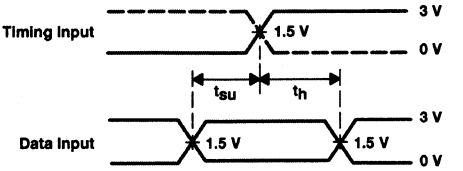


LOAD CIRCUIT

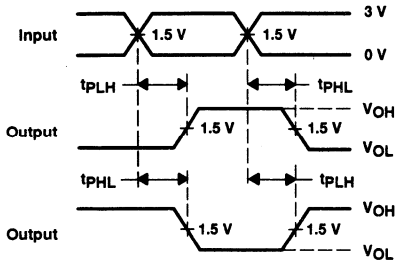
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



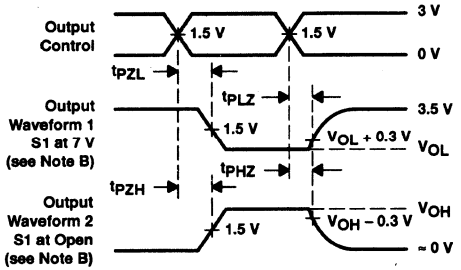
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

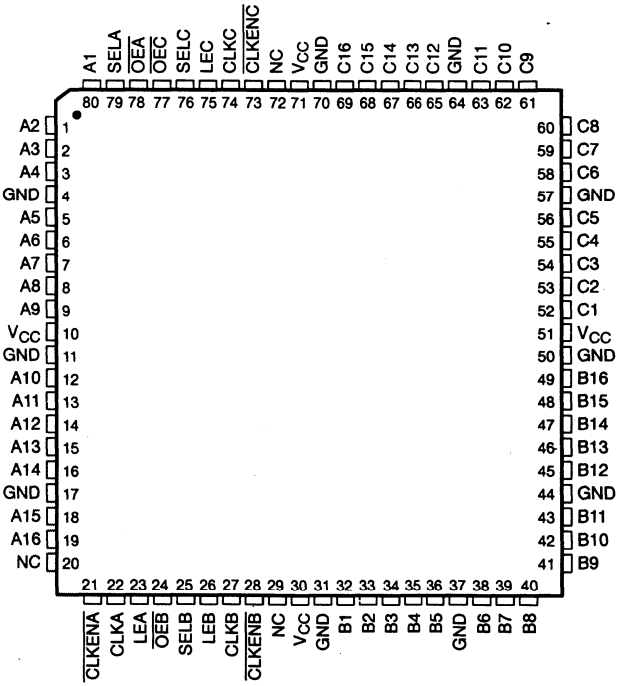
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

SCBS179E – JUNE 1992 – REVISED MAY 1997

- Members of the Texas Instruments *Widebus+*™ Family
- State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation
- *UBE*™ (Universal Bus Exchanger) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, Clocked, or Clock-Enabled Mode
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C
- High-Impedance State During Power Up and Power Down
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include 80-Pin Plastic Thin Quad Flat (PN) Package With 12 × 12-mm Body Using 0.5-mm Lead Pitch and 84-Pin Ceramic Quad Flat (HT) Package

'ABTH32316 . . . PN PACKAGE
(TOP VIEW)

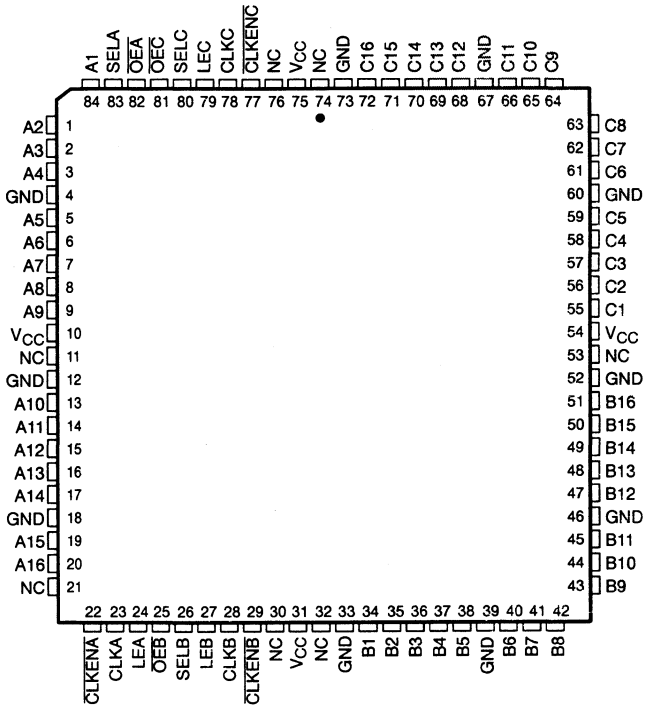


NC – No internal connection

Widebus+, EPIC-IIB, and UBE are trademarks of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

SN54ABTH32316 . . . HT PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABTH32316 consist of three 16-bit registered input/output (I/O) ports. These registers combine D-type latches and flip-flops to allow data flow in transparent, latch, and clock modes. Data from one input port can be exchanged to one or more of the other ports. Because of the universal storage element, multiple combinations of real-time and stored data can be exchanged among the three ports.

Data flow in each direction is controlled by the output-enable ($\overline{OEA}$, $\overline{OEB}$, and $\overline{OEC}$), select-control (SELA, SELB, and SELC), latch-enable (LEA, LEB, and LEC), and clock (CLKA, CLKB, and CLKC) inputs. The A data register operates in the transparent mode when LEA is high. When LEA is low, data is latched if CLKA is held at a high or low logic level. If LEA and clock-enable A ($\overline{CLKENA}$) are low, data is stored on the low-to-high transition of CLKA. Output data selection is accomplished by the select-control pins. All three ports have active-low output enables, so when the output-enable input is low, the outputs are active; when the output-enable input is high, the outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

description (continued)

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ABTH32316 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH32316 is characterized for operation from –40°C to 85°C.

Function Tables

STORAGE†

INPUTS				OUTPUT
$\overline{\text{CLKENA}}$	CLKA	LEA	A	
H	X	L	X	Q_0‡
L	↑	L	L	L
L	↑	L	H	H
X	H	L	X	Q_0‡
X	L	L	X	Q_0‡
X	X	H	L	L
X	X	H	H	H

† A-port register shown. B and C ports are similar but use $\overline{\text{CLKENB}}$, $\overline{\text{CLKENC}}$, CLKB, CLKC, LEB, and LEC.

‡ Output level before the indicated steady-state input conditions were established

A-PORT OUTPUT

INPUTS		OUTPUT A
$\overline{\text{OEA}}$	SELA	
H	X	Z
L	H	Output of C register
L	L	Output of B register

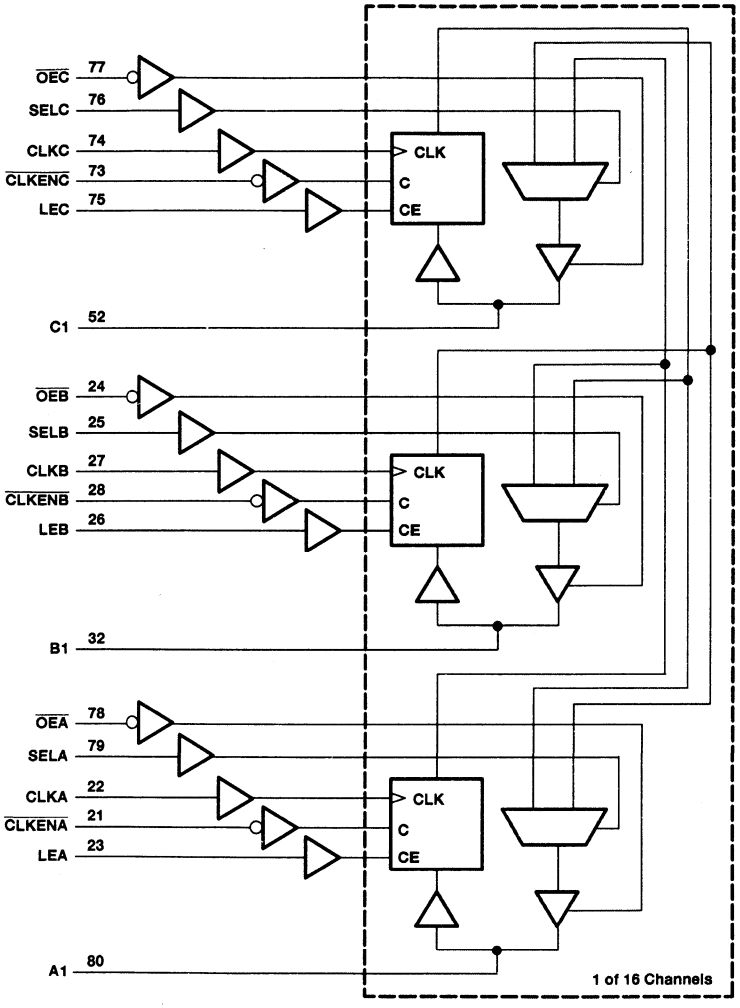
B-PORT OUTPUT

INPUTS		OUTPUT B
$\overline{\text{OEB}}$	SELB	
H	X	Z
L	H	Output of A register
L	L	Output of C register

C-PORT OUTPUT

INPUTS		OUTPUT C
$\overline{\text{OEC}}$	SELC	
H	X	Z
L	H	Output of B register
L	L	Output of A register

logic diagram (positive logic)



Pin numbers shown are for the PN package.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH32316 ..... 96 mA
SN74ABTH32316 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): PN package ..... 62°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABTH32316		SN74ABTH32316		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ABTH32316			SN74ABTH32316			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2			–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5			V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3			
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2						
			I_{OH} = –32 mA				2			
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55				V
			I_{OL} = 64 mA						0.55	
V_{hys}					100			100		mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1			±1	µA
	A, B, or C ports	V_{CC} = 2.1 V to 5.5 V,	V_I = V_{CC} or GND			±100			±20	
$I_{I(hold)}$	A, B, or C ports	V_{CC} = 4.5 V	V_I = 0.8 V	100			100			µA
			V_I = 2 V	–100			–100			
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100			±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50			50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–100	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2			2	mA
			Outputs low			40			40	
			Outputs disabled			1			1	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1			0.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3			3		pF
C_{io}	A, B, or C ports	V_O = 2.5 V or 0.5 V			11.5			11.5		pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ This parameter is specified by characterization.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

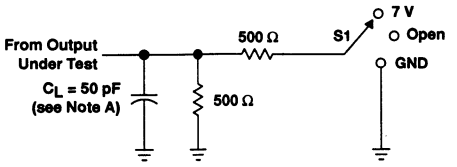
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54ABTH32316		SN74ABTH32316		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	150	0	150	MHz
t_w	Pulse duration	LE high	3.3		3.3		ns
		CLK high or low	3.3		3.3		
t_{su}	Setup time	A, B, or C before CLK↑	2.6		2.4		ns
		A or B before LE↓	2.5		2.1		
		$\overline{CLKEN}$ before CLK↑	3.5		3.2		
t_h	Hold time	A, B, or C after CLK↑	1.8		1.4		ns
		A or B after LE↓	2.4		2.1		
		$\overline{CLKEN}$ after CLK↑	1.5		1.1		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

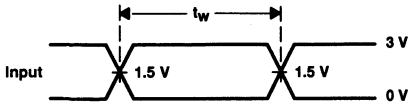
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABTH32316		SN74ABTH32316		UNIT
			MIN	MAX	MIN	MAX	
f_{max}			150		150		MHz
t_{PLH}	A, B, or C	C, B, or A	0.8	6.5	1.4	6.1	ns
t_{PHL}			0.5	6.8	1.1	6.6	
t_{PLH}	SEL	A, B, or C	0.8	6.7	1.4	6.5	ns
t_{PHL}			0.8	6.8	1.8	6.5	
t_{PLH}	LE	A, B, or C	1.5	8	2.6	7.5	ns
t_{PHL}			1.5	7.4	2.6	6.9	
t_{PLH}	CLK	A, B, or C	1.5	8	2.5	7.5	ns
t_{PHL}			1.5	7.2	2.5	6.7	
t_{PZH}	$\overline{OE}$	A, B, or C	0.8	6.7	1.5	6.4	ns
t_{PZL}			1.5	7.1	2.4	6.8	
t_{PHZ}	$\overline{OE}$	A, B, or C	0.8	7.2	1.5	6	ns
t_{PLZ}			0.8	6.4	1.9	6.1	

PARAMETER MEASUREMENT INFORMATION

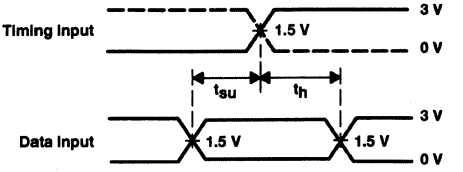


LOAD CIRCUIT

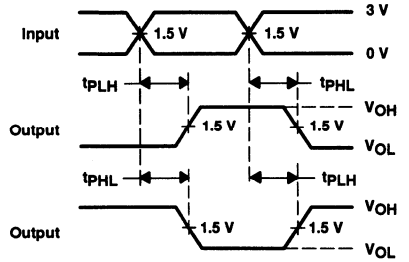
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



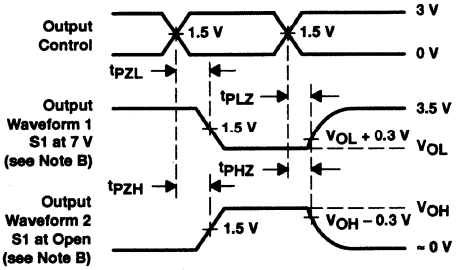
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



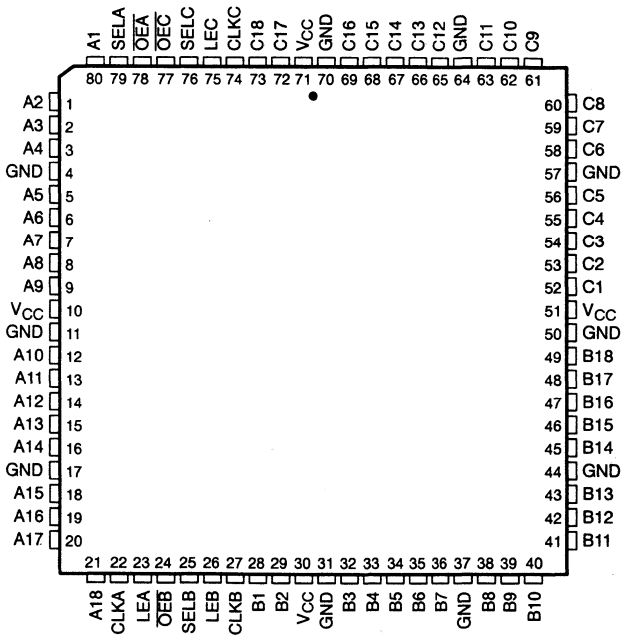
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- Members of the Texas Instruments *Widebus+*™ Family
- State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation
- *UBE*™ (Universal Bus Exchanger) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C
- High-Impedance State During Power Up and Power Down
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include 80-Pin Plastic Thin Quad Flat (PN) Package With 12 × 12-mm Body Using 0.5-mm Lead Pitch and 84-Pin Ceramic Quad Flat (HT) Package

SN74ABTH32318 . . . PN PACKAGE
(TOP VIEW)



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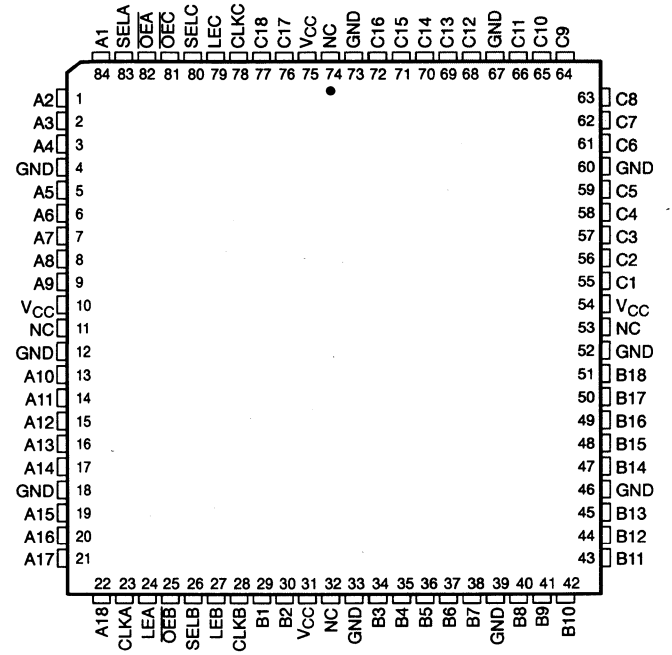
TEXAS INSTRUMENTS

SN54ABTH32318 . . . HT PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'ABTH32318 consist of three 18-bit registered input/output (I/O) ports. These registers combine D-type latches and flip-flops to allow data flow in transparent, latch, and clock modes. Data from one input port can be exchanged to one or more of the other ports. Because of the universal storage element, multiple combinations of real-time and stored data can be exchanged among the three ports.

Data flow in each direction is controlled by the output-enable ($\overline{OEA}$, $\overline{OEB}$, and $\overline{OEC}$), select-control (SELA, SELB, and SELC), latch-enable (LEA, LEB, and LEC), and clock (CLKA, CLKB, and CLKC) inputs. The A data register operates in the transparent mode when LEA is high. When LEA is low, data is latched if CLKA is held at a high or low logic level. If LEA is low, data is stored on the low-to-high transition of CLKA. Output data selection is accomplished by the select-control pins. All three ports have active-low output enables, so when the output-enable input is low, the outputs are active; when the output-enable input is high, the outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

description (continued)

The SN54ABTH32318 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH32318 is characterized for operation from –40°C to 85°C.

Function Tables

STORAGE†

INPUTS			OUTPUT
CLKA	LEA	A	
↑	L	L	L
↑	L	H	H
H	L	X	Q_0‡
L	L	X	Q_0‡
X	H	L	L
X	H	H	H

† A-port register shown. B and C ports are similar but use CLKB, CLKC, LEB, and LEC.

‡ Output level before the indicated steady-state input conditions were established

A-PORT OUTPUT

INPUTS		OUTPUT A
$\overline{OEA}$	SELA	
H	X	Z
L	H	Output of C register
L	L	Output of B register

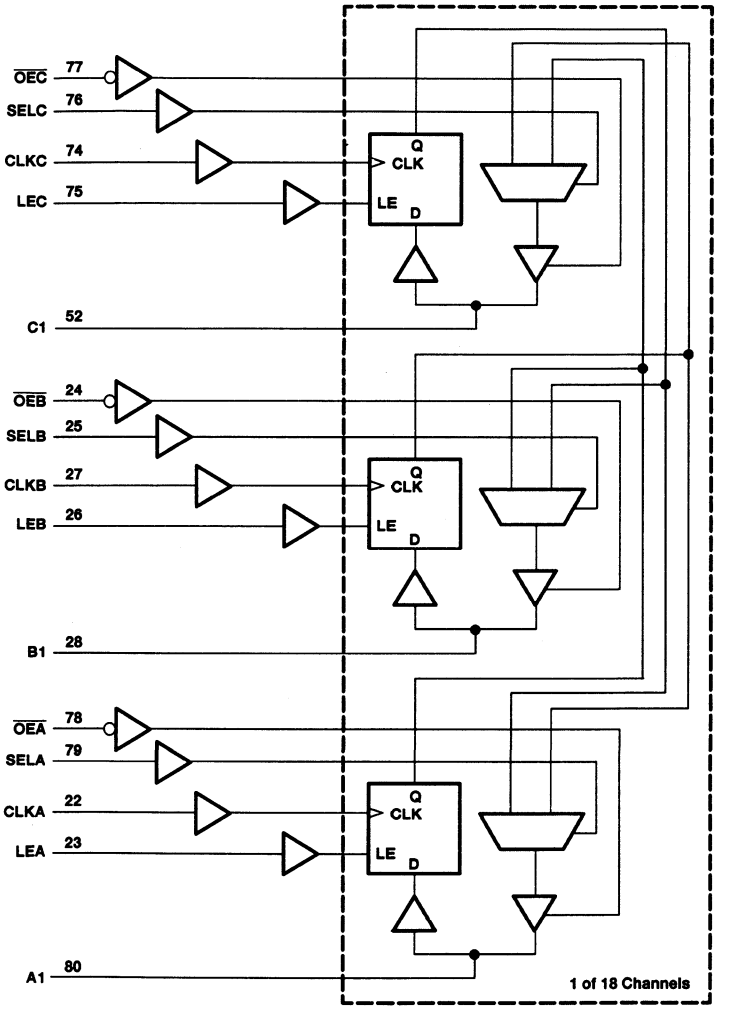
B-PORT OUTPUT

INPUTS		OUTPUT B
$\overline{OEB}$	SELB	
H	X	Z
L	H	Output of A register
L	L	Output of C register

C-PORT OUTPUT

INPUTS		OUTPUT C
$\overline{OEC}$	SELC	
H	X	Z
L	H	Output of B register
L	L	Output of A register

logic diagram (positive logic)



Pin numbers shown are for the PN package.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH32318 ..... 96 mA
SN74ABTH32318 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): PN package ..... 62°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABTH32318		SN74ABTH32318		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		µs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ABTH32318			SN74ABTH32318			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2			–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5			V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3			
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2						
			I_{OH} = –32 mA				2			
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55			0.55	V
			I_{OL} = 64 mA			0.55			0.55	
V_{hys}					100			100		mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1			±1	µA
	A, B, or C ports	V_{CC} = 2.1 V to 5.5 V,	V_I = V_{CC} or GND			±20			±20	
$I_{I(hold)}$	A, B, or C ports	V_{CC} = 4.5 V	V_I = 0.8 V	100			100			µA
			V_I = 2 V	–100			–100			
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100			±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50			50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–100	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2			2	mA
			Outputs low			45			45	
			Outputs disabled			1			1	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				0.5			0.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3			3		pF
C_{io}	A, B, or C ports	V_O = 2.5 V or 0.5 V			11.5			11.5		pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ This parameter is specified by characterization.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

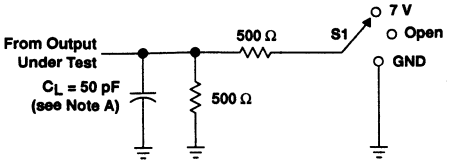
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54ABTH32318		SN74ABTH32318		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			150		150	MHz
t_w	Pulse duration	LE high	3.3		3.3		ns
		CLK high or low	3.3		3.3		
t_{su}	Setup time	A, B, or C before CLK↑	2.4		2.4		ns
		A, B, or C before LE↓	2.1		2.1		
t_h	Hold time	A, B, or C after CLK↑	1.4		1.4		ns
		A, B, or C after LE↓	2.1		2.1		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

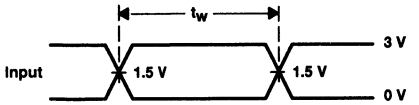
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABTH32318		SN74ABTH32318		UNIT
			MIN	MAX	MIN	MAX	
f_{max}			150		150		MHz
t_{PLH}	A, B, or C	C, B, or A	1.4	6.5	1.4	6.1	ns
t_{PHL}			1.1	6.8	1.1	6.6	
t_{PLH}	SEL	A, B, or C	1.4	6.7	1.4	6.5	ns
t_{PHL}			1.8	6.8	1.8	6.5	
t_{PLH}	LE	A, B, or C	2.6	8	2.6	7.5	ns
t_{PHL}			2.6	7.4	2.6	6.9	
t_{PLH}	CLK	A, B, or C	2.5	8	2.5	7.4	ns
t_{PHL}			2.5	7.2	2.5	6.7	
t_{PZH}	$\overline{OE}$	A, B, or C	1.4	6.9	1.4	6.8	ns
t_{PZL}			2.4	7.2	2.4	7.1	
t_{PHZ}	$\overline{OE}$	A, B, or C	1	6.4	1	6.2	ns
t_{PLZ}			2	6.4	2	6	

PARAMETER MEASUREMENT INFORMATION

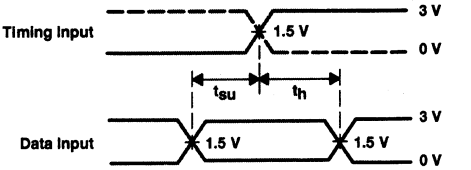


LOAD CIRCUIT

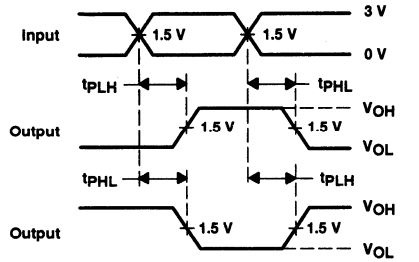
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



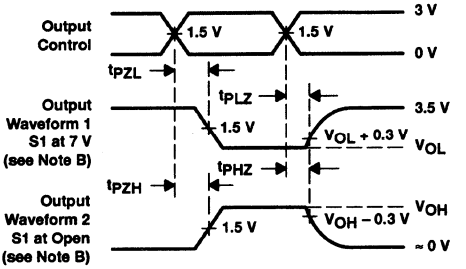
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



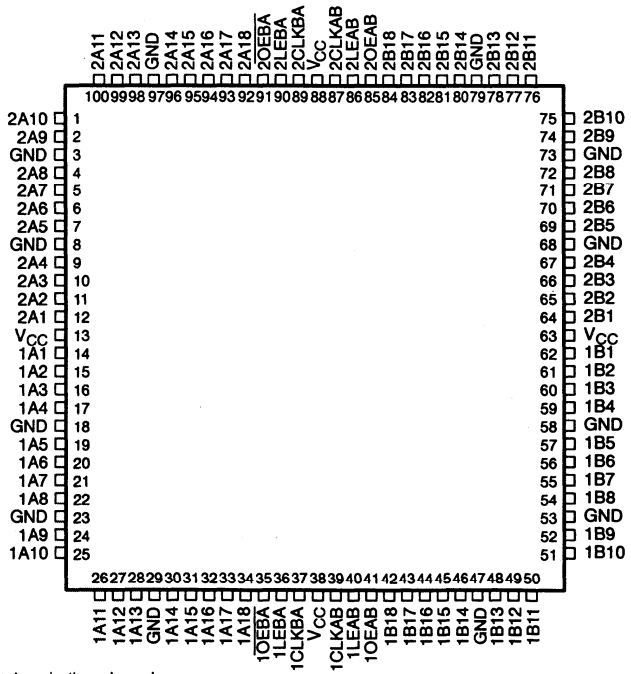
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- Members of the Texas Instruments *Widebus+*™ Family
- State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- *UBT*™ (Universal Bus Transceiver) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Released as DSCC SMD 5962-9557601NXD
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C
- High-Impedance State During Power Up and Power Down
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include 100-Pin Plastic Thin Quad Flat (PZ) Package With 14 × 14-mm Body Using 0.5-mm Lead Pitch and Space-Saving 100-Pin Ceramic Quad Flat (HS) Package†

'ABTH32501 . . . PZ PACKAGE
(TOP VIEW)

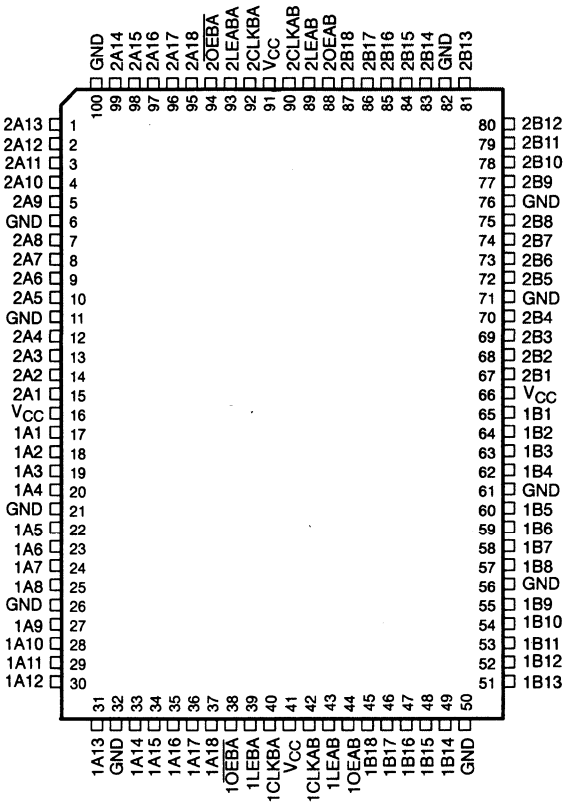


† The HS package is not production released.

Widebus+, EPIC-IIB, and UBT are trademarks of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

SN54ABTH32501 . . . HS PACKAGE†
(TOP VIEW)



† For HS package availability, please contact the factory or your local TI Field Sales Office.

description

These 36-bit UBTs combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes.

Data flow in each direction is controlled by output-enable (OEAB and $\overline{\text{OEBA}}$), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. Data flow for B to A is similar to that of A to B, but uses $\overline{\text{OEBA}}$, LEBA, and CLKBA.

Output-enable OEAB is active high. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state. The output enables are complementary (OEAB is active high, and $\overline{\text{OEBA}}$ is active low).

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

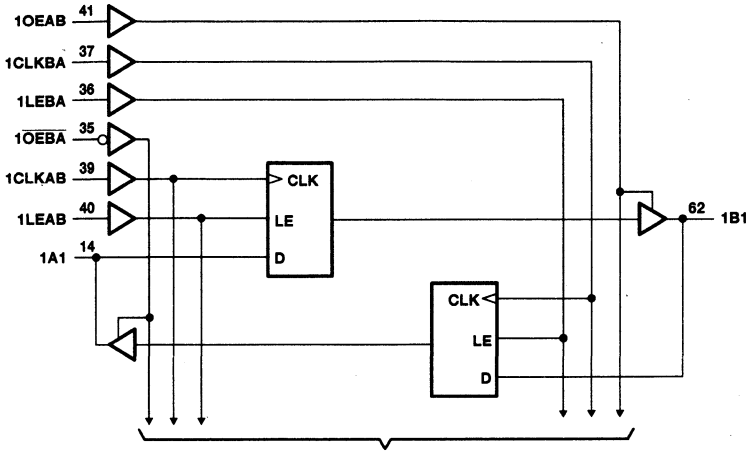
The SN54ABTH32501 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH32501 is characterized for operation from –40°C to 85°C.

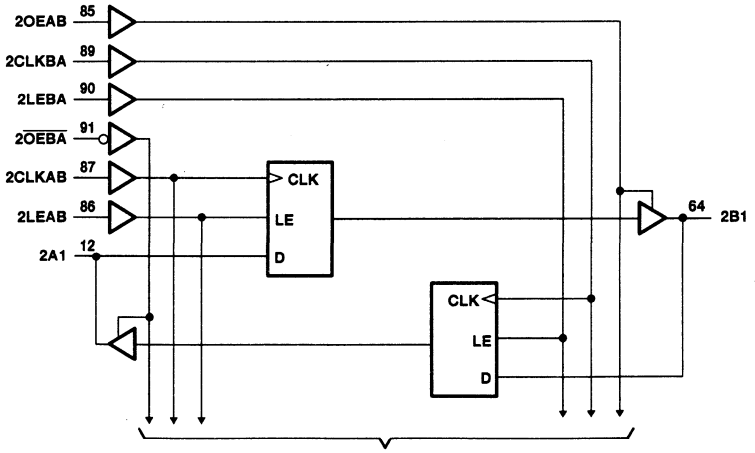
FUNCTION TABLE†

INPUTS				OUTPUT
OEAB	LEAB	CLKAB	A	B
L	X	X	X	Z
H	H	X	L	L
H	H	X	H	H
H	L	↑	L	L
H	L	↑	H	H
H	L	H	X	B_0‡
H	L	L	X	B_0§

† A-to-B data flow is shown: B-to-A flow is similar, but uses $\overline{\text{OEBA}}$, LEBA, and CLKBA.
‡ Output level before the indicated steady-state input conditions were established
§ Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

logic diagram (positive logic)





Pin numbers shown are for the PZ package.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH32501 ..... 96 mA
SN74ABTH32501 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): PZ package ..... 50°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABTH32501		SN74ABTH32501		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ABTH32501			SN74ABTH32501			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2			–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5			V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3			
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2						
			I_{OH} = –32 mA				2			
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55			0.55	V
			I_{OL} = 64 mA						0.55	
V_{hys}					100			100		mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND						±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V,	V_I = V_{CC} or GND						±20	
	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±5				
	A or B ports					±50				
$I_{I(hold)}$	A or B ports	V_{CC} = 4.5 V	V_I = 0.8 V	100			100			µA
			V_I = 2 V	–100			–100			
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, OE or $\overline{OE}$ = X				±50			±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, OE or $\overline{OE}$ = X				±50			±50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V						±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50			50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–100	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			6			6	mA
			Outputs low			90			90	
			Outputs disabled			6			6	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1			1	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3.5			3.5		pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			11.5			11.5		pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ This parameter is specified by characterization.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

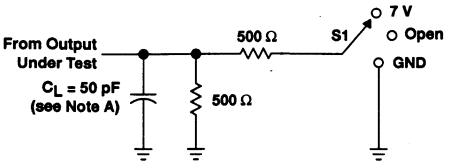
			SN54ABTH32501		SN74ABTH32501		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	150	0	150	MHz
t_w	Pulse duration	LE high	3.5		3.3		ns
		CLK high or low	3.5		3.3		
t_{su}	Setup time	A or B before CLK↑	4.3		3.5		ns
		A or B before LE↓	2.5		1.6		
t_h	Hold time	A or B after CLK↑	0.2		0		ns
		A or B after LE↓	1.8		1.6		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABTH32501			SN74ABTH32501			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
f_{max}			150			150			MHz
t_{PLH}	A or B	B or A	0.5	2.9	5.2	1.3	2.9	4.8	ns
t_{PHL}			0.5	2.7	5.8	1.4	2.7	5.4	
t_{PLH}	LEAB or LEBA	A or B	0.7	3.4	5.7	1.6	3.4	5.3	ns
t_{PHL}			0.7	3.6	5.9	1.9	3.6	5.5	
t_{PLH}	CLKAB or CLKBA	A or B	0.5	3.2	5.7	1.5	3.2	5.3	ns
t_{PHL}			0.7	3.3	5.8	1.7	3.3	5.4	
t_{PZH}	OEAB or $\overline{OEBA}$	A or B	0.5	3.2	6.2	1.2	3.2	5.6	ns
t_{PZL}			0.5	3.6	6.6	1.5	3.6	6	
t_{PHZ}	OEAB or $\overline{OEBA}$	A or B	0.7	3.6	7	1.8	3.6	5.9	ns
t_{PLZ}			0.7	3.5	6.1	1.7	3.5	5.6	

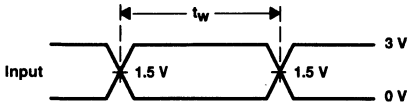
† All typical values are at V_{CC} = 5 V, T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

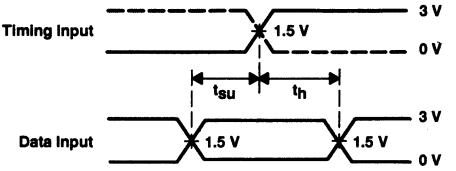


LOAD CIRCUIT

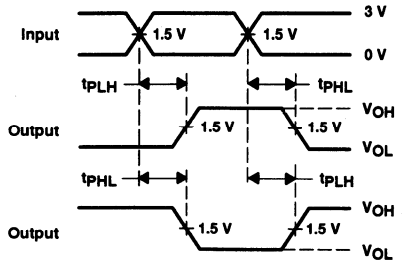
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



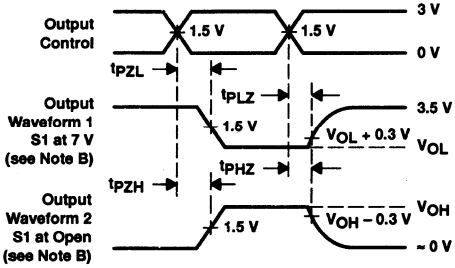
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



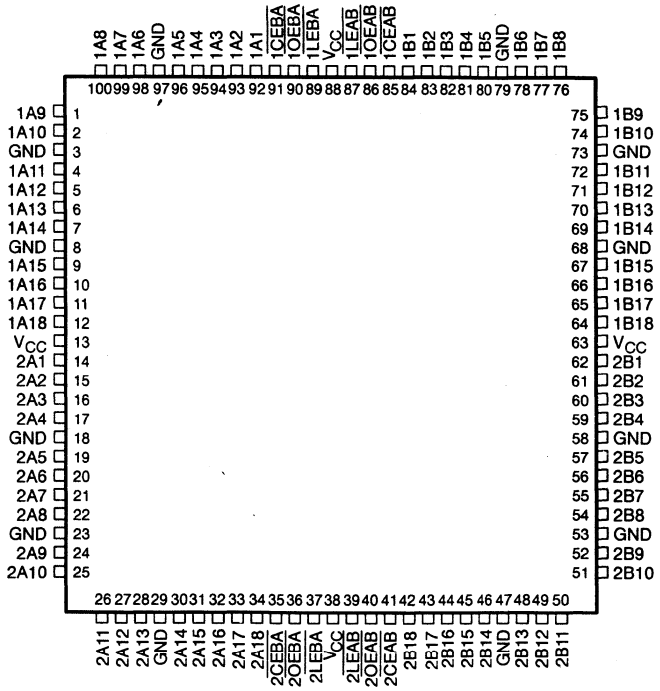
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus+*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Released as DSCC SMD 5962-9557801NXD**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Package Options Include 100-Pin Plastic Thin Quad Flat (PZ) Package With 14 × 14-mm Body Using 0.5-mm Lead Pitch and Space-Saving 100-Pin Ceramic Quad Flat (HS) Package†**

'ABTH32543 . . . PZ PACKAGE
(TOP VIEW)



† The HS package is not production released.

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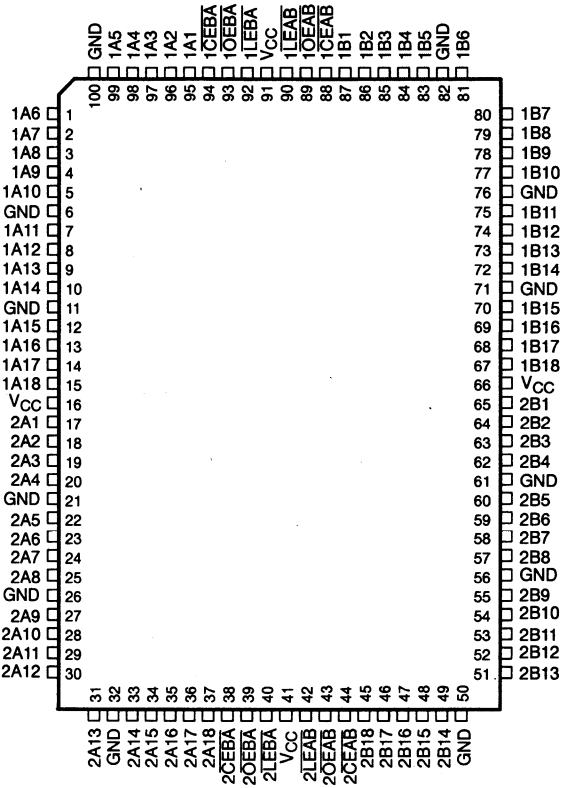
TEXAS INSTRUMENTS

SN54ABTH32543 . . . HS PACKAGE†
(TOP VIEW)



† For HS package availability, please contact the factory or your local TI Field Sales Office.

description

The 'ABTH32543 are 36-bit registered transceivers that contain two sets of D-type latches for temporary storage of data flowing in either direction. These devices can be used as two 18-bit transceivers or one 36-bit transceiver. Separate latch-enable ($\overline{LEAB}$ or $\overline{LEBA}$) and output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable ($\overline{CEAB}$) input must be low to enter data from A or to output data from B. If $\overline{CEAB}$ is low and $\overline{LEAB}$ is low, the A-to-B latches are transparent; a subsequent low-to-high transition of $\overline{LEAB}$ puts the A latches in the storage mode. With $\overline{CEAB}$ and $\overline{OEAB}$ both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$ inputs.

description (continued)

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

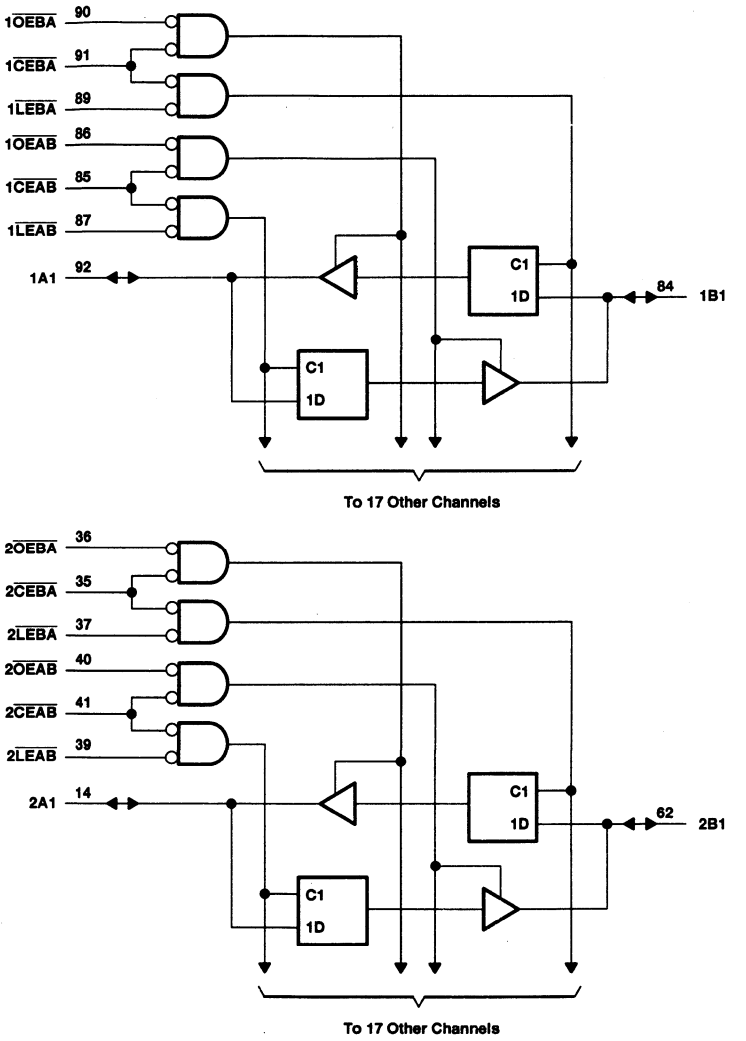
The SN54ABTH32543 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH32543 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE† (each 18-bit section)

INPUTS				OUTPUT
$\overline{CEAB}$	$\overline{LEAB}$	$\overline{OEAB}$	A	B
H	X	X	X	Z
X	X	H	X	Z
L	H	L	X	B_0‡
L	L	L	L	L
L	L	L	H	H

† A-to-B data flow is shown; B-to-A flow control is the same except that it uses $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$.
‡ Output level before the indicated steady-state input conditions were established

logic diagram (positive logic)



Pin numbers shown are for the PZ package.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH32543 ..... 96 mA
SN74ABTH32543 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): PZ package ..... 50°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABTH32543		SN74ABTH32543		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ABTH32543			SN74ABTH32543			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2			–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = – 3 mA	2.5			2.5			V
		V_{CC} = 5 V,	I_{OH} = – 3 mA	3			3			
		V_{CC} = 4.5 V	I_{OH} = – 24 mA	2						
			I_{OH} = – 32 mA				2			
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55			0.55	V
			I_{OL} = 64 mA						0.55	
V_{hys}					100			100		mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND						±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V,	V_I = V_{CC} or GND						±20	
	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1				
	A or B ports					±20				
$I_{I(hold)}$	A or B ports	V_{CC} = 4.5 V	V_I = 0.8 V				100			µA
			V_I = 2 V				–100			
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V						±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50			50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–100	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3			3	mA
			Outputs low			20			20	
			Outputs disabled			2			2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1			1	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3.5			3.5		pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9.5			9.5		pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ This parameter is specified by characterization.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C#		SN54ABTH32543		SN74ABTH32543		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low		3.3		3.3		3.3		ns
t_{su}	Setup time	Data before $\overline{LEAB}$↑ or $\overline{LEBA}$↑	2.1		2.6		2.1		ns
		Data before $\overline{CEAB}$↑ or $\overline{CEBA}$↑	1.7		2		1.7		
t_h	Hold time	Data after $\overline{LEAB}$↑ or $\overline{LEBA}$↑	0.6		1.1		0.6		ns
		Data after $\overline{CEAB}$↑ or $\overline{CEBA}$↑	0.9		1.2		0.9		

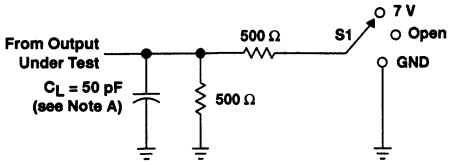
These limits apply only to the SN74ABTH32543.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C†			SN54ABTH32543		SN74ABTH32543		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	3.5	5.2	0.5	6.3	1	5.9	ns
t_{PHL}			1	3.5	5.1	0.5	5.9	1	5.7	
t_{PLH}	$\overline{LE}$	A or B	1.9	4.6	6.3	0.8	7.9	1.9	7.5	ns
t_{PHL}			1.9	4.3	5.9	0.8	6.9	1.9	6.6	
t_{PZH}	$\overline{CE}$	A or B	1.7	4.3	6.7	0.8	8.3	1.7	8	ns
t_{PZL}			2.6	5.2	8	1	8.8	2.6	8.8	
t_{PHZ}	$\overline{CE}$	A or B	1.6	3.8	6.6	0.5	7.4	1.6	7.1	ns
t_{PLZ}			2.4	4.6	7	1	7.9	2.4	7.5	
t_{PZH}	$\overline{OE}$	A or B	1.4	3.8	6.1	0.5	7.6	1.4	7.3	ns
t_{PZL}			2.3	4.7	7.4	1	8.2	2.3	8.1	
t_{PHZ}	$\overline{OE}$	A or B	1.3	3.4	6.1	0.5	6.7	1.3	6.5	ns
t_{PLZ}			2	4.2	6.6	0.8	7.2	2	6.9	

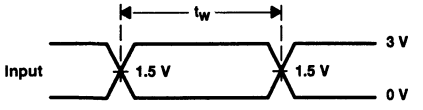
† These limits apply only to the SN74ABTH32543.

PARAMETER MEASUREMENT INFORMATION

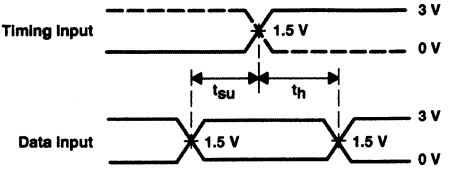


LOAD CIRCUIT

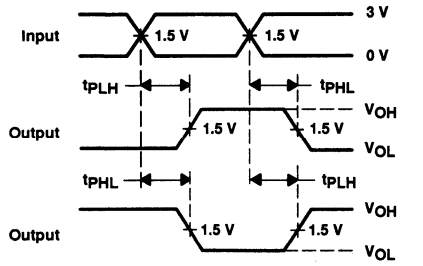
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



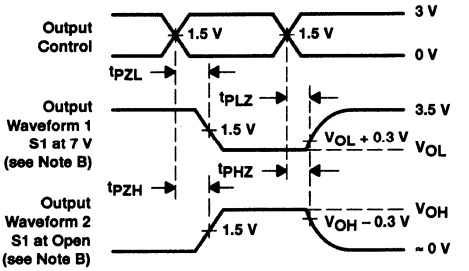
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

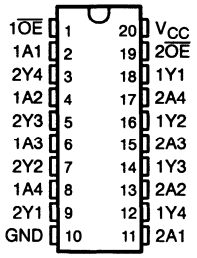
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

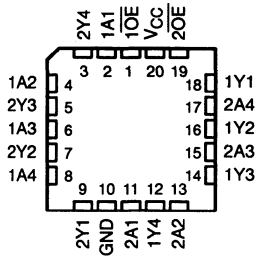
Contents

- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT2240 . . . J OR W PACKAGE
SN74ABT2240A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT2240 . . . FK PACKAGE
(TOP VIEW)



description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the 'ABT2241 and 'ABT2244A, these devices provide combinations of inverting and noninverting outputs, symmetrical active-low output-enable ($\overline{OE}$) inputs, and complementary OE and $\overline{OE}$ inputs. These devices feature high fan-out and improved fan-in.

These devices are organized as two 4-bit line drivers with separate $\overline{OE}$ inputs. When $\overline{OE}$ is low, the devices pass inverted data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

The outputs, which are designed to sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

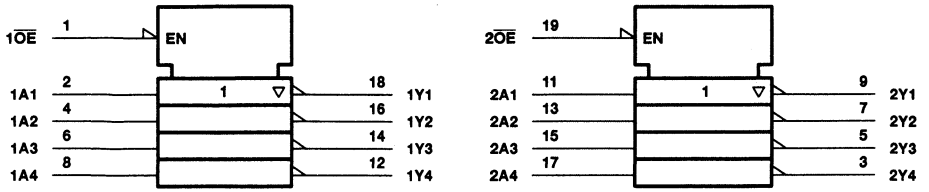
The SN54ABT2240 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT2240A is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE
(each buffer)

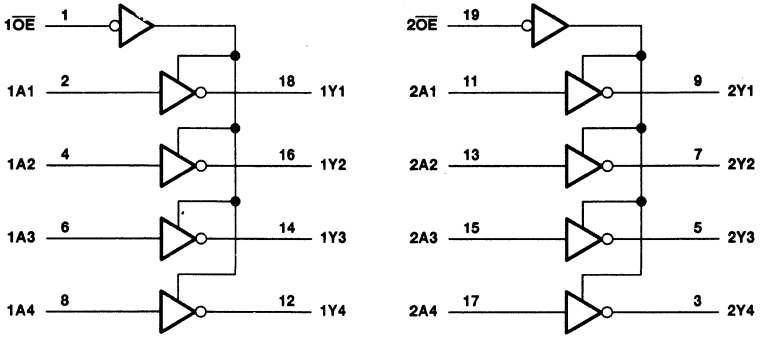
INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	L
L	L	H
H	X	Z

logic symbol†

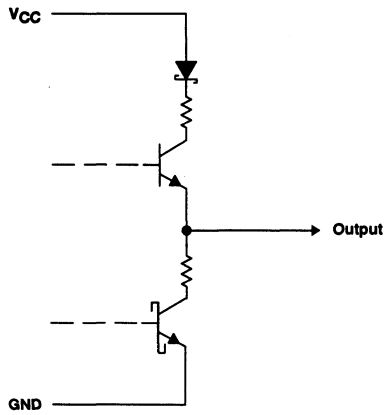


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematic of Y outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O	30 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	115°C/W
DW package	97°C/W
N package	67°C/W
PW package	128°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT2240		SN74ABT2240A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT2240		SN74ABT2240A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V,	I_{OL} = 12 mA			0.8		0.8		0.8	V
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			10*		10		10	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–10*		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			4						pF
C_o		V_O = 2.5 V or 0.5 V			7						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

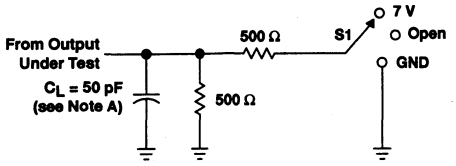
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT2240					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	3	4	1	5	ns
t_{PHL}			3	4.8	5.8	3	6.3	
t_{PZH}	$\overline{OE}$	Y	1.5	3.7	4.7	1.5	6.1	ns
t_{PZL}			4.2	6.5	7.6	4.2	8.8	
t_{PHZ}	$\overline{OE}$	Y	1.9	3.8	5.6	1.9	6.2	ns
t_{PLZ}			2.5	4.7	5.8	2.5	6.9	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

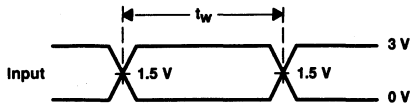
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT2240A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	3	4.1	1	4.8	ns
t_{PHL}			2.1	4.1	5.1	2.1	5.4	
t_{PZH}	$\overline{OE}$	Y	1.1	3.1	4.7	1.1	5.2	ns
t_{PZL}			1.7	4.5	6.4	1.7	6.8	
t_{PHZ}	$\overline{OE}$	Y	1.8	3.4	5.7	1.8	6.4	ns
t_{PLZ}			1.9	3.6	6	1.9	6.2	

PARAMETER MEASUREMENT INFORMATION

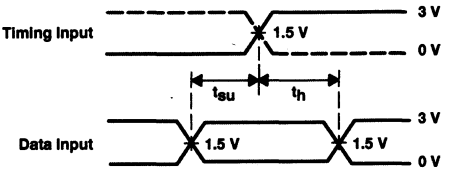


LOAD CIRCUIT

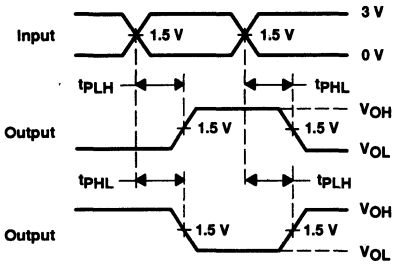
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



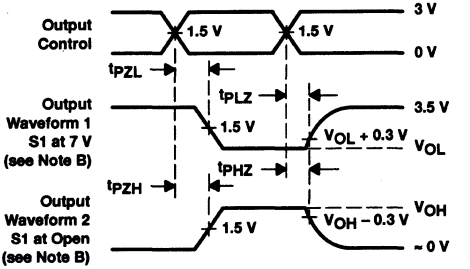
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



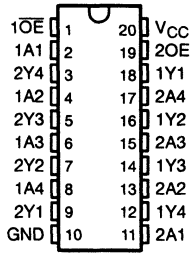
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

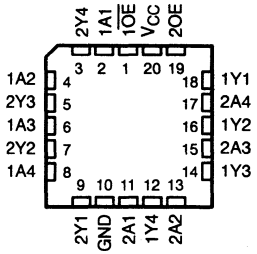
Figure 1. Load Circuit and Voltage Waveforms

- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs**

SN54ABT2241 . . . J PACKAGE
SN74ABT2241 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT2241 . . . FK PACKAGE
(TOP VIEW)



description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the SN54ABT2240, SN74ABT2240A and 'ABT2244A, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable ($\overline{OE}$) inputs, and complementary OE and $\overline{OE}$ inputs. These devices feature high fan-out and improved fan-in.

The outputs, which are designed to sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT2241 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT2241 is characterized for operation from –40°C to 85°C.

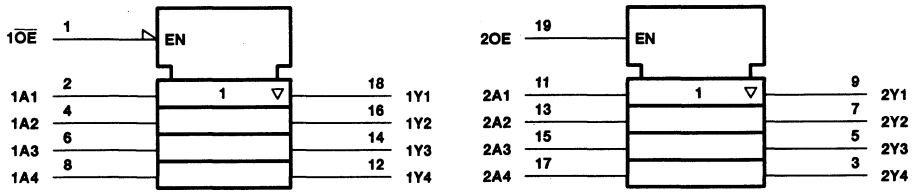
EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLES

INPUTS		OUTPUT
$1\overline{OE}$	1A	1Y
L	H	H
L	L	L
H	X	Z

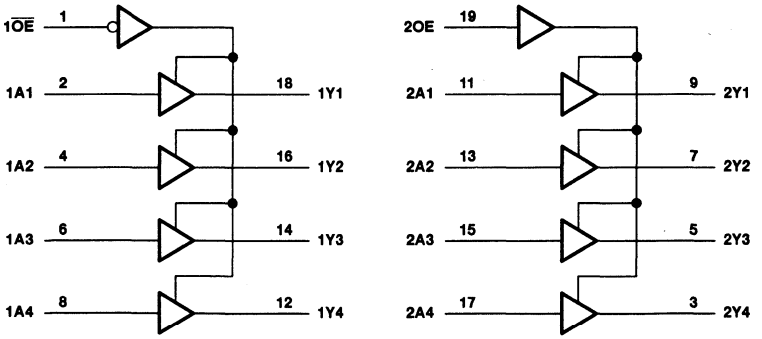
INPUTS		OUTPUT
2OE	2A	2Y
H	H	H
H	L	L
L	X	Z

logic symbol†

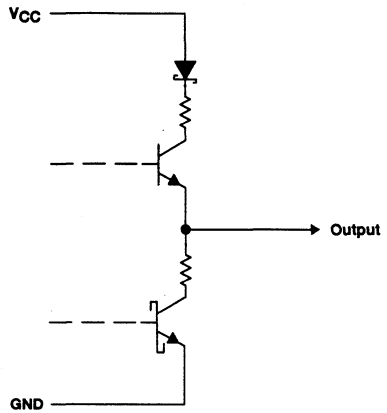


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematic of Y outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT2241		SN74ABT2241		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

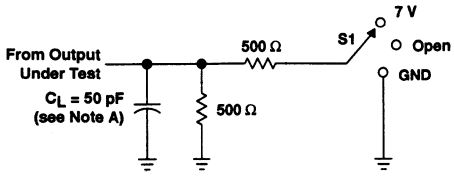
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT2241		SN74ABT2241		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V,	I_{OL} = 12 mA			0.8		0.8		0.8	V
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i	C_i	V_I = 2.5 V or 0.5 V			3						pF
C_o	C_o	V_O = 2.5 V or 0.5 V			8.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

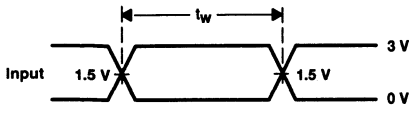
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT2241		SN74ABT2241		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	3	4.3	1	4.8	1	4.7	ns
t_{PHL}			1	4.3	5.3	1	5.7	1	5.6	
t_{PZH}	OE or $\overline{OE}$	Y	1.1	3.5	4.8	1	6.1	1.1	5.8	ns
t_{PZL}			2.1	6.2	7.6	2	8.6	2.1	8.4	
t_{PHZ}	OE or $\overline{OE}$	Y	1.7	4.2	5.6	1.7	6.7	1.7	6.6	ns
t_{PLZ}			1.7	3.9	5.8	1.7	6.9	1.7	6.4	

PARAMETER MEASUREMENT INFORMATION

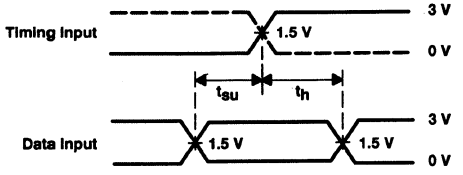


LOAD CIRCUIT

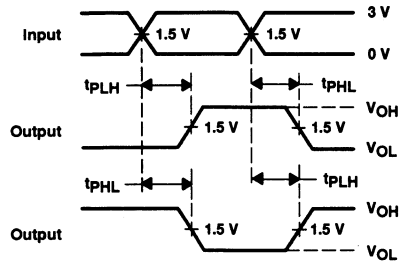
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



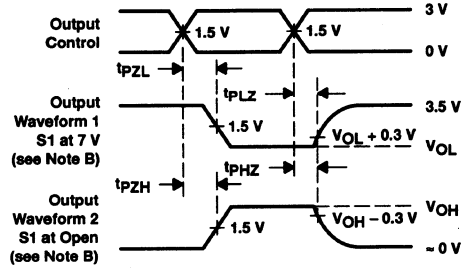
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



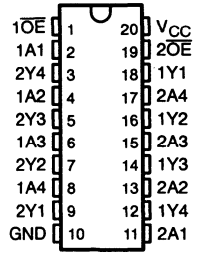
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

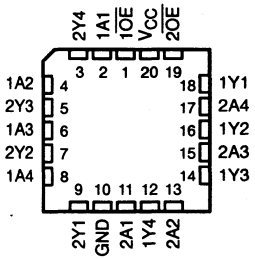
Figure 1. Load Circuit and Voltage Waveforms

- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Packages**

SN54ABT2244A . . . J OR W PACKAGE
SN74ABT2244A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT2244A . . . FK PACKAGE
(TOP VIEW)



description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the SN54ABT2240, SN74ABT2240A, and 'ABT2241, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable ($\overline{OE}$) inputs, and complementary OE and $\overline{OE}$ inputs. These devices feature high fan-out and improved fan-in.

The outputs, which are designed to sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

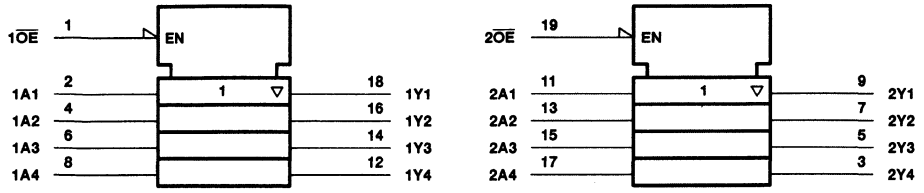
The SN54ABT2244A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT2244A is characterized for operation from –40°C to 85°C.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

FUNCTION TABLE
(each buffer)

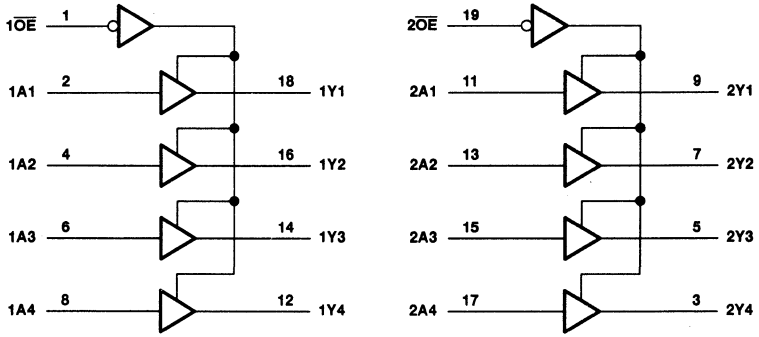
INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

logic symbol†

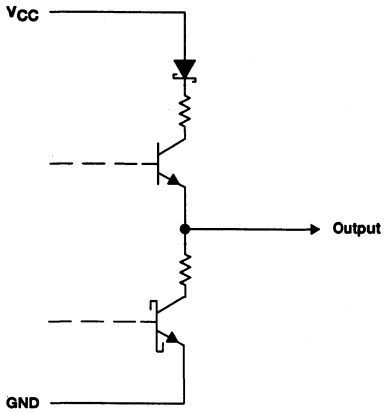


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematic of Y outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT2244A		SN74ABT2244A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT2244A		SN74ABT2244A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V,	I_{OL} = 12 mA			0.8		0.8		0.8	V
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		50		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–50		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}¶	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			4						pF
C_o		V_O = 2.5 V or 0.5 V			5.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

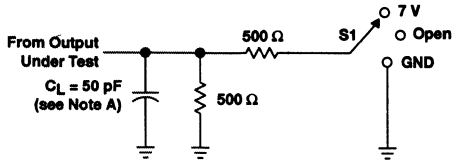
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT2244A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	3.4	4.4	1	5.3	ns
t_{PHL}			1	4.5	6.3	1	6.8	
t_{PZH}	$\overline{OE}$	Y	1.1	3.8	5.5	1.1	6.5	ns
t_{PZL}			2.1	6.3	9	2.1	10.2	
t_{PHZ}	$\overline{OE}$	Y	2.1	4.5	6.9	2.1	7	ns
t_{PLZ}			1.7	4.3	6.9	1.7	7.4	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

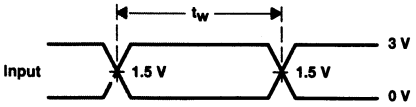
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT2244A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	3.4	4.3	1	4.7	ns
t_{PHL}			1	4.5	5.3	1	5.6	
t_{PZH}	$\overline{OE}$	Y	1.1	3.8	4.8	1.1	5.5	ns
t_{PZL}			2.1	6.3	7.3	2.1	8.3	
t_{PHZ}	$\overline{OE}$	Y	2.1	4.5	5.6	2.1	6.6	ns
t_{PLZ}			1.7	4.3	5.3	1.7	5.8	

PARAMETER MEASUREMENT INFORMATION

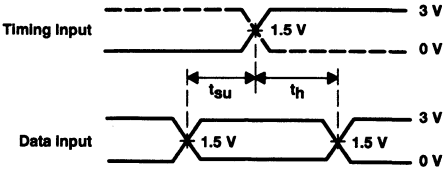


LOAD CIRCUIT

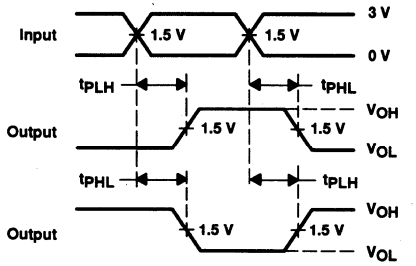
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



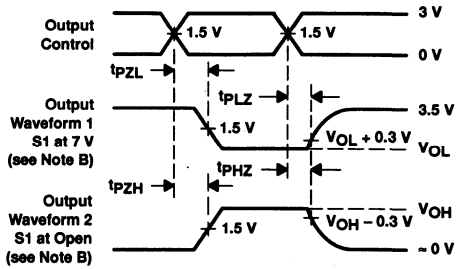
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



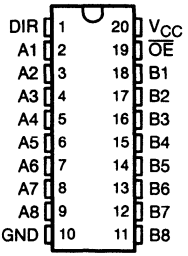
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

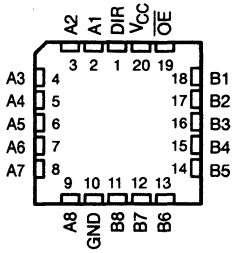
Figure 1. Load Circuit and Voltage Waveforms

- **B-Port Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-833, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT2245 . . . J OR W PACKAGE
SN74ABT2245 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT2245 . . . FK PACKAGE
(TOP VIEW)



description

These octal transceivers and line drivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so the buses are effectively isolated.

The B-port outputs, which are designed to sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The SN54ABT2245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT2245 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

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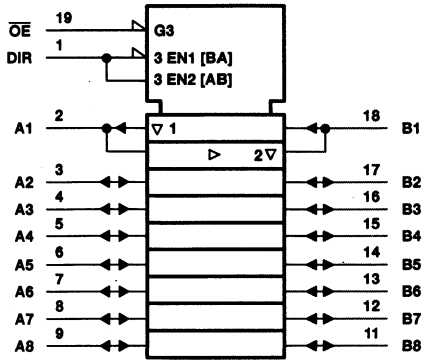
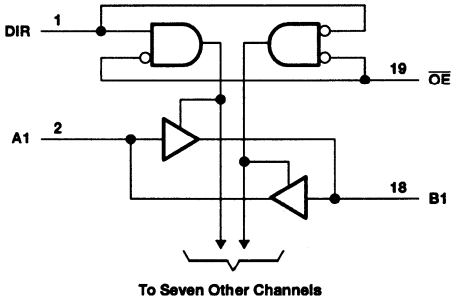
TEXAS INSTRUMENTS

logic symbol†

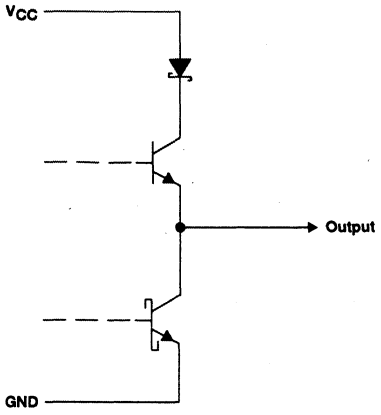


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

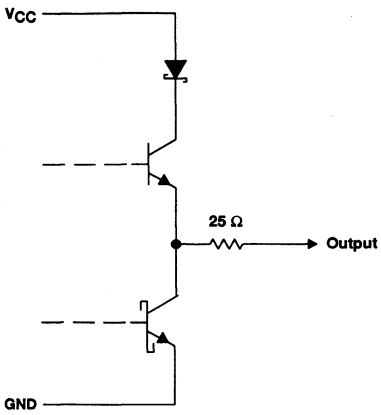
logic diagram (positive logic)



schematic of A-port outputs



schematic of B-port outputs



All resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT2245 (except B port)	96 mA
SN74ABT2245 (except B port)	128 mA
B port	30 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	115°C/W
DW package	97°C/W
N package	67°C/W
PW package	128°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT2245		SN74ABT2245		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	A port		–24		–32	mA
		B port		–12		–12	
I_{OL}	Low-level output current	A port		48		64	mA
		B port		12		12	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

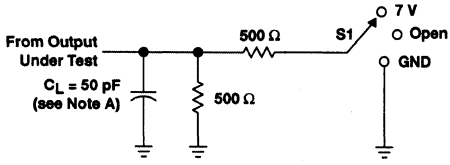
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT2245		SN74ABT2245		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	B port	V_{CC} = 4.5 V,	I_{OH} = –1 mA	3.35			3.3		3.35		V
		V_{CC} = 5 V,	I_{OH} = –1 mA	3.85			3.8		3.85		
		V_{CC} = 4.5 V	I_{OH} = –3 mA				3		3.1		
			I_{OH} = –12 mA	2.6					2.6		
	A port	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}	B port	V_{CC} = 4.5 V	I_{OL} = 8 mA			0.65		0.8		0.65	V
			I_{OL} = 12 mA			0.8				0.8	
	A port		I_{OL} = 48 mA			0.55		0.55			
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±20		±20	
I_{OZH}‡		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}‡		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{OZPU}§		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}§		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O¶	B port	V_{CC} = 5.5 V,	V_O = 2.5 V	–25		–100	–25	–100	–25	–100	mA
	A port			–50	–100	–180	–50	–180	–50	–180	
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	32		32		32	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_{io}		V_O = 2.5 V or 0.5 V			6						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ This parameter is characterized but not production tested.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

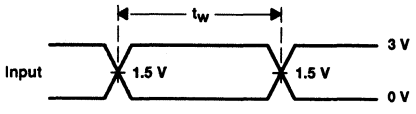
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT2245		SN74ABT2245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	B	1	2.5	3.4	1	4	1	3.8	ns
t_{PHL}			1	3.2	4.2	1	4.6	1	4.5	
t_{PLH}	B	A	1	2.2	3.2	1	3.8	1	3.6	ns
t_{PHL}			1	2.7	3.6	1	4.2	1	4	
t_{PZH}	$\overline{OE}$	A	1	3.3	4.6	1	5.6	1	5.5	ns
t_{PZL}			1	3.2	4.7	1	6	1	5.7	
t_{PHZ}	$\overline{OE}$	A	2	4	5.1	2	5.7	2	5.6	ns
t_{PLZ}			1	2.9	4	1	4.6	1	4.5	
t_{PZH}	$\overline{OE}$	B	1.5	3.6	4.9	1.5	6.3	1.5	6.1	ns
t_{PZL}			1.5	3.9	5.3	1.5	6.6	1.5	6.3	
t_{PHZ}	$\overline{OE}$	B	1.5	3.6	4.7	1.5	5.5	1.5	5.3	ns
t_{PLZ}			1.5	3.3	4.4	1.5	4.9	1.5	4.8	

PARAMETER MEASUREMENT INFORMATION

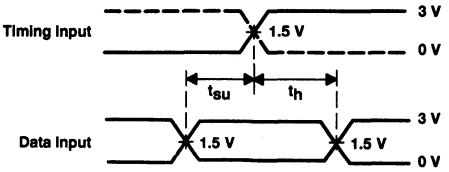


LOAD CIRCUIT

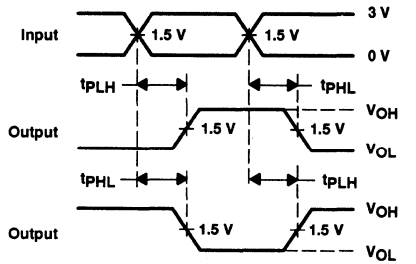
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



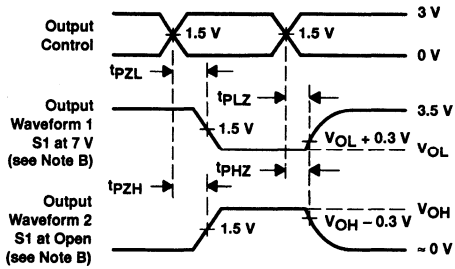
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



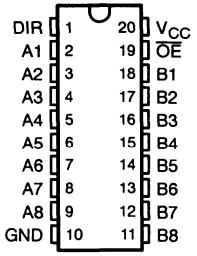
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

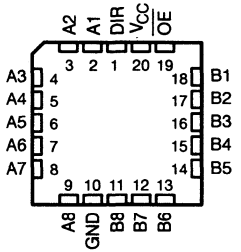
Figure 1. Load Circuit and Voltage Waveforms

- **Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **High-Impedance State During Power Up and Power Down**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-833, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Thin Very Small-Outline (DGV) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs**

SN54ABTR2245 . . . J PACKAGE
SN74ABTR2245 . . . DB, DGV, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABTR2245 . . . FK PACKAGE
(TOP VIEW)



description

These octal transceivers and line drivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so the buses are effectively isolated.

Both the A-port and B-port outputs, which are designed to sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTR2245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTR2245 is characterized for operation from –40°C to 85°C.

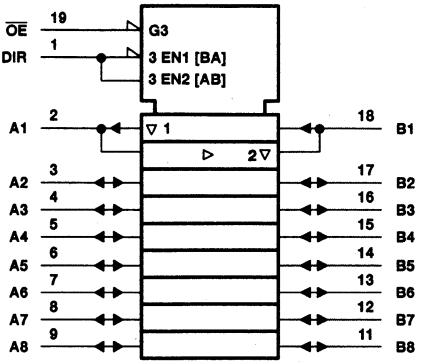
FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

EPIC-IIB is a trademark of Texas Instruments Incorporated.

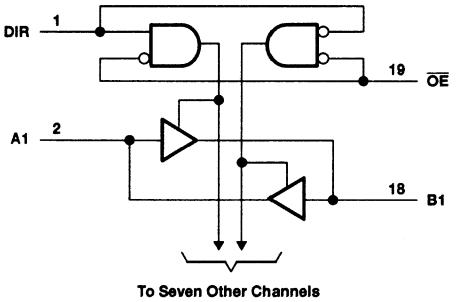
TEXAS INSTRUMENTS

logic symbol†

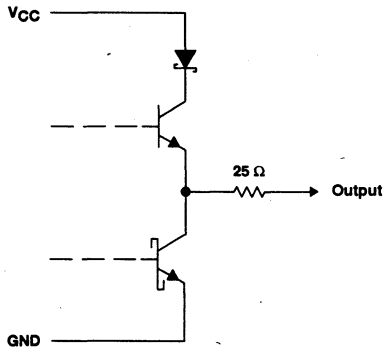


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



output schematic



All resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package ..... 115°C/W
DGV package ..... 146°C/W
DW package ..... 97°C/W
N package ..... 67°C/W
PW package ..... 128°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABTR2245		SN74ABTR2245		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–12		–12	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		µs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

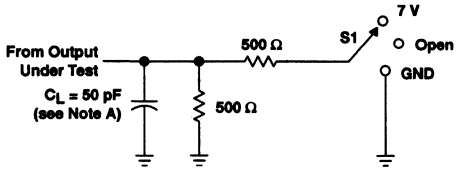
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABTR2245		SN74ABTR2245		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –1 mA	3.35			3.3		3.35		V
		V_{CC} = 5 V,	I_{OH} = –1 mA	3.85			3.8		3.85		
		V_{CC} = 4.5 V	I_{OH} = –3 mA				3		3.1		
			I_{OH} = –12 mA	2.6					2.6		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 8 mA			0.65		0.8		0.65	V
			I_{OL} = 12 mA			0.8				0.8	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±20		±20	
I_{OZH}‡		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}‡		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{OZPU}§		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}§		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–25		–100	–25	–100	–25	–100	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250		250		250	µA
			Outputs low		24	32		32		32	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_{io}		V_O = 2.5 V or 0.5 V			6						pF

* On products compliant to MIL-PRF–38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ This parameter is characterized but not production tested.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

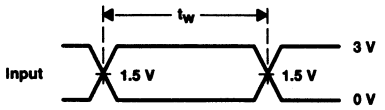
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABTR2245		SN74ABTR2245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	2.5	3.4	1	4	1	3.8	ns
t_{PHL}			1	3.2	4.2	1	4.6	1	4.5	
t_{PZH}	$\overline{OE}$	A or B	1.5	3.6	4.9	1.5	6.3	1.5	6.1	ns
t_{PZL}			1.5	3.9	5.3	1.5	6.6	1.5	6.3	
t_{PHZ}	$\overline{OE}$	A or B	1.5	3.6	4.7	1.5	5.5	1.5	5.3	ns
t_{PLZ}			1.5	3.3	4.4	1.5	4.9	1.5	4.8	

PARAMETER MEASUREMENT INFORMATION

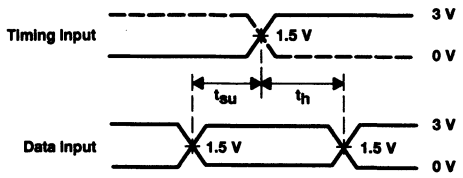


LOAD CIRCUIT

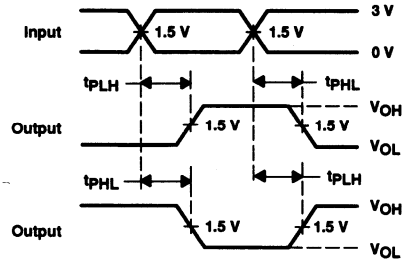
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



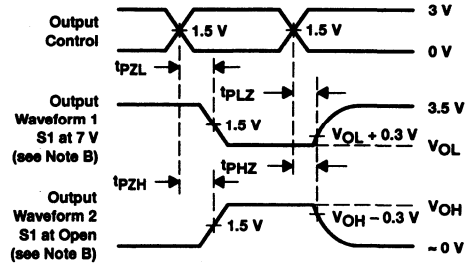
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



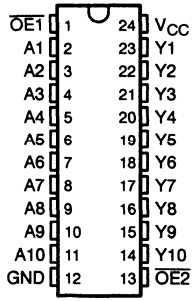
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

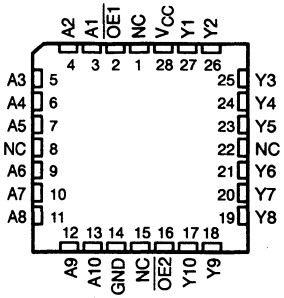
Figure 1. Load Circuit and Voltage Waveforms

- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Package Options Include Plastic Small-Outline (DW) Package, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT2827 . . . JT PACKAGE
SN74ABT2827 . . . DW OR NT PACKAGE
(TOP VIEW)



SN54ABT2827 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

These 10-bit buffers or bus drivers provide a high-performance bus interface for wide data paths or buses carrying parity.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all ten outputs are in the high-impedance state. The 'ABT2827 provide true data at their outputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

The SN54ABT2827 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT2827 is characterized for operation from –40°C to 85°C.

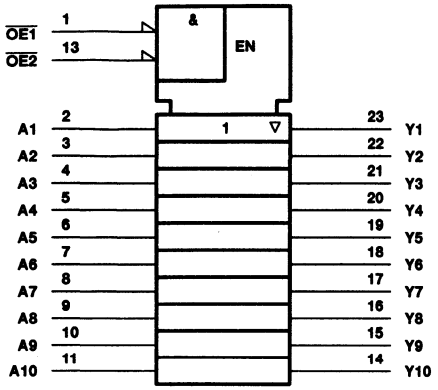
EPIC-IIB is a trademark of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

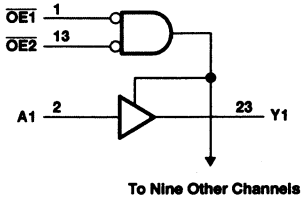
FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT2827 ..... 96 mA
SN74ABT2827 ..... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package ..... 81°C/W
NT package ..... 67°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT2827		SN74ABT2827		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–12		–12	mA
I_{OL}	Low-level output current		12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

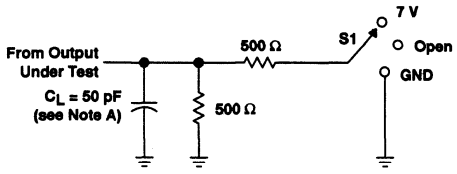
PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT2827		SN74ABT2827		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –1 mA	2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –1 mA	3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –3 mA	2.4			2.4		2.4		
		I_{OH} = –12 mA	2			2		2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 12 mA			0.8		0.8		0.8	V
V_{hys}				100						mV
I_I	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			10‡		10		10‡	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V			–10‡		–10		–10‡	µA
I_{off}	V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–140	–225‡	–50	–225‡	–50	–225‡	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		80	250		250		250	µA
		Outputs low		35	40‡		40‡		40‡	mA
		Outputs disabled		80	250		250		250	µA
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
		Outputs disabled			50		50		50	µA
		Control inputs			1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V			4						pF
C_o	V_O = 2.5 V or 0.5 V			8.5						pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ This data sheet limit may vary among suppliers.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

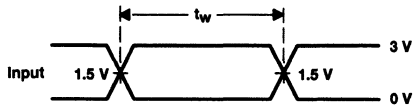
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT2827		SN74ABT2827		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.1	3.3	5.1	1.1	5.6	1.1	5.5	ns
t_{PHL}			1.1	2.7	4.5	1.1	5.2	1.1	5.1	
t_{PZH}	$\overline{OE}$	Y	1	4	5.9	1	6.8	1	6.7	ns
t_{PZL}			1	4.2	6.8	1	8	1	7.8	
t_{PHZ}	$\overline{OE}$	Y	2	5.3	6.7	2	7.4	2	7.2	ns
t_{PLZ}			1.3	4.8	7.2	1.3	8.5	1.3	7.5	

PARAMETER MEASUREMENT INFORMATION

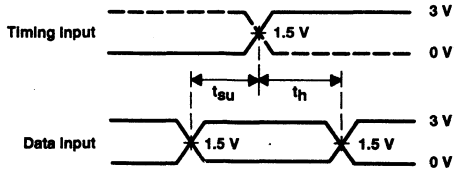


LOAD CIRCUIT

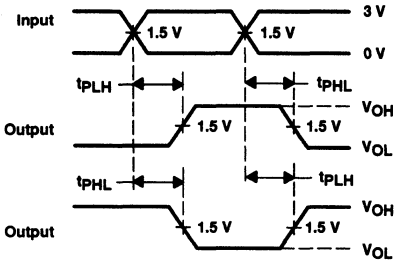
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



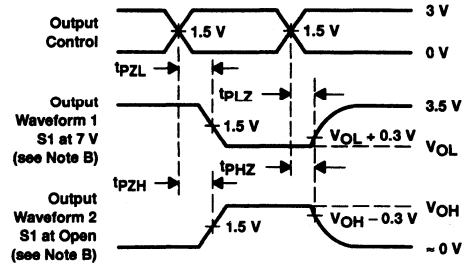
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



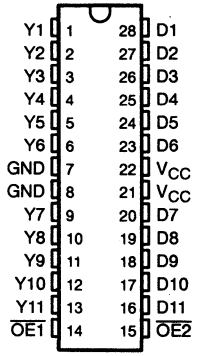
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

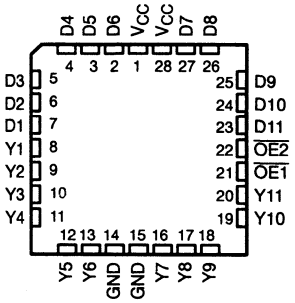
Figure 1. Load Circuit and Voltage Waveforms

- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Typical V_{OLV} (Output Undershoot) < 0.5 V at V_{CC} = 5 V, T_A = 25°C**
- **Package Options Include Plastic Small-Outline (DW) Package and Ceramic Chip Carriers (FK) and DIPs (JT)**

SN54ABT5400A . . . JT PACKAGE
SN74ABT5400A . . . DW PACKAGE
(TOP VIEW)



SN54ABT5400A . . . FK PACKAGE
(TOP VIEW)



description

These 11-bit buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all 11 outputs are in the high-impedance state.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

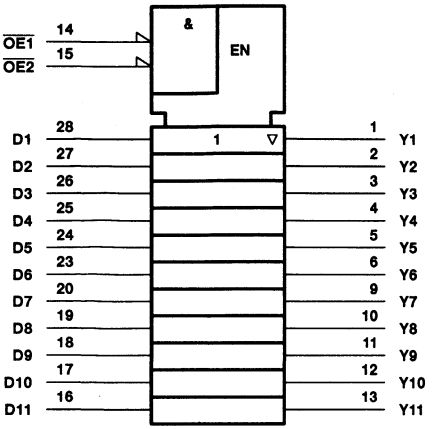
The SN54ABT5400A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT5400A is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	D	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

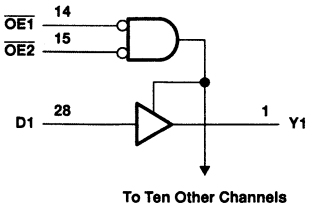
EPIC-IIB is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW and JT packages.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package ..... 78°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT5400A		SN74ABT5400A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–12		–12	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

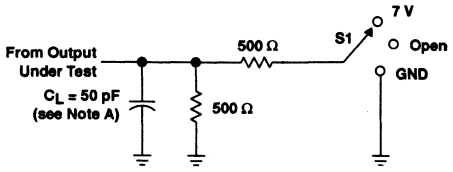
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT5400A		SN74ABT5400A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –1 mA	3.35	3.7		3.3		3.35		V
		V_{CC} = 5 V,	I_{OH} = –1 mA	3.85	4.2		3.8		3.85		
		V_{CC} = 4.5 V	I_{OH} = –3 mA				3		3.1		
			I_{OH} = –12 mA	2.6					2.6		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 8 mA					0.8		0.65	V
			I_{OL} = 12 mA							0.8	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O		V_{CC} = 5.5 V,	V_O = 2.5 V	–25	–45	–100	–25	–100	–25	–100	mA
I_{OS}‡		V_{CC} = 5.5 V,	V_O = 0	–50		–200	–50	–200	–50	–200	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		5	50		50		50	µA
			Outputs low		36	45		45		45	mA
			Outputs disabled		1	50		50		50	µA
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_o		V_O = 2.5 V or 0.5 V			8						pF

† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

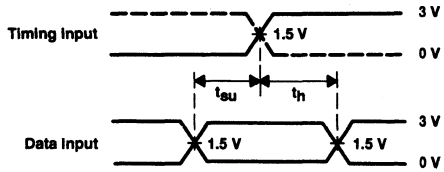
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT5400A		SN74ABT5400A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Y	2	4.5	5.2	2	6.3	2	6.2	ns
t_{PHL}			1.5	3.7	5	1.5	5.7	1.5	5.6	
t_{PZH}	$\overline{OE}$	Y	2.5	5.7	7.6	2.5	8.8	2.5	8.7	ns
t_{PZL}			2	4.4	6.3		7.6	2	7.5	
t_{PHZ}	$\overline{OE}$	Y	1.5	3.6	4.4	1.5	5.5	1.5	5.2	ns
t_{PLZ}			1.5	4.2	5.4	1.5	7.4	1.5	6.9	

PARAMETER MEASUREMENT INFORMATION

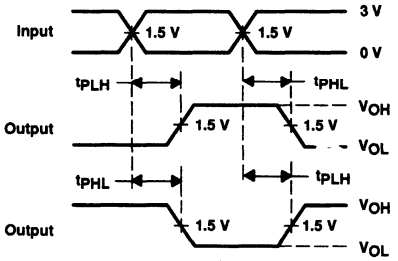


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

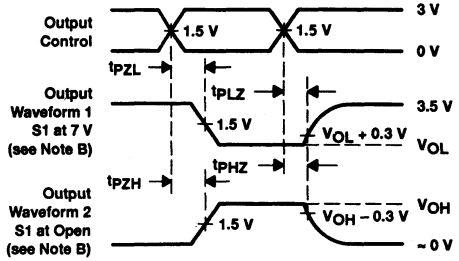
LOAD CIRCUIT



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



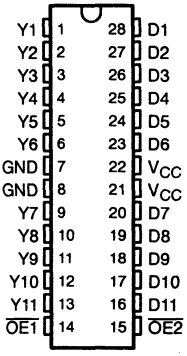
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

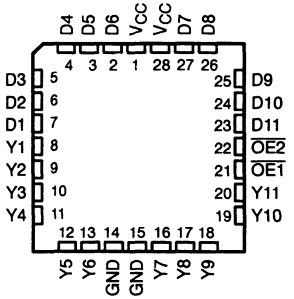
Figure 1. Load Circuit and Voltage Waveforms

- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Typical V_{OLV} (Output Undershoot) < 0.5 V at V_{CC} = 5 V, T_A = 25°C**
- **Package Options Include Plastic Small-Outline (DW) Package, Ceramic Chip Carriers (FK), and DIPs (JT)**

SN54ABT5401 . . . JT PACKAGE
SN74ABT5401 . . . DW PACKAGE
(TOP VIEW)



SN54ABT5401 . . . FK PACKAGE
(TOP VIEW)



description

These 11-bit buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all 11 outputs are in the high-impedance state. These devices provide inverted data.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT5401 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT5401 is characterized for operation from –40°C to 85°C.

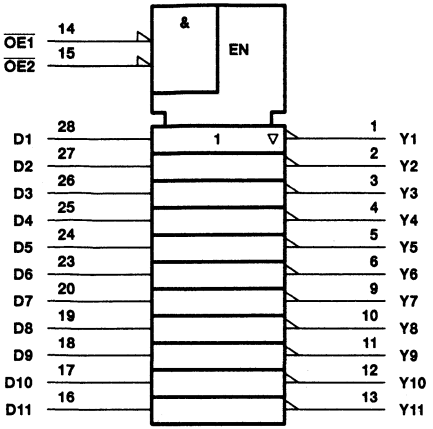
FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	D	Y
L	L	L	H
L	L	H	L
H	X	X	Z
X	H	X	Z

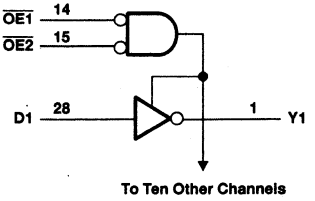
EPIC-IIB is a trademark of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW and JT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package ..... 78°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT5401		SN74ABT5401		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–12		–12	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

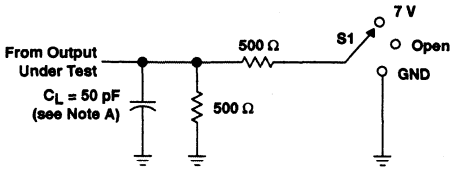
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT5401		SN74ABT5401		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –1 mA	3.35	3.7		3.3		3.35		V
		V_{CC} = 5 V,	I_{OH} = –1 mA	3.85	4.2		3.8		3.85		
		V_{CC} = 4.5 V	I_{OH} = –3 mA				3		3.1		
			I_{OH} = –12 mA	2.6					2.6		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 8 mA					0.8		0.65	V
			I_{OL} = 12 mA							0.8	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O		V_{CC} = 5.5 V,	V_O = 2.5 V	–25	–45	–100	–25	–100	–25	–100	mA
I_{OS}‡		V_{CC} = 5.5 V,	V_O = 0	–50		–200	–50	–200	–50	–200	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		5	50		50		50	µA
			Outputs low		36	45		45		45	mA
			Outputs disabled		1	50		50		50	µA
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_o		V_O = 2.5 V or 0.5 V			8						pF

† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

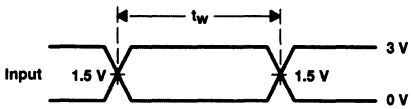
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT5401		SN74ABT5401		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Y	2	4.5	6.1	2	7	2	6.9	ns
t_{PHL}			1.5	4.4	5.2	1.5	5.9	1.5	5.7	
t_{PZH}	$\overline{OE}$	Y	2.5	5.7	6.6	2.5	8.6	2.5	8.5	ns
t_{PZL}			2	4.4	5.5	2	6.9	2	6.8	
t_{PHZ}	$\overline{OE}$	Y	1.5	3.6	4.4	1.5	5.5	1.5	5.2	ns
t_{PLZ}			1.5	4.2	5.4	1.5	7.4	1.5	6.9	

PARAMETER MEASUREMENT INFORMATION

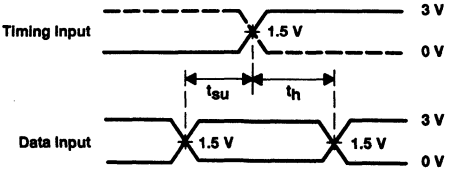


LOAD CIRCUIT

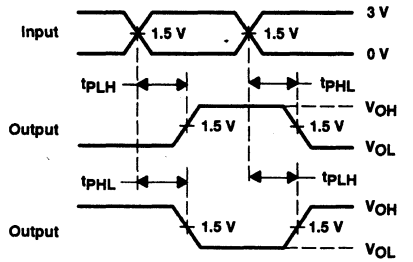
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



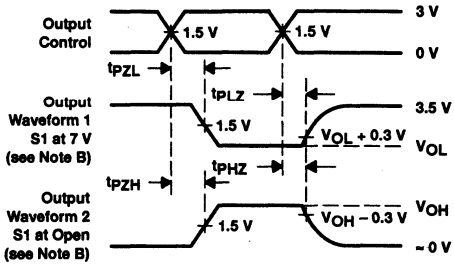
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



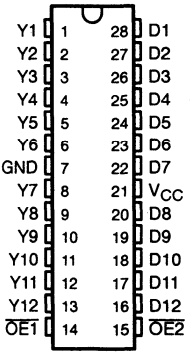
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

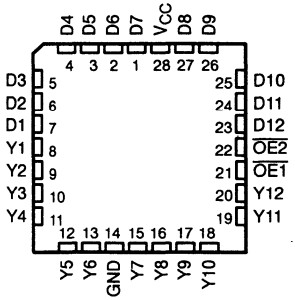
Figure 1. Load Circuit and Voltage Waveforms

- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Typical V_{OLV} (Output Undershoot) < 0.5 V at V_{CC} = 5 V, T_A = 25°C**
- **Package Options Include Plastic Small-Outline (DW) Package and Ceramic Chip Carriers (FK) and DIPs (JT)**

SN54ABT5402A . . . JT PACKAGE
SN74ABT5402A . . . DW PACKAGE
(TOP VIEW)



SN54ABT5402A . . . FK PACKAGE
(TOP VIEW)



description

These 12-bit buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all 12 outputs are in the high-impedance state.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

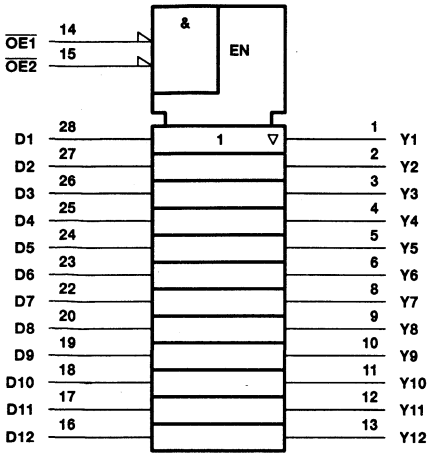
The SN54ABT5402A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT5402A is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	D	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

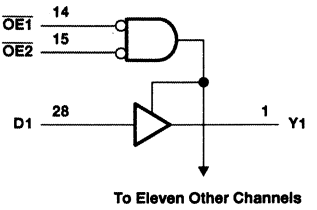
EPIC-IIB is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW and JT packages.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O	30 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	78°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT5402A		SN74ABT5402A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–12		–12	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

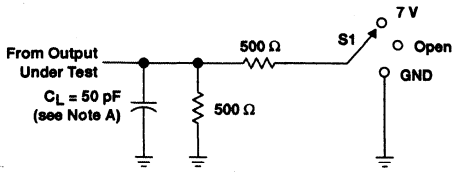
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT5402A		SN74ABT5402A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –1 mA	3.35	3.7		3.3		3.35		V
		V_{CC} = 5 V,	I_{OH} = –1 mA	3.85	4.2		3.8		3.85		
		V_{CC} = 4.5 V	I_{OH} = –3 mA				3		3.1		
			I_{OH} = –12 mA	2.6					2.6		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 8 mA					0.8		0.65	V
			I_{OL} = 12 mA							0.8	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5.V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O		V_{CC} = 5.5 V,	V_O = 2.5 V	–25	–45	–100	–25	–100	–25	–100	mA
I_{OS}‡		V_{CC} = 5.5 V,	V_O = 0	–50		–200	–50	–200	–50	–200	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		5	50		50		50	µA
			Outputs low		39	48		48		48	mA
			Outputs disabled		1	50		50		50	µA
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_o		V_O = 2.5 V or 0.5 V			8						pF

† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

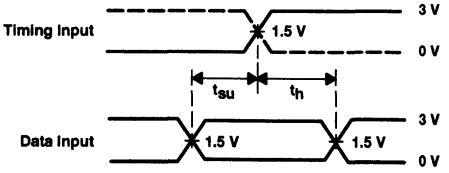
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT5402A		SN74ABT5402A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Y	2	4.5	5.2	2	6.3	2	6.2	ns
t_{PHL}			1.5	3.7	5	1.5	5.7	1.5	5.6	
t_{PZH}	$\overline{OE}$	Y	2.5	5.7	7.6	2.5	8.8	2.5	8.7	ns
t_{PZL}			2	4.4	6.3		7.6	2	7.5	
t_{PHZ}	$\overline{OE}$	Y	1.5	3.6	4.4	1.5	5.5	1.5	5.2	ns
t_{PLZ}			1.5	4.2	5.4	1.5	7.4	1.5	6.9	

PARAMETER MEASUREMENT INFORMATION

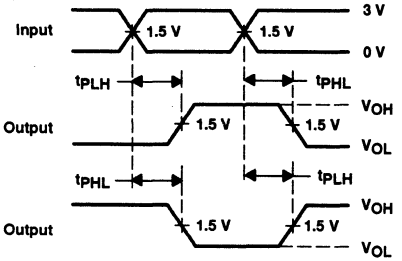


LOAD CIRCUIT

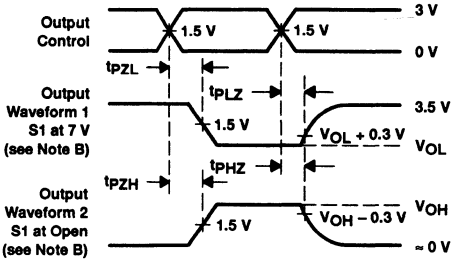
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



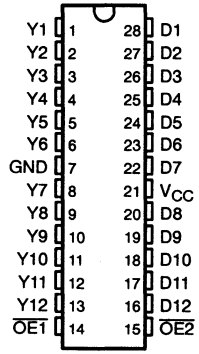
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

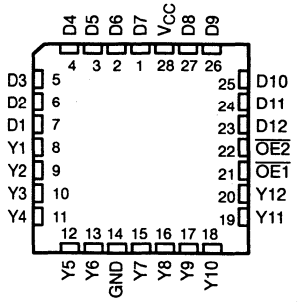
Figure 1. Load Circuit and Voltage Waveforms

- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Typical V_{OLV} (Output Undershoot) < 0.5 V at V_{CC} = 5 V, T_A = 25°C**
- **Package Options Include Plastic Small-Outline (DW) Package, Ceramic Chip Carriers (FK), and DIPs (JT)**

SN54ABT5403 . . . JT PACKAGE
SN74ABT5403 . . . DW PACKAGE
(TOP VIEW)



SN54ABT5403 . . . FK PACKAGE
(TOP VIEW)



description

These 12-bit buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all 12 outputs are in the high-impedance state. These devices provide inverted data.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

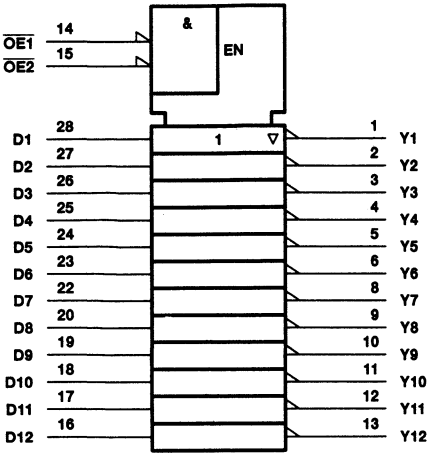
The SN54ABT5403 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT5403 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

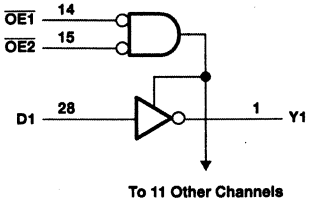
INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	D	Y
L	L	L	H
L	L	H	L
H	X	X	Z
X	H	X	Z

EPIC-IIB is a trademark of Texas Instruments Incorporated.

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW and JT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package ..... 78°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT5403		SN74ABT5403		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–12		–12	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

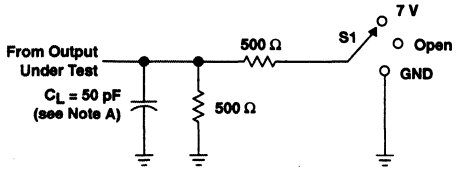
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT5403		SN74ABT5403		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –1 mA	3.35	3.7		3.3		3.35		V
		V_{CC} = 5 V,	I_{OH} = –1 mA	3.85	4.2		3.8		3.85		
		V_{CC} = 4.5 V	I_{OH} = –3 mA				3		3.1		
			I_{OH} = –12 mA	2.6					2.6		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 8 mA					0.8		0.65	V
			I_{OL} = 12 mA							0.8	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O		V_{CC} = 5.5 V,	V_O = 2.5 V	–25	–45	–100	–25	–100	–25	–100	mA
I_{OS}‡		V_{CC} = 5.5 V,	V_O = 0	–50		–200	–50	–200	–50	–200	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		5	50		50		50	µA
			Outputs low		36	45		45		45	mA
			Outputs disabled		1	50		50		50	µA
ΔI_{CC}§	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_o		V_O = 2.5 V or 0.5 V			8						pF

† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

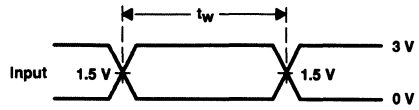
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT5403		SN74ABT5403		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Y	2	4.5	6.1	2	7	2	6.9	ns
t_{PHL}			1.5	4.4	5.2	1.5	5.9	1.5	5.7	
t_{PZH}	$\overline{OE}$	Y	2.5	5.7	6.6	2.5	8.6	2.5	8.5	ns
t_{PZL}			2	4.4	5.5		6.9	2	6.8	
t_{PHZ}	$\overline{OE}$	Y	1.5	3.6	4.4	1.5	5.5	1.5	5.2	ns
t_{PLZ}			1.5	4.2	5.4	1.5	7.4	1.5	6.9	

PARAMETER MEASUREMENT INFORMATION

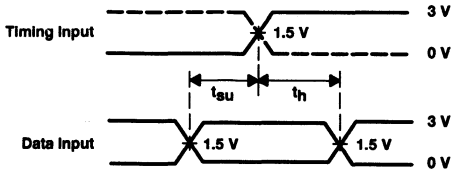


LOAD CIRCUIT

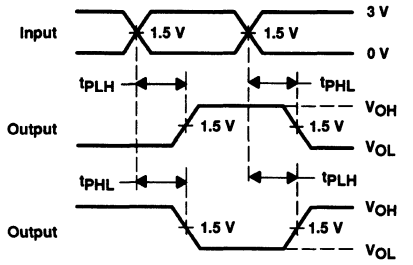
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



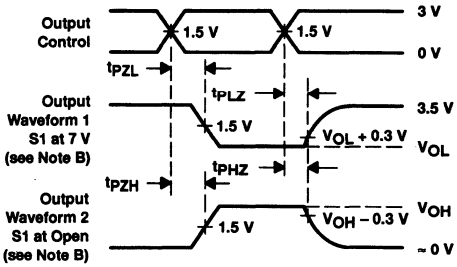
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



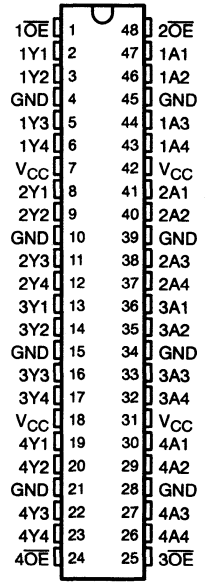
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT162244 . . . WD PACKAGE
SN74ABT162244 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The 'ABT162244 are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide noninverting outputs and symmetrical active-low output-enable ($\overline{OE}$) inputs.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

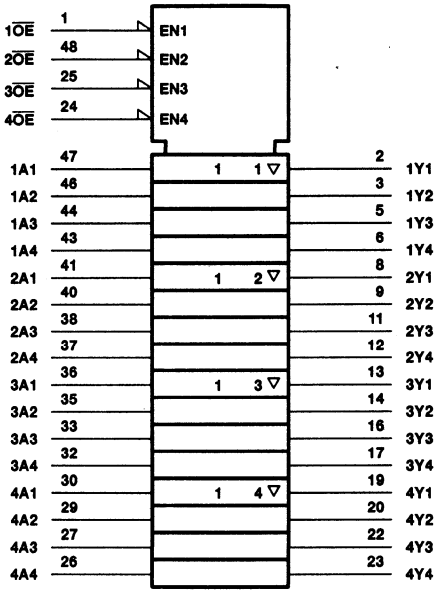
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT162244 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT162244 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 4-bit buffer)

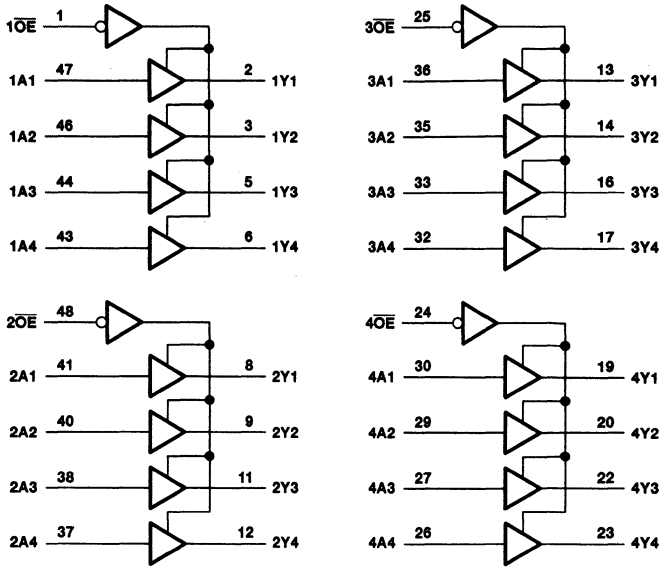
INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DGV package ..... 93°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT162244		SN74ABT162244		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–12		–12	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT162244		SN74ABT162244		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = −18 mA			−1.2		−1.2		−1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = −1 mA	3.35			3.35		3.35		V
		V_{CC} = 5 V,	I_{OH} = −1 mA	3.85			3.85		3.85		
		V_{CC} = 4.5 V	I_{OH} = −3 mA	3.1			3.1		3.1		
			I_{OH} = −12 mA	2.6*					2.6		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 8 mA		0.4	0.8		0.8		0.65	V
			I_{OL} = 12 mA							0.8	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				−10		−10		−10	µA
I_{off}		V_{CC} = 0, V_I or V_O ≤ 4.5 V				±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Ouptputs high			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	−25	−55	−100	−25	−100	−25	−100	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			30		30		30	
			Outputs disabled			2		2		2	
ΔI_{CC}¶	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			50		50		50	µA
			Outputs disabled			50		50		50	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_o		V_O = 2.5 V or 0.5 V			8						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

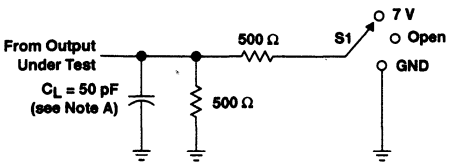
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT162244					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.5	3.6	1	4.1	ns
t_{PHL}			1	3.1	4.7	1	5.3	
t_{PZH}	$\overline{OE}$	Y	1	3.2	4.8	1	5.6	ns
t_{PZL}			1	3.2	4.7	1	5.5	
t_{PHZ}	$\overline{OE}$	Y	1	3.2	5.3	1	6.3	ns
t_{PLZ}			1	3.1	4.6	1	4.9	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

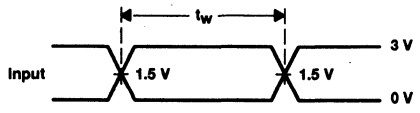
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT162244					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.5	3.2	1	3.9	ns
t_{PHL}			1	3.1	4	1	4.8	
t_{PZH}	$\overline{OE}$	Y	1	3.2	4.2	1	5.4	ns
t_{PZL}			1	3.2	4.1	1	5.1	
t_{PHZ}	$\overline{OE}$	Y	1	3.2	4	1	4.6	ns
t_{PLZ}			1	3.1	3.9	1	4.5	

PARAMETER MEASUREMENT INFORMATION

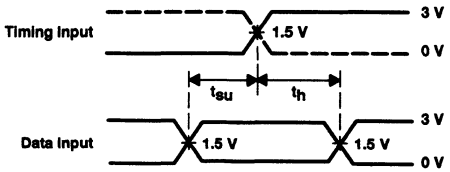


LOAD CIRCUIT

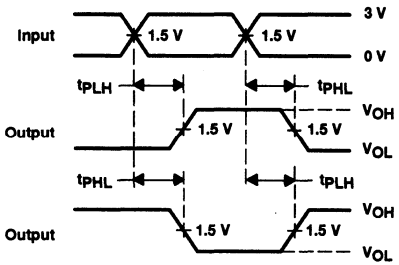
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



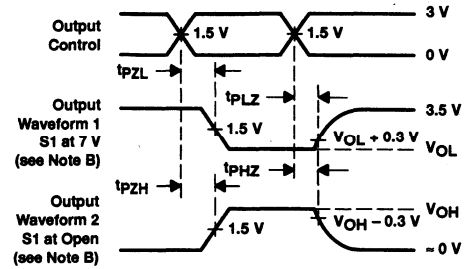
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



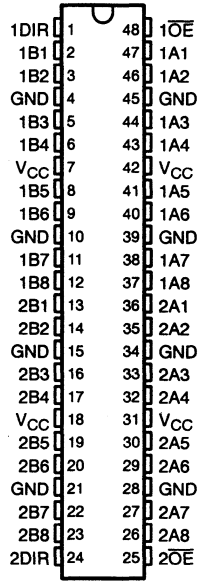
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **A-Port Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT162245 . . . WD PACKAGE
SN74ABT162245 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT162245 are 16-bit noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so that the buses are effectively isolated.

The A-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT162245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT162245 is characterized for operation from –40°C to 85°C.

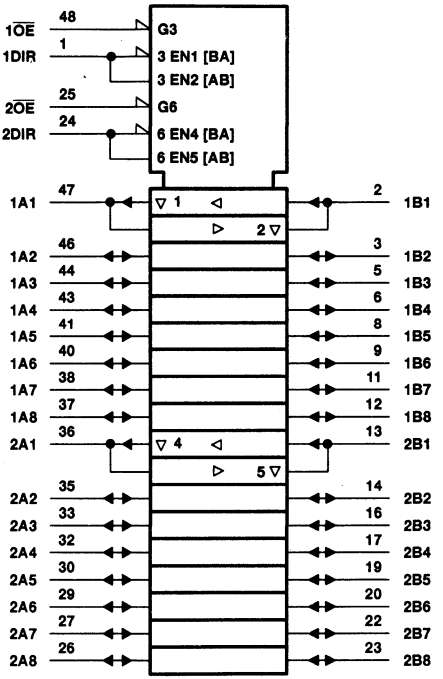
Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

FUNCTION TABLE
(each 8-bit section)

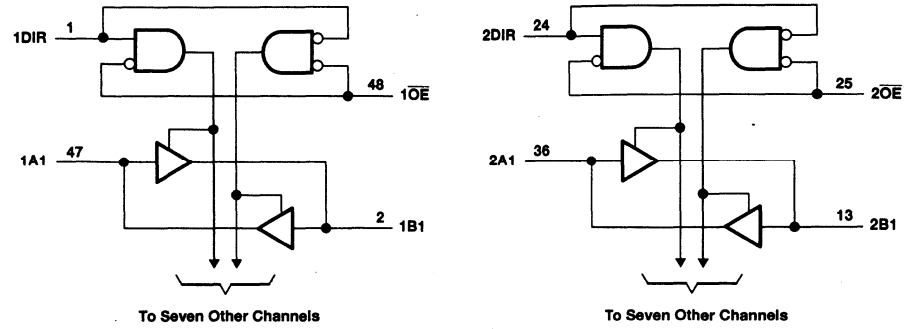
INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT162245 (B port) ..... 96 mA
SN74ABT162245 (B port) ..... 128 mA
SN54/74ABT162245 (A port) ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 89°C/W
DL package ..... 94°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT162245		SN74ABT162245		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	B port		–24		–32	mA
		A port		–12		–12	
I_{OL}	Low-level output current	B port		48		64	mA
		A port		12		12	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

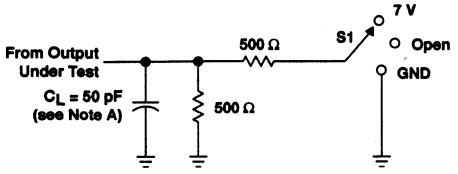
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT162245		SN74ABT162245		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	A port	V_{CC} = 5 V,	I_{OH} = –1 mA	3.8			2.5		2.5		V
		V_{CC} = 4.5 V	I_{OH} = –1 mA	3.3			3		3		
			I_{OH} = –3 mA	3.1			3		3.1		
			I_{OH} = –12 mA	2.6*					2.6		
	B port	V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –3 mA	2.5			2.5		2.5		
			I_{OH} = –24 mA				2				
			I_{OH} = –32 mA	2*					2		
V_{OL}	A port	V_{CC} = 4.5 V	I_{OL} = 12 mA			0.8		0.8		0.8	V
	B port		I_{OL} = 48 mA			0.45		0.45		0.45	
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports					±20		±20		±20	
I_{OZH}§		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}§		V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶	A port	V_{CC} = 5.5 V,	V_O = 2.5 V	–25	–50	–100‡	–25	–90	–25	–100	mA
	B port			–50	–100	–180	–50	–180	–50	–180	
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			32		32		32	
			Outputs disabled			2		2		2	
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1		2		2	mA
			Outputs disabled			0.05		1		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_{io}		V_O = 2.5 V or 0.5 V			6						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This limit applies only to the SN74ABT162245.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

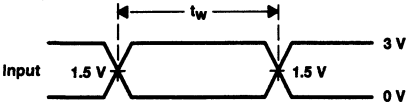
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT162245		SN74ABT162245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	B	1	2.2	3.4	1	4.1	1	3.9	ns
t_{PHL}			1	2.3	3.7	1	4.4	1	4.2	
t_{PLH}	B	A	1	2.7	4.1	1	4.9	1	4.6	ns
t_{PHL}			1.5	3.1	4.6	1.5	5.2	1.5	5.1	
t_{PZH}	$\overline{OE}$	B	1	3.6	5.2	1	6.4	1	6.3	ns
t_{PZL}			1	3.7	5.4	1	6.5	1	6.4	
t_{PHZ}	$\overline{OE}$	B	2	4.4	5.8	2	6.4	2	6.3	ns
t_{PLZ}			1.5	3.3	4.7	1.5	5.6	1.5	5.2	
t_{PZH}	$\overline{OE}$	A	1.5	4.1	6	1.5	7.2	1.5	7.1	ns
t_{PZL}			1.5	4.3	6.1	1.5	7.3	1.5	7	
t_{PHZ}	$\overline{OE}$	A	2	4.5	6.1	2	6.8	2	6.6	ns
t_{PLZ}			1.5	3.7	5.1	1.5	6.1	1.5	5.7	

PARAMETER MEASUREMENT INFORMATION

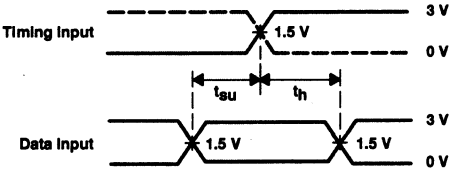


LOAD CIRCUIT

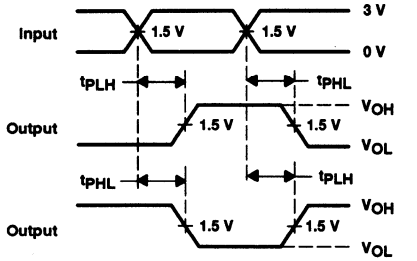
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



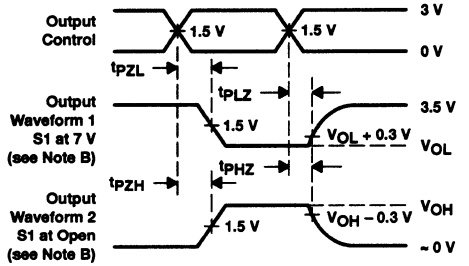
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



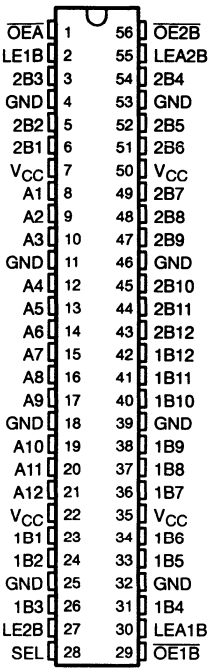
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **B-Port Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABTH162260 . . . WD PACKAGE
SN74ABTH162260 . . . DL PACKAGE
(TOP VIEW)



description

The 'ABTH162260 are 12-bit to 24-bit multiplexed D-type latches used in applications where two separate data paths must be multiplexed onto, or demultiplexed from, a single data path. Typical applications include multiplexing and/or demultiplexing of address and data information in microprocessor or bus-interface applications. These devices are also useful in memory-interleaving applications.

Three 12-bit I/O ports (A1–A12, 1B1–1B12, and 2B1–2B12) are available for address and/or data transfer. The output-enable ($\overline{OE1B}$, $\overline{OE2B}$, and $\overline{OEA}$) inputs control the bus-transceiver functions. The $\overline{OE1B}$ and $\overline{OE2B}$ control signals also allow bank control in the A-to-B direction.

Address and/or data information can be stored using the internal storage latches. The latch-enable (LE1B, LE2B, LEA1B, and LEA2B) inputs are used to control data storage. When the latch-enable input is high, the latch is transparent. When the latch-enable input goes low, the data present at the inputs is latched and remains latched until the latch-enable input is returned high.

The B-port outputs, which are designed to sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

description (continued)

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTH162260 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH162260 is characterized for operation from –40°C to 85°C.

Function Tables

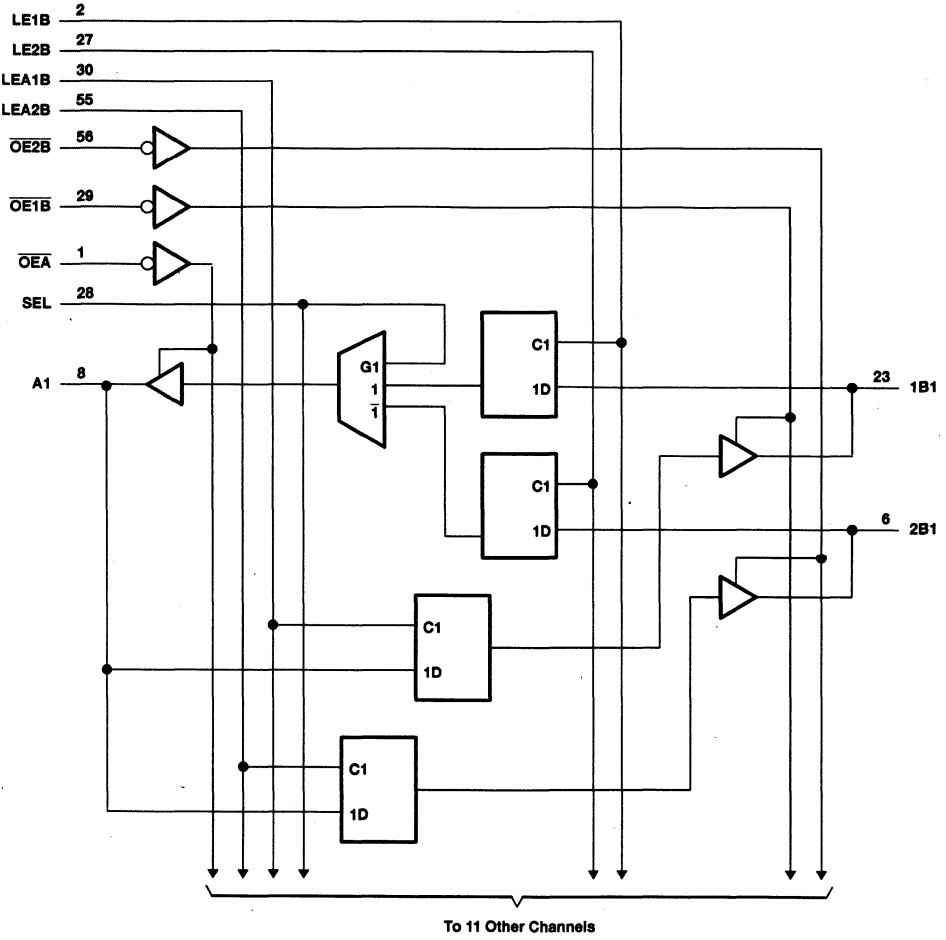
B TO A ($\overline{OEB}$ = H)

INPUTS						OUTPUT
1B	2B	SEL	LE1B	LE2B	$\overline{OEA}$	A
H	X	H	H	X	L	H
L	X	H	H	X	L	L
X	X	H	L	X	L	A_0
X	H	L	X	H	L	H
X	L	L	X	H	L	L
X	X	L	X	L	L	A_0
X	X	X	X	X	H	Z

A TO B ($\overline{OEA}$ = H)

INPUTS					OUTPUTS	
A	LEA1B	LEA2B	$\overline{OE1B}$	$\overline{OE2B}$	1B	2B
H	H	H	L	L	H	H
L	H	H	L	L	L	L
H	H	L	L	L	H	$2B_0$
L	H	L	L	L	L	$2B_0$
H	L	H	L	L	$1B_0$	H
L	L	H	L	L	$1B_0$	L
X	L	L	L	L	$1B_0$	$2B_0$
X	X	X	H	H	Z	Z
X	X	X	L	H	Active	Z
X	X	X	H	L	Z	Active
X	X	X	L	L	Active	Active

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH162260 (A port) ..... 96 mA
SN74ABTH162260 (A port) ..... 128 mA
B port ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABTH162260		SN74ABTH162260		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current	A port		48		64	mA
		B port		12		12	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused control inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABTH162260		SN74ABTH162260		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}	A port	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
	B port		I_{OL} = 12 mA			0.8		0.8		0.8	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±20		±20	
$I_{I(hold)}$	A or B ports	V_{CC} = 4.5 V	V_I = 0.8 V							100	µA
			V_I = 2 V							–100	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–225	–50	–225	–50	–225	mA
I_{CC}	Outputs high	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND				1.5		1.5		1.5	mA
	Outputs low					63		63		63	
	Outputs disabled					1		1		1	
ΔI_{CC}#		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1		1.5		1	mA
C_i		V_I = 2.5 V or 0.5 V			3						pF
C_o		V_O = 2.5 V or 0.5 V			11.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized but not tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

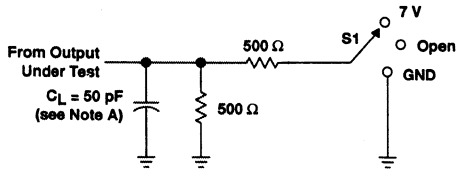
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V_{CC} = 5 V, T_A = 25°C		SN54ABTH162260		SN74ABTH162260		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE1B, LE2B, LEA1B, or LEA2B high	3.3		3.3		3.3		ns
t_{su}	Setup time, data before LE1B, LE2B, LEA1B, or LEA2B↓	1.5		1.5		1.5		ns
t_h	Hold time, data after LE1B, LE2B, LEA1B, or LEA2B↓	1		1		1		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

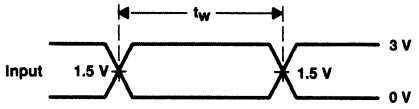
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABTH162260		SN74ABTH162260		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	B	1.4	3.6	5.2	1.4	6.3	1.4	6.1	ns
t_{PHL}			2.7	4.8	6.4	2.7	7.4	2.7	7.1	
t_{PLH}	B	A	1.6	3.6	5.2	1.6	6.4	1.6	6	ns
t_{PHL}			1.7	3.8	5.5	1.7	6.5	1.7	6.2	
t_{PLH}	LE	A	1.8	3.9	5.3	1.8	6.6	1.8	6.3	ns
t_{PHL}			2.3	4.1	5.4	2.3	6.1	2.3	5.8	
t_{PLH}	LE	B	1.6	3.7	5.4	1.6	6.4	1.6	6.1	ns
t_{PHL}			2.8	4.9	6.4	2.8	7.5	2.8	7.1	
t_{PLH}	SEL (1B)	A	1.5	3.6	5	1.5	5.9	1.5	5.6	ns
t_{PHL}			1.8	3.5	4.8	1.8	5.2	1.8	5	
t_{PLH}	SEL (2B)	A	1.2	3.6	5.1	1.2	6.5	1.2	6.3	ns
t_{PHL}			1.7	4	5.5	1.7	6.5	1.7	6.2	
t_{PZH}	$\overline{OE}$	A	1.1	3.5	5.2	1.1	6.5	1.1	6.3	ns
t_{PZL}			2.1	4.2	5.7	2.1	6.6	2.1	6.5	
t_{PZH}	$\overline{OE}$	B	1	3.4	4.9	1	6.4	1	6.3	ns
t_{PZL}			2.9	5.5	6.8	2.9	8.3	2.9	8.2	
t_{PHZ}	$\overline{OE}$	A	2.5	4.5	5.9	2.5	6.9	2.5	6.7	ns
t_{PLZ}			1.8	3.4	4.8	1.8	5.6	1.8	5.2	
t_{PHZ}	$\overline{OE}$	B	2.1	4.4	5.7	2.1	7.7	2.1	7.5	ns
t_{PLZ}			1.7	3.9	5.4	1.7	6.3	1.7	6.2	

PARAMETER MEASUREMENT INFORMATION

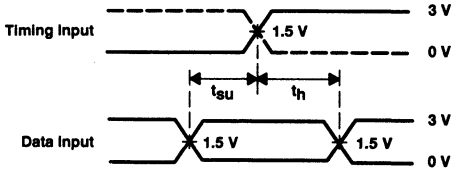


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

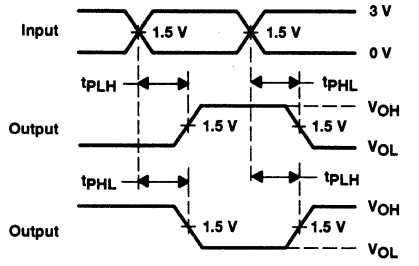
LOAD CIRCUIT



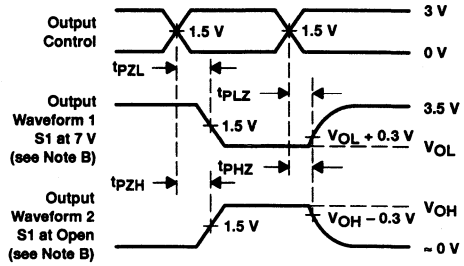
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



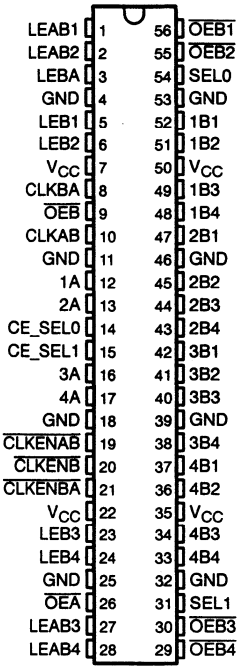
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **B-Port Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABTH162460 . . . WD PACKAGE
SN74ABTH162460 . . . DL PACKAGE
(TOP VIEW)



description

The 'ABTH162460 are 4-bit to 1-bit multiplexed registered transceivers used in applications where four separate data paths must be multiplexed onto or demultiplexed from a single data path. Typical applications include multiplexing and/or demultiplexing of address and data information in microprocessor or bus-interface applications. This device also is useful in memory-interleaving applications.

Five 4-bit I/O ports (1A–4A, 1B1–4, 2B1–4, 3B1–4, and 4B1–4) are available for address and/or data transfer. The output-enable ($\overline{OEB}$, $\overline{OEB1}$–$\overline{OEB4}$, and $\overline{OEA}$) inputs control the bus-transceiver functions. These control signals also allow 4-bit or 16-bit control, depending on the $\overline{OEB}$ level.

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TEXAS INSTRUMENTS

description (continued)

Address and/or data information can be stored using the internal storage latches/flip-flops. The latch-enable (LEB1–LEB4, LEBA, and LEAB1–LEAB4) and clock/clock-enable (CLK/$\overline{\text{CLKEN}}$) inputs are used to control data storage. When either one of the latch-enable inputs is high, the latch is transparent (clock is a don't care as long as the latch enable is high). When the latch-enable input goes low (providing that the clock does not transit from low to high), the data present at the inputs is latched and remains latched until the latch-enable input is returned high. When the clock enable is low and the corresponding latch enable is low, data can be clocked on the low-to-high transition of the clock. When either the clock enable or the corresponding latch enable is high, the clock is a don't care.

Four select (SEL0, SEL1, CE_SEL0, and CE_SEL1) pins are provided to multiplex data (A port), or to select one of four clock enables (B port). This allows the user the flexibility of controlling one bit at a time.

The B-port outputs, which are designed to sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTH162460 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH162460 is characterized for operation from –40°C to 85°C.

Function Tables

A-TO-B OUTPUT ENABLE†

INPUTS		OUTPUT
$\overline{\text{OEB}}$	$\overline{\text{OEBn}}$	Bn
H	H	Z
H	L	Z
L	H	Z
L	L	Active

† n = 1, 2, 3, 4

A-TO-B STORAGE
(assuming $\overline{\text{OEB}}$ = L, $\overline{\text{OEBn}}$ = L)‡

INPUTS								OUTPUTS			
$\overline{\text{CLKENAB}}$	CE_SEL1	CE_SEL0	CLKAB	LEAB1	LEAB2	LEAB3	LEAB4	B1	B2	B3	B4
X	X	X	H or L	H	L	L	L	A	A_0	A_0	A_0
X	X	X	H or L	H	H	H	L	A	A	A	A_0
L	X	X	L	L	L	L	L	A_0	A_0	A_0	A_0
L	L	L	↑	L	L	L	L	A	A_0	A_0	A_0
L	L	H	↑	L	L	L	L	A_0	A	A_0	A_0
L	H	L	↑	L	L	L	L	A_0	A_0	A	A_0
L	H	H	↑	L	L	L	L	A_0	A_0	A_0	A
H	X	X	↑	L	L	L	L	A_0	A_0	A_0	A_0

‡ This table does not cover all the latch-enable cases since they have similar results.

Function Tables (Continued)

B-TO-A STORAGE
(before point P)

INPUTS								P
$\overline{CLKENB}$	CLKBA	LEB1	LEB2	LEB3	LEB4	SEL1	SEL0	
X	X	H	L	L	L	L	L	B1
X	X	L	H	L	L	L	H	B2
X	X	L	L	H	L	H	L	B3
X	X	L	L	L	H	H	H	B4
L	↑	L	L	L	L	L	L	B1
						L	H	B2
						H	L	B3
						H	H	B4
L	L	L	L	L	L	L	L	$B1_0$†
						L	H	$B2_0$†
						H	L	$B3_0$†
						H	H	$B4_0$†

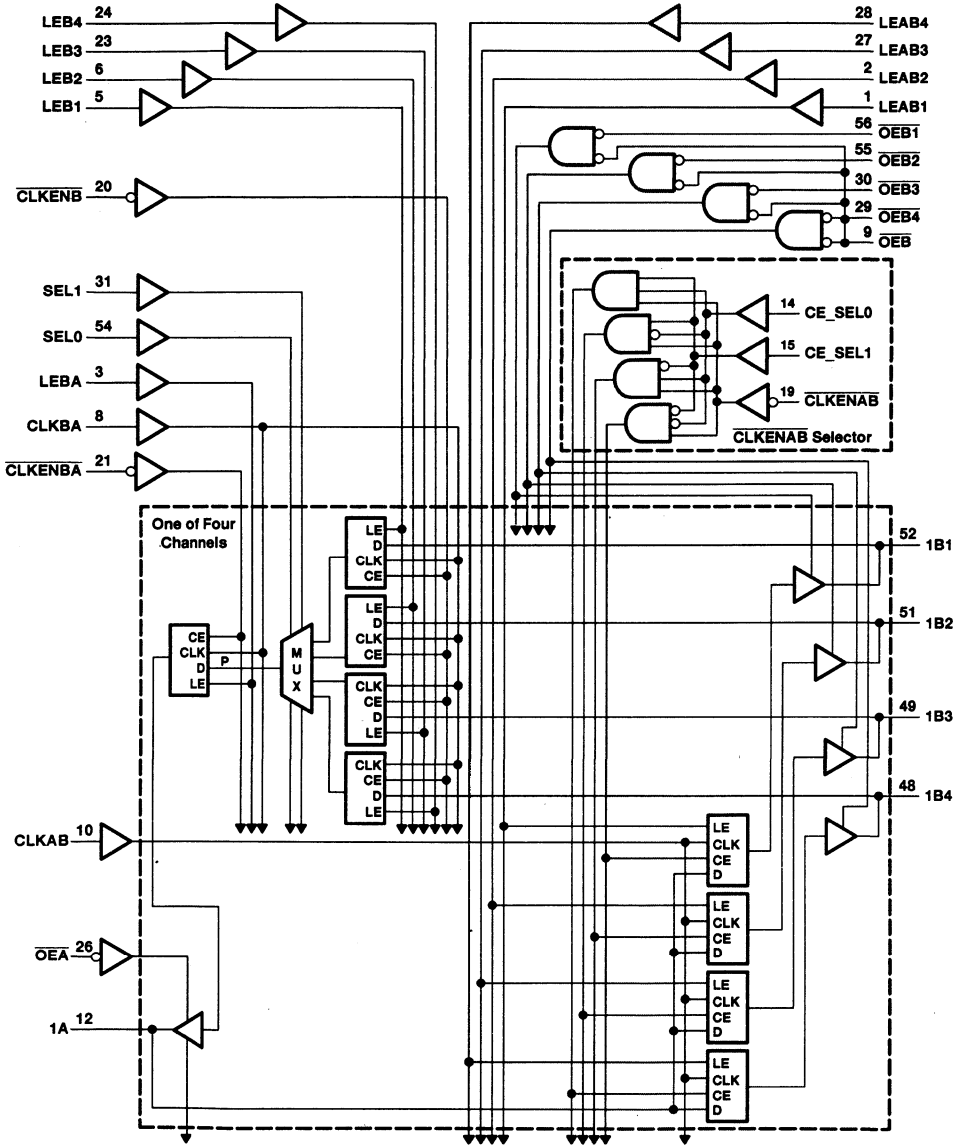
† Output level before the indicated steady-state input conditions were established

B-TO-A STORAGE
(after point P)

INPUTS					OUTPUT
$\overline{CLKENBA}$	CLKBA	LEBA	$\overline{OEA}$	B	A
X	X	X	H	X	Z
X	X	H	L	L	L
X	X	H	L	H	H
H	X	L	L	X	A_0†
L	↑	L	L	L	L
L	↑	L	L	H	H
L	L	L	L	X	A_0†

† Output level before the indicated steady-state input conditions were established

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABTH162460 (A port) ..... 96 mA
SN74ABTH162460 (A port) ..... 128 mA
B port ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package ..... 74 °C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABTH162460			SN74ABTH162460			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.8			0.8	V
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current	A port			–24			–32	mA
		B port			–12			–12	
I_{OL}	Low-level output current	A port			48			64	mA
		B port			12			12	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled			10			10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200			200			µs/V
T_A	Operating free-air temperature		–55		125	–40		85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ABTH162460			SN74ABTH162460			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2			–1.2	V
V_{OH}	A port	V_{CC} = 5 V,	I_{OH} = –3 mA	3	3.4		3	3.4		V
		V_{CC} = 4.5 V	I_{OH} = –3 mA	2.5	3					
			I_{OH} = –32 mA				2	2.7		
	B port	V_{CC} = 5 V,	I_{OH} = –1 mA	3.8	4.2		3.85			
		V_{CC} = 4.5 V	I_{OH} = –1 mA	3.3	3.7		3.35			
			I_{OH} = –3 mA	3	3.6		3.1			
			I_{OH} = –12 mA				2.6			
V_{OL}	A port	V_{CC} = 4.5 V	I_{OL} = 24 mA		0.25	0.55				V
			I_{OL} = 64 mA					0.3	0.55	
	B port	V_{CC} = 4.5 V	I_{OL} = 8 mA		0.4	0.8		0.4	0.65	
			I_{OL} = 12 mA					0.5	0.8	
V_{hys}					100			100		mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V,	V_I = V_{CC} or GND			±1			±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V,	V_I = V_{CC} or GND			±20			±20	
$I_{I(hold)}$	A or B ports	V_{CC} = 5.5 V,	V_I = 0.8 V	75		500	75		500	µA
		V_{CC} = 4.5 V,	V_I = 2 V	–75		–500	–75		–500	
I_O‡	A port	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–110	–180	–50		–180	mA
	B port	V_{CC} = 5.5 V	V_O = 2.5 V	–25	–55	–90	–25		–90	
			V_O = 0	–50	–110	–180	–50		–180	
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50			50	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100			±100	µA
I_{OZPU}§		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{OZPD}§		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50			±50	µA
I_{CC}	Outputs high	V_{CC} = 5.5 V, Outputs open				1.5		0.7	1.5	mA
	A port low					10		6	10	
	B port low					32		18	32	
	Outputs disabled					1.5		0.7	1.5	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1			1	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3.5			3.5		pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			8			8		pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This parameter is characterized but not production tested.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

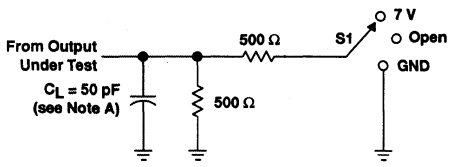
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(see Figure 1)

				V_{CC} = 5 V, T_A = 25°C		SN54ABTH162460		SN74ABTH162460		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			0	160	0	160	0	160	MHz
t_w	Pulse duration	CLKAB high or low		3.8		3.8		3.8		ns
		CLKBA high or low		4.5		4.5		4.5		
		LEAB1, 2, 3, or 4 high		2.8		2.8		2.8		
		LEBA high		2.8		2.8		2.8		
		LEB1, 2, 3, or 4 high		3		3		3		
t_{su}	Setup time	Before CLKAB↑	A bus	2.5		2.5		2.5		ns
			CE_SEL0/1	3.2		3.2		3.2		
			$\overline{CLKENAB}$	3.2		3.2		3.2		
		Before LEAB1, 2, 3, or 4↓	A bus	3.6		3.6		3.6		
		Before CLKBA↑	B bus	3.8		3.8		3.8		
			$\overline{CLKENB}$	2.3		2.3		2.3		
			$\overline{CLKENBA}$	2.5		2.5		2.5		
			LEB1, 2, 3, or 4	4.3		4.3		4.3		
			SEL0/1	4.5		4.5		4.5		
		Before LEB1, 2, 3, or 4↓	B bus	3.2		3.2		3.2		
		Before LEBA↓	B bus	4		4		4		
			LEB1, 2, 3, or 4	4.4		4.4		4.4		
			SEL0/1	4.3		4.3		4.3		
t_h	Hold time	After CLKAB↑	A bus	0.5		0.5		0.5		ns
			CE_SEL0/1	1.1		1.1		1.1		
			$\overline{CLKENAB}$	0.5		0.5		0.5		
		After LEAB1, 2, 3, or 4↓	A bus	1.2		1.2		1.2		
		After CLKBA↑	B bus	1.3		1.3		1.3		
			$\overline{CLKENB}$	1		1		1		
			$\overline{CLKENBA}$	1		1		1		
			SEL0/1	0		0		0		
		After LEB1, 2, 3, or 4↓	B bus	1.5		1.5		1.5		
		After LEBA↓	B bus	0.4		0.4		0.4		
			SEL0/1	0.1		0.1		0.1		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

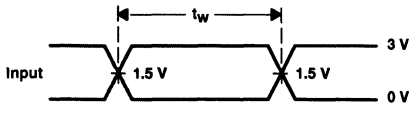
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABTH162460		SN74ABTH162460		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			160			160		160		MHz
t_{PLH}	B	A	2	3.6	5.9	2	7.1	2	6.5	ns
t_{PHL}			2	3.5	5.8	2	6.8	2	6.5	
t_{PZH}	$\overline{OEA}$	A	1.5	2.8	4.8	1.5	5.9	1.5	5.6	ns
t_{PZL}			1.5	2.6	4.8	1.5	5.7	1.5	5.5	
t_{PHZ}	$\overline{OEA}$	A	2	3.8	5.3	2	6	2	5.9	ns
t_{PLZ}			1.5	4	6.1	1.5	7	1.5	6.5	
t_{PLH}	A	B	2	3.3	5.5	2	6.5	2	6.2	ns
t_{PHL}			2	3.7	5.8	2	6.8	2	6.5	
t_{PZH}	$\overline{OEB}$	B	2	3.9	5.8	2	7.1	2	6.8	ns
t_{PZL}			2	3.7	5.6	2	6.6	1.5	6.3	
t_{PHZ}	$\overline{OEB}$	B	2	4	5.6	2	6.4	2	6.2	ns
t_{PLZ}			2	3.7	5.2	2	6.1	2	5.8	
t_{PZH}	$\overline{OEB1}$, $\overline{2}$, $\overline{3}$, $\overline{4}$	B	2	3.7	5.8	2	6.8	2	6.6	ns
t_{PZL}			2	3.5	5.4	2	6.4	2	6.2	
t_{PHZ}	$\overline{OEB1}$, $\overline{2}$, $\overline{3}$, $\overline{4}$	B	1.5	3.3	4.8	1.5	5.4	1.5	5.3	ns
t_{PLZ}			1.5	3.1	4.4	1.5	5.1	1.5	4.9	
t_{PLH}	CLKBA	A	1.5	4.2	6.7	1.5	8.1	1.5	7.4	ns
t_{PHL}			1.5	4.4	6.9	1.5	8.4	1.5	7.7	
t_{PLH}	CLKAB	B	2	3.5	5.8	2	6.9	2	6.5	ns
t_{PHL}			2	3.7	6	2	7	2	6.5	
t_{PLH}	LEBA	A	1.5	3	5.2	1.5	6.3	1.5	5.8	ns
t_{PHL}			1.5	3	5	1.5	6.3	1.5	5.8	
t_{PLH}	LEAB1, 2, 3, 4	B	2	3.4	5.4	2	6.5	2	6.2	ns
t_{PHL}			2	3.6	5.7	2	6.3	2	6.2	
t_{PLH}	LEBA1, 2, 3, 4	A	2	4	6.5	2	7.8	2	7.2	ns
t_{PHL}			2	4	6.1	2	7.5	2	6.8	
t_{PLH}	SEL	A	2	4.1	6.7	2	8.1	2	7.5	ns
t_{PHL}			2	3.8	6.2	2	7.3	2	6.9	

PARAMETER MEASUREMENT INFORMATION

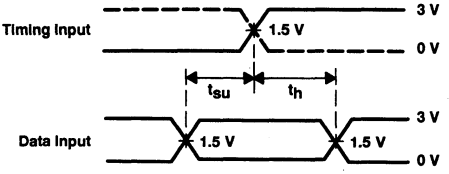


LOAD CIRCUIT

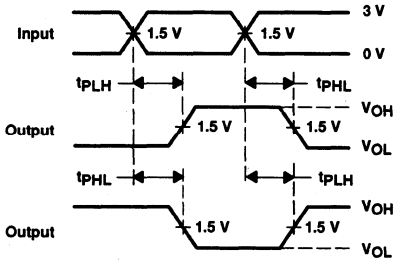
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



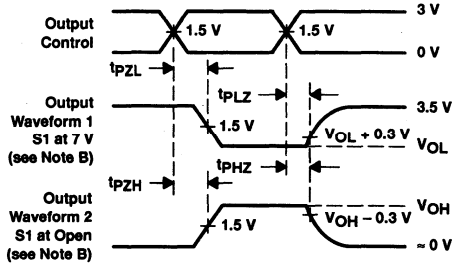
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



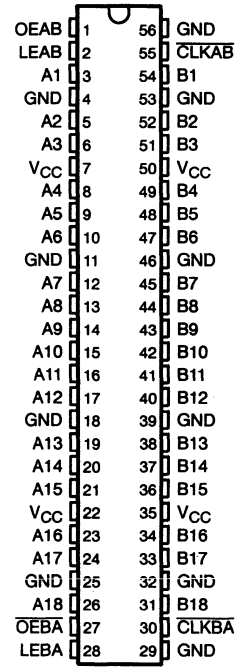
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **B-Port Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- ***UBT*™ (Universal Bus Transceiver) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT162500 . . . WD PACKAGE
SN74ABT162500 . . . DL PACKAGE
(TOP VIEW)



description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes. Data flow in each direction is controlled by output-enable (OEAB and $\overline{\text{OEBA}}$), latch-enable (LEAB and LEBA), and clock ($\overline{\text{CLKAB}}$ and $\overline{\text{CLKBA}}$) inputs.

For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if $\overline{\text{CLKAB}}$ is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the high-to-low transition of $\overline{\text{CLKAB}}$. Output-enable OEAB is active high. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B but uses $\overline{\text{OEBA}}$, LEBA, and $\overline{\text{CLKBA}}$. The output enables are complementary (OEAB is active high and $\overline{\text{OEBA}}$ is active low).

The B-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

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description (continued)

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The SN54ABT162500 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT162500 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

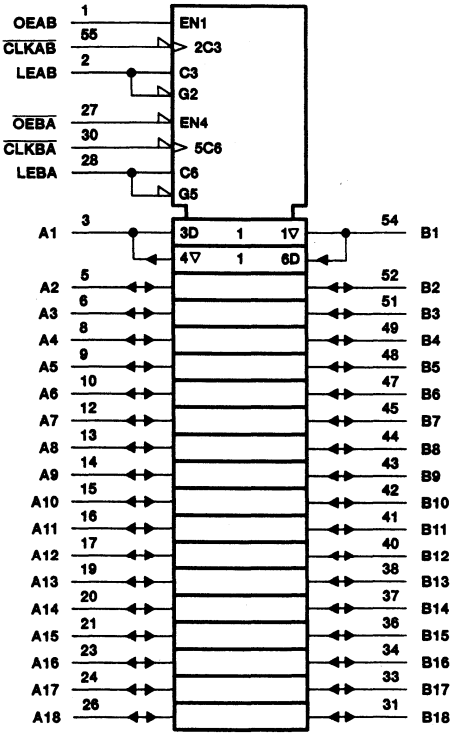
INPUTS				OUTPUT
OEAB	LEAB	$\overline{CLKAB}$	A	B
L	X	X	X	Z
H	H	X	L	L
H	H	X	H	H
H	L	↓	L	L
H	L	↓	H	H
H	L	H	X	B_0‡
H	L	L	X	B_0§

† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{OEBA}$, LEBA, and $\overline{CLKBA}$.

‡ Output level before the indicated steady-state input conditions were established

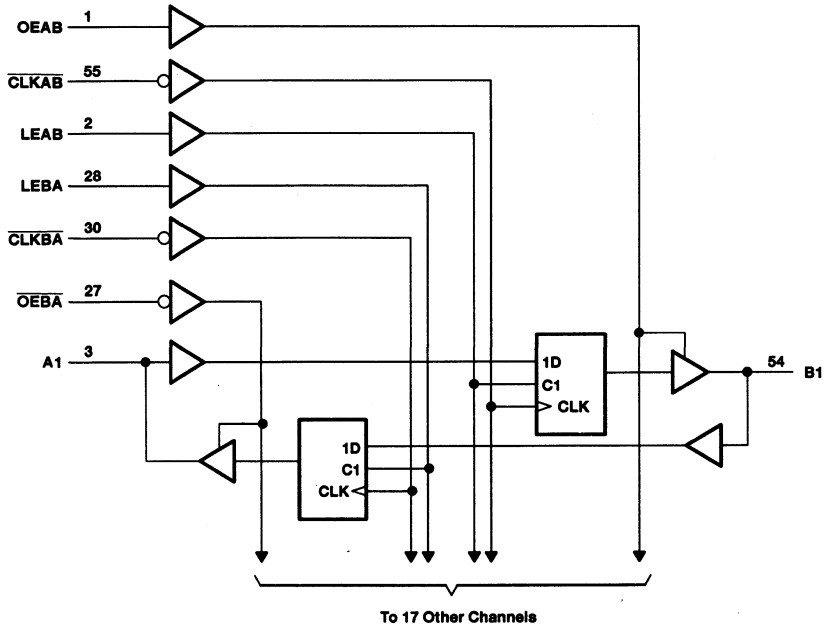
§ Output level before the indicated steady-state input conditions were established, provided that $\overline{CLKAB}$ was low before LEAB went low

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT162500 (A port)	96 mA
SN74ABT162500 (A port)	128 mA
B port	30 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT162500		SN74ABT162500		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	A port		–24		–32	mA
		B port		–12		–12	
I_{OL}	Low-level output current	A port		48		64	mA
		B port		12		12	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		µs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT162500		SN74ABT162500		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	A port	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
	B port	V_{CC} = 4.5 V,	I_{OH} = –1 mA	3.35			3.3		3.35		
		V_{CC} = 5 V,	I_{OH} = –1 mA	3.85			3.8		3.85		
		V_{CC} = 4.5 V	I_{OH} = –3 mA	3.1			3		3.1		
			I_{OH} = –12 mA	2.6					2.6		
V_{OL}	A port	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
	B port	V_{CC} = 4.5 V,	I_{OL} = 12 mA			0.8		0.8		0.8	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±20		±20	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ or OE = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ or OE = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V or OE ≤ 0.8 V¶				10		10		10	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V or OE ≤ 0.8 V¶				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O#	A port	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–110	–180	–50	–180	–50	–180	mA
	B port			–25	–55	–90	–25	–90	–25	–90	
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3		3		3	mA
			Outputs low			36		36		36	
			Outputs disabled			3		3		3	
ΔI_{CC}‖		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	µA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ For V_{CC} between 2.1 V and 4 V, OE should be less than or equal to 0.5 V to ensure a low state.
# Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
‖ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

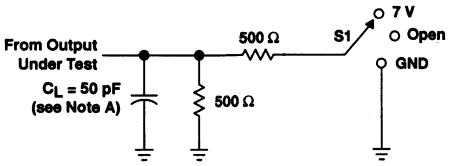
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN54ABT162500		SN74ABT162500		UNIT
				MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			0	150	0	150	MHz
t_w	Pulse duration	LEAB or LEBA high		2.5		2.5		ns
		$\overline{CLKAB}$ or $\overline{CLKBA}$ high or low		3		3		
t_{su}	Setup time	A before $\overline{CLKAB}$↓		3.3		3.3		ns
		B before $\overline{CLKBA}$↓		3.3		3.3		
		A before LEAB↓ or B before LEBA↓	$\overline{CLK}$ high	1		1		
			$\overline{CLK}$ low	2.5		2.5		
t_h	Hold time	A after $\overline{CLKAB}$↓ or B after $\overline{CLKBA}$↓		0		0		ns
		A after LEAB↓ or B after LEBA↓		2		2		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

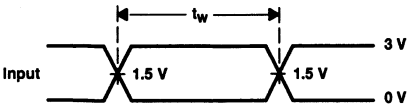
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT162500		SN74ABT162500		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			150	200		150		150		MHz
t_{PLH}	A or B	B or A	1.5	2.6	4	1.5	5.1	1.5	4.8	ns
t_{PHL}			2	3.4	5.2	2	6.1	2	5.7	
t_{PLH}	LEAB or LEBA	B or A	2	3.3	4.8	2	6.1	2	5.6	ns
t_{PHL}			2	3.8	5.2	2	6.4	2	5.9	
t_{PLH}	$\overline{CLKAB}$ or $\overline{CLKBA}$	B or A	1.5	3.7	4.9	1.5	6.4	1.5	5.9	ns
t_{PHL}			1.5	3.8	5.2	1.5	6.4	1.5	6	
t_{PZH}	OEAB or $\overline{OEBA}$	B or A	1.5	3.4	4.6	1.5	5.6	1.5	5.3	ns
t_{PZL}			2	3.8	4.7	2	5.6	2	5.4	
t_{PHZ}	OEAB or $\overline{OEBA}$	B or A	2	4.5	5.7	2	6.9	2	6.5	ns
t_{PLZ}			1.5	3.8	5.3	1.5	6.3	1.5	5.8	

PARAMETER MEASUREMENT INFORMATION

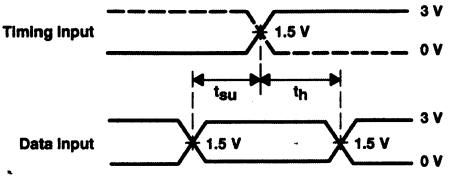


LOAD CIRCUIT

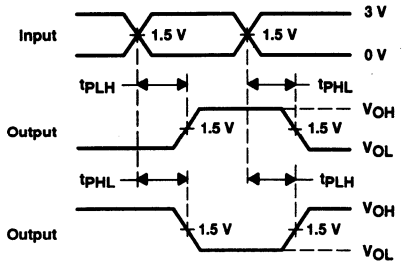
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
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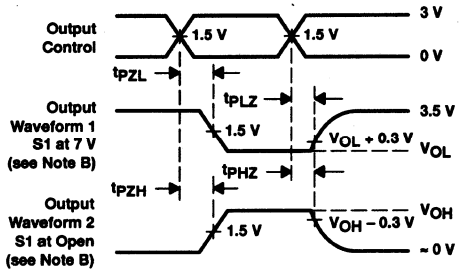
INVERTING AND NONINVERTING OUTPUTS



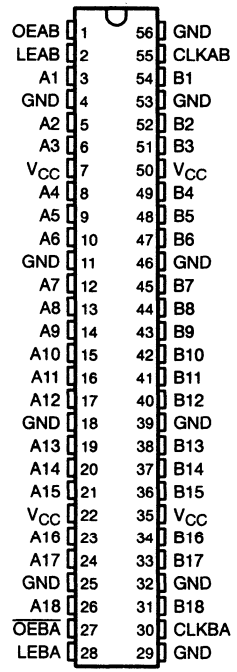
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **B-Port Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- ***UBT*™ (Universal Bus Transceiver) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT162501 . . . WD PACKAGE
SN74ABT162501 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

These 18-bit universal bus transceivers consist of storage elements that can operate either as D-type latches or D-type flip-flops to allow data flow in transparent or clocked modes.

Data flow in each direction is controlled by output-enable (OEAB and $\overline{\text{OEBA}}$), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B but uses $\overline{\text{OEBA}}$, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and $\overline{\text{OEBA}}$ is active low).

The B-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

Widebus, EPIC-IIB, and UBT are trademarks of Texas Instruments Incorporated.

description (continued)

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

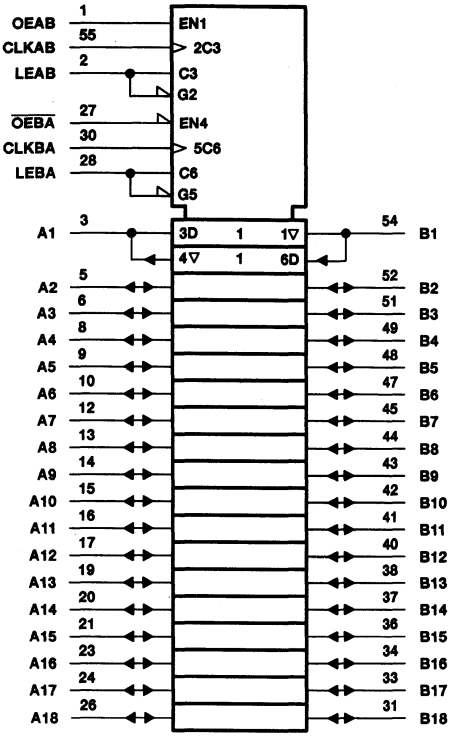
The SN54ABT162501 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT162501 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

INPUTS				OUTPUT
OEAB	LEAB	CLKAB	A	B
L	X	X	X	Z
H	H	X	L	L
H	H	X	H	H
H	L	↑	L	L
H	L	↑	H	H
H	L	H	X	B_0‡
H	L	L	X	B_0§

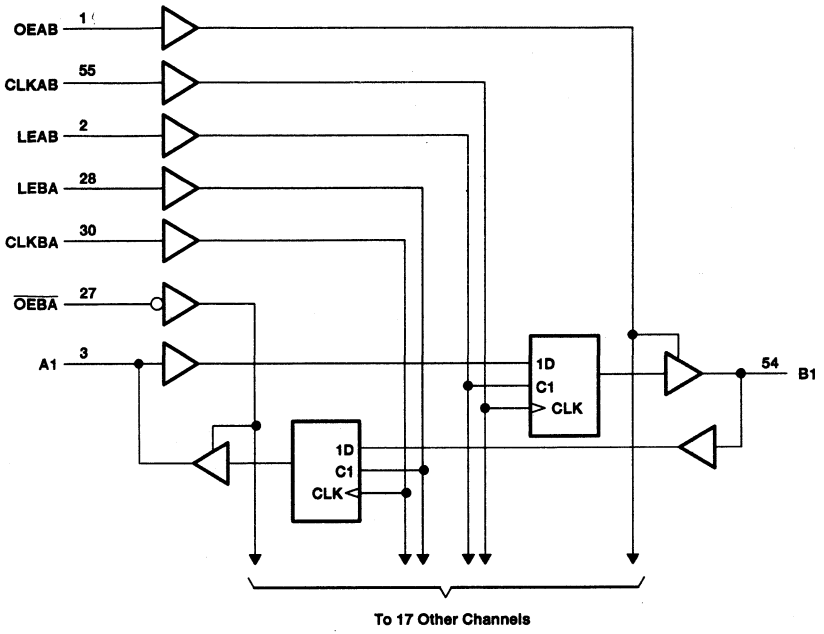
† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{OEBA}$, LEBA, and CLKBA.
‡ Output level before the indicated steady-state input conditions were established, provided that CLKAB was high before LEAB went low
§ Output level before the indicated steady-state input conditions were established

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT162501 (A port) ..... 96 mA
SN74ABT162501 (A port) ..... 128 mA
B port ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT162501		SN74ABT162501		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	A port		–24		–32	mA
		B port		–12		–12	
I_{OL}	Low-level output current	A port		48		64	mA
		B port		12		12	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		µs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT162501		SN74ABT162501		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	A port	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
	B port	V_{CC} = 4.5 V,	I_{OH} = –1 mA	3.35			3.3		3.35		
		V_{CC} = 5 V,	I_{OH} = –1 mA	3.85			3.8		3.85		
		V_{CC} = 4.5 V	I_{OH} = –3 mA	3.1			3		3.1		
			I_{OH} = –12 mA	2.6					2.6		
V_{OL}	A port	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
	B port	V_{CC} = 4.5 V,	I_{OL} = 12 mA			0.8		0.8		0.8	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±20		±20	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ or OE = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ or OE = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V or OE ≤ 0.8 V¶				10		10		10	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V or OE ≤ 0.8 V¶				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O#	A port	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–110	–180	–50	–180	–50	–180	mA
	B port	V_{CC} = 5.5 V,	V_O = 2.5 V	–25	–55	–90	–25	–90	–25	–90	
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3		3		3	mA
			Outputs low			36		36		36	
			Outputs disabled			3		3		3	
ΔI_{CC}‖		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	µA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ For V_{CC} between 2.1 V and 4 V, OE should be less than or equal to 0.5 V to ensure a low state.
# Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
‖ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

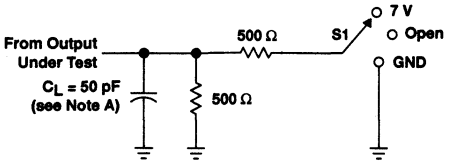
				SN54ABT162501		SN74ABT162501		UNIT
				MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			0	150	0	150	MHz
t_w†	Pulse duration	LEAB or LEBA high		3		3		ns
		CLKAB or CLKBA high or low		3.3		3.3		
t_{su}	Setup time	A before CLKAB↑		4.3		4.3		ns
		B before CLKBA↑		4.3		4.3		
		A before LEAB↓ or B before LEBA↓	CLK high	2.5		2.5		
			CLK low	1		1		
t_h	Hold time	A after CLKAB↑ or B after CLKBA↑		0		0		ns
		A after LEAB↓ or B after LEBA↓		2		2		

† This parameter is characterized, but not production tested.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT162501		SN74ABT162501		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			150	200		150		150		MHz
t_{PLH}	A or B	B or A	1.5	2.6	4	1.5	5.1	1.5	4.8	ns
t_{PHL}			2	3.4	5.2	2	6.1	2	5.7	
t_{PLH}	LEAB or LEBA	B or A	2	3.3	4.8	2	6.1	2	5.6	ns
t_{PHL}			2	3.8	5.2	2	6.4	2	5.9	
t_{PLH}	CLKAB or CLKBA	B or A	1.5	3.5	4.7	1.5	6	1.5	5.5	ns
t_{PHL}			1.5	3.5	4.8	1.5	5.8	1.5	5.3	
t_{PZH}	OEAB or $\overline{OEBA}$	B or A	1.5	3.4	4.6	1.5	5.6	1.5	5.3	ns
t_{PZL}			2	3.8	4.7	2	5.6	2	5.4	
t_{PHZ}	OEAB or $\overline{OEBA}$	B or A	2	4.5	5.7	2	6.9	2	6.5	ns
t_{PLZ}			1.5	3.8	5.3	1.5	6.3	1.5	5.8	

PARAMETER MEASUREMENT INFORMATION



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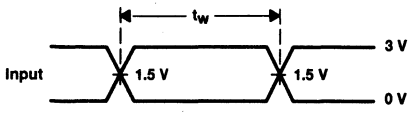
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



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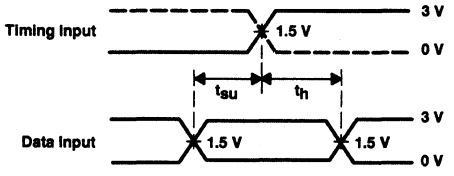

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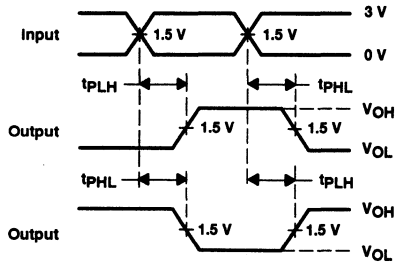

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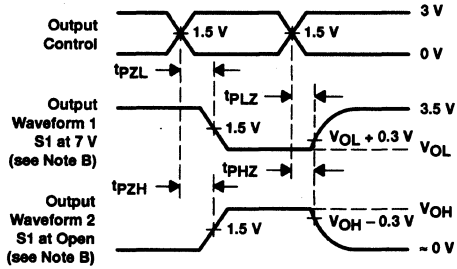

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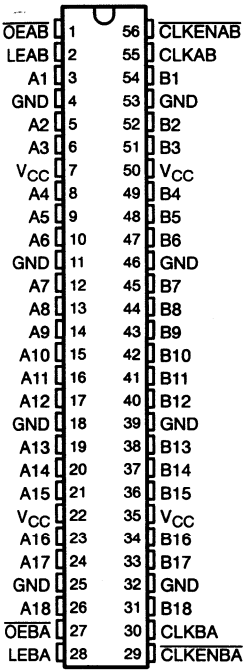


description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes.

Data flow in each direction is controlled by output-enable ($\overline{OEAB}$ and $\overline{OEBA}$), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable ($\overline{CLKENAB}$ and $\overline{CLKENBA}$) inputs.

For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. Output-enable $\overline{OEAB}$ is active-low. When $\overline{OEAB}$ is low, the outputs are active. When $\overline{OEAB}$ is high, the outputs are in the high-impedance state. Data flow for B to A is similar to that of A to B but uses $\overline{OEBA}$, LEBA, CLKBA, and $\overline{CLKENBA}$.

The B-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

description (continued)

The SN54ABT162601 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT162601 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

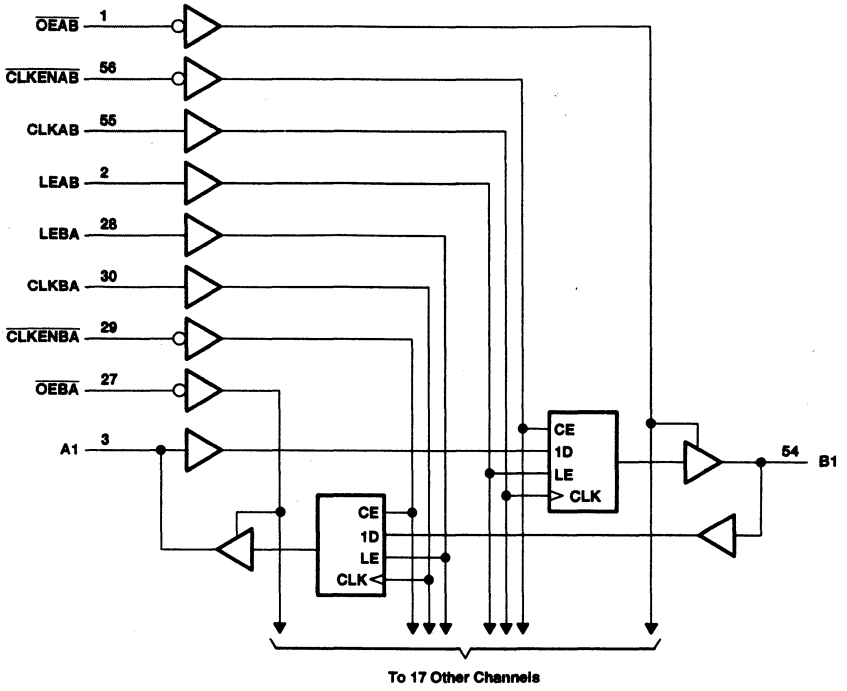
INPUTS					OUTPUT
$\overline{CLKENAB}$	$\overline{OEAB}$	LEAB	CLKAB	A	B
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	B_0‡
H	L	L	X	X	B_0‡
L	L	L	↑	L	L
L	L	L	↑	H	H
L	L	L	L	X	B_0‡
L	L	L	H	X	B_0§

† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{OEBA}$, LEBA, CLKBA, and $\overline{CLKENBA}$.

‡ Output level before the indicated steady-state input conditions were established

§ Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT162601 (A port) ..... 96 mA
SN74ABT162601 (A port) ..... 128 mA
B port ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT162601		SN74ABT162601		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	A port		–24		–32	mA
		B port		–12		–12	
I_{OL}	Low-level output current	A port		48		64	mA
		B port		12		12	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT162601		SN74ABT162601		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	A port	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
	B port	V_{CC} = 4.5 V,	I_{OH} = –1 mA	3.35			3.3		3.35		
		V_{CC} = 5 V,	I_{OH} = –1 mA	3.85			3.8		3.85		
		V_{CC} = 4.5 V	I_{OH} = –3 mA	3.1			3		3.1		
			I_{OH} = –12 mA	2.6					2.6		
V_{OL}	A port	V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
	B port	V_{CC} = 4.5 V,	I_{OL} = 12 mA			0.8		0.8		0.8	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports	V_{CC} = 2.1 V to 5.5 V, V_I = V_{CC} or GND				±20		±20		±20	
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶	A port	V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
	B port			–25	–55	–100	–25	–100	–25	–100	
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			3		3		3	mA
			Outputs low			36		36		36	
			Outputs disabled			3		3		3	
ΔI_{CC}#		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	µA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

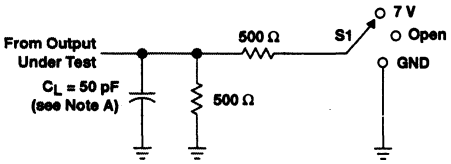
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(see Figure 1)

				SN54ABT162601		SN74ABT162601		UNIT
				MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			0	150	0	150	MHz
t_w	Pulse duration	LEAB or LEBA high		2.5		2.5		ns
		CLKAB or CLKBA high or low		3		3		
t_{su}	Setup time	A before CLKAB↑ or B before CLKBA↑		4.3		4.3		ns
		A before LEAB↓ or B before LEBA↓	CLK high	2.5		2.5		
			CLK low			1		
		CLKEN before CLK↑		2.7		2.7		
t_h	Hold time	A after CLKAB↑ or B after CLKBA↑		0		0		ns
		A after LEAB↓ or B after LEBA↓		0.5		0.5		
		CLKEN after CLK↑		0		0		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

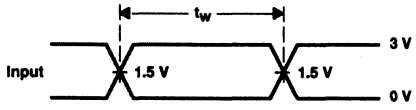
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT162601		SN74ABT162601		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			150			150		150		MHz
t_{PLH}	A	B	1.5	2.8	4	1.5	5.1	1.5	4.8	ns
t_{PHL}			2	3.7	5.2	2	6.1	2	5.7	
t_{PLH}	B	A	1	2.5	3.6	1	4.2	1	4	ns
t_{PHL}			2	3.3	4.5	2	5.1	2	4.9	
t_{PLH}	LEBA	A	2	3.3	4.5	2	5.6	2	5	ns
t_{PHL}			2	3.6	4.7	2	5.4	2	5	
t_{PLH}	LEAB	B	2	3.4	4.8	2	6.1	2	5.6	ns
t_{PHL}			2	3.8	5.2	2	6.4	2	5.9	
t_{PLH}	CLKBA	A	1.5	3.1	4.7	1.5	5.4	1.5	5.3	ns
t_{PHL}			1.5	3.1	4.3	1.5	5.2	1.5	5	
t_{PLH}	CLKAB	B	1.5	3.3	4.7	1.5	6	1.5	5.5	ns
t_{PHL}			1.5	3.5	4.8	1.5	5.8	1.5	5.3	
t_{PZH}	$\overline{OEBA}$	A	2	3.5	4.6	2	5.3	2	5.1	ns
t_{PZL}			2	3.7	4.7	2	5.6	2	5.4	
t_{PZH}	$\overline{OEAB}$	B	2	3.8	5.3	2	6.6	2	6.1	ns
t_{PZL}			2	3.6	5.1	2	6.2	2	5.7	
t_{PHZ}	$\overline{OEBA}$	A	2	3.6	5.4	2	6.6	2	6.2	ns
t_{PLZ}			1.5	3.2	4.7	1.5	5.8	1.5	5.4	
t_{PHZ}	$\overline{OEAB}$	B	2	3.4	4.8	2	5.6	2	5.4	ns
t_{PLZ}			1.5	3.2	4.5	1.5	5.7	1.5	5.2	

PARAMETER MEASUREMENT INFORMATION

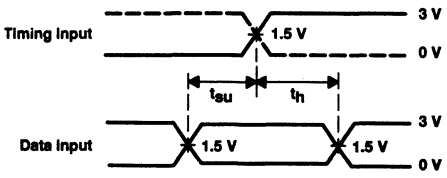


LOAD CIRCUIT

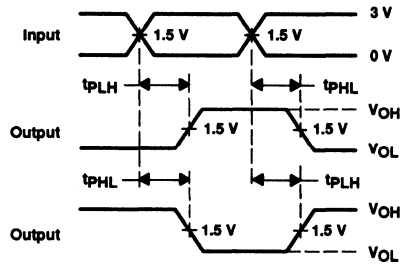
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



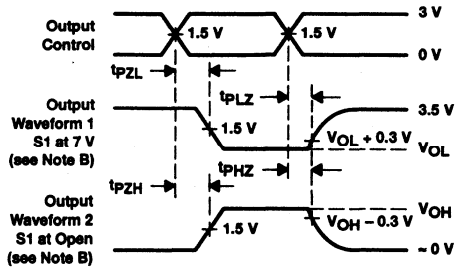
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



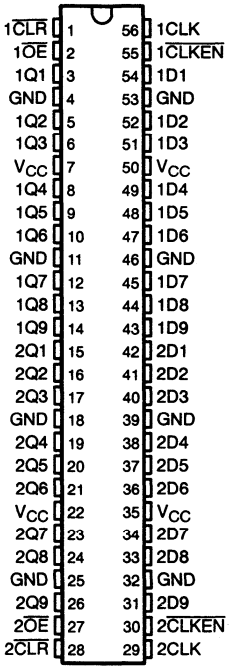
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Output Ports Have Equivalent 25-Ω Series Resistors So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **High-Impedance State During Power Up and Power Down**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT162823A . . . WD PACKAGE
SN74ABT162823A . . . DL PACKAGE
(TOP VIEW)



description

These 18-bit bus-interface flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

The 'ABT162823A can be used as two 9-bit flip-flops or one 18-bit flip-flop. With the clock-enable ($\overline{CLKEN}$) input low, the D-type flip-flops enter data on the low-to-high transitions of the clock. Taking $\overline{CLKEN}$ high disables the clock buffer, thus latching the outputs. Taking the clear ($\overline{CLR}$) input low causes the Q outputs to go low independently of the clock.

A buffered output-enable ($\overline{OE}$) input places the nine outputs in either a normal logic state (high or low level) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components. $\overline{OE}$ does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

description (continued)

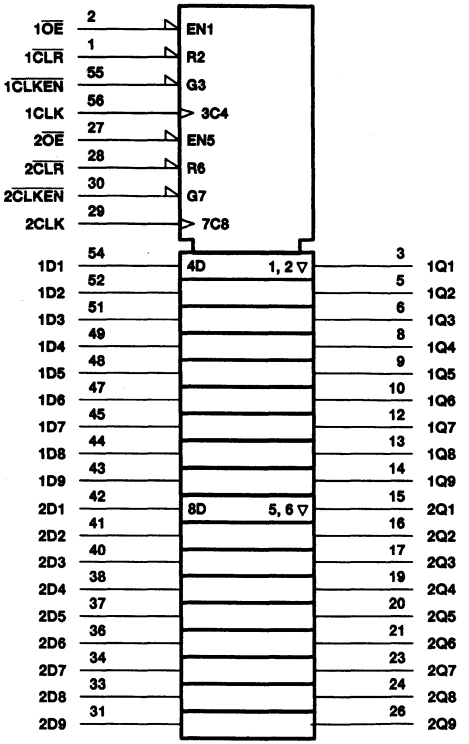
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT162823A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT162823A is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 9-bit flip-flop)

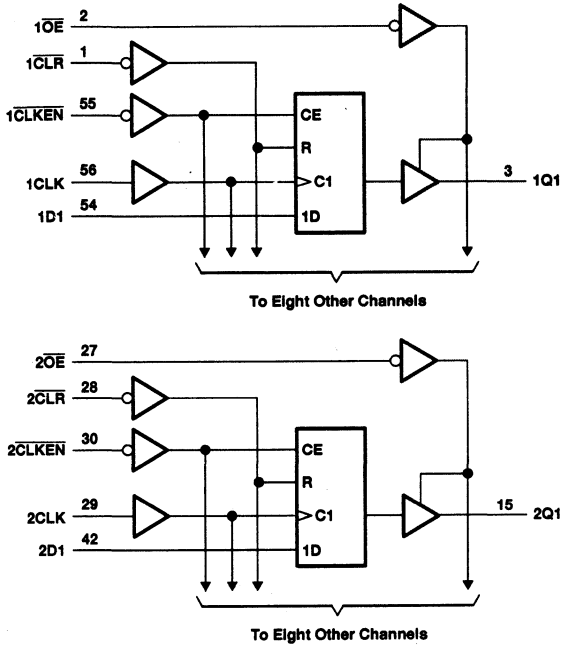
INPUTS					OUTPUT
$\overline{OE}$	$\overline{CLR}$	$\overline{CLKEN}$	CLK	D	Q
L	L	X	X	X	L
L	H	L	↑	H	H
L	H	L	↑	L	L
L	H	L	L	X	Q_0
L	H	H	X	X	Q_0
H	X	X	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O	30 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT162823A		SN74ABT162823A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–12		–12	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Input transition rise or fall rate			200	200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT162823A		SN74ABT162823A		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –1 mA	2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –1 mA	3			3		3		
	V_{CC} = 4.5 V	I_{OH} = –3 mA	2.4			2.4		2.4		
		I_{OH} = –12 mA	2*					2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 8 mA		0.4	0.8		0.8		0.65	V
		I_{OL} = 12 mA							0.8	
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	μA
I_{OZPU}	V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	μA
I_{OZPD}	V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	μA
I_{OZH}‡	V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	μA
I_{OZL}‡	V_{CC} = 5.5 V,	V_O = 0.5 V			–10		–10		–10	μA
I_{off}	V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	μA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	μA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V	–25	–55	–100	–25	–100	–25	–100	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			0.5		0.5		0.5	mA
		Outputs low			80		80		80	
		Outputs disabled			0.5		0.5		0.5	
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V			3.5						pF
C_o	V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL-voltage level rather than V_{CC} or GND.

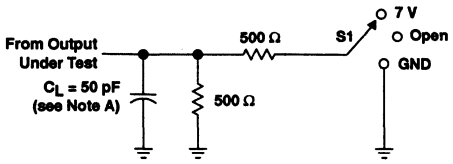
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C		SN54ABT162823A		SN74ABT162823A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	150	0	150	0	150	MHz
t_w	Pulse duration	$\overline{CLR}$ low	3.3		3.3		3.3		ns
		CLK high or low	3.3		3.3		3.3		
t_{su}	Setup time before CLK↑	$\overline{CLR}$ inactive	1.6		2		1.6		ns
		Data	2		3		2		
		$\overline{CLKEN}$ low	2.8		3.8		2.8		
t_h	Hold time after CLK↑	Data	1.2		1.2		1.2		ns
		$\overline{CLKEN}$ low	0.6		0.6		0.6		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

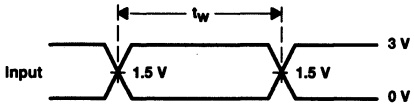
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT162823A		SN74ABT162823A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			150			150		150		MHz
t_{PLH}	CLK	Q	2.3	4.6	6.2	2.3	8.4	2.3	7.5	ns
t_{PHL}			2.8	4.6	6.1	2.8	7.1	2.8	6.7	
t_{PHL}	$\overline{CLR}$	Q	2.8	5	6.3	2.8	7.2	2.8	7	ns
t_{PZH}	$\overline{OE}$	Q	1.7	3.8	5	1.7	5.8	1.7	5.9	ns
t_{PZL}			3	5	6.1	3	7.2	3	7	
t_{PHZ}	$\overline{OE}$	Q	2.6	4.8	6.1	2.6	7.3	2.6	6.6	ns
t_{PLZ}			1.9	4.6	6.7	1.9	10.2	1.9	9	

PARAMETER MEASUREMENT INFORMATION

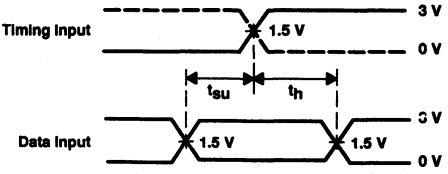


LOAD CIRCUIT

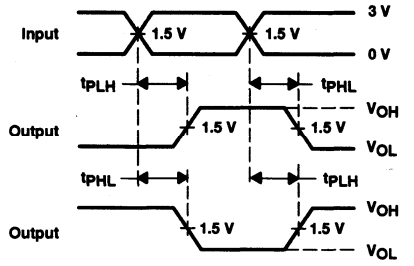
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



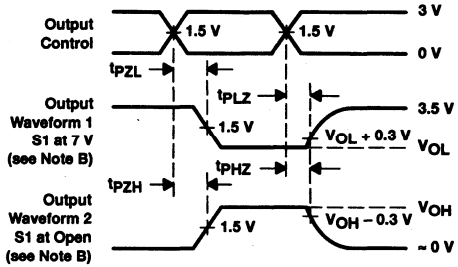
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



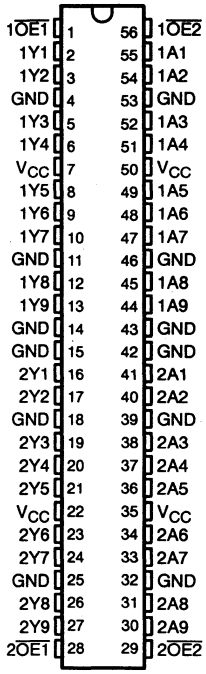
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT162825 . . . WD PACKAGE
SN74ABT162825 . . . DL PACKAGE
(TOP VIEW)



description

The 'ABT162825 are 18-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. These devices provide true data, and can be used as two 9-bit buffers or one 18-bit buffer.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all nine affected outputs are in the high-impedance state.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

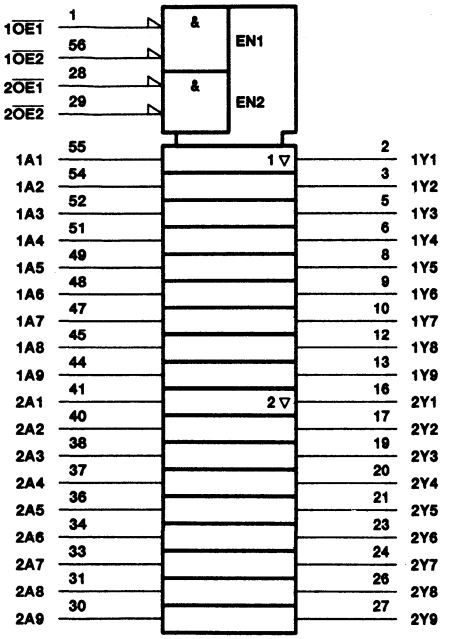
The SN54ABT162825 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT162825 is characterized for operation from –40°C to 85°C.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

FUNCTION TABLE
(each 9-bit buffer)

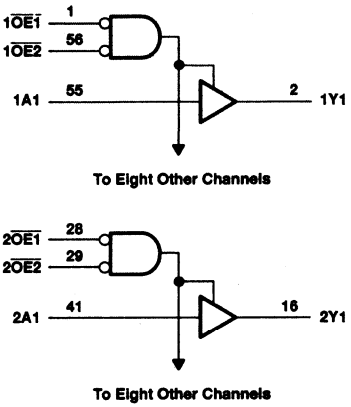
INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT162825		SN74ABT162825		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–12		–12	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Control inputs		9		9	ns/V
		Data inputs		10		10	
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		µs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

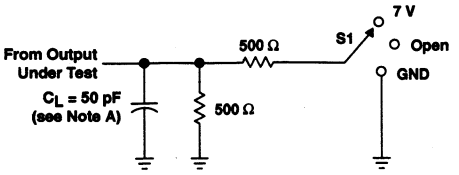
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT162825		SN74ABT162825		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –1 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –1 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –3 mA	2.4			2.4		2.4		
			I_{OH} = –12 mA	2			2		2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 8 mA		0.4	0.8		0.8		0.65	V
			I_{OL} = 12 mA							0.8	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–25	–75	–100	–25	–100	–25	–100	mA
I_{CC}	Outputs high	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND				2		2		2	mA
	Outputs low					32		32		32	
	Outputs disabled					2		2		2	
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1		1.5		1	mA
			Outputs disabled			0.05		1		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			8						pF

† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

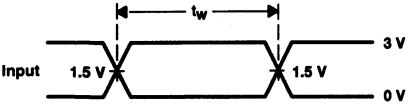
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT162825		SN74ABT162825		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2.1	3.6	1	4.1	1	3.9	ns
t_{PHL}			1.1	2.8	4.2	1.1	5	1.1	4.7	
t_{PZH}	$\overline{OE}$	Y	1.5	3.4	6.3	1.5	7.2	1.5	6.9	ns
t_{PZL}			1.6	3.5	7.3	1.6	6.6	1.6	6.3	
t_{PHZ}	$\overline{OE}$	Y	2.1	4.1	6.5	2.1	6.8	2.1	6.6	ns
t_{PLZ}			1.5	3.5	5.9	1.5	7.3	1.5	6.3	

PARAMETER MEASUREMENT INFORMATION

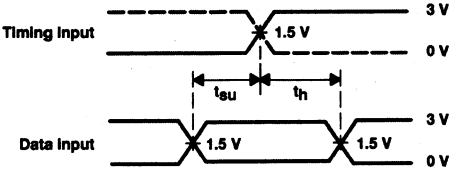


LOAD CIRCUIT

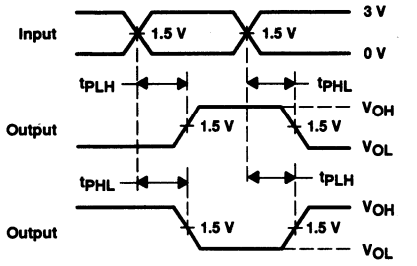
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



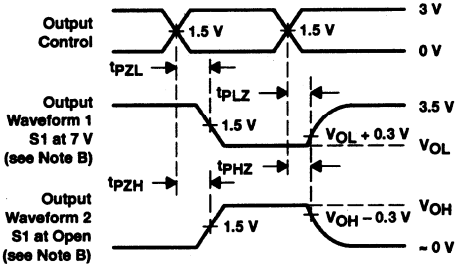
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



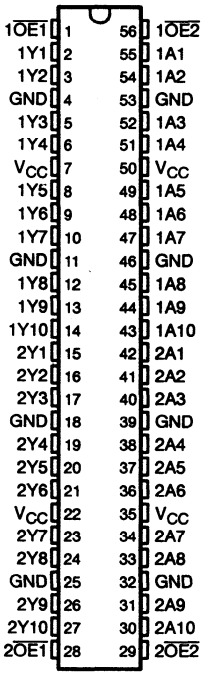
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **High-Impedance State During Power Up and Power Down**
- **State-of-the-Art *EPIC*-IIB™ BICMOS Design Significantly Reduces Power Dissipation**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package**

SN54ABT162827A . . . WD PACKAGE
SN74ABT162827A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The 'ABT162827A are noninverting 20-bit buffers composed of two 10-bit buffers with separate output-enable signals. For either 10-bit buffer, the two output-enable (1$\overline{OE1}$ and 1$\overline{OE2}$, or 2$\overline{OE1}$ and 2$\overline{OE2}$) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 10-bit buffer are in the high-impedance state.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT162827A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT162827A is characterized for operation from –40°C to 85°C.

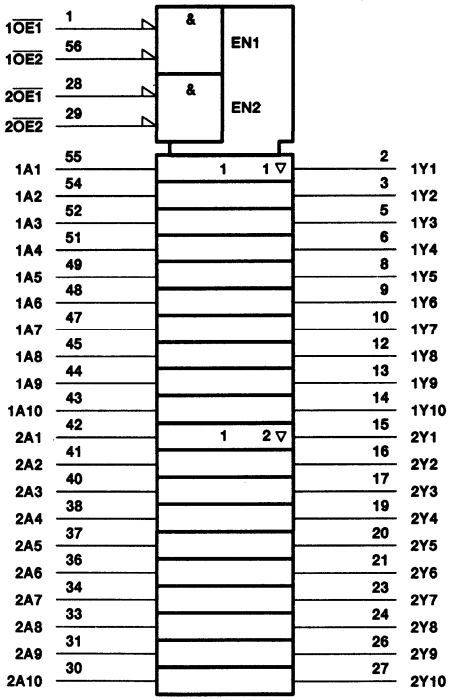
Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

FUNCTION TABLE
(each 10-bit buffer)

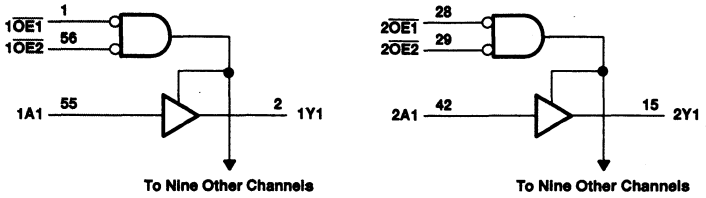
INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 81°C/W
DGV package ..... 86°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

		SN54ABT162827A		SN74ABT162827A		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–12		–12	mA
I_{OL}	Low-level output current		12		12	mA
$\Delta t/\Delta V$	Input transition rise or fall rate		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		µs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

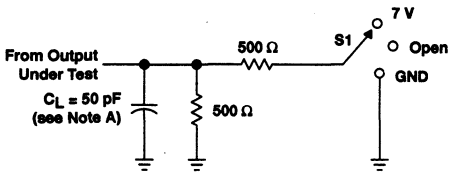
PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT162827A		SN74ABT162827A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –1 mA	3.35			3.35		3.35		V
		V_{CC} = 5 V,	I_{OH} = –1 mA	3.85			3.85		3.85		
		V_{CC} = 4.5 V	I_{OH} = –3 mA	3.1			3.1		3.1		
			I_{OH} = –12 mA	2.6			2.6		2.6		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 8 mA		0.4	0.8		0.8		0.65	V
			I_{OL} = 12 mA							0.8	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}§		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}§		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	µA
I_{off}		V_{CC} = 0, V_I or V_O ≤ 4.5 V				±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–25	–75	–100	–25	–100	–25	–100	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			32		32		32	
			Outputs disabled			2		2		2	
ΔI_{CC}#	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1		1.5		1	mA
			Outputs disabled			0.05		1		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			4						pF
C_o		V_O = 2.5 V or 0.5 V			7						pF

† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

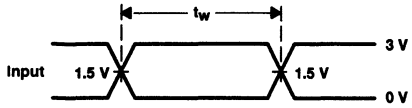
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT162827A		SN74ABT162827A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2.1	3.6	1	4.1	1	3.9	ns
t_{PHL}			1.1	2.8	4.2	1.1	5	1.1	4.7	
t_{PZH}	$\overline{OE}$	Y	1.5	3.4	6.3	1.5	7.2	1.5	6.9	ns
t_{PZL}			1.6	3.5	5.3	1.6	6.6	1.6	6.3	
t_{PHZ}	$\overline{OE}$	Y	2.1	4.1	6.5	2.1	6.8	2.1	6.6	ns
t_{PLZ}			1.5	3.5	5.9	1.5	7.3	1.5	6.3	

PARAMETER MEASUREMENT INFORMATION

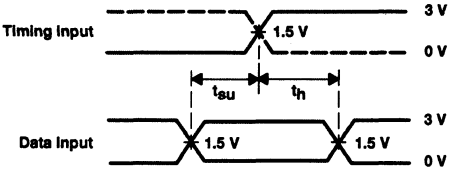


LOAD CIRCUIT

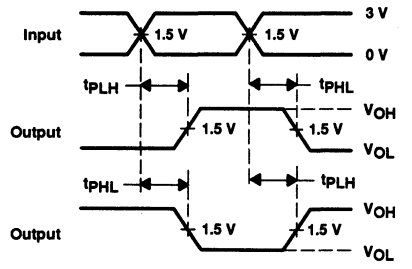
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



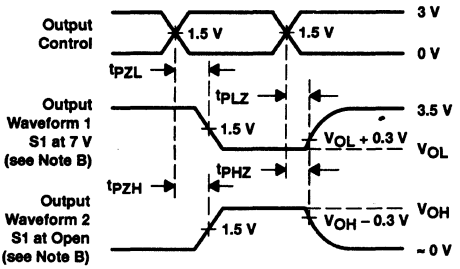
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



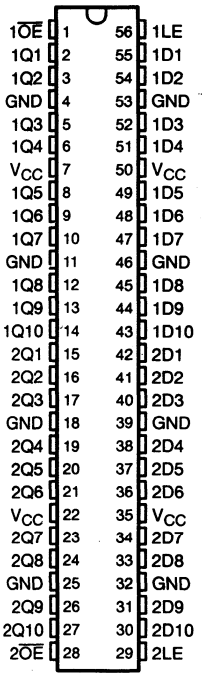
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

- **Members of the Texas Instruments *Widebus*™ Family**
- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art *EPIC-IIB*™ BICMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Impedance State During Power Up and Power Down**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT162841 . . . WD PACKAGE
SN74ABT162841 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

These 20-bit transparent D-type latches feature noninverting 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The 'ABT162841 can be used as two 10-bit latches or one 20-bit latch. While the latch-enable (1LE or 2LE) input is high, the Q outputs of the corresponding 10-bit latch follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable ($1\overline{OE}$ or $2\overline{OE}$) input can be used to place the outputs of the corresponding 10-bit latch in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

The outputs, which are designed to sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

$\overline{OE}$ does not affect the internal operation of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

description (continued)

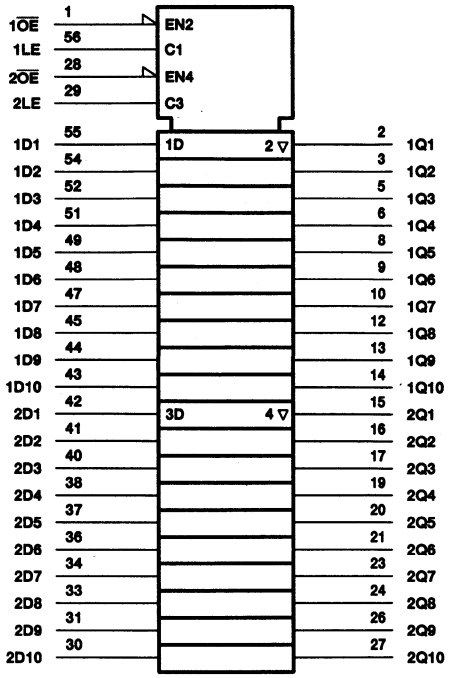
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT162841 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT162841 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 10-bit latch)

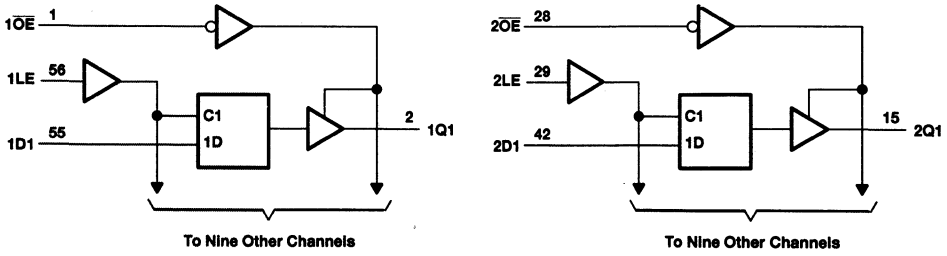
INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} ..... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) ..... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O ..... –0.5 V to 5.5 V
Current into any output in the low state, I_O ..... 30 mA
Input clamp current, I_{IK} ($V_I < 0$) ..... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) ..... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package ..... 86°C/W
DL package ..... 74°C/W
Storage temperature range, T_{stg} ..... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT162841		SN74ABT162841		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–12		–12	mA
I_{OL}	Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT162841		SN74ABT162841		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = −18 mA			−1.2		−1.2		−1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = −1 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = −1 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = −3 mA	2.4			2.4		2.4		
			I_{OH} = −12 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 8 mA		0.4	0.8		0.8		0.65	V
			I_{OL} = 12 mA			0.55*				0.8	
V_{hys}					100						mV
I_I		V_{CC} = 0 to 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZPU}‡		V_{CC} = 0 to 2.1 V, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZPD}‡		V_{CC} = 2.1 V to 0, V_O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	µA
I_{OZH}		V_{CC} = 2.1 V to 5.5 V, V_O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	µA
I_{OZL}		V_{CC} = 2.1 V to 5.5 V, V_O = 0.5 V, $\overline{OE}$ ≥ 2 V				−10		−10		−10	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_O§		V_{CC} = 5.5 V,	V_O = 2.5 V	−25	−75	−100	−25	−100	−25	−100	mA
I_{CC}	Outputs high	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND				0.5		0.5		0.5	mA
	Outputs low					89		89		89	
	Outputs disabled					0.5		0.5		0.5	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

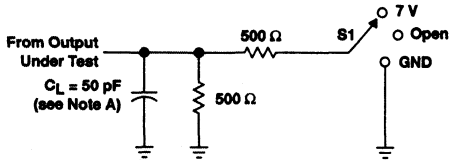
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V_{CC} = 5 V, T_A = 25°C		SN54ABT162841		SN74ABT162841		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high or low	4		4		4		ns
t_{su}	Setup time, data before LE↓	0.8		0.8		0.8		ns
t_h	Hold time, data after LE↓	1.8		1.8		1.8		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

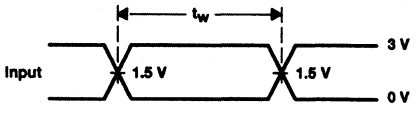
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT162841		SN74ABT162841		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	2.1	3.5	4.5	2.1	5.7	2.1	5.2	ns
t_{PHL}			3	4.3	5.3	3	6.2	3	6	
t_{PLH}	LE	Q	2.1	3.5	4.5	2.1	5.6	2.1	5.4	ns
t_{PHL}			2.8	4.1	5.1	2.8	6.1	2.8	5.8	
t_{PZH}	$\overline{OE}$	Q	2	3.6	4.7	2	5.8	2	5.7	ns
t_{PZL}			3	4.6	5.7	3	6.7	3	6.5	
t_{PHZ}	$\overline{OE}$	Q	2.6	4.3	5.7	2.6	6.6	2.6	6.5	ns
t_{PLZ}			2.2	3.6	5.8	2.2	8.4	2.2	7.1	

PARAMETER MEASUREMENT INFORMATION

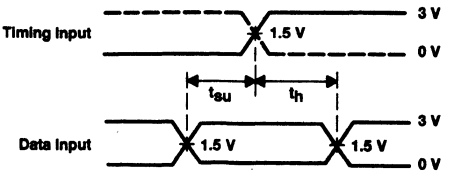


LOAD CIRCUIT

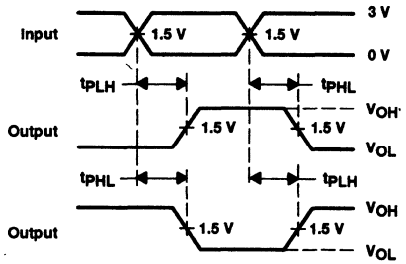
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



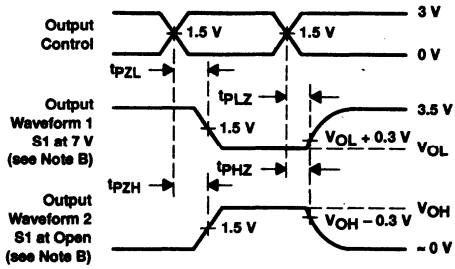
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

Contents

ABT Enables Optimal System Design

SCBA001A
March 1997

TEXAS INSTRUMENTS

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Contents

List of Illustrations

Introduction

As operating frequencies of microprocessors increase, the time allotted for memory access, arithmetic computation, or similar operations decreases. With this in mind, a new series of Advanced Bus-Interface Logic (ABIL) products developed with Texas Instruments (TI) submicron Advanced BiCMOS Technology (ABT) process assumes a prominent role as the key high-performance logic needed in today's workstation, personal and portable computer, and telecom systems. The goal of this family of products is to provide system designers a bus-interface solution combining high-drive capability, low power consumption, signal integrity, and propagation delays small enough to appear transparent with respect to overall system performance. Fine-pitch package options simplify layout, reduce required board space, and decrease overall system costs. Novel circuit-design techniques add value over competitive solutions.

Trends Important for Today's System Designer

Modern system designers face many complex challenges in meeting their design goals. The trends toward (need for) faster cycle times, lower power consumption, smaller footprints, greater reliability, and lower total system cost combine to put ever-increasing pressure on today's system designer.

The need for faster cycle time traditionally has been addressed by the microprocessor manufacturer. Clock and microprocessor frequencies have increased steadily with each succeeding product generation. The most advanced RISC processors in development are touting frequencies of about 200 MHz. For production systems, it is not unusual for processors to run on the order of 50 MHz and above. Increasing clock and microprocessor frequencies are now beginning to put pressure on surrounding memory and logic to make greater contributions in reducing overall system cycle times and improving overall system performance.

Higher-performance systems require the designer to focus on total system power requirements. Faster systems traditionally require more power, which often means more costly solutions. Power costs money to supply, and heat buildup due to this power costs money to remove. Also, excess power consumption adversely affects reliability due to the increase in the junction temperature of the silicon components. Lower-power devices reduce requirements for larger power supplies and high-cost cooling techniques, and could lead to smaller system packaging.

Occurring in parallel with demands for increased system performance and reduced system power consumption is demand to house systems in smaller cases, boxes, chassis, and cabinets. This miniaturization requires that each system component be optimally laid out in silicon, packaged, and mounted on the printed-circuit board (PCB).

Speed, power, size, cost, and reliability are all parameters by which system and end-equipment success are measured. Semiconductor manufacturers must be sensitive to these parameters and be able to provide well-defined and well-designed products to meet these needs.

Advanced Bus-Interface Logic (ABIL) as the System Bus Interface

Semiconductor vendors are required by system design houses to provide new products that are faster, consume less power, exist in smaller packages, and present a lower relative cost than their predecessors. Since the early 1970s, many different logic-product technologies have attempted to meet these demands.

Early logic-product technologies often forced the system designer to make tradeoffs. As shown in Figure 1, speed and power were the most typical design goals traded off. Solutions such as Schottky or HCMOS, respectively, offered high speed at the expense of low power or low power at the expense of high speed. In a typical system application, this logic technology is used between only a few system blocks, such as a simple 8-MHz processor, a slow 256K DRAM, and a local TTL bus. Their functional role was little more than small-scale integration (SSI) or medium-scale integration (MSI). Despite these shortcomings, early logic technologies thrived because they were inexpensive and readily available.

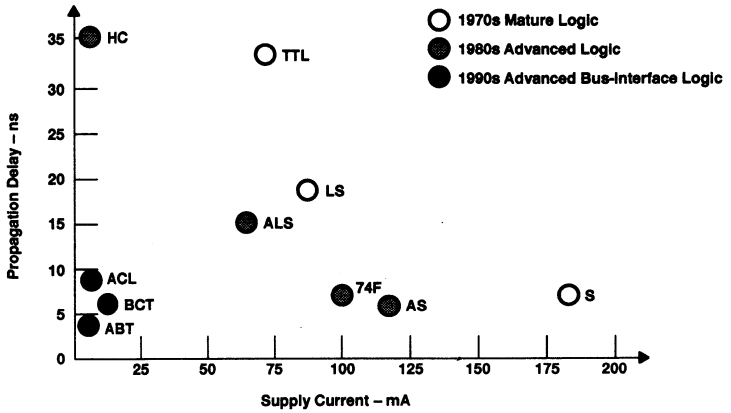


Figure 1. ABT Assumes Optimal Position

Cycle-time requirements for interface logic vary as a function of microprocessor and clock speed. In an 8-MHz system, the total system cycle available for completion of all operations is 250 ns. This can be roughly budgeted into 160 ns for the memory access, 45 ns for processor setup, and 45 ns for the interface logic (including signal propagation across PCB traces). With 45 ns available for interface, a forgiving, low-performance technology such as low-power Schottky or HCMOS can be utilized.

The situation changes dramatically when system speeds increase to 45 or 50 MHz. At 45 MHz, only 44 ns of total cycle time is available to complete all operations. Now, more expensive memories are needed with access times in the 20-ns range. Microprocessor setups can only be 8 ns. This leaves only 16 ns for interface and signal-trace propagation delay. The interface cycle time is a much higher percentage of the total system cycle time at 45 MHz than at 8 MHz.

As cycle-time requirements shrink, each nanosecond becomes critical in meeting the total system budget. The system designer has the option of using higher-performance memories, processors, or interface logic in squeezing additional nanoseconds out of the system delay. There is great demand for using interfacing logic to meet these budget needs because typically it is much less expensive for the designer to use than higher-performance memories or processors.

In light of decreasing total system cycle-time requirements, early logic technologies gave way to faster technologies. Significant gains made since the Schottky and HCMOS days result in products that no longer force the system designer into a tradeoff box. New-product development in the area of complex memories, processors, and ASICs has led the way for an equal, if not greater, acceleration in new-product development for advanced digital-logic products.

This development has propelled logic up from the ranks of *glue* status, used to fill in design gaps around the other major system blocks, to its new position as the system bus interface. ABIL products are now responsible for controlling the signals between the backplane buses and the other major system design blocks. They have become a major system design block in their own right, exerting significant influence over the performance of the final design.

In a modern-day system, ABIL products are likely to connect many major system design blocks, including application-specific parallel processors, 4M DRAMs, fast-cache SRAMs, and complex ASIC gate arrays/standard cells. The task of this new breed of advanced logic is to effectively transceive the address, data, and control signals of these integrated-circuit elements to and from heavily loaded TTL/CMOS/BTL system backplanes.

A wide variety of industry-standard and proprietary backplane specifications add to the difficulty of the task. At the low end of the scale, exhibiting data-transfer rates in the range of 10 to 20 Mbytes/s, are the PC-, AT-, and EISA-type buses. For midrange server and graphics-workstation applications, the 50- to 100-Mbytes/s data-transfer-rate range of Multibus II and microchannel-type buses is typical. High-end server and mainframe computer applications require the ≥ 100-Mbytes/s data-transfer rates of Futurebus+-type buses. Transceivers connecting to each of these backplanes must provide very high-drive current capability to effectively and reliably migrate signals across. ABIL products from TI uniquely address this need.

Enablers to Continuous New-Product Development

Reduction in minimum process dimension, enhanced value-added circuit design techniques, utilization of fine-pitch packaging, and incorporation of lower-power supply voltages are the most important enablers to continuous new development for logic products.

The minimum process dimension represents the width of the transistor-gate region and gives an indication of the switching speed of the transistor. In general, the smaller the minimum process dimension, the faster the transistors switch. An added advantage of reducing the minimum process dimension is the gain in gate density that can be achieved. A gain in gate density results in increased device functionality without a corresponding increase in silicon die area. Currently, state-of-the-art high-volume-production logic processes consider a 0.8-μm minimum process dimension. However, work is ongoing to prototype more advanced processes characterized by 0.6-, 0.5-, and 0.35-μm minimum process dimensions.

Enhanced value-added circuit-design techniques greatly increase the functionality of a logic device as well as improve its performance. These techniques often eliminate the need for the designer to utilize discrete components such as resistors, capacitors, and diodes because these are built into the silicon device itself. Additionally, optimizations in I/O or core circuitry can positively affect speed and power performance.

An aggressive drive exists to convert classic through-hole package approaches to totally above-board surface-mount approaches. Occurring in parallel is a drive to upgrade existing surface-mount packages with finer pin-to-pin pitches so as to minimize total package area. However, with smaller packages comes increased reliance on thermal-management techniques. The increased difficulty in removing heat from the smaller packages can preclude the use of inexpensive plastic packages. The need for ceramic or other alternatives would act to drive up design costs.

Finally, system designers are beginning to drive the semiconductor industry to move below 5 V as the baseline for power supplies. The migration to lower voltages, such as 3.3 V, enhances the reliability of advanced process technologies exhibiting minimum process dimensions of 0.6 μm or lower. The need for low-voltage memory and processor product interface, lower device-generated noise levels, lower power consumption, and increased battery life for unregulated portable systems accelerate the demand for 3.3-V logic. New 3.3-V logic opportunities will emerge as system designers continue to rely on advanced process technologies.

What Is Advanced BiCMOS Technology (ABT)?

Advanced BiCMOS Technology (ABT) is available today in products from TI to aid designers doing high-performance bus management. It is currently available in many different product options, including 8-bit octal, 16-, 18-, and 20-bit Widebus™, and 32- and 36-bit Widebus+™ versions.

At TI, ABT evolved from an earlier 1.5-μm BiCMOS process. It was designed to provide speeds equivalent to existing advanced bipolar solutions but with 90% less device power. This standard BiCMOS process introduced high-performance, lower-power, bus-interface products to the marketplace two years ahead of the nearest competitor. Since its bus-interface introduction in 1987, TI has utilized BiCMOS and advanced BiCMOS in products such as mixed-signal integrated circuits, high-performance gate arrays, high-speed cache tags, and application-specific processors such as the SuperSPARC™.

ABT employs a submicron 0.8-μm minimum process dimension. It combines elements of both bipolar and CMOS circuit/process technologies onto a single silicon chip. ABT offers the system designer the best combination of high speed, high drive, and low power consumption in the industry. As shown in Figure 1, ABT provides a performance point closer to the origin of the speed/power graph than any other logic technology available. Specifically, ABT is based on a CMOS core-circuit structure with an NPN bipolar output transistor module added. This means adding about four additional masks to the CMOS process. The current single NPN transistor output structure of ABT has been optimized for 5-V operation.

Simplified input and output stages of an ABT transceiver are shown in Figure 2. The inputs are designed to offer TTL-compatible levels with guaranteed switching between a V_{IH} minimum of 2 V and a V_{IL} maximum of 0.8 V. These inputs are implemented with CMOS circuitry; therefore, they offer characteristic high impedance for low leakage and low capacitance for minimal bus loading. The CMOS supply voltage of the input stage is dropped by diode D1 and transistor Q1, centering the threshold around 1.5 V. When inputs are in the low state, Q_r raises the voltage of source Q_p up to the rail, ensuring proper operation of the feedback stage. This stage provides about 100 mV of input hysteresis, increasing noise margins and reducing oscillations.

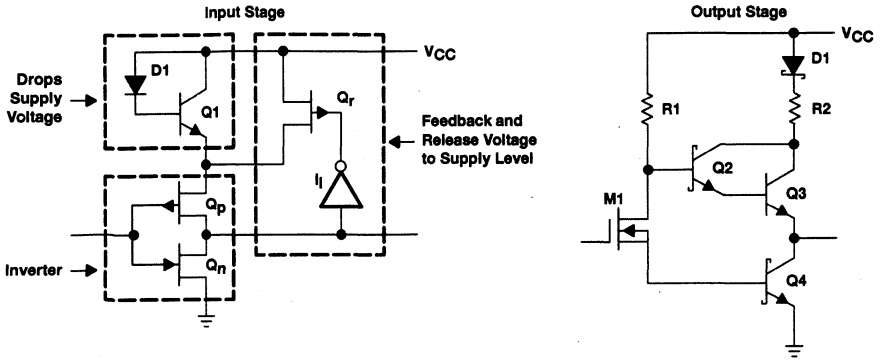


Figure 2. ABT Input/Output Circuit Structure

ABT outputs utilize bipolar circuitry to provide the high speed and drive necessary for a bus interface. A major advantage of using bipolar circuitry in the output stage is the reduced voltage swing, which lowers ground noise, improves signal integrity, and reduces dynamic power consumption. In Figure 2, M1 acts as a current switch that drives the outputs low when conducting current from R1 through to the base of Q4. The base of Q2 is pulled low, turning off the upper output. For a low-to-high output transition, M1 turns off and current through R1 charges the base of Q2. As Q2 goes high, the Darlington pair, Q2 and Q3, turns on. With its supply of base current now cut off, Q4 turns off and the output transition switches low to high. R2 limits output current in the high state and D1 is a blocking diode preventing current flow in power-down applications.

By virtue of its small minimum process geometry, tight metal pitch, and shallow junctions, ABT can provide strong output drive currents (sink currents specified at 64 mA and source currents specified at 32 mA) and low parasitic capacitances. As a result of these enhancements, internal propagation delays are very fast and very well behaved. Figure 3 shows that typical propagation delays are on the order of 2–3 ns across the operating temperature range. This excellent consistency allows ABT to be specified over the industrial temperature range of –40°C to 85°C. Figure 3 also shows that ABT performance is very well behaved across capacitive load and multiple-output switching conditions.

Maximum propagation delays for ABT are as low as 4–5 ns, depending on the device type and propagation path. Table 1 compares the data sheet maximums of several ABT 16-bit Widebus™ transceiver devices with competing FCTB/C CMOS and 74F/ALS bipolar solutions. It is clear from both Figure 3 and Table 1 that ABT is the system designer's best choice for bus-interface applications that require consistent speed performance for many different conditions.

From a power (current) consumption standpoint, the use of bipolar in the output stage is advantageous for two reasons. First, the voltage swing is less than that of a CMOS output. The power consumed when charging or discharging internal circuit capacitances and the external load capacitance is reduced. Second, the bipolar transistors are capable of turning off more efficiently than CMOS transistors. The wasteful flow of current from V_{CC} to GND is reduced. Although bipolar does tend to have a high static power consumption, its lower dynamic power consumption allows for better overall power performance at high frequencies than either pure bipolar or CMOS. This is because the dynamic power component makes up the majority of a device's overall power consumption.

The ABT maximum high-impedance supply currents (I_{CCZ}) range from about 50 µA for 8-bit octals to about 2–3 mA for 16-bit Widebus™ products. Maximum dynamic supply currents (I_{CCL}) range from about 30 mA for 8-bit octals to about 34 mA for 16-bit Widebus™ products. Power on demand, an enhanced circuit design improvement to the bipolar output stage on new ABT product families, reduces dynamic current consumption levels by up to 50%. High-impedance and dynamic supply-current goals for the new 32-/36-bit Widebus+™ family are 500 µA and 60 mA, respectively.

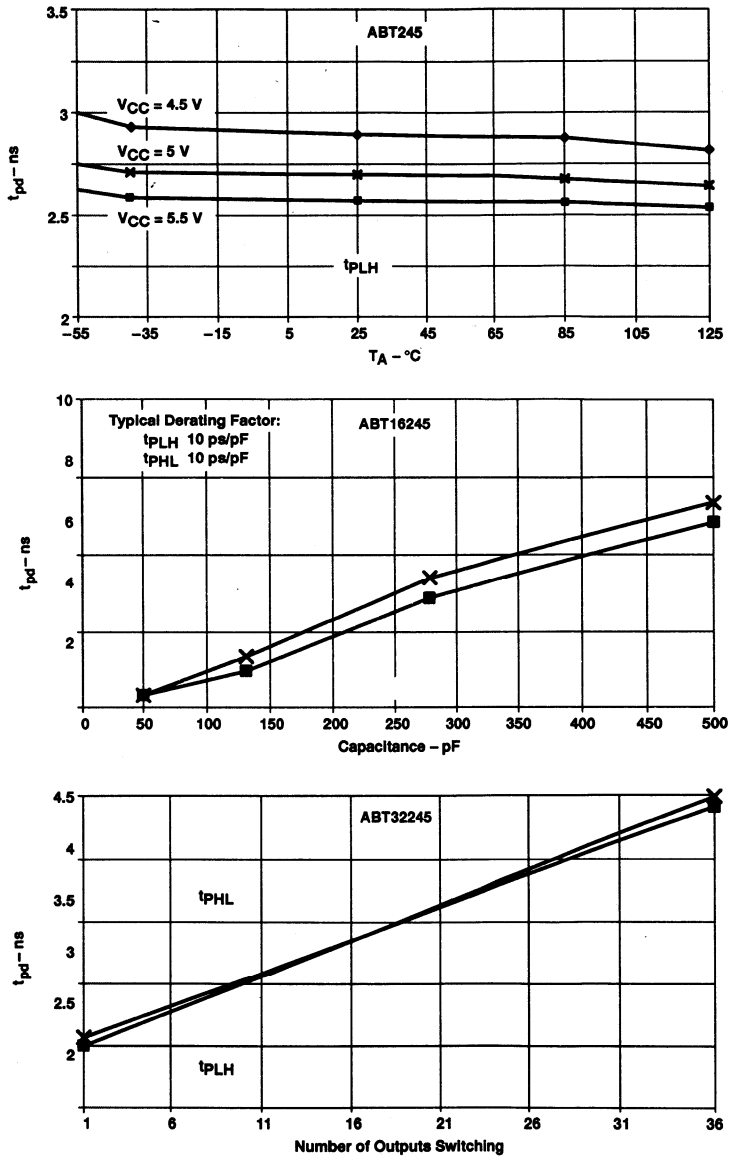
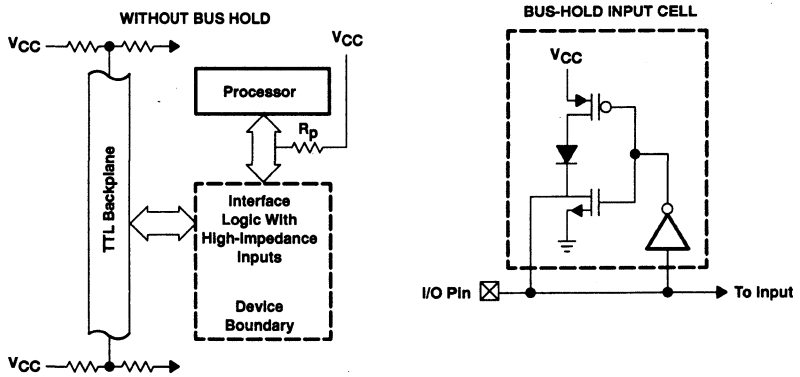


Figure 3. ABT Process Provides Consistency

Table 1. ABT Is the Speed Benchmark

REGISTERED TRANSCEIVER WITH CLKEN	ABT16952 (ns)	29FCT52C (ns)	F2952 (ns)
t_{pd} CLK to A/B	4.5	6.3	9
$t_{pd(en)}$ $\overline{OE}$ to A/B	6	7	10
$t_{pd(dis)}$ $\overline{OE}$ to A/B	5.5	6.5	9
TRANSCEIVER WITH PARITY	**ABT16657 (ns)**	**ABT657 (ns)**	**F657 (ns)**
t_{pd} A to B	4.3	5.5	8
t_{pd} A to PARITY	6.7	11.3	16
t_{pd} B to $\overline{ERR}$	6.7	15.7	22.5
REGISTERED TRANSCEIVER WITH PARITY	**ABT16833 (ns)**	**FCT833B (ns)**	**ALS29833 (ns)**
t_{pd} A to B	4.3	7	10
t_{pd} A to PARITY	6.7	10.5	15
t_{pd} CLK to $\overline{ERR}$	4.6	15	16

Bus hold, as shown in Figure 4, is another example of an enhanced, value-added circuit design technique available on new ABT product families. The bus-hold cell provides for a small holding current of 100 µA to be delivered to I/O pins configured as inputs left unused or floating. This current latches the last known input state to a valid logic level. Floating input conditions are common to CMOS backplanes or device bus-interface situations where driving entities are periodically required to be in 3 state. Bus-hold cells eliminate passive pullup (to V_{CC}) or pulldown (to GND) termination resistors necessary to prevent application problems or oscillations. External provision for these resistors by the system designer consumes board area, increases bus capacitance, contributes to bus loading, and lowers system performance. The bus-hold feature is particularly effective when offered on products with a lot of I/O capability such as 32-/36-bit Widebus+™ devices.



- Holds the last known state of the input
- Provides for ±100 µA of holding current at 0.8 V and 2 V
- Bus-hold current does not load down the driving output at valid logic levels
- Negligible impact to input/output capacitance (0.5 pF)
- Eliminates the need for external resistors on unused or floating input/output pins

Figure 4. Bus-Hold Circuit and Benefits

Fine-Pitch Packaging Shrinks ABT Device Size

As the push for smaller system sizes becomes intense, the system designer will require the logic manufacturer to house high-performance silicon in increasingly smaller packages. Most notably, the system designer has been leveraging the advantages of plastic-leaded chip carriers (PLCCs) and small-outline integrated circuits (SOICs).

Both PLCC and SOIC packages provide a gull-wing lead profile. Both utilize 1.27-mm pin-to-pin pitch spacing. The reduced pitch offers a major space improvement over bulky plastic dual-in-line (PDIP) through-hole packages. The major difference between PLCC and SOIC is philosophical. The PLCC has pins on all four sides (arranged either in square or rectangular configuration) while the SOIC has pins on only two sides (arranged in flow-through configuration).

In spite of the advantages of PLCC and SOIC, system designers are beginning to specify surface-mount packages with finer pitch values to keep their end equipments competitive in the marketplace or to avoid falling behind more aggressive rivals. Such fine-pitch versions available in volume today offer improvements in the pin-to-pin pitch down to 0.635 mm. More advanced fine-pitch alternatives exhibiting characteristic pitches of 0.5, 0.4, and 0.3 mm are on the horizon.

The plastic quad flat package (PQFP) is a fine-pitch version of the PLCC package. It offers a 0.635-mm pitch and is widely used for microprocessors, ASICs, or other custom devices. The 44-pin PQFP is the smallest used in volume, while the largest versions provide over 200-pin capability. However, for the system designer using ABIL products, it is advantageous to combine the fine-pitch capability of the PQFP with the two-sided dual-in-line design of the SOIC.

SOICs have evolved in two distinct paths to meet this need. The first path considers reducing the surface area and pin pitch of the package while keeping the pin count and bit density constant. The second path considers increasing the bit density of the package by increasing pin count and reducing pin pitch. Figure 5 clearly shows both of these migratory paths starting from the standard octal SOIC package in the upper left corner.

Package size reductions are shown from top to bottom in Figure 5, with each succeeding reduction occupying a new row at constant bit density and pin count. Bit-density and pin-count increases are shown horizontally across Figure 5.

There are five new fine-pitch packages represented in Figure 5. Four of these offer a density-upgrade path for the SOIC. The fifth is a new package offering a density upgrade for the PQFP. All of these packages were developed and standardized exclusively for high-performance ABIL ABT products by TI.

The shrink small-outline package (SSOP) is available in two worldwide standard form factors. The first, approved by the Joint Electronic Device Engineering Council (JEDEC), allows for 16-, 18-, or 20-bit I/O functions in a package roughly the same size as the octal SOIC. The pin pitch for the JEDEC SSOP is 0.635 mm. The JEDEC SSOP is available in a 48-pin version for the basic 16-bit driver and transceiver functions and in a 56-pin version for complex 16- to 20-bit transceiver functions. The very popular ABT Widebus™ family uses the JEDEC-approved SSOP.

The second form factor, approved by the Electronics Industry Association of Japan (EIAJ), allows for 8- and 9-bit I/O functions in a package about 40% of the size of the octal SOIC. The pin pitch for the EIAJ SSOP is 0.65 mm. The EIAJ SSOP is available in a 20-pin version for basic ABT 8-bit driver and transceiver functions and in a 24-pin version for complex ABT 8- and 9-bit transceiver functions.

The bottom row of Figure 5 represents the third form-factor upgrade to the SOIC available from TI. The thin shrink small-outline package (TSSOP) is EIAJ approved and offers a reduced thickness (height) specification of 1.1 mm. The pin pitch of the EIAJ TSSOP is 0.65 mm (the body width is 4.4 mm). The TSSOP is compatible with Type I and Type II card physical requirements of the Personal Computer Memory Card International Association (PCMCIA). TSSOP offers the smallest package size available for 20- and 24-pin drivers and transceivers. For denser memory arrays, TSSOP facilitates front and back side mount in under 3.3-mm thickness specified by PCMCIA if card thicknesses are kept under 1 mm.

For wide-word applications with extreme space and height restrictions, TI offers Widebus™ devices in a new package called the Shrink Widebus™. Available in 48- and 56-pin versions, this new package has a 1.1-mm maximum height, a 6.1-mm body width, and a 0.5-mm lead pitch. The Shrink Widebus™ package, developed by TI, is registered with the EIAJ, meets the requirements of the PCMCIA, and occupies 40% less board area than the standard JEDEC SSOP.

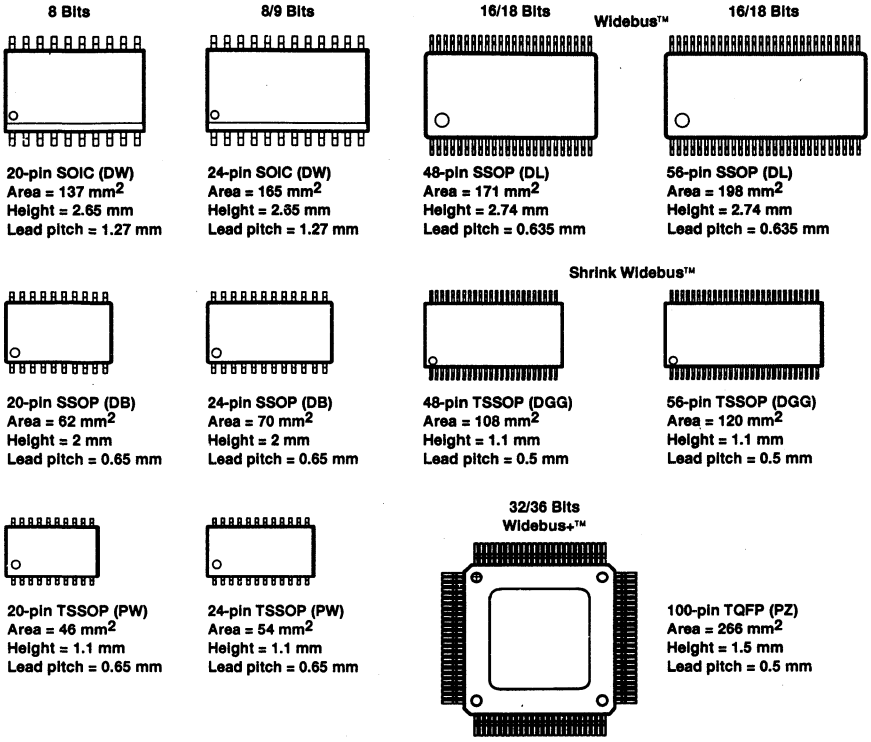


Figure 5. Fine-Pitch Package Options for ABT

The EIAJ thin quad flat package (TQFP) provides the density upgrade path for the PQFP. This 100-pin package allows single-chip 32- and 36-bit I/O solutions in over 50% less area than with octal SOIC connections. The pin pitch for the EIAJ TQFP is 0.5 mm, which is the smallest in production today. The reduced pitch of the TQFP offers a 35% area reduction over 100-pin PQFP solutions. The new 32- and 36-bit ABT Widebus+™ family, announced at the BUSCON '92 West trade show in Long Beach, California, uses the 100-pin TQFP.

All of the fine-pitch package options are superior for space-saving applications. The JEDEC SSOP and EIAJ TQFP are superior in several other areas as well. The JEDEC SSOP incorporates a flow-through architecture where input and output pins each have their own dedicated side of the package. Flow-through pinouts offer the system designer a very easy route path for signal traces.

A standard SOIC octal package can afford only one GND pin for every eight I/Os. This ratio improves to 2:1 and 3:1 for JEDEC SSOP and EIAJ TQFP, respectively. Both the JEDEC SSOP and the EIAJ TQFP provide multiple V_{CC} and GND pins distributed along the sides. The larger number of GND pins and distribution of these pins results in less noise and allows for less propagation delay than octal functions. As a result, ABT octals, ABT Widebus™, and ABT Widebus+™, all typically exhibit less than 1 V of noise, even though the maximum number of switched outputs increases from 8 bits to 18 bits to 36 bits with each respective family.

As package area decreases, the thermal impedance of the package to the ambient environment increases. Thermal impedance represents the ability of a package to dissipate heat. The higher the thermal impedance, the more difficulty the package has in dissipating heat. The higher thermal impedances of fine-pitch packages require additional attention and care from the system designer. Proper thermal management techniques as well as proper power dissipation guidelines must be used to ensure operation. Fortunately, the low power of ABIL ABT products is more conducive to a fine-pitch packaging approach than competitive CMOS solutions.

ABT Products Provide End-Equipment-Specific Solutions

Combining previously discussed state-of-the-art elements of the ABT process with its numerous advanced fine-pitch package options and enhanced circuit-design features yields a very impressive portfolio of new products. These new products effectively serve the distinct needs of the workstation, personal and portable computer, and telecom end-equipment markets.

Table 2 categorizes the entire ABIL product spectrum built with the ABT process technology. These families offer features and benefits dedicated to specific markets and industry standards. Figure 6 shows the relationships of these features and benefits.

Table 2. ABT Products and Features

NAME	EXAMPLE PART NUMBER	KEY FEATURES	NO. OF BITS	PACKAGES	MAX PROP DELAY (ns)	I_{CCZ} (mA)	I_{OL} (mA)	I_{OH} (mA)	TARGET APPLICATIONS
ABT	SN74ABT245A	0.8-µm process, –40°C/85°C	8, 9, 10	DIP, SOIC, SSOP (EIAJ), TSSOP	3.6	0.25	64	32	High-speed bus interface, PC, EWS, telecom
ABT Widebus™	SN74ABT16245A	Flow-through pinouts, low noise	16, 18, 20	SSOP (JEDEC), TSSOP	4.0	0.19	64	32	Higher performance, space-conscious applications
ABT Widebus+™	SN74ABT32245	Bus-hold cell, power on demand	32, 36	TQFP (EIAJ)	5.2	2	64	32	Single-chip 32-bit interface
IWS Drivers	SN74ABT25245	Enhanced output drivers	8	DIP, SOIC	4.3	0.5	188	96	25-Ω incident-wave switching
Memory Drivers	SN74ABT2245	Series output-damping resistors	8, 10, 11, 12, 16	DIP, SOIC, SSOP (EIAJ), SSOP (JEDEC)	4.5	0.25	12	12	Low noise, high-reliability driving, memory interface
Futurebus+	SN74FB2031	BTL port, 2-ns minimum edge rate	8, 9, 18	PQFP, SSOP (JEDEC), TQFP (EIAJ)	7.6	10	100	3	IEEE 896.1 backplane interface
BTL Drivers	SN74FB2033A	BTL-TTL-level translation	8, 9	PQFP, SSOP (JEDEC)	6.1	10	100	3	IEEE 1194.1 backplane interface
SCOPE™	SN74ABT8245	Testability, built-in self-test	8, 16, 18	DIP, SOIC, SSOP (EIAJ), SSOP (JEDEC), TQFP (EIAJ)	4.7	0.05	64	32	IEEE 1149.1 backplane interface
LVT	SN74LVT245B	3.3-V V_{CC}, mixed mode, bus hold	8	SOIC, SSOP, TSSOP	4	0.19	64	32	Battery portables, notebook computers, POS terminals
LVT Widebus™	SN74LVT16245A	3.3-V V_{CC}, mixed mode, bus hold, power on demand	16, 18	SSOP (JEDEC), TSSOP	4.1	0.19	64	32	Workstations, portable computers

For high-performance engineering workstation and server markets, the ABT Widebus™ and Widebus+™ families provide the highest integration and performance. They are necessary to connect the most demanding CISC/RISC microprocessors to the most heavily loaded, high-frequency backplanes.

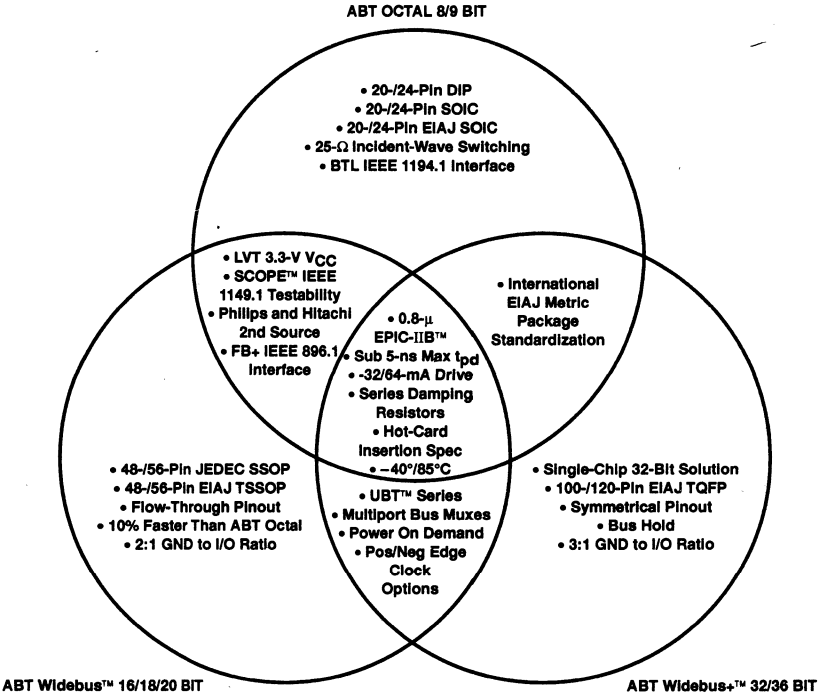


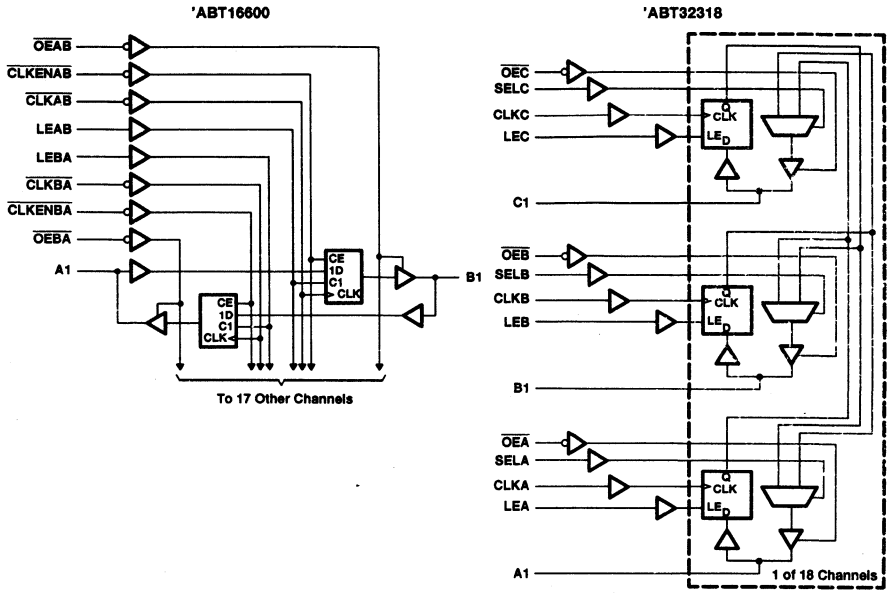
Figure 6. ABT Products and Features

The Universal Bus Transceiver (UBT™) is unique in the industry because it can be operated in several distinct bus-interface modes. Each package contains D-type latches and flip-flops. Flexible control-logic options provide for output-enable, latch-enable, clock, and clock-enable combinations.

UBT™s can be configured as transparent, data-flow-through transceivers (like the dedicated '245 function), latch-enabled transceivers (like the dedicated '543 function), clocked registered transceivers (like the dedicated '646 function), and clock-enabled registered transceivers (like the dedicated '952 function). Workstation designers can minimize inventory and procurement requirements, costs, and overhead with UBT™ flexibility. Designed specifically for workstation bus-interface applications, the UBT™ is perfect as an interface to the many different microprocessor architectures and system backplane specifications available.

Figure 7 details the current UBT™ portfolio from TI and includes block diagrams for two devices in the series. The 'ABT16600 is an 18-bit UBT™ packaged in the 56-pin SSOP package. It can be configured in each of four different data-flow modes between its A port and B port.

The 'ABT32318 is an 18-bit multiplexed UBT™ that can be configured in each of three different data-flow modes between its A port, B port, and C port. This UBT™ allows the system designer multiple combinations for real-time and stored data exchanges between the three ports. It is particularly useful for multibus communication, multiway interleaving memory applications, and high-performance, multiplexed-address and data-bus interface.



SERIES	NO. OF BITS	NO. OF PORTS	PACKAGE	NO. OF PINS	PARTITIONING	CONTROL LOGIC			
						OE	LE	CLK	CLKEN
16500/1	18	2	SSOP, TSSOP	56	x 18	Yes	Yes	Yes	No
16600/1	18	2	SSOP, TSSOP	56	x 18	Yes	Yes	Yes	Yes
32316	16	3	TQFP	80	x 16	Yes	Yes	Yes	Yes
32318	18	3	TQFP	80	x 18	Yes	Yes	Yes	No
32501	36	2	TQFP	100	x 18	Yes	Yes	Yes	No

Figure 7. UBT™ Portfolio

Several ABT product families directly address upper-end workstation and server equipment. A series of transceivers compliant with the IEEE 896.1 Futurebus+ backplane-interface standard are available. The special Futurebus+ protocols dictate special electrical requirements of the transceivers to ensure proper connection to Futurebus+ backplanes. Each of seven transceivers in the series utilize backplane transceiver logic (BTL) switching levels in accordance with the Futurebus+ standard. Complementing these Futurebus+ transceivers is a series of BTL transceivers compliant with the IEEE 1194.1 standard. Both transceiver series contain a TTL A port along with the BTL B port and can perform TTL-to-BTL and BTL-to-TTL-level translation.

SCOPE™ transceivers and drivers are available in ABT, which are compliant with the IEEE 1149.1 testability standard. For high reliability and fault-tolerant system needs, these devices provide their own internal self-test capabilities. A complete line of SCOPE™ hardware and software system products have been developed by TI.

The personal-computer market is characterized by very short design cycle times and intense pressure to lower costs. The major driving force is the need for workstation-type performance in machines designed for desktop, home, and portable applications. ABT in fine-pitch package options meets these needs nicely.

A new series of low-voltage products definitively addresses the needs of the portable subsegment of this market. The low-voltage technology (LVT) family has been developed with the submicron ABT process and will be available in both 8-bit octal and 16-/18-bit Widebus™ versions. Supply voltage for LVT is specified from 2.7 V to 3.6 V. The LVT 8-bit product uses the TSSOP to facilitate the smallest area for portable applications. The LVT Widebus™ product uses both the JEDEC SSOP and the 48-/56-pin EIAJ Shrink Widebus™ SSOP.

Market requirements for 3.3-V logic products are being driven now by battery laptops and hand-held instruments. Higher-performance desktop PCs and workstations could lag a year behind portables in their demand for 3.3-V logic.

As shown in Figure 8, the 5-V ABT I/O structure has been optimized for use with 3.3-V supply currents. LVT 3.3-V speed performance is equivalent to ABT 5-V speed performance. This special I/O circuitry also allows for a *mixed-mode* 3.3-V to 5-V interface capability. Designers can use the same LVT logic for the core 3.3-V system partition as for the external 5-V backplane interface. This is particularly important as other system elements (microprocessors, ASICs, and memories) migrate to 3.3 V at different rates.

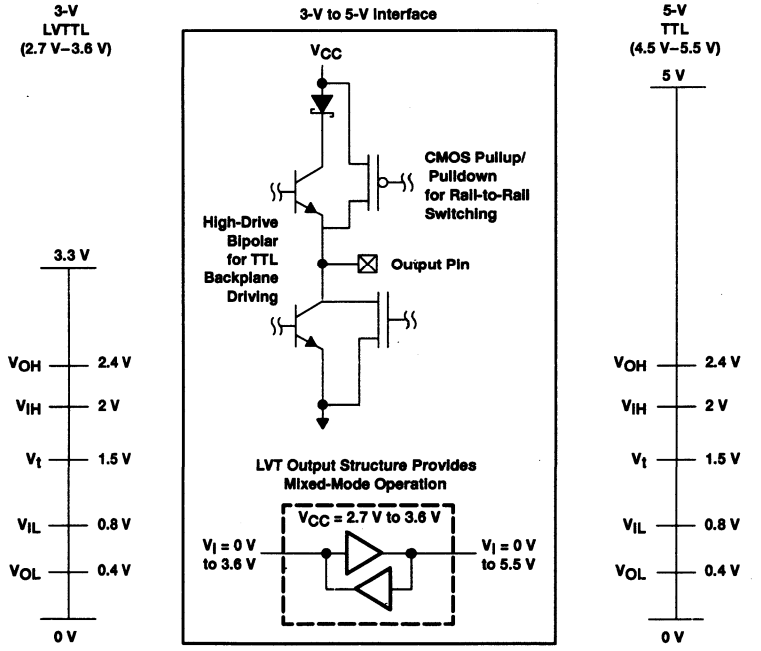


Figure 8. LVT Provides Optimized 3.3-V I/O

LVT I/O circuitry provides multiple output-current ratings for multiple system requirements. LVT devices are specified to drive at rail-to-rail low-voltage CMOS levels and standard 5-V TTL levels. LVT employs bus-hold and power-on-demand circuits increasing reliability, decreasing discrete component count, and minimizing enabled and disabled static power consumption. Maximum I_{CCL}, I_{CCH}, and I_{CCZ} current specifications are 5 mA, 0.1 mA, and 0.1 mA, respectively.

The majority of traditional telecom end equipments can be divided into switching and transmission categories. Switching equipment, such as central offices, cross connects, and branch exchanges, are analogous to large mainframes or supercomputers. ABT octal and Widebus™ product families are targeted for these telecom equipments.

For transmission equipment, such as line cards, bridgers, and routers, products with enhanced data-sheet specifications covering hot-card insertion and power up/down are required. In these applications, a board (card) typically is removed (inserted) from an active (hot) system for upgrade, maintenance, or repair. The additional specifications characterize the device's performance when supply currents change (ramp) rapidly.

It is necessary to know how the device behaves when V_{CC} is 0 V, when V_{CC} is at the rail (5.5 V), and when V_{CC} ramps between these voltages. To address this requirement specifically for telecom transmission applications, ABT transceiver data sheets take into account I_I, I_{OZH}, I_{OZL}, and I_{OZ} current conditions for various V_{CC} ramp rates. Transmission-system designers can then profile ABT device performance in hot-card insertion and power up/down conditions.

Summary

TI provides the system designer with the most advanced products to date, aiding the solution of complex design challenges. Advanced bus-interface logic (ABIL) products processed in submicron advanced BiCMOS technologies (ABT) address specific end-equipment demands of the workstation, personal and portable computer, and telecom markets. Advanced fine-pitch package options, such as SSOP, TSSOP, and TQFP, offer space-saving form factors. Circuit design techniques, such as bus hold and power on demand, add value over competitive solutions.

The evolutionary development of process and package technologies is illustrated in Figure 9. Solid lines indicate process-technology migration for CMOS and BiCMOS. The minimum process dimension is represented on the ordinate in units of microns. The dashed line indicates package-technology migration from PDIP to SOIC to SSOP to TQFP. For the dashed line, the ordinate represents minimum lead pitch in millimeters.

Figure 9 shows some interesting trends. BiCMOS solutions, initially well behind their CMOS cousins in terms of performance, have closed the gap almost completely during the past six years. For 5-V logic applications, ABT offers significant advantages over an equivalent CMOS version, particularly with the advent of thermally enhanced fine-pitch packages like the TQFP.

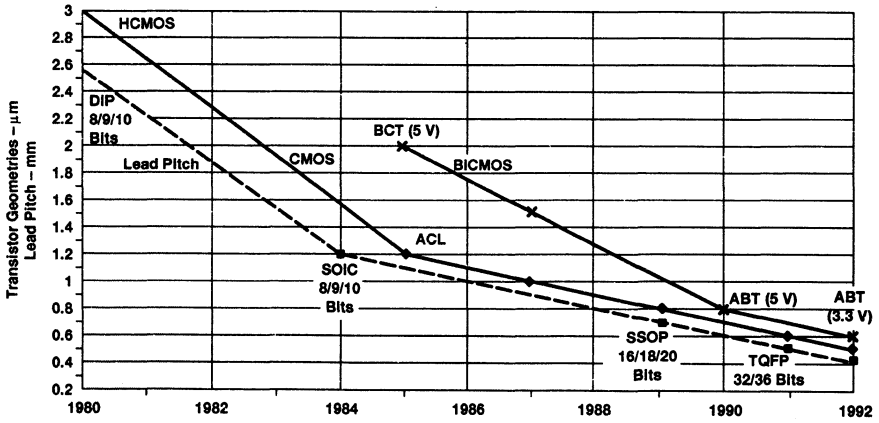


Figure 9. Bus-Interface Evolution

The advanced BiCMOS opportunity is to provide more processing capability and overall throughput at a time when the next-generation CMOS technologies are not quite ready, or where a mixed-technology approach provides a more practical solution. For ABIL products, the high performance and drive capability of ABT are necessary for rack-mount supercomputers, workstations, and telecom switching equipment. However, the low power consumption of ABT is necessary if these end equipments are to migrate to the desktop.

As process geometries drop to 0.6 μm and below, advanced BiCMOS and advanced CMOS will continue to compete in the pursuit of the best low-voltage solutions. Future enhancements to advanced BiCMOS might include extensions to a complementary structure of NPN and PNP transistors to better cope with reduction in power-supply voltages. As supply voltages drop to 2.6 V and below, it appears likely that advanced BiCMOS and advanced CMOS will coexist as viable product technologies, each supporting a dedicated group of customers. Time will tell.

Implications of Slow or Floating CMOS Inputs

SCBA004A
March 1997

TEXAS INSTRUMENTS

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Contents

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Introduction

In recent years, CMOS (AC, ACT, LVC) and BiCMOS (ABT, LVT) logic families have further strengthened their position in the semiconductor market. New designs have adopted both technologies in almost every system that exists, whether it is a PC, a workstation, or a digital switch. The reason is very obvious: power consumption is becoming a major issue in today's market. However, when designing systems using CMOS and BiCMOS devices, one must understand the characteristics of these families and the way inputs and outputs behave in systems. It is very important for the designer to follow all rules and restrictions that the manufacturer requires, as well as to design within the data-sheet specifications. Because data sheets do not cover the input behavior of a device in detail, this application note explains the input characteristics of CMOS and BiCMOS families in general. It also explains ways to deal with problem issues when designing with such families where floating inputs are a concern. Understanding the behavior of these inputs results in more robust designs and better reliability.

Characteristics of Slow or Floating CMOS Inputs

Both advanced CMOS and BiCMOS (ABT/LVT) families have a CMOS input structure. This structure is an inverter consisting of a p-channel to V_{CC} and an n-channel to GND as shown in Figure 1. With low-level input, the p-channel transistor is on and the n-channel is off, causing current to flow from V_{CC} and pulling the node to a high state. With high-level input, the n-channel transistor is on and the p-channel is off and the current flows to GND, pulling the node low. In both cases, no current flows from V_{CC} to GND. However, when switching from one state to another, the input crosses the threshold region, causing the n-channel and the p-channel to turn on simultaneously, generating a current path between V_{CC} and GND. This current surge can be damaging, depending on the length of time that the input is in the threshold region (0.8 to 2 V). The supply current (I_{CC}) can rise to several milliamperes per input, peaking at approximately 1.5 V V_I (see Figure 2). This is not a problem when switching states at the data-sheet-specified input transition time (see Figure 3).

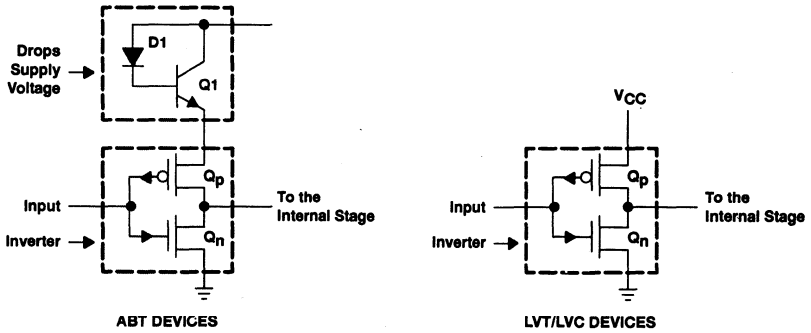

Figure 1. Input Structures of ABT and LVT/LVC Devices

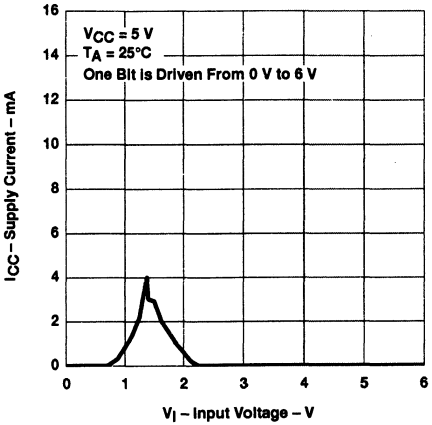

Figure 2. Supply Current Versus Input Voltage (One Input)

recommended operating conditions

			MIN	MAX	UNIT
$\Delta t/\Delta v$	Input transition rise or fall rate	ABT octals		5	ns/V
		ABT Widebus™ and Widebus+™		10	
		LVT, LVC, ALVC		10	
		LV		100	

Figure 3. Input Transition Rise or Fall Rate as Specified in Data Sheets

Slow Input Edge Rate

With increased speed, logic devices have become more sensitive to slow input edge rates. A slow input edge rate, coupled with the noise generated on the power rails when the output switches, can cause excessive output errors or oscillations. Similar situations can occur if an unused input is left floating or is not actively held at a valid logic level.

These functional problems are due to voltage transients induced on the device's power system as the output load current (I_O) flows through the parasitic lead inductances during switching (see Figure 4). Because the device's internal power-supply nodes are used as voltage references throughout the integrated circuit, inductive voltage spikes, V_{GND}, affect the way signals appear to the internal gate structures. For example, as the voltage at the device's ground node rises, the input signal, V_I, appears to decrease in magnitude. This undesirable phenomenon can then erroneously change the output if a threshold violation occurs.

In the case of a slowly rising input edge, if the change in voltage at GND is large enough, the apparent signal, V_I', at the device will appear to be driven back through the threshold and the output will start to switch in the opposite direction. If worst-case conditions prevail (simultaneously switching all of the outputs with large transient load currents), the slow input edge will be repeatedly driven back through the threshold, causing the output to oscillate. Therefore, the maximum input transition time of the device should not be violated, so no damage to the circuit or the package can occur (refer to Figure 3 for the maximum transition rate for each family).

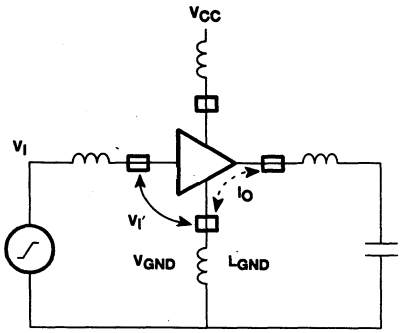

Figure 4. Input/Output Model

Floating Inputs

If a voltage between 0.8 V and 2 V is applied to the input for a prolonged period of time, this situation becomes critical and should not be ignored, especially with higher bit count and more dense packages (SSOP, TSSOP). For example, if an 18-bit transceiver had 36 I/O pins floating at the threshold, the current from V_{CC} could be as high as 150 to 200 mA. This is approximately 1 W of power consumed by the device, which leads to a serious overheating problem. This continuous overheating of the device affects its reliability. Also, because the inputs are in the threshold region, the outputs tend to oscillate, resulting in damage to the internal circuit over a long period of time. The data sheet shows the increase in supply current (ΔI_{CC}) when the input is at a TTL level [for ABT V_I = 3.4 V, ΔI_{CC} = 1.5 mA (see Figure 5)]. This becomes more critical when the input is in the threshold region as shown in Figure 6.

These characteristics are typical for all CMOS input circuits, including microprocessors and memories.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	MAX	UNIT
ΔI_{CC}†	ABT	V_{CC} = 5.5 V,	One input at 3.4 V,	Other inputs at V_{CC} or GND		1.5	mA
	LVT	V_{CC} = 3 V to 3.6 V,	One input at V_{CC} – 0.6 V,	Other inputs at V_{CC} or GND		0.2	
	LVC, ALVC, LV					0.5	

† This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

Figure 5. Supply-Current Change of the Input at TTL Level as Specified in Data Sheets

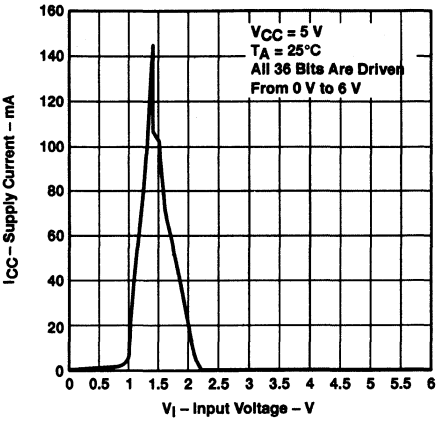

Figure 6. Supply Current Versus Input Voltage (36 Inputs)

As long as the driver is active in a transmission path or bus, the receiver's input is always in a valid state. No input specification is violated as long as the rise and fall times are within the data-sheet limits. However, when the driver is in a high-impedance state, the receiver input is no longer at a defined level and tends to float. This situation can worsen when several transceivers share the same bus. Figure 7 is an example of a typical bus system. When all transceivers are inactive, the bus-line levels are undefined. When a voltage that is determined by the leakage currents of each component on the bus is reached, the condition is known as a *floating state*. The result is a considerable increase in power consumption and a risk of damaging all components on the bus. Holding the inputs or I/O pins at a valid logic level when they are not being used or when the part driving them is in the high-impedance state is recommended.

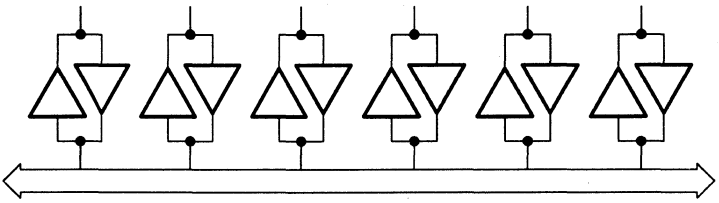

Figure 7. Typical Bidirectional Bus

Recommendations for Designing More Reliable Systems

Bus Control

The simplest way to avoid floating inputs in a bus system is to ensure that the bus is always either active or inactive for a limited time when the voltage buildup does not exceed the maximum V_{IL} specification (0.8 V for TTL-compatible input). At this voltage, the corresponding I_{CC} value is too low and the device operates without any problem or concern (see Figures 2 and 4).

To avoid damaging components, the designer must know the maximum time the bus can float. First, assuming that the maximum leakage current is I_{OZ} = 50 µA and the total capacitance (I/O and line capacitance) is C = 20 pF, the change in voltage with respect to time on an inactive line that exceeds the 0.8-V level can be calculated as in equation 1.

$$\Delta V/\Delta t = \frac{I_{oz}}{C} = \frac{50\ \mu A}{20\ pF} = 2.5\ V/\mu s \quad (1)$$

The permissible floating time for the bus in this example should be reduced to 320 ns maximum, which ensures that the bus will not exceed the 0.8-V level specified above. The time constant does not change when multiple components are involved because their leakage currents and capacitances are summed.

The advantage of this method is that it requires no additional cost for adding special components. Unfortunately, this method does not always apply because buses are not always active.

Pullup or Pulldown Resistors

When buses are disabled for more than the maximum allowable time, other ways should be used to prevent components from being damaged or overheated. A pullup or a pulldown resistor to V_{CC} or GND, respectively, should be used to keep the bus in a defined state. The size of the resistor plays an important role and if its resistance is not chosen properly, a problem may occur. Usually, a 1-kΩ to 10-kΩ resistor is recommended. The maximum input transition time must not be violated when selecting pullup or pulldown resistors (see Figure 3). Otherwise, components can be destroyed.

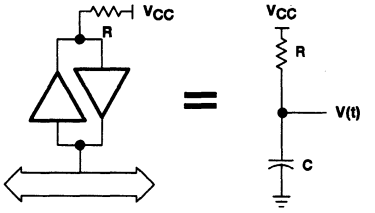

Figure 8. Inactive-Bus Model With a Defined Level

Assume that an active-low bus goes to the high-impedance state as modeled in Figure 8. C represents the device plus the bus-line capacitance and R is a pullup resistor to V_{CC}. The value of the required resistor can be calculated as in equation 2.

$$V(t) = V_{CC} - [e^{-t/RC} (V_{CC} - V_B)] \quad (2)$$

Where:

- V(t) = voltage at time t
- V_B = 0.8 V, maximum allowable floating voltage
- V_{CC} = 5 V
- C = total capacitance
- R = pullup resistor
- t = maximum input rise time as specified in Figure 3 of the data sheet

Solving for R, the equation becomes:

$$R = \frac{t}{0.17 \times C} \quad (3)$$

For multiple transceivers on a bus:

$$R = \frac{t}{0.17 \times C \times N} \quad (4)$$

Where:

- N = number of components connected to the bus

Assuming that there are ten components connected to the bus, each with a capacitance C = 20 pF requiring a maximum rise time of 10 ns/V and t = 50-ns total rise time for 5-V input, the maximum resistor size can be calculated:

$$R = \frac{50 \text{ ns}}{0.17 \times 20 \text{ pF} \times 10} = 1.5 \text{ k}\Omega \quad (5)$$

This pullup resistor method is recommended for ac-powered systems; however, it is not recommended for battery-operated equipment because power consumption is very critical. Instead, use the bus-hold feature that is discussed in the next section. The overall advantage of using pullup resistors is that they ensure defined levels when the bus is floating and help eliminate some of the line reflections because resistors can act as bus terminations as well.

Bus-Hold Circuits

The most effective method to provide defined levels for a floating bus is to use Texas Instruments (TI) built-in bus-hold feature on selected families or as an external component like the SN74ACT1071 and SN74ACT1073 (refer to Table 1).

Table 1. Devices With Bus Hold

DEVICE TYPE	BUS HOLD INCORPORATED
SN74ACT1071	10-bit bus hold with clamping diodes
SN74ACT1073	16-bit bus hold with clamping diodes
ABT Widebus+™ (32 and 36 bit)	All devices
ABT Octals and Widebus™	Selected devices only
Low Voltage (LVT and ALVC)	All devices
LVC Widebus™	All devices

Bus hold is a circuit used in selected TI families to help solve the floating-input problem and eliminate the need for pullup and pulldown resistors. It consists of two back-to-back inverters with the output fed back to the input through a resistor (see Figure 9). To understand how the bus-hold cell operates, assume that an active driver has switched the line to a high level. This results in no current flowing through the feedback circuit. Now, the driver goes to the high-impedance state and the bus-hold circuit holds the high level through the feedback resistor. The current requirement of the bus hold is determined only by the leakage current of the circuit. The same condition applies when the bus is in the low state and then goes inactive.

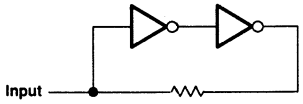

Figure 9. Typical Bus-Hold Cell

As mentioned previously in this section, TI offers the bus hold as stand-alone 10-bit and 16-bit devices (SN74ACT1071 and SN74ACT1073) with clamping diodes to V_{CC} and GND for added protection against line reflections caused by impedance mismatch on the bus. Because purely ohmic resistors cannot be implemented easily in CMOS circuits, a configuration known as a transmission gate is used as the feedback element (see Figure 10). An n-channel and a p-channel are arranged in parallel between the input and the output of the buffer stage. The gate of the n-channel transistor is connected to V_{CC} and the gate of the p-channel is connected to GND. When the output of the buffer is high, the p-channel is on, and when the output is low, the n-channel is on. Both channels are of relatively small surface area — the on resistance from drain to source, R_{dson}, is about 5 kΩ.

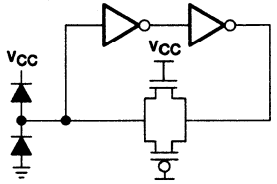

Figure 10. Stand-Alone Bus-Hold Cell (SN74ACT107x)

Now, assume that in a practical application the leakage current of a driver on a bus is I_{OZ} = 10 μA and the voltage drop across the 5 kΩ resistance is V_D = 0.8 V (this value is assumed to ensure a defined logic level). Then, the maximum number of components that a bus hold can handle is calculated as follows:

$$N = \frac{V_D}{I_{OZ} \times R} = \frac{0.8\ V}{10\ \mu A \times 5\ k\Omega} = 16 \text{ components} \quad (6)$$

The 74ACT1071 and 74ACT1073 also provide clamping diodes as an added feature to the bus hold. These diodes are useful for clamping any overshoot or undershoot generated by line reflections. Figure 11 shows the characteristics of the diodes when the input voltage is above V_{CC} or below GND. At V_I = –1V, the diode can source about 50 mA, which can help eliminate undershoots. This can be very useful when noisy buses are a concern.

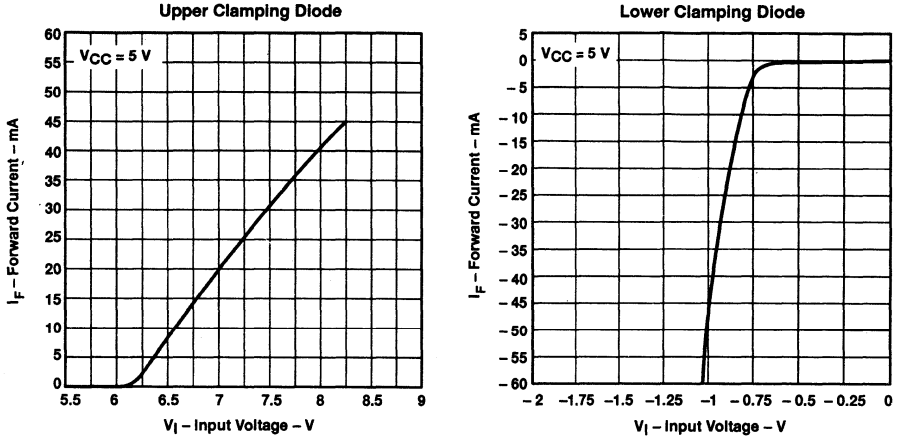

Figure 11. Diode Characteristics (SN74ACT107x)

TI also offers the bus-hold circuit as a feature added to some of the advanced-family drivers and receivers. This circuit is similar to the stand-alone circuit with a diode added to the drain of the second inverter (ABT and LVT only, see Figure 12). The diode blocks the overshoot current when the input voltage is higher than V_{CC} ($V_I > V_{CC}$), so only the leakage current is present. This circuit uses the device's input stage as its first inverter; a second inverter creates the feedback feature. The calculation of the maximum number of components that the bus hold can handle is similar to the previous example. However, the advantage of this circuit over the stand-alone bus hold is that it eliminates the need for external components or resistors that occupy more area on the board. This becomes very critical for some designs, especially when wide buses are used. Also, because cost and board-dimension restrictions are a major concern, designers prefer the easy fix: drop-in replaceable parts. TI offers this feature in most of the commonly used functions in several families (refer to Table 1 for more details).

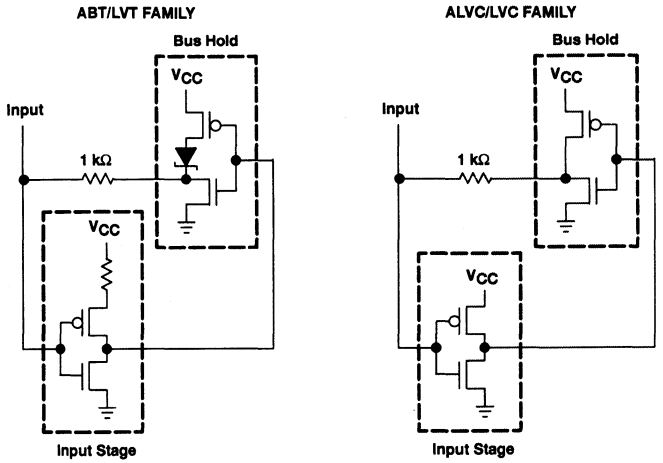

Figure 12. Input Structure of ABT/LVT and ALVC/LVC Families With Bus Hold

Figure 13 shows the input characteristics of the bus hold at 3.3-V and 5-V operations, as the input voltage is swept from 0 to 5 V. These characteristics are similar in behavior to a weak driver. This driver sinks current into the part when the input is low and sources current out of the part when the input is high. When the voltage is near the threshold, the circuit tries to switch to the other state, always keeping the input at a valid level. This is the result of the internal feedback circuit. The plot also shows that the current is at its maximum when the input is near the threshold. $I_{I(hold)}$ maximum is approximately 25 μA for 3.3-V input and 400 μA for 5-V input.

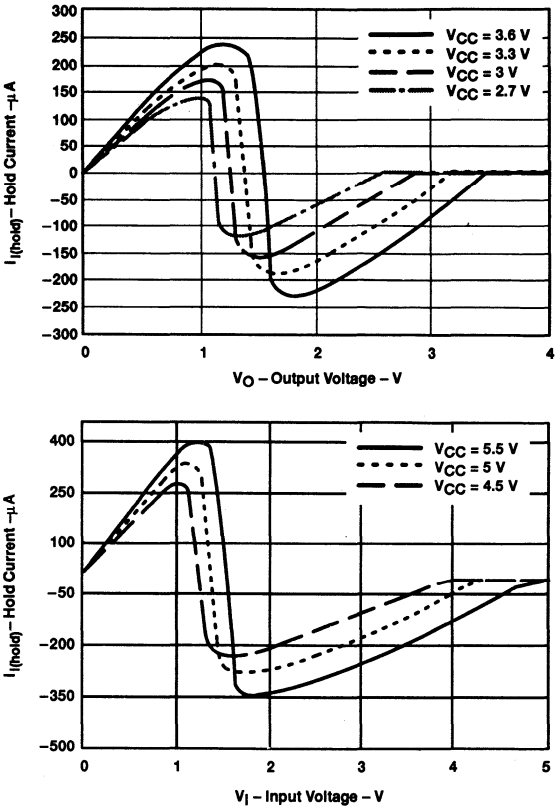

Figure 13. Bus-Hold Input Characteristics

When multiple devices with bus hold are driven by a single driver, one may be concerned about the ac switching capability of the driver becoming weaker. As small drivers, bus-hold cells require an ac current to switch them. This current is not significant when using TI CMOS and BiCMOS families. Figure 14 shows a 4-mA buffer driving six LVTH16244 devices. The trace is a 75-Ω transmission line. The receivers are separated by 1cm, with the driver located in the center of the trace. Figure 15 shows the bus-hold loading effect on the driver when connected to six receivers switching low or high. It also shows the same system with the bus hold disconnected from the receivers. Both plots show the effect of bus hold on the driver's rise and fall times. Initially, the bus hold tries to counteract the driver, causing the rise or fall time to increase. Then, the bus hold changes states (note the crossover point), which helps the driver switch faster, decreasing the rise or fall time.

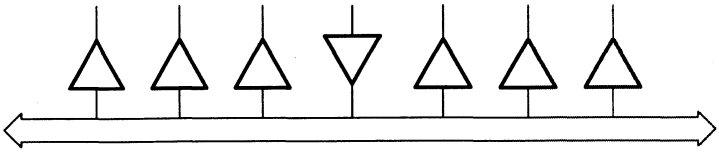

Figure 14. Driver and Receiver System

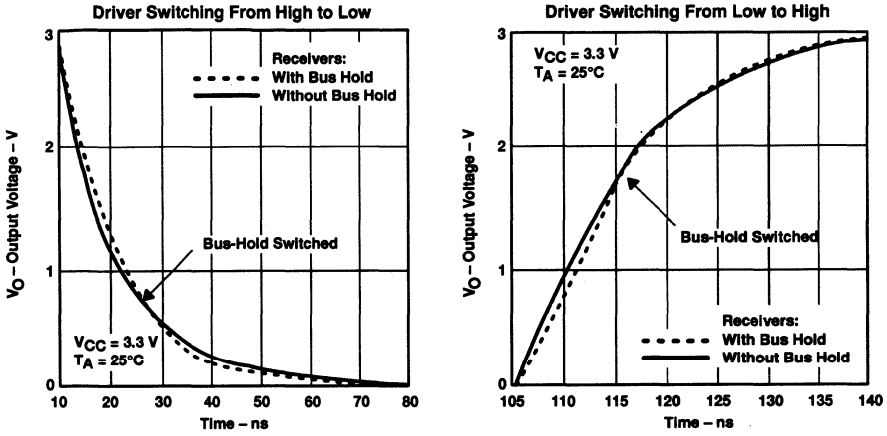

Figure 15. Output Waveforms of Driver With and Without Receiver Bus Hold

Figure 16 shows the supply current (I_{CC}) of the bus-hold circuit as the input is swept from 0 to 5 V. Again, the spike seen at about 1.5-V V_I is due to both the n-channel and the p-channel conducting simultaneously. This is one of the CMOS transistor characteristics.

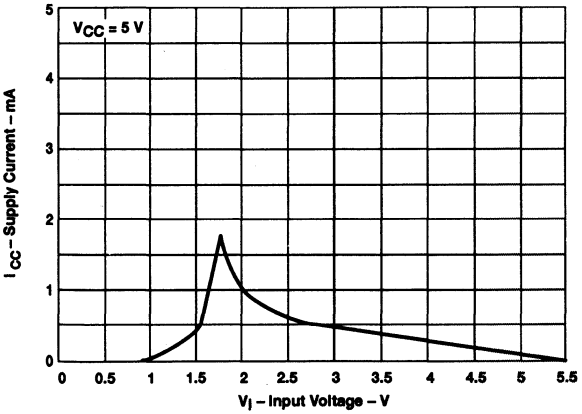

Figure 16. Bus-Hold Supply Current Versus Input Voltage

The power consumption of the bus hold is minimal when switching the input at higher frequencies. Figure 17 shows the power consumed by the input at different frequencies with or without bus hold. As shown, the increase in power consumption of the bus hold at higher frequencies is not significant enough to be considered in power calculations.

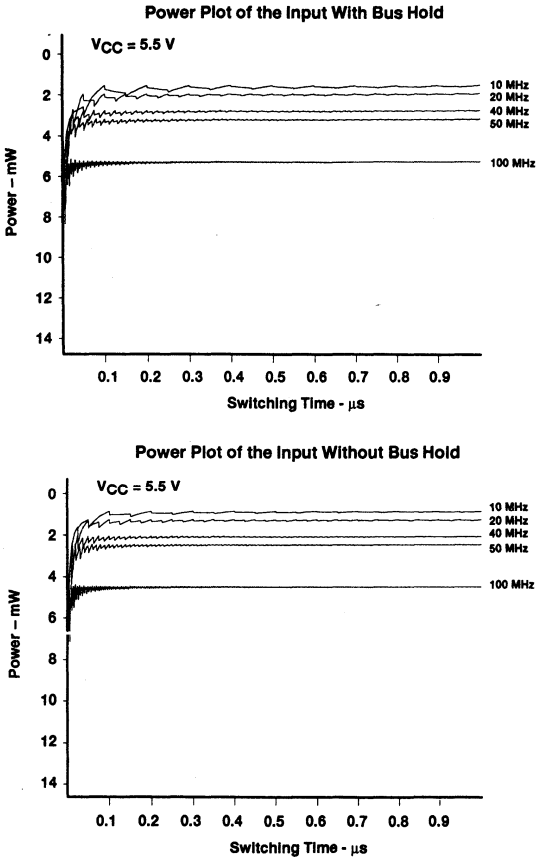

Figure 17. Input Power With or Without Bus Hold at Different Frequencies

Figure 18 shows the data sheet dc specifications for bus hold. The first test condition is the minimum current required to hold the bus at 0.8 V or 2 V. These voltages meet the specified low and high levels for TTL inputs. The second test condition is the maximum current that the bus hold sources or sinks at any input voltage between 0 V and 3.6 V (for low-voltage families) or between 0 V and 5.5 V (for ABT). The bus-hold current becomes minimal as the input voltage approaches the rail voltage. The output leakage currents, I_{OZH} and I_{OZL}, are insignificant for transceivers with bus hold because a true leakage test cannot be performed due to the existence of the bus-hold circuit. Because bus hold behaves as a small driver, it tends to source or sink a current that is opposite in direction to the leakage current. This situation is true for transceivers with bus hold only and does not apply to buffers. All LVT, ABT Widebus+™, and selected ABT octal and Widebus™ devices have the bus-hold feature (refer to Table 1 or contact the local TI sales office for more information).

electrical characteristics over recommended operating free-air temperature range (for families with bus-hold feature)

PARAMETER			TEST CONDITIONS		MIN	MAX	UNIT
$I_{I(hold)}$	Data inputs or I/Os	LVT, LVC, ALVC	V_{CC} = 3 V	V_I = 0.8 V	75		μA
				V_I = 2 V	−75		
		LVC, ALVC	V_{CC} = 3.6 V,	V_I = 0 to 3.6 V		±500	
		ABT Widebus+™ and selected ABT	V_{CC} = 4.5 V	V_I = 0.8 V	100		
				V_I = 2 V	−100		
I_{OZH}/I_{OZL}	Transceivers with bus hold	ABT	This test is not a true I_{OZ} test since bus hold is always active on an I/O pin. It tends to supply a current that is opposite in direction to the output leakage current.			±1	μA
		LVT, LVC, ALVC					
	Buffers with bus hold	ABT	This test is a true I_{OZ} test since bus hold does not exist on an output pin.			±10	
		LVT, LVC, ALVC				±5	

Figure 18. Data-Sheet Minimum Specification for Bus Hold

Summary

Floating inputs and slow rise and fall times are important issues to consider when designing with CMOS and advanced BiCMOS families. It is important to understand the complications associated with floating inputs. Terminating the bus properly plays a major role in achieving reliable systems. All three methods that were recommended in this application note should be considered. If it is not possible to control the bus directly and adding pullup or pulldown resistors is impractical due to power-consumption and board-space limitations, bus hold is the best choice. TI designed bus hold to reduce the need for resistors used in bus designs, thus reducing the number of components on the board and improving the overall reliability of the system.

The Bypass Capacitor in High-Speed Environments

SCBA007A
November 1996

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Introduction

High-speed switching environments generate noise on power lines (or planes) due to the charging and discharging of internal and external capacitors of an integrated circuit. The instantaneous current generated with the rising and falling edges of the outputs causes the power line (or plane) to ring. This behavior can violate the V_{CC} recommended operating conditions or generate false signals, creating serious problems. A simple and easy solution must be considered to prevent such a problem from occurring. This solution is the bypass capacitor.

Bypass Definition

A bypass capacitor stores an electrical charge that is released to the power line whenever a transient voltage spike occurs. It provides a low-impedance supply, thereby minimizing the noise generated by the switching outputs of the device.

Bypassing Considerations

A system without bypassing techniques can create severe power disturbance and cause circuit failures. Figure 1 shows the V_{CC} line of the 'ABT541 ringing while all outputs are switching. Note that there is no bypass capacitor at the V_{CC} pin. There are a few issues that should be considered when bypassing power lines (or planes).

- The capacitor type
- The capacitor placement
- The output load effect
- The capacitor size

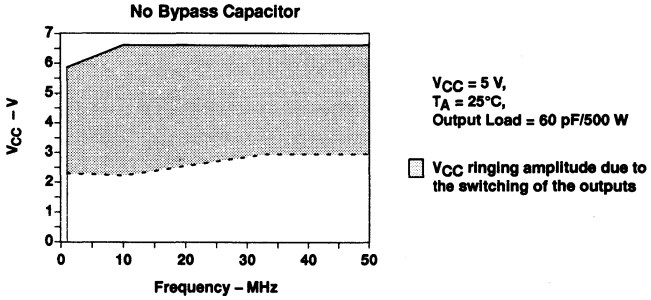

Figure 1. V_{CC} Line Disturbance vs Frequency

Capacitor Type

In a high-speed environment the lead inductances of a bypass capacitor become very critical. High-speed switching of a part's outputs generates high frequency noise (>100 MHz) on the power line (or plane). These harmonics cause the capacitor with high lead inductance to act as an open circuit, preventing it from supplying the power line (or plane) with the current needed to maintain a stable level, and resulting in functional failure of the circuit. Therefore, bypassing a power line (or plane) from the device internal noise requires capacitors with very small inductances. That is why the multilayer ceramic chip capacitors (MLC) are more favorable than others for bypassing power lines (or planes). They exhibit negligible internal inductance, thereby allowing the charge to flow easily, when needed, without degradation.

Capacitor Placement

Most of the printed circuit boards are designed to maintain a short distance between power and ground. This is done by laminating the power line (or plane) with the ground plane and can be electrically approximated with lumped capacitances as shown in Figure 2. However, this is not enough to have a reliable system, and another technique must be considered to provide a low-impedance path for the transient current to be grounded. This can be done by placing the bypass capacitor close to the power pin of the device.

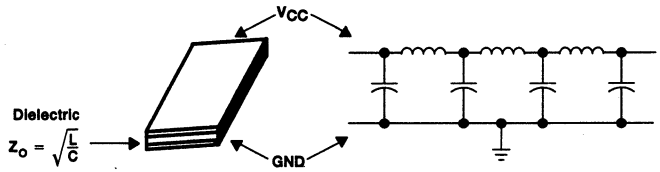

Figure 2. Typical Power Layout

Why This Location Is Very Important

Consider a device driving a line from low to high having an impedance ($Z \cong 100\ \Omega$) and a supply voltage ($V_{CC} = 5$ V) (see Figure 3). In order for the device to change state, an output current ($I = 50$ mA) is needed instantaneously. Note that for eight outputs switching, $I = 50 \times 8 = 400$ mA. This current is provided by the power line (or plane) in a period less than or equal to the rise time of the output (approximately 3 ns for ABT). The bypass capacitor must supply the charge in that same period to avoid V_{CC} drop; therefore, distance becomes an important issue. Line inductances can block the charge from flowing, leaving the power line (or plane) disturbed.

Using the formula for paralleled wires:

$$L = l\frac{\mu_0}{\pi}\ln\frac{d}{r} \quad (1)$$

Where:

- d = distance between wires
- l = length of the wires
- r = radius of the wires
- μ_0 = permeability of medium between wires

The inductance (L) is directly proportional to the distance between the lines as well as the length of the lines. Therefore, by reducing the loop ABCD in Figure 3, the inductance is minimized, allowing the capacitor to function more efficiently and, hence, keep the noise off the power line (or plane).

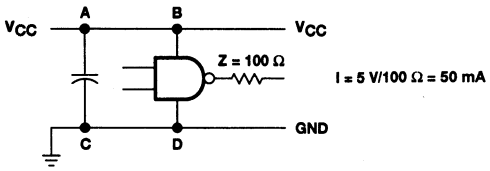

Figure 3. Capacitive Storage (Bypass Capacitor)

Several tests were performed on an 'ABT541 device to study the behavior of its power line (or plane) as the outputs switch simultaneously. This data is taken at different distances from the power pin (0.3, 1, and 2 inches) using four capacitors (0.001, 0.01, 0.1, and 1 μF), with an input frequency of 33 MHz and all eight outputs switching simultaneously (worst case). Figure 4 shows that the line disturbance increases as the capacitor is moved away from the power pin.

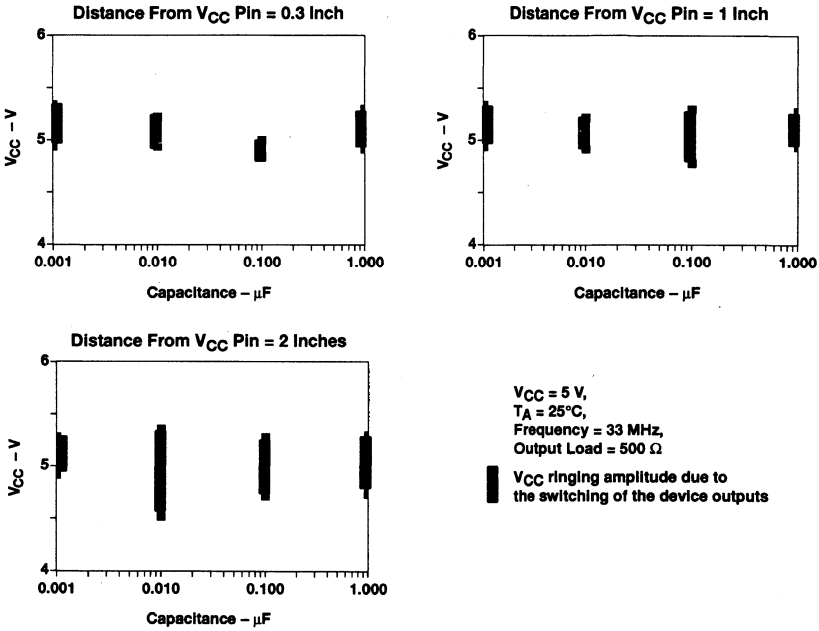

Figure 4. V_{CC} Line Disturbance vs Capacitor Size at Different Distances

Output Load Effect

Capacitive loads combined with increased frequency result in higher transient current and possible V_{CC} oscillation. If the output load is purely resistive, the increase in frequency does not affect the rising and falling edge of the outputs; therefore, it does not increase the V_{CC} line disturbance. Figure 5 shows the power line behavior across frequency while driving only a resistive load. Figure 6 shows the same plot with an additional 60-pF capacitive load.

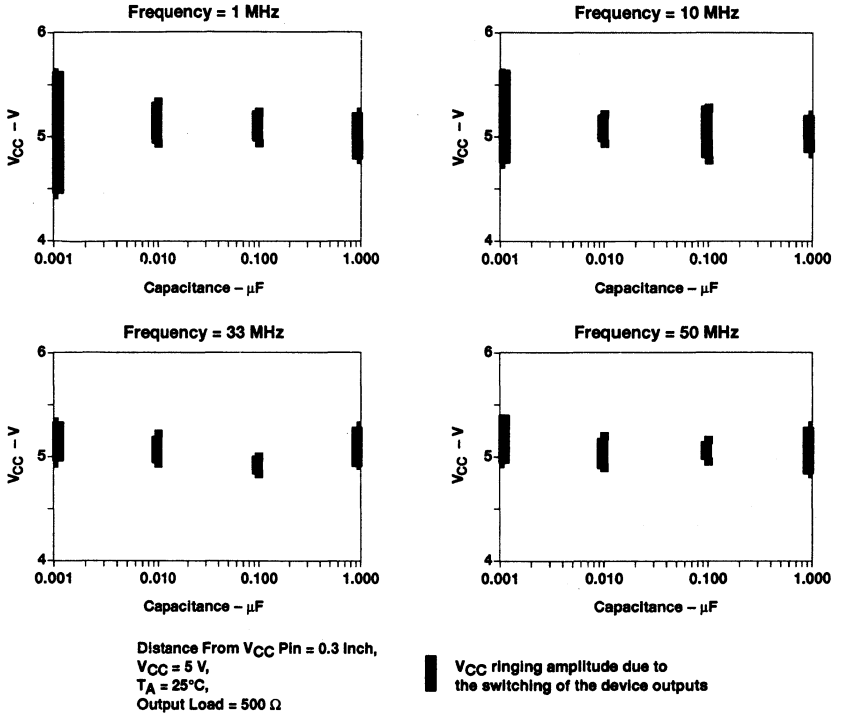

Figure 5. V_{CC} Line Disturbance vs Capacitor Size With Resistive Load at Different Frequencies

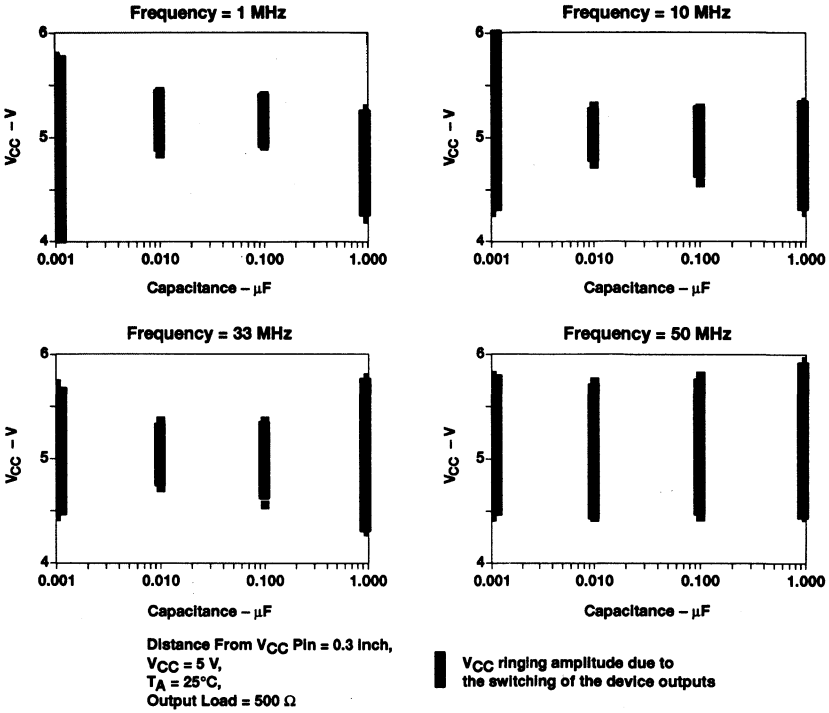

Figure 6. V_{CC} Line Disturbance vs Capacitor Size With 60-pF Load at Different Frequencies

When driving large capacitive loads, more charge must be supplied to the output load, resulting in a slower rising or falling edge. However, if the bypass capacitor is not capable of providing the needed charge, power lines (or planes) start to ring and eventually oscillate, causing failures across the board. These oscillations can be of a great amplitude, 2- to 3-V p-to-p. Figure 7 shows these oscillations at four different loads (0, 60, 115, and 200 pF) using four different bypass capacitors (0.001, 0.01, 0.1, and 1 μF).

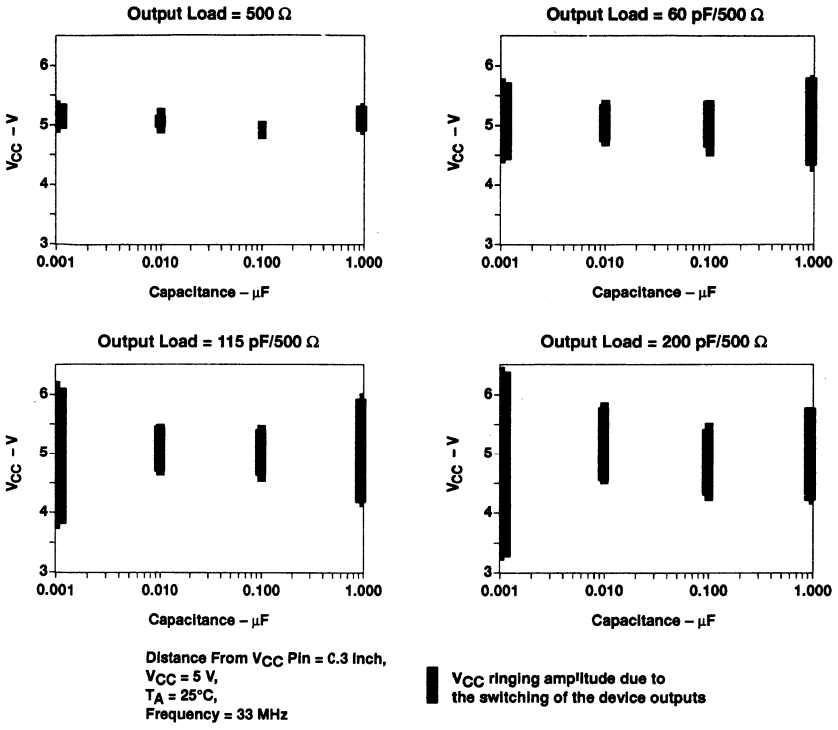

Figure 7. V_{CC} Line Disturbance vs Capacitor Size at Different Capacitive Loads

Capacitor Size

How can we choose the right bypass capacitor? The most important parameter is the ability to supply instantaneous current when it is needed.

There are two ways to calculate the bypass-capacitor size for a device:

1. The amount of current needed to switch one output from low to high (I), the number of outputs switching (N), the time required for the capacitor to charge the line (Δt), and the drop in V_{CC} that can be tolerated (ΔV) must be known.

   The following equation can be used:

   $$C = \frac{I \times N \times \Delta t}{\Delta V} \quad (2)$$

   where Δt and ΔV can be assumed.

For example, with $\Delta V = 0.1$ V, $\Delta t = 3$ ns, $N = 8$, and I obtained from either Figure 3 (for rough estimate) or from the plot in Figure 8 (assuming 50-MHz frequency), using $I = 44$ mA, the equation is:

$$C = \frac{44 \times 10^{-3} \times 8 \times 3 \times 10^{-9}}{0.1} = 10080 \times 10^{-12} = 0.01\ \mu F \quad (3)$$

2. Several capacitor manufacturers specify the maximum pulse slew rate. This allows the capacitor's maximum current to be calculated. For example, a 0.1-µF capacitor rated at 50 V/µs can supply: $i = c\ dv/dt = 0.1 \times 50 = 5$ A. This current is greater than the maximum current ($I \times N = 44$ mA $\times$ 8 outputs switching = 352 mA) required by the device used in the previous example.

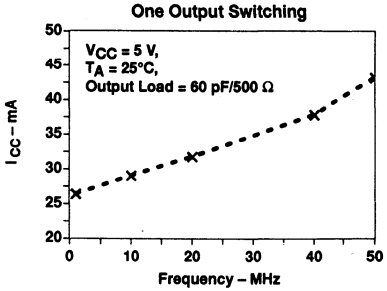

Figure 8. I_{CC} vs Frequency

Summary

Bypass capacitors play a major role in achieving reliable systems. The absence of the bypass capacitor can generate false signals and create major problems across the entire board. Figure 1 shows the undesired ringing caused by simultaneously switching the outputs of the 'ABT541. Also, choosing a capacitor with negligible lead inductance can avoid unpredictable behavior at high frequencies. Locating the capacitor closer to the V_{CC} pin of a device can avoid further complications and eliminate the ringing entirely. Figure 6 shows the V_{CC} line behavior with the bypass capacitor placed 0.3 inch away from the V_{CC} pin, whereas Figure 9 shows the same plot with the same load, but the bypass capacitor is located at the pin; there is dramatic improvement in the latter case. This technique can also be applied to Texas Instruments Widebus™ family by bypassing all V_{CC} pins. This is the most effective method for eliminating the V_{CC} line ringing. It is always important to minimize the loop between the V_{CC} pin, the ground, and the bypass capacitor. Finally, choosing the capacitor size by using either method mentioned earlier is highly recommended. If one considers all these issues, a good bypass technique can be employed.

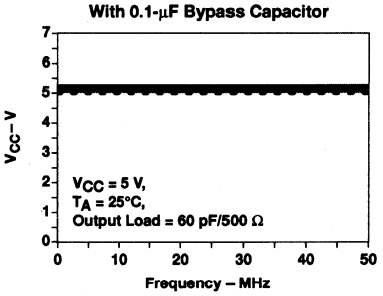

Figure 9. V_{CC} Line Disturbance vs Frequency

References

1 Texas Instruments Incorporated, "Advanced Schottky Family (ALS/AS) Applications," *ALS/AS Logic Data Book*, 1995, literature number SDAD001C.

2 Walton, D., "P.C.B. Layout for High-Speed Schottky TTL".

Family of Curves Demonstrating Output Skews for Advanced BiCMOS Devices

SCBA006A
December 1996

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Introduction

The data in this application report demonstrates the skew between the outputs of a sample of Texas Instruments Advanced BiCMOS (ABT) devices. This report explains which output skew is being examined, where the data comes from, and how the data is analyzed. Some of the errors that may be present in the data are discussed.

Skews

Skew is a term that defines the difference in time between two signal edges. Several different types of skew being used are defined in JEDEC 99 clause 2.3.5.

Output Skew [$t_{sk(o)}$] – The difference between two concurrent propagation delay times that originate at either a single input or two inputs switching simultaneously and terminating at different outputs.

Input Skew [$t_{sk(i)}$] – The difference between two propagation delay times that originate at different inputs and terminate at a single output.

Pulse Skew [$t_{sk(p)}$] – The difference between the propagation delay times t_{PLH} and t_{PHL} when a single switching input causes one or more outputs to switch.

Process Skew [$t_{sk(pr)}$] – The difference between identically specified propagation delay times on any two samples of an IC at identical operating conditions.

Limit Skew [$t_{sk(l)}$] – The difference between: 1) The greater of the maximum specified values of t_{PLH} and t_{PHL} and 2) The lesser of the minimum specified values of t_{PLH} and t_{PHL}.

The skew discussed here is the skew of propagation delays across the outputs of a device. More specifically, it is the difference between the largest value obtained for a propagation delay and the smallest value across all of the outputs. For example, if output 3 has the largest propagation delay t_{PLH} and output 14 has the smallest, the output skew for this device would be the difference between the propagation delays for output 3 and output 14 (see Figure 1).

The majority of the curves presented in this paper consist of data taken on devices that have one output switching at a time. This produces a skew that should not be confused with the defined data-sheet skew $t_{sk(o)}$. The data-sheet value for $t_{sk(o)}$ is found by switching all of the outputs simultaneously. Two of the devices examined in this paper ('ABT16240 and 'ABT16500A) include curves that present $t_{sk(o)}$ data.

Source of Data

The data used to produce the curves presented in this paper was extracted from the characterization data bases used to prepare the data sheets for the devices presented. The sample size of the data base is approximately 30 devices for each characterization lot (wafer) used.

The data was sorted so that the maximum skew for each device at a particular V_{CC} and temperature combination could be determined. Next, the maximum skew values were averaged to produce a data point for each transition. Further statistical analysis of this data was performed to calculate a standard deviation of the maximum skew across the devices. This value was then used to produce a three-standard-deviation data point for each V_{CC} and temperature combination. The data is presented as a family of curves across V_{CC}, with each member of the family being an output skew versus temperature curve. The curves for each device are broken out by output transition (i.e., t_{PLH}, t_{PHL}). Each transition is further separated into a set of curves depicting the average skew across the devices and a set representing the average skew, plus three standard deviations.

For those devices ('ABT16952 and 'ABT16500A) that have registers, the data path chosen for each device was the path that put the device in a transparent mode. Also, for the bidirectional devices ('ABT16245, 'ABT16952, and 'ABT16500A), the A-to-B direction was used.

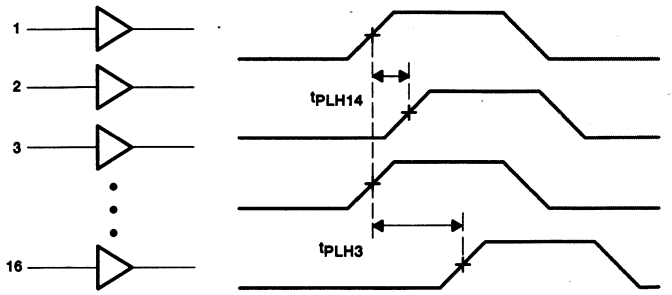

Figure 1. Skew = $|t_{PLH14} - t_{PLH3}|$

Sources of Error in Data

The data in this report was taken on an IMPACT tester, which is automatic test equipment used to characterize integrated circuits. The tester is offset using a golden unit that has had data taken on a laboratory bench setup. The offsetting process is the main source of error in the data.

Briefly, the tester is offset in the following manner. The golden unit has its propagation delay measurements taken at 25°C and 85°C using a pulse generator as the source and an oscilloscope as the measurement device. The golden unit is then placed on the IMPACT and the data is again taken. The difference between the two values is the offset. The 25°C offsets are used for the data taken at –55°C, –40°C, and 25°C, while the 85°C offsets are used at 85°C and 125°C.

Great care is taken during this process to ensure that the induced error is kept to a minimum. For example, the boards are checked before use to ensure the output loads are correct, the oscilloscope is calibrated each day, and the input signals are closely monitored to ensure that the intended signal is delivered to the golden unit.

This reduction in error is quite important in this application because the average skews for the devices are about 200 ps. A 20-ps error in offsets translates into an approximate error of 10% in the output skew data. However, it can be seen in the curves presented here that the error has been kept to a minimum and that the curves are fairly well behaved.

Summary

The family of curves presented in Figures 2 through 9 demonstrates that the Texas Instruments Advanced BiCMOS family of devices can be expected to produce an average skew between outputs that remain below 400 ps for devices with single switching outputs. Also, when a device's outputs switch simultaneously, the average skew across the outputs can be expected to remain below 700 ps.

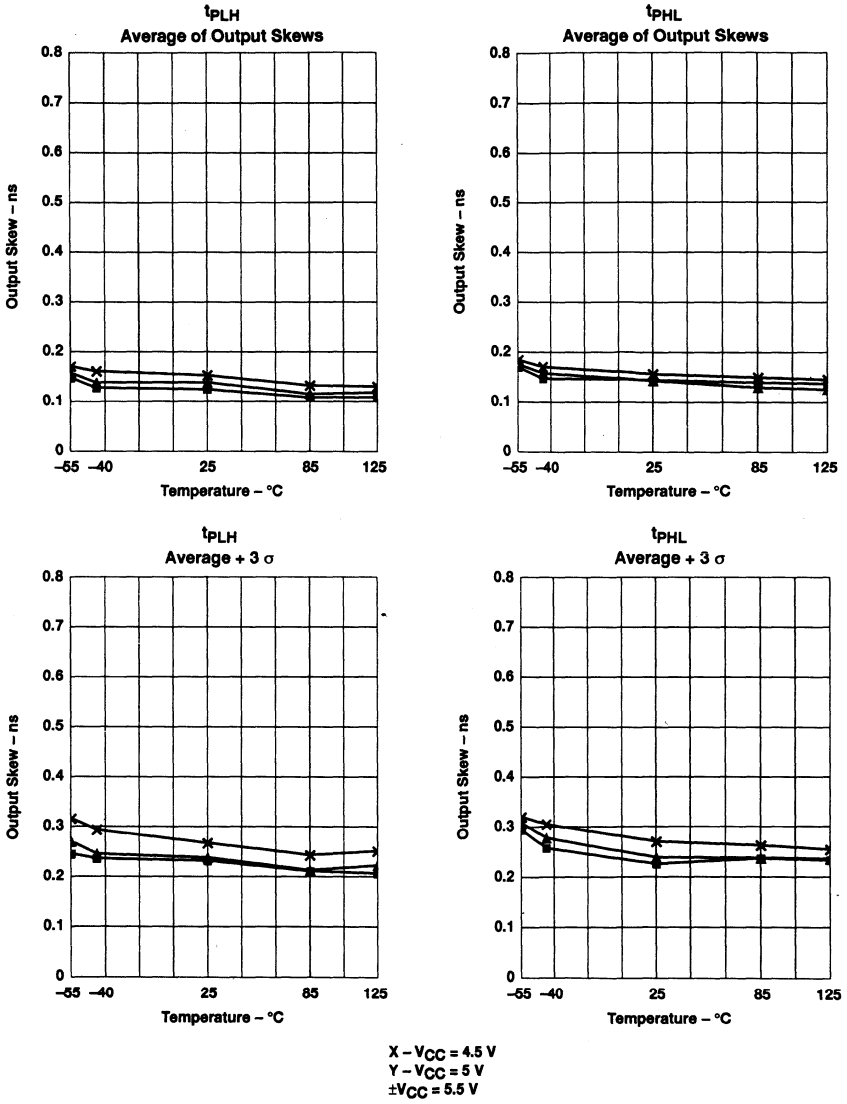

Figure 2. 'ABT16240 – Single Switching

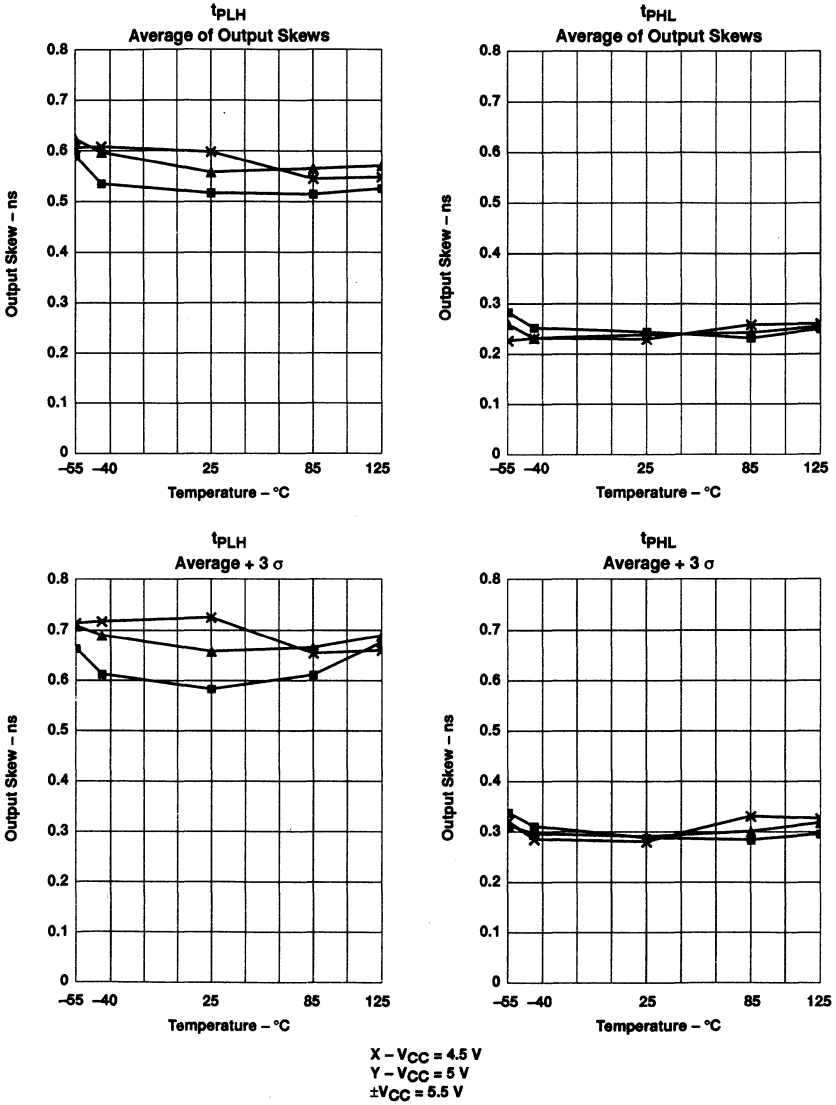

Figure 3. 'ABT16240 – Simultaneous Switching

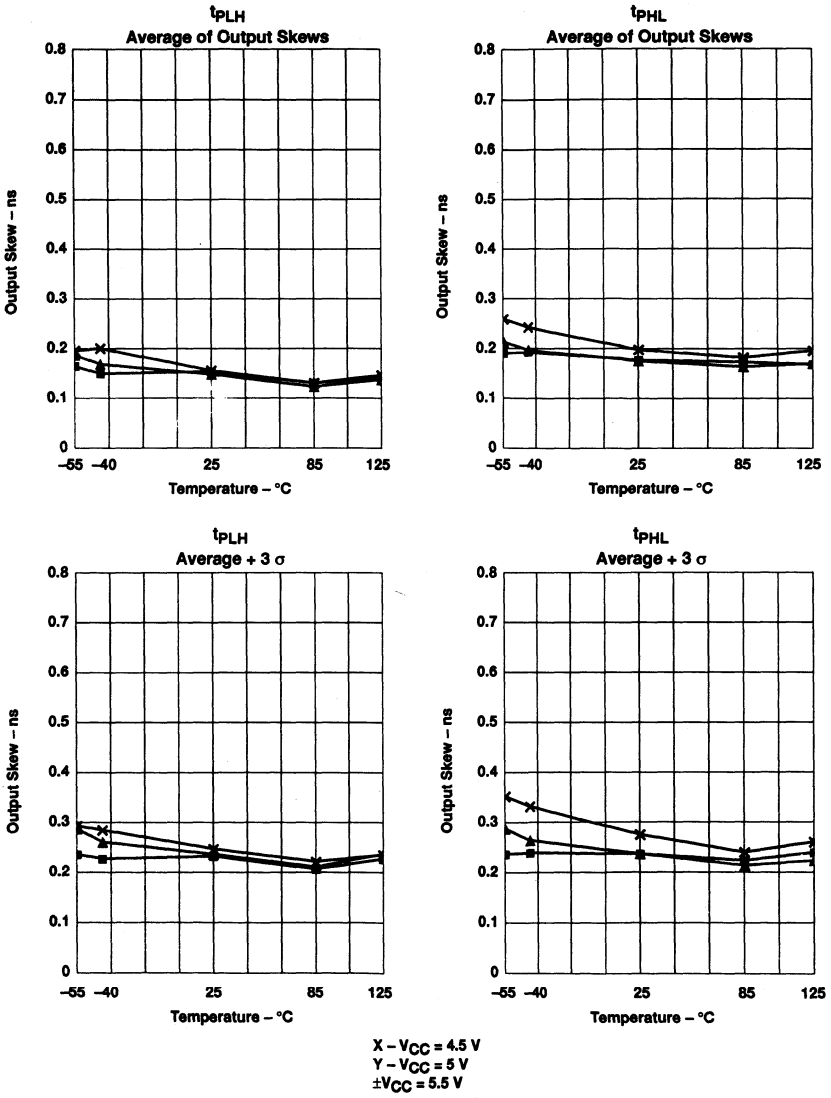

Figure 4. 'ABT16245 – Single Switching

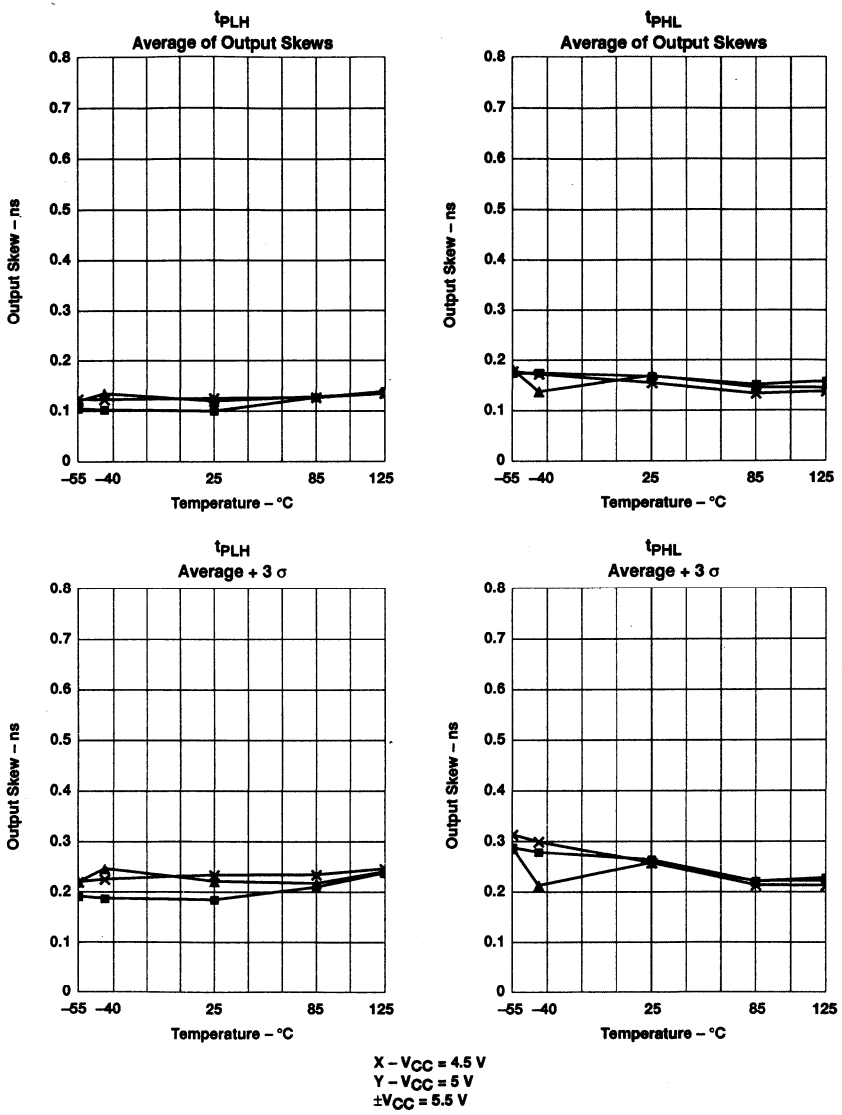

Figure 5. 'ABT16952 – Single Switching

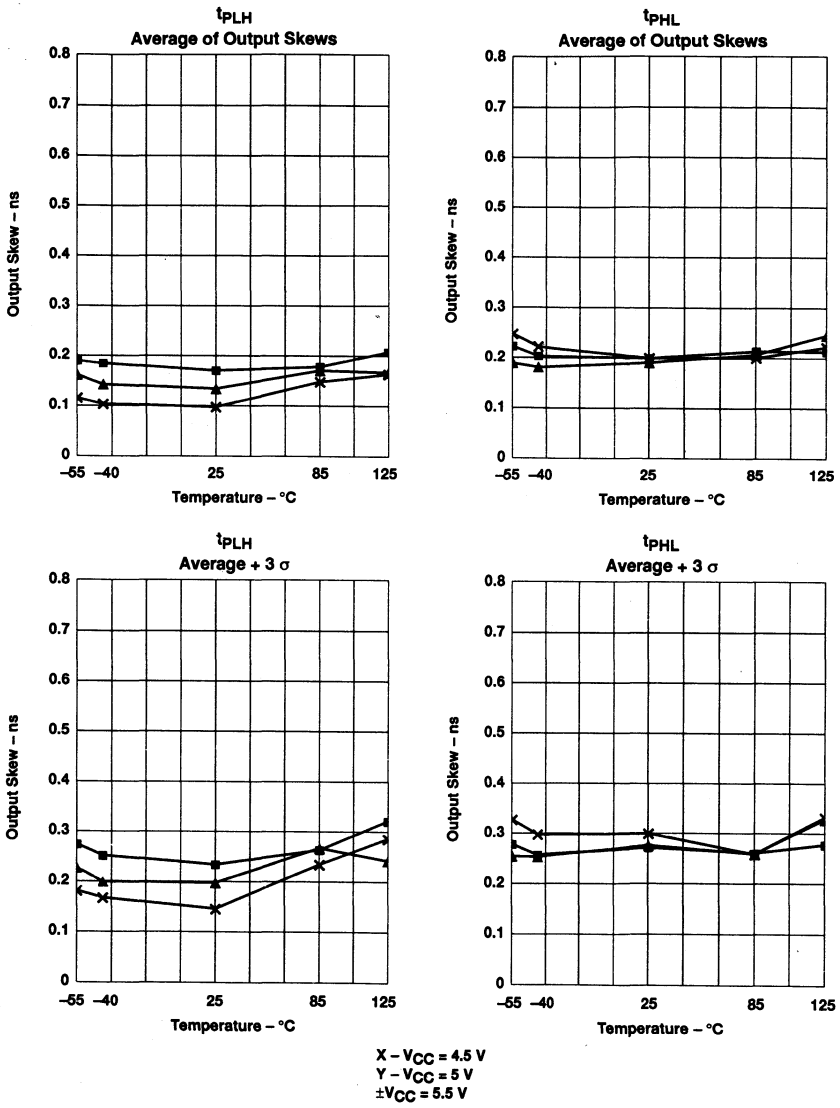

Figure 6. 'ABT16500A – Single Switching

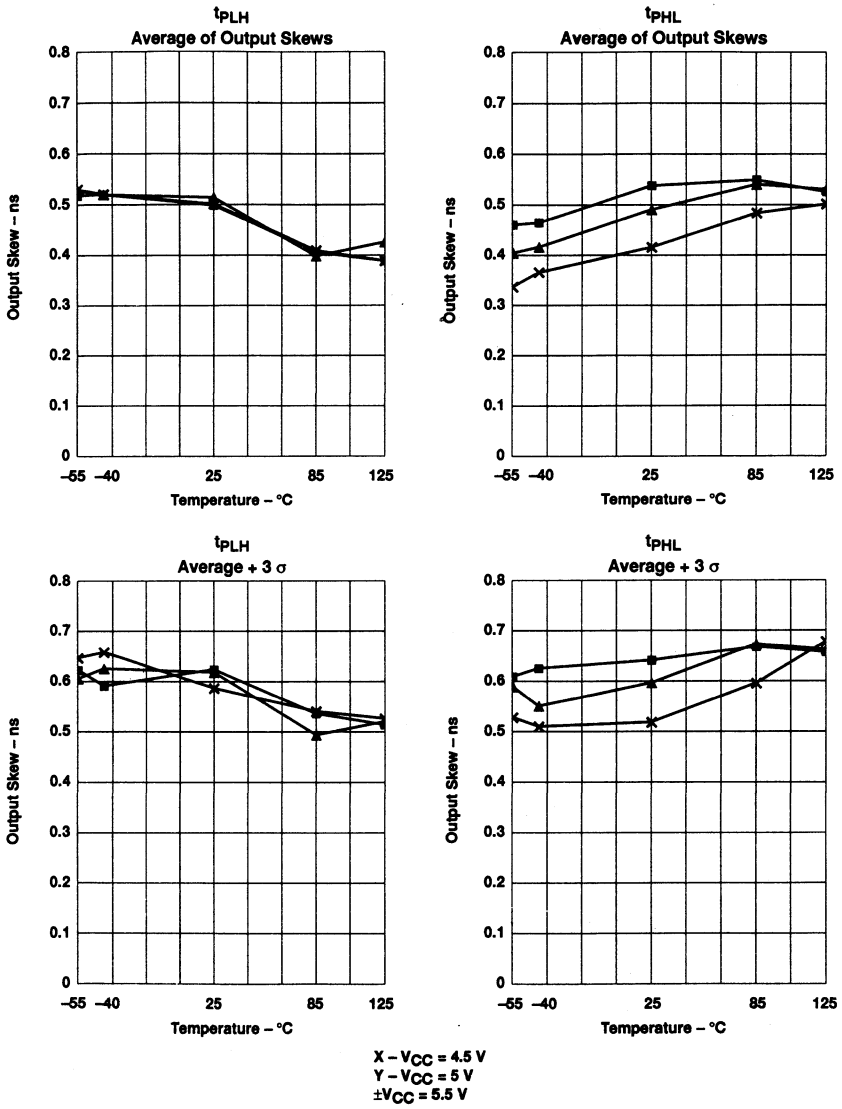

Figure 7. 'ABT16500A – Simultaneous Switching

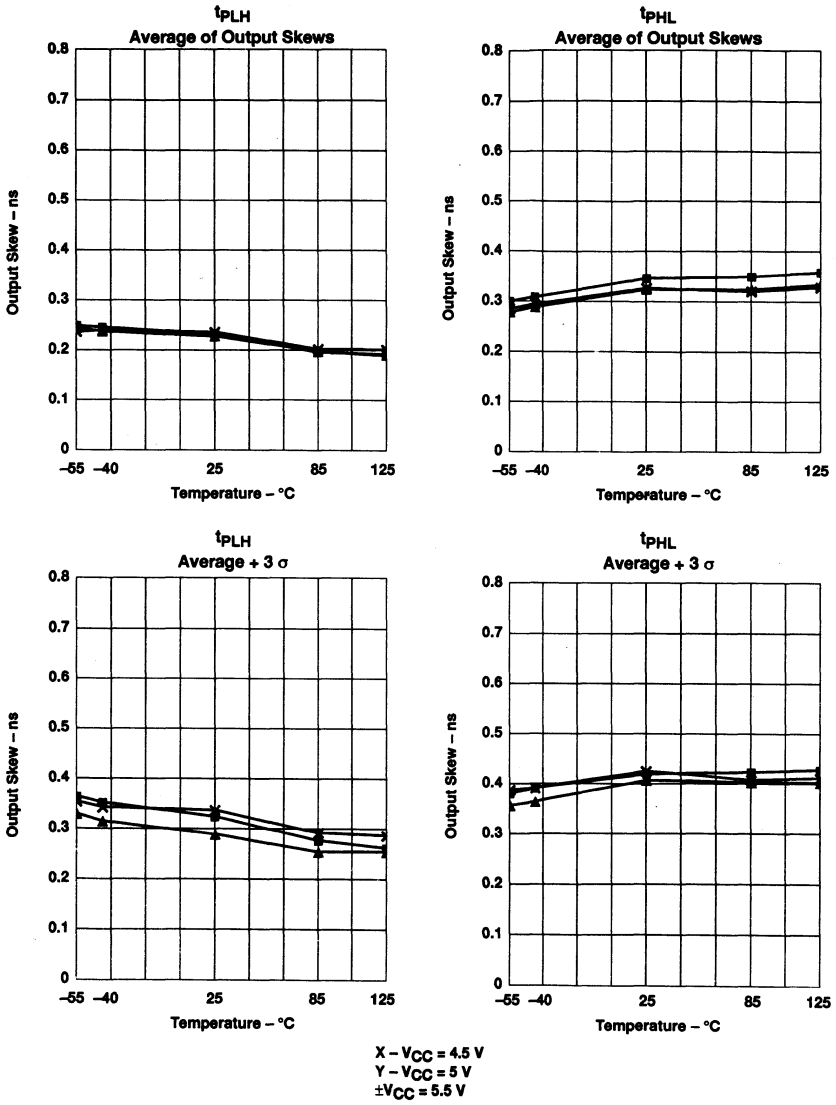

Figure 8. 'ABT244 – Single Switching

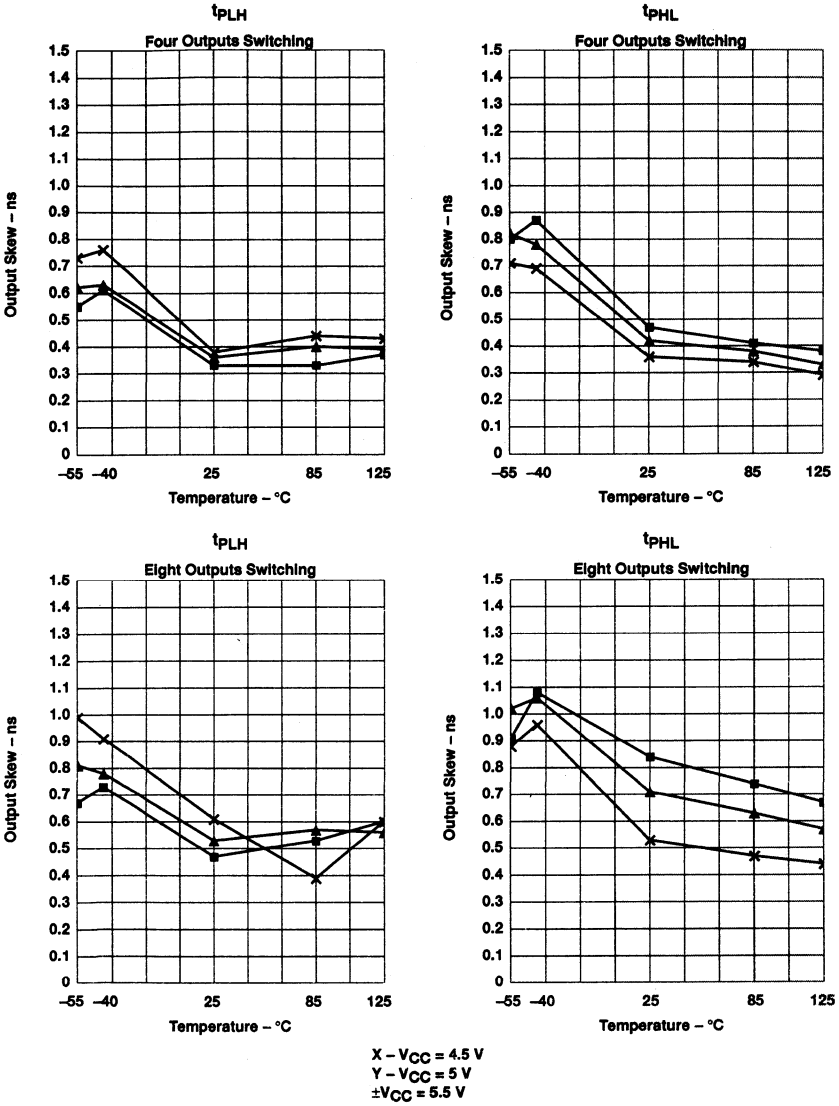

Figure 9. 'ABT244 – Multiple-Output Switching

Thermal Characteristics of Standard Linear and Logic (SLL) Packages and Devices

SCZA005
March 1997

TEXAS INSTRUMENTS

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Contents

Thermal Considerations for Standard Linear and Logic (SLL) Packages and Devices

Users of Texas Instruments (TI™) SLL products must consider device power dissipation, package power capability, and maximum ambient temperatures when designing with these products. The product users also need to be aware of the long-term reliability impact of maximum device-junction temperatures.

This application report is intended to help users understand and evaluate these factors. Three concepts — package thermal performance, device power dissipation, and reliability — are discussed in separate sections.

The first section, *Package Thermal Performance*, includes data about the recently developed JEDEC standard (EIA/JEDEC-Std-JESD51) for package thermal impedance measurement. It discusses most SLL package types and lists θ_{JA} (thermal impedance) values for those packages.

The second section, *Power Calculation*, discusses the power consumption by CMOS and BiCMOS/bipolar semiconductors. Standard formulas are given that allow the user to calculate the maximum power dissipated by a device in a typical application using data-book specifications, operating frequency, and voltage. The only characteristic not readily known is the output loading of the devices under consideration.

The third section, *Benefits of Minimizing Power Consumption*, discusses ways to reduce power consumption and the benefits thereof.

The final section, *Reliability Implications*, discusses the effects of chip temperature on reliability and electromigration. Information presented in this section allows the user to make an informed judgment as to the maximum chip temperature versus device wearout acceptable in the particular application.

The recommended analysis procedure is to assume a maximum chip temperature (see *Reliability Implications*) then, using θ_{JA} values for the chosen package (see *Package Thermal Performance*) and the known environmental requirements, calculate the maximum permissible power for that package. The formula presented in the *Power Calculation* section can then be used to ensure the operating conditions do not exceed the power capability of the chosen package type. Of course, the user can choose to calculate the maximum power from the application, then select a package that can meet the power dissipation requirement.

Package Thermal Performance

The most common measure of package thermal performance is thermal impedance (θ_{JA}) measured (or modeled) from the chip junction to the air surrounding the package surface (ambient). The mathematical expression for θ_{JA} is:

$$\theta_{JA} = \frac{T_j - T_a}{P} \quad (1)$$

Where:

T_j = chip junction temperature
T_a = ambient temperature
P = device power dissipation

θ_{JA} values are also the most subject to interpretation. Factors that can greatly influence the measurement and calculation of θ_{JA} are:

- Whether or not the device is board mounted
- Trace size, composition, thickness, and geometry
- Orientation of the device (horizontal or vertical)
- Volume of the ambient air surrounding the device under test and airflow
- Whether other surfaces are in close proximity to the device being tested

JEDEC established the JC 15.1 committee, comprising industry representatives, to develop industry-standard specifications for thermal testing. The specifications include development of electrical test procedures, careful descriptions of appropriate test environments, guidelines for the design of thermal test chips, guidelines for thermal modeling, and specifications for component mounting. The specifications for component mounting are divided into a series for different package types. The specifications include test-board descriptions for low effective thermal-conductivity test boards with a single metal layer and high effective thermal-conductivity test boards with embedded solid copper planes simulating system power and ground planes.

In August 1996, the Electronics Industries Association released EIA/JEDEC Std JESD51-3 titled *Low Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages*. The standard describes guidelines with parameters for thermal-test-board design for low effective thermal conductivity (one signal layer in the trace fanout area) as differentiated from a multilayer printed-circuit board (PCB), which might include power and ground planes. The specified parameters include the area of the test board, the amount of copper traces on the test board, and the resulting trace fanout area, each important to the heat-sinking characteristics of the PCB. Prior to release of the standard, thermal-impedance data for similar packages varied widely within the industry due to the use of different test-board designs. As the industry adopts this standard methodology, thermal-impedance variations from test-board design should be minimized.

Key features of the standard test-board design are:

- Board thickness: 0.062 in.
- Board dimensions: 4.0 × 4.5 in. for packages > than 27 mm in length, 3.0 × 4.5 in. for packages ≤ 27 mm in length
- Trace thickness: 0.0028 in.
- Trace length: 25.0 mm (0.984 in.)

The SLL product group uses test boards designed to EIA/JEDEC Std JESD51-3 for thermal-impedance measurements. The parameters outlined in the standard also are used to set up thermal models. The thermal-model program used by SLL is ThermCAL, a finite-difference thermal-modeling tool.

Eleven SLL packages were tested using a JEDEC test-board design and compared to ThermCAL model results to validate the correlation between model results and data (see Table 1). This comparison shows that the models are accurate to within 10% of measured data. In many cases the model data varies from measured data by less than 5%.

Table 1. Package Comparison

PACKAGE TYPE (PINS, DESIGNATION)	DIE SIZE (mils)	θ_{JA} MEASURED (°C/W)	θ_{JA} MODELED (°C/W)	CHANGE (%)
56 DL	120 x 120	73.5	78.3	6.5
20 DW	62 x 62	96.6	90.9	–5.9
160 PCM	240 x 240	34.9	34.9	0
52 PAH†	120 x 120	87.2	92.2	5.7
52 PAH‡	120 x 120	72.7	75.2	3.4
100 PZ	360 x 360	45	42.8	–4.9
208 PDV	240 x 240	50.1	52.8	5.4
48 DGG	120 x 120	89.1	93.5	4.9
14 DGV	62 x 62	181.5	191.7	5.6
48 DGV	62 x 186	92.9	89.9	–3.2
100 PCA	240 x 240	33.3	34.9	4.8

† S-pad leadframe
‡ Conventional leadframe

After the accuracy of the model results was established, all other SLL packages could be modeled. θ_{JA} data based on EIA/JEDEC Std JESD51-3 is available for all SLL leaded surface-mount packages (see Table 2). The data is grouped by package type with values of θ_{JA} shown at different airflow levels. Leadframe pad size and die size are shown.

Junction-to-case thermal-impedance (θ_{JC}) data is shown with the junction-to-ambient data. Measured θ_{JC} data was generated for the packages tested using the JEDEC PCB. Previously published values of θ_{JC} are used for packages not yet tested using the PCB designed to EIA/JEDEC Std JESD51-3.

Table 2. SLL Package Thermal-Impedance Data

PIN COUNT	TI PACKAGE	JEDEC SPECIFICATION	PAD SIZE (mils)	CHIP SIZE (mils)	θ_{JA} (°C/W) AT AIRFLOW (LFM)				MEASURED/ MODELED	θ_{JC} (°C/W)
					0	150	250	500		
SOIC										
14	D	MS-012	70 × 70	32 × 37	126.6	104	96.4	87.4	Modeled	46
16	D	MS-012	90 × 90	44 × 65	112.6	91.2	83.9	74.8	Modeled	42
20	DW	MS-013	90 × 110	62 × 62	96.6	82.2	77.7	71.5	Measured	38.3
24	DW	MS-013	140 × 160	84 × 122	80.7	53.7	47.5	40.7	Modeled	25
28	DW	MS-013	120 × 140	90 × 128	78.2	54.3	48.4	41.9	Modeled	
SSOP										
14	DB	MO-150	71 × 71	43 × 52	158	128.6	118.9	106.5	Modeled	47
16	DB	MO-150	83 × 91	51 × 61	130.8	105.9	97.3	86.5	Modeled	47
20	DB	MO-150	87 × 106	61 × 65	114.6	92	84	74.7	Modeled	45
24	DB	MO-150	87 × 106	74 × 91	104.2	83.5	76.3	67.5	Modeled	42
28	DL	MO-118	150 × 180	97 × 142	97	77.2	70.9	63.1	Modeled	
48	DL	MO-118	120 × 180	73 × 128	93.5	69.9	63.8	57.1	Modeled	26
56	DL	MO-118	150 × 220	120 × 120	73.5	62.3	59	54.6	Measured	27.3
QSOP										
20	DBQ	MS-137	96 × 140	61 × 75	118.1	95.3	86.9	76.7	Modeled	46
24	DBQ	MS-137	96 × 140	61 × 75	113	92	84.1	74.6	Modeled	42
PLCC										
28	FN	MS-018	300 × 348	214 × 319	70.9	58.8	52.7	46	Modeled	26.7
44	FN	MS-018	270 × 270	235 × 235	46.2	38.6	35.4	31.6	Modeled	22
68	FN	MS-018	325 × 325	280 × 280	39.3	33	30.5	27.6	Modeled	14.5
84	FN	MS-018	275 × 275	188 × 185	39.7	33.9	31.8	29.4	Modeled	11.9
QFP										
52	RC	MS-022	210 × 210	120 × 120	78.9	48.4	43.6	38.1	Modeled	20
80	PH		265 × 265	232 × 240	76.1	67.9	61.4	53.6	Modeled	15.1
132	PQ	MO-069	315 × 315	272 × 272	46.3	34.5	31.6	28.3	Modeled	9.8
144	PCM	MS-022	433 × 433	338 × 338	38.8	27.3	25.1	22.4	Modeled	14.5
160	PCM	MS-022	511 × 511	433 × 433	34.9	29.9	28.3	24.7	Measured	11.4
208	PPM	MO-143	413 × 413	268 × 268	36.7	30.4	28.1	26.7	Modeled	
TQFP										
52	PAH	MO-136	S-Pad	120 × 120	87.2	76.1	71.5	67	Measured	28.3
52	PAH	MO-136	3.5 × 3.5 mm	120 × 120	72.7	62.6	59.2	53.8	Measured	24.0
64	PM	MO-136	6.75 × 6.75 mm	235 × 235	66.9	53.6	47.6	40.6	Modeled	10.4
64	PAG	MO-136	S-Pad	240 × 240	58.2	48.8	45.2	40.3	Measured	22.6
80	PN	MO-136	S-Pad	240 × 240	61.5	52.8	49.3	44.6	Measured	26.4
100	PZ	MO-136	S-Pad	360 × 360	45	38.3	35.3	27.9	Measured	7.6
100	PZ	MO-136	S-Pad	240 × 240	50.1	42.7	40.4	36.8	Measured	21.1
100	PCA	MO-136	6.5 × 6.5 mm	240 × 240	33.3	24.7	21.8	19.2	Measured	4.3
120	PCB	MO-136	6.5 × 6.5 mm	240 × 240	28.1	22.3	21	18	Modeled	3.3
144	PGE	MO-136	342 × 350	378 × 378	48.3	39.1	35.5	31	Modeled	9.9
208	PDV	MO-136	S-Pad	240 × 240	50.1	43.63	40.9	37.3	Measured	9.9

Table 2. SLL Package Thermal-Impedance Data (Continued)

PIN COUNT	TI PACKAGE	JEDEC SPECIFICATION	PAD SIZE (mils)	CHIP SIZE (mils)	θ_{JA} (°C/W) AT AIRFLOW (LFM)				MEASURED/ MODELED	θ_{JC} (°C/W)
					0	150	250	500		
SOP										
14	NS	EIAJ-TYPE-II	79 × 87	55 × 57	127.1	103.7	95.5	85.2	Modeled	95
16	NS	EIAJ-TYPE-II	87 × 142	76 × 86	111.3	89.3	81.4	71.5	Modeled	95
20	NS	EIAJ-TYPE-II	87 × 118	60 × 77	100.3	82.8	76.2	68	Modeled	90
TSSOP										
14	PW	MO-153	71 × 71	48 × 53	169.8	146.7	136	121.7	Modeled	35
16	PW	MO-153	104 × 104	56 × 76	148.9	127.9	117.6	103.9	Modeled	35
20	PW	MO-153	102 × 106	53 × 69	128	110.6	101.9	90.8	Modeled	34
24	PW	MO-153	94 × 140	74 × 91	119.9	98.8	90.6	80	Modeled	33
48	DGG	MO-153	4.6 × 3.2 mm	120 × 120	89.1	78.5	75.1	69.4	Measured	25.2
56	DGG	MO-153	3.94 × 5.08 mm	132 × 176	81.2	72.8	65.8	57.9	Modeled	13
64	DGG	MO-153	5.7 × 3.6 mm	120 × 120	72.9	63.3	61.8	57.1	Measured	21.3
TVSOP										
14	DGV	MO-194	75 × 75	62 × 62	181.5	165.8	159.5	150.4	Measured	66.7
16	DGV	MO-194	75 × 75	65 × 65	179.6	153.2	141.7	126.3	Modeled	
20	DGV	MO-194	104 × 104	94 × 94	146.1	122.3	111.6	97.4	Modeled	
24	DGV	MO-194	104 × 104	94 × 94	138.6	116.2	106.2	93.2	Modeled	
48	DGV	MO-194	100 × 240	62 × 186	92.9	80.9	77.1	71	Measured	27.2
56	DGV	MO-194	100 × 274	90 × 262	85.9	64.6	57.1	48.4	Modeled	
80	DBB	MO-194	100 × 224	93 × 203	105.6	78.4	71.8	63.7	Modeled	
PDIP (assumes zero trace length)										
8	P	MS-001			104					41
14/16	N	MS-001			78					32
20	N	MS-001			67					33
24	NT	MS-001			67					25
		BGA								
256	GFN	MO-151			42				ANAM data	6.2
388	GFW	MO-151			18.9				Model data	

Power Calculation

Reduction of power consumption makes a device more robust and reliable. When calculating the total power consumption of a circuit, both the static and the dynamic currents must be taken into account. Both bipolar and BiCMOS devices have varying static-current levels, depending on the state of the output (I_{CCL}, I_{CCH}, or I_{CCZ}), while a CMOS device has a single value for I_{CC}. These values can be found in the individual data sheets. TTL-compatible CMOS and BiCMOS inputs, when driven at TTL levels, also consume additional current because they may not be driven all the way to V_{CC} or GND; therefore, the input transistors are not switched completely off. This value, known as ΔI_{CC}, also is provided in the data sheet.

Due to the high operating frequencies, there is a strict limit on power consumption in computer systems. Therefore, allowable power consumption for each device on a board must be minimized. Power calculations are made to determine power-supply sizing, current requirements, cooling/heatsink requirements, and criteria for device selection. Power calculation also can determine the maximum reliable operating frequency.

There are two components that establish the amount of power consumption in a CMOS circuit:

- Static power consumption
- Dynamic power consumption

Dynamic power consumption results from charging and discharging external load and internal parasitic capacitances. The parameter for CMOS device parasitic capacitance is C_{pd}, which is listed in the data sheet and is obtained using equations 2 and 3:

$$C_{pd} = \frac{I_{CC}}{V_{CC} \times f_I} - C_{L(eff)} \quad (2)$$

$$C_{L(eff)} = C_L \times N_{SW} \times \frac{f_O}{f_I} \quad (3)$$

To explain the C_{pd} and the method of calculating dynamic power, see Table 3, which indicates the C_{pd} test conditions for AHC devices. The symbols used in Table 3 are:

V = V_{CC} (5 V)
G = ground (0 V)
1 = high logic level = V_{CC} (5 V)
0 = low logic level = ground (0 V)
X = don't care: 1 or 0, but not switching
C = 50% duty cycle input pulse (1 MHz) (see Figure 1)
D = 50% duty cycle input (1/2 frequency) out-of-phase input pulse (see Figure 1)
S = standard ac output load (50 pF to GND)

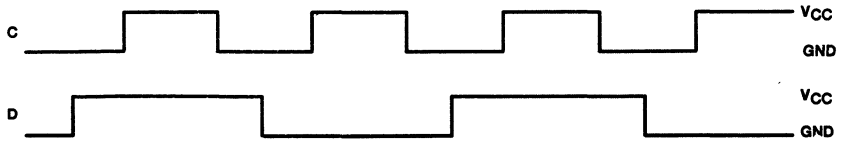


Figure 1. Input Waveform

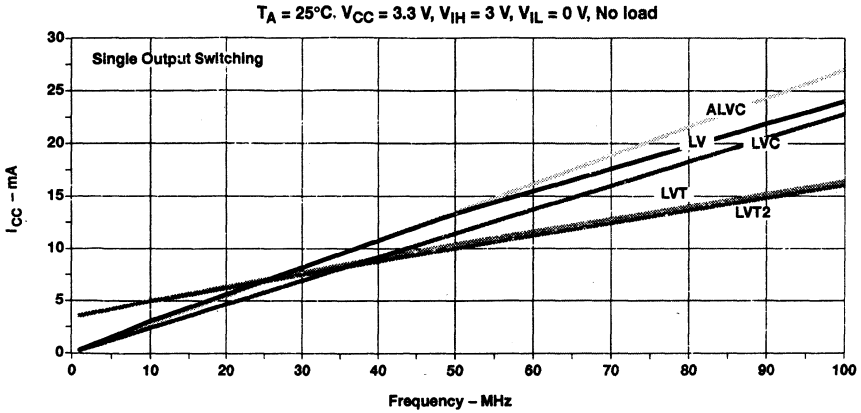
Table 3 shows the switching of each pin for AHC devices. Once the C_{pd} is determined from the table, the P_D is easy to calculate using equations explained in the following sections.

Although a C_{pd} value is not provided for ABT and LVT, the I_{CC} versus frequency curves display essentially the same information (see Figures 2 and 3). The slope of the curve provides a value in the form of mA/(MHz × bit), which when multiplied by the number of outputs switching and the desired frequency, provides the dynamic power dissipated by the device without the load current. Equations 4 through 14 can be used to calculate total power for CMOS or BiCMOS devices.

Table 3. C_{pd} Test Conditions With One- or Multiple-Bit Switching

TYPE	PIN NO.																			
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
AHC00	C	1	S	X	X	S	G	S	X	X	S	X	X	V						
AHC02	S	C	0	S	X	X	G	X	X	S	X	X	S	V						
AHC04	C	S	X	S	X	S	G	S	X	S	X	S	X	V						
AHC08	C	1	S	X	X	S	G	S	X	X	S	X	X	V						
AHC10	C	1	X	X	X	S	G	S	X	X	X	S	1	V						
AHC11	C	1	X	X	X	S	G	S	X	X	X	S	1	V						
AHC14	C	S	X	S	X	S	G	S	X	S	X	S	X	V						
AHC32	C	1	S	X	X	S	G	S	X	X	S	X	X	V						
AHC74	1	D	C	1	S	S	G	S	S	X	X	X	1	V						
AHC86	C	1	S	X	X	S	G	S	X	X	S	X	X	V						
AHC138	C	0	0	0	0	1	S	G	S	S	S	S	S	S	S	V				
AHC139	0	C	0	S	S	S	S	G	S	S	S	S	X	X	X	V				
AHC240	0	C	S	X	S	X	S	X	S	G	X	S	X	S	X	S	X	S	X	V
AHC244	0	C	S	X	S	X	S	X	S	G	X	S	X	S	X	S	X	S	X	V
AHC245	1	C	X	X	X	X	X	X	X	G	S	S	S	S	S	S	S	S	0	V
AHC373†	0	S	D	D	S	S	D	D	S	G	C	S	D	D	S	S	D	D	S	V
AHC374‡	0	S	D	D	S	S	D	D	S	G	C	S	D	D	S	S	D	D	S	V
AHC540	0	C	X	X	X	X	X	X	X	G	S	S	S	S	S	S	S	S	0	V
AHC541	0	C	X	X	X	X	X	X	X	G	S	S	S	S	S	S	S	S	0	V
AHC573†	0	D	D	D	D	D	D	D	D	G	C	S	S	S	S	S	S	S	S	V
AHC574‡	0	D	D	D	D	D	D	D	D	G	C	S	S	S	S	S	S	S	S	V

† All bits switcning, but with no active clock signal
‡ All bits switching



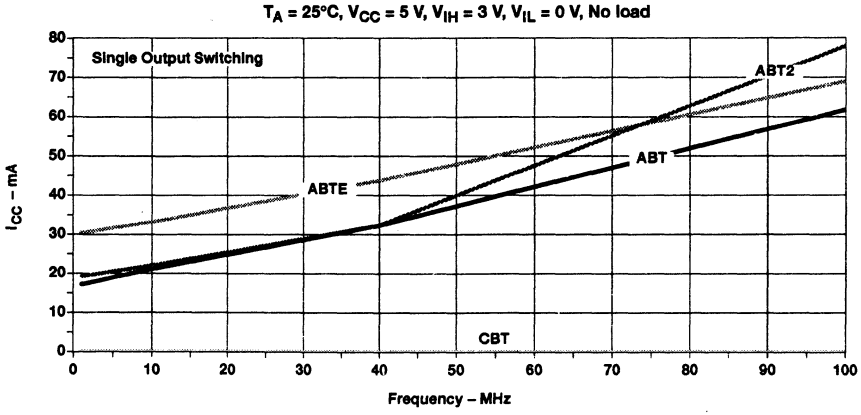


Figure 2. Power Consumption With a Single Output Switching

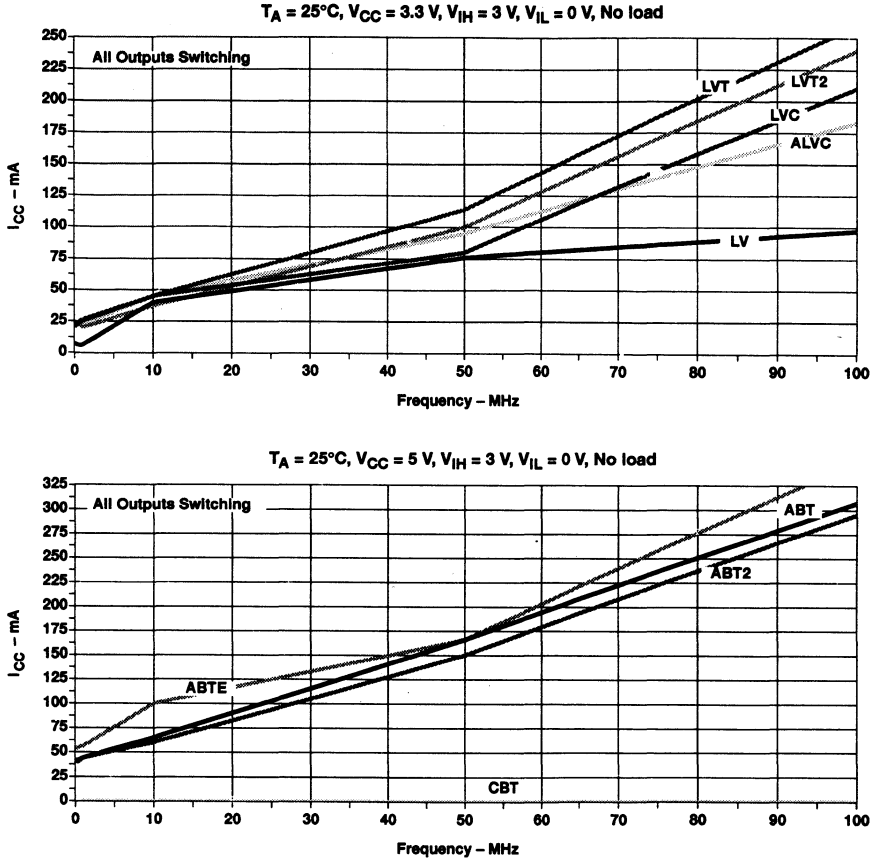


Figure 3. Power Consumption With All Outputs Switching

CMOS

CMOS-Level Inputs

Static power consumption can be calculated using equation 4.

$$P_s = V_{CC} \times I_{CC} \quad (4)$$

The dynamic power consumption of a CMOS device is calculated by adding the transient-power consumption and capacitive-load power consumption.

Transient Power Consumption

The transient power is due to the current that flows only when the transistors of the devices are switching from one logic state to another. This power is a result of the current required to charge the internal nodes (*switching current*) plus the current that flows from V_{CC} to GND when the p-channel and n-channel transistors turn on briefly at the same time during the logic transition (*through current*). The frequency at which the device is switching, plus the rise and fall time of the input signal, as well as the internal nodes of the device, have a direct effect on the duration of the current spike. For fast input transition rates, the through current of the gate is negligible in comparison with the switching current. For this reason, the dynamic supply current is governed by the internal capacitance of the device and the charge and discharge current of the load capacitance.The transient power consumption can be calculated using equation 5.

$$P_T = C_{pd} \times V_{CC}^2 \times f_I \times N_{SW} \quad (5)$$

In case of single-bit switching, N_{SW} in equation 5 becomes 1.

Capacitive-Load Power Consumption

Additional power is consumed in charging of external load capacitance and is dependent on switching frequency. Equation 6 can be used to calculate this power while all outputs have the same load and are switching at the same output frequency.

$$P_L = C_L \times V_{CC}^2 \times f_O \times N_{SW} \text{ (C_L is the load per output)} \quad (6)$$

In case of different loads and different output frequencies at all outputs, equation 7 is used to calculate capacitive load power consumption.

$$P_L = \Sigma(C_{Ln} \times f_{On}) \times V_{CC}^2 \quad (7)$$

Therefore, dynamic power consumption (P_D) is the sum of these two power consumptions, and is expressed in equation 8 (single-bit-switching case) and 9 (multiple-bit switching with variable load and variable output frequencies):

$$P_D = (C_{pd} \times f_I \times V_{CC}^2) + (C_L \times f_O \times V_{CC}^2) \quad (8)$$

$$P_D = \left[(C_{pd} \times f_I \times N_{SW}) + \Sigma(C_{Ln} \times f_{On})\right]V_{CC}^2 \quad (9)$$

Total power consumption with a CMOS-level input is the sum of static and dynamic power consumption.

TTL-Level Inputs

Similarly, with TTL-level inputs, both static and dynamic power consumption can be calculated using equations 10, 11, and 12.

$$P_S = V_{CC}[I_{CC} + (N_{TTL} \times \Delta I_{CC} \times DC_d)] \quad (10)$$

$$P_D = (C_{pd} \times f_I \times V_{CC}^2) + (C_L \times f_O \times V_{CC}^2) \text{ (single-bit switching)} \quad (11)$$

$$P_D = \left[(C_{pd} \times f_I \times N_{SW}) + \Sigma(C_{Ln} \times f_{On})\right]V_{CC}^2 \quad (12)$$

(multiple-bit switching with variable load and frequency)

BiCMOS

Static Power

$$P_S = V_{CC}\left\{DC_{en}\left[\left(N_H \times \frac{I_{CCH}}{N_T}\right) + \left(N_L \times \frac{I_{CCL}}{N_T}\right)\right] + (1 - DC_{en})I_{CCZ} + (N_{TTL} \times \Delta I_{CC} \times DC_d)\right\} \quad (13)$$

Where:

ΔI_{CC} = 0 for bipolar devices

NOTE:
For a continuous waveform at 50% duty cycle, DC_{en} = 1.

Equation 13 becomes:

$$P_S = V_{CC}\left[\left(N_H \times \frac{I_{CCH}}{N_T}\right) + \left(N_L \times \frac{I_{CCL}}{N_T}\right)\right] \quad (14)$$

NOTE:
If half of the time the waveform is high and half of the time the waveform is low and the waveform is switching continuously, $\Rightarrow (N_H = N_L = 1/2\ N_T)$, P_S becomes:

$$P_S = \left(\frac{V_{CC}}{2}\right)(I_{CCH} + I_{CCL}) \quad (15)$$

Dynamic Power

$$P_D = (DC_{en} \times N_{SW} \times V_{CC} \times f \times I_{CCD}) \text{ Condition is } 50\ pF \parallel 500\ \Omega \quad (16)$$

I_{CCD} is calculated with 50 pF ‖ 500 Ω, and given number of outputs switching.

NOTE:
For a continuous waveform at 50% duty cycle, $DC_{en} = 1$.

Dynamic power with external capacitance:

$$P_D = DC_{en} \times N_{SW} \times V_{CC} \times f \times (V_{OH} - V_{OL}) \times (C_L - 50\ pF) + DC_{en} \times N_{SW} \times V_{CC} \times f \times I_{CCD} \quad (17)$$

I_{CCD} is calculated with 50 pF ‖ 500 Ω, and given number of output switching.

Power is also consumed by the upper output driver due to the output resistor (500 Ω in most load circuits for outputs in the data sheet). This power is very small but must be included in the dynamic power consumption calculation. Equation 18 is used to calculate this power consumption.

$$P_{\_Res} = (V_{CC} - V_{OH}) \times \frac{V_{OH}}{R} \quad (18)$$

NOTE:
Assume that the output waveform is always at logic high and is not frequency dependent.

Therefore, total dynamic power consumption is:

$$P_{D\_TOT} = P_D + P_{\_Res} \quad (19)$$

Finally, total power consumption can be calculated as:

$$P_{\_Total} = P_{D\_TOT} + P_S \quad (20)$$

Where:

V_{CC} = supply voltage (V)
I_{CC} = power-supply current (A) (from the data sheet)
I_{CCL} = power-supply current when outputs are in low state (A) (from the data sheet)
I_{CCH} = power-supply current when outputs are in high state (A) (from the data sheet)
I_{CCZ} = power-supply current when outputs are in high-impedance state (A) (from the data sheet)
ΔI_{CC} = power-supply current when one input is at a TTL level (A) (from the data sheet)
DC_{en} = % duty cycle enabled (50% = 0.5)

DC_d = % duty cycle of the data (50% = 0.5)
N_H = number of outputs in high state
N_L = number of outputs in low state
N_{sw} = total number of outputs switching
N_T = total number of outputs

N_{TTL} = number of inputs driven at TTL levels

fi = input frequency (Hz)
f_O = output frequency (Hz)
f = operating frequency (Hz)
V_{OH} = output voltage in high state (V)
V_{OL} = output voltage in low state (V)
C_L = external-load capacitance (F)
I_{CCD} = slope of the I_{CC} versus frequency curve (A/Hz × bit)

$C_{L(eff)}$ = effective-load capacitance (F)
f_O/f_I = ratio of output and input frequency (Hz)
P_T = transient power consumption
P_D = dynamic power consumption
P_S = static power consumption
$P_{\_Res}$ = power consumption due to output resistance
P_{D_TOT} = total dynamic power consumption
$P_{\_Total}$ = total power consumption

C_{PD} = dynamic power dissipation capacitance (F)
P_L = capacitive-load power consumption
Σ = sum of n different frequencies and loads at n different outputs
f_{On} = all different output frequencies at each output numbered 1 through n (Hz)
C_{Ln} = all different load capacitances at each output numbered 1 through n

For GTL and BTL/FB devices, the power consumption/calculation is similar to a BiCMOS device with the addition of the output power consumption through the pullup resistor, since GTL is open drain and BTL/FB is open collector.

The total power calculated using these equations should be less than the package power dissipation mentioned in the data sheets. Otherwise, the device might not function properly.

Benefits of Minimizing Power Consumption

Power consumption can be minimized in a number of ways. DC power consumption can be reduced to leakage by using only CMOS logic, as opposed to bipolar and BiCMOS logic. The leakage, in turn, is proportional to the area of diffusion, so the use of minimum-size devices is an advantage. Dynamic power consumption can be limited by reducing supply voltage, switched capacitance, and the frequency at which the logic is clocked. Supply voltage tends to be a system design consideration, and low-power systems use 1.5-V to 3.3-V supplies.

Power consumption is a function of the load capacitance, the frequency of operation, and the supply voltage. A reduction of any one of these is beneficial. A reduction in power consumption provides several other benefits. Less heat is generated, which reduces problems associated with high temperature, such as the need for heatsinks. This provides the consumer with a product that costs less. Furthermore, the reliability of the system is increased due to lower temperature stress gradients on the device, and the integrity of the signal is improved due to the reduction of ground bounce and signal noise. An additional benefit of the reduced power consumption is the extended life of the battery in battery-powered systems.

Reliability Implications

The IC component power dissipation during operation elevates the device junction temperature. The thermal impedance (θ_{JA} or k-factor) of an IC package is defined as the increase in the junction temperature, above ambient temperature, due to the device power dissipation. Thermal impedance is measured in degrees Celsius per watt. Thermal characteristics of an IC package are commonly described using two indices, Q_{JA} (junction to ambient) and Q_{JC} (junction to case). Controlling the junction temperature within a desired range is critical for proper device functionality and long-term reliability.

Table 4, based on long-term sustained temperatures, shows the relationship between junction temperature and predicted failure rate.

Table 4. Junction Temperature Versus 100,000-Hour Predicted Failure Rate

JUNCTION TEMPERATURE (°C)	FAILURE RATE (%)
100	0.02
110	1
120	11
130	46
140	80
150	96

Higher component temperatures increase the possibility of component wearout due to such failure mechanisms as electromigration and ball-bond intermetallic failures.

Thermal Definitions

Heat — A form of energy associated with the motion of atoms or molecules in solids, and capable of being transmitted through solid and fluid media by conduction, through fluid media by convection, and through empty space by radiation

Conduction Heating — The most commonly recognized form of heat transfer. Metal materials are good conductors of heat and can be quantified by a proportionality constant (k), also known as thermal conductivity. The higher the thermal-conductivity number, the more quickly heat transfer, by means of conduction, occurs. Leadframes are the primary media for conduction heating in plastic ICs; however, mold compound materials play a major role in this type of heat transference.

Convection Heating — The heat transfer by fluid motion between regions of unequal density that result from nonuniform heating. This type of heat transfer is most commonly seen when air is forced across a heated surface, resulting in the cooling of the heat source. Heat is transferred to the air by means of convection heating. The rate of heat transfer depends on the surface area of the heat source and the velocity and physical properties of the air flow. When an IC package is generating heat through normal operation, the IC package can be cooled by applying a constant air flow across the surface of the package.

Radiation — Radiant heat transfer occurs between two objects separated within a vacuum.

Ambient Temperature — The temperature of the surrounding air, usually used as a reference point to calculate the junction or case temperature. This temperature is measured at some specific distance from the IC component.

Case Temperature — The temperature on the package surface measured at the center of the top of the package

Junction Temperature — The temperature of the die inside the package of the IC component

Acknowledgment

The authors of this report are David Holmgreen, Doug Romm, Abul Sarwar, and Ron Eller. The thermal-model program, ThermCAL, was developed by Darvin Edwards.

References

1 Electronic Industries Association, EIA/JEDEC Std JESD51-3, *Low Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages*, August 1996.

2 Darvin Edwards, "Thermal Analysis Using FEA (v1.1)," November 1991.

3 Darvin Edwards, "Development of JEDEC Standard Thermal Measurement Test Boards."

ABT
Advanced BiCMOS Technology
Characterization Information

SCBA008B
June 1997

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Appendixes

Introduction

The purpose of this document is to assist the designers of high-performance digital logic systems in using the advanced BiCMOS technology (ABT) logic family.

Detailed electrical characteristics of these bus-interface devices are provided and tables and graphs have been included to compare specific parameters of the ABT family with those of other logic families.

In addition, typical data is provided to give the hardware designer a better understanding of how the ABT devices operate under various conditions.

The major subject areas covered in the report are as follows:

- AC Performance
- Power Considerations
- Input Characteristics
- Output Characteristics
- Signal Integrity
- Advanced Packaging
- Characterization Information

The characterization information provided is typical data and is not intended to be used as minimum or maximum specifications, unless noted as such.

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AC Performance

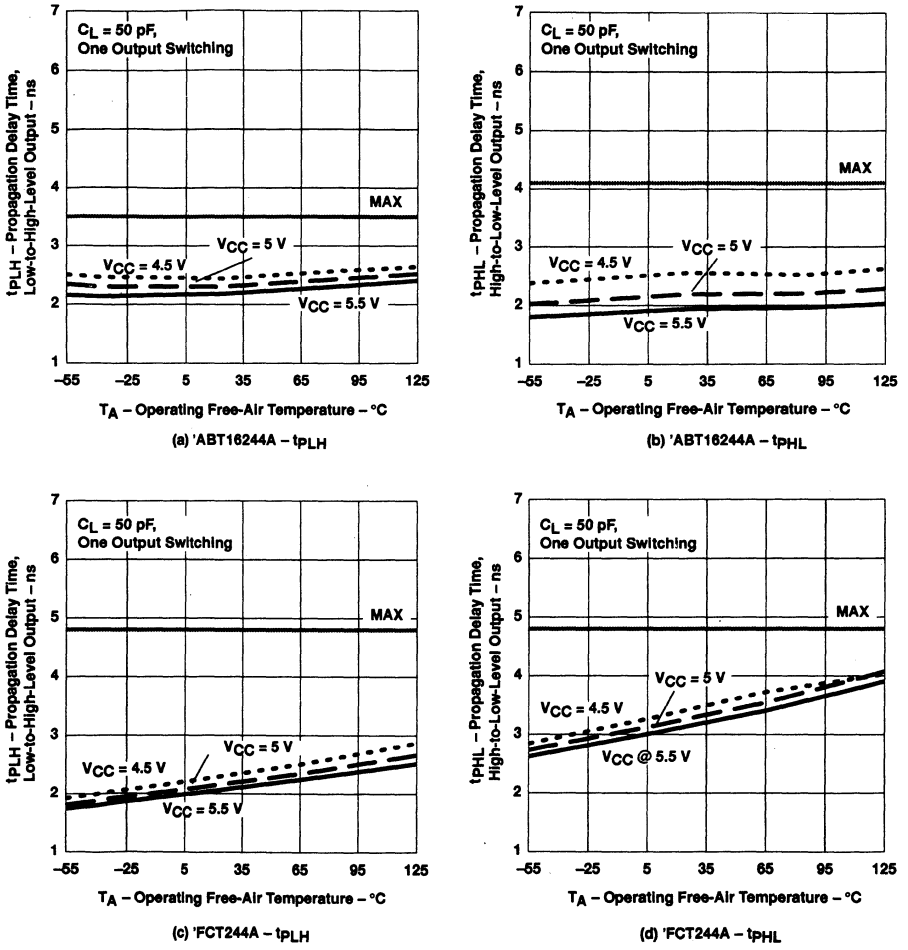
As microprocessor operating frequencies increase, the period of time allotted for operations, such as memory access or arithmetic functions, decreases. With this in mind, TI developed a family of bus-interface devices – ABT – utilizing advanced BiCMOS technology. The goal of the ABT family of devices is to give system designers one bus-interface solution that provides high drive capability, good signal integrity, and propagation delays short enough to appear transparent with respect to overall system performance.

Advances in IC process technology, including smaller minimum feature size, tighter metal pitch, and shallower junctions, combine to provide stronger drive strengths and smaller parasitic capacitances. As a result, internal propagation delays have become extremely short. With the advent of the 0.8-µm, EPIC-IIB™ BiCMOS process and new circuit innovations, the ABT family offers typical propagation delays as low as 2-3 ns as shown in Figure 1. Maximum specifications are as low as 3–5 ns, depending on the device type.

Figure 2 shows the propagation delay versus change in both temperature and supply voltage for an 'ABT16244A, 'FCT244A, and a 'F244 device. The graphs highlight two important aspects of the ABT logic family. First, ABT interface devices have extremely short propagation delay times. The figures clearly show the improvement in speed of an ABT device over that of a 74F and 74FCTA device. Second, the variance in speed with respect to both temperature and supply voltage is minimal for ABT. At low temperatures, the increase in CMOS performance compensates for the decrease in bipolar device strength. At high temperatures, the reverse occurs. This complementary performance of both CMOS and bipolar devices on a single chip results in a slope that is virtually flat across the entire temperature range of –55°C to 125°C.

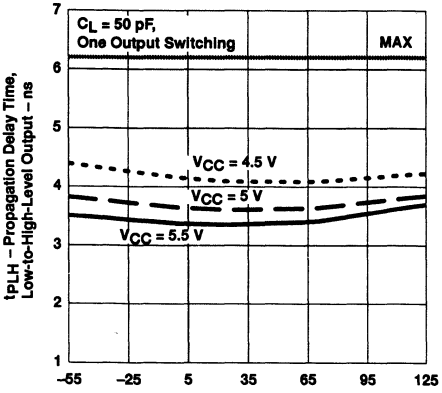
For most applications, the data sheet specifications may not provide all of the information a designer would like to see for a particular device. For instance, a designer might benefit from data such as propagation delay with multiple outputs switching or with various loads. This type of data is extremely difficult to test using automatic test equipment; therefore, it is provided in this document as family characteristics shown in Figure 2 and Figure 3.

To get a clear picture of where ABT stands in reference to other logic families, data is shown for a comparable (same function) 74F and 74FCTA device. It is clear that ABT is the designer's best choice for bus-interface applications that require consistent speed performance over various conditions.

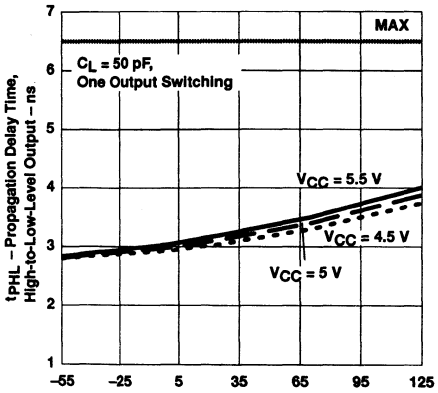


NOTE: MAX is data sheet specification

Figure 1. Propagation Delay vs Operating Free-Air Temperature A to Y



(e) 'F244 – t_{PLH}



(f) 'F244 – t_{PHL}

NOTE: MAX is data sheet specification.

Figure 1. Propagation Delay vs Operating Free-Air Temperature A to Y (Continued)

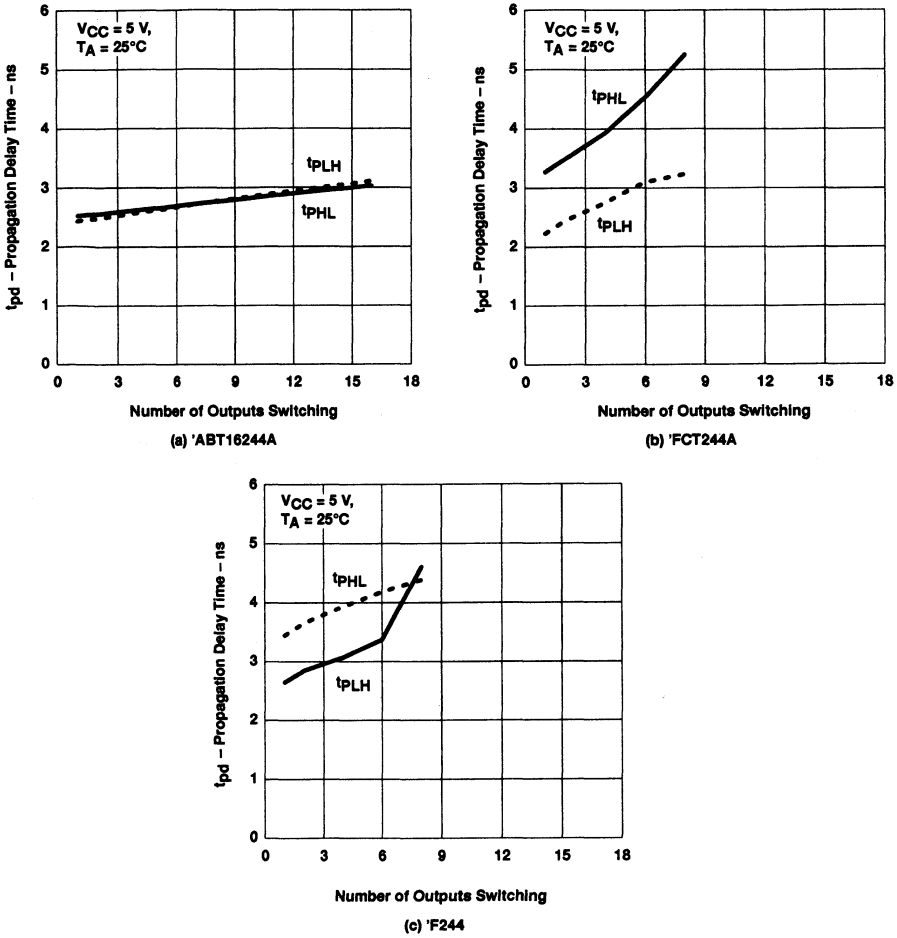


Figure 2. Propagation Delay Time vs Number of Outputs Switching

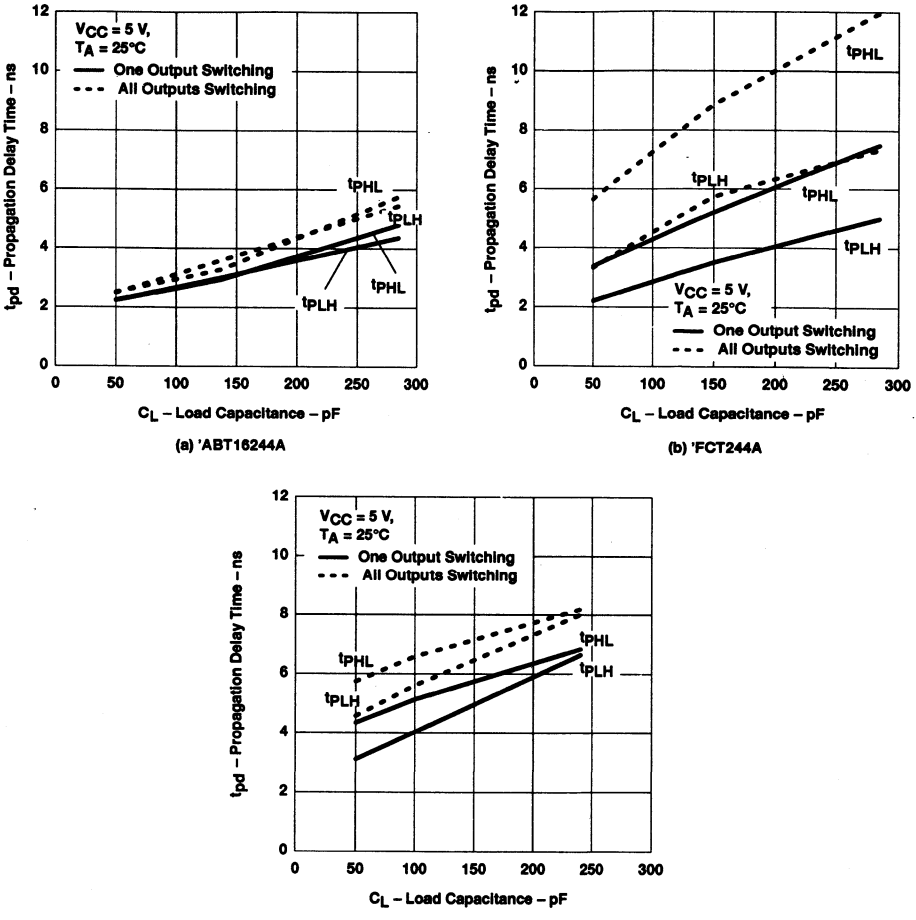


Figure 3. Propagation Delay vs Capacitive Load

Power Considerations

With the challenge to make systems more dense while improving performance comes the need to replace power-hungry devices without compromising speed. The ABT family of drivers provides a solution with low CMOS power consumption and high-speed bipolar technology on a single device.

There are two basic things to consider when calculating power consumption, static (dc) power, and dynamic power. Static power is calculated using the value of I_{CC} as shown in the data sheet. This is a dc value with no load on the outputs. To understand the relationship between pure CMOS, pure bipolar, and advanced BiCMOS for dc power rating, see Table 1, which shows the various data sheet values. The bipolar device shows the highest I_{CC} values, with little relief, regardless of the state of the outputs. This is not the case with ABT octals, which offer the low static power consumption of CMOS while in the high-impedance state, or when the outputs are high (I_{CCZ}, I_{CCH}).

Table 1. Supply Current

PARAMETER	TEST CONDITIONS		'F244		'FCT244		SN74ABT244	
			MIN	MAX	MIN	MAX	MIN	MAX
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		60 mA				250 µA
		Outputs low		90 mA				30 mA
		Outputs disabled		90 mA				250 µA
	V_{CC} = maximum, $V \geq V_{CC} - 0.2$ V, $V \leq V_{CC} - 0.2$ V					1.5 mA		

Dynamic power involves the charging and discharging of internal capacitances, as well as the external load capacitance. It is this dynamic component that makes up the majority of the total power dissipation. Figure 4 shows power as a function of frequency for ABT, FCT, and F devices. Although bipolar devices tend to have extremely high static power, there is a point on the frequency curve, commonly referred to as the crossover point, where the CMOS device no longer consumes less power. With ABT devices, the power increase at higher frequencies is less than that of the pure CMOS FCT.

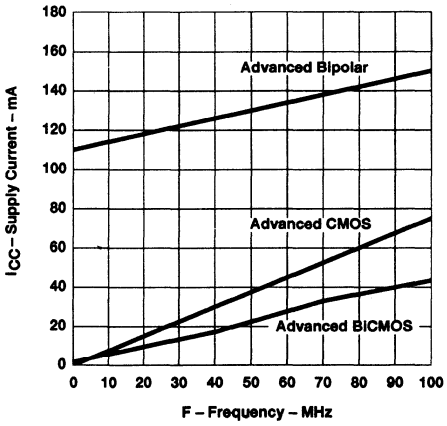


Figure 4. Supply Current vs Frequency

The use of bipolar transistors in the output stage is advantageous in two ways. First, the voltage swing is less than with a CMOS output, reducing the power consumed when charging or discharging the external load. Second, bipolar transistors are capable of turning off more efficiently than CMOS transistors, thus reducing the flow of current from V_{CC} to GND. Combined, these features allow for better power performance at high frequencies.

Input Characteristics

ABT bus-interface devices are designed to ensure TTL-compatible input levels switching between 0.8 V and 2 V (typically 1.5 V). Additionally, these inputs are implemented with CMOS circuitry, resulting in high impedance (low leakage) and low capacitance, which reduces overall bus loading. This section is an overview of the circuitry utilized for a typical ABT input, the corresponding electrical characteristics, and guidelines for proper termination of unused inputs.

ABT Input Circuitry

Figure 5 shows a typical ABT input schematic. A pure CMOS-input threshold is normally set at one-half of V_{CC}. To shift the threshold voltage to be centered around 1.5 V (see Figure 6), the supply voltage of the input stage is dropped by the diode, D1, and the transistor, Q1. Reducing the voltage at the source of Q_p enables it to turn off more efficiently when flow is from V_{CC} to GND (ΔI_{CC}). When the input is in the low state, Q_r raises the voltage of the source of Q_p to V_{CC} to ensure proper operation of the following stage. This feedback circuit provides approximately 100 mV of input hysteresis, which increases the noise margin and helps ensure the device is free from oscillations when operated within specified input ramp rates.

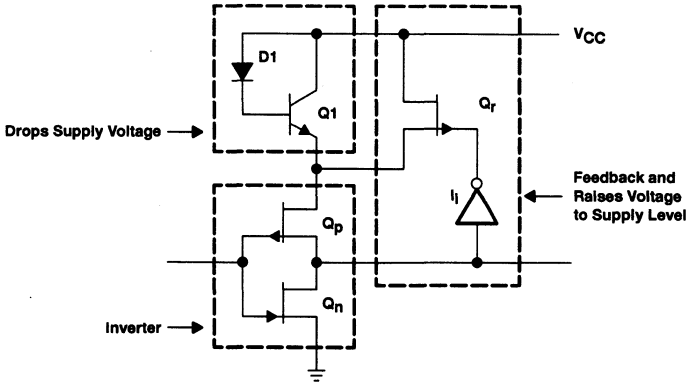


Figure 5. Simplified Input Stage of an ABT Circuit

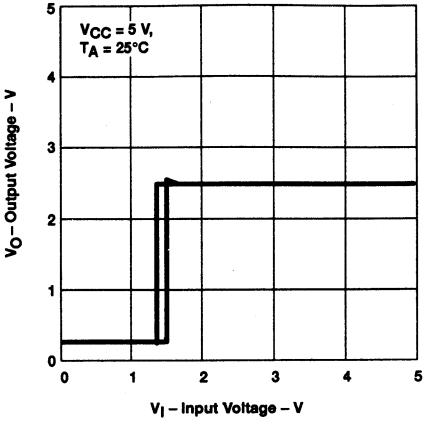


Figure 6. Output Voltage vs Input Voltage

Input Current Loading

The utilization of submicron (0.8-µm) CMOS technology for the input stage of ABT devices causes minimal loading of the system bus due to low leakage currents and low capacitance. The small geometries of the EPIC-IIB process have resulted in capacitances as low as 3 pF for inputs and 8 pF for C_{io} of a transceiver. Figure 7 and Table 2 indicate the low input current performance and specifications. Considering this low capacitance along with the negligible input current, systems designers can decrease their overall bus loading.

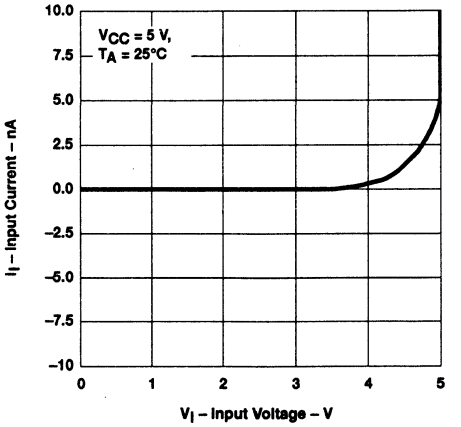


Figure 7. Input Current vs Input Voltage

Table 2. Input Current Specifications

PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT245		SN74ABT245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
I_{OZH}†	V_{CC} = 5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}†	V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA

† The parameters I_{OZH} and I_{OZL} include the input leakage current.

Supply Current Change (ΔI_{CC})

Because ABT devices utilize a CMOS-input stage but operate in a TTL-level signal environment, there is a current specification unique to this set of conditions known as ΔI_{CC}. Given a CMOS inverter with the input voltage set so that both the p and n channel devices are on, current flows from V_{CC} to GND. This can occur when the input to an ABT device is at a valid high level (>2 V), which turns on the n-channel, but not high enough to completely turn off the p-channel device. The current that flows under these conditions is specified in the data sheet (ΔI_{CC}) and is measured one input at a time with the input voltage set at 3.4 V. Figure 8 shows the change in I_{CC} as the input is ramped from 0 V to 5 V. For ABT non-storage devices, a feature is added that turns off the input when the outputs are disabled to reduce power consumption (see Table 3 for an example. Refer to individual data sheets for this specification).

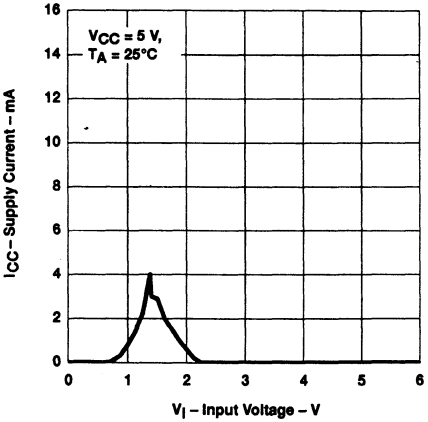


Figure 8. Supply Current vs Input Voltage

Table 3. Supply Current Change (ΔI_{CC})

PARAMETER	TEST CONDITIONS		T_A = 25°C		SN54ABT244		SN74ABT244		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
ΔI_{CC}†	V_I = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled		1.5		1.5		1.5	mA
		Outputs disabled		50		50		50	µA

† This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

Proper Termination of Unused Inputs

With advancements in speed, logic devices have become more sensitive to slow input edge rates. A slow input edge rate, coupled with the noise generated on the power rails when the output switches, can cause excessive output glitching or, in some cases, oscillations. Similar situations can occur if an unused input is left floating or not being actively held at a valid logic level.

These problems are due to voltage transients induced on the device's power system as the output load current (I_O) flows through the parasitic lead inductances during switching (see Figure 9). Since the device's internal power-supply nodes are used as voltage references throughout the integrated circuit, the inductive voltage spikes (V_{gnd}) affect the way signals appear to the internal gate structures. For instance, as the voltage at the device's ground node rises, the input signal (V_i') appears to decrease in magnitude. This undesirable phenomena can erroneously change the output's transition if a threshold violation takes place.

In the case of a slowly rising input edge, if the ground movement is large enough, the apparent signal, V_i', at the device appears to be driven back through the threshold and the output starts to switch in the opposite direction. If worst-case conditions prevail (simultaneously switching all of the outputs with large transient load currents) the slow input edge is repeatedly driven back through the threshold, resulting in output oscillation.

ABT devices are recommended to have input edge rates faster than 5 ns/V for standard parts, and 10 ns/V for the Widebus™ series of products when the outputs are enabled. A critical area for this edge rate is in the transition region between 1 V and 2 V. It is also recommended to hold inputs or I/O pins at a valid logic high or low when they are not being used or when the part driving them is in the high-impedance state.

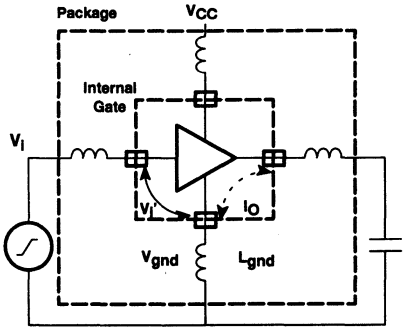


Figure 9. Sample Input/Output Model

Output Characteristics

The current trend is consolidation of the functionality of multiple logic devices into complex, high pin-count ASICs and programmables. There are a number of important advantages for utilizing bus-interface devices in standard high-volume packages. These include the need for high drive capability and good signal integrity. The use of bipolar circuitry in the output stage makes it possible to provide these requirements, along with increased speed, using the ABT family.

Figure 10 shows a simplified schematic of an ABT output stage. Data is transmitted to the gate of M1, which acts as a simple current switch. When M1 is turned on, current flows through R1 and M1 to the base of Q4, turning it on and driving the output low. At the same time, the base of Q2 is pulled low, thus turning off the upper output. For a low-to-high transition, the gate of M1 must be driven low, turning M1 off. Current through R1 charges the base of Q2, pulling it high and turning on the Darlington pair, consisting of Q2 and Q3. Meanwhile, with its supply of base drive cut off, Q4 turns off, and the output switches from low to high. R2 is used to limit output current in the high state, and D1 is a blocking diode used to prevent reverse current flow in specific power-down applications.

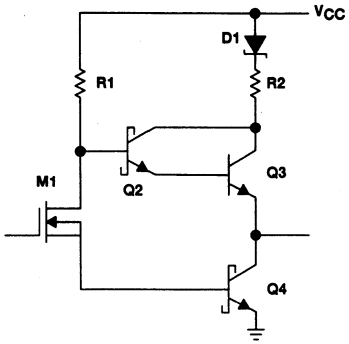


Figure 10. Simplified ABT Output Stage

A clear advantage of using bipolar circuitry in the output stage (as opposed to CMOS) is the reduced voltage swing. This helps to lower ground noise and reduce power consumption. Refer to *Signal Integrity* and *Power Considerations* in this document for further information.

Output Drive

The I_{OH} and I_{OL} curves for a typical ABT output are shown in Figure 11. With a specified I_{OL} of 64 mA and I_{OH} of –32 mA, ABT accommodates many standard backplane specifications. However, these devices are capable of driving well beyond these limits. This is important when considering switching a low-impedance backplane on the incident wave.

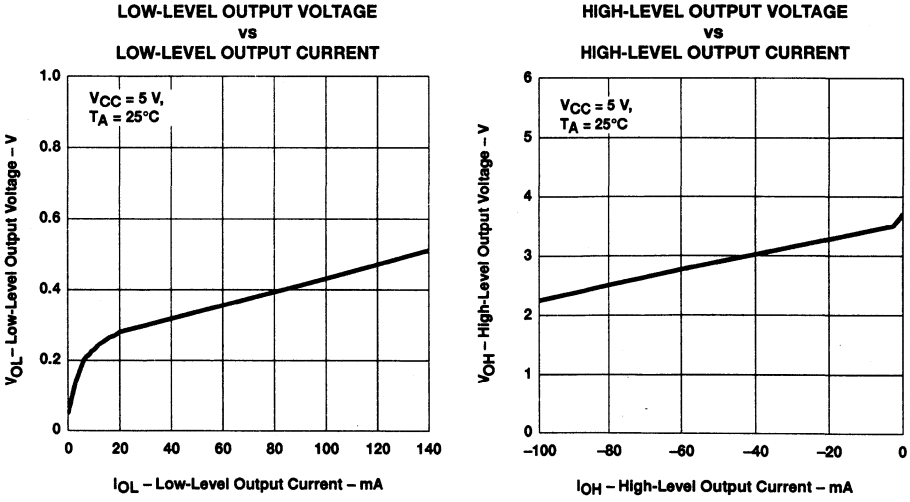


Figure 11. Typical ABT Output Characteristics

Incident-wave switching ensures that for a given transition (either high-to-low or low-to-high) the output reaches a valid V_{IH} or V_{IL} level on the initial wave front (i.e., does not require reflections). Figure 12 shows the problems a designer might encounter when a device does not switch on the incident wave. A shelf below $V_{IL(max)}$, signal A, causes the propagation delay to slow by the amount of time it takes for the signal to reach the receiver and reflect back. Signal B shows the case in which there is a shelf in the threshold region. When this happens, the input to the receiver is uncertain and could cause several problems associated with slow input edges, depending on the length of time the shelf remains in this region. A signal as shown in example C does not cause a problem because the shelf does not occur until the necessary V_{IH} level has been attained.

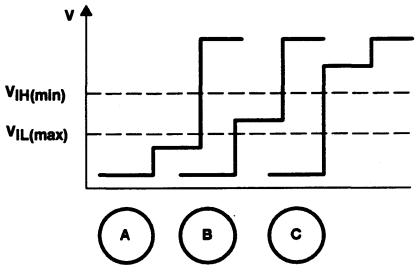


Figure 12. Reflected Wave Switching

Using typical V_{OH} and V_{OL} values along with data points from the curves, ABT devices can typically drive lines in the 25-Ω range on the incident wave.

For a low-to-high transition, (I_{OH} = 85 mA @ V_{OH} = 2.4 V)

$$Z_{LH} = \frac{V_{OH}(min) - V_{OL}(typ)}{I_{OH}} = \frac{2.4\ V - 0.3\ V}{85\ mA} = 25\ \Omega \quad (1)$$

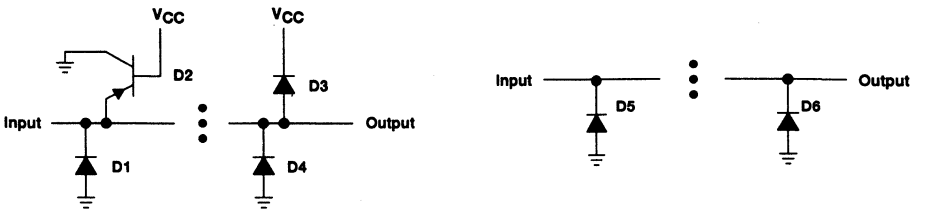
For a high-to-low transition, (I_{OL} = 135 mA @ V_{OL} = 0.5 V)

$$Z_{HL} = \frac{V_{OH}(typ) - V_{OL}(max)}{I_{OL}} = \frac{3.5\ V - 0.5\ V}{135\ mA} = 22\ \Omega \quad (2)$$

Partial Power Down

One application, addressed when designing the ABT family, is partial system power down. When using a standard CMOS device, there is a path from either the input or the output (or both) to V_{CC}. This prevents partial power down for such applications as hot-card insertion without adding current limiting components. This is not the case with ABT as these paths have been eliminated with the use of blocking diodes. Figure 13 shows functionally equivalent schematics of the input structures for CMOS and ABT devices.

Consider the situation shown in Figure 14. The driving device is powered with V_{CC} = 5 V, while the receiving device is powered down (V_{CC} = 0). If these devices are CMOS, the receiver can be powered up through diode D2 when the driver is in a high state. ABT devices do not have a comparable path and are thus immune to this problem, making them more desirable for this application.



(a) CMOS EQUIVALENT INPUT STRUCTURE

(b) ABT EQUIVALENT INPUT STRUCTURE

Figure 13. Simplified Input Structures for CMOS and ABT Devices

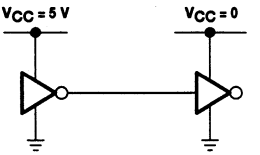


Figure 14. Example of Partial System Power Down

Signal Integrity

A frequent concern of system designers is the performance degradation of ICs when outputs are switched. TI's priority when designing the ABT bus-interface family was to insure signal integrity and eliminate the need for excess settling time of an output waveform. This section addresses the simultaneous switching performance of both the ABT octals and the Widebus functions.

Simultaneous-Switching Phenomenon

Figure 15 shows a simple model of an output pin, including the associated capacitance of the output load and the inherent inductance of the ground lead. The voltage drop across the GND inductor, V_L, is determined by the value of the inductance and the rate of change in current across the inductor. When multiple outputs are switched from high to low, the transient current (di/dt) through the GND inductor generates a difference in potential on the chip ground with respect to the system ground. This induced GND variation can be observed indirectly as shown in Figure 16. The voltage output low peak (V_{OLP}) is measured on one quiet output when all others are switched from high to low.

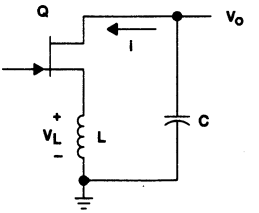
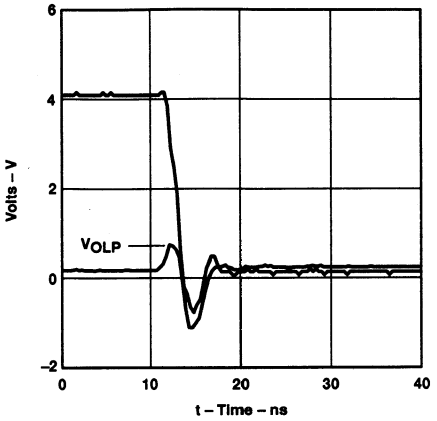


Figure 15. Simultaneous-Switching Output Model



NOTE: V_{OLP} = Maximum (peak) voltage induced on a quiescent low-level output during switching of other outputs

Figure 16. Simultaneous-Switching-Noise Waveform

A similar phenomena occurs with respect to the V_{CC} plane on a low-to-high transition, known as voltage output high valley (V_{OHV}). Most problems are associated with a large V_{OLP} because the range for a logic 0 is much less than the range for a logic 1, as shown in Figure 17. For a comprehensive discussion of simultaneous switching, see *Simultaneous Switching Evaluation and Testing*, Section 4.1, in the *Advanced CMOS Logic (ACL) Designer's Handbook*, literature number SCAA001B.

The impact of these voltage noise spikes on a system can be extreme. The noise can cause loss of stored data, severe speed degradation, false clocking, and/or reduction in system noise immunity. For an overview of how propagation delay is affected by the switching of multiple outputs, please refer to *ac Performance* in this document.

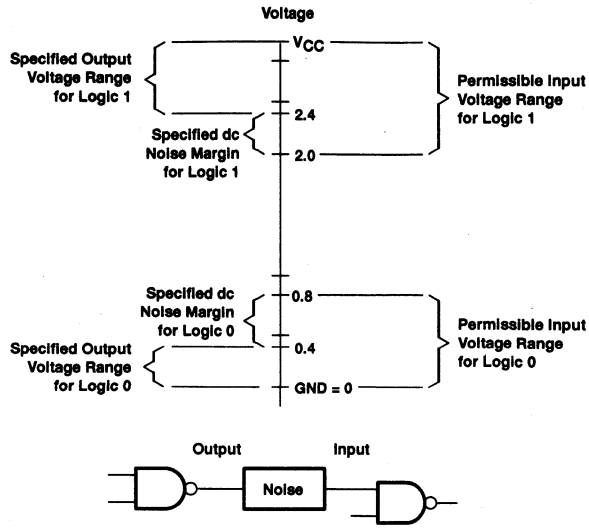


Figure 17. TTL DC Noise Margin

Simultaneous Switching Solutions

Some methods an IC manufacturer can use to reduce the effects of simultaneous switching include: reducing the inductance of the power pins, adding multiple power pins, and controlling the turn on of the output. These techniques are described in the *Advanced CMOS Logic (ACL) Designer's Handbook*, literature number SCAA001B.

Octal ABT devices employ the standard end-pin GND and V_{CC} configuration, while maintaining acceptable simultaneous switching performance, as shown in Figure 18. This is due to the TTL-level output swing (0.3–3 V) and a controlled feedback, which limits the base drive to the lower output.

The ABT Widebus series (16-, 18-, and 20-bit functions) are offered in an SSOP package (see *Packaging* in this document), which TI developed to save valuable board space and reduce simultaneous switching effects. One might expect an increase in noise with 16 outputs switching in a single package; however, the simultaneous switching performance is actually improved. There is a GND pin for every two outputs and a V_{CC} pin for every four. This allows the transient current to be distributed across multiple power pins and decreases the overall d_i/d_t effect. This results in a typical V_{OLP} value on the order of 500 mV for the ABT16500, as shown in Figure 19.

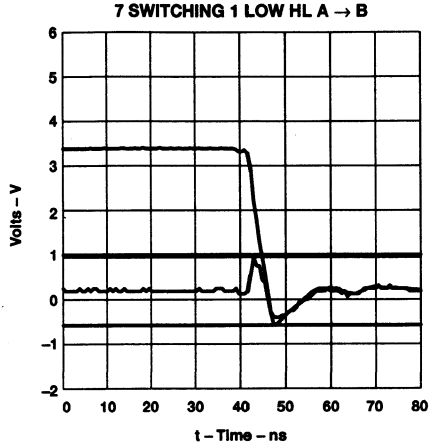


Figure 18. ABT646A Simultaneous-Switching Waveform

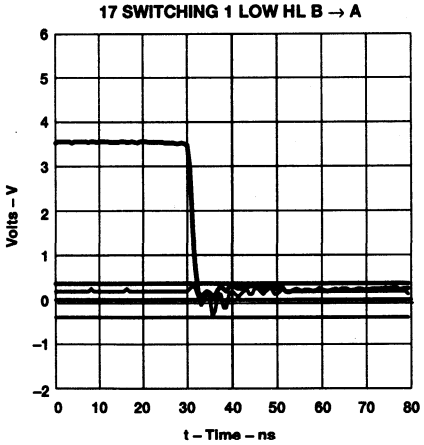


Figure 19. ABT16500B Simultaneous-Switching Waveform

Advanced Packaging

Along with a strong commitment to provide fast, low- power, high-drive ICs, TI is the leader in logic packaging advancements. The development of the shrink small-outline package (SSOP) in 1989 provided system designers the opportunity to reduce the amount of board space required for bus-interface devices by 50%. Several 24-pin solutions including the familiar SOIC, the SSOP, and the TSOP (thin small-outline package) are shown in Figure 20.

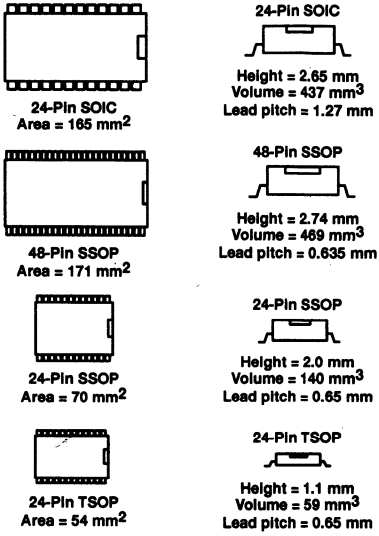


Figure 20. 24-Pin Surface-Mount Comparison

The 48/56-pin SSOP packages allow for twice the functionality (16-, 18-, and 20-bit functions) in approximately the same board area as a standard SOIC. This is accomplished by using a 25-mil (0.635 mm) lead pitch, as opposed to 50-mil (1.27 mm) in SOIC. Figure 21 shows a typical pinout structure for the 48-pin SSOP. The flow-through architecture is standard for all Widebus devices, making signal routing easier during board layout. Also note the distributed GND and V_{CC} pins, which improve simultaneous switching effects as discussed in *Signal Integrity* in this document.

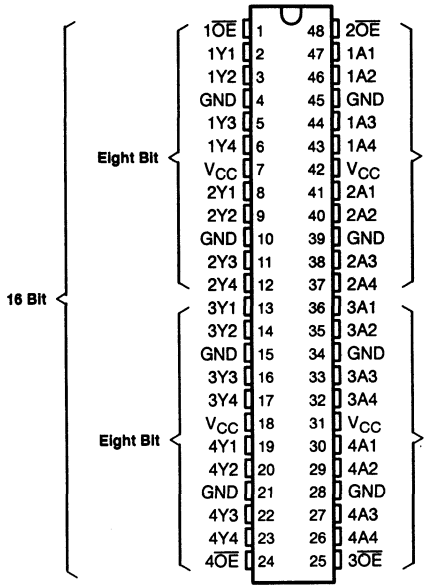


Figure 21. Distributed Pinout of 'ABT16244A

When using the small pin count SSOPs (8-, 9-, and 10-bit functions) the same functionality occupies less than half the board area of a SOIC (70 mm^2 vs 165 mm^2). There also is a height improvement over the SOIC, which is beneficial when the spacing between boards is a consideration. For very dense memory arrays the packaging evolution has been taken one step further with the TSOP. The TSOP thickness of 1.1 mm gives a 58% height improvement over the SOIC.

Table 4 provides a quick reference of the mechanical specifications of the various SSOP packages. For more information, see *Recent Advancements in Bus-Interface Packaging and Processing*, literature number SCZA001A, and *Thin Very Small-Outline Package (TVSOP)*, literature number SCBA009C.

Table 4. SSOP Metric Specifications†

PACKAGE SPECIFICATIONS						PIN SPECIFICATIONS	
PACKAGE TYPE	PINS	INDUSTRY STANDARD	THICKNESS (mm)	BODY WIDTH (mm)	STANDOFF HEIGHT (mm)‡	PIN PITCH (mm)	PIN WIDTH (mm)
SSOP	20	EIAJ	2.00	5.3	0.05	0.650	0.30
SSOP	24	EIAJ	2.00	5.3	0.05	0.650	0.30
SSOP	28	JEDEC	2.59	7.5	0.20	0.635	0.25
SSOP	48	JEDEC	2.59	7.5	0.20	0.635	0.25
SSOP	56	JEDEC	2.59	7.5	0.20	0.635	0.25

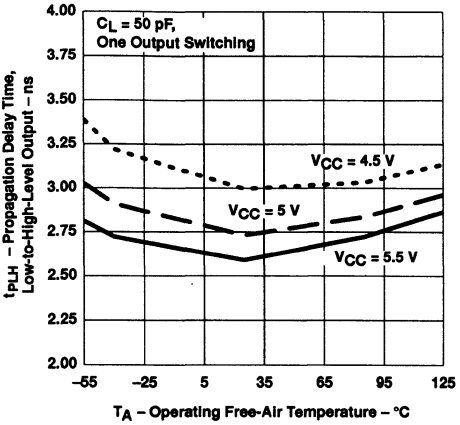
† All values are maximum typical values unless otherwise indicated.
‡ Minimum values

APPENDIX A
'ABT646A Characterization Data

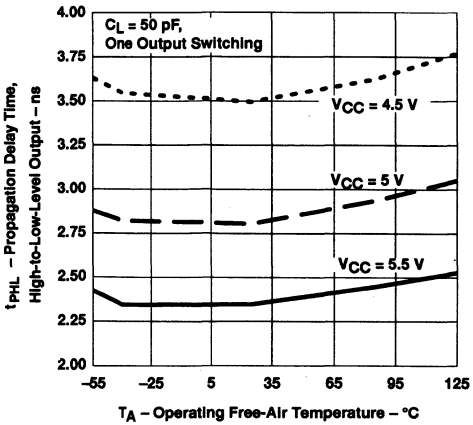
A

Propagation Delay Time vs Temperature

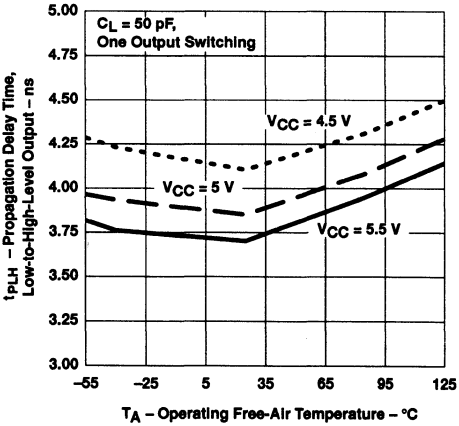
PROPAGATION DELAY TIME
LOW-TO-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
A TO B



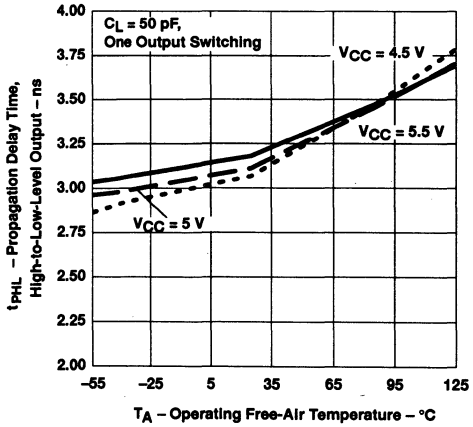
PROPAGATION DELAY TIME
HIGH-TO-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
A TO B



PROPAGATION DELAY TIME
LOW-TO-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
CLKAB to B

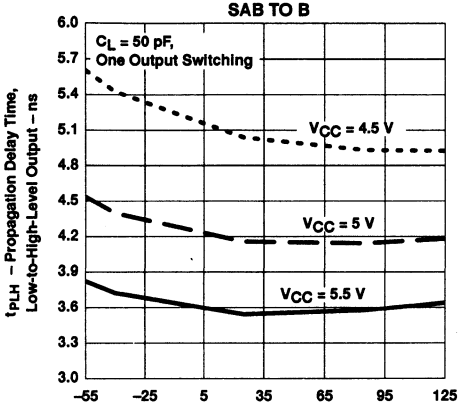


PROPAGATION DELAY TIME
HIGH-TO-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
CLKAB TO B

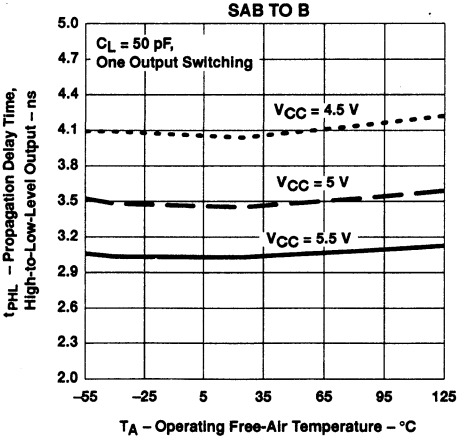


Propagation Delay Time vs Temperature

PROPAGATION DELAY TIME
LOW-TO-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
SAB TO B

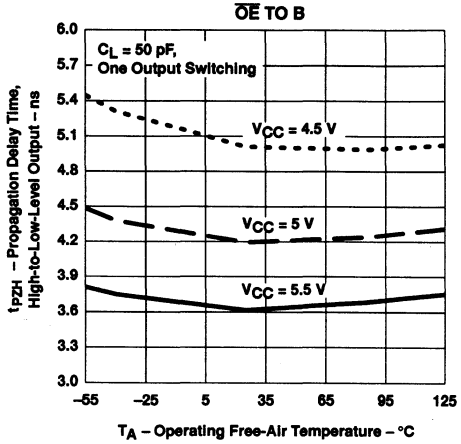


PROPAGATION DELAY TIME
HIGH-TO-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
SAB TO B

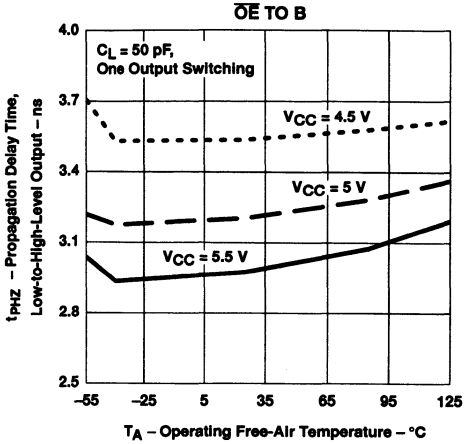


Propagation Delay Time vs Temperature

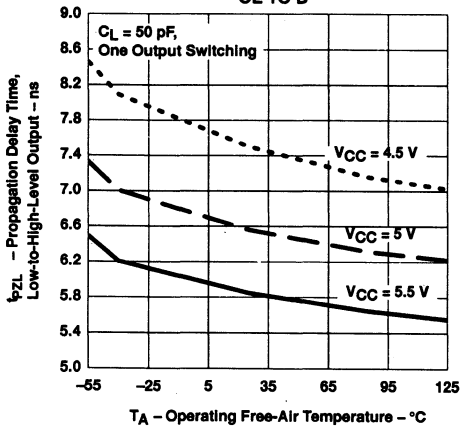
**PROPAGATION DELAY TIME
ENABLE-TO-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
$\overline{OE}$ TO B**



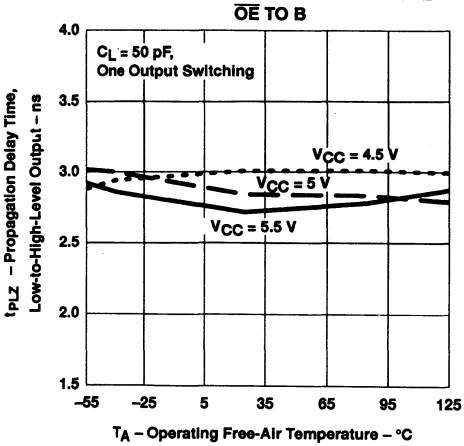
**PROPAGATION DELAY TIME
DISABLE-FROM-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
$\overline{OE}$ TO B**



**PROPAGATION DELAY TIME
ENABLE-TO-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
$\overline{OE}$ TO B**

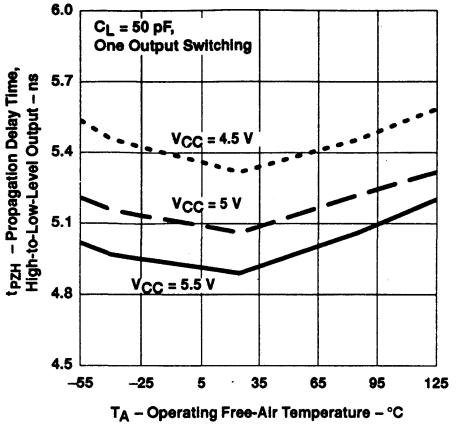


**PROPAGATION DELAY TIME
DISABLE-FROM-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
$\overline{OE}$ TO B**

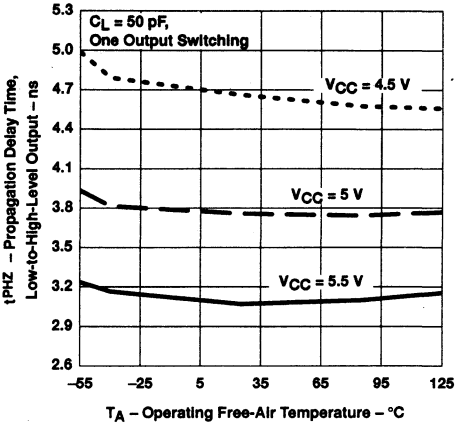


Propagation Delay Time vs Temperature

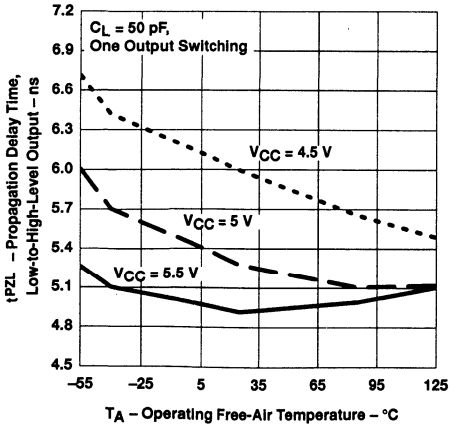
PROPAGATION DELAY TIME
ENABLE-TO-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
DIR TO B



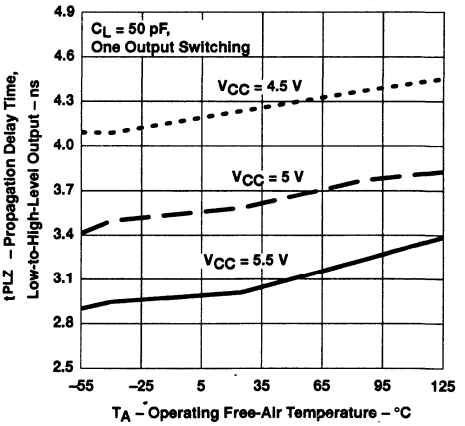
PROPAGATION DELAY TIME
DISABLE-FROM-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
DIR TO B



PROPAGATION DELAY TIME
ENABLE-TO-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
DIR TO B

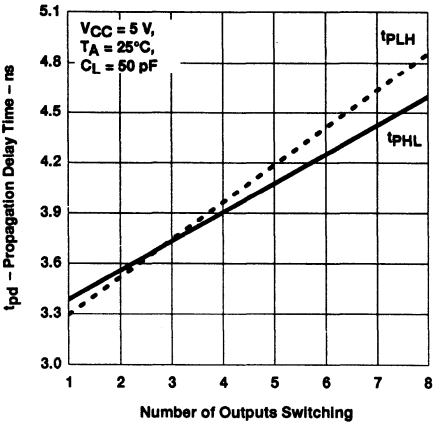


PROPAGATION DELAY TIME
DISABLE-FROM-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
DIR TO B

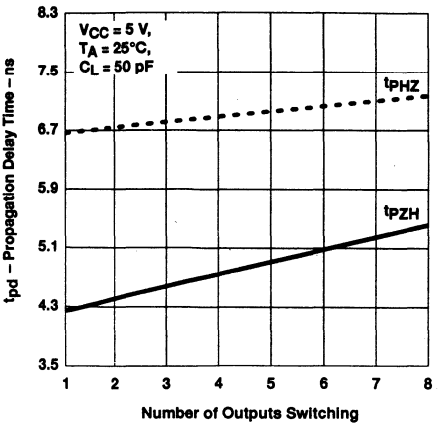


Propagation Delay Time vs Number of Outputs Switching

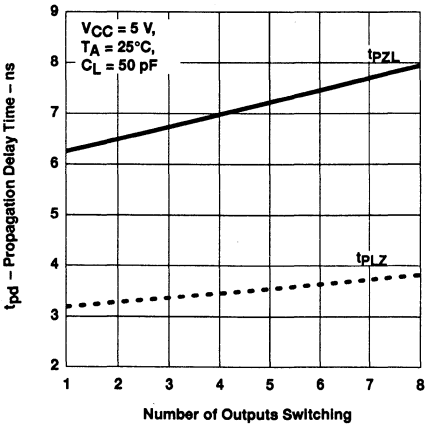
PROPAGATION DELAY TIME
vs
NUMBER OF OUTPUTS SWITCHING
A TO B



PROPAGATION DELAY TIME
vs
NUMBER OF OUTPUTS SWITCHING
A TO B

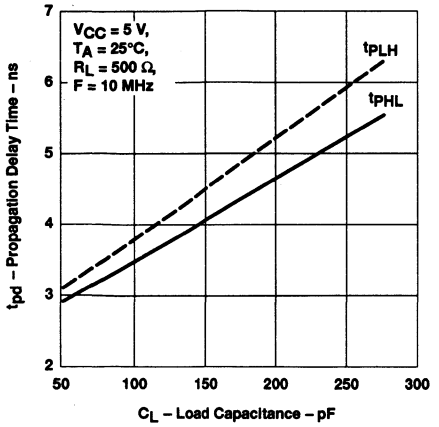


PROPAGATION DELAY TIME
vs
NUMBER OF OUTPUTS SWITCHING
A TO B

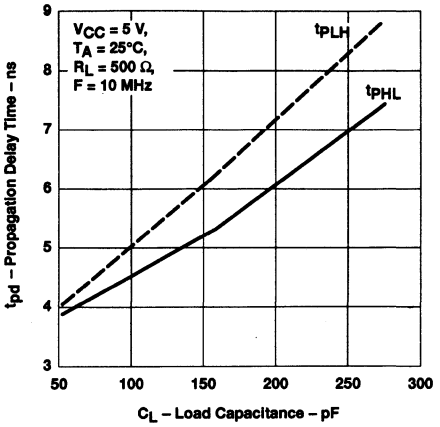


Propagation Delay Time vs Load Capacitance

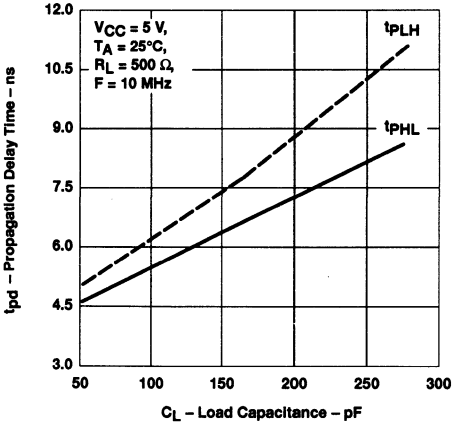
A TO B
ONE OUTPUT SWITCHING



A TO B
FOUR OUTPUTS SWITCHING

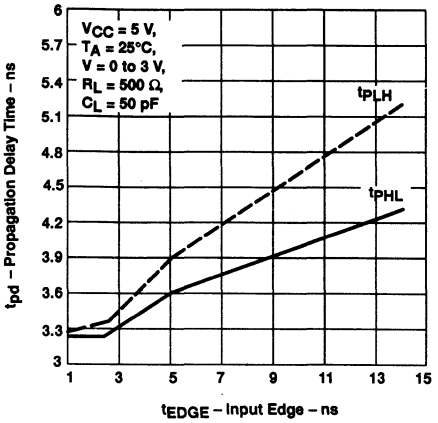


A TO B
EIGHT OUTPUTS SWITCHING

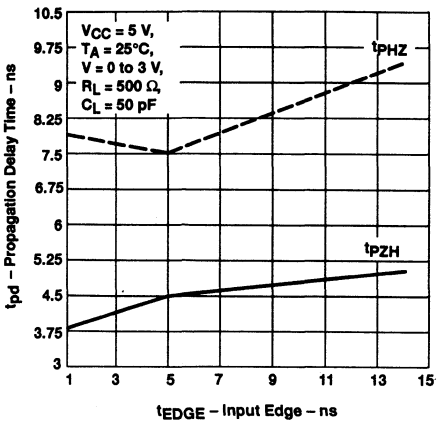


Propagation Delay Time vs Input Edge

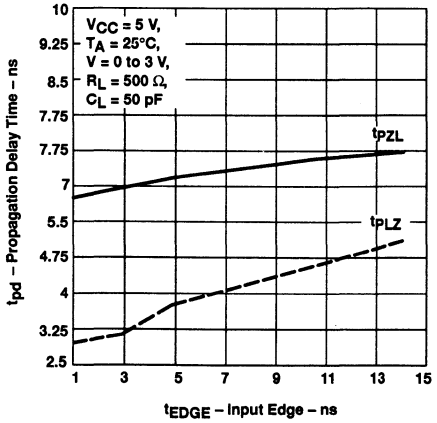
PROPAGATION DELAY TIME
vs
INPUT EDGE
A TO B



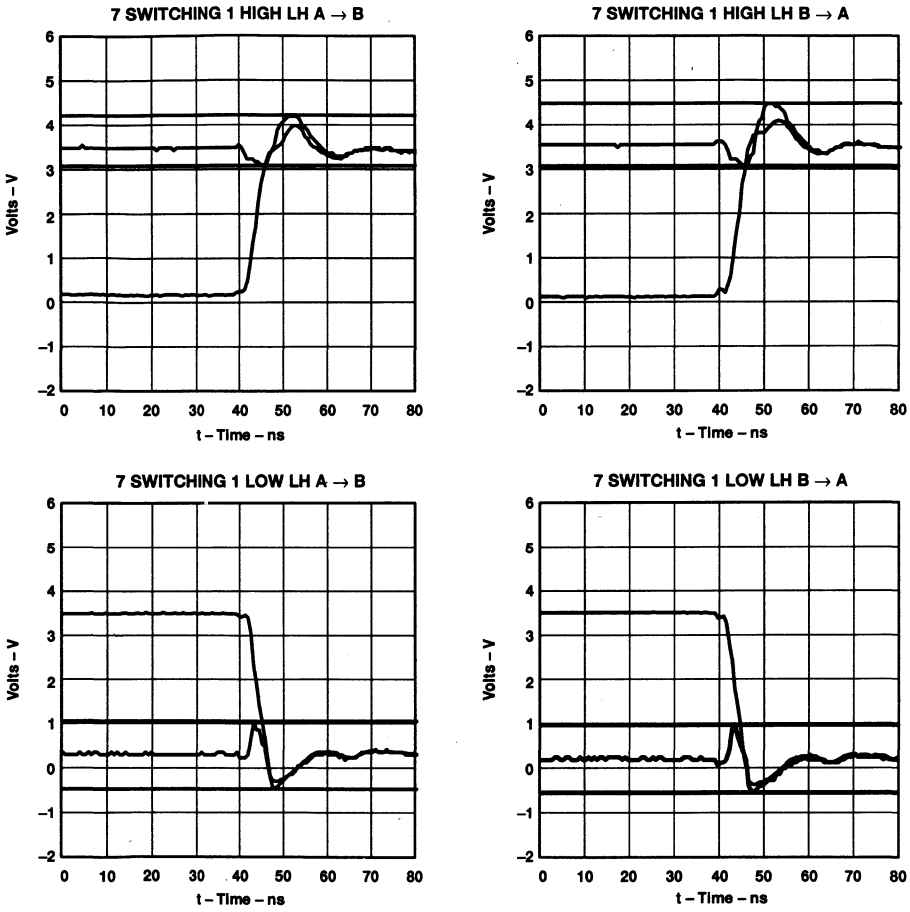
PROPAGATION DELAY TIME
vs
INPUT EDGE
A TO B



PROPAGATION DELAY TIME
vs
INPUT EDGE
A TO B



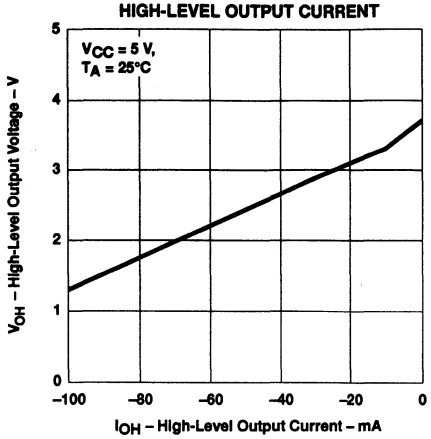
V_{OHV} and V_{OLP}



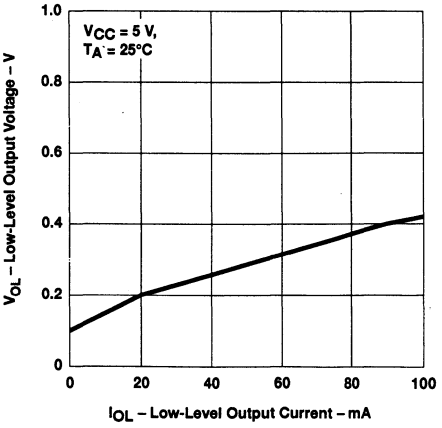
V_{OHV} = Minimum (valley) voltage induced on a quiescent high-level output during switching of other outputs.
V_{OLP} = Maximum (peak) voltage induced on a quiescent low-level output during switching of other outputs.

Typical Characteristics

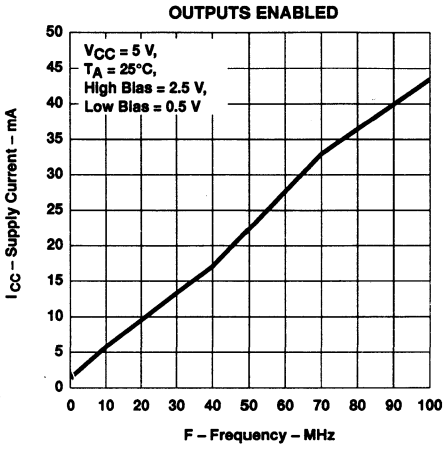
HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

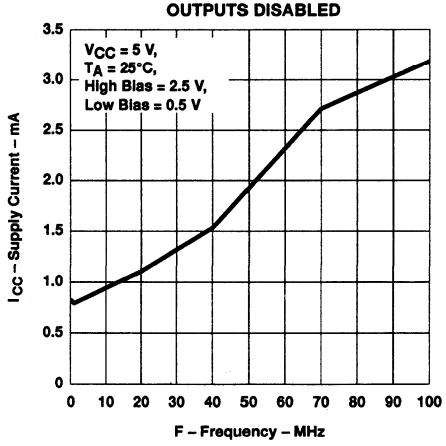


LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT



Supply Current vs Frequency



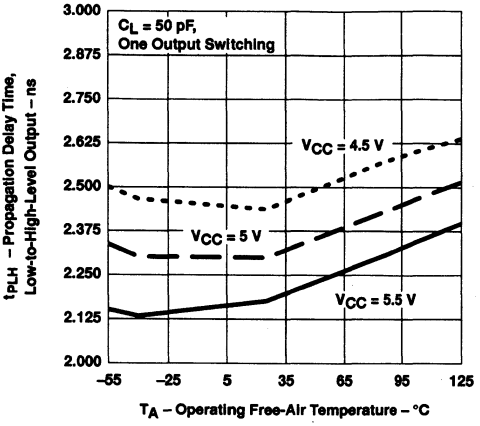


APPENDIX B
SN54ABT16244, SN74ABT16244A Characterization Data

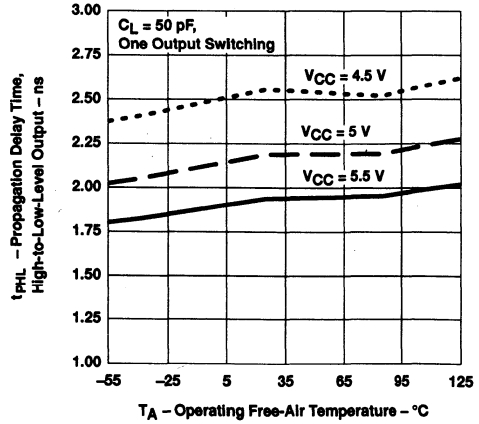
B

Propagation Delay Time vs Temperature

PROPAGATION DELAY TIME
LOW-TO-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
A TO Y

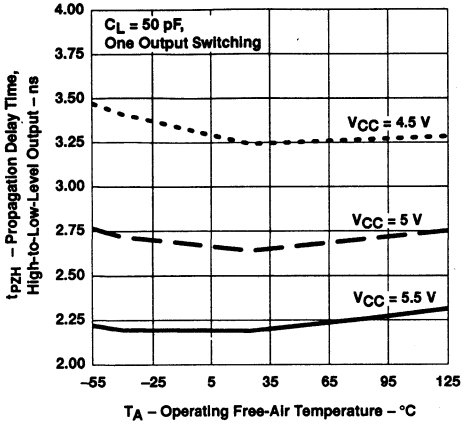


PROPAGATION DELAY TIME
HIGH-TO-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
A TO Y

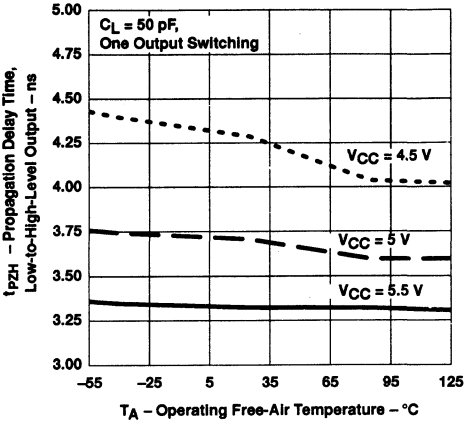


Propagation Delay Time vs Temperature

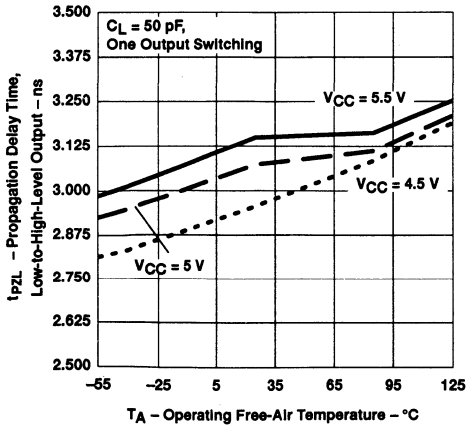
PROPAGATION DELAY TIME
ENABLE-TO-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
$\overline{OE}$ TO Y



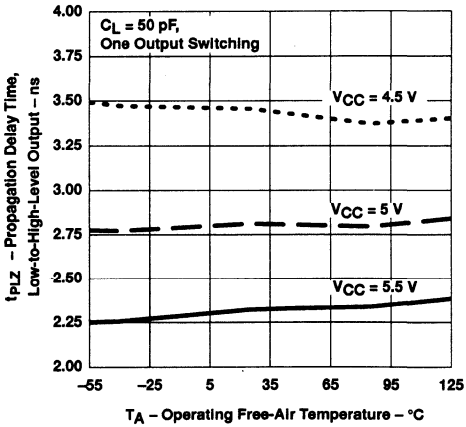
PROPAGATION DELAY TIME
DISABLE-FROM-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
$\overline{OE}$ TOY



PROPAGATION DELAY TIME
ENABLE-TO-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
$\overline{OE}$ TO Y

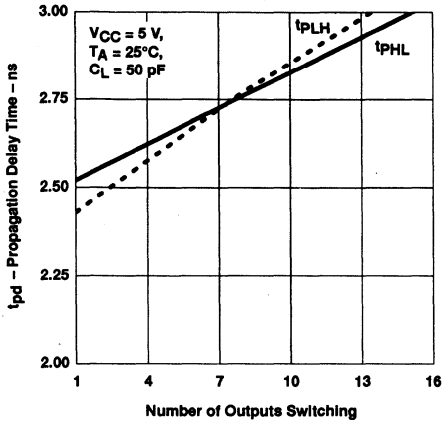


PROPAGATION DELAY TIME
DISABLE-FROM-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
$\overline{OE}$ TO Y

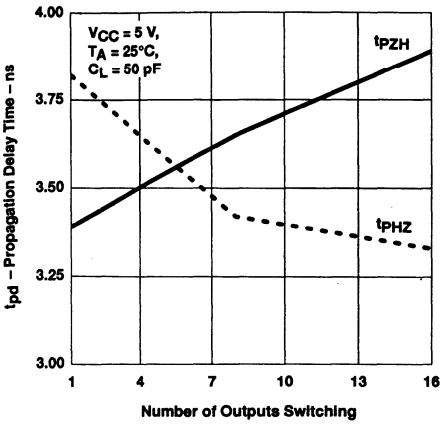


Propagation Delay Time vs Number of Outputs Switching

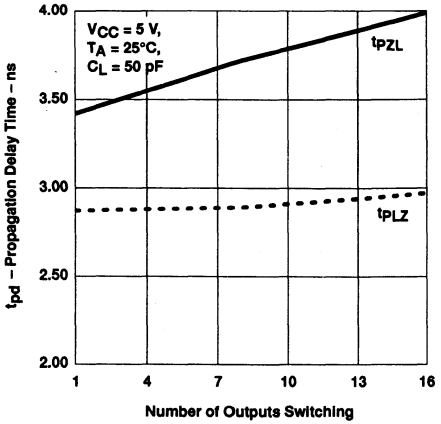
PROPAGATION DELAY TIME
vs
NUMBER OF OUTPUTS SWITCHING
A TO Y



PROPAGATION DELAY TIME
vs
NUMBER OF OUTPUTS SWITCHING
$\overline{OE}$ TO Y

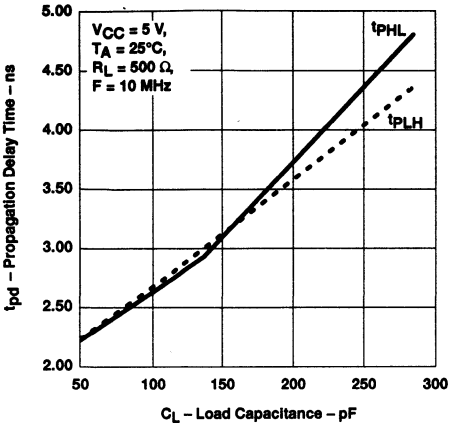


PROPAGATION DELAY TIME
vs
NUMBER OF OUTPUTS SWITCHING
$\overline{OE}$ TO Y

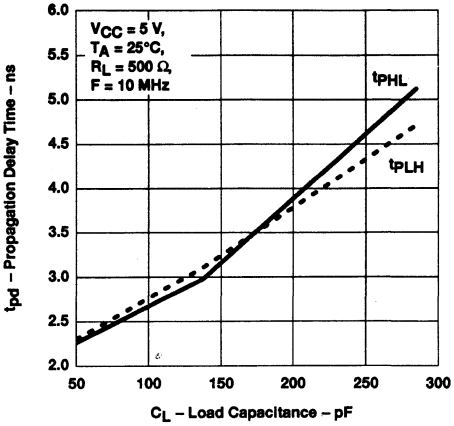


Propagation Delay Time vs Load Capacitance

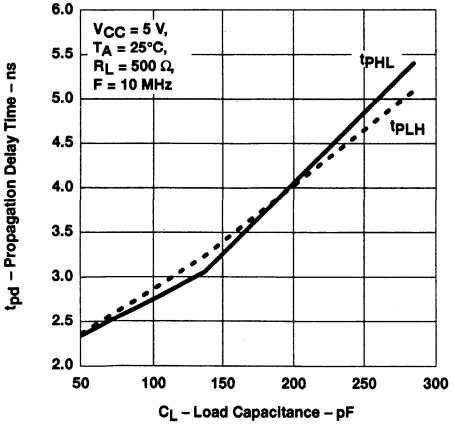
A TO Y
ONE OUTPUT SWITCHING



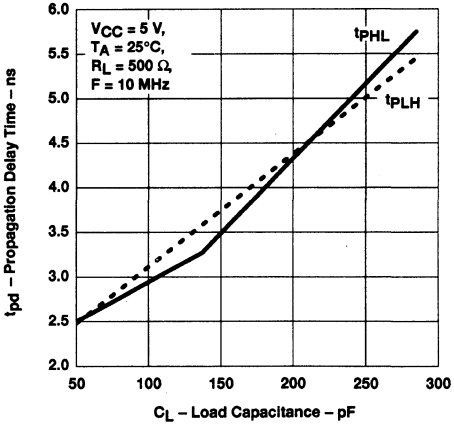
A TO Y
FOUR OUTPUTS SWITCHING



A TO Y
EIGHT OUTPUTS SWITCHING

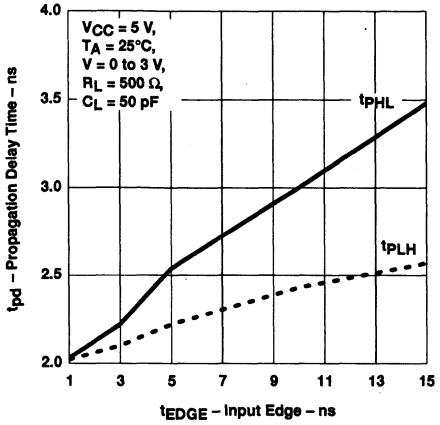


A TO Y
16 OUTPUTS SWITCHING

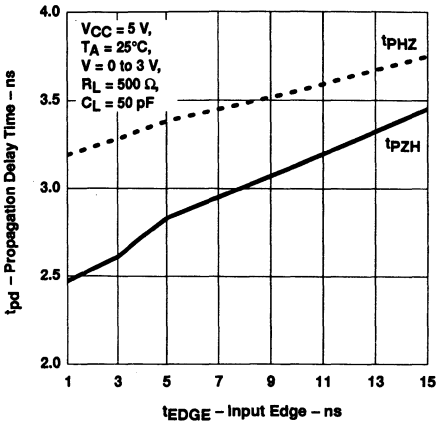


Propagation Delay Time vs Input Edge

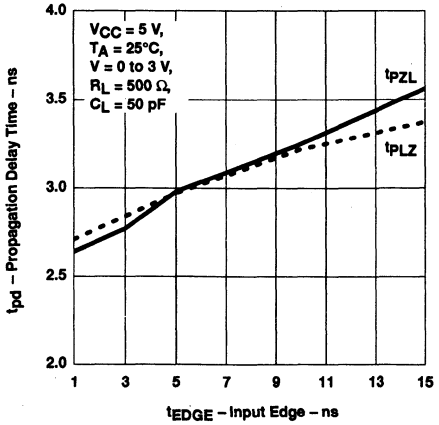
PROPAGATION DELAY TIME
vs
INPUT EDGE
A TO Y



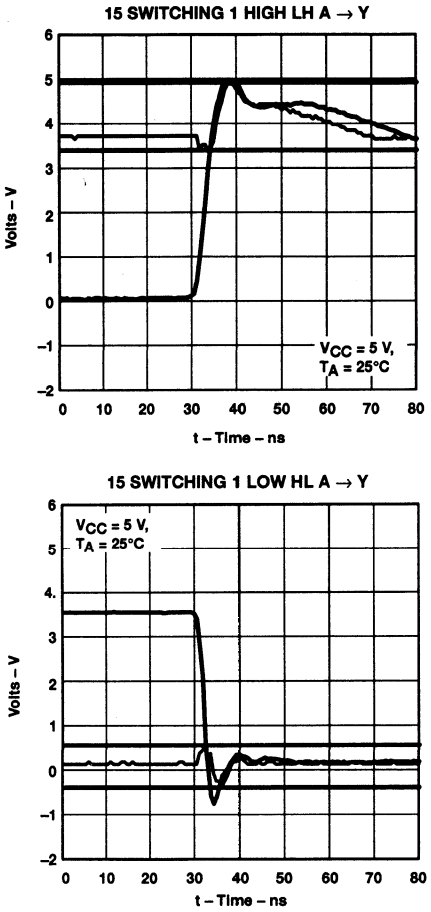
PROPAGATION DELAY TIME
vs
INPUT EDGE
$\overline{OE}$ TO Y



PROPAGATION DELAY TIME
vs
INPUT EDGE
$\overline{OE}$ TO Y



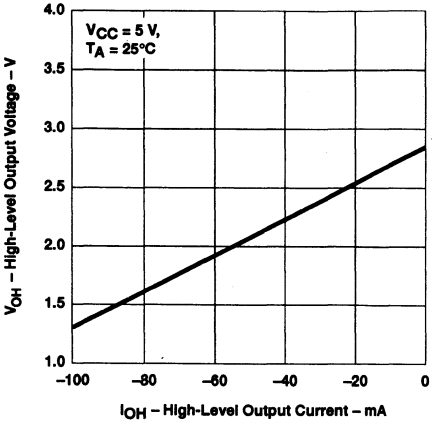
V_{OHV} and V_{OLP}



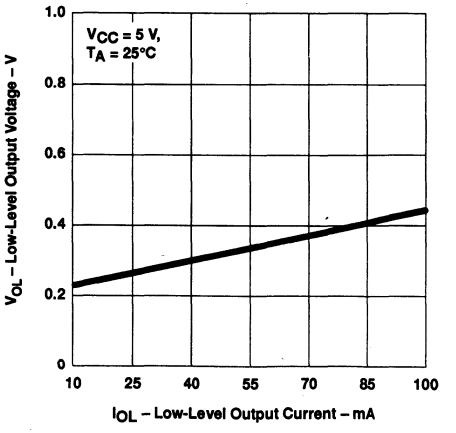
V_{OHV} = Minimum (valley) voltage induced on a quiescent high-level output during switching of other outputs.
V_{OLP} = Maximum (peak) voltage induced on a quiescent low-level output during switching of other outputs.

Typical Characteristics

HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

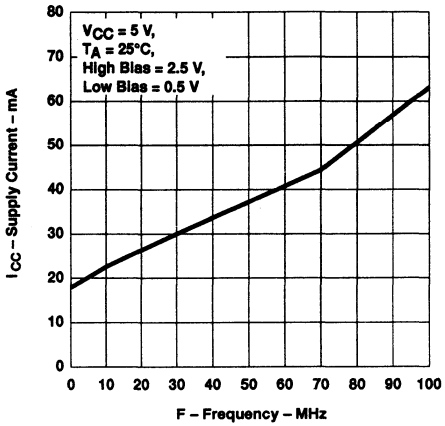


LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

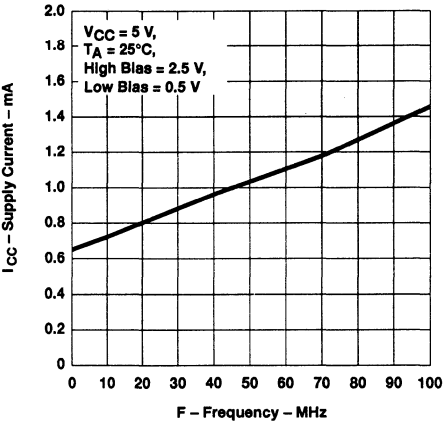


Supply Current vs Frequency

OUTPUTS ENABLED



OUTPUTS DISABLED

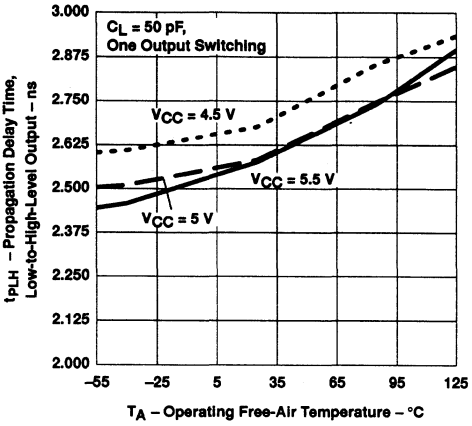


APPENDIX C
'ABT16500B Characterization Data

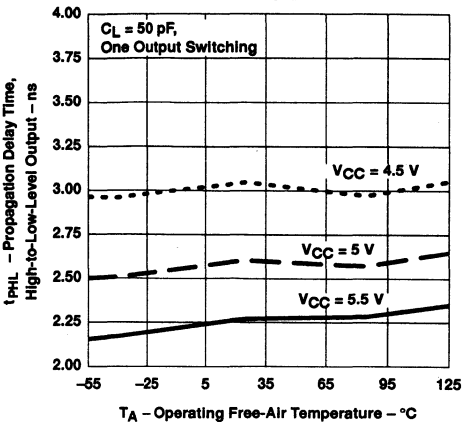
C

Propagation Delay Time vs Temperature

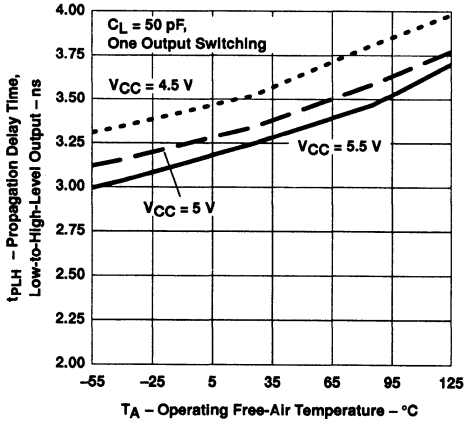
PROPAGATION DELAY TIME
LOW-TO-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
A TO B



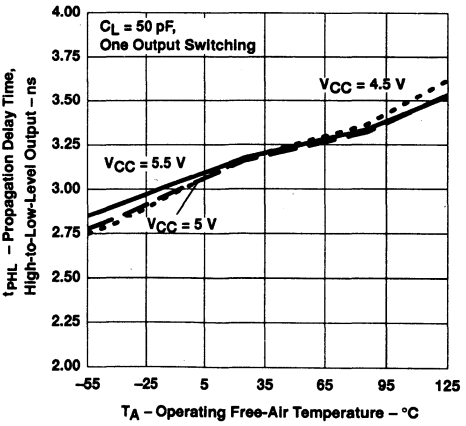
PROPAGATION DELAY TIME
HIGH-TO-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
A TO B



PROPAGATION DELAY TIME
LOW-TO-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
LEAB TO B

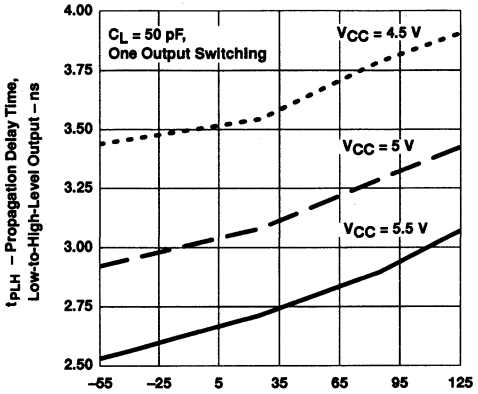


PROPAGATION DELAY TIME
HIGH-TO-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
LEAB TO B

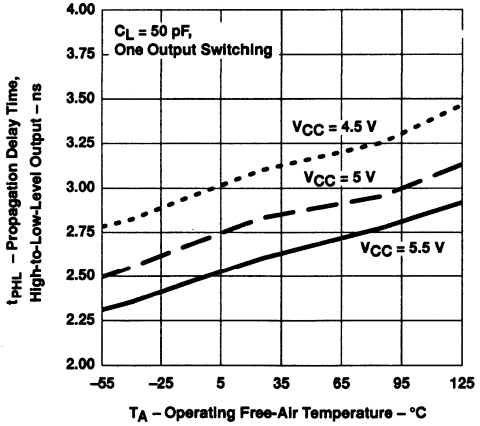


Propagation Delay Time vs Temperature

PROPAGATION DELAY TIME
LOW-TO-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
$\overline{CLKAB}$ TO B

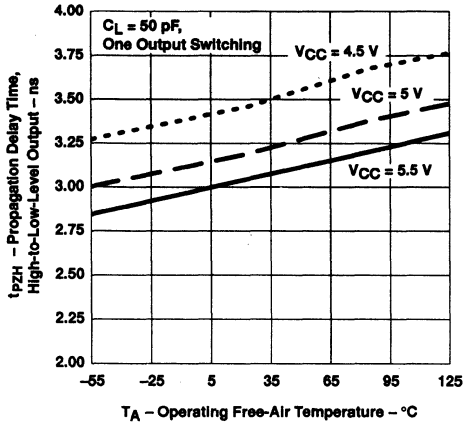


PROPAGATION DELAY TIME
HIGH-TO-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
$\overline{CLKAB}$ TO B

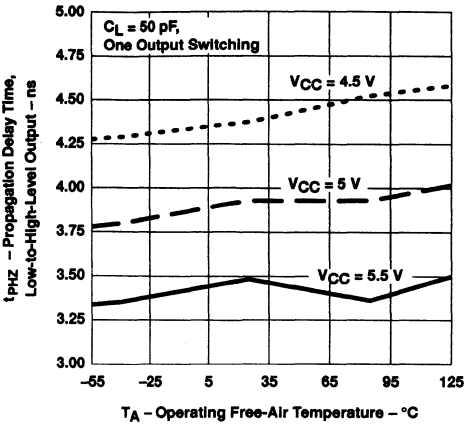


Propagation Delay Time vs Temperature

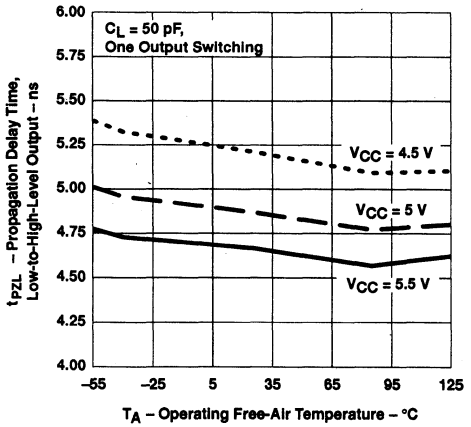
PROPAGATION DELAY TIME
ENABLE-TO-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
OEAB TO B



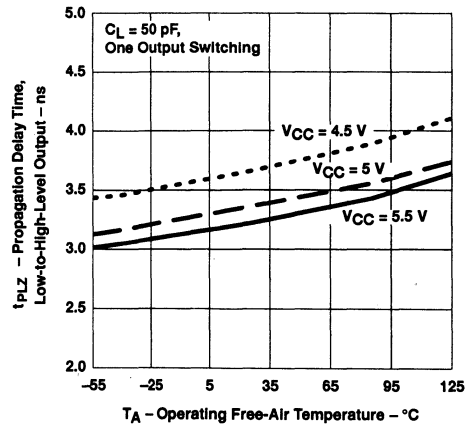
PROPAGATION DELAY TIME
DISABLE-FROM-HIGH-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
OEAB TO B



PROPAGATION DELAY TIME
ENABLE-TO-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
OEAB TO B

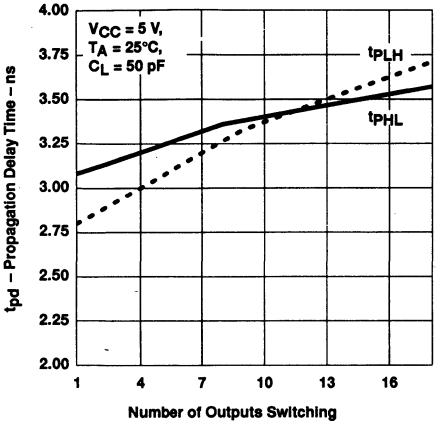


PROPAGATION DELAY TIME
DISABLE-FROM-LOW-LEVEL OUTPUT
vs
OPERATING FREE-AIR TEMPERATURE
OEAB TO B

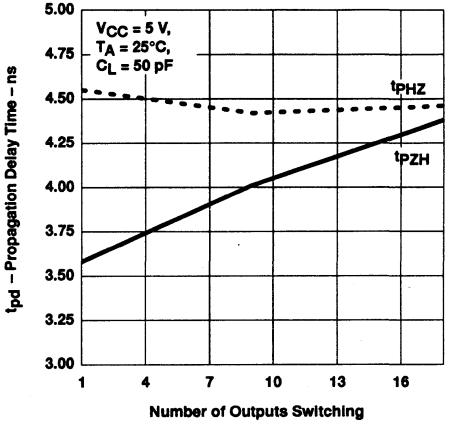


Propagation Delay Time vs Number of Outputs Switching

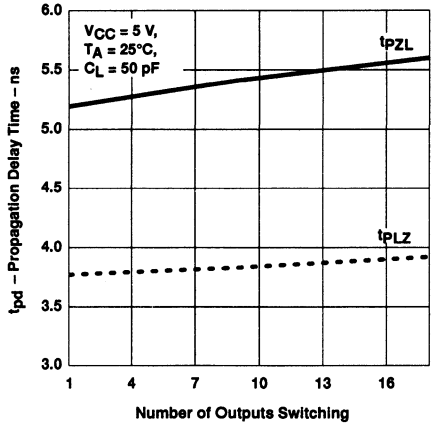
PROPAGATION DELAY TIME
vs
NUMBER OF OUTPUTS SWITCHING
A TO B



PROPAGATION DELAY TIME
vs
NUMBER OF OUTPUTS SWITCHING
OEAB TO B

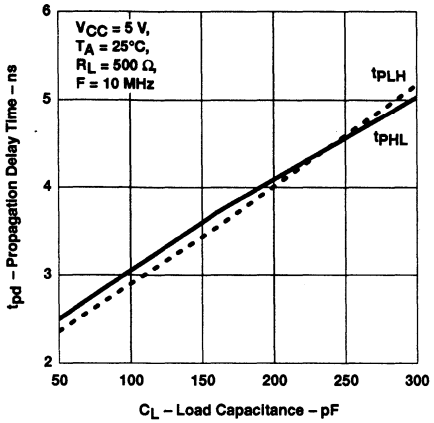


PROPAGATION DELAY TIME
vs
NUMBER OF OUTPUTS SWITCHING
OEAB TO B

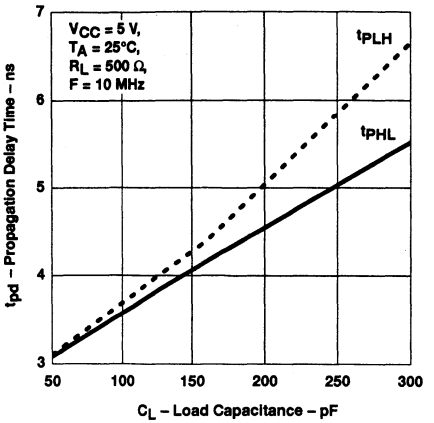


Propagation Delay Time vs Load Capacitance

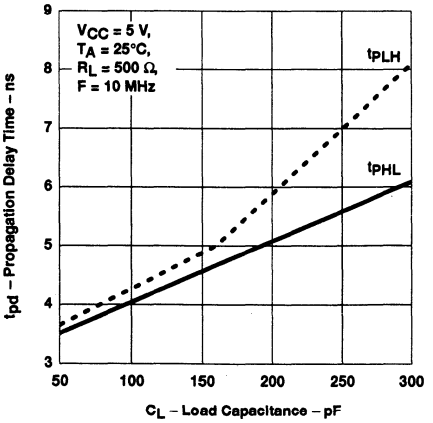
A TO B
ONE OUTPUT SWITCHING



A TO B
NINE OUTPUTS SWITCHING

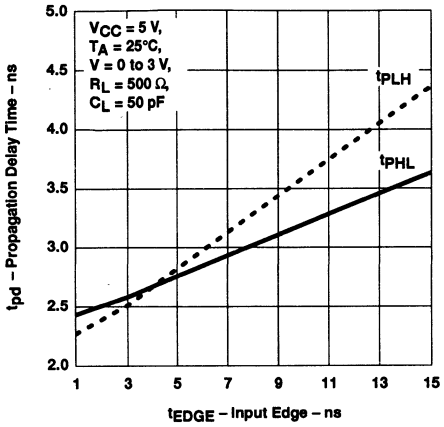


A TO B
18 OUTPUTS SWITCHING

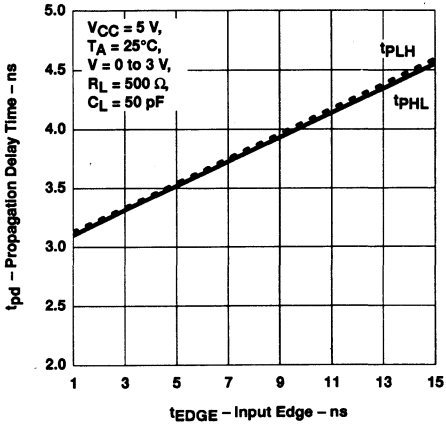


Propagation Delay Time vs Input Edge

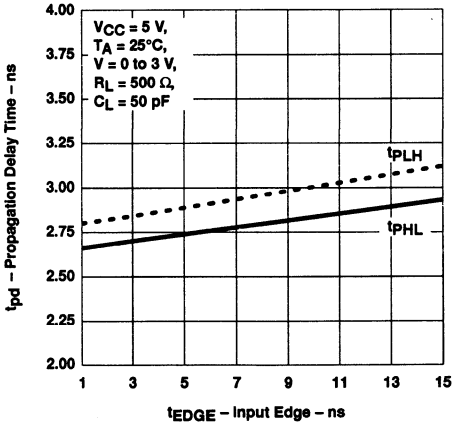
PROPAGATION DELAY TIME
vs
INPUT EDGE
A TO B



PROPAGATION DELAY TIME
vs
INPUT EDGE
LEAB TO B

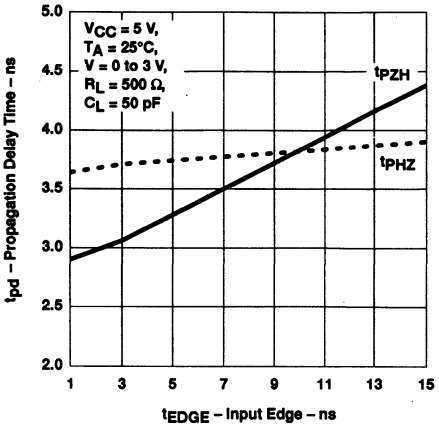


PROPAGATION DELAY TIME
vs
INPUT EDGE
CLKAB TO B

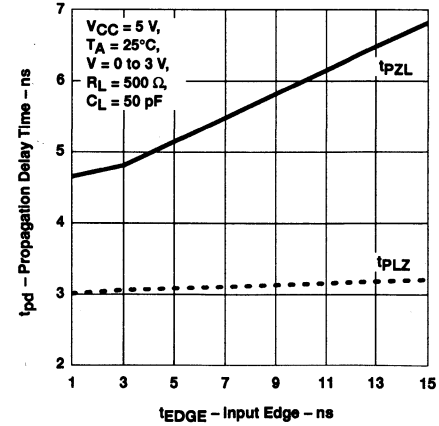


Propagation Delay Time vs Input Edge

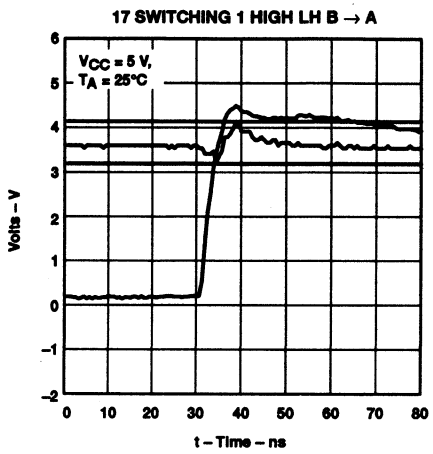
PROPAGATION DELAY TIME
vs
INPUT EDGE
OEAB TO B



PROPAGATION DELAY TIME
vs
INPUT EDGE
OEAB TO B



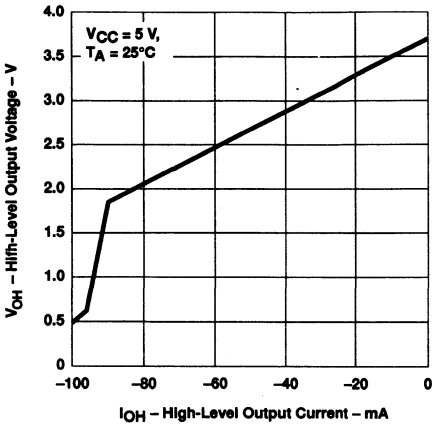
V_{OHV} and V_{OLP}



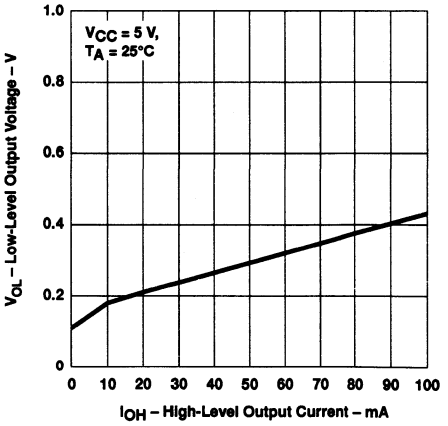
V_{OHV} = Minimum (valley) voltage induced on a quiescent high-level output during switching of other outputs.
V_{OLP} = Maximum (peak) voltage induced on a quiescent low-level output during switching of other outputs.

Typical Characteristics

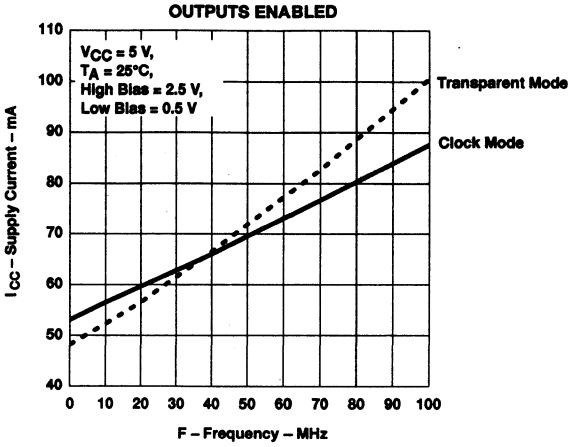
HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT



LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

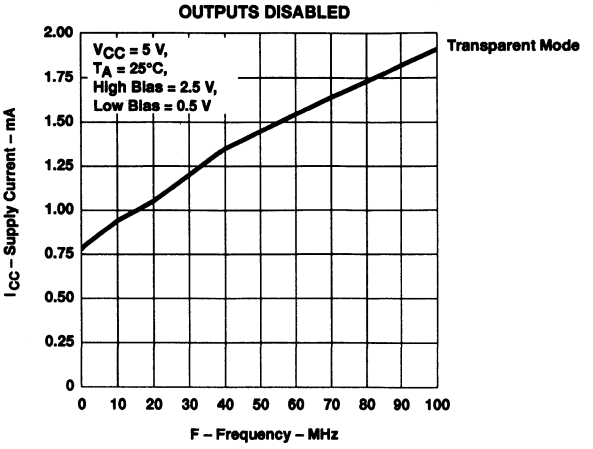


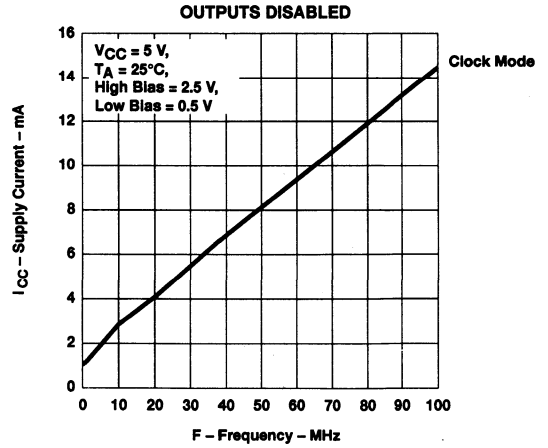
Supply Current vs Frequency



NOTE: Characteristics for latch mode are similar to those when in clock mode.

Supply Current vs Frequency





NOTE: Characteristics for latch mode are similar to those when in clock mode.

Contents

Electrical characteristics presented in this data book, unless otherwise noted, apply for the circuit type(s) listed in the page heading regardless of package. The availability of a circuit function in a particular package is denoted by an alphabetical reference above the pin-connection diagram(s). These alphabetical references refer to mechanical outline drawings shown in this section.

Factory orders for circuits described in this data book should include a three-part type number as explained in the following example.

EXAMPLE: SN 74ABT16500B DGG R

Prefix

SN = Standard prefix
SNJ = Compliant to MIL-PRF-38535 (QML)

Unique Circuit Description

MUST CONTAIN EIGHT TO TWELVE CHARACTERS

Examples: 74ABT125
74ABT2244A
74ABT162823A

Package

MUST CONTAIN ONE TO THREE LETTERS

D, DW = plastic small-outline package
DB, DL = plastic shrink small-outline package
DGG, PW = plastic thin shrink small-outline package
DGV = plastic thin very small-outline package
FK = leadless ceramic chip carrier
J, JT = ceramic dual-in-line package
N, NT = plastic dual-in-line package
PN, PZ = plastic thin quad flat package
W, WD = ceramic flat package
(from pin-connection diagram on individual data sheet)

Tape and Reel Packaging

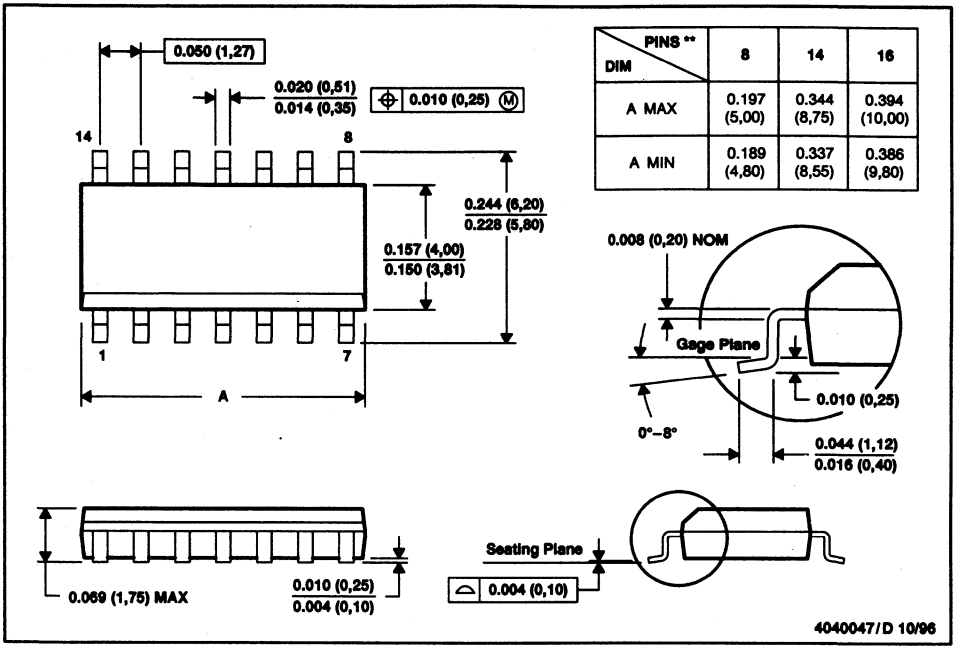
Valid for surface-mount packages only. All orders for tape and reel must be for whole reels.

MUST CONTAIN ONE OR TWO LETTERS

LE = Left embossed tape and reel (required for DB and PW packages)
R = Standard tape and reel (required for DGG and DGV; optional for D, DL, and DW packages)

D (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PIN SHOWN

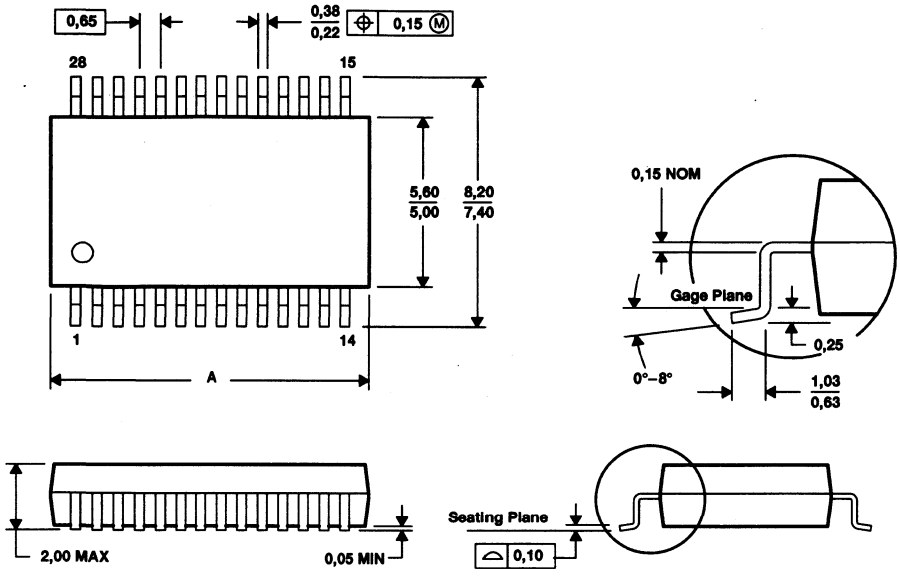


DIM \ PINS **	8	14	16
A MAX	0.197 (5,00)	0.344 (8,75)	0.394 (10,00)
A MIN	0.189 (4,80)	0.337 (8,55)	0.386 (9,80)

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-012

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

28 PIN SHOWN



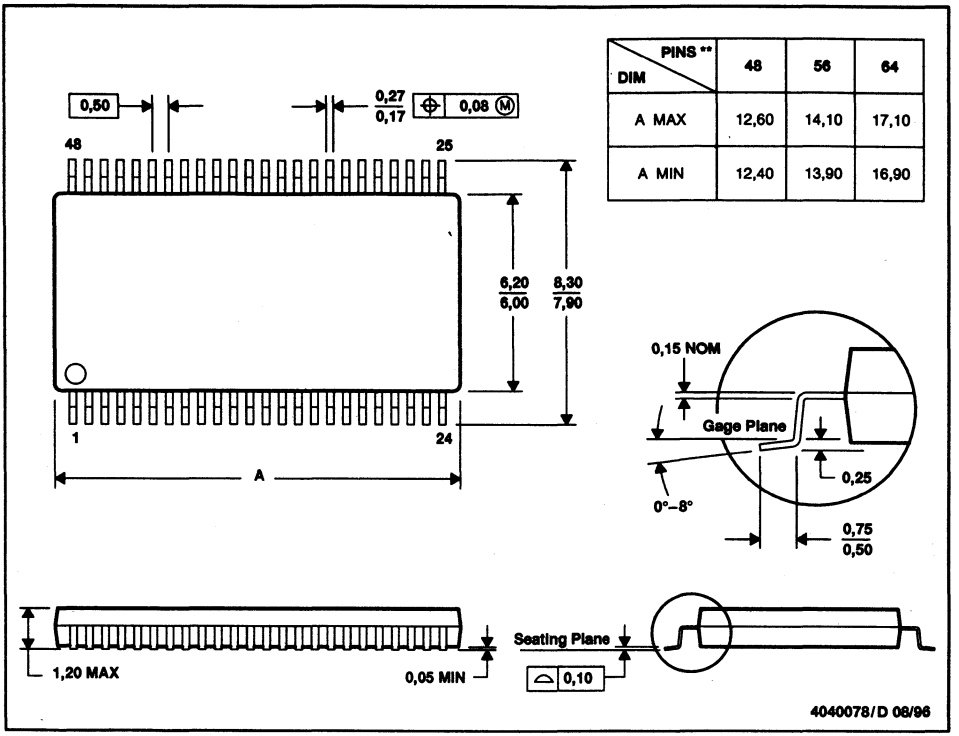
DIM \ PINS **	8	14	16	20	24	28	30	38
A MAX	3,30	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	2,70	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 / C 10/95

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

DGG (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

48 PIN SHOWN

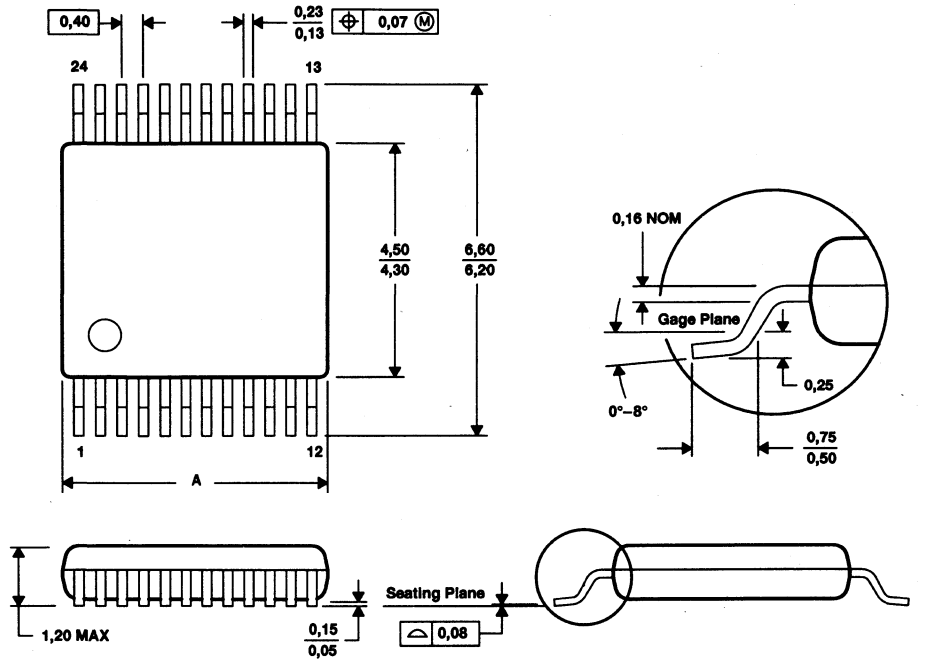


DIM \ PINS **	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MO-153

DGV (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

24 PIN SHOWN



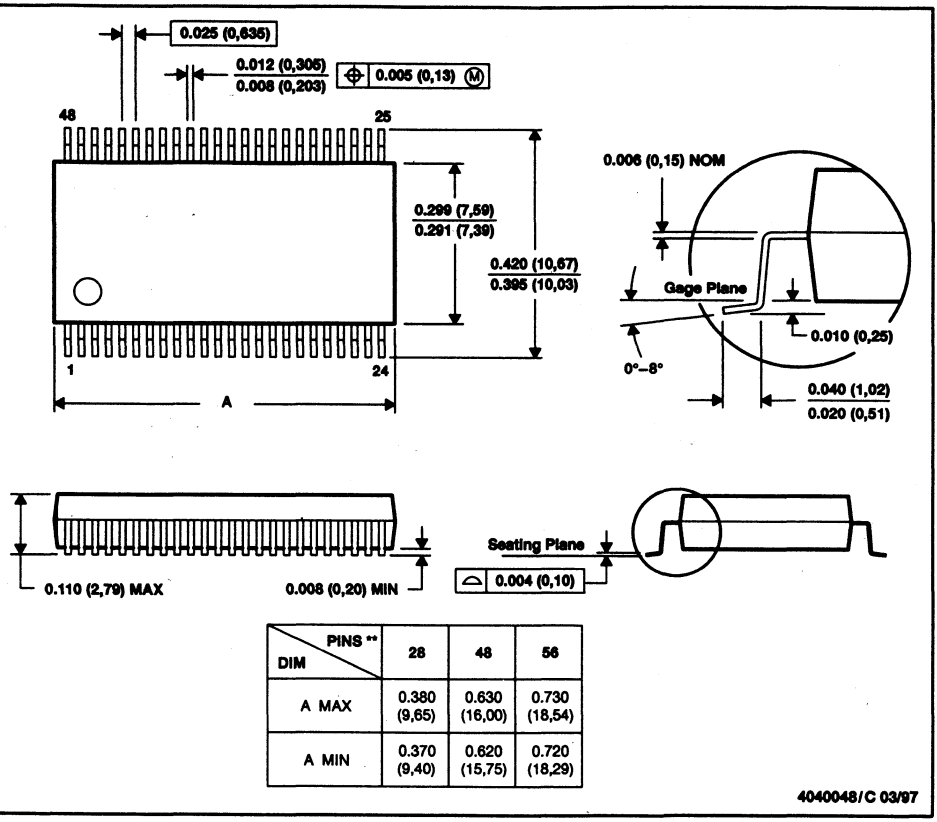
DIM \ PINS **	14	16	20	24	48	56
A MAX	3,70	3,70	5,10	5,10	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	9,60	11,20

4073251/b 03/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. The 24 and 48 pins falls within JEDEC MO-153 and the 14, 16, 20, and 56 pins falls within JEDEC MO-194.

DL (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

48 PIN SHOWN



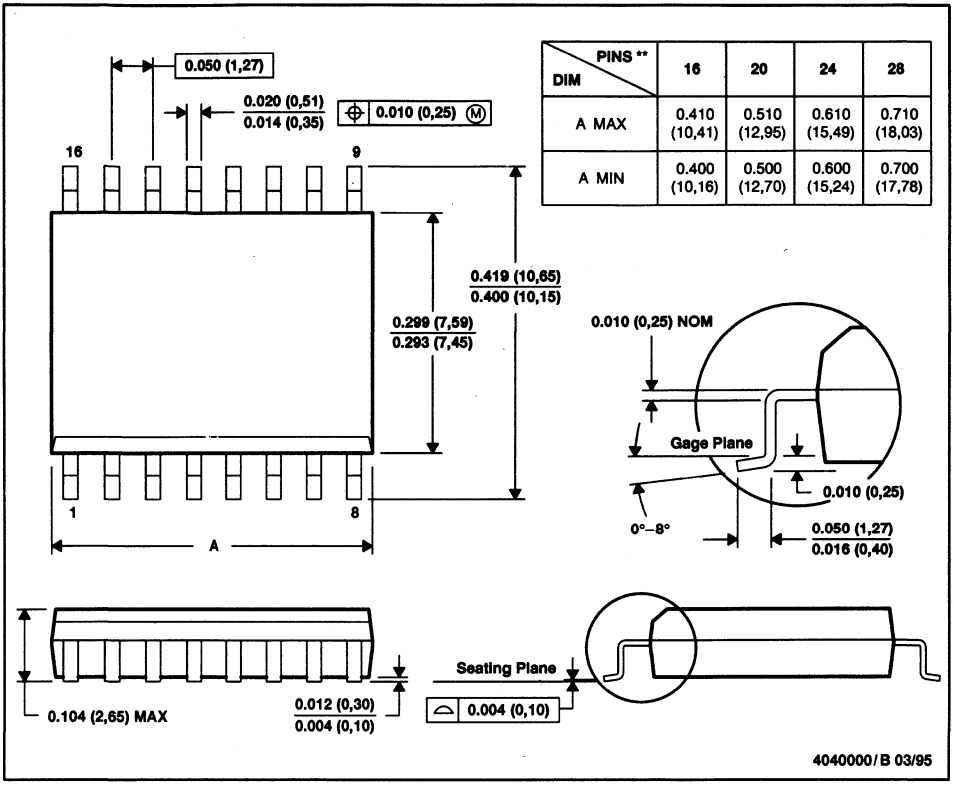
DIM \ PINS **	28	48	56
A MAX	0.380 (9,65)	0.630 (16,00)	0.730 (18,54)
A MIN	0.370 (9,40)	0.620 (15,75)	0.720 (18,29)

4040048/C 03/97

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MO-118

DW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

16 PIN SHOWN

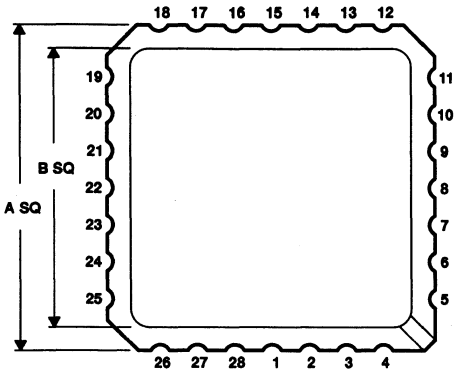


DIM \ PINS **	16	20	24	28
A MAX	0.410 (10,41)	0.510 (12,95)	0.610 (15,49)	0.710 (18,03)
A MIN	0.400 (10,16)	0.500 (12,70)	0.600 (15,24)	0.700 (17,78)

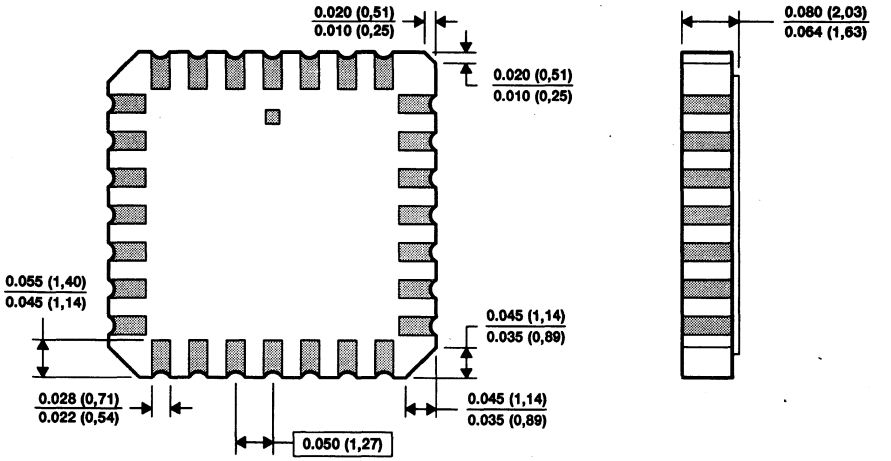
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

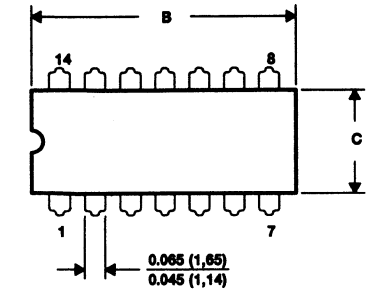


4040140/D 10/96

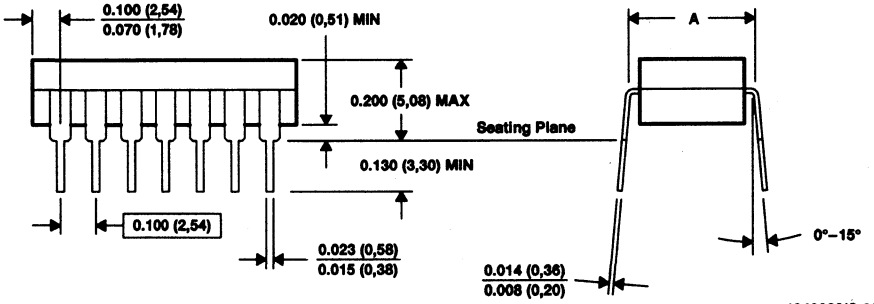
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

J (R-GDIP-T)** **CERAMIC DUAL-IN-LINE PACKAGE**

14 PIN SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.310 (7,87)	0.310 (7,87)	0.310 (7,87)	0.310 (7,87)
A MIN	0.290 (7,37)	0.290 (7,37)	0.290 (7,37)	0.290 (7,37)
B MAX	0.785 (19,94)	0.785 (19,94)	0.910 (23,10)	0.975 (24,77)
B MIN	0.755 (19,18)	0.755 (19,18)	—	0.930 (23,62)
C MAX	0.280 (7,11)	0.300 (7,62)	0.300 (7,62)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.245 (6,22)	0.245 (6,22)

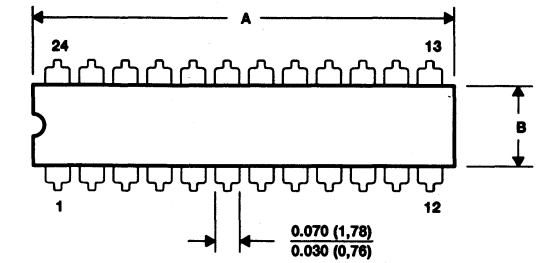


4040083/C 08/96

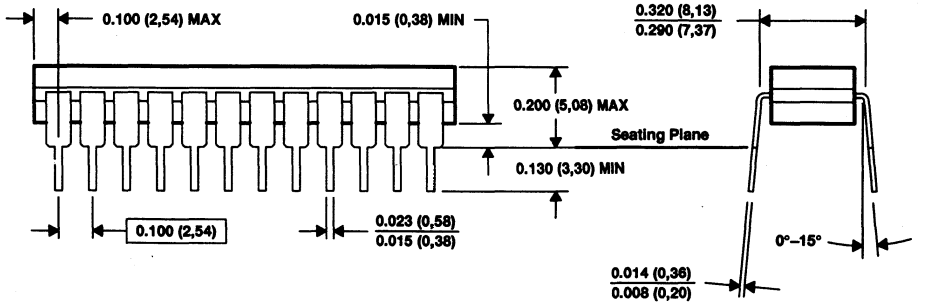
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL-STD-1835 GDIP1-T14, GDIP1-T16, GDIP1-T18, and GDIP1-T20

JT (R-GDIP-T)** **CERAMIC DUAL-IN-LINE PACKAGE**

24 PIN SHOWN



DIM \ PINS**	24	28
A MAX	1.280 (32,51)	1.460 (37,08)
A MIN	1.240 (31,50)	1.440 (36,58)
B MAX	0.300 (7,62)	0.291 (7,39)
B MIN	0.245 (6,22)	0.285 (7,24)



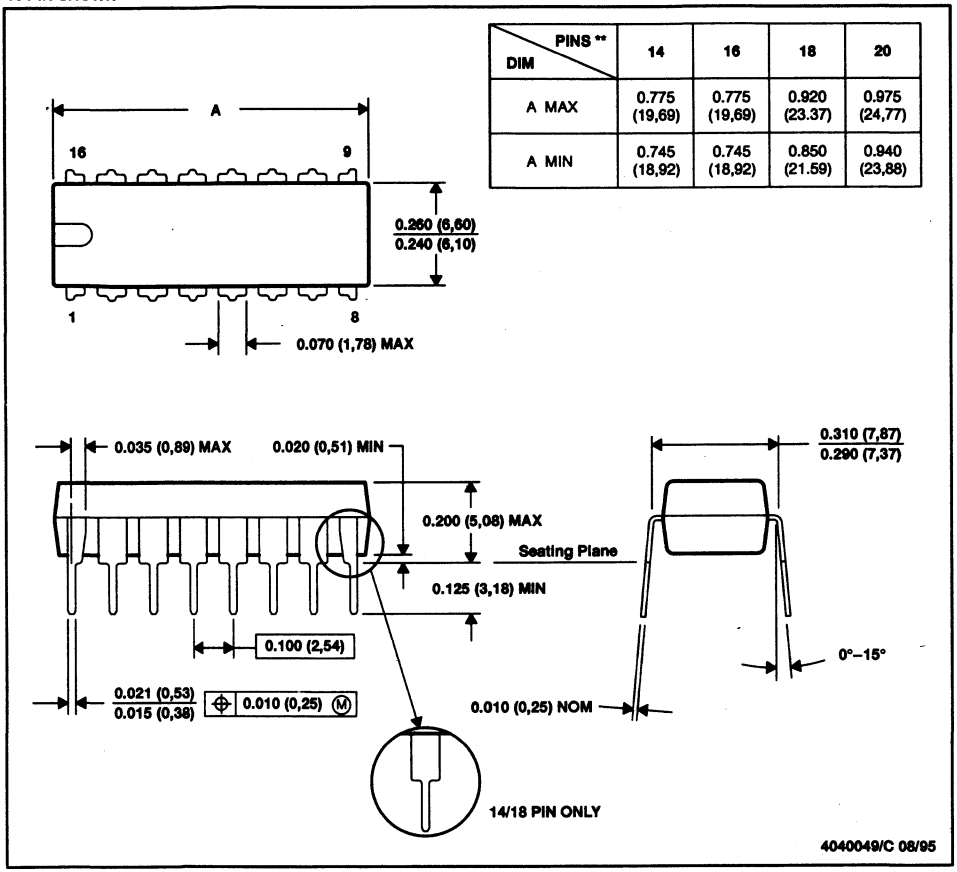
4040110/C 08/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP-T24, GDIP-T28 and JEDEC MO-058 AA, MO-058 AB.

N (R-PDIP-T)** **PLASTIC DUAL-IN-LINE PACKAGE**

16 PIN SHOWN

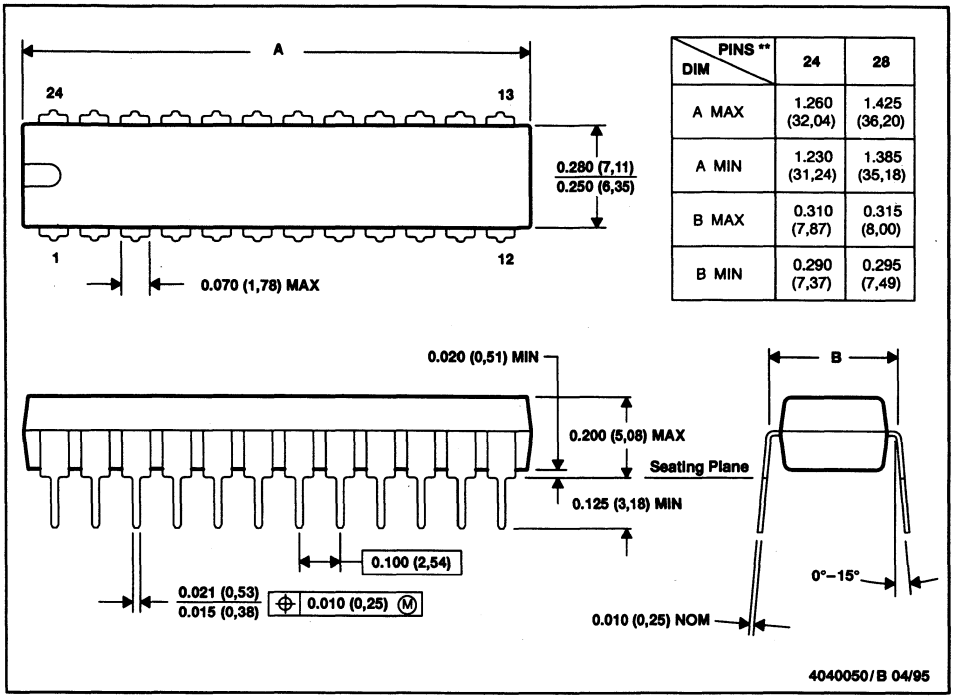
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23.37)	0.975 (24,77)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21.59)	0.940 (23,88)



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001 (20 pin package is shorter then MS-001.)

NT (R-PDIP-T)** **PLASTIC DUAL-IN-LINE PACKAGE**

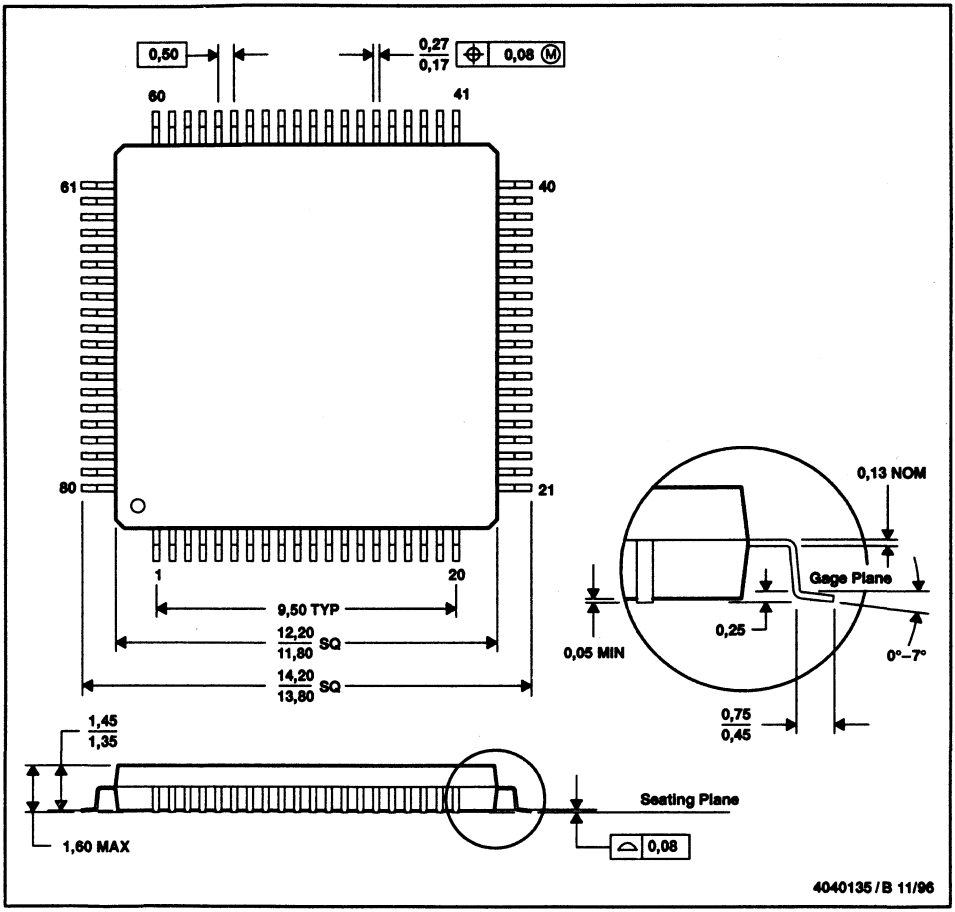
24 PIN SHOWN



DIM \ PINS **	24	28
A MAX	1.260 (32,04)	1.425 (36,20)
A MIN	1.230 (31,24)	1.385 (35,18)
B MAX	0.310 (7,87)	0.315 (8,00)
B MIN	0.290 (7,37)	0.295 (7,49)

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

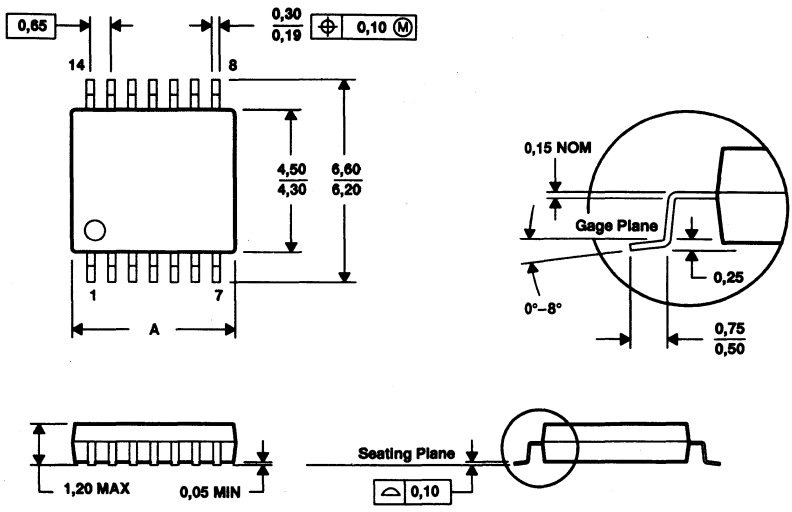
PN (S-PQFP-G80) **PLASTIC QUAD FLATPACK**



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-026

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PIN SHOWN

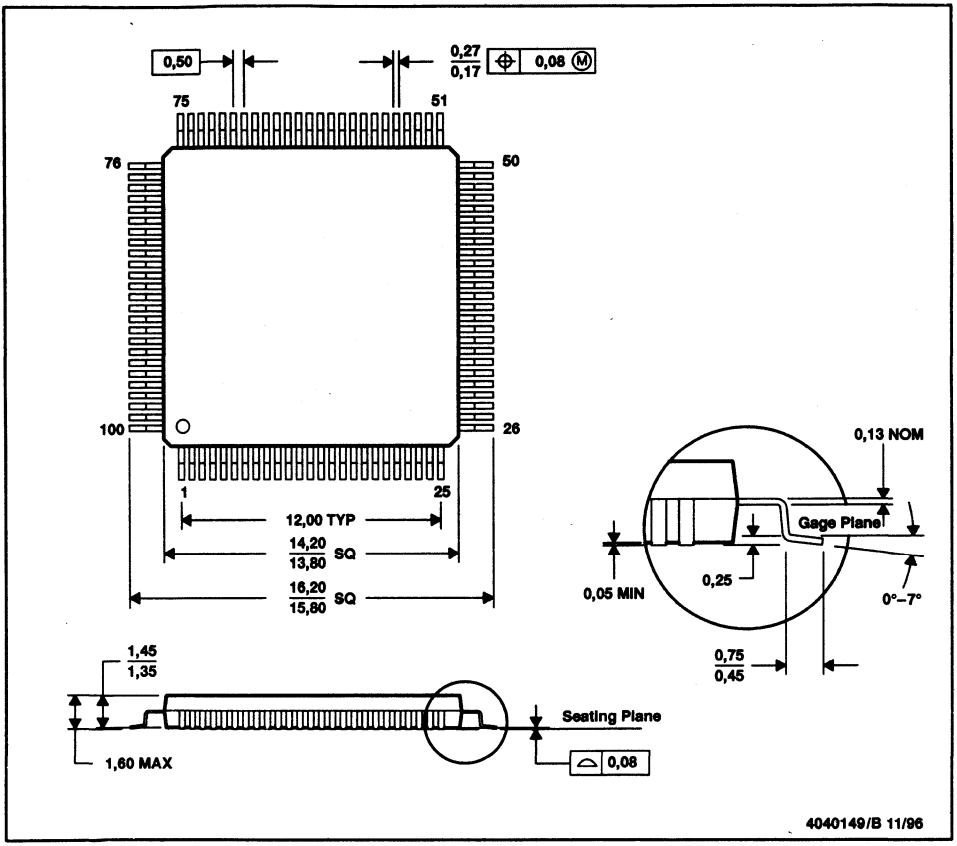


DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/E 08/96

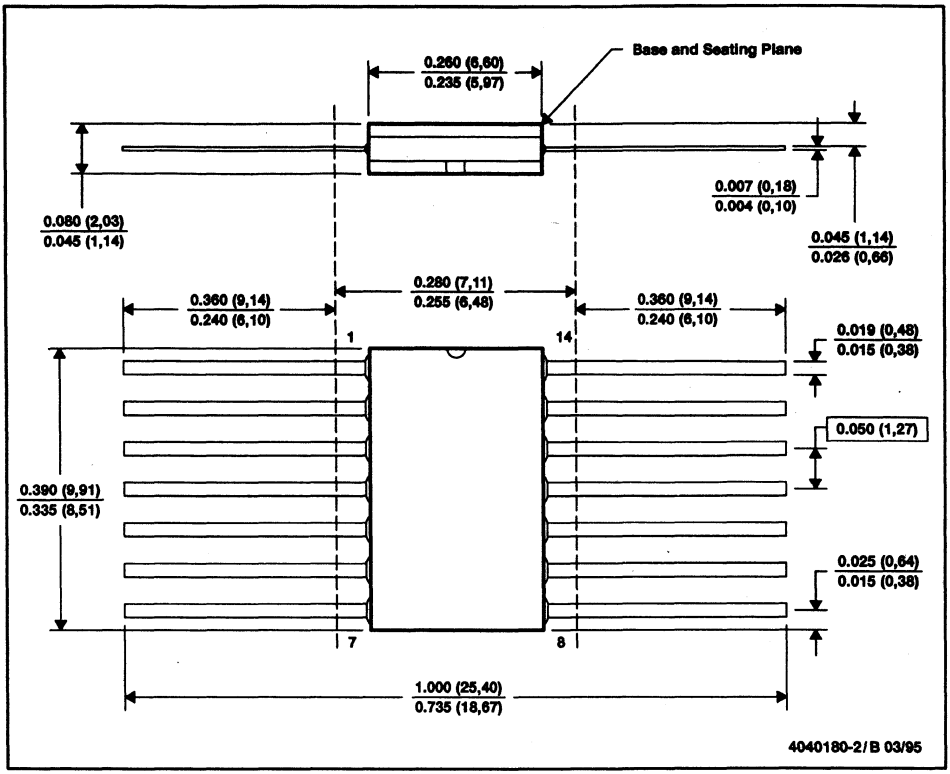
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

PZ (S-PQFP-G100) **PLASTIC QUAD FLATPACK**



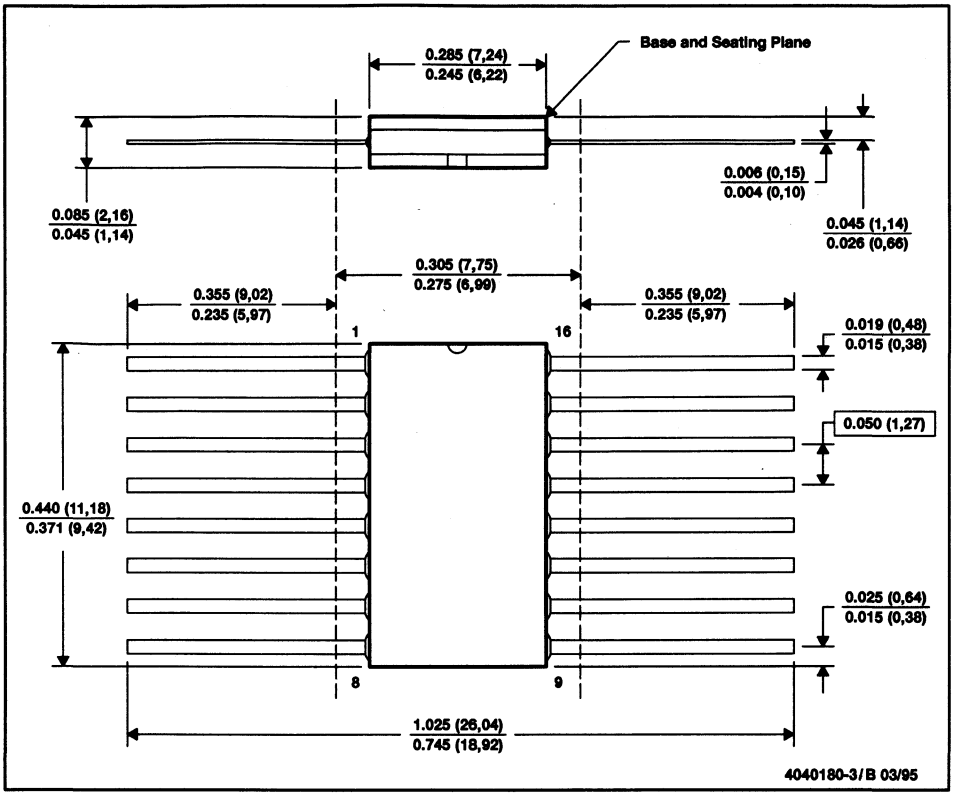
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-026

W (R-GDFP-F14) **CERAMIC DUAL FLATPACK**



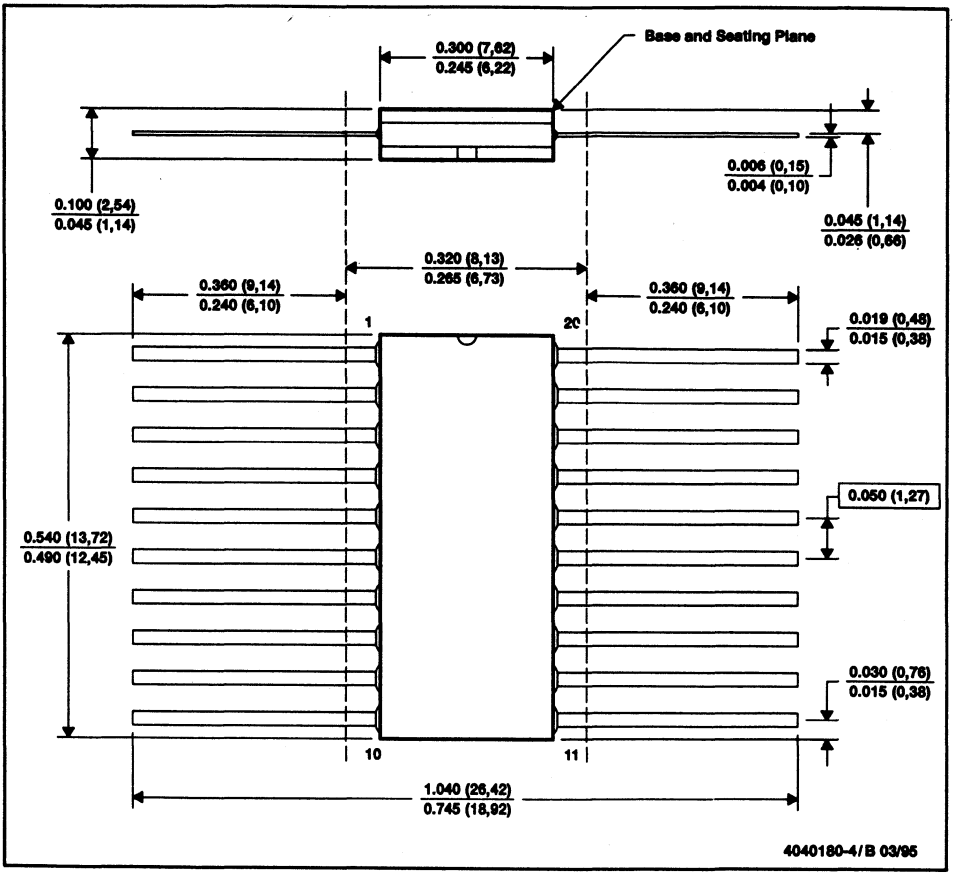
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

W (R-GDFP-F16) **CERAMIC DUAL FLATPACK**



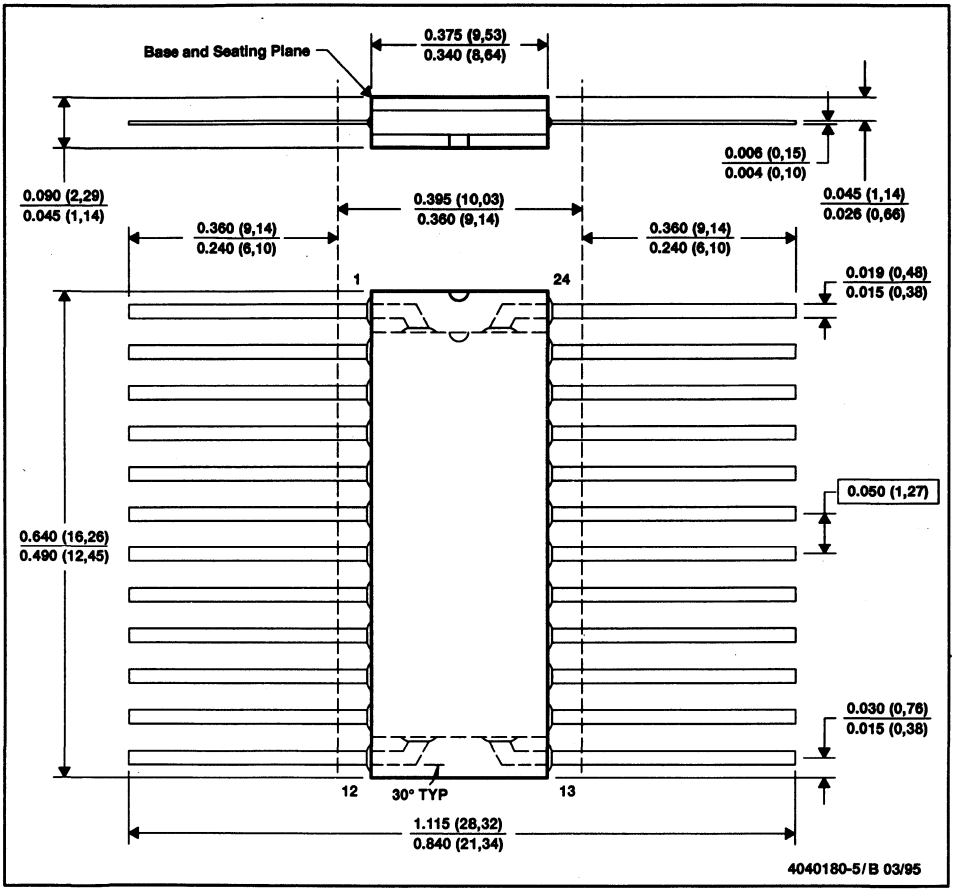
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL-STD-1835 GDFP1-F16 and JEDEC MO-092AC

W (R-GDFP-F20) **CERAMIC DUAL FLATPACK**



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL-STD-1835 GDFP2-F20

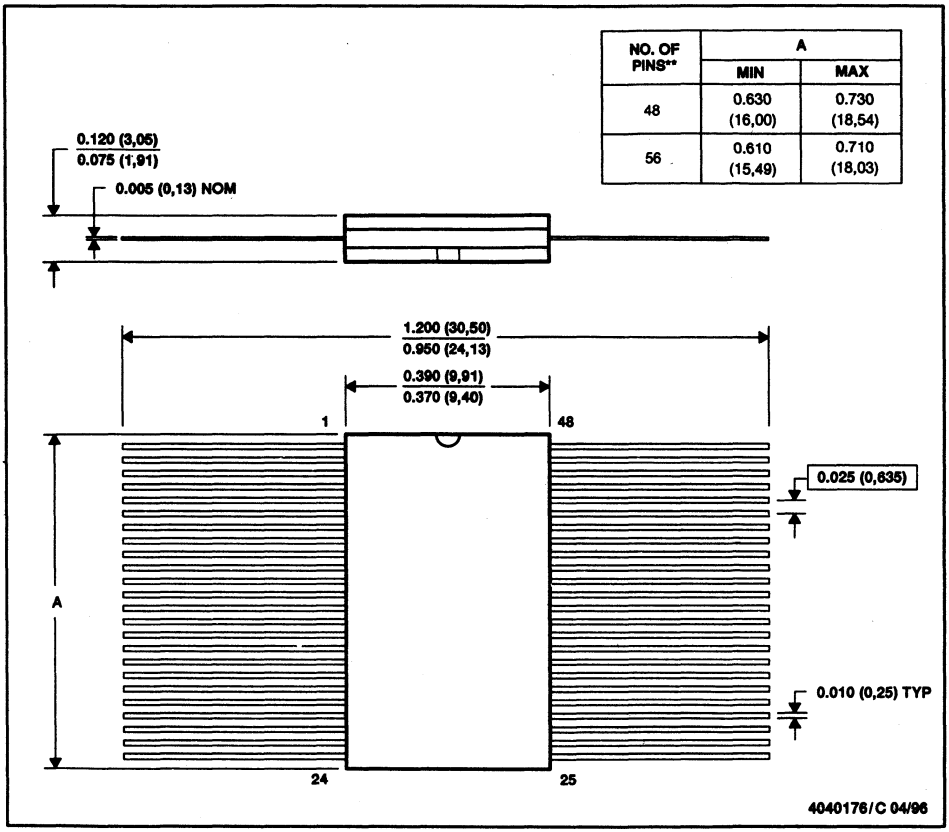
W (R-GDFP-F24) **CERAMIC DUAL FLATPACK**



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
E. Index point is provided on cap for terminal identification only.

WD (R-GDFP-F)** **CERAMIC DUAL FLATPACK**

48 PIN SHOWN



NO. OF PINS**	A	
	MIN	MAX
48	0.630 (16,00)	0.730 (18,54)
56	0.610 (15,49)	0.710 (18,03)

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for pin identification only
E. Falls within MIL-STD-1835: GDFP1-F48 and JEDEC MO-146AA
GDFP1-F56 and JEDEC MO-146AB

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